

SuperH™ RISC engine

SH7718R

Hardware Manual

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Preface

The SH7718R is a high-performance RISC (reduced instruction set computer) microcomputer. It represents a new generation of microcomputer (SuperH™* RISC engine) that incorporates peripheral functions needed for system configuration while achieving the low power consumption vital to microcomputer applications.

The SH7718R CPU has a RISC type instruction set, in which basic instructions run at one instruction per state, creating a dramatic improvement in the speed of instruction execution. It has an on-chip floating-point unit (FPU) compliant with the IEEE754 single-precision floating-point specification, enabling most FPU operations, including multiply-and-accumulate operations, to be executed by a single chip, for high precision at higher speed. The SH7718R's instructions are upward-compatible with the instructions of the SH-1, SH-2, and SH-3, facilitating migration from an SH-1, SH-2, or SH-3 to the SH7718R. The SH7718R is also fully compatible with the SH7708 Series (SH7708, SH7708S, and SH7708R).

To enable users to construct systems with the smallest number of parts, the SH7718R has an on-chip coprocessor as its floating point operations unit (FPU), an on-chip oscillation circuit, interrupt controller (INTC), timer, real-time clock (RTC), and serial communication interface (SCI) peripheral modules. A user break controller (UBC) is provided on chip to support program development and facilitate simple debugging.

Cache memory has been built in to increase CPU processing performance, and a memory management unit (MMU) translates 4 Gbytes of virtual and physical space addresses. The efficiency of external memory accesses has been increased by a bus state controller (BSC) that supports external memory accesses. DRAM, Synchronous DRAM, and pseudo-SRAM can be connected directly without glue logic.

This manual describes the hardware of the SH7718R. For information on instructions, see the *Programming Manual*.

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Related Manual

Details of SH7718R execution instructions:

SH-3/SH-3E/SH3-DSP Programming Manual

Contact the nearest sales office for information on the development environment system.

Main Revisions and Additions in this Edition

Page	Item	Revisions (See Manual for Details)
3	Table 1.1 Features	Hardware standby mode added to power-down modes
5		Product lineup addition
7	Figure 1.2 Pin Arrangement	<ul style="list-style-type: none"> Pin arrangement positions amended (entire figure rotated 90° so that pin 1 is at bottom left) Correction of pins 107, 126, and 129
56	2.6 Usage Note	New section added
192	10.11 Notes on Board Design	Following items added: Power Supply Pin Wiring External Device Connection
210	11.2.3 Wait State Control Register 1 (WCR1)	Bit 15 (WAITSEL) description added
244	11.3.3 Basic Interface	Added description of wait state timing when WAITSEL is set to 1
274	Figure 11.30 Synchronous DRAM Auto-Refresh Timing	RD/ \overline{WR} waveform amended
302	11.4.1 When Area 6 is Designated for PCMCIA, with a 16-Bit Bus Width	New sections added
302	11.4.2 Self-Refreshing	
302 to 303	11.4.3 PCMCIA Area Access	
325	Table 13.1 RTC Pin Configuration	Note amended
342	13.4 Usage Notes	New section added
473	Figure 17.43 Synchronous DRAM Self-Refresh Cycle (TPC = 0)	RD/ \overline{WR} signal waveform amended
549	Table D.1 List of Models	List of Models added

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Section 1 Overview

1.1 SH7718R Features

The SH7718R is a 32-bit RISC (reduced instruction set computer) microprocessor. Its object code is up-ward compatible with the SH-1 and SH-2 and fully pin compatible with SH7708 Series (SH7708, SH7708S, SH7708R). It has a built-in single precision floating point operations unit (FPU) and a memory management unit (MMU) that has an 8-kbyte cache that can be used for write-back or write-through and a 128-entry, 4-way set-associative translation lookaside buffer (TLB).

The SH7718R has an on-chip bus state controller (BSC) and can be connected directly to DRAM, synchronous DRAM (SDRAM), and pseudo-SRAM (PSRAM) without external circuits. The length of SH7718R instructions is fixed to 16 bits, so the code size can be almost cut in half compared to programs that use 32-bit instructions.

The features of the SH7718R are listed in table 1.1.

Table 1.1 SH7718R Features

Item	Features
CPU	<ul style="list-style-type: none">• Original Hitachi SuperH architecture• 32-bit internal data bus• General-register files<ul style="list-style-type: none">— Sixteen 32-bit general registers (eight 32-bit shadow registers)— Five 32-bit control registers— Six 32-bit system registers• RISC-type instruction set (downward compatibility with the SH-1 and SH-2 series)<ul style="list-style-type: none">— Instruction length: 16-bit fixed length for improved code efficiency— Load-store architecture— Delayed branch instructions— Instruction set based on C language• Instruction execution time: one instruction/cycle for basic instructions• Logical address space: 4 Gbytes (448-Mbyte actual memory space)• Space identifier ASID: 8 bits, 256 logical address space• On-chip multiplier• Five-stage pipeline
FPU	<ul style="list-style-type: none">• SuperH architecture coprocessor• Supports single precision floating-point format• Supports subset of the IEEE754 standard data type• Supports invalid-operation and division-by-zero exceptions (subset of the IEEE754 standard)• Supports rounding to zero (subset of the IEEE754 standard)• Sixteen 32-bit floating-point data registers• Supports FMAC (multiply & accumulate)• Supports FDIV/FSQRT (division/square root instructions)• Supports FLDI0/FLDI1 (load constant0/1)• Instruction latency time: two cycles for FMAC/FADD/FSUB/FMUL• Execution pitch: one cycle for FMAC/FADD/FSUB/FMUL

Table 1.1 SH7718R Features (cont)

Item	Features
Operating modes, clock pulse generator	<ul style="list-style-type: none">• Clock mode: selected from an on-chip oscillator module, a frequency-doubling circuit, or a clock output by combining with PLL synchronization circuit• Processing states:<ul style="list-style-type: none">— Power-on reset state— Manual reset state— Exception processing state— Program execution state— Power-down state— Bus-released state• Power-down modes:<ul style="list-style-type: none">— Sleep mode— Standby mode— Hardware standby mode• On-chip clock pulse generator• Watchdog timer: 1 channel
Memory management unit	<ul style="list-style-type: none">• 4 Gbytes of address space, 256 address spaces (ASID 8 bits)• Supports single virtual memory mode and multiplexed virtual memory mode• Page unit sharing• Supports multiple page sizes: 1, 4 kbytes• 128-entry, 4-way set associative TLB• Supports software selection of replacement way and random-replacement algorithms• Contents of TLB are directly accessible by address mapping
Cache memory	<ul style="list-style-type: none">• Mixed instruction/data• Selectable operating modes:<ul style="list-style-type: none">— Normal mode (8 kbytes cache)— RAM mode (4-kbyte cache and 4-kbyte RAM)• 128 entries, 16-byte block length<ul style="list-style-type: none">— 4-way set associative (8-kbyte cache)— 2-way set associative (4-kbyte cache)

Table 1.1 SH7718R Features (cont)

Item	Features
Cache memory (cont)	<ul style="list-style-type: none">• Selectable write policy (write-back/write-through), least recently used (LRU) replacement algorithm• 1-stage write-back buffer• Contents of cache memory can be accessed directly by address mapping (can be used as on-chip memory)
Interrupt controller	<ul style="list-style-type: none">• Five external interrupt pins ($\overline{\text{NMI}}$, $\overline{\text{IRL0}}$–$\overline{\text{IRL3}}$) and encoded input of 15 external interrupt causes (through $\overline{\text{IRL0}}$–$\overline{\text{IRL3}}$ pins)• On-chip peripheral interrupts: set priority levels for each module
User break controller	<ul style="list-style-type: none">• Supports debugging by user break interrupts• 2 break channels• Addresses, data values, type of access, and data size can all be set as break conditions• Supports a sequential break function
Bus state controller	<ul style="list-style-type: none">• Supports external memory access<ul style="list-style-type: none">— 32/16/8-bit external data bus• Physical address space divided into seven areas, each 64 Mbytes, with the following features settable for each area:<ul style="list-style-type: none">— Bus size (8, 16, or 32 bits)— Number of wait cycles (also supports a hardware wait function)— Setting the type of space enables direct connection to DRAM, SDRAM, PSRAM, and burst ROM— DRAM supports fast-page mode and EDO— Supports PCMCIA interface— Outputs chip select signal (CS0–CS6) for corresponding area• DRAM/SDRAM refresh function<ul style="list-style-type: none">— Programmable refresh interval— Supports CAS-before-RAS refresh and self-refresh modes• DRAM/SDRAM/PSRAM burst access function• Configurable as either big or little endian machine

Table 1.1 SH7718R Features (cont)

Item	Features
Timer	<ul style="list-style-type: none"> • 3-channel auto-reload type 32-bit timer • Input capture function • 6 types of counter input clocks can be selected • Maximum resolution: 2 MHz
Real-time clock	<ul style="list-style-type: none"> • Built-in clock and calendar functions • On-chip 32-kHz crystal oscillator circuit with a maximum resolution (cycle interrupt) of 1/256 second
Serial communication interface	<ul style="list-style-type: none"> • Select start-stop sync mode or clock sync system • Full-duplex communication • Supports smart card interface

Product lineup

Abbr.	Voltage	Operating Frequency	Mask Version	Model	Package
SH7718R	3.15 V to 3.6 V	100 MHz	—	HD6417718RF100	144-pin plastic
			A-mask	HD6417718RF100A	LQFP (FP-144F)

1.2 Block Diagram

Figure 1.1 is a functional block diagram of the SH7718R.

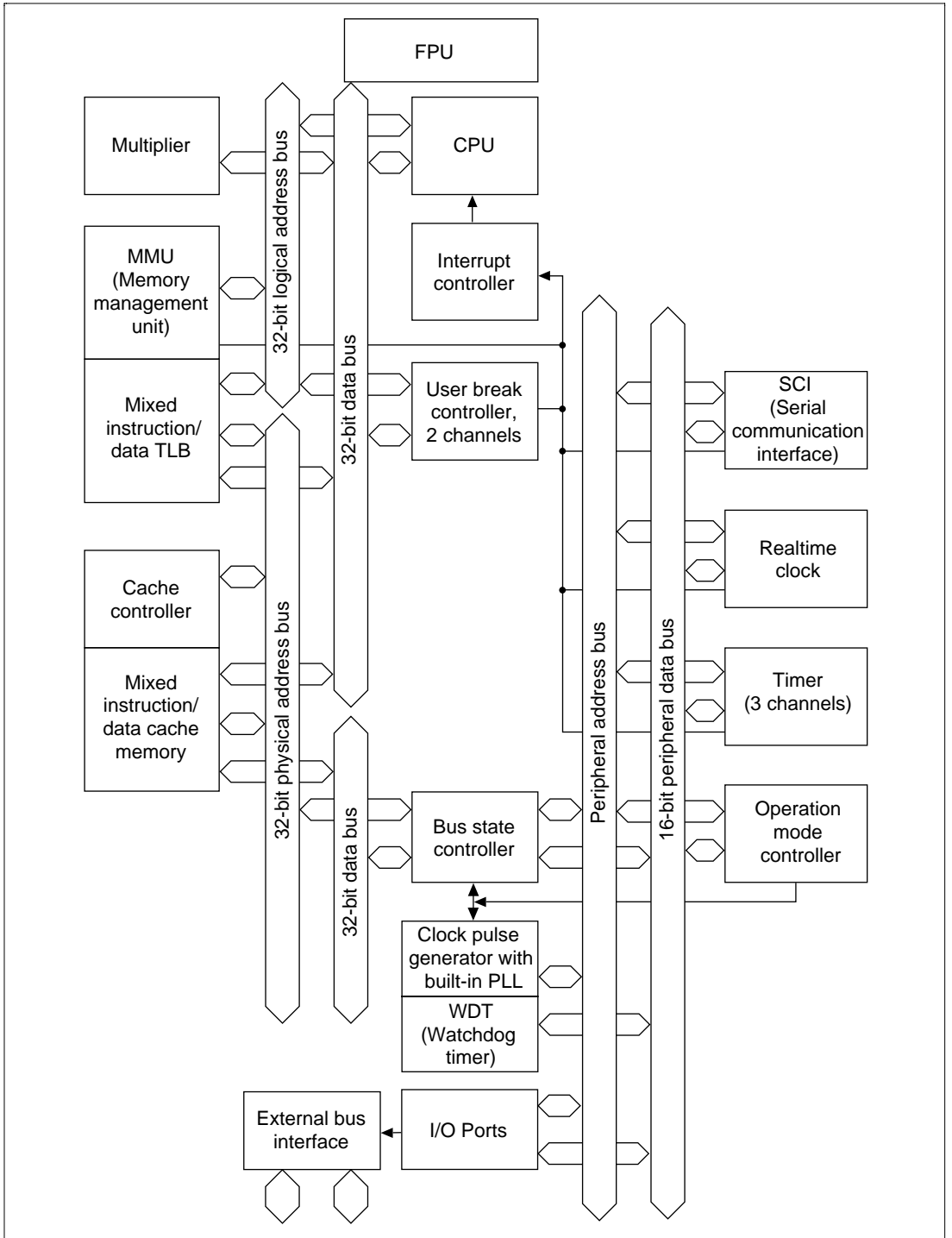


Figure 1.1 SH7718R Block Diagram

1.3 Pin Description

1.3.1 Pin Arrangement

Figure 1.2 shows the pin arrangement.

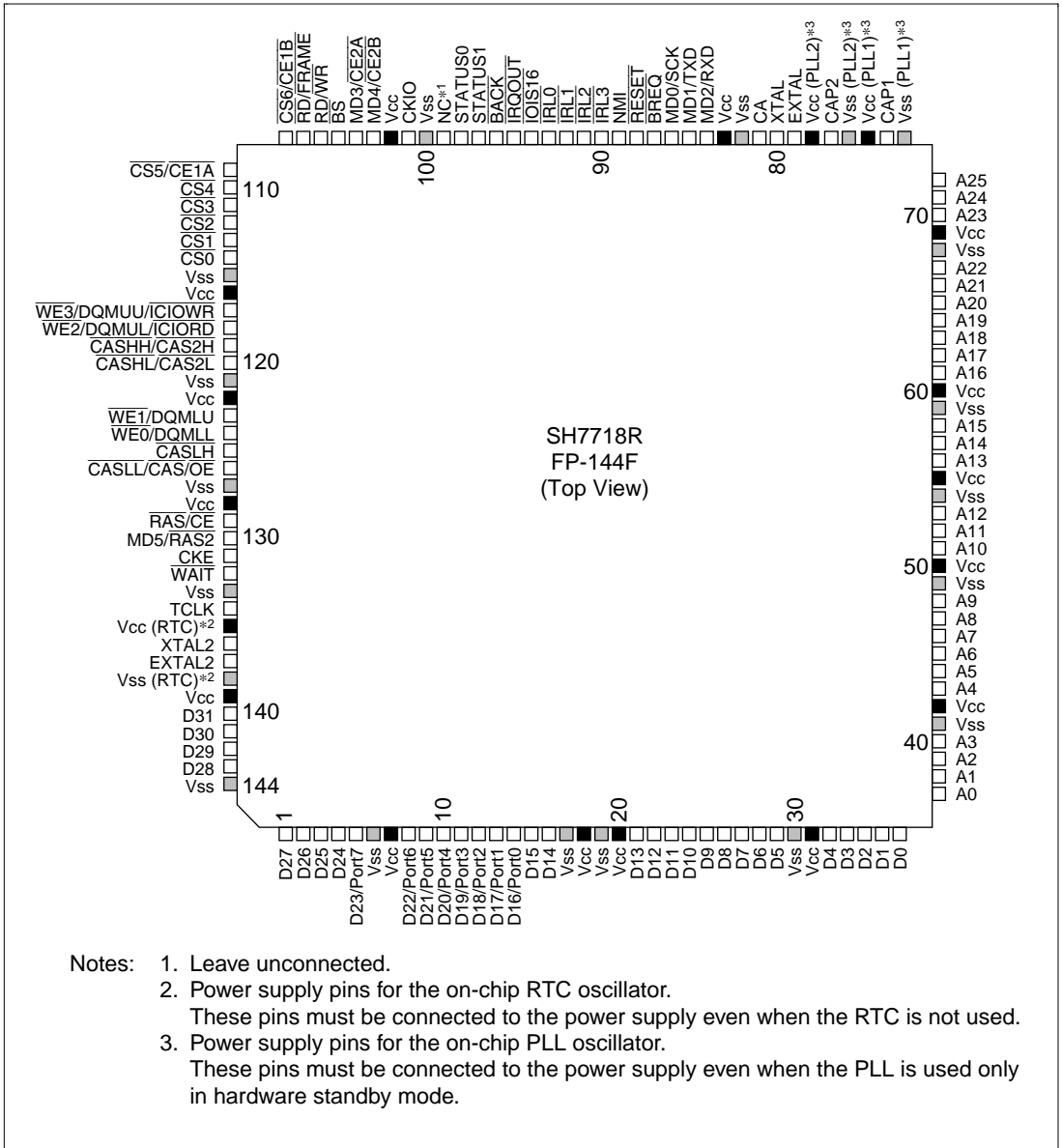


Figure 1.2 Pin Arrangement

1.3.2 SH7718R Pin Functions

Table 1.2 shows the pin functions.

Table 1.2 SH7718R Pin Functions

No.	Terminal	I/O	Description
1	D27	I/O	Data bus/Port
2	D26	I/O	Data bus/Port
3	D25	I/O	Data bus/Port
4	D24	I/O	Data bus/Port
5	D23/Port7	I/O	Data bus/Port
6	V _{ss}	Power	Power (0 V)
7	V _{cc}	Power	Power (3.3 V)
8	D22/Port6	I/O	Data bus/Port
9	D21/Port5	I/O	Data bus/Port
10	D20/Port4	I/O	Data bus/Port
11	D19/Port3	I/O	Data bus/Port
12	D18/Port2	I/O	Data bus/Port
13	D17/Port1	I/O	Data bus/Port
14	D16/Port0	I/O	Data bus/Port
15	D15	I/O	Data/address bus
16	D14	I/O	Data/address bus
17	V _{ss}	Power	Power (0 V)
18	V _{cc}	Power	Power (3.3 V)
19	V _{ss}	Power	Power (0 V)
20	V _{cc}	Power	Power (3.3 V)
21	D13	I/O	Data bus
22	D12	I/O	Data bus
23	D11	I/O	Data bus
24	D10	I/O	Data bus
25	D9	I/O	Data bus
26	D8	I/O	Data bus
27	D7	I/O	Data bus
28	D6	I/O	Data bus
29	D5	I/O	Data bus

Table 1.2 SH7718R Pin Functions (cont)

No.	Terminal	I/O	Description
30	V _{SS}	Power	Power (0 V)
31	V _{CC}	Power	Power (3.3 V)
32	D4	I/O	Data bus
33	D3	I/O	Data bus
34	D2	I/O	Data bus
35	D1	I/O	Data bus
36	D0	I/O	Data bus
37	A0	O	Address bus
38	A1	O	Address bus
39	A2	O	Address bus
40	A3	O	Address bus
41	V _{SS}	Power	Power (0 V)
42	V _{CC}	Power	Power (3.3 V)
43	A4	O	Address bus
44	A5	O	Address bus
45	A6	O	Address bus
46	A7	O	Address bus
47	A8	O	Address bus
48	A9	O	Address bus
49	V _{SS}	Power	Power (0 V)
50	V _{CC}	Power	Power (3.3 V)
51	A10	O	Address bus
52	A11	O	Address bus
53	A12	O	Address bus
54	V _{SS}	Power	Power (0 V)
55	V _{CC}	Power	Power (3.3 V)
56	A13	O	Address bus
57	A14	O	Address bus
58	A15	O	Address bus
59	V _{SS}	Power	Power (0 V)
60	V _{CC}	Power	Power (3.3 V)

Table 1.2 SH7718R Pin Functions (cont)

No.	Terminal	I/O	Description
61	A16	O	Address bus
62	A17	O	Address bus
63	A18	O	Address bus
64	A19	O	Address bus
65	A20	O	Address bus
66	A21	O	Address bus
67	A22	O	Address bus
68	V _{SS}	Power	Power (0 V)
69	V _{CC}	Power	Power (3.3 V)
70	A23	O	Address bus
71	A24	O	Address bus
72	A25	O	Address bus
73	V _{SS} (PLL1)* ²	Power	Power (0 V) for PLL1
74	CAP1	O	External capacitance pin for PLL
75	V _{CC} (PLL1)* ²	Power	Power (3.3 V) for PLL1
76	V _{SS} (PLL2)* ²	Power	Power (0 V) for PLL2
77	CAP2	O	External capacitance pin for PLL
78	V _{CC} (PLL2)* ²	Power	Power (3.3 V) for PLL2
79	EXTAL	I	External clock/crystal oscillator pin
80	XTAL	O	Crystal oscillator pin
81	CA	I	Chip active
82	V _{SS}	Power	Power (0 V)
83	V _{CC}	Power	Power (3.3 V)
84	MD2/RXD	I	Operating mode pin/serial data input
85	MD1/TXD	I/O	Operating mode pin/serial data output
86	MD0/SCK	I/O	Operating mode pin/serial clock
87	$\overline{\text{BREQ}}$	I	Bus request
88	$\overline{\text{RESET}}$	I	Reset
89	NMI	I	Nonmaskable interrupt request
90	$\overline{\text{IRL3}}$	I	External interrupt cause input
91	$\overline{\text{IRL2}}$	I	External interrupt cause input

Table 1.2 SH7718R Pin Functions (cont)

No.	Terminal	I/O	Description
92	$\overline{\text{IRL1}}$	I	External interrupt cause input
93	$\overline{\text{IRL0}}$	I	External interrupt cause input
94	$\overline{\text{IOIS16}}$	I	IO16-bit instruction
95	$\overline{\text{IRQOUT}}$	O	Bus request output
96	$\overline{\text{BACK}}$	O	Bus acknowledge
97	STATUS1	O	Processor status
98	STATUS0	O	Processor status
99	NC	O	Do not connect anything
100	V _{SS}	Power	Power (0 V)
101	CKIO	I/O	System clock I/O
102	V _{CC}	Power	Power (3.3 V)
103	MD4/CE2B	I/O	Operating mode pin/PCMCIA CE pin
104	MD3/CE2A	I/O	Operating mode pin/PCMCIA CE pin
105	$\overline{\text{BS}}$	O	Bus cycle start
106	$\overline{\text{RD/WR}}$	O	Read/write
107	$\overline{\text{RD}}$	O	Read pulse
108	$\overline{\text{CS6/CE1B}}$	O	Chip select 6/PCMCIA CE pin
109	$\overline{\text{CS5/CE1A}}$	O	Chip select 5/PCMCIA CE pin
110	$\overline{\text{CS4}}$	O	Chip select 4
111	$\overline{\text{CS3}}$	O	Chip select 3
112	$\overline{\text{CS2}}$	O	Chip select 2
113	$\overline{\text{CS1}}$	O	Chip select 1
114	$\overline{\text{CS0}}$	O	Chip select 0
115	V _{SS}	Power	Power (0 V)
116	V _{CC}	Power	Power (3.3 V)
117	$\overline{\text{WE3/DQMUU/ICIOWR}}$	O	D31–D24 selection signal/IO write
118	$\overline{\text{WE2/DQMUL/ICIORD}}$	O	D23–D16 selection signal/IO read
119	$\overline{\text{CASHH/CAS2H}}$	O	D31–D24/D15–D8 selection signal
120	$\overline{\text{CASHL/CAS2L}}$	O	D23–D16/D7–D0 selection signal
121	V _{SS}	Power	Power (0 V)
122	V _{CC}	Power	Power (3.3 V)

Table 1.2 SH7718R Pin Functions (cont)

No.	Terminal	I/O	Description
123	$\overline{\text{WE1}}/\text{DQMLU}$	O	D15–D8 selection signal
124	$\overline{\text{WE0}}/\text{DQMLL}$	O	D7–D0 selection signal
125	$\overline{\text{CASLH}}$	O	D15–D8 selection signal
126	$\overline{\text{CASLL}}/\overline{\text{CAS}}/\overline{\text{OE}}$	O	D7–D0 selection/memory selection signal
127	V_{SS}	Power	Power (0 V)
128	V_{CC}	Power	Power (3.3 V)
129	$\overline{\text{RAS}}/\overline{\text{CE}}$	O	RAS/PSRAM CE
130	$\text{MD5}/\overline{\text{RAS2}}$	I/O	Operating mode pin/RAS for DRAM
131	CKE	O	Clock enable control for SDRAM
132	$\overline{\text{WAIT}}$	I	Hardware wait request
133	V_{SS}	Power	Power (0 V)
134	TCLK	I/O	Clock I/O for TMU/RTC
135	$V_{\text{CC}}(\text{RTC})^{*3}$	Power	Power for RTC oscillator (3.3 V)
136	XTAL2	O	Crystal oscillator pin for on-chip RTC
137	EXTAL2	I	Crystal oscillator pin for on-chip RTC
138	$V_{\text{SS}}(\text{RTC})^{*3}$	Power	GND for RTC oscillator (0 V)
139	V_{CC}	Power	Power (3.3 V)
140	D31	I/O	Data bus
141	D30	I/O	Data bus
142	D29	I/O	Data bus
143	D28	I/O	Data bus
144	V_{SS}	Power	Power (0 V)

- Notes: 1. Except in hardware standby mode, connect all V_{CC} and V_{SS} pins to the system power supply (power should be supplied constantly). In hardware standby mode, power should be supplied at least to $V_{\text{CC}}(\text{RTC})$ and $V_{\text{SS}}(\text{RTC})$. If power is not supplied to V_{CC} and V_{SS} pins other than $V_{\text{CC}}(\text{RTC})$ and $V_{\text{SS}}(\text{RTC})$, hold the CA pin low.
2. Provide the power supply regardless of whether the built-in PLL is used.
3. Provide the power supply regardless of whether the built-in RTC is used.

2.1 Organization of Registers

2.1.1 Privileged Mode and Banks

Processing Modes: The SH7718R has two operating modes: user mode and privileged mode. The SH7718R operates in user mode under normal conditions and enters privileged mode in response to an exception or interrupt. There are three types of registers: general, system, and control. All of these registers are 32 bits. Which registers can be accessed through software depends on the processing mode.

General-Purpose Registers: There are 16 general-purpose registers, numbered R0 through R15. General-purpose registers R0 to R7 are banked registers that are switched by the processor mode.

In privileged mode, the register bank (RB) bit in the status register (SR) defines which banked registers can be accessed as general-purpose registers and which cannot. Inaccessible registers can be accessed through the load control register (LDC) and store control register (STC) instructions.

When the RB bit is one (BANK1 is selected), BANK1 general-purpose registers R0_BANK1 through R7_BANK1 and non-banked general-purpose registers R8 through R15 (a total of 16 registers) can be accessed as general-purpose registers R0 through R15 and BANK0 general-purpose registers R0_BANK0 through R7_BANK0 (eight registers) are accessed by the LDC and STC instructions. When the RB bit is a zero (BANK0 is selected), BANK0 general-purpose registers R0_BANK0 through R7_BANK0 and nonbanked general-purpose registers R8 through R15 (16 registers) can be accessed as general-purpose registers R0 through R15 and BANK1 general-purpose registers R0_BANK1 through R7_BANK1 (eight registers) are accessed by the LDC and STC instructions.

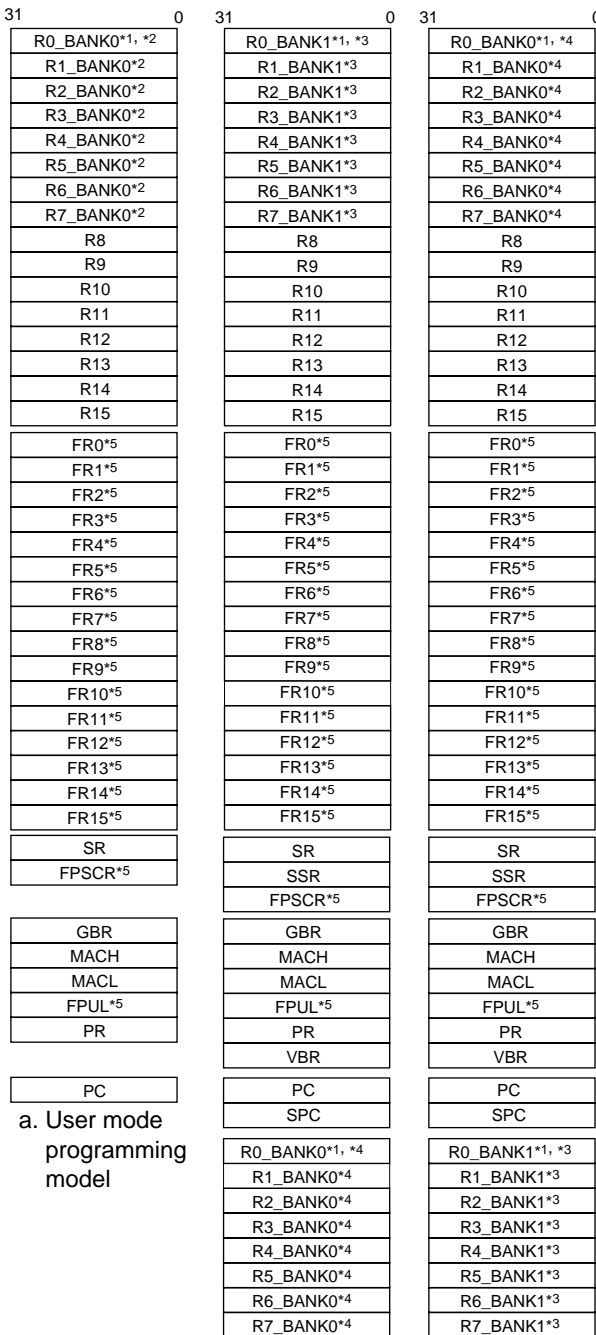
In user mode, BANK0 general-purpose registers R0_BANK0 through R7_BANK0 and nonbanked general-purpose registers R8 through R15 can be accessed as general-purpose registers R0 through R15 (a total of 16 registers) and BANK1 general-purpose registers R0_BANK1 through R7_BANK1 (eight registers) cannot be accessed.

Control Registers: The control registers include registers that can be accessed in either mode (the global base register (GBR) and status register (SR)) and registers that can only be accessed in privileged mode (the saved status register (SSR), saved program counter (SPC), and vector base register (VBR)). Some bits in the status register (for example, the RB bit) can only be accessed in privileged mode.

System Registers: There are four system registers that can be accessed in either processing mode:

- Multiply and accumulate registers
 - Multiply and accumulate high (MACH)
 - Multiply and accumulate low (MACL)
- Procedure register (PR)
- Program counter (PC)

The register configurations are shown in figure 2.1 by processing mode. Switch between user and privileged modes using the processing operation mode bit in the status register.



- Notes:
1. R0 functions as an index register in the indexed register-indirect addressing mode and indexed GBR-indirect addressing mode.
 2. Banked register.
 3. Banked register. Accessible as general-purpose register when SR, RB is 1. Accessible by LDC or STC instruction when SR, RB is 0.
 4. Banked register. Accessible as general-purpose register when SR, RB is 0. Accessible by LDC or STC instruction when SR, RB is 1.
 5. FPU register. For more information, see section 3, Floating Point Unit.

b. Privileged mode programming model (RB = 1) c. Privileged mode programming model (RB = 0)

Figure 2.1 Register Configurations for Different Processing Modes

Table 2.1 shows the register values after a reset.

Table 2.1 Initial Register Values

Register Type	Register	Initial Value* ¹
General purpose	R0–R15	Undefined
	FR0–FR15* ²	Undefined
Control	SR	MD bit is 1, RB bit is 1, BL bit is 1, bits 13–10 are 1111 (H'F), reserved bits are 0, and all others are undefined
	GBR, SSR, SPC	Undefined
	VBR	H'00000000
System	MACH, MACL, PR, FPSCR* ² , FPUL* ²	Undefined
	PC	H'A0000000

Notes: 1. Initialized by a power-on reset or manual reset.

2. There registers are used in floating point operations. For more information on FR0 to FR15, FPSCR, and FPUL, see section 3, Floating Point Unit.

2.1.2 General-Purpose Registers

There are 16 general-purpose registers, numbered R0–R15. R0–R7 are banked registers. Different banks of R0–R7 registers (R0_BANK0 through R7_BANK0 and R0_BANK1 through R7_BANK1) are accessible in different modes (figure 2.1).

Figure 2.2 shows the structure of the general-purpose registers.

31

0

General-purpose registers

Undefined after reset

R0*1, *2
R1*2
R2*2
R3*2
R4*2
R5*2
R6*2
R7*2
R8
R9
R10
R11
R12
R13
R14
R15

31

0

Floating point data register

The FMAC instruction uses FR0 to set the multiplication value.

FR0*3
FR1*3
FR2*3
FR3*3
FR4*3
FR5*3
FR6*3
FR7*3
FR8*3
FR9*3
FR10*3
FR11*3
FR12*3
FR13*3
FR14*3
FR15*3

- Notes:
1. R0 functions as an index register in the indexed register-indirect addressing mode and indexed GBR-indirect addressing mode. In some instructions, only R0 can be used as the source or destination register.
 2. R0–R7 are banked registers. In privileged mode, the SR register's RB bit determines which banks are accessed as general-purpose registers(R1_BANK0 through R7_BANK0 and R1_BANK1 through R7_BANK1). In some instructions, R0 is fixed as the source of the destination register.
 3. See section 3, Floating Point Unit, for more information on floating point registers FR0–FR15.

Figure 2.2 Structure of the General-Purpose Registers

2.1.3 System Registers

The system registers are accessed by the LDS and STS instructions. When an exception occurs, the contents of the PC are saved in the SPC. The PC contents are also restored from the SPC when ending exception processing with an RTE instruction. The six system registers are:

- MACH: Multiply and accumulate high register
- MACL: Multiply and accumulate low register
- PR: Procedure register
- PC: Program counter
- FPUL: FPU communication register
- FPSCR: Floating point status/control register

Figure 2.3 shows the system registers.

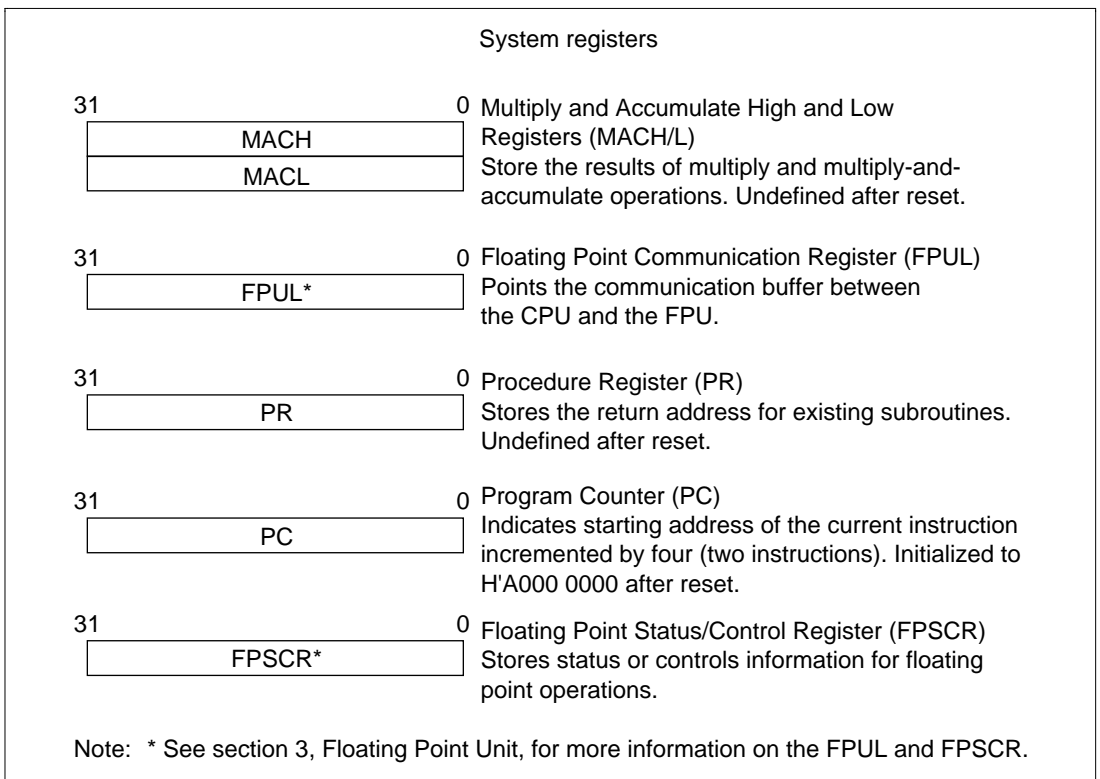


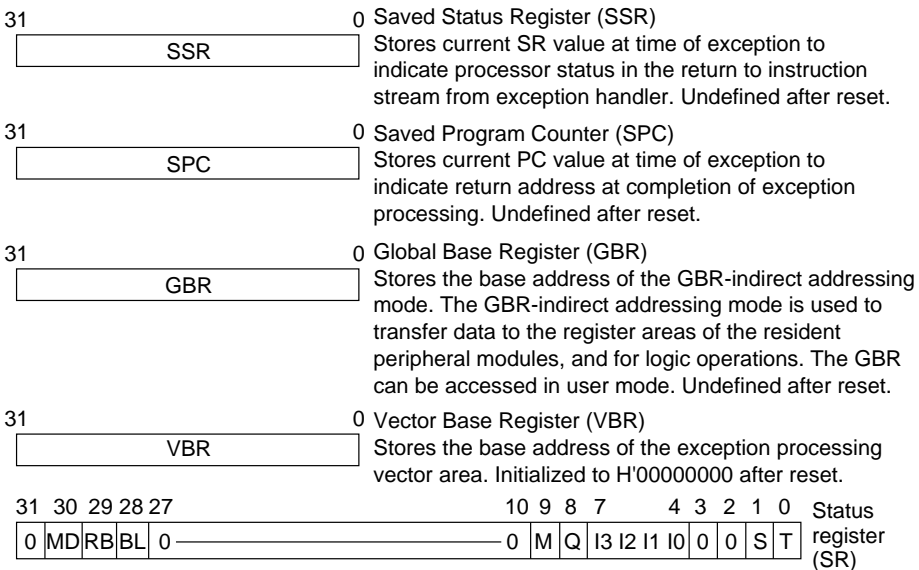
Figure 2.3 System Register Configuration

2.1.4 Control Registers

The control registers can be accessed by the LDC and STC instructions in privileged mode. The GBR can also be accessed in user mode. The five control registers are:

- SR: Status register
- SSR: Saved status register
- SPC: Saved program counter
- GBR: Global base register
- VBR: Vector base register

Figure 2.4 shows the organization of the control registers.



MD: Processor operation mode bit: Indicates the processor operation mode as follows: 1 = Privileged mode; 0 = User mode. Becomes 1 when an exception or interrupt occurs. Initialized to 1 reset.

RB: Register bank bit: Defines the general-purpose register used as bank in privileged mode. A logic 1 designates R0_BANK1–R7_BANK1 and R8–R15 are accessed as general-purpose registers, and R0_BANK0–R7_BANK0 are only accessed by LDC and STC instructions; a logic zero designates R0_BANK0–R7_BANK0 and R8–R15 are accessed as general-purpose registers, and R0_BANK1–R7_BANK1 are only accessed by LDC and STC instructions. Becomes 1 when an exception or interrupt occurs. Initialized to 1 reset.

BL: Block bit: Masks exceptions and interrupts when 1. For details, see section 5, Exception Processing. When 0, accepts exceptions and interrupts. Becomes 1 when an exception or interrupt occurs. Initialized to 1 at reset.

M and Q bits: Used by the DIVOS/DIVOU and DIV1 instructions.

I3–I0: Interrupt mask bits: A 4-bit field indicating the interrupt request mask level. The level of interrupt acceptance does not change when an interrupt occurs. Initialized to B'1111 at reset.

S bit: Used by the MAC instruction.

T bit: The MOV_T, CMP/cond, TAS, TST, BT, BF, SETT, CLRT, and DT instructions use the T bit to indicate true (logic one) or false (logic zero). The ADD_V/ADDC, SUB_V/SUBC, DIVOU/DIVOS, DIV1, NEGC, SHAR/SHAL, SHLR/SHRL, ROTA/ROTL, and ROTCR/ROTCL instructions also use the T bit to indicate a carry, borrow, overflow or underflow.

0 bits: Always read as 0, and should always be written as 0.

Note: Only the M, Q, S, and T can be set or cleared by special instructions from user mode. Undefined after reset. All other bits are read or written from privileged mode.

Figure 2.4 Control Registers Configuration

2.2 Data Formats

2.2.1 Data Format in Registers

Register operands are always longwords (32 bits). When the memory data operand size is only byte (8 bits) or word (16 bits), it is sign-extended into a longword when loaded into a register.

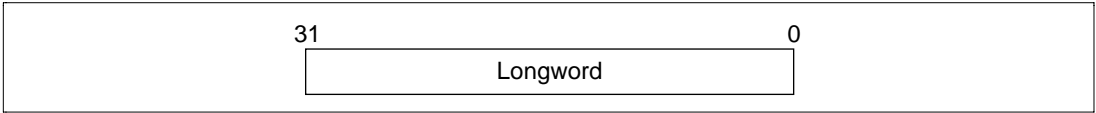


Figure 2.5 Longword Operand

2.2.2 Data Format in Memory

Memory data formats are classified into bytes, words, and longwords. Memory can be accessed in bytes (8 bits), words (16 bits), or longwords (32 bits). Memory operands that do not fill out 32 bits are sign-extended and stored in a register.

Access word operands from word boundaries (even addresses two bytes apart: $2n$ addresses) and longword operands from longword boundaries (even addresses four bytes apart: $4n$ addresses). Other accesses cause address errors. Byte operands can be accessed from any address.

Data formats can use either big endian or little endian byte order. Use the external pin (MD5) to set the endian at power-on reset. When MD5 is low, the processor operates in big endian; when MD5 is high, the processor operates in little endian. Endians cannot be changed dynamically. Numbers are always assigned to bit positions, from most significant to least significant and from left to right. For example, in a longword (32 bits), the leftmost bit (31) is the most significant and the rightmost bit (0) is the least significant.

Figure 2.6 shows the data format in memory. When little endian is used, data written in bytes (8 bits) should be read in bytes. Data written in words (16 bits) should be read in words.

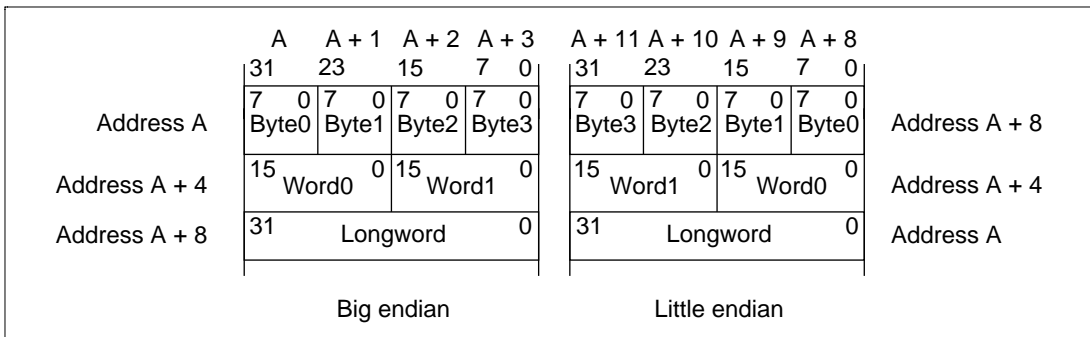


Figure 2.6 Data Formats in Memory

2.3 Instruction Features

2.3.1 Executing Instructions

Data Length: The SH7718R instruction set is implemented in fixed-length 16-bit wide instructions executed in a pipelined sequence with single-cycle execution for most instructions. All data is processed in 32-bit longword units. Memory can be accessed in 8-bit byte, 16-bit word, or 32-bit longword units, with byte or word units sign-extended into 32-bit longwords. Literals are sign-extended in arithmetic operations (MOV, ADD, and CMP/EQ instructions) and zero-extended in logical operations (TST, AND, OR, and XOR instructions).

Load Store Architecture: The SH7718R features a load-store architecture in which basic operations are executed in registers. Operations requiring memory access are executed in registers following register loading by data transfer instructions, except for bit-manipulation operations such as logical AND functions, which are executed directly in memory.

Delayed Branches: Unconditional branching is implemented as delayed branch operations. Pipeline disruptions due to branching are minimized by the execution of the instruction following the delayed branch instruction prior to branching. There are two types of conditional branch instructions: delayed branch instructions and ordinary branch instructions. For example:

```

BRA      TRGET
ADD     R1, R0      ;ADD is executed prior to branching to TRGET

```

T Bits: The T bit in the status register (SR) is used to indicate the result of comparison operations, and is read as a TRUE/FALSE condition determining if a conditional branch is taken or not. To improve processing speed, the T bit logic state is modified only by specific instructions. An example of how the T bit may be used in a sequence of operations:

```
ADD      #1, R0      ;T bit not modified by ADD operation
CMP/EQ   #0, R0      ;T bit set to 1 when R0 = 0
BT       TRGET       ;Branch taken to TRGET when T bit = 1 (R0 = 0)
```

Literals: Byte-wide literals are inserted directly into the instruction code as immediate data. To maintain the 16-bit fixed-length instruction code, word or longword literals are stored in a table in main memory rather than inserted directly into the instruction code. The memory table is accessed by the MOV instruction using PC-relative addressing with displacement, as follows:

```
MOV.W    @(disp, PC), R0
```

Absolute Addresses: As with word and longword literals, absolute addresses must also be stored in a table in main memory. The value of the absolute address is transferred to a register and the operand access is specified by indexed register-indirect addressing, with the absolute address loaded (as are word and longword immediate data) during instruction execution.

16-bit and 32-bit Displacements: In the same way, 16-bit and 32-bit displacements used in referencing data also must be stored in a table in main memory. As with absolute addresses, the displacement value is transferred to a register and the operand access is specified by indexed register-indirect addressing, loading the displacement (as with word and longword immediate data) during instruction execution.

2.3.2 Addressing Modes

Table 2.2 describes addressing modes and effective address calculation.

Table 2.2 Addressing Modes and Effective Addresses

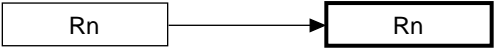
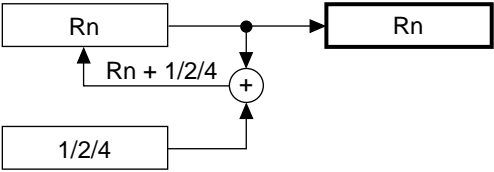
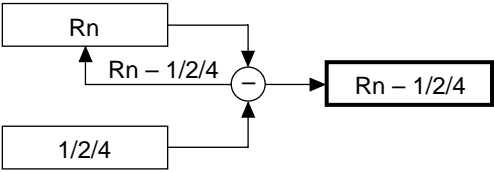
Addressing Mode	Instruction Format	Effective Address Calculation	Equation
Direct register addressing	Rn	The effective address is register Rn. (The operand is the contents of register Rn.)	—
Indirect register addressing	@Rn	The effective address is the content of register Rn. 	Rn
Post-increment indirect register addressing	@Rn+	The effective address is the content of register Rn. A constant is added to the content of Rn after the instruction is executed. 1 is added for a byte operation, 2 for a word operation, and 4 for a longword operation. 	Rn (After the instruction executes) Byte: $Rn + 1 \rightarrow Rn$ Word: $Rn + 2 \rightarrow Rn$ Longword: $Rn + 4 \rightarrow Rn$
Pre-decrement indirect register addressing	@-Rn	The effective address is the value obtained by subtracting a constant from Rn. 1 is subtracted for a byte operation, 2 for a word operation, and 4 for a longword operation. 	Rn - 1 $\rightarrow Rn$ Word: $Rn - 2 \rightarrow Rn$ Longword: $Rn - 4 \rightarrow Rn$ (Instruction executed with Rn after calculation)

Table 2.2 Addressing Modes and Effective Addresses (cont)

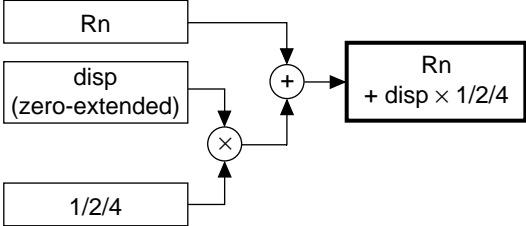
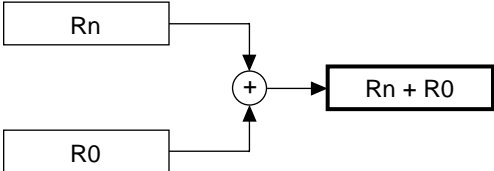
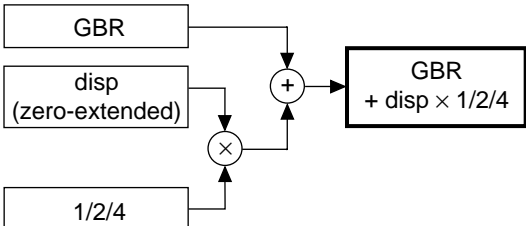
Addressing Mode	Instruction Format	Effective Address Calculation	Equation
Indirect register addressing with displacement	@ (disp:4, Rn)	<p>The effective address is Rn plus a 4-bit displacement (disp). The value of disp is zero-extended, and remains the same for a byte operation, is doubled for a word operation, and is quadrupled for a longword operation.</p> 	<p>Byte: $Rn + disp$ Word: $Rn + disp \times 2$ Longword: $Rn + disp \times 4$</p>
Indirect indexed register addressing	@ (R0, Rn)	<p>The effective address is the Rn value plus R0.</p> 	$Rn + R0$
Indirect GBR addressing with displacement	@ (disp:8, GBR)	<p>The effective address is the GBR value plus an 8-bit displacement (disp). The value of disp is zero-extended, remains the same for a byte operation, is doubled for a word operation, and is quadrupled for a longword operation.</p> 	<p>Byte: $GBR + disp$ Word: $GBR + disp \times 2$ Longword: $GBR + disp \times 4$</p>

Table 2.2 Addressing Modes and Effective Addresses (cont)

Addressing Mode	Instruction Format	Effective Address Calculation	Equation
Indirect indexed GBR addressing	@(R0, GBR)	The effective address is the GBR value plus R0.	$GBR + R0$
Indirect PC addressing with displacement	@(disp:8, PC)	The effective address is the PC value plus an 8-bit displacement (disp). The value of disp is zero-extended, remains the same for a byte operation, is doubled for a word operation, and is quadrupled for a longword operation. For a longword operation, the lowest two bits of the PC value are masked.	Word: $PC + disp \times 2$ Longword: $PC \& H'FFFFFFC + disp \times 4$
PC relative addressing	disp:8	The effective address is the PC value sign-extended with an 8-bit displacement (disp), doubled, and added to the PC value.	$PC + disp \times 2$

Table 2.2 Addressing Modes and Effective Addresses (cont)

Addressing Mode	Instruction Format	Effective Address Calculation	Equation
PC relative addressing (cont)	disp:12	The effective address is the PC value sign-extended with a 12-bit displacement (disp), doubled, and added to the PC value.	$PC + disp \times 2$
Rn		The effective address is the register PC value plus Rn.	$PC + Rn$
Immediate addressing	#imm:8	The 8-bit immediate data (imm) for the TST, AND, OR, and XOR instructions are zero-extended.	—
	#imm:8	The 8-bit immediate data (imm) for the MOV, ADD, and CMP/EQ instructions are sign-extended.	—
	#imm:8	The 8-bit immediate data (imm) for the TRAPA instruction is zero-extended and is quadrupled.	—

Note: In addressing modes that use the following displacements, the assembler statements of this manual show values before scaling ($\times 1$, $\times 2$, $\times 4$) according to operand size. This is done to make descriptions of LSI operation clearer. See the notation rules for the assembler in question for actual assembler statements.

- @(disp:4, Rn) ;Indirect addressing with displacement
- @(disp:8, Rn) ;Indirect GBR addressing with displacement
- @(disp:8, PC) ;PC relative addressing with displacement
- disp:8, disp:12 ;PC relative addressing

2.3.3 Instruction Formats

The instruction format table, table 2.3, describes the source operand and the destination operand. The meaning of the operand depends on the instruction code. The symbols used are as follows:

- xxxx: Instruction code
- mmmm: Source register
- nnnn: Destination register
- iiiii: Immediate data
- dddd: Displacement

Table 2.3 Instruction Formats

Instruction Format	Source Operand	Destination Operand	Example
0 format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx xxxx xxxx xxxx </div>	—	—	NOP
n format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx nnnn xxxx xxxx </div>	—	nnnn: Direct register	MOVT Rn
	Control register or system register	nnnn: Direct register	STS MACH, Rn
	Control register or system register	nnnn: Indirect pre-decrement register	STC.L SR, @-Rn
m format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx mmmm xxxx xxxx </div>	mmmm: Direct register	Control register or system register	LDC Rm, SR
	mmmm: Indirect post-increment register	Control register or system register	LDC.L @Rm+, SR
	mmmm: Indirect register	—	JMP @Rn
	mmmm: PC relative using Rn	—	BRAF Rn

Table 2.3 Instruction Formats (cont)

Instruction Format	Source Operand	Destination Operand	Example
nm format	mmmm: Direct register	nnnn: Direct register	ADD Rm, Rn
15 <div style="border: 1px solid black; padding: 2px; display: inline-block;"> xxxx nnnn mmmm xxxx </div> 0	mmmm: Direct register	nnnn: Indirect register	MOV.L Rm, @Rn
	mmmm: Indirect post-increment register (multiply/accumulate)	MACH, MACL	MAC.W @Rm+, @Rn+
	nnnn: Indirect post-increment register (multiply/accumulate)*		
	mmmm: Indirect post-increment register	nnnn: Direct register	MOV.L @Rm+, Rn
	mmmm: Direct register	nnnn: Indirect pre-decrement register	MOV.L Rm, @-Rn
	mmmm: Direct register	nnnn: Indirect indexed register	MOV.L Rm, @(R0, Rn)
md format	mmmmmddd: Indirect register with displacement	R0 (Direct register)	MOV.B @(disp, Rm), R0
15 <div style="border: 1px solid black; padding: 2px; display: inline-block;"> xxxx xxxx mmmm dddd </div> 0			
nd4 format	R0 (Direct register)	nnnnddd: Indirect register with displacement	MOV.B R0, @(disp, Rn)
15 <div style="border: 1px solid black; padding: 2px; display: inline-block;"> xxxx xxxx nnnn dddd </div> 0			
nmd format	mmmm: Direct register	nnnnddd: Indirect register with displacement	MOV.L Rm, @(disp, Rn)
15 <div style="border: 1px solid black; padding: 2px; display: inline-block;"> xxxx xxxx dddd dddd </div> 0			
	mmmmmddd: Indirect register with displacement	nnnn: Direct register	MOV.L @(disp, Rm), Rn

Table 2.3 Instruction Formats (cont)

Instruction Format	Source Operand	Destination Operand	Example
d format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx dddd dddd dddd </div>	ddddddd: Indirect GBR with displacement	R0 (Direct register)	MOV.L @(disp,GBR),R0
	R0(Direct register)	ddddddd: Indirect GBR with displacement	MOV.L R0,@(disp,GBR)
	ddddddd: PC relative with displacement	R0 (Direct register)	MOVA @(disp,PC),R0
	ddddddd: PC relative	—	BF label
d12 format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx nnnn dddd dddd </div>	ddddddddddd: PC relative	—	BRA label (label = disp + PC)
	nd8 format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx nnnn dddd dddd </div>	ddddddd: PC relative with displacement	nnnn: Direct register
i format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx xxxx iiii iiii </div>	iiiiiii: Immediate	Indirect indexed GBR	AND.B #imm,@(R0,GBR)
	iiiiiii: Immediate	R0 (Direct register)	AND #imm,R0
	iiiiiii: Immediate	—	TRAPA #imm
ni format 15 0 <div style="border: 1px solid black; padding: 2px; display: inline-block; margin-top: 5px;"> xxxx nnnn iiii iiii </div>	iiiiiii: Immediate	nnnn: Direct register	ADD #imm,Rn

Note: In multiply/accumulate instructions, nnnn is the source register.

2.4 Instruction Set

2.4.1 Instruction Set by Classification

Table 2.4 summarizes instructions by functional class.

Table 2.4 Classification of Instructions

Classification	Types	Operation Code	Function	No. of Instructions
Data transfer	5	MOV	Data transfer Immediate data transfer Peripheral module data transfer Structure data transfer	39
		MOVA	Effective address transfer	
		MOVT	T bit transfer	
		SWAP	Swap of upper and lower bytes	
		XTRCT	Extraction of the middle of registers connected	
		Arithmetic operations	21	
ADDC	Binary addition with carry			
ADDV	Binary addition with overflow check			
CMP/cond	Comparison			
DIV1	Division			
DIV0S	Initialization of signed division			
DIV0U	Initialization of unsigned division			
DMULS	Signed double-length multiplication			
DMULU	Unsigned double-length multiplication			
DT	Decrement and test			
EXTS	Sign extension			
EXTU	Zero extension			
MAC	Multiply/accumulate, double-length multiply/accumulate operation			

Table 2.4 Classification of Instructions (cont)

Classification	Types	Operation		No. of Instructions
		Code	Function	
Arithmetic operations (cont)	21 (cont)	MUL	Double-length multiplication (32 × 32 bits)	33 (cont)
		MULS	Signed multiplication (16 × 16 bits)	
		MULU	Unsigned multiplication (16 × 16 bits)	
		NEG	Negation	
		NEGC	Negation with borrow	
		SUB	Binary subtraction	
		SUBC	Binary subtraction with carry	
		SUBV	Binary subtraction with underflow check	
Logic operations	6	AND	Logical AND	14
		NOT	Bit inversion	
		OR	Logical OR	
		TAS	Memory test and bit set	
		TST	Logical AND and T bit set	
		XOR	Exclusive OR	
Shift	12	ROTL	One-bit left rotation	16
		ROTR	One-bit right rotation	
		ROTCL	One-bit left rotation with T bit	
		ROTCR	One-bit right rotation with T bit	
		SHAL	One-bit arithmetic left shift	
		SHAR	One-bit arithmetic right shift	
		SHLL	One-bit logical left shift	
		SHLLn	n-bit logical left shift	
		SHLR	One-bit logical right shift	
		SHLRn	n-bit logical right shift	
		SHAD	Dynamic arithmetic shift	
		SHLD	Dynamic logical shift	

Table 2.4 Classification of Instructions (cont)

Classification	Types	Operation Code	Function	No. of Instructions
Branch	9	BF	Conditional branch, conditional branch with delay (T = 0)	11
		BT	Conditional branch, conditional branch with delay (T = 1)	
		BRA	Unconditional branch	
		BRAF	Unconditional branch	
		BSR	Branch to subroutine procedure	
		BSRF	Branch to subroutine procedure	
		JMP	Unconditional branch	
		JSR	Branch to subroutine procedure	
		RTS	Return from subroutine procedure	
System control	15	CLRT	T bit clear	83 (75)*
		CLRMAC	MAC register clear	
		CLRS	Clear S bit	
		LDC	Load to control register	
		LDS*	Load to system register	
		LDTLB	Load PTE to TLB	
		NOP	No operation	
		PREF	Prefetching data to cache	
		RTE	Return from exception processing	
		SETS	S bit set	
		SETT	T bit set	
		SLEEP	Shift into power-down mode	
		STC	Storing control register data	
		STS*	Storing system register data	
TRAPA	Trap exception handling			

Table 2.4 Classification of Instructions (cont)

Classification	Types	Operation		No. of Instructions
		Code	Function	
Floating point	16	FABS	FP absolute value	23
		FADD	FP addition	
		FCMP	FP comparison	
		FDIV	FP division	
		FLDI0	FP Load immediate zero	
		FLDI1	FP Load immediate one	
		FLDS	FP load to FPUL	
		FLOAT	FP convert from integer	
		FMAC	FP multiply and accumulate	
		FMOV	FP data transfer	
		FMUL	FP multiply	
		FNEG	FP negate	
		FSQRT	FP square root	
		FSTS	FP store from FPUL	
		FSUB	FP subtract	
FTRC	FP truncate and convert to integer			
Total: 84				219 (211)*

Note: * The LDC and STS instructions include instructions for loading and storing to the FPU's control register. Numbers in parentheses are with these subtracted.

Table 2.5 lists the instruction code format used in tables 2.6 through 2.13. These tables list various operation instructions.

Table 2.5 Instruction Code Format

Item	Format	Explanation
Instruction	OP.Sz SRC,DEST	OP: Operation code Sz: Size SRC: Source DEST: Destination Rm: Source register Rn: Destination register imm: Immediate data disp: Displacement
Operation	→, ← (xx) M/Q/T & ^ ~ <<n, >>n	Direction of transfer Memory operand Flag bits in the SR Logical AND of each bit Logical OR of each bit Exclusive OR of each bit Logical NOT of each bit n-bit shift
Code	MSB ↔ LSB	mmmm: Source register nnnn: Destination register 0000: R0, FR0 0001: R1, FR1 1111: R15, FR15 iiii: Immediate data dddd: Displacement (scaled according to the instruction's operand size)
Privilege		Indicates whether privileged mode applies
Cycles		The execution cycles listed in the table are minimums. The actual number of cycles may be increased: <ol style="list-style-type: none"> 1. When contention occurs between instruction fetches and data access, or 2. When the destination register of the load instruction (memory → register) and the register used by the next instruction are the same.
T bit		Value of T bit after instruction is executed —: No change

Table 2.6 Data Transfer Instructions

Instruction		Operation	Code	Privilege	Cycles	T Bit
MOV	#imm,Rn	#imm → Sign extension → Rn	1110nnnniiiiiii	—	1	—
MOV.W	@(disp,PC),Rn	(disp × 2 + PC) → Sign extension → Rn	1001nnnnddddddd	—	1	—
MOV.L	@(disp,PC),Rn	(disp × 4 + PC) → Rn	1101nnnnddddddd	—	1	—
MOV	Rm,Rn	Rm → Rn	0110nnnnnnmm0011	—	1	—
MOV.B	Rm,@Rn	Rm → (Rn)	0010nnnnnnmm0000	—	1	—
MOV.W	Rm,@Rn	Rm → (Rn)	0010nnnnnnmm0001	—	1	—
MOV.L	Rm,@Rn	Rm → (Rn)	0010nnnnnnmm0010	—	1	—
MOV.B	@Rm,Rn	(Rm) → Sign extension → Rn	0110nnnnnnmm0000	—	1	—
MOV.W	@Rm,Rn	(Rm) → Sign extension → Rn	0110nnnnnnmm0001	—	1	—
MOV.L	@Rm,Rn	(Rm) → Rn	0110nnnnnnmm0010	—	1	—
MOV.B	Rm,@-Rn	Rn-1 → Rn, Rm → (Rn)	0010nnnnnnmm0100	—	1	—
MOV.W	Rm,@-Rn	Rn-2 → Rn, Rm → (Rn)	0010nnnnnnmm0101	—	1	—
MOV.L	Rm,@-Rn	Rn-4 → Rn, Rm → (Rn)	0010nnnnnnmm0110	—	1	—
MOV.B	@Rm+,Rn	(Rm) → Sign extension → Rn, Rm + 1 → Rm	0110nnnnnnmm0100	—	1	—
MOV.W	@Rm+,Rn	(Rm) → Sign extension → Rn, Rm + 2 → Rm	0110nnnnnnmm0101	—	1	—
MOV.L	@Rm+,Rn	(Rm) → Rn, Rm + 4 → Rm	0110nnnnnnmm0110	—	1	—
MOV.B	R0,@(disp,Rn)	R0 → (disp + Rn)	1000000nnnnddd	—	1	—
MOV.W	R0,@(disp,Rn)	R0 → (disp × 2 + Rn)	10000001nnnnddd	—	1	—
MOV.L	Rm,@(disp,Rn)	Rm → (disp × 4 + Rn)	0001nnnnnnmmddd	—	1	—
MOV.B	@(disp,Rm),R0	(disp + Rm) → Sign extension → R0	10000100nnnnddd	—	1	—
MOV.W	@(disp,Rm),R0	(disp × 2 + Rm) → Sign extension → R0	10000101nnnnddd	—	1	—
MOV.L	@(disp,Rm),Rn	(disp × 4 + Rm) → Rn	0101nnnnnnmmddd	—	1	—
MOV.B	Rm,@(R0,Rn)	Rm → (R0 + Rn)	0000nnnnnnmm0100	—	1	—
MOV.W	Rm,@(R0,Rn)	Rm → (R0 + Rn)	0000nnnnnnmm0101	—	1	—

Table 2.6 Data Transfer Instructions (cont)

Instruction	Operation	Code	Privilege	Cycles	T Bit
MOV.L Rm,@(R0,Rn)	Rm → (R0 + Rn)	0000nnnnnnmm0110	—	1	—
MOV.B @(R0,Rm),Rn	(R0 + Rm) → Sign extension → Rn	0000nnnnnnmm1100	—	1	—
MOV.W @(R0,Rm),Rn	(R0 + Rm) → Sign extension → Rn	0000nnnnnnmm1101	—	1	—
MOV.L @(R0,Rm),Rn	(R0 + Rm) → Rn	0000nnnnnnmm1110	—	1	—
MOV.B R0,@(disp,GBR)	R0 → (disp + GBR)	11000000ddddddd	—	1	—
MOV.W R0,@(disp,GBR)	R0 → (disp × 2 + GBR)	11000001ddddddd	—	1	—
MOV.L R0,@(disp,GBR)	R0 → (disp × 4 + GBR)	11000010ddddddd	—	1	—
MOV.B @(disp,GBR),R0	(disp + GBR) → Sign extension → R0	11000100ddddddd	—	1	—
MOV.W @(disp,GBR),R0	(disp × 2 + GBR) → Sign extension → R0	11000101ddddddd	—	1	—
MOV.L @(disp,GBR),R0	(disp × 4 + GBR) → R0	11000110ddddddd	—	1	—
MOVA @(disp,PC),R0	disp × 4 + PC → R0	11000111ddddddd	—	1	—
MOVT Rn	T → Rn	0000nnnn00101001	—	1	—
PREF @Rn	(Rn) → cache	0000nnnn10000011	—	1	—
SWAP.B Rm,Rn	Rm → Swap the bottom two bytes → REG	0110nnnnnnmm1000	—	1	—
SWAP.W Rm,Rn	Rm → Swap two consecutive words → Rn	0110nnnnnnmm1001	—	1	—
XTRCT Rm,Rn	Rm: Middle 32 bits of Rn → Rn	0010nnnnnnmm1101	—	1	—

Table 2.7 Arithmetic Instructions

Instruction		Operation	Code	Privilege	Cycles	T Bit
ADD	Rm, Rn	$Rn + Rm \rightarrow Rn$	0011nnnnnnnnmm1100	—	1	—
ADD	#imm, Rn	$Rn + imm \rightarrow Rn$	0111nnnniiiiiiii	—	1	—
ADDC	Rm, Rn	$Rn + Rm + T \rightarrow Rn$, Carry $\rightarrow T$	0011nnnnnnnnmm1110	—	1	Carry
ADDV	Rm, Rn	$Rn + Rm \rightarrow Rn$, Overflow $\rightarrow T$	0011nnnnnnnnmm1111	—	1	Overflow
CMP/EQ	#imm, R0	If $R0 = imm$, $1 \rightarrow T$	10001000iiiiiiii	—	1	Comparison result
CMP/EQ	Rm, Rn	If $Rn = Rm$, $1 \rightarrow T$	0011nnnnnnnnmm0000	—	1	Comparison result
CMP/HS	Rm, Rn	If $Rn \geq Rm$ with unsigned data, $1 \rightarrow T$	0011nnnnnnnnmm0010	—	1	Comparison result
CMP/GE	Rm, Rn	If $Rn \geq Rm$ with signed data, $1 \rightarrow T$	0011nnnnnnnnmm0011	—	1	Comparison result
CMP/HI	Rm, Rn	If $Rn > Rm$ with unsigned data, $1 \rightarrow T$	0011nnnnnnnnmm0110	—	1	Comparison result
CMP/GT	Rm, Rn	If $Rn > Rm$ with signed data, $1 \rightarrow T$	0011nnnnnnnnmm0111	—	1	Comparison result
CMP/PZ	Rn	If $Rn \geq 0$, $1 \rightarrow T$	0100nnnn00010001	—	1	Comparison result
CMP/PL	Rn	If $Rn > 0$, $1 \rightarrow T$	0100nnnn00010101	—	1	Comparison result
CMP/STR	Rm, Rn	If Rn and Rm have an equivalent byte, $1 \rightarrow T$	0010nnnnnnnnmm1100	—	1	Comparison result
DIV1	Rm, Rn	Single-step division (Rn/Rm)	0011nnnnnnnnmm0100	—	1	Calculation result
DIV0S	Rm, Rn	MSB of $Rn \rightarrow Q$, MSB of $Rm \rightarrow M$, $M \wedge Q \rightarrow T$	0010nnnnnnnnmm0111	—	1	Calculation result
DIV0U		$0 \rightarrow M/Q/T$	000000000011001	—	1	0

Table 2.7 Arithmetic Instructions (cont)

Instruction	Operation	Code	Privilege	Cycles	T Bit
DMULS.L Rm, Rn	Signed operation of $Rn \times Rm \rightarrow MACH$, $MACL\ 32 \times 32 \rightarrow 64$ bits	0011nnnnnnnnmm1101	—	$2-5^{*1}$	—
DMULU.L Rm, Rn	Unsigned operation of $Rn \times Rm \rightarrow MACH$, $MACL\ 32 \times 32 \rightarrow 64$ bits	0011nnnnnnnnmm0101	—	$2-5^{*1}$	—
DT Rn	$Rn - 1 \rightarrow Rn$, if $Rn =$ 0, 1 $\rightarrow T$, else 0 $\rightarrow T$	0100nnnn00010000	—	1	Comparison result
EXTS.B Rm, Rn	A byte in Rm is sign- extended $\rightarrow Rn$	0110nnnnnnnnmm1110	—	1	—
EXTS.W Rm, Rn	A word in Rm is sign- extended $\rightarrow Rn$	0110nnnnnnnnmm1111	—	1	—
EXTU.B Rm, Rn	A byte in Rm is zero- extended $\rightarrow Rn$	0110nnnnnnnnmm1100	—	1	—
EXTU.W Rm, Rn	A word in Rm is zero- extended $\rightarrow Rn$	0110nnnnnnnnmm1101	—	1	—
MAC.L @Rm+, @Rn+	Signed operation of $(Rn) \times (Rm) + MAC \rightarrow$ MAC	0000nnnnnnnnmm1111	—	$2-5^{*1}$	—
MAC.W @Rm+, @Rn+	Signed operation of $(Rn) \times (Rm) + MAC \rightarrow$ MAC $16 \times 16 + 64 \rightarrow 64$ bits	0100nnnnnnnnmm1111	—	$2-5^{*1}$	—
MUL.L Rm, Rn	$Rn \times Rm \rightarrow MACL$ $32 \times 32 \rightarrow 32$ bits	0000nnnnnnnnmm0111	—	$2-5^{*1}$	—
MULS.W Rm, Rn	Signed operation of $Rn \times Rm \rightarrow MAC$ $16 \times 16 \rightarrow 32$ bits	0010nnnnnnnnmm1111	—	$1-3^{*2}$	—
MULU.W Rm, Rn	Unsigned operation of $Rn \times Rm \rightarrow MAC$ $16 \times 16 \rightarrow 32$ bits	0010nnnnnnnnmm1110	—	$1-3^{*2}$	—

Table 2.7 Arithmetic Instructions (cont)

Instruction		Operation	Code	Privilege	Cycles	T Bit
NEG	Rm, Rn	$0-R_m \rightarrow R_n$	0110nnnnnnmmmm1011	—	1	—
NEGC	Rm, Rn	$0-R_m-T \rightarrow R_n$, Borrow $\rightarrow T$	0110nnnnnnmmmm1010	—	1	Borrow
SUB	Rm, Rn	$R_n-R_m \rightarrow R_n$	0011nnnnnnmmmm1000	—	1	—
SUBC	Rm, Rn	$R_n-R_m-T \rightarrow R_n$, Borrow $\rightarrow T$	0011nnnnnnmmmm1010	—	1	Borrow
SUBV	Rm, Rn	$R_n-R_m \rightarrow R_n$, Underflow $\rightarrow T$	0011nnnnnnmmmm1011	—	1	Underflow

- Notes: 1. The normal minimum number of execution cycles is 2, but 5 cycles are required when the results of an operation are read from the MAC register immediately after the instruction.
2. The normal minimum number of execution cycles is 1, but 3 cycles are required when the results of an operation are read from the MAC register immediately after a MUL instruction.

Table 2.8 Logic Operation Instructions

Instruction		Operation	Code	Privilege	Cycles	T Bit
AND	Rm,Rn	$Rn \& Rm \rightarrow Rn$	0010nnnnrrrrrrrr1001	—	1	—
AND	#imm,R0	$R0 \& imm \rightarrow R0$	11001001iiiiiiii	—	1	—
AND.B	#imm,@(R0,GBR)	$(R0 + GBR) \& imm \rightarrow (R0 + GBR)$	11001101iiiiiiii	—	3	—
NOT	Rm,Rn	$\sim Rm \rightarrow Rn$	0110nnnnrrrrrrrr0111	—	1	—
OR	Rm,Rn	$Rn Rm \rightarrow Rn$	0010nnnnrrrrrrrr1011	—	1	—
OR	#imm,R0	$R0 imm \rightarrow R0$	11001011iiiiiiii	—	1	—
OR.B	#imm,@(R0,GBR)	$(R0 + GBR) imm \rightarrow (R0 + GBR)$	11001111iiiiiiii	—	3	—
TAS.B	@Rn	If (Rn) is 0, $1 \rightarrow T$; $1 \rightarrow$ MSB of (Rn)	0100nrrrr00011011	—	3	Test result
TST	Rm,Rn	$Rn \& Rm$; if the result is 0, $1 \rightarrow T$	0010nnnnrrrrrrrr1000	—	1	Test result
TST	#imm,R0	$R0 \& imm$; if the result is 0, $1 \rightarrow T$	11001000iiiiiiii	—	1	Test result
TST.B	#imm,@(R0,GBR)	$(R0 + GBR) \& imm$; if the result is 0, $1 \rightarrow T$	11001100iiiiiiii	—	3	Test result
XOR	Rm,Rn	$Rn \wedge Rm \rightarrow Rn$	0010nnnnrrrrrrrr1010	—	1	—
XOR	#imm,R0	$R0 \wedge imm \rightarrow R0$	11001010iiiiiiii	—	1	—
XOR.B	#imm,@(R0,GBR)	$(R0 + GBR) \wedge imm \rightarrow (R0 + GBR)$	11001110iiiiiiii	—	3	—

iTable 2.9 Shift Instructions

Instruction		Operation	Code	Privilege	Cycles	T Bit
ROTL	Rn	$T \leftarrow Rn \leftarrow \text{MSB}$	0100nnnn00000100	—	1	MSB
ROTR	Rn	$\text{LSB} \rightarrow Rn \rightarrow T$	0100nnnn00000101	—	1	LSB
ROTCL	Rn	$T \leftarrow Rn \leftarrow T$	0100nnnn00100100	—	1	MSB
ROTCR	Rn	$T \rightarrow Rn \rightarrow T$	0100nnnn00100101	—	1	LSB
SHAD	Rm, Rn	$Rn \geq 0; Rn \ll Rm \rightarrow Rn$ $Rn < 0; Rn \gg Rm \rightarrow$ $(\text{MSB} \rightarrow)Rn$	0100nnnnnnnnnn1100	—	1	—
SHAL	Rn	$T \leftarrow Rn \leftarrow 0$	0100nnnn00100000	—	1	MSB
SHAR	Rn	$\text{MSB} \rightarrow Rn \rightarrow T$	0100nnnn00100001	—	1	LSB
SHLD	Rm, Rn	$Rn \geq 0; Rn \ll Rm \rightarrow Rn$ $Rn < 0; Rn \gg Rm \rightarrow$ $(0 \rightarrow)Rn$	0100nnnnnnnnnn1101	—	1	—
SHLL	Rn	$T \leftarrow Rn \leftarrow 0$	0100nnnn00000000	—	1	MSB
SHLR	Rn	$0 \rightarrow Rn \rightarrow T$	0100nnnn00000001	—	1	LSB
SHLL2	Rn	$Rn \ll 2 \rightarrow Rn$	0100nnnn00001000	—	1	—
SHLR2	Rn	$Rn \gg 2 \rightarrow Rn$	0100nnnn00001001	—	1	—
SHLL8	Rn	$Rn \ll 8 \rightarrow Rn$	0100nnnn00011000	—	1	—
SHLR8	Rn	$Rn \gg 8 \rightarrow Rn$	0100nnnn00011001	—	1	—
SHLL16	Rn	$Rn \ll 16 \rightarrow Rn$	0100nnnn00101000	—	1	—
SHLR16	Rn	$Rn \gg 16 \rightarrow Rn$	0100nnnn00101001	—	1	—

Table 2.10 Branch Instructions

Instruction	Operation	Code	Privilege	Cycles	T Bit
BF	label If T = 0, disp × 2 + PC → PC; if T = 1, nop (where label is disp + PC)	1000101111111111	—	3/1*	—
BF/S	label Delayed branch, if T = 0, disp × 2 + PC → PC; if T = 1, nop	1000111111111111	—	2/1*	—
BT	label Delayed branch, if T = 1, disp × 2 + PC → PC; if T = 0, nop	1000100111111111	—	3/1*	—
BT/S	label If T = 1, disp × 2 + PC → PC; if T = 0, nop	1000110111111111	—	2/1*	—
BRA	label Delayed branch, disp × 2 + PC → PC	1010111111111111	—	2	—
BRAF	Rm Rm + PC → PC	0000mmmm00100011	—	2	—
BSR	label Delayed branch, PC → PR, disp × 2 + PC → PC	1011111111111111	—	2	—
BSRF	Rm PC → PR, Rm + PC → PC	0000mmmm00000011	—	2	—
JMP	@Rm Delayed branch, Rm → PC	0100mmmm00101011	—	2	—
JSR	@Rm Delayed branch, PC → PR, Rm → PC	0100mmmm00001011	—	2	—
RTS	Delayed branch, PR → PC	0000000000001011	—	2	—

Note: * One state when it does not branch.

Table 2.11 System Control Instructions

Instruction	Operation	Code	Privilege	Cycles	T Bit
CLRMAC	0 → MACH, MACL	0000000000101000	—	1	—
CLRS	0 → S	0000000001001000	—	1	—
CLRT	0 → T	0000000000001000	—	1	0
LDC Rm, SR	Rm → SR	0100mmmm00001110	Yes	5	LSB
LDC Rm, GBR	Rm → GBR	0100mmmm00011110	—	1	—
LDC Rm, VBR	Rm → VBR	0100mmmm00101110	Yes	1	—
LDC Rm, SSR	Rm → SSR	0100mmmm00111110	Yes	1	—
LDC Rm, SPC	Rm → SPC	0100mmmm01001110	Yes	1	—
LDC Rm, R0_BANK	Rm → R0_BANK	0100mmmm10001110	Yes	1	—
LDC Rm, R1_BANK	Rm → R1_BANK	0100mmmm10011110	Yes	1	—
LDC Rm, R2_BANK	Rm → R2_BANK	0100mmmm10101110	Yes	1	—
LDC Rm, R3_BANK	Rm → R3_BANK	0100mmmm10111110	Yes	1	—
LDC Rm, R4_BANK	Rm → R4_BANK	0100mmmm11001110	Yes	1	—
LDC Rm, R5_BANK	Rm → R5_BANK	0100mmmm11011110	Yes	1	—
LDC Rm, R6_BANK	Rm → R6_BANK	0100mmmm11101110	Yes	1	—
LDC Rm, R7_BANK	Rm → R7_BANK	0100mmmm11111110	Yes	1	—
LDC.L @Rm+, SR	(Rm) → SR, Rm + 4 → Rm	0100mmmm00000111	Yes	7	LSB
LDC.L @Rm+, GBR	(Rm) → GBR, Rm + 4 → Rm	0100mmmm00010111	—	1	—
LDC.L @Rm+, VBR	(Rm) → VBR, Rm + 4 → Rm	0100mmmm00100111	Yes	1	—
LDC.L @Rm+, SSR	(Rm) → SSR, Rm + 4 → Rm	0100mmmm00110111	Yes	1	—
LDC.L @Rm+, SPC	(Rm) → SPC, Rm + 4 → Rm	0100mmmm01000111	Yes	1	—
LDC.L @Rm+, R0_BANK	(Rm) → R0_BANK, Rm + 4 → Rm	0100mmmm10000111	Yes	1	—
LDC.L @Rm+, R1_BANK	(Rm) → R1_BANK, Rm + 4 → Rm	0100mmmm10010111	Yes	1	—
LDC.L @Rm+, R2_BANK	(Rm) → R2_BANK, Rm + 4 → Rm	0100mmmm10100111	Yes	1	—
LDC.L @Rm+, R3_BANK	(Rm) → R3_BANK, Rm + 4 → Rm	0100mmmm10110111	Yes	1	—

Table 2.11 System Control Instructions (cont)

Instruction	Operation	Code	Privilege	Cycles	T Bit
LDC.L @Rm+, R4_BANK	(Rm) → R4_BANK, Rm + 4 → Rm	0100mmmm11000111	Yes	1	—
LDC.L @Rm+, R5_BANK	(Rm) → R5_BANK, Rm + 4 → Rm	0100mmmm11010111	Yes	1	—
LDC.L @Rm+, R6_BANK	(Rm) → R6_BANK, Rm + 4 → Rm	0100mmmm11100111	Yes	1	—
LDC.L @Rm+, R7_BANK	(Rm) → R7_BANK, Rm + 4 → Rm	0100mmmm11110111	Yes	1	—
LDS Rm, MACH	Rm → MACH	0100mmmm00001010	—	1	—
LDS Rm, MACL	Rm → MACL	0100mmmm00011010	—	1	—
LDS Rm, PR	Rm → PR	0100mmmm00101010	—	1	—
LDS.L @Rm+, MACH	(Rm) → MACH, Rm + 4 → Rm	0100mmmm00000110	—	1	—
LDS.L @Rm+, MACL	(Rm) → MACL, Rm + 4 → Rm	0100mmmm00010110	—	1	—
LDS.L @Rm+, PR	(Rm) → PR, Rm + 4 → Rm	0100mmmm00100110	—	1	—
LDTLB	PTEH/PTEL → TLB	000000000111000	Yes	1	—
NOP	No operation	000000000001001	—	1	—
PREF @Rm	(Rm) → cache	0000mmmm10000011	—	1	—
RTE	Delayed branch, SSR/SPC → SR/PC	000000000101011	Yes	4	—
SETS	1 → S	0000000001011000	—	1	—
SETT	1 → T	000000000011000	—	1	1
SLEEP	Sleep	000000000011011	Yes	4*1	—
STC SR, Rn	SR → Rn	0000nnnn00000010	Yes	1	—
STC GBR, Rn	GBR → Rn	0000nnnn00010010	—	1	—
STC VBR, Rn	VBR → Rn	0000nnnn00100010	Yes	1	—
STC SSR, Rn	SSR → Rn	0000nnnn00110010	Yes	1	—
STC SPC, Rn	SPC → Rn	0000nnnn01000010	Yes	1	—
STC R0_BANK, Rn	R0_BANK → Rn	0000nnnn10000010	Yes	1	—
STC R1_BANK, Rn	R1_BANK → Rn	0000nnnn10010010	Yes	1	—
STC R2_BANK, Rn	R2_BANK → Rn	0000nnnn10100010	Yes	1	—
STC R3_BANK, Rn	R3_BANK → Rn	0000nnnn10110010	Yes	1	—
STC R4_BANK, Rn	R4_BANK → Rn	0000nnnn11000010	Yes	1	—

Table 2.11 System Control Instructions (cont)

Instruction		Operation	Code	Privilege	Cycles	T Bit
STC	R5_BANK, Rn	R5_BANK → Rn	0000nmmnn11010010	Yes	1	—
STC	R6_BANK, Rn	R6_BANK → Rn	0000nmmnn11100010	Yes	1	—
STC	R7_BANK, Rn	R7_BANK → Rn	0000nmmnn11110010	Yes	1	—
STC.L	SR, @-Rn	Rn - 4 → Rn, SR → (Rn)	0100nmmnn00000011	Yes	1	—
STC.L	GBR, @-Rn	Rn - 4 → Rn, GBR → (Rn)	0100nmmnn00010011	—	1	—
STC.L	VBR, @-Rn	Rn - 4 → Rn, VBR → (Rn)	0100nmmnn00100011	Yes	1	—
STC.L	SSR, @-Rn	Rn - 4 → Rn, SSR → (Rn)	0100nmmnn00110011	Yes	1	—
STC.L	SPC, @-Rn	Rn - 4 → Rn, SPC → (Rn)	0100nmmnn01000011	Yes	1	—
STC.L	R0_BANK, @-Rn	Rn - 4 → Rn, R0_BANK → (Rn)	0100nmmnn10000011	Yes	2	—
STC.L	R1_BANK, @-Rn	Rn - 4 → Rn, R1_BANK → (Rn)	0100nmmnn10010011	Yes	2	—
STC.L	R2_BANK, @-Rn	Rn - 4 → Rn, R2_BANK → (Rn)	0100nmmnn10100011	Yes	2	—
STC.L	R3_BANK, @-Rn	Rn - 4 → Rn, R3_BANK → (Rn)	0100nmmnn10110011	Yes	2	—
STC.L	R4_BANK, @-Rn	Rn - 4 → Rn, R4_BANK → (Rn)	0100nmmnn11000011	Yes	2	—
STC.L	R5_BANK, @-Rn	Rn - 4 → Rn, R5_BANK → (Rn)	0100nmmnn11010011	Yes	2	—
STC.L	R6_BANK, @-Rn	Rn - 4 → Rn, R6_BANK → (Rn)	0100nmmnn11100011	Yes	2	—
STC.L	R7_BANK, @-Rn	Rn - 4 → Rn, R7_BANK → (Rn)	0100nmmnn11110011	Yes	2	—
STS	MACH, Rn	MACH → Rn	0000nmmnn00001010	—	1	—
STS	MACL, Rn	MACL → Rn	0000nmmnn00011010	—	1	—

Table 2.11 System Control Instructions (cont)

Instruction		Operation	Code	Privilege	Cycles	T Bit
STS	PR, Rn	PR → Rn	0000nnnn00101010	—	1	—
STS.L	MACH, @-Rn	Rn - 4 → Rn, MACH → (Rn)	0100nnnn00000010	—	1	—
STS.L	MACL, @-Rn	Rn - 4 → Rn, MACL → (Rn)	0100nnnn00010010	—	1	—
STS.L	PR, @-Rn	Rn - 4 → Rn, PR → (Rn)	0100nnnn00100010	—	1	—
TRAPA	#imm	PC/SR → SPC/SSR, #imm << 2 → TRA, 0 × 160 → EXPEVT, VBR + H'0100 → PC	11000011iiiiiiii	—	6	—

- Notes:
1. The number of execution states before the chip enters the sleep state.
 2. This table lists the minimum execution cycles. In practice, the number of execution cycles increases when the instruction fetch is in contention with data access or when the destination register of a load instruction (memory → register) is the same as the register used by the next instruction.

Table 2.12 Floating Point Instructions

Instruction	Operation	Code	Privilege	Cycles	T Bit
FABS FRn	FRn → FRn	1111nnnn01011101	—	1	—
FADD FRm, FRn	FRn + FRm → FRn	1111nnnnnnnnmm0000	—	1	—
FCMP/EQ FRm, FRn	(FRn = FRm) 1 → T	1111nnnnnnnnmm0100	—	1	Comparison result
FCMP/GT FRm, FRn	(FRn > FRm) 1 → T	1111nnnnnnnnmm0101	—	1	Comparison result
FDIV FRm, FRn	FRn/FRm → FRn	1111nnnnnnnnmm0011	—	13	—
FLDI0 FRn	0x00000000 → FRn	1111nnnn10001101	—	1	—
FLDI1 FRn	0x3F800000 → FRn	1111nnnn10011101	—	1	—
FLDS FRm, FPUL	FRm → FPUL	1111nnnn00011101	—	1	—
FLOAT FPUL, FRn	(float)FPUL → FRn	1111nnnn00101101	—	1	—
FMAC FR0, FRm, FRn	FR0 × FRm + FRn → FRn	1111nnnnnnnnmm1110	—	1	—
FMOV FRm, FRn	FRm → FRn	1111nnnnnnnnmm1100	—	1	—
FMOV.S @(R0, Rm), FRn	(R0 + Rm) → FRn	1111nnnnnnnnmm0110	—	1	—
FMOV.S @Rm+, FRn	(Rm) → FRn, Rm + 4 → Rm	1111nnnnnnnnmm1001	—	1	—
FMOV.S @Rm, FRn	(Rm) → FRn	1111nnnnnnnnmm1000	—	1	—
FMOV.S FRm, @(R0, Rn)	FRm → (R0 + Rn)	1111nnnnnnnnmm0111	—	1	—
FMOV.S FRm, @-Rn	Rn - 4 → Rn, FRm → (Rn)	1111nnnnnnnnmm1011	—	1	—
FMOV.S FRm, @Rn	FRm → (Rn)	1111nnnnnnnnmm1010	—	1	—
FMUL FRm, FRn	FRn × FRm → FRn	1111nnnnnnnnmm0010	—	1	—
FNEG FRn	-FRn → FRn	1111nnnn01001101	—	1	—
FSQRT FRn	√FRn → FRn	1111nnnn01101101	—	13	—
FSTS FPUL, FRn	FPUL → FRn	1111nnnn00001101	—	1	—
FSUB FRm, FRn	FRn - FRm → FRn	1111nnnnnnnnmm0001	—	1	—
FTRC FRm, FPUL	(long) FRm → FPUL	1111nnnn00111101	—	1	—

Table 2.13 CPU Instructions Related to FPU

Instruction		Operation	Code	Privilege	Cycles	T Bit
LDS	Rm, FPSCR	Rm → FPSCR	0100nnnn01101010	—	1	—
LDS	Rm, FPUL	Rm → FPUL	0100nnnn01011010	—	1	—
LDS.L	@Rm+, FPSCR	@Rm → FPSCR, Rm + 4 → Rm	0100nnnn01100110	—	1	—
LDS.L	@Rm+, FPUL	@Rm → FPUL, Rm + 4 → Rm	0100nnnn01010110	—	1	—
STS	FPSCR, Rn	FPSCR → Rn	0000nnnn01101010	—	1	—
STS	FPUL, Rn	FPUL → Rn	0000nnnn01011010	—	1	—
STS.L	FPSCR, @-Rn	Rn - 4, FPSCR → @Rn	0100nnnn01100010	—	1	—
STS.L	FPUL, @-Rn	Rn - 4, FPUL → @Rn	0100nnnn01010010	—	1	—

2.4.2 Operation Code Map

Table 2.14 is an operation code map.

Table 2.14 Operation Code Map

Instruction Code				Fx: 0000	Fx: 0001	Fx: 0010	Fx: 0011–1111
MSB		LSB		MD: 00	MD: 01	MD: 10	MD: 11
0000	Rn	Fx	0000				
0000	Rn	Fx	0001				
0000	Rn	00MD	0010	STC SR, Rn	STC GBR, Rn	STC VBR, Rn	STC SSR, Rn
0000	Rn	01MD	0010	STC SPC, Rn			
0000	Rn	10MD	0010	STC R0_BANK, Rn	STC R1_BANK, Rn	STC R2_BANK, Rn	STC R3_BANK, Rn
0000	Rn	11MD	0010	STC R4_BANK, Rn	STC R5_BANK, Rn	STC R6_BANK, Rn	STC R7_BANK, Rn
0000	Rn	00MD	0011	BSRF Rm		BRAF Rm	
0000	Rm	10MD	0011	PREF @Rm			
0000	Rn	Rm	01MD	MOV.B Rm, @(R0, Rn)	MOV.W Rm, @(R0, Rn)	MOV.L Rm, @(R0, Rn)	MUL.L Rm, Rn
0000	0000	00MD	1000	CLRT	SETT	CLRMAC	LDTLB
0000	0000	01MD	1000	CLRS	SETS		
0000	0000	Fx	1001	NOP	DIVOU		
0000	0000	Fx	1010				
0000	0000	Fx	1011	RTS	SLEEP	RTE	
0000	Rn	Fx	1000				
0000	Rn	Fx	1001			MOVT Rn	
0000	Rn	00MD	1010	STS MACH, Rn	STS MACL, Rn	STS PR, Rn	
0000	Rn	01MD	1010		STS FPUL, Rn	STS FPSCR, Rn	
0000	Rn	Fx	1011				
0000	Rn	Rm	11MD	MOV.B @(R0, Rm), Rn	MOV.W @(R0, Rm), Rn	MOV.L @(R0, Rm), Rn	MAC.L @Rm+, @Rn+
0001	Rn	Rm	disp	MOV.L Rm, @(disp:4, Rn)			
0010	Rn	Rm	00MD	MOV.B Rm, @Rn	MOV.W Rm, @Rn	MOV.L Rm, @Rn	
0010	Rn	Rm	01MD	MOV.B Rm, @-Rn	MOV.W Rm, @-Rn	MOV.L Rm, @-Rn	DIVOS Rm, Rn
0010	Rn	Rm	10MD	TST Rm, Rn	AND Rm, Rn	XOR Rm, Rn	OR Rm, Rn
0010	Rn	Rm	11MD	CMP/STR Rm, Rn	XTRCT Rm, Rn	MULU.W Rm, Rn	MULS.W Rm, Rn
0011	Rn	Rm	00MD	CMP/EQ Rm, Rn		CMP/HS Rm, Rn	CMP/GE Rm, Rn

Table 2.14 Operation Code Map (cont)

Instruction Code				Fx: 0000	Fx: 0001	Fx: 0010	Fx: 0011–1111
MSB		LSB		MD: 00	MD: 01	MD: 10	MD: 11
0011	Rn	Rm	01MD	DIV1 Rm, Rn	DMULU.L Rm, Rn	CMP/HI Rm, Rn	CMP/GT Rm, Rn
0011	Rn	Rm	10MD	SUB Rm, Rn		SUBC Rm, Rn	SUBV Rm, Rn
0011	Rn	Rm	11MD	ADD Rm, Rn	DMULU.L Rm, Rn	ADDC Rm, Rn	ADDV Rm, Rn
0100	Rn	Fx	0000	SHLL Rn	DT Rn	SHAL Rn	
0100	Rn	Fx	0001	SHLR Rn	CMP/PZ Rn	SHAR Rn	
0100	Rn	00MD	0010	STS.L MACH, @-Rn	STS.L MACL, @-Rn	STS.L PR, @-Rn	
0100	Rn	01MD	0010		STS.L FPUL, @-Rn	STS.L FPSCR, @-Rn	
0100	Rn	00MD	0011	STC.L SR, @-Rn	STC.L GBR, @-Rn	STC.L VBR, @-Rn	STC.L SSR, A-Rn
0100	Rn	01MD	0011	STC.L SPC, @-Rn			
0100	Rn	10MD	0011	STC.L R0_BANK, @-Rn	STC.L R1_BANK, @-Rn	STC.L R2_BANK, @-Rn	STC.L R3_BANK, @-Rn
0100	Rn	11MD	0011	STC.L R4_BANK, @-Rn	STC.L R5_BANK, @-Rn	STC.L R6_BANK, @-Rn	STC.L R7_BANK, @-Rn
0100	Rn	Fx	0100	ROTL Rn		ROTCL Rn	
0100	Rn	Fx	0101	ROTR Rn	CMP/PL Rn	ROTCR Rn	
0100	Rm	00MD	0110	LDS.L @Rm+, MACH	LDS.L @Rm+, MACL	LDS.L @Rm+, PR	
0100	Rm	01MD	0110		LDS.L @Rm+, FPUL	LDS.L @Rm+, FPSCR	
0100	Rm	00MD	0111	LDC.L @Rm+, SR	LDC.L @Rm+, GBR	LDC.L @Rm+, VBR	LDC.L @Rm+, SSR
0100	Rm	01MD	0111	LDC.L @Rm+, SPC			
0100	Rm	10MD	0111	LDC.L @Rm+, R0_BANK	LDC.L @Rm+, R1_BANK	LDC.L @Rm+, R2_BANK	LDC.L @Rm+, R3_BANK
0100	Rm	11MD	0111	LDC.L @Rm+, R4_BANK	LDC.L @Rm+, R5_BANK	LDC.L @Rm+, R6_BANK	LDC.L @Rm+, R7_BANK
0100	Rn	Fx	1000	SHLL2 Rn	SHLL8 Rn	SHLL16 Rn	
0100	Rn	Fx	1001	SHLR2 Rn	SHLR8 Rn	SHLR16 Rn	
0100	Rm	00MD	1010	LDS Rm, MACH	LDS Rm, MACL	LDS Rm, PR	
0100	Rm	01MD	1010		LDS Rm, FPUL	LDS Rm, FPSCR	

Table 2.14 Operation Code Map (cont)

Instruction Code				Fx: 0000	Fx: 0001	Fx: 0010	Fx: 0011–1111
MSB		LSB		MD: 00	MD: 01	MD: 10	MD: 11
0100	Rn	Fx	1011	JSR @Rm	TAS.B @Rn	JMP @Rm	
0100	Rm	Rm	1100	SHAD Rm, Rn			
0100	Rm	Rm	1101	SHLD Rm, Rn			
0100	Rm	00MD	1110	LDC Rm, Sr	LDC Rm, GBR	LDC Rm, VBR	LDC Rm, SSR
0100	Rm	01MD	1110	LDC Rm, SPC			
0100	Rm	10MD	1110	LDC Rm, R0_BANK	LDC Rm, R1_BANK	LDC Rm, R2_BANK	LDC Rm, R3_BANK
0100	Rm	11MD	1110	LDC Rm, R4_BANK	LDC Rm, R5_BANK	LDC Rm, R6_BANK	LDC Rm, R7_BANK
0100	Rn	Rm	1111	MAC.W @Rm+, @Rn+			
0101	Rn	Rm	disp	MOV.L @(disp:4, Rm), Rn			
0110	Rn	Rm	00MD	MOV.B @Rm, Rn	MOV.W @Rm, Rn	MOV.L @Rm, Rn	MOV Rm, Rn
0110	Rn	Rm	01MD	MOV.B @Rm+, Rn	MOV.W @Rm+, Rn	MOV.L @Rm+, Rn	NOT Rm, Rn
0110	Rn	Rm	10MD	SWAP.B Rm, Rn	SWAP.W Rm, Rn	NEGC Rm, Rn	NEG Rm, Rn
0110	Rn	Rm	11MD	EXTU.B Rm, Rn	EXTU.W Rm, Rn	EXTS.B Rm, Rn	EXTS.W Rm, Rn
0111	Rn		imm	ADD #imm:8, Rn			
1000	00MD	Rn	disp	MOV.B R0, @(disp:4, Rn)	MOV.W R0, @(disp:4, Rn)		
1000	01MD	Rm	disp	MOV.B @(disp:4, Rm), R0	MOV.W @(disp:4, Rm), R0		
1000	10MD		imm/disp	CMP/EQ #imm:8, R0	BT disp:8		BF label:8
1000	10MD		imm/disp		BT/S disp:8		BF/S label:8
1001	Rn		disp	MOV.W @(disp:8, PC), Rn			
1010			disp	BRA label:12			
1011			disp	BSR label:12			
1100	00MD		imm/disp	MOV.B R0, @(disp:8, GBR)	MOV.W R0, @(disp:8, GBR)	MOV.L R0, @(disp:8, GBR)	TRAPA #imm:8
1100	01MD		disp	MOV.B @(disp:8, GBR), R0	MOV.W @(disp:8, GBR), R0	MOV.L @(disp:8, GBR), R0	MOVA @(disp:8, PC), R0

Table 2.14 Operation Code Map (cont)

Instruction Code			Fx: 0000	Fx: 0001	Fx: 0010	Fx: 0011–1111	
MSB	LSB		MD: 00	MD: 01	MD: 10	MD: 11	
1100	10MD	imm	TST #imm:8,R0	AND #imm:8,R0	XOR #imm:8,R0	OR #imm:8,R0	
1100	11MD	imm	TST.B #imm:8, @(R0,GBR)	AND.B #imm:8, @(R0,GBR)	XOR.B #imm:8, @(R0,GBR)	OR.B #imm:8, @(R0,GBR)	
1101	Rn	disp	MOV.L @(disp:8,PC),Rn				
1110	Rn	imm	MOV #imm:8,Rn				
1111	Rn	Rm	00MD	FADD FRm,FRn	FSUB FRm,FRn	FMUL FRm,FRn	FDIV FRm,FRn
1111	Rn	Rm	01MD	FCMP/EQ FRm,FRn	FCMP/GT FRm,FRn	FMOV.S @(R0,Rm),FRm	FMOV.S FRm,@(R0,Rn)
1111	Rn	Rm	10MD	FMOV.S @Rm,FRn	FMOV.S @Rm+,FRm	FMOV.S FRm,@Rn	FMOV.S FRm,@- Rn
1111	Rn	Rm	1100	FMOV FRm,FRn			
1111	Rn	00MD	1101	FSTS FPUL,FRn	FLDS FRn,FPUL	FLOAT FPUL,FRn	FTRC FRn, FPUL
1111	Rn	01MD	1101	FNEG FRn	FABS FRn	FSQRT FRn	
1111	Rn	10MD	1101	FLDI0 FRn	FLDI1 FRn		
1111	Rn	Rm	1110	FMAC FR0,FRm,FRn			

Note: Further details are also given in the SH-3/SH-3E Programming Manual.

2.5 Processing States and Processing Modes

2.5.1 Processing States

The CPU has five processing states: reset, exception processing, bus release, program execution, and power-down.

Reset State: The CPU resets in the reset state. This occurs when the $\overline{\text{RESET}}$ pin level goes low. When the $\overline{\text{BREQ}}$ pin is high, the result is a power-on reset; when it is low, a manual reset will occur. See section 5, Exception Processing, for more information on resets.

A power-on reset initializes the CPU's internal states and on-chip peripheral module registers. A manual reset initializes the CPU's internal states and all on-chip peripheral modules except the bus state controller (BSC). The BSC is not initialized during a manual reset, so refresh operations continue. For more information, see the register descriptions in their individual sections.

Exception Processing State: The exception processing state is a transient state that occurs when exception processing sources such as resets, ordinary exceptions, or interrupts alter the CPU's processing state flow.

For a reset, the CPU branches to H'A0000000 and starts running the user-created exception processing program.

For an ordinary exception or interrupt, the program counter (PC) is saved to the saved program counter (SPC) and the status register (SR) is saved to the saved status register (SSR). The CPU branches to the start address of the user-created exception service routine found by adding the data in the vector base register to the vector offset and the program starts running. See section 5, Exception Processing, for more information on ordinary exceptions, interrupts, and resets.

Program Execution State: In the program execution state, the CPU sequentially executes the program.

Power-Down State: In the power-down state, the CPU operation halts and power consumption declines. The SLEEP instruction places the CPU in the power-down state. This state has two modes: sleep mode and standby mode. See section 9, Power-Down Mode, for more information on the power-down mode.

Bus Release State: In the bus release state, the CPU releases access rights to the bus to the device that has requested them.

Figure 2.7 shows the transitions between the states.

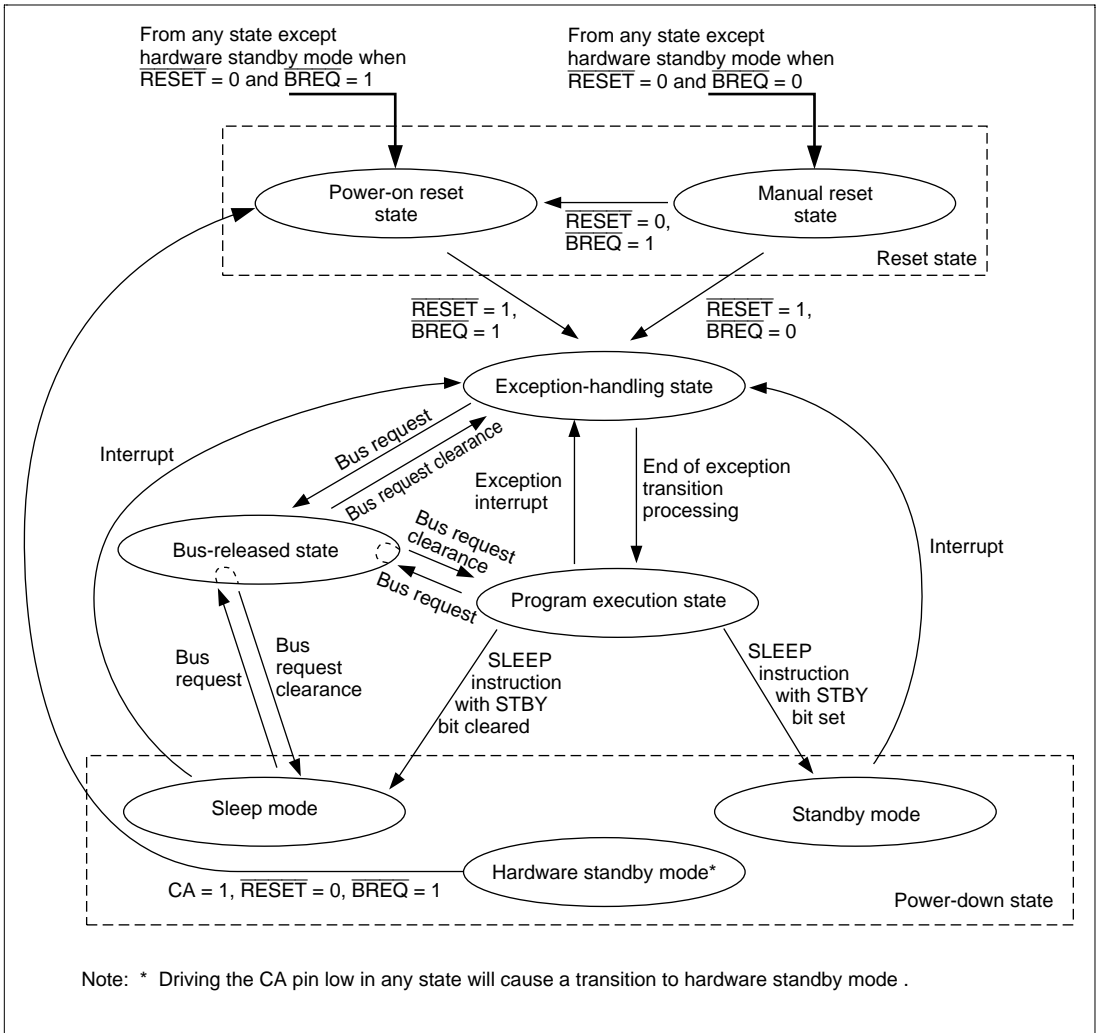


Figure 2.7 Transitions between Processing States

2.5.2 Processing Mode

There are two processing modes: privileged mode and user mode. Use the processing mode bit (MD) in the status register (SR) to select the mode. When MD is 1, the mode is privileged; when MD is 0, the mode is user. MD is always 1 in the reset and exception states. When exception processing ends, the MD bit is cleared to switch to user mode. Some bits and registers can only be accessed in privileged mode.

2.6 Usage Note

Operations may not be performed correctly when the following sequences are executed with the cache on.

Address	Instruction
4n	MAC.L (or MAC.W, DMULS.L, DMULU.L, MUL.L)
4n+2	MAC.L (or MAC.W, DMULS.L, DMULU.L, MUL.L)
4n+4	STS(.L)/LDS(.L) MACH/MACL
	or
4n+2	MAC.L (or MAC.W, DMULS.L, DMULU.L, MUL.L)
4n+4	NOP (or one-cycle instruction except MAC.W instruction* ¹ or branch instruction* ²)
4n+6	MAC.L (or MAC.W, DMULS.L, DMULU.L, MUL.L)
4n+8	STS(.L)/LDS(.L) MACH/MACL

- Notes: 1. MULS.W, MULU.W, MAC.L, MAC.W, DMULS.L, DMULU.L, MUL.L, MULS.W, MULU.W
2. BF, BF/S, BT, BT/S, BRA, BRAF, BSR, BSRF, JMP, JSR, RTS

Software Remedy: This problem can be avoided in either of the following ways.

1. Do not use the above sequences.
2. When performing STS/LDS on the MACL/MACH register after consecutive execution of MAC instructions, insert an NOP instruction between the MAC instructions and STS/LDS instruction.

Section 3 Floating Point Unit

3.1 Introduction

The SH7718R has a built-in floating point operations unit (FPU). Figure 3.1 shows the FPU registers.

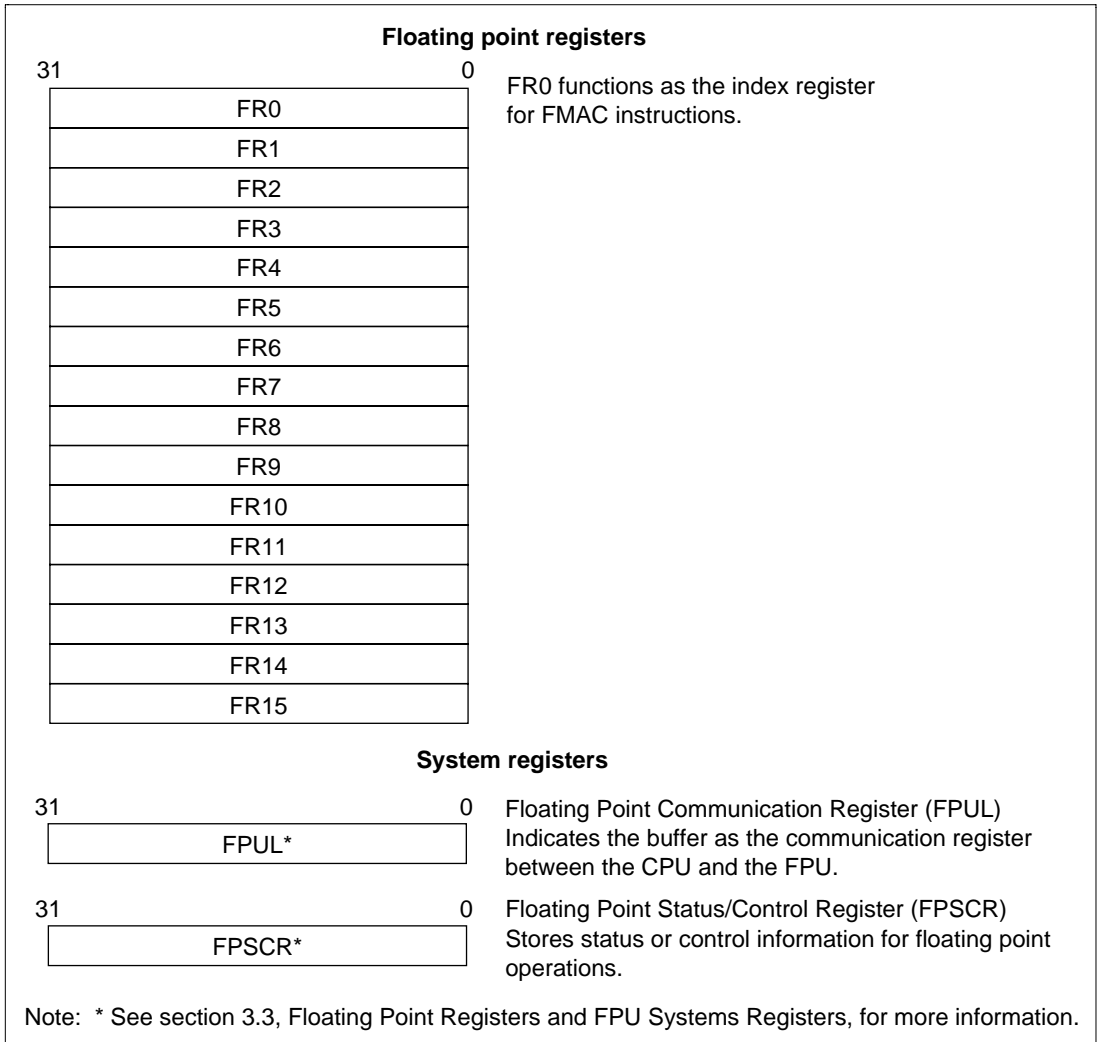


Figure 3.1 Register Set Overview: Floating Point and System Registers

3.2 Floating Point Registers and System Registers for FPU

3.2.1 Floating Point Register File

The SH7718R provides sixteen 32-bit single-precision floating point registers. Register designators are always 4-bits. In assembly language, the floating point registers are designated as FR0, FR1, FR2, etc. FR0 functions as the index for FMAC instructions.

3.2.2 Floating Point Communication Register (FPUL)

Information is transferred between the FPU and the CPU through a communication register, FPUL, which is analogous to the MACL and MACH registers of the integer unit. The SH7718R provides this communication register because of the differences between integer format and FPU format. FPUL is a 32-bit system register, accessed on the CPU side by LDS and STS instructions.

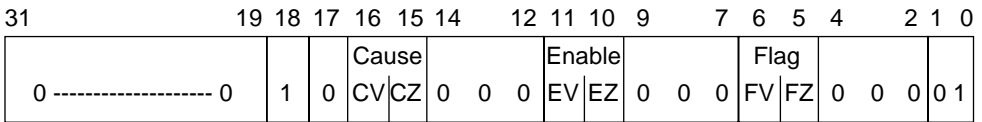
3.2.3 Floating Point Status/Control Register (FPSCR)

The SH7718R implements a floating point status and control register, FPSCR, as a system register accessed through the LDS and STS instructions (figure 3.2). FPSCR is available for modification by user programs. The FPSCR is part of the process context. It must be saved across context switches and may need to be saved across procedure calls.

The FPSCR is a 32-bit register that controls FPU rounding, handling of denormalized values, and captures details about floating point exceptions.

In the SH7718R, only the following modes are supported for these functions.

- Rounding mode: Rounding toward 0.
- Handling of denormalized values: When denormalized values are in the source or destination operand, they are always treated as 0.
- FPU exceptions: Divide by zero (Z) and invalid (V).



CV: Invalid-operation cause bit

1: Invalid-operation exception occurred during execution of the current instruction

0: Invalid-operation exception did not occur

CZ: Divide-by-zero cause bit

1: Divide-by-zero exception occurred during the execution of the current instruction

0: Divide-by-zero exception did not occur

EV: Invalid-operation exception enable bit

1: Enable invalid-operation exception

0: Disable invalid-operation exception and return qNaN as a result

EZ: Divide-by-zero exception enable bit

1: Enable divide-by-zero exception

0: Disable divide-by-zero exception and return correctly signed infinity

FV: Invalid-operation exception flag bit

1: Invalid-operation exception occurred during execution of the current instruction

0: Invalid-operation exception did not occur

FZ: Divide-by-zero exception flag bit

1: Divide-by-zero exception occurred during the execution of the current instruction

0: Divide-by-zero exception did not occur

Note: With the exception of the above bits, all bits are reserved as shown in the figures and cannot be modified even by LDS instruction.

Figure 3.2 Floating Point Status/Control Register

The bits in the cause field indicate the cause of exception for the executing of the current instruction. The cause bits are modified by execution of a floating point instruction. These bits are set to 0 or 1, depending on occurrence or non-occurrence of exception conditions during the execution of a single instruction.

The bits in the enable field indicate the specific types of exceptions that are enabled to cause an exception, that is, change of flow to an exception handling procedure. An exception occurs if the enable bit and the corresponding cause bit are set by the execution of the current instruction.

The bits in the flag field are used to capture the cumulative effect of all exceptions during the execution of a sequence of instructions. These bits, once set by an instruction, can not be reset by following instructions. The bits in this field can only be reset by an explicit store operation on FPSCR.

See section 3.4, Floating Point Exceptions Model, for more information on handling of floating point exceptions.

3.3 Floating Point Format

3.3.1 Floating Point Format

The SH7718R supports single-precision floating point operations. It also conforms fully to the IEEE754 standard.

Floating point numbers are composed of three fields:

- Sign field : s
- Exponent field : e
- Mantissa field : f

The exponent is biased. In other words:

$$e = E + \text{bias}$$

The range of unbiased exponents E is $E_{\min}-1$ to $E_{\max}+1$. The two values ($E_{\min}-1$ and $E_{\max}+1$) are distinguished as follows. $E_{\min}-1$ represents zero (sign is both positive and negative) and a denormalized number while $E_{\max}+1$ represents positive and negative infinity and a not-a-number (NaN). In single-precision operations, the bias value is 127, E_{\min} is -126 , and E_{\max} is 127.

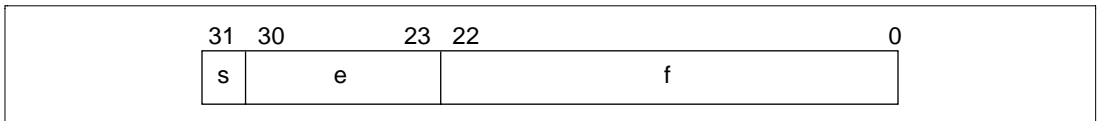


Figure 3.3 Floating Point Format

The value v of the floating point number is determined as follows:

If $E == E_{\max}+1$ and $f != 0$, then v is not a number (NaN) regardless of sign s

If $E == E_{\max}+1$ and $f == 0$, then $v = (-1)^s$ (infinity) [positive or negative infinity]

If $E_{\min} <= E <= E_{\max}$, then $v = (-1)^s 2^E$ (1.f) [normalized number]

If $E == E_{\min}-1$ and $f != 0$, then $v = (-1)^s 2^{E_{\min}}$ (0.f) [denormalized number]

If $E == E_{\min}-1$ and $f == 0$, then $v = (-1)^s 0$ [positive or negative zero]

3.3.2 Not a Number (NaN)

In not-a-number (NaN) expressions in single-precision operations, at least one of the bits 22–0 is set. Set bit 22 for a signaling NaN (sNaN). When bit 22 is reset, the value is then the quiet NaN (qNaN).

The following figure shows the bit pattern of the not-a-number (NaN). Bit N in the figure is set for sNaN and reset for qNaN. An x indicates a don't-care bit. At least one of bits 22-0 must be set.

In a not-a-number (NaN), the sign bit is a don't-care bit.

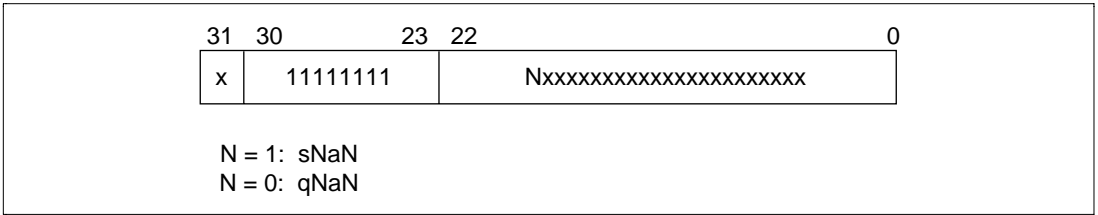


Figure 3.4 NaN Bit Pattern

When a not-a-number (sNaN) is entered in the operation that generates the floating point value:

- When the EV bit is reset in the FPSCR, the operation result (output) is qNaN.
- When the EV bit is set in the FPSCR, an invalid operation exception occurs. In such cases, the contents of the register at the destination side of the operation do not change.

When qNaN is input to the operation that generates the floating point value and sNaN is not input to the operation, the output will always be qNaN regardless of how the EV bit is set in the FPSCR. No exception will occur.

See the *SH-3, SH-3E Programming Manual* for more information on floating point operations when a not-a-number (NaN) is input.

3.3.3 Denormalized Values

Denormalized floating point values are expressed by a biased exponent of 0, a nonzero mantissa, and a hidden bit of 0. In the SH7718R's floating point unit, denormalized values (operand source or operation result) are uniformly flushed with 0 in floating point operations (other than copy) that generate values.

3.3.4 Other Special Values

Other special values are as stipulated by standard IEEE754. Table 3.1 shows the seven different types of special values in floating point value expressions.

Table 3.1 Special Value Expressions in Single-Precision Stipulated in IEEE754

Value	Expression
+0.0	0x00000000
-0.0	0x80000000
Denormalized number	See section 3.3.3, Denormalized Values
+INF	0x7F800000
-INF	0xFF800000
qNaN (quiet NaN)	See section 3.3.2, Not a Number (NaN)
sNaN (signaling NaN)	See section 3.3.2, Not a Number (NaN)

3.4 Floating Point Exception Model

3.4.1 Enabled Exception

Invalid-operation and divide-by-zero exceptions are enabled by setting the enable bit for the relevant exception (the EV or EZ bit) in FPSCR. All exceptions caused by the FPU are mapped as FPU exception events. The meaning of an individual exception is determined by software by reading the FPSCR system register and analyzing the information held there.

3.4.2 Disabled Exception

If enable bit EV is not set in FPSCR, the result of an invalid operation will be qNaN (with the exception of FCMP and FTRC). If enable bit EZ is not set, division by zero will return infinity with the sign of the current expression (+ or -).

The other floating-point exceptions specified in the IEEE754 standard—inexact, overflow, and underflow—are not supported by the SH7718R. In these cases, the SH7718R operates as described below.

- An overflow will produce the number whose absolute value is the largest representable finite number in the format with the correct sign bit. An underflow will produce a correctly signed zero. If the result of an operation is inexact, the destination register will hold the inexact result.

3.4.3 Exception Event and Code for FPU

All FPU exceptions are mapped onto the single general exception event at address H'0x120. Loads and stores of system registers FPUL and FPSCR cause the normal memory management general exceptions.

3.4.4 Alignment of Floating Point Data in Memory

Single precision floating point data is aligned on modulus-4 boundaries, that is, in the same fashion as SH7718R long integers.

3.4.5 Arithmetic with Special Operands

All arithmetic with special operands (qNaN, sNaN, +INF, -INF, +0, -0) follows IEEE754 rules. See the *SH-3, SH-3E Programming Manual* for details.

3.5 Synchronization Issues

Synchronization with CPU: Floating-point and CPU instructions are issued serially in program order, but may complete out-of-order due to execution cycle differences. A floating point operation that accesses only FPU resources does not require synchronization with the CPU, and subsequent CPU operations can complete before the completion of the floating point operation. Therefore an optimized program can hide the execution cycle of a long-execution-cycle floating point operation such as Divide. A floating point operation such as Compare that accesses CPU resources, however, requires synchronization to ensure program order.

Floating Point Instructions Requiring Synchronization: Loads, stores, compares/tests, and instructions accessing FPUL access CPU resources and therefore require synchronization. Loads and Stores refer to general registers. Post-increment loads and pre-decrement stores modify general registers. Compares/tests modify the T bit. Instructions accessing FPUL refer to or modify FPUL. These references and modifications must be synchronized with the CPU.

Maintaining Program Order on Exceptions: Floating point instructions are never completed until subsequent CPU instructions are completed. If an FPU exception is detected before subsequent CPU instructions finish and an FPU exception occurs, subsequent CPU instructions are canceled.

During a floating point instruction execution, if a subsequent instruction causes an exception, the floating point instruction is left executing and FPU resources cannot be accessed by other instructions. The other instructions must await the completion of the floating point operation before they can access. This ensures program order.

Section 4 Memory Management Unit (MMU)

4.1 Overview

4.1.1 Features

The SH7718R has an on-chip memory management unit (MMU) that implements address translation and features a resident translation look-aside buffer (TLB) that caches information for user-created address translation tables located in external memory. It enables high-speed translation of virtual addresses into physical addresses. Address translation uses the paging system and supports two page sizes (1 kbyte and 4 kbytes). It defines permitted access types to logical address space for privileged and user modes to support memory protection.

4.1.2 Function

The MMU is devised to enable effective use of physical memory. As figure 4.1 shows, when the process is smaller than physical memory, the entire process can be mapped to physical memory. When the process is too large to fit in physical memory, however, the process must be divided and the parts needed for execution mapped into physical memory when they are needed for execution [1]. This places a heavy burden on the process, which must be mapped to physical memory in a way that reflects the manner of its own execution. To lighten this burden, a virtual memory system was devised to handle all mapping to physical memory at once [2]. Under the virtual memory system, a virtual memory that is sufficiently large relative to the size of the physical memory is provided. The process is then mapped onto this virtual memory. The process thus only needs to consider its operation in virtual memory. Mapping from virtual to physical memory is performed by the MMU. The MMU is normally managed by the OS, which swaps physical memory to enable smooth mapping onto physical memory of the virtual memory required by the process. Swapping of physical memory occurs between it and secondary memory.

This type of virtual memory system works at its best in a time sharing system (TSS) that runs multiple processes simultaneously [3]. The multiple simultaneously running processes would not run efficiently if they each had to consider their own mapping to physical memory. To increase efficiency, a virtual memory system is used to decrease the burden on each process [4]. In this virtual memory system, each process is assigned to its own virtual memory. The MMU works to efficiently map multiple virtual memories to physical memory. So that additional processes do not mistakenly access another process's physical memory, the MMU has a memory protection function.

When addresses are translated from virtual memory to physical memory using the MMU, the translation information is not always registered in the MMU and mistaken accesses of the virtual memory of other processes sometimes occurs. When it does, the MMU generates an exception, changes the physical memory mapping, and registers new address translation information.

The MMU functions can also be implemented using software alone, but translating by software every time the process accesses physical memory is inefficient. For that reason, a buffer for address translation is placed in hardware (the TLB) where frequently used address translation information can be stored. The TLB is basically a cache for address translation information. Unlike the regular cache, however, swapping of address translation information when a mistake occurs in address translation (i.e., when an exception occurs) is done by software. This enables flexible management of memory by software.

There are two systems of mapping virtual memory to physical memory in the MMU: fixed length address translation (paging) and variable length address translation (segmenting). In the paging system, address spaces of fixed sizes called pages (usually between 1 kbyte and 64 kbytes) are used as the unit of translation.

In figure 4.1, address space in virtual memory is called virtual address space while address space in physical memory is called physical memory space.

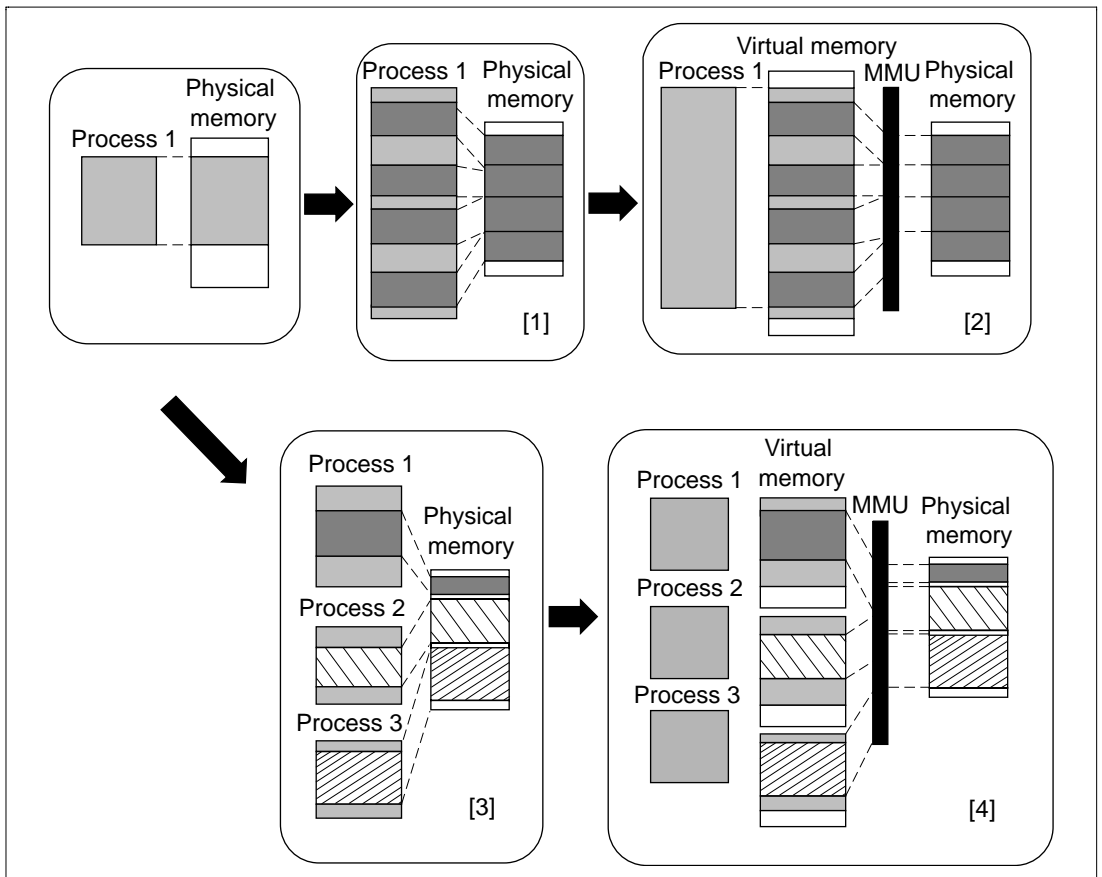


Figure 4.1 MMU Function

4.1.3 The SH7718R MMU

Virtual Address Map: The SH7718R supports 32-bit virtual addresses to access a 4-Gbytes virtual address space that is divided into several areas. Address space mapping is shown in figure 4.2.

In the privileged mode, there are five areas, P0–P4.

The P0 and P3 areas are mapped onto physical address space in page units according to address translation table information. H'7F000000 through H'7FFFFFFF in the P0 area, however, can be used as on-chip RAM if so set in the cache control register (CCR). (See section 6, Cache, for details.) If used as RAM, mapping through the address translation table does not occur in the on-chip RAM space. The write access is also set by the CCR, enabling selection between copy back and write through.

Mapping of the P1 area is fixed to physical address space (H'00000000 to H'1FFFFFFF). In the P1 area, setting a virtual address MSB (bit 31) to 0 generates the corresponding physical address. P1 area access can be cached, and the cache control register (CCR) is set to indicate whether to cache or not. Write-back or write-through mode can be selected.

Mapping of the P2 area is fixed to physical address space (H'00000000 to H'1FFFFFFF). In the P2 area, setting the top three virtual address MSBs (bits 31, 30, and 29) to 0 generates the corresponding physical address. P2 area access cannot be cached.

The P1 and P2 areas are not mapped by the address translation table, so the TLB is not used and no exceptions like TLB misses occur. Initialization of the MMU control register, exception processing handling, and the like are located in the P1 and P2 areas. Because the P1 area is cached, handlers that require high-speed processing are placed there.

The P4 area is used for mapping control areas such as peripheral module registers.

In user mode, the two Gbytes of virtual address space from H'00000000 to H'7FFFFFFF (U0) can be accessed. U0 is mapped onto physical address space in page units according to address translation table information. Also, as in the P0 area, H'7F000000 through H'7FFFFFFF can be used as on-chip RAM if so set in the cache control register (CCR). If used as RAM, mapping through the address translation table does not occur in the on-chip RAM space. The 2 Gbytes of virtual address space from H'80000000 to H'FFFFFFF cannot be accessed in user mode. Attempting to do so creates an address error. The write access is also set by the CCR, enabling selection between copy back and write through.

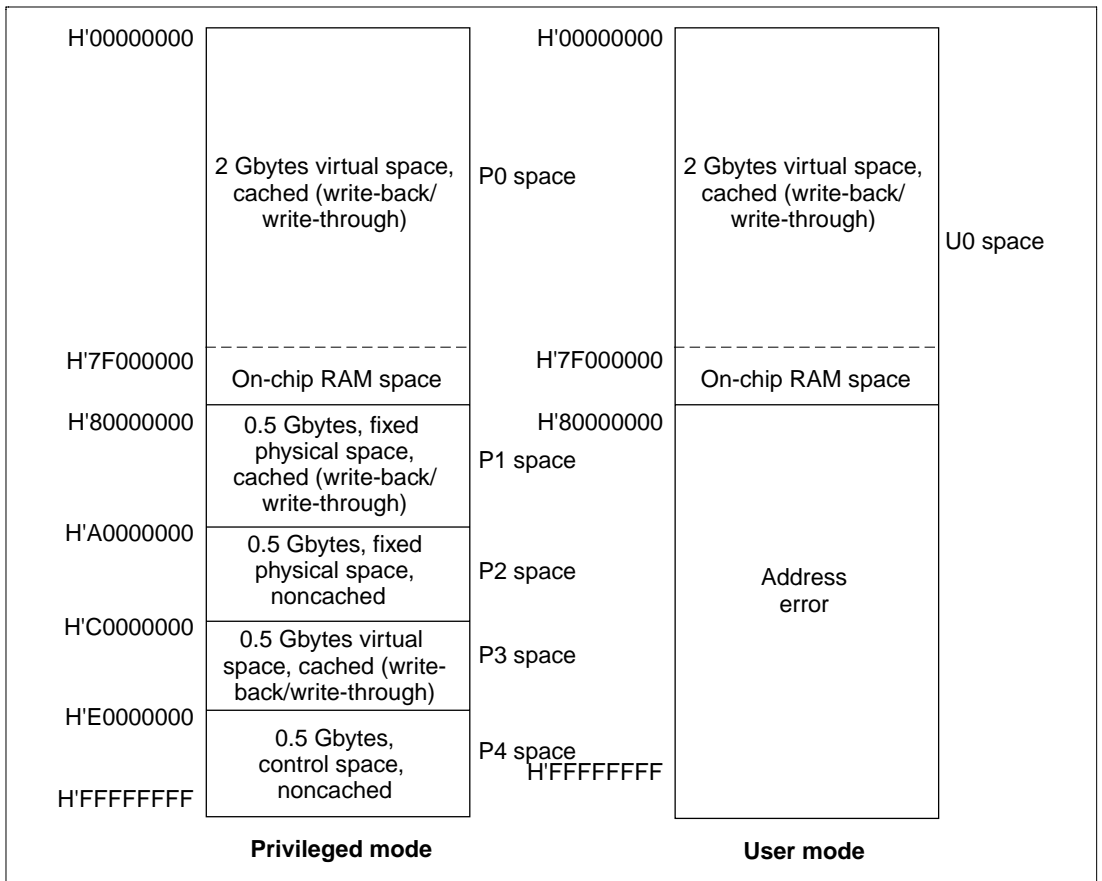


Figure 4.2 Virtual Address Space Mapping

Physical Address Space: The SH7718R supports 32-bit physical addresses, but the top three bits are actually ignored and treated as shadows. For more information, see section 11, Bus State Controller.

Address Translation: When the MMU is enabled, the virtual address space is divided into units called pages. Physical addresses are translated in page units. Address translation tables in external memory hold information such as the physical address that corresponds to the virtual address and memory protection codes. The TLB caches the address table data in external memory to speed up address translation. When an access to an area other than P4 occurs, there is no TLB access and the physical address is defined uniquely if the virtual address accessed belongs to areas P1 or P2. If it belongs to areas P0, P3, or U0, the TLB is searched by virtual address and, if that virtual address is registered in the TLB, the access hits the TLB. The corresponding physical address and the page control information are read from the TLB and the physical address is determined.

If the virtual address is not registered in the TLB, a TLB miss exception occurs and processing shifts to the TLB miss handler. In the TLB miss handler, the TLB address translation table in

external memory is searched and the corresponding physical address and the page control information are registered in the TLB. After returning from the handler, the instruction that caused the TLB miss is re-executed. Do not register address translation information in the TLB that will make the physical address fall between H'80000000 and H'FFFFFFFF while the MMU is enabled.

When the MMU is disabled, the virtual address is equal to the physical address without any changes. The SH7718R supports a 29-bit address space as its physical address space, so the top three bits of physical address are ignored and handled as shadow space (see section 11, Bus State Controller). For example, address H'00001000 of area P0, address H'80001000 of area P1, address H'A0001000 of area P2, and address H'C0001000 of area P3 are all mapped to the same physical memory. When these addresses are accessed when the cache is enabled, they are stored in addresses with the top three bits of the physical addresses masked to 0 to ensure data coherency in the cache's address array.

Single Virtual Memory Mode and Multiple Virtual Memory Mode: There are two virtual memory modes selected by the MMU control register (MMUCR): single virtual memory mode and multiple virtual memory mode. In single virtual memory mode, multiple processes run in parallel using the virtual address space exclusively and the physical address corresponding to a given virtual address is specified uniquely. In multiple virtual memory mode, multiple processes run in parallel sharing the virtual address space, so a given virtual address may be translated into different physical addresses depending on the process. By the value set to the MMU control register, either single or multiple virtual mode is selected. The only difference in how single virtual memory mode and multiple virtual memory mode work is the system of TLB address comparison (see section 4.3.3, TLB Address Comparison, for details).

ASID: Multiple virtual memory mode uses ASIDs (address space IDs) to distinguish multiple processes running simultaneously sharing virtual address space. The ASID is 8 bits and can be set in the PTEH within the MMU for the current process. With ASIDs, the TLB need not be purged at every process switch.

In single virtual memory mode, ASIDs are used to protect memory for multiple processes running simultaneously through using virtual address space exclusively (see section 4.4.2, MMU Software Management).

4.1.4 Register Configuration

Table 4.1 lists the configuration of the MMU control register.

Table 4.1 Register Configuration

Name	Abbreviation	R/W	Size	Initial Value* ¹	Address
Page table entry register high	PTEH	R/W	Longword	Undefined	H'FFFFFFF0
Page table entry register low	PTEL	R/W	Longword	Undefined	H'FFFFFFF4
Translation table base register	TTB	R/W	Longword	Undefined	H'FFFFFFF8
TLB exception address register	TEA	R/W	Longword	Undefined	H'FFFFFFFC
MMU control register	MMUCR	R/W	Longword	* ²	H'FFFFFFE0

Notes: 1. Initialized by a power-on reset or manual reset.

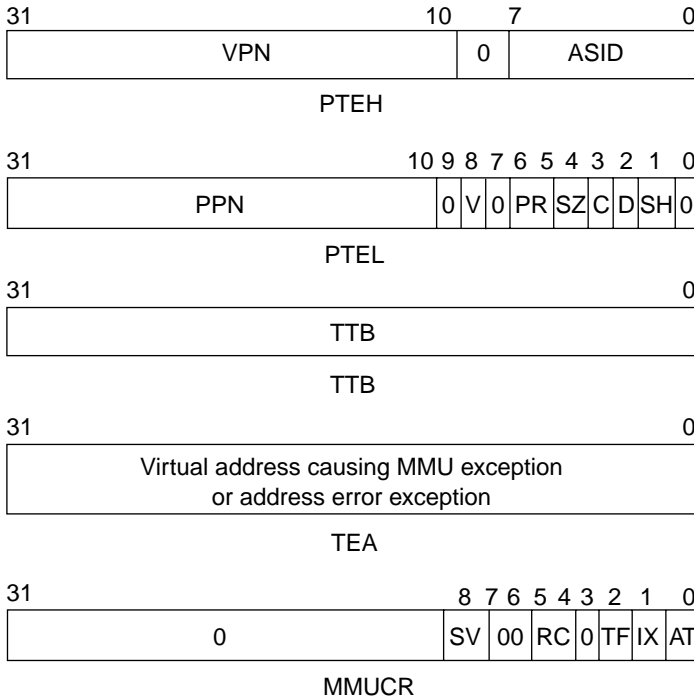
2. SV bit is undefined. All others are 0.

4.2 Description of Registers

There are five registers for MMU processing. These are all peripheral module registers, so they are located in address space area P4 and can only be accessed from privileged mode by specifying the address. These registers consist of:

1. The page table entry high (PTEH) register residing at address H'FFFFFFF0 contains the virtual page number (VPN) and ASID. When an MMU exception or address error exception occurs, the hardware sets the virtual address where the exception occurred as the VPN. When the page size is 4 kbytes, the VPN is the top 20 bits of the virtual address, but the top 22 bits of the virtual address are set. The VPN can also be modified by software. The number of the process currently running is set as the ASID by software. This VPN and ASID are registered in the TLB by the LDTLB instruction.
2. The page table entry low (PTEL) register residing at address H'FFFFFFF4 is used to store the physical page number and page management information registered in the TLB by the LDTLB instruction. The contents of this register do not change unless directed to by software.
3. The translation table base (TTB) register residing at address H'FFFFFFF8, which may, for example, store the base address of the current page table. The data in the TTB does not change unless directed to by software. The TTB is available to the software for general purposes.
4. The TLB exception address (TEA) register residing at address H'FFFFFFFC, which stores the virtual address of any MMU exception or address error exception that occurs. The value is valid until the next exception or interrupt occurs.
5. The MMU control register (MMUCR) residing at address H'FFFFFFE0 sets the MMU as shown in figure 4.3. Any program that modifies the MMUCR should reside in the P1 or P2 area.

The MMU registers are shown in figure 4.3.



- 0: Reserved bits (except MMUCR) : Always read as 0. Writes are ignored.
Reserved bits (MMUCR) : Bits other than bit 3 are always read as 0. Bit 3 is a don't care bit. Specify 0 when writing.
- SV: Single virtual memory mode bit. Set to 1 for single virtual memory mode, 0 for multiple virtual memory mode.
- RC: Random counter. A 2-bit counter that is automatically updated by hardware when an MMU exception occurs following the rules described below. When a TLB miss exception occurs, all ways of the TLB entry for the virtual address that caused the exception are checked and RC is incremented by one if all ways are valid. When some ways are invalid, the smallest numbered way is set to the RC. When the MMU exception other than a TLB miss occurs, the way that caused the exception is set to the RC.
- TF: TLB flush bit. Write 1 to flush (clear all bits to 0). Always reads 0.
- IX: Index mode bit. A logic 1 designates that the EX-ORED value of bits 4–0 of the ASID and VPN number bits 16–12 in the PTEH are used to index the TLB; 0 specifies that only VPN number bits 16–12 are used to index the TLB.
- AT: Address translation bit. Enables/disables MMU; 1 = MMU enabled; 0 = MMU disabled.

Figure 4.3 MMU Register Contents

4.3 TLB Functions

4.3.1 TLB Structure

The TLB caches address translation table information located in external memory. The address translation table stores the virtual page number, the physical page number translated from the virtual page number, the ASID, and the control information for the page. Figure 4.4 shows the overall TLB configuration. The TLB is 4-way set associative with 128 entries (32 entries for each way). Figure 4.5 shows the configuration of virtual addresses and TLB entries.

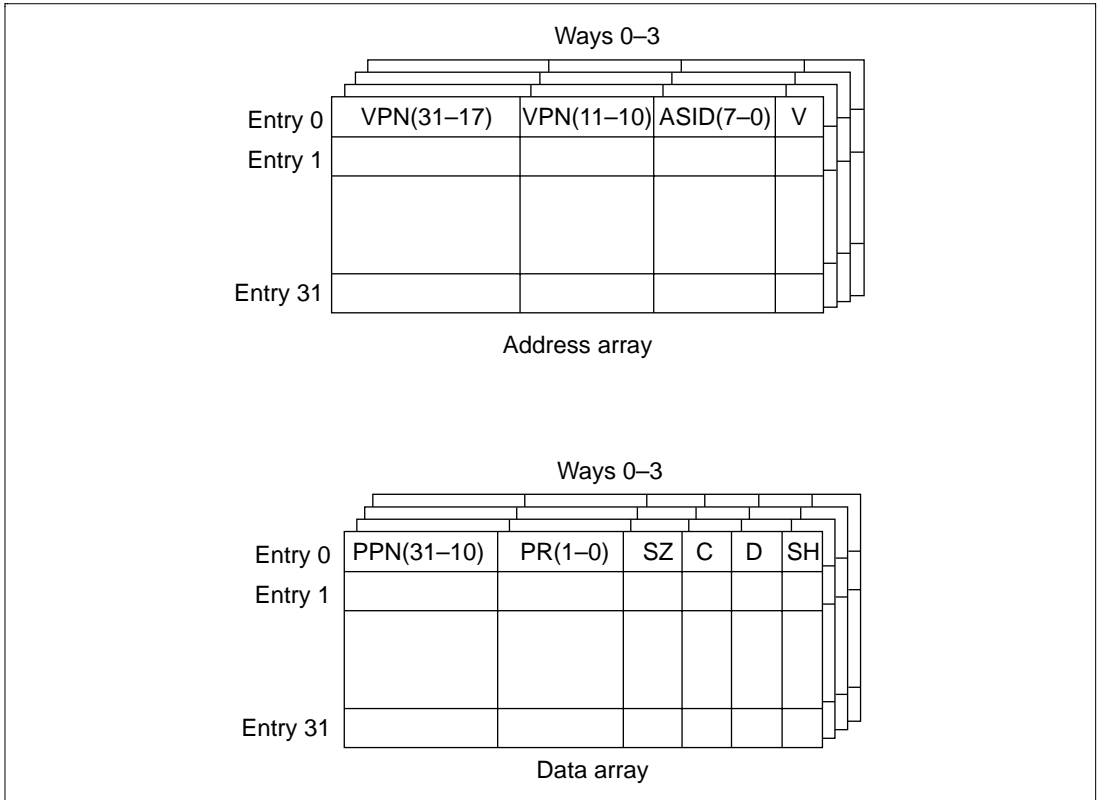
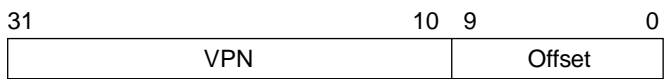
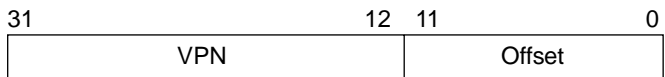


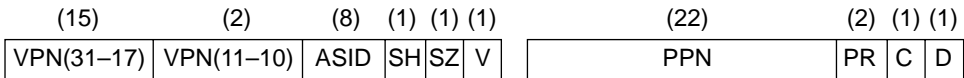
Figure 4.4 Overall Configuration of the TLB



Virtual address (1-kbyte page)



Virtual address (4-kbyte page)



TLB entry

- VPN: Virtual page number. The top 20 bits of virtual address for a 4-kbyte page or the top 22 bits of virtual address for a 1-kbyte page. Since VPN(16–12) are used as the index number, they are not stored in the TLB entry.
- ASID: Address space identifier. Indicates the process that can access the virtual page. In single virtual memory mode and user mode or in multiple virtual memory mode, the ASID in PTEH is compared in address comparisons if the SH bit is 0.
- SH: Share status bit; 0 = page not shared between processes; 1 = page shared between processes.
- SZ: Page size bit; 1 = 4-kbyte page; 0 = 1-kbyte page.
- V: Valid bit. Indicates if entry is valid; 1 = valid; 0 = invalid. Cleared to 0 by a power-on reset; not changed by a manual reset.
- PPN: Physical page number. Top 22 bits of physical address. PPN(11–10) are not used with 4-kbyte pages. Watch for synonym problems with 1-kbyte pages (see section 4.4.4, Avoiding Synonym Problems).
- PR: Protection key field. 2-bit field encoded to define the access rights to the page.
 - 00: Read-only in privileged mode.
 - 01: Read and write in privileged mode.
 - 10: Read-only in privileged and user mode.
 - 11: Read and write in privileged and user mode.
- C: Cacheable bit. Indicates if page resides in cacheable area of memory; 1 = cacheable; 0 = noncacheable.
- D: Dirty bit. Indicates if the page has been written to; 1 = written to, 0 = not written to.

Figure 4.5 Virtual Address and TLB Structure

4.3.2 Creating TLB Index Numbers

The TLB uses a 4-way set associative scheme, so entries must be selected by index. VPN bits 16 to 12 and the PTEH's ASID (4–0) are used as index numbers. The index address can be generated in two different ways depending on the setting of the IX bit in the MMUCR:

1. When IX = 1, VPN bits 16–12 are EX-ORed with ASID bits 4–0 to generate the index number
2. When IX = 0, VPN bits 16–12 are used as the index number.

The first method is used to prevent lowered TLB efficiency when multiple processes run simultaneously in the same virtual address space (multiple virtual memory mode) and a specific entry is selected by multiple processes by indexing. Figures 4.6 and 4.7 illustrate the indexing schemes.

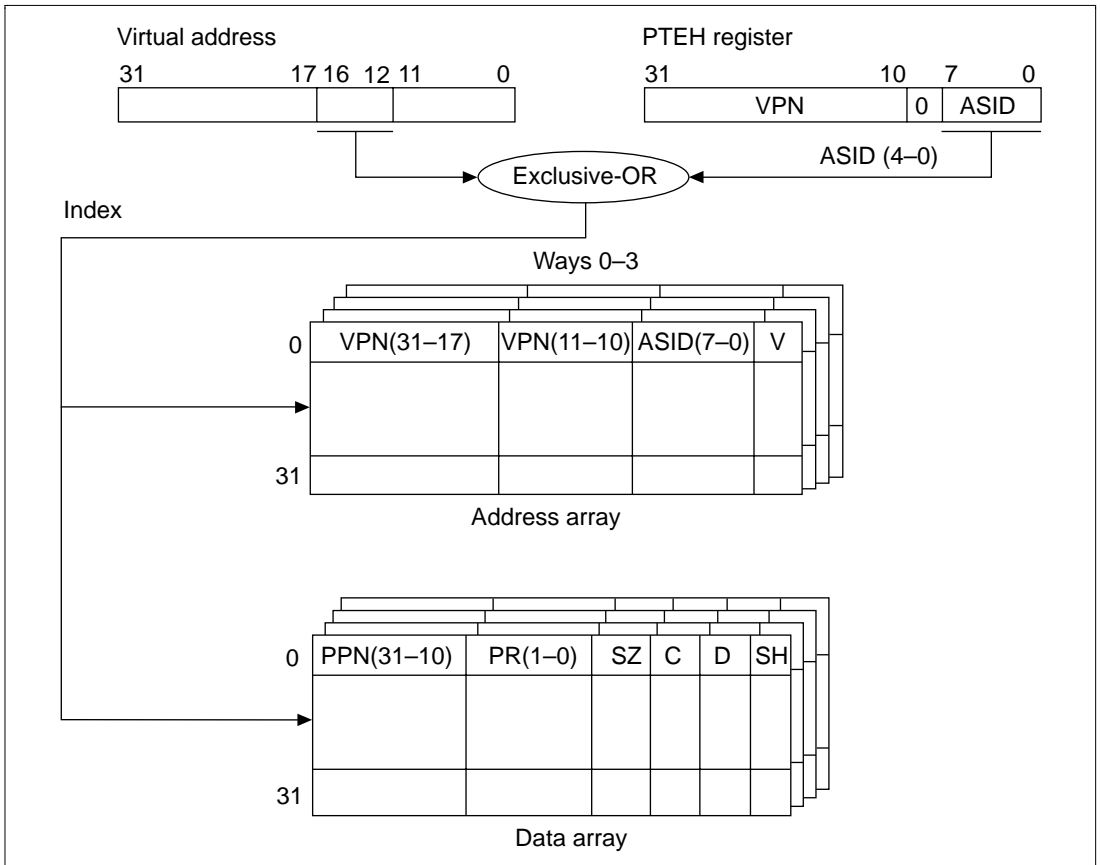


Figure 4.6 TLB Indexing (IX = 1)

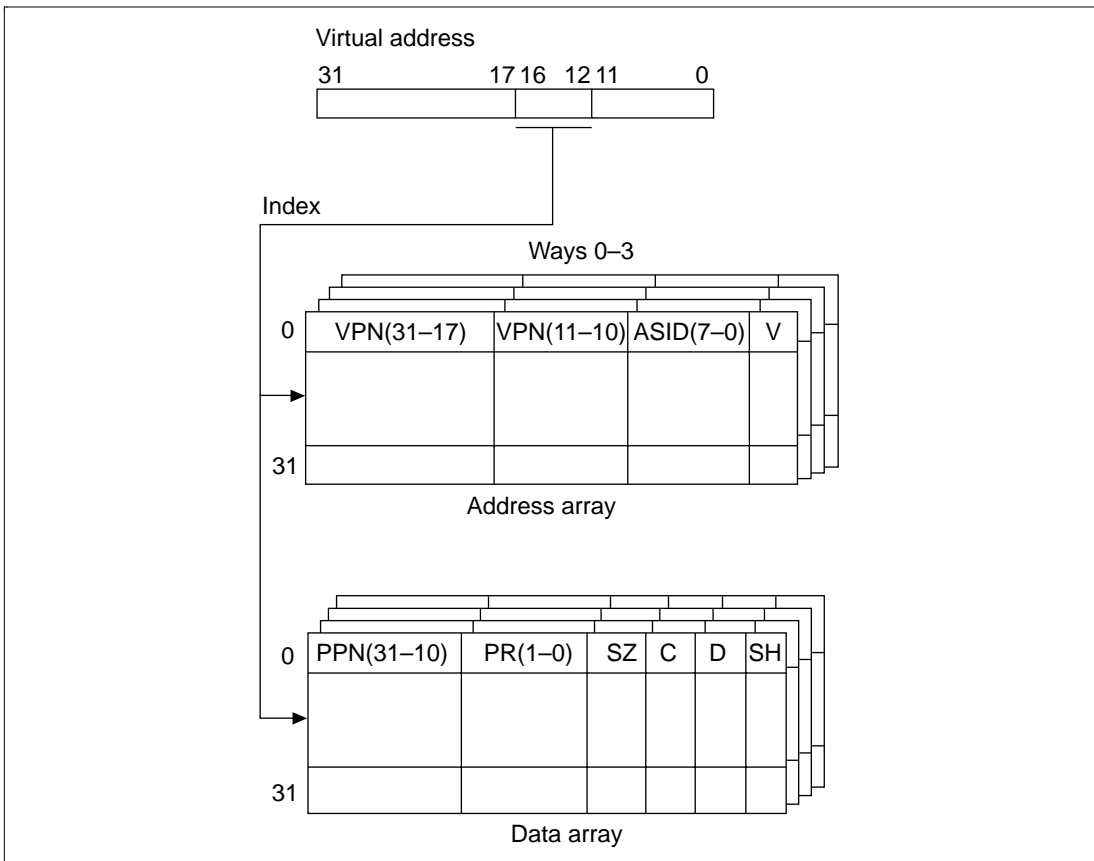


Figure 4.7 TLB Indexing (IX = 0)

4.3.3 TLB Address Comparison

TLB address comparison is used when fetching instructions from programs in external memory and when accessing data in external memory. The virtual page number (VPN) and ASID are used for address comparison. The VPN of the virtual address that accesses external memory is compared to the VPN of the indexed TLB entry. The ASID within the PTEH is compared to the ASID of the indexed TLB entry. All four ways are searched simultaneously. If the compared values match and the indexed TLB entry is valid (V bit = 1), the TLB hit is registered. Configure the software to ensure that multiple ways are not TLB hit simultaneously. Should this occur, hardware operation cannot be guaranteed. For example, make sure that the software is set so that only the process with ASID=H'FF is hit for two TLB entries with the same VPN where one shares (SH=1) and the other does not (SH=0). Otherwise, when the ASID in PTEH changes to H'FF, there is the possibility of a TLB hit to two ways simultaneously. Do not make these kinds of settings using software.

The object compared varies depending on the page management information (SZ, SH) in the TLB entry. It also varies depending on whether the system supports multiple virtual memory or single virtual memory.

The page size bit (SZ) determines whether VPN (11–10) are compared. VPN (11–10) are compared for 1 kbyte pages (SZ = 0) but not for 4 kbytes pages (SZ = 1).

The sharing information bit (SH) determines whether the PTEH.ASID and the ASID in the TLB entry are compared. ASIDs are compared when there is no sharing between processes (SH = 0) but not when there is sharing (SH = 1).

When single virtual memory mode (MMUCR.SV = 1) and privileged mode are engaged (SR.MD = 1), all process resources can be accessed because ASIDs are not compared. The objects of address comparison are shown in figure 4.8.

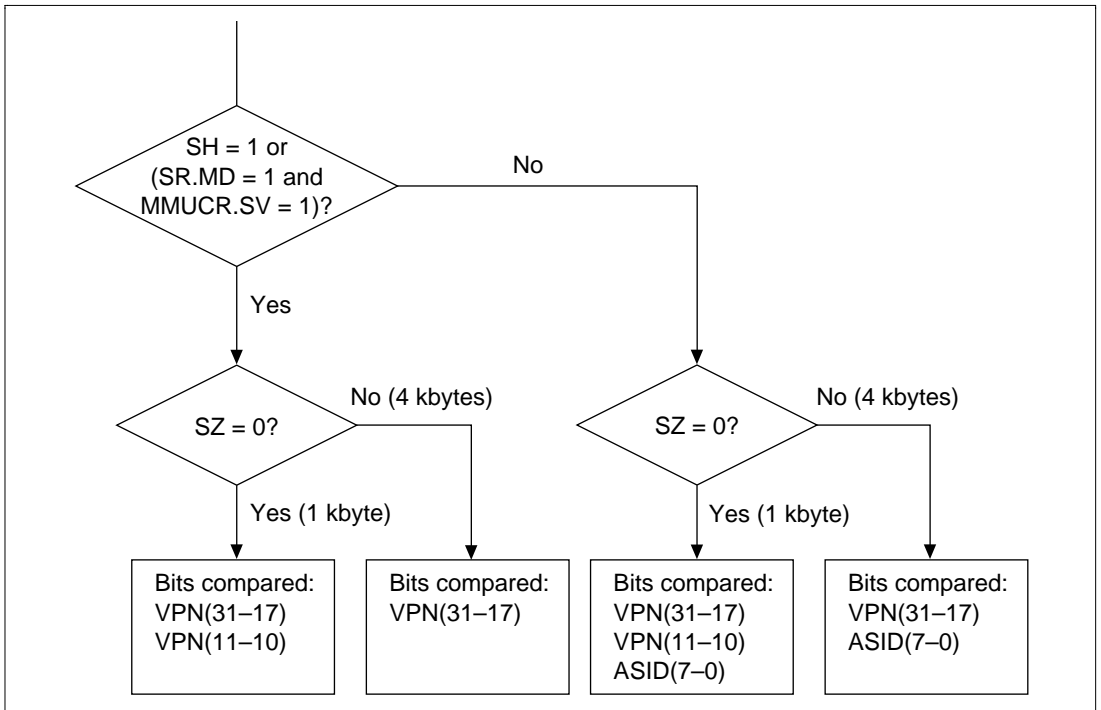


Figure 4.8 Objects of Address Comparison

4.3.4 Page Management Information

In addition to the SH and SZ bits, the page management information of TLB entries also includes D, C, and PR bits.

The D bit of a TLB entry indicates if the page is dirty (i.e., has been written to). If the D bit is 0, an attempt to write to the page results in an initial page write exception. For physical page swapping between secondary memory and main memory, for example, pages are controlled so that a dirty page is paged out of main memory only after that page is written back to secondary memory. To record that there has been a write to a given page in the address translation table in memory, an initial page write exception is used.

The C bit in the entry indicates whether the referenced page resides in a cacheable or non-cacheable area of memory. The PR field specifies the access rights for the page in privileged and user modes and is used to protect memory. Attempts at prohibited accesses result in TLB protection violation exceptions.

Table 4.2. shows the access states of the D, C, and PR bits.

Table 4.2 Access States of the D, C, and PR Bits

Bits	Privileged Mode			User Mode	
		Read	Write	Read	Write
D bit	0	OK	Initial page write exception	OK	Initial page write exception
	1	OK	OK	OK	OK
C bit	0	OK (no caching)	OK (no caching)	OK (no caching)	OK (no caching)
	1	OK (caching)	OK (caching)	OK (caching)	OK (caching)
PR bits	00	OK	TLB protection violation exception	TLB protection violation exception	TLB protection violation exception
	01	OK	OK	TLB protection violation exception	TLB protection violation exception
	10	OK	TLB protection violation exception	OK	TLB protection violation exception
	11	OK	OK	OK	OK

4.4 MMU Functions

4.4.1 MMU Hardware Management

There are two types of MMU hardware management.

1. Decoding a virtual address accessed from a process and translating the address by controlling the TLB according to MMUCR settings.
2. Receiving page management information and hit information from the TLB when the address is translated and checking for MMU exceptions and for whether the cache was accessed (C bit). See section 4.5, MMU Exceptions, for a description of this method of checking and hardware processing.

4.4.2 MMU Software Management

There are three types of MMU software management.

MMU Register Settings: Set the MMUCR in areas P1 and P2, which do not translate addresses. Also, since changing the SV and IX bits changes the address translation system, simultaneously write a 1 to the TF bit to flush the TLB. When the MMU is disabled with an AT bit of 0, no MMU exceptions occur, so it should always be disabled for software that does not use the MMU.

Registering, Deleting, and Reading TLB Entries: Data can be registered in a TLB entry either by using the LDTLB instruction or by writing directly to memory-mapped TLB. TLB entries can be deleted or read by accessing the memory-mapped TLB. See section 4.4.3, MMU Instructions, for details about the LDTLB instruction and section 4.6, Memory-Mapped TLB, for details about the memory-mapped TLB.

MMU Exception Processing: Information set through the hardware is restored to the original when an MMU exception occurs. See section 4.5, MMU Exceptions, for more information.

When single virtual memory mode is used, the share bit (SH) can be set to 0 and all TLB entries registered to create a state that enables access to all physical memory only in privileged mode. This strengthens protection of memory between processes and creates a special access level for privileged mode.

Synonym problems may occur when registering 1 kbyte page TLB entries. See section 4.4.4, Avoiding Synonym Problems.

4.4.3 MMU Instructions (LDTLB)

The load TLB (LDTLB) instruction is used to register TLB entries. When the MMUCR.IX bit is 0, the LDTLB instruction uses the VPN (16–12) specified in PTEH as the index number and changes the TLB entry of the way specified by the MMUCR.RC bit to the values specified in PTEH and PTEL. When the MMUCR.IX bit is 1, the LDTLB instruction EX-ORs the VPN (16 to 12) specified in PTEH and the ASID (4–0) in the PTEH for the index number.

Figure 4.9 shows the operation of the LDTLB instruction when the MMUCR.IX bit is 0.

The virtual page number of the virtual address that causes an MMU exception is set by hardware in the PTEH when the exception occurs. Ways are also set in the MMUCR.RC bit according to the rules described in figure 4.4. For this reason, if an LDTLB instruction is called in an MMU exception processing routine with only PTEL set, the TLB entry can be registered. Rewriting the PTEH and MMUCR.RC bit with software enables rewriting of any TLB entry.

The LDTLB instruction changes the address translation information, so it may degrade address translation information that is currently executing when it is called in the P0, U0, or P3 areas. Be sure to call it in the P1 or P2 areas. Instructions that involve access of the P0, U0, or P3 area (e.g., the RTE instruction) must be separated from the LDTLB instruction by at least one instruction.

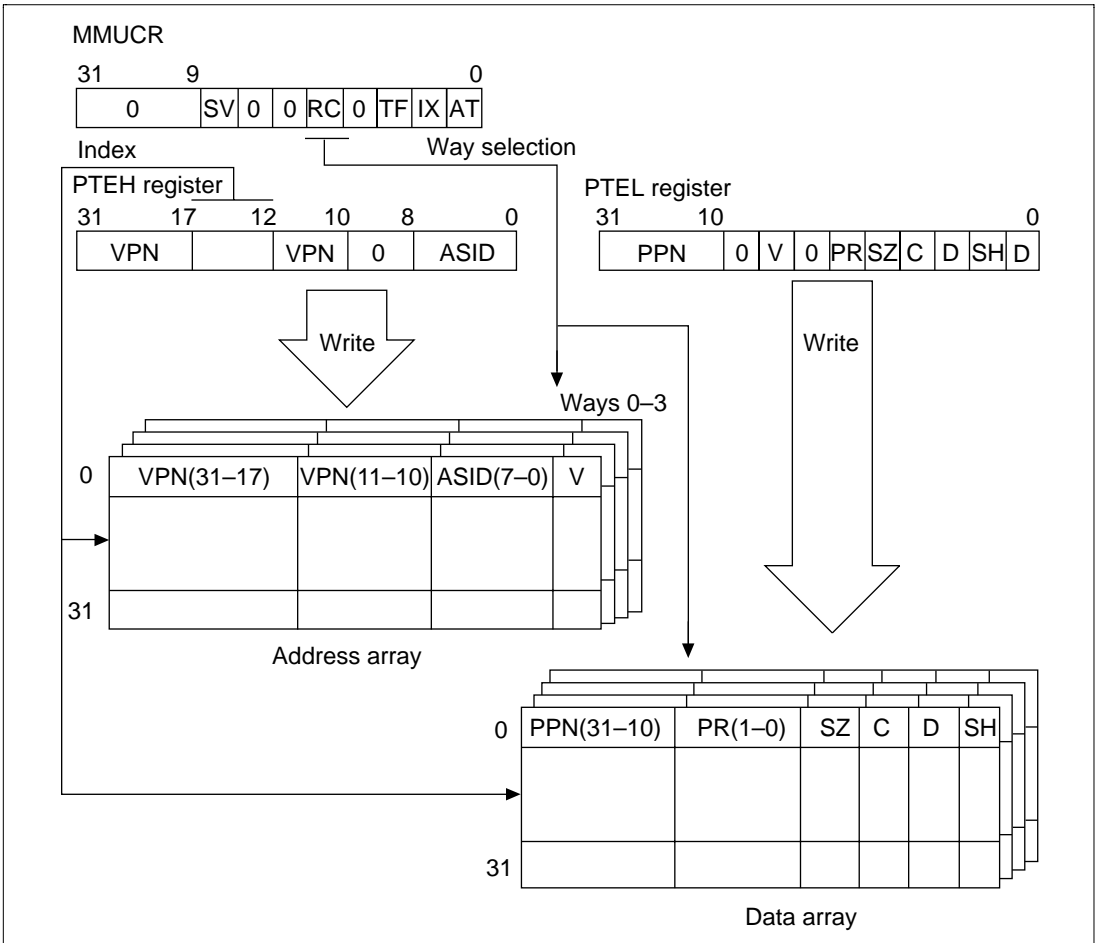


Figure 4.9 Operation of the LDTLB Instruction

4.4.4 Avoiding Synonym Problems

Synonym problems may occur when 1-kbyte pages are registered in TLB entries. Synonym problems occur when multiple virtual addresses are mapped to a single physical address and the same physical address data is registered in multiple cache entries, making it impossible to guarantee the consistency of the data. Figure 4.10 shows why this problem only occurs when 1-kbyte pages are used.

The SH7718R creates index numbers using virtual address (10–4) to speed up cache operations. When 4-kbytes pages are used, (10–4) of the virtual address are included in the offset and are not objects of address translation, so they are the same as physical address (10–4). The cache tag address is the physical address for comparisons of addresses in the cache and registration in address arrays, so (31–10) of the physical address are registered.

When 1-kbyte pages are used, (10–4) of the virtual address are used to create the cache's index number. For 1-kbyte pages, however, virtual address (10) is an object of address translation, so it is not always the same as physical address (10). For this reason, the physical address is registered in a different entry from the cache address array's index number that indicates the physical address.

For example, in a 1-kbyte page TLB entry, two TLB entries can be registered to translate as follows:

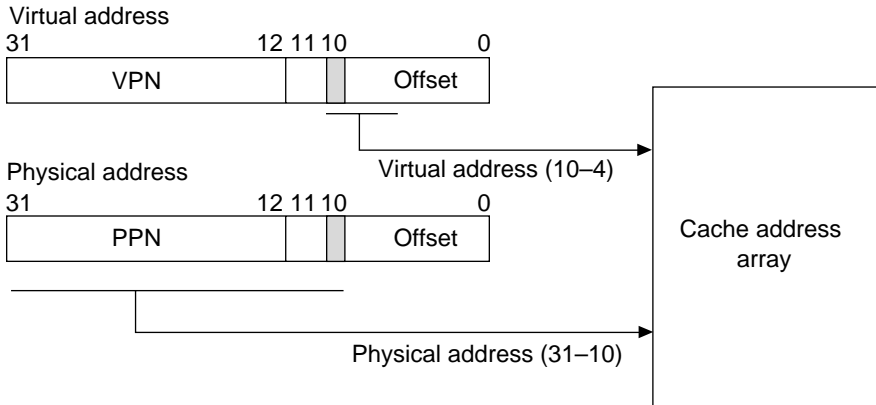
Virtual address 1 H'00000000 → Physical address H'00000400

Virtual address 2 H'00000400 → Physical address H'00000400

Virtual address 1 is registered in cache entry H'00 while virtual address 2 is registered in entry H'40. Despite the identical physical address, they are registered in different cache entries, so coherency will be lost if either virtual address is written to even once.

For this reason, when registering a 1-kbyte TLB entry, do not register the same virtual address (10) if the physical address is the same as one already used by another TLB entry.

- Using 4-kbyte page



- Using 1-kbyte page

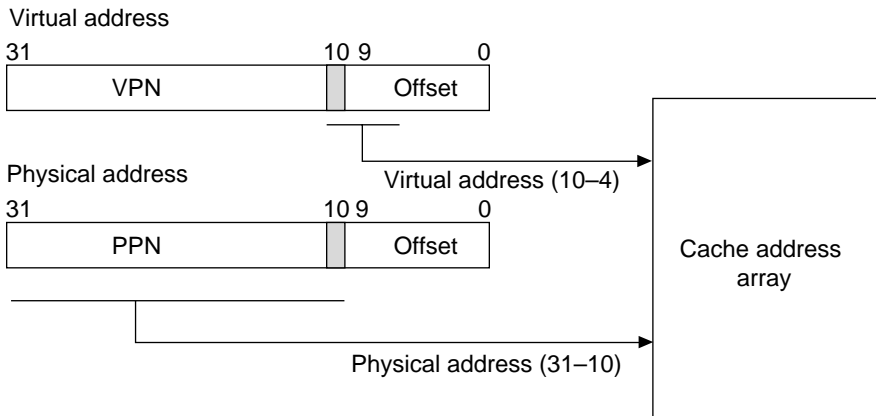


Figure 4.10 Synonym Problems

4.5 MMU Exceptions

There are four MMU exceptions: TLB miss, TLB protection violation, TLB invalid, and initial page write.

4.5.1 TLB Miss

A TLB miss results when the virtual address and the address array of the selected TLB entry are compared and no match is found. TLB miss exception processing includes both hardware and software operations.

Hardware Operations: In a TLB miss, the SH7718R hardware executes a set of prescribed operations, as follows:

1. The VPN field of the virtual address causing the exception is written into the PTEH register.
2. The virtual address causing the exception is written into the TEA register.
3. Either exception code H'040 for a load access, or H'060 for a store access, is written to the EXPEVT register.
4. The value of the PC indicating the address of the instruction in which the exception occurred is written into the save program counter (SPC). If the exception occurred in a delay slot, the PC value indicating the address of the related delayed branch instruction is written into the SPC.
5. The contents of the status register (SR) at the time of the exception are written into the save status register (SSR).
6. The mode (MD) bit in SR is set to a logic one to place the SH7718R in privileged mode.
7. The block (BL) bit in SR is set to a logic one to mask any further exception requests.
8. The register bank (RB) bit of the SR is set to 1.
9. All ways of the TLB entry for the virtual address that caused the exception are checked and the random counter (RC) of the MMU control register (MMUCR) is incremented by 1 when all ways are valid. When some entries indexed are invalid, the smallest numbered of the ways is set to the RC.
10. Execution branches to the address obtained by adding the value of VBR contents and H'00000400 to invoke the TLB miss handler routine.

Software (TLB Miss Handler) Operations: The software searches the page tables in external memory and allocates the required page table entry. To retrieve the required page table entry, the software must execute the following operations:

1. Write the values of the physical page number (PPN) field and the protection key (PR), page size (SZ), cacheable (C), dirty (D), share status (SH), and valid (V) bits of the page table entry recorded in the address translation table in external memory into the PTEL register.
2. If using software to select ways for entry replacement, write the desired value into the RC field in MMUCR.
3. Issue the LDTLB instruction to load the contents of PTEH and PTEL into the TLB.
4. Issue the return from exception handler (RTE) instruction to terminate the handler routine and return to the instruction stream. Separate the LDTLB and RTE instructions by at least one other instruction.

4.5.2 TLB Protection Violation

A TLB protection violation exception results when the virtual address and the address array of the selected TLB entry are compared and a valid entry is found to match, but the type of access is not

permitted by the access rights specified in the PR field. TLB protection violation exception processing includes both hardware and software operations.

Hardware Operations: In a TLB protection violation exception, the SH7718R hardware executes a set of prescribed operations, as follows:

1. The VPN field of the virtual address causing the exception is written into the PTEH register.
2. The virtual address causing the exception is written into the TEA register.
3. Either exception code H'0A0 for a load access, or H'0C0 for a store access, is written to the EXPEVT register.
4. The value of the PC indicating the address of the instruction in which the exception occurred is written into SPC. (If the exception occurred in a delay slot, the PC value indicating the address of the related delayed branch instruction is written into SPC.)
5. The contents of SR at the time of the exception are written into SSR.
6. The MD bit in SR is set to a logic one to place the SH7718R in privileged mode.
7. The BL bit in SR is set to a logic one to mask any further exception requests.
8. The register bank (RB) bit of the SR is set to 1.
9. The way that generated the exception is set in the random counter (RC) of the MMUCR.
10. Execution branches to the address obtained by adding the value of VBR contents and H'00000100 to invoke the TLB protection violation exception handler routine.

Software (TLB Protection Violation Handler) Operations: The software resolves the TLB protection violation and issues the RTE (return from exception handler) instruction to terminate the handler routine and return to the instruction stream. Separate the LDTLB and RTE instructions by at least one other instruction.

4.5.3 TLB Invalid Exception

A TLB invalid exception results when the virtual address is compared to a selected TLB entry address array and a match is found but the entry was not valid (a V bit of 0). TLB invalid exception processing includes both hardware and software operations.

Hardware Operations: In a TLB invalid exception, the SH7718R hardware executes a set of prescribed operations, as follows:

1. The VPN number of the virtual address causing the exception is written into the PTEH register.
2. The virtual address causing the exception is written into the TEA register.
3. The way number causing the exception is written into RC of the MMUCR.
4. Either exception code H'040 for a load access, or H'060 for a store access, is written to the EXPEVT register.

5. The value of the PC indicating the address of the instruction in which the exception occurred is written into the SPC. If the exception occurred in a delay slot, the PC value indicating the address of the delayed branch instruction is written into the SPC.
6. The contents of the SR at the time of the exception are written into the SSR.
7. The mode (MD) bit in the SR is set to one to place the SH7718R in privileged mode.
8. The block (BL) bit in the SR is set to one to mask any further exception requests.
9. The register bank (RB) bit in the SR is set to one.
10. Execution branches to the address obtained by adding the value of VBR contents and H'00000100 and the TLB protection violation handler starts.

Software (TLB Invalid Exception Handler) Operations: The software searches the page tables in external memory and assigns the required page table entry. Upon retrieving the required page table entry, the software must execute the following operations:

1. Write the values of the physical page number (PPN) field and the protection key (PR), page size (SZ), cacheable (C), dirty (D), share status (SH), and valid (V) bits of the page table entry recorded in external memory into the PTEL register.
2. If using software to select the way for entry replacement, write the desired value into the RC field in MMUCR.
3. Issue the LDTLB instruction to load the contents of PTEH and PTEL into the TLB.
4. Issue the RTE instruction to terminate the handler routine and return to the instruction stream. Separate the LDTLB and RTE instructions by at least one other instruction.

4.5.4 Initial Page Write

An initial page write exception results in a write access when the virtual address and the address array of the selected TLB entry are compared and a valid entry with the appropriate access rights is found to match but the D (dirty) bit of the entry is a logic zero (page cannot be written to).

Initial page write exception processing includes both hardware and software operations.

Hardware Operations: In an initial page write exception, the SH7718R hardware executes a set of prescribed operations, as follows:

1. The VPN field of the virtual address causing the exception is written to the PTEH register.
2. The virtual address causing the exception is written to the TEA register.
3. Exception code H'080 is written into the EXPEVT register.
4. The value of the PC indicating the address of the instruction in which the exception occurred is written to SPC. If the exception occurred in a delay slot, the PC value indicating the address of the related delayed branch instruction is written to SPC.
5. The contents of SR at the time of the exception are written to SSR.
6. The MD bit in SR is set to a logic one to place the SH7718R in privileged mode.

7. The BL bit in SR is set to a logic one to mask any further exception requests.
8. The register bank (RB) bit of the SR is set to 1.
9. The way that caused the exception is set in the random counter (RC) of the MMUCR.
10. Execution branches to the address obtained by adding the value of VBR contents and H'00000100 to invoke the user-written initial page write exception handler routine.

Software (Initial Page Write Handler) Operations: The software must execute the following operations:

1. Retrieve the required page table entry from external memory.
2. Set the D bit of the page table entry in external memory to a logic one.
3. Write the value of the PPN field and the PR, SZ, C, D, SH, and V bits of the page table entry in external memory into the PTEL register.
4. If using software to select the way for entry replacement, write the desired value into the RC field in MMUCR.
5. Issue the LDTLB instruction to load the contents of PTEH and PTEL into the TLB.
6. Issue the RTE instruction to terminate the handler routine and return to the instruction stream. Separate the LDTLB and RTE instructions by at least one other instruction.

Figure 4.11 shows the flow of MMU exceptions.

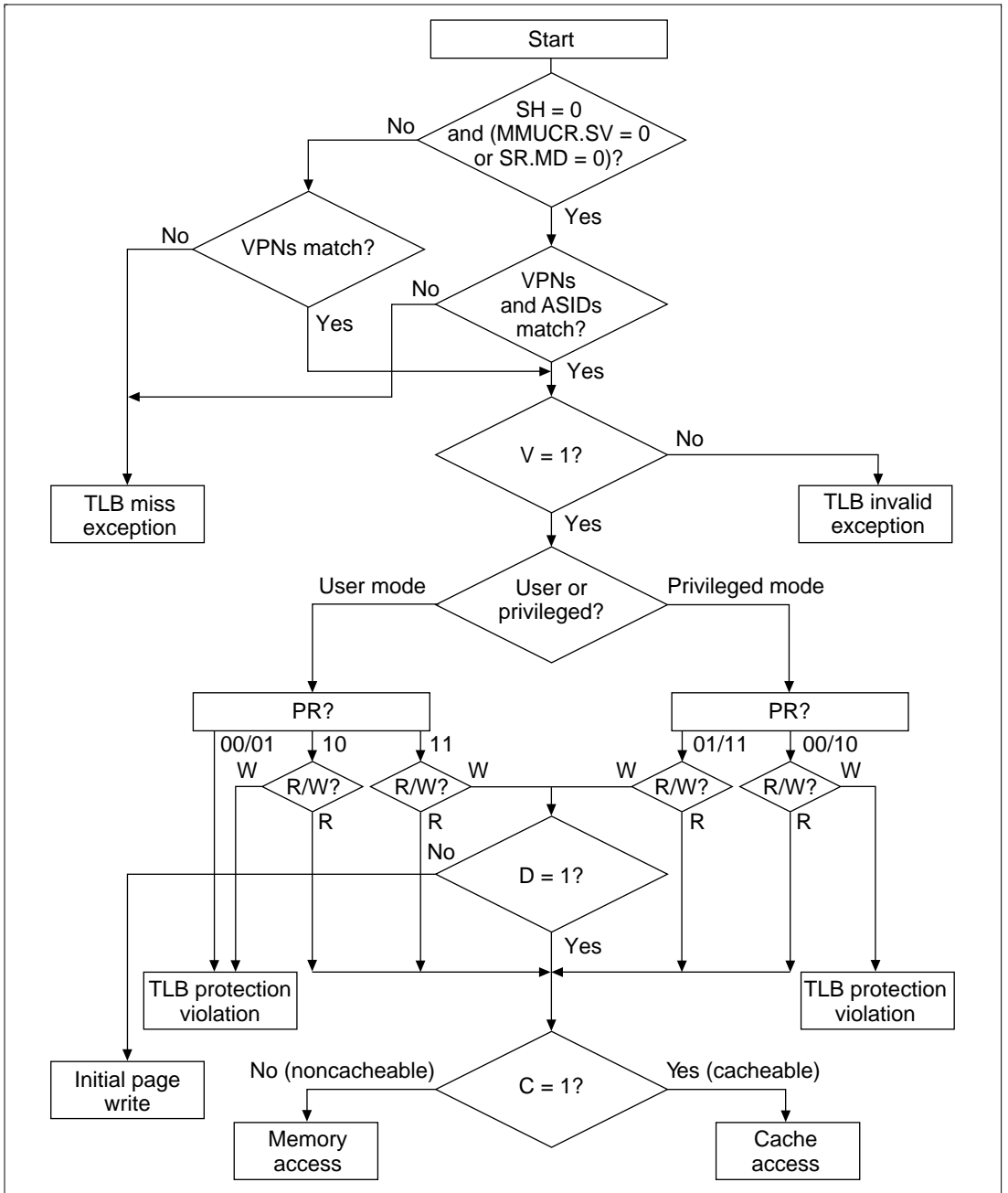


Figure 4.11 MMU Exception Generation Flowchart

4.5.5 Processing when an MMU Exception Occurs

Figure 4.12 shows the MMU exception during instruction fetch.

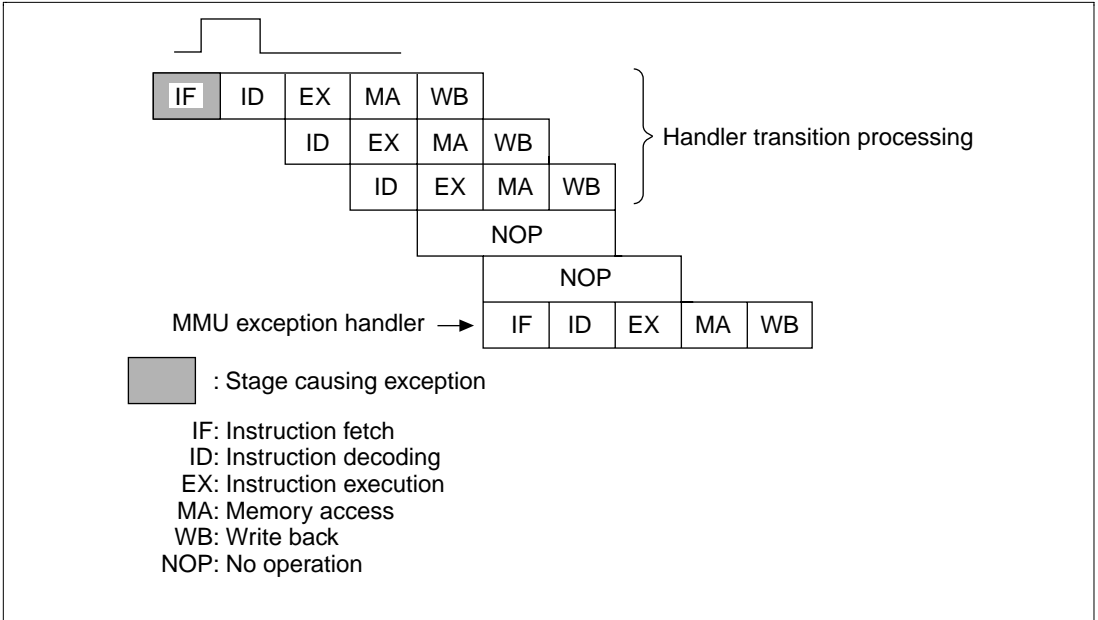


Figure 4.12 MMU Exception Signals during Instruction Fetch

Figure 4.13 shows MMU exception during data access.

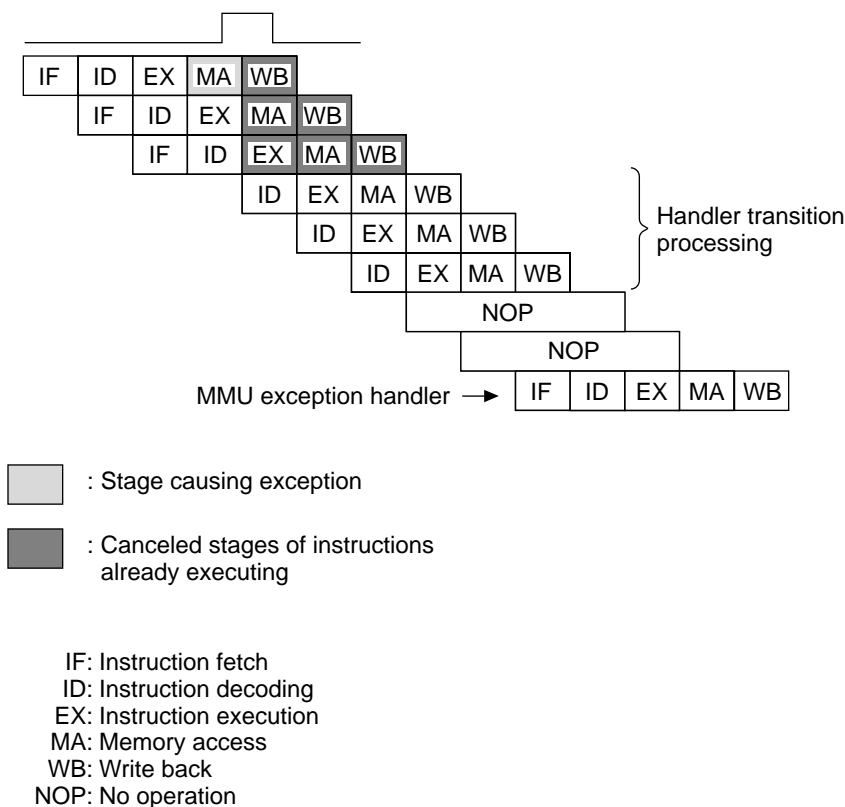


Figure 4.13 MMU Exception Signals during Data Access

4.6 Memory-Mapped TLB

To manage TLB operations by software, the TLB can be read and written using the MOV instruction in privileged mode. The TLB is assigned to virtual address space P4. The TLB address array (VPN, V bit, and ASID) is mapped to H'F2000000 to H'F2FFFFFFF and the data array (PPN, PR, SZ, C, D, and SH bits) is mapped to H'F3000000 to H'F3FFFFFFF. The address array's V bit can also be accessed from the data array. Access sizes are longword for both address array and data array.

4.6.1 Address Array

The address array is assigned to H'F2000000 to H'F2FFFFFFF. To access an address array, the 32-bit address section (for read/write) and 32-bit data section (for write) must be specified. The

address section specifies information for selecting the entry to be accessed; the data section specifies the VPN, V bit and ASID to be written to the address array (figure 4.14 (1)).

In the address section, specify the index address for selecting the entry (VPN bits 16–12) in bits (16–12) of the address section, the W for selecting the way in bits (9–8) of the address section, and HF2 to indicate address array access in bits (31–24). The IX bit of the MMUCR indicates whether an EX-OR is taken of VPN (16–12) and the PTEH register's ASID (4–0) for the index address.

When writing, specify bit 7 as the associative (A) bit. The A bit indicates whether addresses are compared during writing. When the A bit is 1, the VPNs of the four entries selected by the index addresses are compared to the VPN to be written into the address array specified in the data section. Writing takes place to the way that has a hit. When a miss occurs, nothing is written to the address array and no operation occurs. The way number specified in bits 9–8 is not used. The item compared is determined by the SZ and SH bits of the entry selected by the index address, the SV bit of the MMUCR, and the MD bit of the SR, just as in ordinary operations (see section 4.3.3).

When the A bit is 0, it is written to the entry selected by the index address and way without comparing addresses.

When reading, the VPN, V bit, and ASID of the entry specified by the index address and way are read in the format of the data section in figure 4.14 without comparing addresses. Bits (16–12) of the data section read 0.

To invalidate a specific entry, specify the entry and write 0 to its V bit. When 1 is specified for the A bit, only the desired VPN entry is invalidated.

4.6.2 Data Array

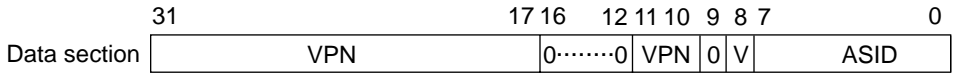
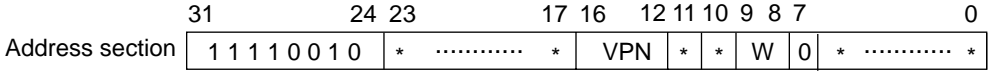
The data array is assigned to HF3000000 to HF3FFFFFFF. To access a data array, the 32-bit address section (for read/write), and 32-bit data section (for write) must be specified. The address section specifies information for selecting the entry to be accessed; the data section specifies the longword data to be written to the data array (figure 4.14 (2)). The bit structure of the longword data is the same as the PTEL.

In the address section, specify the index address for selecting the entry (VPN bits 16–12) in bits (16–12) of the address section, the W for selecting the way in bits (9–8) of the address section, and HF3 to indicate data array access in bits (31–24). The IX bit of the MMUCR indicates whether an EX-OR is taken of VPN (16–12) and the PTEH register's ASID (4–0) for the index address.

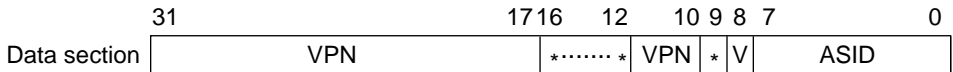
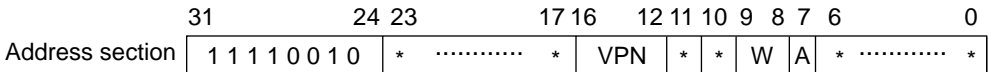
Both reading and writing use the longword of the data array specified by the index address and way.

1. TLB address array access

- Read



- Write



VPN: Virtual page number

ASID: Address space ID

V: Valid bit

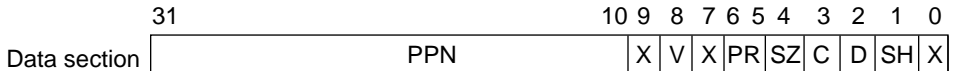
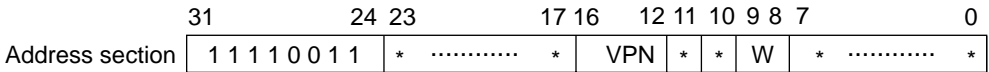
*: Don't care bit

A: Associative bit

W: Way (00: way 0, 01: way 1, 10: way 2, 11: way 3)

2. TLB data array access

- Read/write



PPN: Physical page number

V: Valid bit

PR: Protection key data

SZ: Page size bit

C: Cacheable bit

D: Dirty bit

SH: Share bit

*: Don't care bit

VPN: Virtual page number

X: 0 for read, don't-care for write

W: Way (00: way 0, 01: way 1, 10: way 2, 11: way 3)

Figure 4.14 Specifying Address and Data for Memory-Mapped TLB Access

4.6.3 Examples

Invalidating Specific Entries: Specific TLB entries can be invalidated by writing 0 to the entry's V bit. When the A bit is 1, the VPN and ASID specified by the write data are compared to the VPN and ASID within the TLB entry selected by the index address and data is written to the

matching way. If no match is found, there is no operation. In the following example, R0 specifies the write data and R1 specifies the address.

```
;R0 =H'1547 381C R1 = H'F201 3080
;MMUCR.IX = 0
;Entry corresponding to VPN(31-17) =B'0001 0101 0100 011
VPN(11-10) = B'10 ASID=B'0001 1100 is associated with the entry
selected by the index
MOV.L R0,@R1
```

Reading a Data Array: This example reads the data array of a specific TLB entry. The register is read in the bit order indicated in the data section in figure 4.14 (2). In the following example, R0 specifies the address and the data section of a selected entry is read to R1.

```
;R0=H'F300 4300 VPN(16-12)=B'0 0100 way 3
MOV.L @R0,R1
```

4.7 Cautions

Use instructions that manipulate the SR register's MD and BL bits (LDC Rm, SR instruction, LDC @Rm+, SR instruction, and RTE instruction), instructions that follow them, and LDTLB instructions with the TLB disabled or in fixed physical address space (P1 or P2).

Section 5 Exception Processing

5.1 Overview

5.1.1 Features

Exceptions are deviations from normal program execution that require special handling. The processor responds to an exception by aborting execution of the current instruction (execution is allowed to continue to completion in all interrupt requests) and passing control from the instruction stream to the appropriate user-written exception handling routine. Here, all exceptions other than resets and interrupts will be called general exceptions. There are thus three types of exceptions: resets, general exceptions, and interrupts.

5.1.2 Register Configuration

Table 5.1 lists the register configuration for exception processing.

Table 5.1 Register Configuration

Register	Abbr.	R/W	Size	Initial Value	Address
TRAPA exception register	TRA	R/W	Longword	Undefined	H'FFFFFFD0
Exception event register	EXPEVT	R/W	Longword	Power-on reset: H'000 Manual reset: H'020	H'FFFFFFD4
Interrupt event register	INTEVT	R/W	Longword	Undefined	H'FFFFFFD8

5.2 Exception Processing Function

5.2.1 Exception Processing Flow

Usually the contents of program counter (PC) and status register (SR) are saved in the saved program counter (SPC) and saved status register (SSR), respectively, and execution of the exception handler is invoked from a vector address. The return from exception handler (RTE) instruction is issued by the exception handler routine at the completion of the routine, restoring the contents of the PC and SR to return to the processor status at the point of interruption and the address where the exception occurred.

A basic exception processing sequence consists of the following operations:

1. The contents of PC and SR are saved in SPC and SSR, respectively.

2. The block (BL) bit in SR is set to a logic one, masking any subsequent exceptions.
3. The mode (MD) bit in SR is set to a logic one to place the SH7718R in privileged mode.
4. The register bank (RB) bit in SR is set to a logic one.
5. An encoded value identifying the exception event is written into bits 11–0 of the exception event (EXPEVT) or interrupt event (INTEVT) register.
6. Instruction execution jumps to the designated exception processing vector address to invoke the handler routine.

5.2.2 Exception Processing Vector Table

The reset vector address is fixed at H'A0000000. General exceptions and interrupts are assigned offsets from the vector base address by software. Translation look-aside buffer (TLB) miss traps have an offset from the vector base address of H'00000400. The vector address offset for general exception events other than TLB miss traps is H'00000100. The interrupt vector address offset is H'00000600. The vector base address is loaded into the vector base register (VBR) by software. The vector base address should reside in P1 or P2 fixed physical address space.

Figure 5.1 shows the relationship between the vector base address, the vector offset, and the vector table.

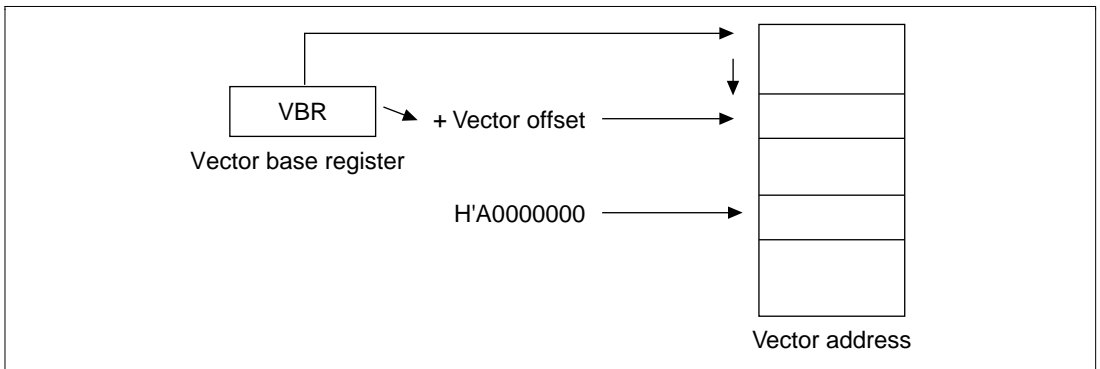


Figure 5.1 Vector Addresses

In table 5.2, exceptions and their vector addresses are listed by exception type, instruction completion status, relative acceptance priority, relative order of occurrence within an instruction execution sequence and vector address.

Table 5.2 Vectored Exception Events

Exception Type	Completion Status	Exception Event	Priority*¹	Exception Order	Vector Address	Vector Offset
Reset	Aborted	Power-on	1	—	H'A00000000	—
		Manual reset	1	—	H'A00000000	—
General exception events	Aborted and retried	Address error (instruction access)	2	1	—	H'00000100
		TLB miss (instruction access)	2	2	—	H'00000400
		TLB invalid (instruction access)	2	3	—	H'00000100
		TLB protection violation (instruction access)	2	4	—	H'00000100
		Reserved instruction code exception	2	5	—	H'00000100
		Illegal slot instruction exception	2	5	—	H'00000100
		Address error (data access)	2	6	—	H'00000100
		TLB miss (data access)	2	7	—	H'00000400
		TLB invalid (data access)	2	8	—	H'00000100
		TLB protection violation (data access)	2	9	—	H'00000100
		FPU exception	2	10	—	H'00000100
		Initial page write	2	10	—	H'00000100
	Completed	Unconditional trap (TRAPA instruction)	2	5	—	H'00000100
	User breakpoint trap	2	n* ²	—	H'00000100	

Table 5.2 Vectored Exception Events (cont)

Exception Type	Completion Status	Exception Event	Priority* ¹	Exception Order	Vector Address	Vector Offset
Interrupt requests	Completed	Nonmaskable interrupt	3	—	—	H'00000600
		External hardware interrupt	4* ³	—	—	H'00000600
		Peripheral module interrupt	4* ³	—	—	H'00000600

- Notes:
1. Priorities are indicated from high to low, 1 being highest and 4 being lowest.
 2. The user can define the break point traps. 1 is a break point before instruction execution and 11 is a break point after instruction execution. For an operand break point, use 11.
 3. Use software to specify relative priorities of external hardware interrupts and peripheral module interrupts.

5.2.3 Receiving Interrupt Causes

Processor resets and interrupts are asynchronous events unrelated to the instruction stream. All exception events are prioritized to establish an acceptance order whenever two or more exception events occur simultaneously. The power-on reset and manual reset may not occur simultaneously, so they have the same priority.

All general exception events occur in a relative order in the execution sequence of an instruction (i.e., execution order), but are handled at priority level 2 in instruction-stream order (i.e., program order). In other words, an exception detected in a preceding instruction is accepted prior to an exception detected in a subsequent instruction.

Three general exception events (reserved instruction code exception, unconditional trap, and illegal slot instruction exception) are detected in the decode stage of different instructions and are mutually exclusive events in the instruction pipeline. They have the same execution priority. Figure 5.2 shows the order of general exception acceptance sequence.

5.2.4 Exception Codes

Table 5.3 lists the exception codes written into bits 11–0 of the EXPEVT register (for reset or general exception events) or the INTEVT register (for general interrupt requests) to identify each specific exception event. An additional exception register, the TRAPA (TRA) register, is used to hold the 8-bit immediate data in an unconditional trap (TRAPA instruction).

Table 5.3 Exception Codes

Exception Type	Exception Event	Module	Factor	Exception Code
Reset	Power-on	—	—	H'000
	Manual reset	—	—	H'020
General exception events	TLB miss/invalid (load)	—	—	H'040
	TLB miss/invalid (store)	—	—	H'060
	Initial page write	—	—	H'080
	TLB protection violation (load)	—	—	H'0A0
	TLB protection violation (store)	—	—	H'0C0
	Address error (load)	—	—	H'0E0
	Address error (store)	—	—	H'100
	FPU exception	—	—	H'120
	Unconditional trap (TRAPA instruction)	—	—	H'160
	Reserved instruction code	—	—	H'180
	Illegal slot instruction	—	—	H'1A0
User breakpoint trap	—	—	H'1E0	
Interrupt requests	Nonmaskable interrupt	—	—	H'1C0
	External hardware interrupts	IRL3–IRL0 = 0000		H'200
		IRL3–IRL0 = 0001		H'220
		IRL3–IRL0 = 0010		H'240
		IRL3–IRL0 = 0011		H'260
		IRL3–IRL0 = 0100		H'280
		IRL3–IRL0 = 0101		H'2A0
		IRL3–IRL0 = 0110		H'2C0
		IRL3–IRL0 = 0111		H'2E0
		IRL3–IRL0 = 1000		H'300
IRL3–IRL0 = 1001			H'320	

Table 5.3 Exception Codes (cont)

Exception Type	Exception Event	Module	Factor	Exception Code
Interrupt requests (cont)	External hardware interrupts (cont)	IRL3–IRL0 = 1010		H'340
		IRL3–IRL0 = 1011		H'360
		IRL3–IRL0 = 1100		H'380
		IRL3–IRL0 = 1101		H'3A0
		IRL3–IRL0 = 1110		H'3C0
	Peripheral module interrupts	TMU0	TUNI0	H'400
		TMU1	TUNI1	H'420
		TMU2	TUNI2	H'440
			TICPI2	H'460
		RTC	ATI	H'480
			PRI	H'4A0
			CUI	H'4C0
		SCI	ERI	H'4E0
			RXI	H'500
			TXI	H'520
			TEI	H'540
		WDT	ITI	H'560
		REF	RCMI	H'580
			ROVI	H'5A0

Note: Exception codes H'140 and H'3E0 are reserved.

5.2.5 Exception Requests and BL Bits

Exceptions and interrupts are accepted when the SR register's BL bit is 0.

If a general exception occurs when the BL bit in SR is one, CPU internal registers go into the reset state; other module registers branch to the same address used for resets in a state where they hold the contents before the ordinary exception occurred (H'A0000000).

If an interrupt occurs when BL = 1, the request held pending and not accepted until the BL bit is cleared to a logic zero by software.

To enable overlapping exception processing to be accepted, SPC and SSR must be saved and the BL bit in SR cleared to zero.

5.2.6 Returning from Exception Processing

Use the RTE instruction to return from exception processing. The RTE instruction saves the PC to SPC and SR to SSR, branches to the SPC address, and returns from exception processing. If SPC and SSR were saved to external memory, call the RTE instruction after changing the SR.BL bit to 1 and returning them.

5.3 Register Description

There are three registers for exception processing. They are peripheral module registers, so they are located in the P4 area. They can only be accessed in privileged mode by specifying an address.

Exception Event Register (EXPEVT): Resides at H'FFFFFFD4. Composed of 12 bits of exception code. The exception code placed in EXPEVT is the exception code from resets and ordinary exception events. The exception code is set automatically by hardware when the exception occurs. EXPEVT can be changed from software.

Interrupt Event Register (INTEVT): Resides at H'FFFFFFD8. Composed of 12 bits of exception code. The exception code placed in INTEVT is the exception code from interrupt requests. The exception code is set automatically by hardware when the exception occurs. INTEVT can be changed from software.

TRAPA Exception Register (TRA): Resides at H'FFFFFFD0. Composed of the 8 bits of immediate data from the TRAPA instruction. TRA is set automatically by hardware when the TRAPA instruction is executed. TRA can be changed from software.

The bit configurations of the EXPEVT, INTEVT, and TRA registers are diagrammed in figure 5.3.

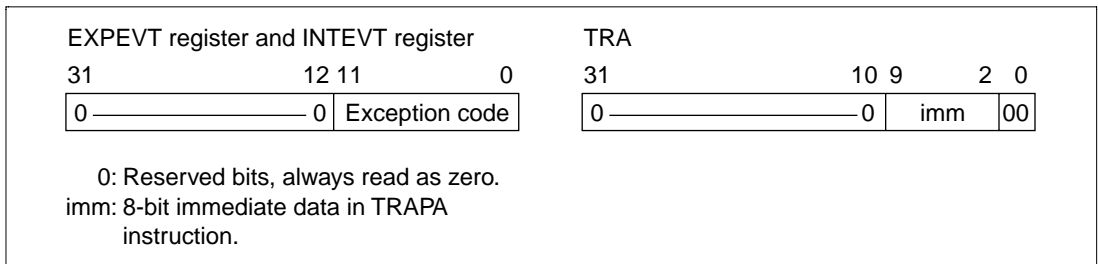


Figure 5.3 Bit Configurations of EXPEVT, INTEVT, and TRA Registers

5.4 Exception Handler Operation

5.4.1 Reset

The reset sequence is used to power up the SH7718R or restart it from the initialization state. The $\overline{\text{RESET}}$ signal is sampled every clock cycle, and if a power-on reset is asserted, the reset sequence is initiated immediately, canceling all current operations (except the RTC) and any pending events. For a manual reset, some processing for ensuring data in external memory continues. The $\overline{\text{BREQ}}$ (bus request) signal is used to distinguish between power-on reset (high-level input) and manual reset (low-level input). The reset sequence consists of the following operations:

1. The MD bit in SR is set to a logic one to place the SH7718R in privileged mode.
2. The BL bit in SR is set to a logic one, masking any subsequent exceptions.
3. The RB bit in SR is set to a logic one.
4. An encoded value of H'000 in a power-on reset or H'020 in a manual reset is written into bits 11–0 of the EXPEVT register to identify the exception event.
5. Instruction execution jumps to the user-written handler routine at address H'A0000000.

5.4.2 Interrupts

Interrupts are accepted at the completion of the current instruction. The interrupt acceptance sequence consists of the following operations:

1. The contents of the PC and SR are saved in SPC and SSR, respectively.
2. The BL bit in SR is set to a logic one, masking any subsequent exceptions.
3. The MD bit in SR is set to a logic one to place the SH7718R in privileged mode.
4. The RB bit in SR is set to a logic one.
5. An encoded value identifying the exception cause is written into bits 11–0 of the INTEVT register.
6. Instruction execution jumps to the vector location designated by the sum of the value of the contents of the vector base register (VBR) and H'00000600 to invoke the handler routine.

5.4.3 General Exceptions

When the SH7718R encounters any exception condition other than a reset or interrupt request, it executes the following operations:

1. The contents of the PC and SR are saved in SPC and SSR, respectively.
2. The BL bit in SR is set to a logic one, masking any subsequent exceptions.
3. The MD bit in SR is set to a logic one to place the SH7718R in privileged mode.
4. The RB bit in SR is set to a logic one.

5. An encoded value identifying the exception cause is written into bits 11–0 of the EXPEVT register.
6. Instruction execution jumps to the vector location designated by either the sum of the vector base address and offset H'00000400 in the vector table in a TLB miss trap, or by the sum of the vector base address and offset H'00000100 for exceptions other than TLB miss traps, to invoke the handler routine.

5.5 Individual Exception Operations

This section describes conditions when specific exception processing runs and the processor operations.

5.5.1 Resets

1. Power-On Resets

Conditions: $\overline{\text{BREQ}}$ pin high and $\overline{\text{RESET}}$ low

Operations: EXPEVT set to H'000, VBR and SR initialized, branch to PC = H'A0000000 occurs. Initialization sets the VBR register to H'00000000. In the SR, the MD, RB, and BL bits are set to 1 and the interrupt mask bits (I3-I0) are set to B'1111. The CPU and on-chip peripheral modules are initialized. For more information, see the register descriptions. Be sure to use a power-on reset when the power is turned on.

2. Manual Resets

Conditions: $\overline{\text{BREQ}}$ pin low and $\overline{\text{RESET}}$ low

Operations: EXPEVT set to H'020, VBR and SR initialized, branch to PC = H'A0000000 occurs. Initialization sets the VBR register to H'00000000. In the SR, the MD, RB, and BL bits are set to 1 and the IMASK field (I3-I0) is set to B'1111. The CPU and on-chip peripheral modules are initialized. For more information, see the register descriptions.

Table 5.4 Resets

Type	Transition Conditions for Reset State		Internal State	On-chip Peripheral Module
	$\overline{\text{BREQ}}$	$\overline{\text{RESET}}$	CPU	
Power-on reset	High	Low	Initialization	See register description in appropriate section
Manual reset	Low	Low	Initialization	

5.5.2 General Exceptions

1. TLB Miss

Conditions: Comparison of TLB addresses shows no address match

Operations: The virtual address (32 bits) that caused the exception is set to the TEA and the corresponding virtual page number (22 bits) is set to PTEH (31–10). The ASID of the PTEH indicates the ASID at the time the exception occurred. The RC bit of the MMUCR is incremented by one for replacement when all ways are valid or set with priority starting at Way 0 if any ways are not valid.

The PC and SR of the instruction that generated the exception are saved to the SPC and SSR, respectively. When the exception occurred during a read, H'040 is set to EXPEVT; when the exception occurred during a write, H'060 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $\text{PC} = \text{VBR} + \text{H}'0400$.

To speed up TLB miss processing, the offset differs from other exceptions.

2. TLB Invalid

Conditions: Comparison of TLB addresses shows address match but $V = 0$

Operations: The virtual address (32 bits) that caused the exception is set to the TEA and the corresponding virtual page number (22 bits) is set to PTEH (31–10). The ASID of the PTEH indicates the ASID at the time the exception occurred. The way that generated the exception is set to the RC bit of the MMUCR.

The PC and SR of the instruction that generated the exception are saved to the SPC and SSR, respectively. When the exception occurred during a read, H'040 is set to EXPEVT; when the exception occurred during a write, H'060 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $\text{PC} = \text{VBR} + \text{H}'0100$.

3. TLB Initial Write

Conditions: A hit occurred to the TLB for a store access, but $D = 0$
This occurs for initial writes to the page registered by the load.

Operations: The virtual address (32 bits) that caused the exception is set to the TEA and the corresponding virtual page number (22 bits) is set to PTEH (31–10). The ASID of the PTEH indicates the ASID at the time the exception occurred. The way that generated the exception is set to MMUCR.RC.

The PC and SR of the instruction that generated the exception are saved to the SPC and SSR, respectively. H'080 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$.

4. TLB Protection

Conditions: Table 5.5 lists the conditions when a hit access violates this TLB protection information (PR bits):

Table 5.5 TLB Protection Conditions

PR	Privileged Mode	User Mode
00	Only read enabled	No access
01	Read/write enabled	No access
10	Only read enabled	Only read enabled
11	Read/write enabled	Read/write enabled

Operations: The virtual address (32 bits) that caused the exception is set to the TEA and the corresponding virtual page number (22 bits) is set to PTEH (31–10). The ASID of the PTEH indicates the ASID at the time the exception occurred. The way that generated the exception is set to the RC bit of the MMUCR.

The PC and SR of the instruction that generated the exception are saved to the SPC and SSR, respectively. When the exception occurred during a read, H'0A0 is set to EXPEVT; when the exception occurred during a write, H'0C0 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$.

5. Address Error

Conditions:

- a. Instruction fetch from odd address ($4n + 1, 4n + 3$)
- b. Word data accessed from addresses other than word boundaries ($4n + 1, 4n + 3$)
- c. Longword accessed from addresses other than longword boundaries ($4n + 1, 4n + 2, 4n + 3$)
- d. Virtual space accessed in user mode in the area H'8000 0000 to H'FFFFFFF.

Operations: The virtual address (32 bits) that caused the exception is set to the TEA. The PC and SR of the instruction that generated the exception are saved to the SPC and SSR, respectively. When the exception occurred during a read, H'0E0 is set to EXPEVT; when the exception occurred during a write, H'100 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$. See 4.5.5, Processing When MMU Exception Occurs, in section 4, The MMU.

6. Unconditional Trap

Conditions: TRAPA instruction executed

Operations: The exception is a processing-completion type, so the PC of the instruction after the TRAPA instruction is saved to the SPC. The SR from the time when the TRAPA instruction was executing is saved to the SSR. The 8-bit immediate value in the TRAPA instruction is quadrupled and set to TRA(9–0). H'160 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$.

7. FPU Exception

Conditions: An FPU exception trap occurs when EV or EZ in the enable field of the FPSCR register is set. This indicates that a floating point computation instruction causes an invalid-operation or divide-by-zero exception as defined in IEEE 754. A floating point computation instruction is one of the following: FADD, FSUB, FMUL, FDIV, FMAC, FCMP/EQ, FCMP/GT, FNEG, FABS, FSQRT, or FTRC.

Operations: An FPU exception will only take place if the corresponding enable bit is set. When the FPU detects an exception cause, it aborts the FPU operation and signals the CPU that a trap is pending. The CPU saves the address of the offending FP opcode in the SPC register, and saves the current state of the SR register in the SSR register. The BL, MD, and RB bits of the SR register are set to 1 and the PC is set to $VBR + H'0120$.

If the FPU operation was in a delay slot, the saved PC (SPC) register will contain the address of the delayed branch instruction. The FPSCR sticky bits will always be updated whether or not an FPU exception was taken, and will remain set until explicitly cleared by user code. The FPSCR cause bits change as FP operations are executed.

Other exceptions defined in IEEE 754, that is, underflow, overflow, and inexact exceptions, are observed by the FPU but do not cause any exception. No other data transfer floating point instructions, such as FLOAT, cause FPU exceptions.

8. General Illegal Instruction

Conditions:

- a. When an undefined instruction not in a delay slot is decoded

Delay slot instructions are JMP, JSR, BRA, BRAF, BSR, BSRF, RTS, RTE, BT/S, and BF/S. Undefined instructions are H'FxxF.

- b. When a privileged instruction not in a delay slot is decoded in user mode

Privileged instructions are LDC, STC, RTE, LDTLB, and SLEEP. Instructions that access GBR with LDC/STC are not privileged instructions.

Operations: The PC and SR of the instruction that generated the exception are saved to the SPC and SSR, respectively. H'180 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$. When undefined code other than H'FxxF is decoded, operation cannot be guaranteed.

9. Illegal Slot Instruction

Conditions:

- a. When an undefined instruction in a delay slot is decoded

Delay slot instructions are JMP, JSR, BRA, BRAF, BSR, BSRF, RTS, RTE, BT/S, and BF/S. Undefined instructions are H'FxxF.

- b. When an instruction that rewrites a PC in a delay slot is decoded

Instructions that rewrite the PC: JMP, JSR, BRA, BRAF, BSR, BSRF, RTS, RTE, BT, BF, BT/S, BF/S, TRAPA, LDC Rm, SR, LDC.L, @Rm+, SR

- c. When a privileged instruction in a delay slot is decoded in user mode

Privileged instructions: LDC, STC, RTE, LDTLB, SLEEP; instructions that access GBR with LDC/STC are not privileged instructions

Operations: The PC of the previous delay branch instruction is saved to the SPC. The SR of the instruction that generated the exception is saved to the SSR. H'1A0 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$. When undefined code other than H'FxxF is decoded, operation cannot be guaranteed.

10. User Break Point Trap

Conditions: When a break condition set in the user break point controller is satisfied

Operations: When the after-execution break occurs, the PC of the instruction immediately after the instruction that set the break point is set to the SPC. If the before-execution break occurs, the PC of the instruction that set the break point is set to the SPC. The SR when the break occurs is set to the SSR. H'1E0 is set to EXPEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0100$. See section 8, User Break Controller, for more information.

5.5.3 Interrupts

1. NMI

Conditions: NMI pin edge detected

Operations: The PC and SR after the instruction that receives the interrupt are saved to the SPC and SSR, respectively. H'01C0 is set to INTEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $PC = VBR + H'0600$. This interrupt is not masked by SR.IMASK and received with top priority when the SR's BL bit is 0. When the BL bit is 1, the interrupt is masked. See section 7, Interrupt Controller, for more information.

2. IRL Pin Interrupts

Conditions: SR.IMASK is lower than the IRL3–IRL0 level and the SR's BL bit is 0. The interrupt is accepted at an instruction boundary.

Operations: The PC after the instruction that accepts the interrupt is saved to the SPC. The SR at the point the interrupt is accepted is saved to the SSR. The code corresponding to the IRL3 to IRL0 level is set to INTEVT. The corresponding code is shown in table 7.4, Interrupt Exception Vectors and Rankings. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $VBR + H'0600$. The received level is not set to SR.IMASK. See section 7, Interrupt Controller, for more information.

3. On-Chip Module Interrupts

Conditions: SR.IMASK is lower than the on-chip module (TMU, RTC, SCI, CPG, REF) interrupt level and the SR's BL bit is 0. The interrupt is accepted at an instruction boundary.

Operations: The PC after the instruction that accepts the interrupt is saved to the SPC. The SR at the point the interrupt is accepted is saved to the SSR. The code corresponding to the interrupt cause is set to INTEVT. The BL, MD, and RB bits of the SR are set to 1 and a branch occurs to $VBR + H'0600$. B'0000 to B'1111 are set to the interrupt priority level registers (IRPA, IRPB) within the interrupt controller. See section 7, Interrupt Controller, for more information.

5.6 Cautions

1. Return from Exception Processing

- a. Check the SR's BL bit with software. When the SPC and SSR have been saved to external memory, set the SR's BL bit to 1 before restoring them.
- b. Issue an RTE instruction. Set the SPC to the PC and the SSR to the SR with the RTE instruction, branch to the SPC address, and return from exception processing.

2. Operation when Exception or Interrupt Occurs While SR.BL = 1

a. Interrupt

Suppress reception until the BL bit of the SR is set to 0 by software. If there is a request and the reception conditions are satisfied, the interrupt is received after the execution of the instruction that sets the SR's BL bit to 0. During the sleep or standby mode, however, the interrupt will be received even when the SR's BL bit is 1.

b. Exception

No user break point trap will occur even when the break conditions are met. When one of the other exceptions occurs, it branches to the fixed address of the reset (H'A0000000). The EXPEVT, SPC, and SSR registers and the SR register's RB bit become undefined.

3. SPC when an Exception Occurs

The PC saved to the SPC when an exception occurs is as shown below.

a. Re-executing-Type Exceptions

The PC of the instruction that caused the exception is set to the SPC and re-executed after return from exception processing. When the exception occurred in a delay slot, however, the PC of the immediately prior delay branch instruction is set to the SPC. When the condition of a conditional delayed branch instruction is not met, the delayed slot PC is set to the SPC.

b. Completed-Type Exceptions and Interrupts

The PC of the instruction after the one that caused the exception is set to the SPC. When the exception occurs in a conditional delayed branch instruction, the PC at the end of the branch is set to the SPC. When the condition of a conditional delayed branch instruction is not met, the delayed slot PC is set to the SPC.

4. Initial Register Values after Reset

Undefined Registers:

R0_BANK0/BANK1–R7_BANK0/BANK1, R8–R15, GBR, SPC, SSR, MACH, MACL, PR

Initialized Registers:

VBR=H'00000000

SR.MD=1, SR.BL=1, SR.RB=1, SR.I3–I0=H'F, other SR bits are undefined

PC=H'A0000000

5. Do not create exceptions in the delay slots of RTE instructions. Operation cannot be guaranteed if they occur.

6. When the SR register's BL bit is 1, do not cause a TLB related exception or address error in an instruction that updates the SR register or the instruction after that with an LDC instruction. It will be considered a multiplexed exception and reset processing will start up.

Section 6 Cache

6.1 Overview

6.1.1 Features

The cache specifications are listed in table 6.1.

Table 6.1 Cache Specifications

Parameter	Specification
Capacity	Selectable: Normal mode: 8 kbytes RAM mode: 4-kbyte cache and 4-kbyte RAM
Structure	Instruction/data mixed, 4-way set associative (2-way set associative in RAM mode)
Line size	16 bytes
Number of entries	128 entries/way
Write system	P0, P1, P3, U0: Write-back/write-through, selectable
Replacement method	Least-recently-used (LRU) algorithm

6.1.2 Cache Structure

The cache mixes data and instructions and uses a 4-way set associative system. It is composed of four ways (banks), each of which is divided into an address section and a data section. Each of the address and data sections is divided into 128 entries. The data section of the entry is called a line. Each line is 16 bytes (4 bytes \times 4). The data capacity per way is 2 kbytes (16 bytes \times 128 entries), with a total of 8 kbytes in the cache as a whole (4 ways). Figure 6.1 shows the cache structure.

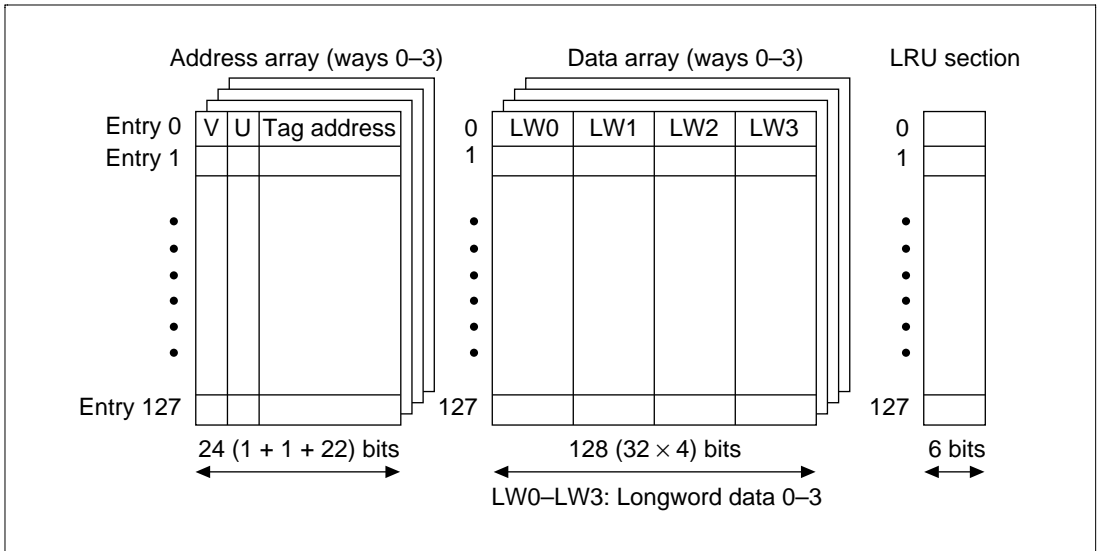


Figure 6.1 Cache Structure

Address Array: The V bit indicates whether the entry data is valid. When the V bit is 1, data is valid; when 0, data is not valid. The U bit indicates whether the entry has been written to in write-back mode. When the U bit is 1, the entry had been written to; when 0, it has not. The tag address holds the physical address used in the external memory access. It is composed of 22 bits (addresses 31–10) used for comparison during cache searches.

In the SH7718R, the top three bits of the 32-bit physical address are used as a shadow (see section 11, Bus State Controller), so 0 is usually entered in the top three bits of the tag address.

The V and U bits are initialized to 0 by a power-on reset but not by a manual reset. The tag address is not initialized by either reset.

Data Array: Holds a 16-byte instruction or data. Entries are registered in the cache in line units (16 bytes).

The data array is not initialized by either a power-on reset or manual reset.

LRU: With the 4-way set associative system, up to four instructions or data with the same entry address (addresses 10–4) can be registered in the cache. When an entry is registered, the LRU bits shows which of the four ways it is recorded in. There are six LRU bits; they are controlled by hardware. The least-recently-used (LRU) algorithm is used to select the way.

In normal mode, four ways are used as cache and six LRU bits indicate the way to be replaced (table 6.2). When a bit pattern other than those listed in table 6.2 is set to the LRU bits by software, the cache does not function correctly. When modifying the LRU bits by software, set one of the patterns listed in table 6.2.

In RAM mode, two ways are used as cache (way 0 and way 1). Bit 5 of the LRU bits indicates which way to be replaced. When bit 5 is equal to 0, way 1 is to be replaced. When bit 5 is equal to 0, way 0 is to be replaced.

The LRU bits are initialized to 0 by a power-on reset but are not initialized by a manual reset.

Table 6.2 LRU Bits and Way Replacement in Normal Mode

LRU Bits (5–0)	Way to be Replaced
000000, 000100, 010100, 100000, 110000, 110100	3
000001, 000011, 001011, 100001, 101001, 101011	2
000110, 000111, 001111, 010110, 011110, 011111	1
111000, 111001, 111011, 111100, 111110, 111111	0

6.1.3 Register Configuration

Table 6.3 lists the configuration of the cache control register.

Table 6.3 Register Configuration

Register	Abbr.	R/W	Size	Initial Value*	Address
Cache control register	CCR	R/W	Longword	H'00000000	H'FFFFFFEC

Note: Initialized by a power-on reset or manual reset.

6.2 Register Description

6.2.1 Cache Control Register (CCR)

The cache is enabled or disabled using the CE bit of the cache control register (CCR). The CCR also has an RA bit (indicates the cache operation mode, RAM mode or normal mode), a CF bit (invalidates all cache entries), and a WT bit (selects either write-through mode or write-back mode). Programs that change the contents of the CCR register should be placed in address space that is not cached. When updating the contents of the CCR register, always set bit 4 to 0. Figure 6.2 shows the configuration of the CCR register.

31										6	5	4	3	2	1	0
—	RA	0	CF	CB	WT	CE	

- RA: RAM bit. Indicates the cache operation mode.
 - 1 = 4 kbytes cache/4 kbytes cache (RAM mode)
 - 0 = 8 kbytes cache (normal mode)
- 0: Always set to 0 when setting the register.
- CF: Cache flush bit. Invalidates all cache entries. 1 = flush (clears the V, U, and LRU bits of all entries to 0).
 - Always reads 0. Write-back to external memory is not performed when the cache is flushed.
- : Reserved bits. Always read 0; and the write value should always be 0.
- CB: P1 area write-back/write-through switching bit
 - 1 = write-back mode, 0 = write-through mode
- WT: Write-through bit. Indicates the cache's operating mode for areas P0, U0, and P3.
 - 1 = write-through mode, 0 = write-back mode.
- CE: Cache enable bit. Indicates whether the cache function is used.
 - 1 = cache used, 0 = cache not used.

Figure 6.2 CCR Configuration

6.3 Cache Operation

6.3.1 Searching the Cache

If the cache is enabled, whenever instructions or data in memory are accessed, the cache will be searched to see if the desired instruction or data is in the cache. Figure 6.3 shows the method by which the cache is searched. The cache is a physical cache and holds physical addresses in its address section.

Entries are selected using bits 10–4 of the address (virtual) of the access to memory and the tag address of that entry is read. In parallel to tag address reading, the virtual address is translated to a physical address in the MMU. The physical address after translation and the physical address (tag address) read from the address are compared. The address comparison uses all four ways in normal mode. In RAM mode, two ways are used in the address comparison. When the comparison shows a match and the selected entry is valid ($V = 1$), a cache hit occurs. Otherwise, a cache miss occurs. Figure 6.3 shows a hit on way 1.

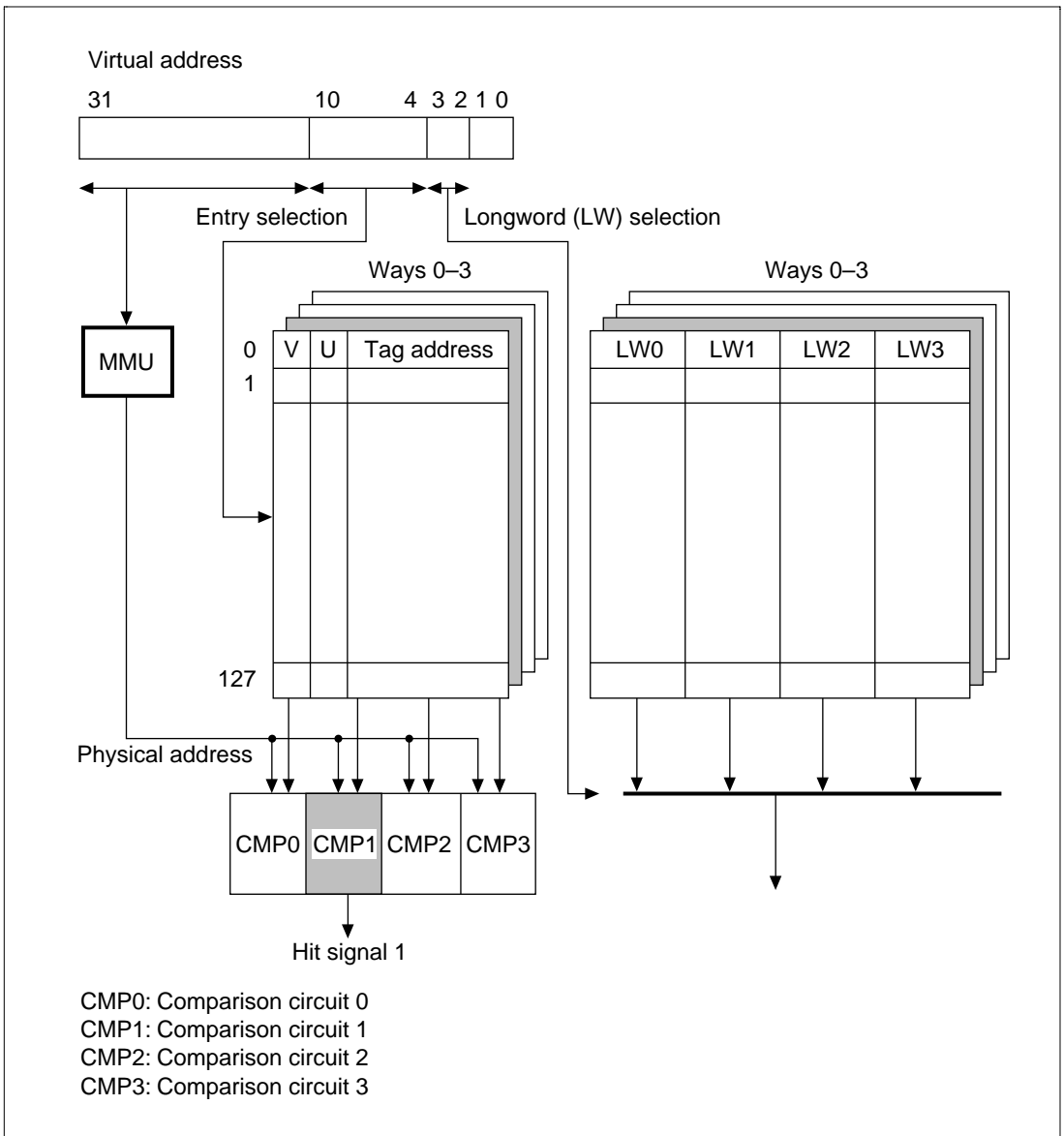


Figure 6.3 Cache Search Scheme (Normal Mode)

6.3.2 Read Access

Read Hit: In a read access, instructions and data are transferred from the cache to the CPU. The transfer unit is 32 bits. The LRU is updated.

Read Miss: The external bus cycle starts up and the entry is updated. The way replaced is the one least recently used. Entries are updated in 16-byte units. When the desired instruction or data is

loaded from external memory to the cache, the instruction or data is transferred to the CPU in parallel with being loaded to the cache. When it is loaded in the cache, the U bit is set to 0 and the V bit to 1. When the U bit of a replaced entry in the write-back mode is 1, the cache fill cycle starts after the entry is transferred to the write-back buffer. After the cache completes its fill cycle, the write-back buffer writes back the entry to memory. The write-back unit is 16 bytes.

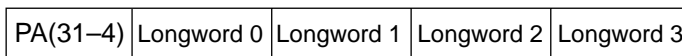
6.3.3 Write Access

Write Hit: In a write access in the write-back mode, data is written to the cache and the U bit of the entry written is set to 1. Writing occurs only to the cache; no write cycle is issued to external memory. In the write-through mode, data is written to the cache and a write cycle is issued to external memory.

Write Miss: In the write-back mode, an external bus cycle starts up when a write miss occurs and an entry with its U bit set to a logic one is replaced. The way to be replaced is the one least recently used. When the U bit of the entry to be replaced is 1, the cache fill cycle starts after the entry is transferred to the write-back buffer. The write-back unit is 16 bytes. Data is written to the cache and the U bit is set to 1. After the cache completes its fill cycle, the write-back buffer writes back the entry to memory. In the write-through mode, no write to cache occurs in a write miss; the write is only to external memory.

6.3.4 Write-Back Buffer

When the U bit of the entry to be replaced in the write-back mode is 1, it must be written back to external memory. To increase performance, the entry to be replaced is first transferred to the write-back buffer and fetching of new entries to the cache takes priority over writing back to external memory. After new entries are fetched to the cache, the write-back buffer is written back to external memory. During the write back cycles, the cache can be accessed. The write-back buffer can hold 1 line of cache data (16 bytes) and its physical address. Figure 6.4 shows the configuration of the write-back buffer.



PA(31–4): Physical address written to external memory.
 Longword 0–3: The line of cache data to be written to external memory.

Figure 6.4 Write-Back Buffer Configuration

6.3.5 Coherency of Cache and External Memory

Use software to ensure coherency between the cache and the external memory. When memory shared by the SH7718R and another device is accessed, the latest data may be in a write-back mode cache, so invalidate the entry that includes the latest data in the cache to generate a write back and update the data in memory before using it. When the caching area is updated by a device other than the SH7718R, invalidate the entry that includes the updated data in the cache.

6.3.6 RAM Mode

In RAM mode, way 0 and way 1 function as a 4 kbytes two-way set associative cache, while way 2 and way 3 function as a 4 kbytes internal RAM. Instructions and data can be placed in on-chip RAM and accessed in byte, word, or longword. The internal RAM is mapped from H'7F000000 to H'7F000FFF with 4 kbytes shadow areas from H'7F001000 to H'7FFFFFFF. In RAM mode with the MMU enabled, access of virtual addresses from H'7F000000 to H'7FFFFFFF access on-chip RAM without address translation. Physical addresses cannot be mapped to on-chip RAM after addresses are translated using the TLB. The internal RAM can be accessed in both privileged and user mode. Before changing the RA bit, all entries in the cache should be invalidated.

6.4 Memory-Mapped Cache

To allow software management of the cache, in the privileged mode, the cache contents can be read or written using the MOV instruction. The cache is mapped to virtual address space P4. The address array is mapped to addresses H'F0000000 to H'F0FFFFFFF and the data array to addresses H'F1000000 to H'F1FFFFFFF. Access size is fixed to longword for both the address and data array and instructions cannot be fetched.

6.4.1 Address Array

The address array is mapped from H'F0000000 to H'F0FFFFFFF. To access an address array, the 32-bit address section (for read/write) and 32-bit data section (for write) must be specified. The address section specifies information for selecting the entry to be accessed; the data section specifies the address, V bit, U bit, and LRU bits to be written to the address array (figure 6.5).

In the address section, specify the entry address for selecting the entry (bits 10–4), the W for selecting the way (bits 12–11), and H'F0 to indicate address array access (bits 31–24). 00 is way 0, 01 is way 1, 10 is way 2, 11 is way 3 in normal mode (8 kbytes cache); 00 and 10 are way 0, and 01 and 11 are way 1 in RAM mode.

When writing, specify bit 3 as the A bit. The A bit indicates whether addresses are compared during writing. When the A bit is 1, the addresses of the four entries selected by the entry addresses are compared to the addresses to be written into the address array specified in the data section. Writing takes place to the way that has a hit. The way number specified in bits 12–11 is

not used. When a miss occurs, nothing is written to the address array and no operation occurs. When the A bit is 0, it is written to the entry selected with the entry address and way number without comparing addresses.

An address specified in bits 31–10 (in the (1–2) data specification of figure 6.5, Address Array Access) is a virtual address. When the MMU is enabled, the address is translated into a physical address, then the physical address is used in comparing addresses when the A bit is equal to a logic one. The physical address is written into the address array.

When reading, the address tag, V bit, U bit, and LRU bits of the entry specified by the entry address and way number are read in the format of the data section in figure 6.5 without comparing addresses. To invalidate a specific entry, specify the entry by entry address and W and write 0 to its V bit. When the A bit is set to a logic one, only the hit entry will be invalidated. When an entry to be invalidated by its V bit being set to a logic zero has a U bit of 1, the entry is written back. This allows coherency to be achieved between the external memory and cache by invalidating the entry. When writing 0 to the V bit, be sure to also write 0 to the entry's U bit.

In the SH7718R, the top three bits of the 32-bit physical address are used as a shadow (see section 11, Bus State Controller), so when a cache miss occurs, 0 is registered in the top three bits of the tag address.

Do not set a value other than 0 to the top three bits of the tag address when changing the address array directly using the MOV instruction.

6.4.2 Data Array

The data array is mapped to H'F1000000 to H'F1FFFFFF. To access a data array, the 32-bit address section (for read/write) and 32-bit data section (for write) must be specified. The address section specifies information for selecting the entry to be accessed; the data section specifies the longword data to be written to the data array (figure 6.5).

In the address section, specify the entry address for selecting the entry (bits 10–4), the L for indicating the longword position within the (16 byte) line (bits 3–2: 00 is longword 0, 01 is longword 1, 10 is longword 2, 11 is longword 3), the W for selecting the way (bits 12–11: 00 is way 0, 01 is way 1, 10 is way 2, 11 is way 3 in normal mode; 00 and 10 are way 0, and 01 and 11 are way 1 in RAM mode), and H'F1 to indicate data array access (bits 31–24).

Both reading and writing use the longword of the data array specified by the entry address, way number and longword address. The access size of the data array is fixed at longword.

Address array access

Address line

Read access

31	24	23	13	12	11	10	4	3	0	
1111 0000			* *		W		Entry		* * * *	

Write access

31	24	23	13	12	11	10	4	3	2	0	
1111 0000			* *		W		Entry		A	* * *	

Data line (both read and write)

31	10	9	4	3	2	1	0		
Tag address (31–10)				LRU		X	X	U	V

Data array access (both read and write)

Address line

31	24	23	13	12	11	10	4	3	2	1	0
1111 0001			* *		W		Entry		L		* *

Data line

31	0
Longword	

X: 0 for read, don't care bit for write

*: Don't care bit

Figure 6.5 Specifying Address and Data for Memory-Mapped Cache Access

6.4.3 Examples

Invalidating Specific Entries: Specific cache entries can be invalidated by writing 0 to the entry's V bit. When the A bit is 1, the tag address specified by the write data is compared to the tag address within the cache selected by the entry address, and data is written when a match is found. If no match is found, there is no operation. R0 specifies the write data in R0 and R1 specifies the address. When the V bit of an entry in the address array is set to 0, the entry is written back if the entry's U bit is 1.

```
;R0=H'01100010; VPN=B'0000 0001 0001 0000 0000 00, U=0, V=0
;R1=H'F0000088; address array access, entry=B'0001000, A=1
;
MOV.L R0,@R1
```

Reading the Data of a Specific Entry: This example reads the data section of a specific cache entry. The longword indicated in the data section of the data array in figure 6.5 is read to the register. R0 specifies the address and R1 is read.

```
;R1=H'F100 004C; data array access, entry=B'0000100
;Way=0, longword address = 3
;
MOV.L @R0,R1 ;longword 3 is read.
```

Section 7 Interrupt Controller (INTC)

7.1 Overview

The interrupt controller (INTC) ascertains the priority of interrupt causes and controls interrupt requests to the CPU. The INTC registers set the order of priority of each interrupt, allowing the user to process interrupt requests according to the user-set priority.

7.1.1 Features

INTC has the following features:

- Fifteen levels of interrupt priority: By setting the two interrupt-priority registers, the priorities of on-chip peripheral module interrupts can be selected from 15 levels for different request sources.
- NMI noise canceling function: The NMI input-level bit indicates the NMI pin status. By reading this bit in the interrupt exception service routine, the pin status can be checked, enabling it to cancel noise.
- External device interrupt notification ($\overline{\text{IRQOUT}}$): For example, when the SH7718R has released the bus right, the external bus master can be notified that an external interrupt, an on-chip peripheral module interrupt, or a memory refresh request has occurred, enabling the SH7718R to request the bus right.

7.1.2 Block Diagram

Figure 7.1 is a block diagram of the INTC.

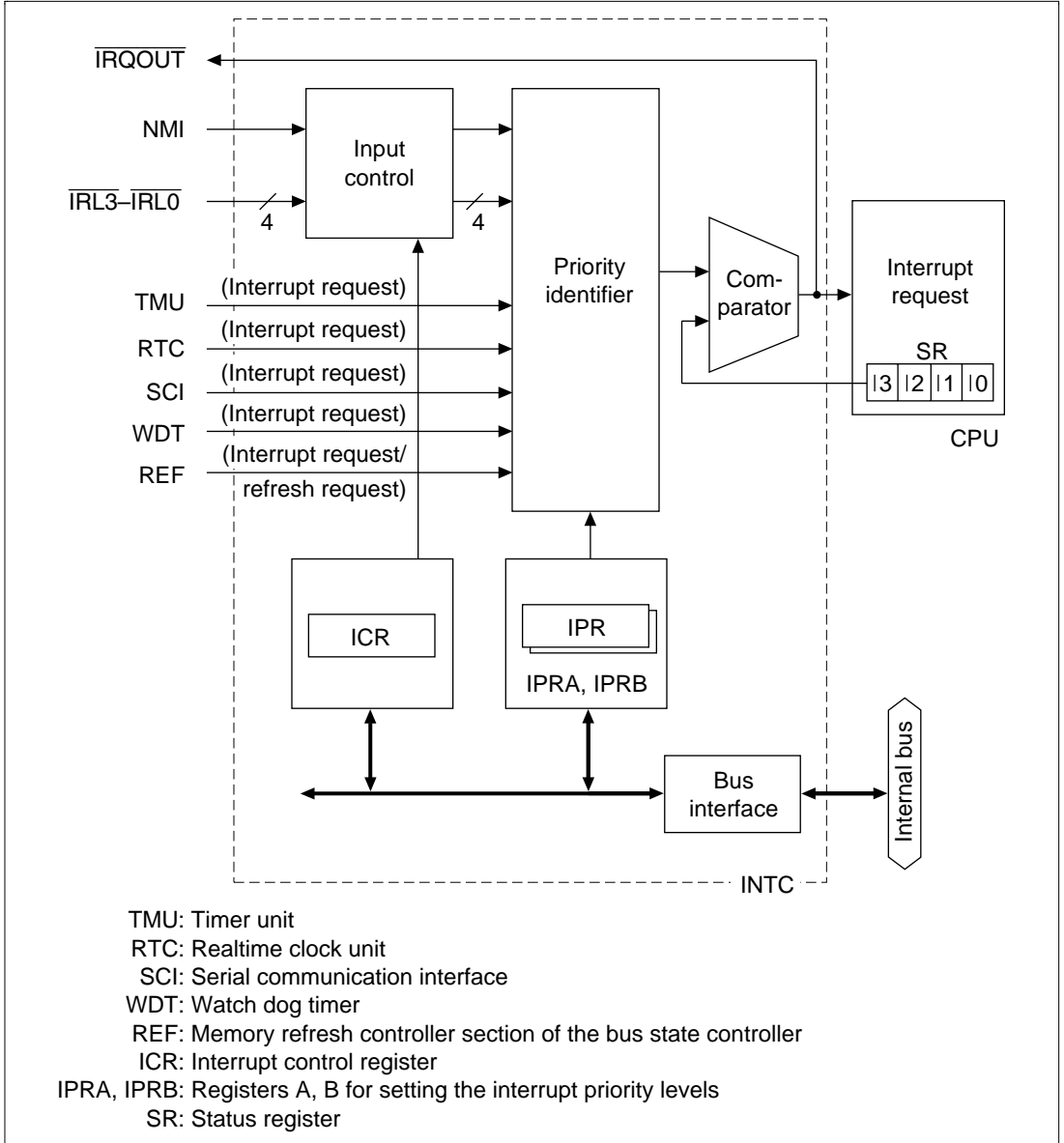


Figure 7.1 INTC Block Diagram

7.1.3 Pin Configuration

Table 7.1 lists the INTC pin configuration.

Table 7.1 Pin Configuration

Name	Abbreviation	I/O	Description
Nonmaskable interrupt input pin	NMI	I	Input of nonmaskable interrupt request signal
Interrupt input pins	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$	I	Input of interrupt request signals, which is maskable by SR.I3–I0
Bus request output pin	$\overline{\text{IRQOUT}}$	O	Output of signal that notifies external devices that an interrupt cause or memory refresh has occurred

7.1.4 Register Configuration

The INTC has the three registers listed in table 7.2.

Table 7.2 Register Configuration

Name	Abbr.	R/W	Initial Value* ¹	Address	Access Size
Interrupt control register	ICR	R/W	* ²	H'FFFFFFE0	16
Interrupt priority setting register A	IPRA	R/W	H'0000	H'FFFFFFE2	16
Interrupt priority setting register B	IPRB	R/W	H'0000	H'FFFFFFE4	16

Notes: 1. Initialized by a power-on reset or manual reset.
2. H'8000 when the NMI pin is at high level. H'0000 when the NMI pin is at low level.

7.2 Interrupt Causes

There are three types of interrupt causes: NMI, IRL, and on-chip peripheral modules. Each interrupt has priority levels (0–16) with 1 the lowest and 16 the highest. Priority level 0 masks an interrupt so its requests are ignored.

7.2.1 NMI Interrupts

The NMI interrupt has the highest priority level of 16. It is always accepted unless the BL bit of the status register in the CPU is set to 1. In sleep or standby mode, the interrupt is accepted regardless of the BL. Input from the NMI pin is edge-detected. The NMI edge select bit (NMIE) in the interrupt control register (ICR) is used to select either the rising or falling edge. When the NMIE bit of the ICR register is changed, the NMI detection flag is cleared to avoid a false detection of the NMI interrupt. For this reason, the NMI interrupt is not detected for up to 20 cycles after changing the ICR.NMIE bit. NMI interrupt exception processing does not affect the interrupt mask level bits (I3–I0) in the status register (SR).

7.2.2 IRL Interrupts

IRL interrupts are entered as levels through the $\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$ pins.

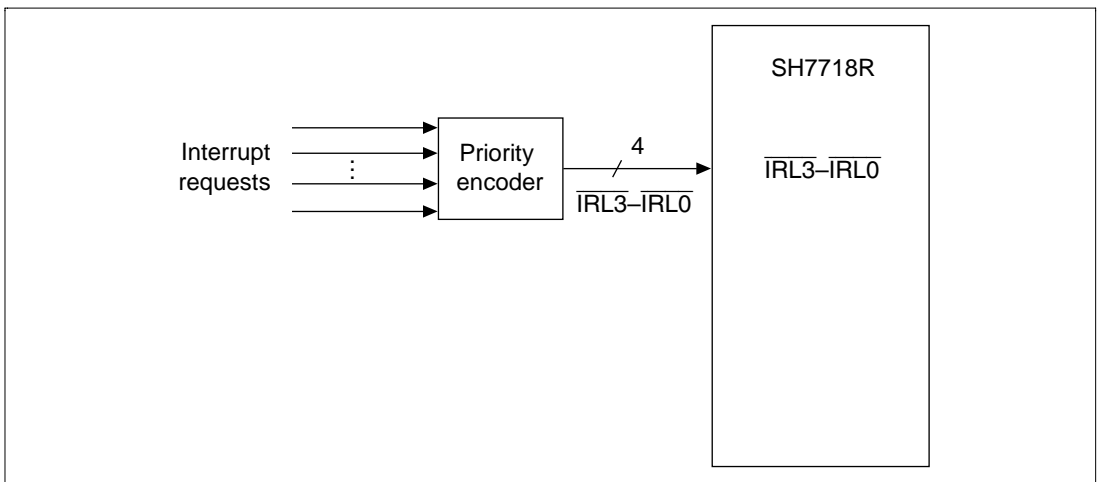


Figure 7.2 Example of IRL Interrupt Connections

Priorities are input as levels through pins $\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$. $\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$ level 0 (0000) is the highest priority interrupt request (level 15); 15 (1111) indicates there is no interrupt request (level 0).

Table 7.3 **IRL3–IRL0 Terminals and Interrupt Levels**

IRL3	IRL2	IRL1	IRL0	Interrupt Level	Remarks
0	0	0	0	15	Level 15 interrupt request
0	0	0	1	14	Level 14 interrupt request
0	0	1	0	13	Level 13 interrupt request
0	0	1	1	12	Level 12 interrupt request
0	1	0	0	11	Level 11 interrupt request
0	1	0	1	10	Level 10 interrupt request
0	1	1	0	9	Level 9 interrupt request
0	1	1	1	8	Level 8 interrupt request
1	0	0	0	7	Level 7 interrupt request
1	0	0	1	6	Level 6 interrupt request
1	0	1	0	5	Level 5 interrupt request
1	0	1	1	4	Level 4 interrupt request
1	1	0	0	3	Level 3 interrupt request
1	1	0	1	2	Level 2 interrupt request
1	1	1	0	1	Level 1 interrupt request
1	1	1	1	0	No interrupt request

IRL interrupt detection has a built-in noise canceler utility. Levels are sampled at every peripheral module cycle. If they remain unchanged for two cycles, noise canceling starts. This prevents the wrong level from being fetched when the IRL pin changes. During standby mode, the peripheral module clock is stopped, so the 32.768 kHz clock for the RTC is used instead for noise canceling. When the RTC is not used, therefore, IRL interrupts cannot be used in standby mode.

The priority level of the IRL interrupt must not be lowered until the interrupt is accepted and the interrupt processing starts. The priority level can be changed to a higher one at any time.

The interrupt mask bits (I3–I0) of the status register (SR) are not affected by IRL interrupt processing.

7.2.3 On-Chip Peripheral Module Interrupts

On-chip peripheral module interrupts are generated by the following five modules:

- Timer unit (TMU)
- Real-time clock (RTC)
- Serial communication interface (SCI)

- Bus state controller (BSC)
- Watchdog timer (WDT)

Not every interrupt cause is assigned a different interrupt vector. Sources are reflected on the interrupt event register (INTEVT). It is easy to identify sources by using the values of the INTEVT register as branch offsets (in the exception service routine).

The priority level (from 0–15) can be set for each module by writing to the interrupt priority setting registers A–B (IPRA–IPRB).

The interrupt mask bits (I3–I0) of the status register are not affected by the on-chip peripheral module interrupt processing.

Update the interrupt cause flag and interrupt enable flag of the on-chip peripheral modules when the BL bit of the SR is set to 1.

To avoid accepting the wrong interrupt because an interrupt cause that should have been updated was not, read the on-chip peripheral module that includes the flag, then set the BL bit to 0. This ensures the necessary timing internally.

To update multiple flags, simply read the register that includes the flags after the last flag is updated.

To update a flag while the BL bit is 0, jump to an interrupt processing routine with an INTEVT register value of 0. This starts up interrupt processing along timing that recognizes the relationship between flag updating and the interrupt request within the SH7718R. In such cases, execute the RTE instruction to continue processing thereafter.

7.2.4 Interrupt Exception Processing and Priority

Table 7.4 lists the codes for the interrupt event register (INTEVT) and interrupt causes, and the order of interrupt priority. Each interrupt cause is assigned a unique INTEVT code. The start address of the interrupt service routine is common to each interrupt cause. This is why, for instance, the value of INTEVT is used as offset at the start of the interrupt service routine and branched to identify the interrupt cause.

The order of priority of the on-chip peripheral module is set within the priority levels 0–15 at will by using the interrupt priority level set in registers A and B (IPRA, IPRB). The order of priority of the on-chip peripheral module is set to zero by RESET.

When the order of priorities for multiple interrupt causes are set to the same level and such interrupts are generated at the same time, they are processed according to the default order listed in table 7.4.

Update interrupt priority setting registers A and B with the BL bit of the status register (SR) at 1. To prevent interrupts from being accepted by mistake, read the interrupt priority setting register and then set the BL bit to 0. This preserves the required internal timing.

Table 7.4 Interrupt Exception Vectors and Rankings

Interrupt Cause	INTEVT Code	Interrupt Priority (Initial Value)	IPR (Bit Numbers)	Priority within IPR Setting Unit	Default Priority
NMI	H'1C0	16	—	—	High
IRL	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0000$	H'200	15	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0001$	H'220	14	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0010$	H'240	13	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0011$	H'260	12	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0100$	H'280	11	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0101$	H'2A0	10	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0110$	H'2C0	9	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 0111$	H'2E0	8	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1000$	H'300	7	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1001$	H'320	6	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1010$	H'340	5	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1011$	H'360	4	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1100$	H'380	3	—	—
	$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1101$	H'3A0	2	—	—
$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}} = 1110$	H'3C0	1	—	—	
TMU0 TUNI0	H'400	0–15 (0)	IPRA (15–12)	—	
TMU1 TUNI1	H'420		IPRA (11–8)	—	
TMU2	TUNI2	H'440	IPRA (7–4)	High	
	TICPI2	H'460		Low	Low

Table 7.4 Interrupt Exception Vectors and Rankings (cont)

Interrupt Cause		INTEVT Code	Interrupt Priority (Initial Value)	IPR (Bit Numbers)	Priority within IPR Setting Unit	Default Priority
RTC	ATI	H'480	0–15 (0)	IPRA (3–0)	High	High
	PRI	H'4A0				
	CUI	H'4C0				
SCI	ERI	H'4E0		IPRB (7–4)	High	
	RXI	H'500				
	TXI	H'520				
	TEI	H'540				
WDT	ITI	H'560		IPRB (15–12)	—	
REF	RCMI	H'580		IPRB (11–8)	High	
	ROVI	H'5A0			Low	Low

Notes: TUNI0–TUNI2: Under flow interrupts
TICPI2: Input capture interrupt
ATI: Alarm interrupt
PRI: Periodic interrupt
CUI: Carry-up interrupt
ERI: Receive error interrupt
RXI: Receive-data-full interrupt
TXI: Transmit-data-empty interrupt
TEI: Transmit-data-end interrupt
ITI: Interval timer interrupt
RCMI: Compare match interrupt
ROVI: Refresh counter overflow interrupt

7.3 Register Descriptions

7.3.1 Interrupt Priority Registers A and B (IPRA, IPRB)

Interrupt priority registers A and B (IPRA and IPRB) are 16-bit read/write registers that set priority levels from 0 to 15 for on-chip peripheral module interrupts. A reset initializes IPRA to IPRB to H'0000. They are not initialized in the standby mode.

Bit:	15	14	13	12	11	10	9	8
Bit name:								
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 7.5 lists the relationship between the interrupt causes and the IPRA and IPRB bits.

Table 7.5 Interrupt Request Sources and IPRA, IPRB

Register	Bits 15 to 12	Bits 11 to 8	Bits 7 to 4	Bits 3 to 0
IPRA	TMU0	TMU1	TMU2	RTC
IPRB	WDT	REF* ¹	SCI	Reserved * ²

Notes: 1. REF is the memory refresh control unit in the bus state controller. See section 11, Bus State Controller, for details.

2. Reserved bits: Always read as 0. The write value should always be 0.

As listed in table 7.5, four sets of on-chip peripheral modules are assigned to each register. 4-bit groups (bits 15 to 12, bits 11 to 8, bits 7 to 4, and bits 3 to 0) are set with values from H'0 (0000) to H'F (1111). Setting H'0 means priority level 0 (masking is requested); H'F is priority level 15 (the highest level). A reset initializes IPRA–IPRB to H'0000.

7.3.2 Interrupt Control Register (ICR)

The ICR is a 16-bit register that sets the input signal detection mode of the external interrupt input pin NMI and indicates the input signal level to the NMI pin. The ICR is initialized by a power-on reset or manual reset. It is not initialized in the standby mode.

Bit:	15	14	13	12	11	10	9	8
Bit name:	NMIL	—	—	—	—	—	—	NMIE
Initial value:	0/1*	0	0	0	0	0	0	0
R/W:	R/W	R	R	R	R	R	R	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	—	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R

Note: When NMI input is high: 1; when NMI input is low: 0.

Bit 15—NMI Input Level (NMIL): Sets the level of the signal input at the NMI pin. This bit can be read to determine the NMI pin level. This bit cannot be modified.

Bit 15: NMIL	Description
0	NMI input level is low
1	NMI input level is high

Bit 8—NMI Edge Select (NMIE): Selects whether the falling or rising edge of the interrupt request signal to the NMI is detected.

Bit 8: NMIE	Description
0	Interrupt request is detected on the falling edge of NMI input (initial value)
1	Interrupt request is detected on rising edge of NMI input

Bits 14–9 and 7–0—Reserved: Always read as 0. The write value should always be 0.

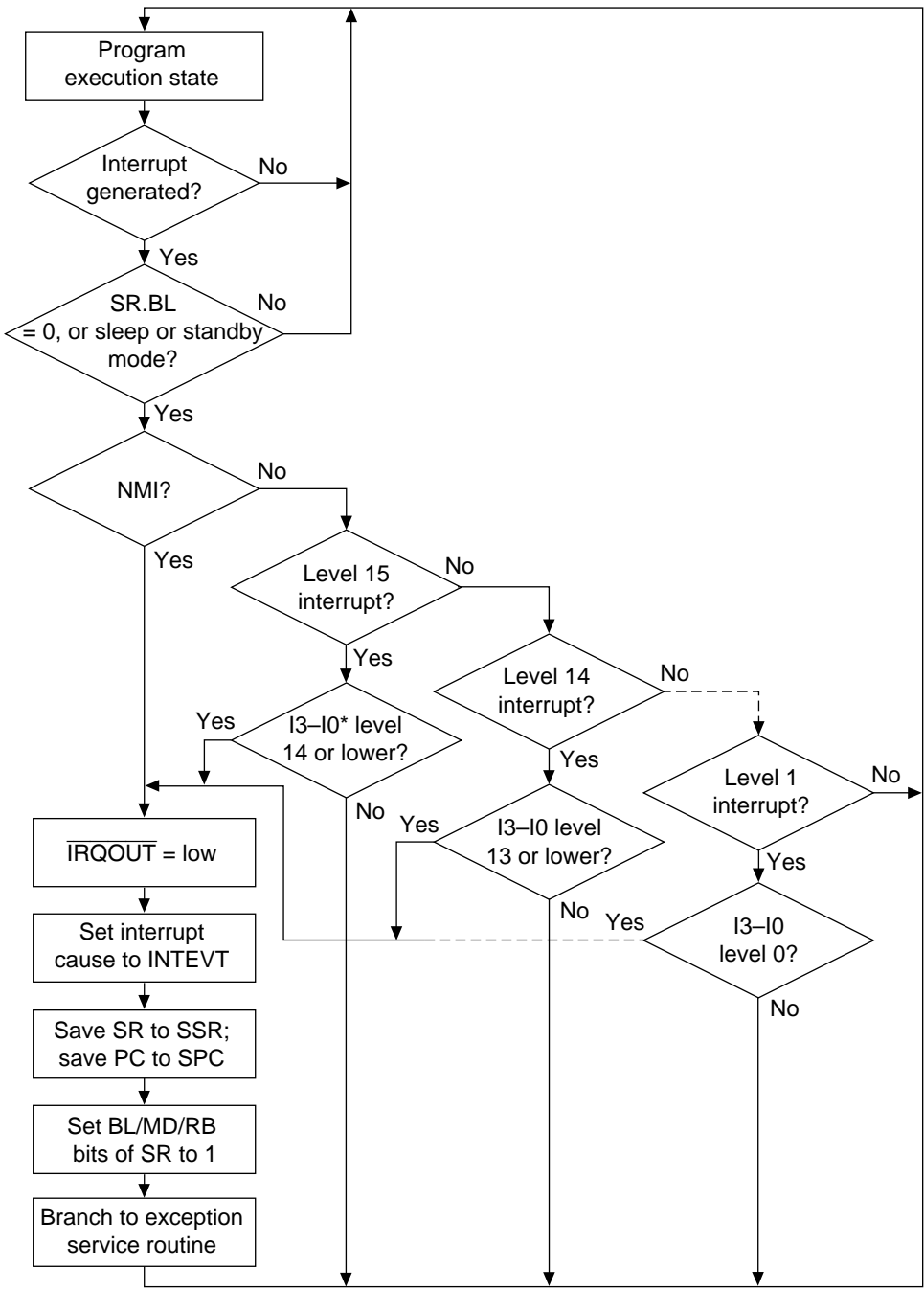
7.4 Operation

7.4.1 Interrupt Sequence

The sequence of interrupt operations is explained below. Figure 7.3 is a flowchart of the operations.

1. The interrupt request sources send interrupt request signals to the interrupt controller.
2. The interrupt controller selects the highest priority interrupt from the interrupt requests sent, following the priority levels set in interrupt priority registers A and B (IPRA and IPRB). Lower priority interrupts are held pending. If two of these interrupts have the same priority level or if multiple interrupts occur within a single module, the interrupt with the highest default priority or the highest priority (as indicated in table 7.4) is selected.
3. The priority level of the interrupt selected by the interrupt controller is compared with the interrupt mask bit (I3–I0) of the status register (SR) of the CPU. If the request priority level is higher than the level in bits I3–I0, the interrupt controller accepts the interrupt and sends an interrupt request signal to the CPU. The $\overline{\text{IRQOUT}}$ pin outputs low.
4. The CPU receives interrupts at breaks in instructions.
5. The interrupt cause code is set to the interrupt event register (INTEVT).
6. The status register (SR) and program counter (PC) are saved to SSR and SPC, respectively.
7. The block bit (BL), mode bit (MD), and register bank bit (RB) in the SR are set to 1.
8. The CPU jumps to the leading address of the interrupt service routine (the sum of H'00000600 and the value set in the vector base register (VBR)). This jump is not a delay branch. The interrupt service routine may branch with the INTEVT register value as its offset in order to identify the interrupt cause. This enables it to branch to the processing routine for the individual interrupt cause.

- Notes:
1. The interrupt mask bits I3–I0 in the status register (SR) are not changed by the acceptance of an interrupt in the SH7718R.
 2. $\overline{\text{IRQOUT}}$ outputs at low level until the interrupt request is cleared. When masking an interrupt cause with the interrupt mask bit, however, the $\overline{\text{IRQOUT}}$ pin returns to high. Output ignores the BL bit.
 3. The interrupt cause flag should be cleared in the interrupt handler. To prevent an interrupt cause that should have been cleared from being re-accepted by mistake, read the cause flag after clearing, wait the length of time stated as the priority evaluation and SR mask bit comparison time in table 7.6, then either clear the BL bit or run an RTE instruction.



Note: I3-I0: interrupt mask bits of status register (SR)

Figure 7.3 Interrupt Operation Flowchart

7.4.2 Multiple Interrupts

When handling multiple interrupts, an interrupt handler should include the following procedures:

1. Branch to a specific interrupt handler corresponding to an interrupt cause with the code in the INTEVT used as a branch-offset for branching to the specific handler.
2. Clear the cause of the interrupt in each specific handler.
3. Save the SSR and SPC to memory.
4. Clear the BL bit of the SR, and set the accepted interrupt level to the IMASK of the SR.
5. Handle the interrupt.
6. Execute the RTC to complete the handler.

When these procedures are followed in order, an interrupt of higher priority than the one being handled can be accepted after clearing the BL in step 4. This shortens interrupt response time for more urgent processing.

7.5 Interrupt Response

Table 7.6 shows the time from the occurrence of an interrupt request to interrupt exception processing and the start of the fetch of the starting instruction of the exception service routine (the interrupt response time).

Figure 7.4 shows the pipeline operation when an IRL interrupt is accepted. When the SR.BL bit is 1, interrupt exception processing is masked and waits until an instruction that sets the BL bit to 0 is completed.

Table 7.6 Interrupt Response Time

Item	Number of Cycles			Comments	
	NMI	IRL	Peripheral Module		
Priority evaluation and SR mask bit comparison time	0.5 × I _{cy} c +0.5 × B _{cy} c +0.5 × P _{cy} c	0.5 × I _{cy} c +0.5 × B _{cy} c +2 × P _{cy} c	0.5 × I _{cy} c +1.5 × P _{cy} c		
Time to wait till end of sequence CPU is executing	x (≥0) × I _{cy} c			The interrupt exception processing waits until the executing instruction ends. If the number of instruction execution cycles is S ^{*1} , the longest wait time is X = S – 1. When BL is set to 1 by instruction execution or an exception, however, it waits until an instruction that sets BL to 0 ends. When an instruction that masks interrupt exception processing follows, it may wait longer.	
Time from interrupt exception processing (saving of SR and PC) to start of fetch of starting instruction in exception service routine	5 × I _{cy} c				
Response time	Total	(5.5 + x) × I _{cy} c + 0.5 × B _{cy} c + 0.5 × P _{cy} c	(5.5 + x) × I _{cy} c + 0.5 × B _{cy} c + 2 × P _{cy} c	(5.5 + x) × I _{cy} c + 1.5 × P _{cy} c	
	Min ^{*2}	6.5	8	7	At 60 MHz: 0.10–0.14 μs
	Max ^{*3}	7 + S	13 + S	10.5 + S	At 60 MHz: 0.23–0.34 μs (when operand is cache hit) At 60 MHz: 0.27–0.37 μs (when external memory access has a wait = 0)

Notes: 1. Abbreviations: I_{cy}c: Time for 1 cycle of internal clock supplied to CPU, etc.
 B_{cy}c: Time for 1 CKIO cycle
 P_{cy}c: Time for 1 cycle of peripheral clock supplied to peripheral modules

2. S includes memory access waiting time. The process that takes the longest is LDC.L @Rm+,SR, which takes 7 instruction execution cycles when the memory access hits the cache. When an external access is performed, those cycles must be added on. Some instructions access external memory twice, so when external memory access is slow, the number of instruction execution cycles increases accordingly.
3. The Internal clock: CKIO: Peripheral clock ratio is 1:1:1.
4. The Internal clock: CKIO: Peripheral clock ratio is 1:1:1/4.

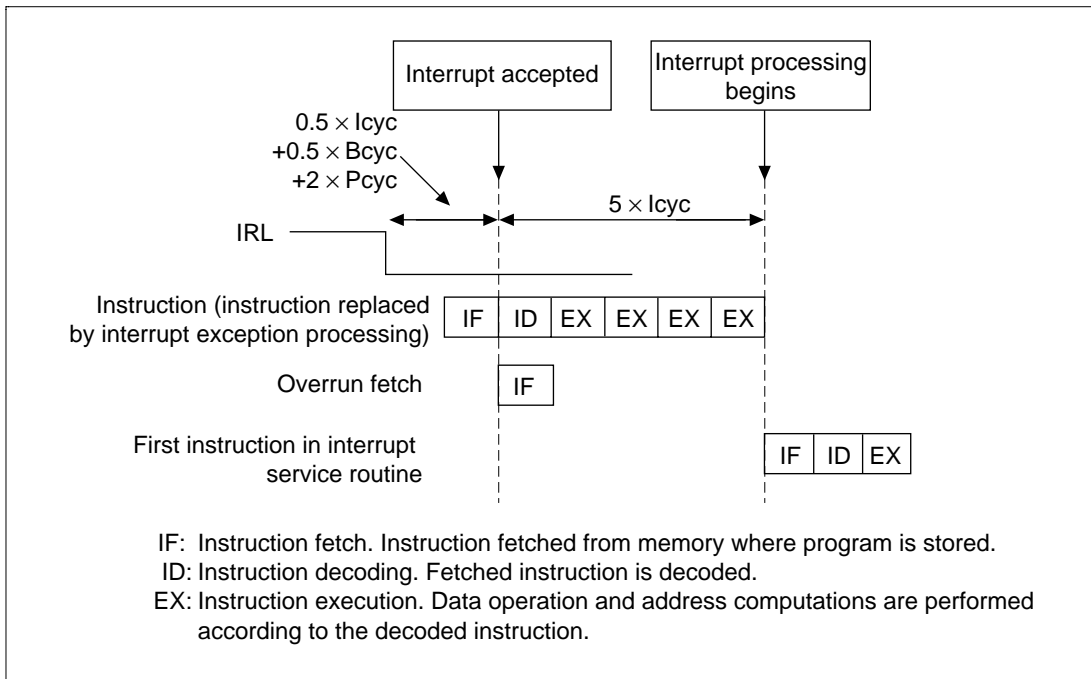


Figure 7.4 Example of Pipeline Operation when IRL Interrupt Is Accepted

Section 8 User Break Controller (UBC)

8.1 Overview

The user break controller (UBC) provides functions that simplify program debugging. This function makes it easy to design a self-monitoring debugger, enabling the chip to debug programs simply without using an in-circuit emulator. The break conditions that can be set in the UBC are instruction fetch data, read/write, data size, data content, address value, and halt timing at time of instruction fetch.

8.1.1 Features

The features of the user break controller are listed below.

- Two break channels (channel A, channel B). User break interrupts can be requested using either independent or sequential condition for the two channels (sequential breaks are channel A, then channel B).
- The following break compare conditions can be selected and set:
 - Address (select what will be compared to the 32-bit virtual address and ASID)
 - Address: Compare all bits, mask bottom 10 bits, mask bottom 12 bits, mask all bits
 - ASID: Compare all bits, mask all bits
 - Data (channel B only, 32 bits maskable)
 - Bus cycle: Instruction fetch/data access
 - Read or write
 - Operand size: byte/word/longword
- Select either to break in the instruction fetch cycle before the instruction is executed or after.
- User break trap generated upon satisfying break conditions. A user-designed user break interrupt exception processing routine can be run.

8.1.2 Block Diagram

Figure 8.1 shows the block diagram of the user break controller.

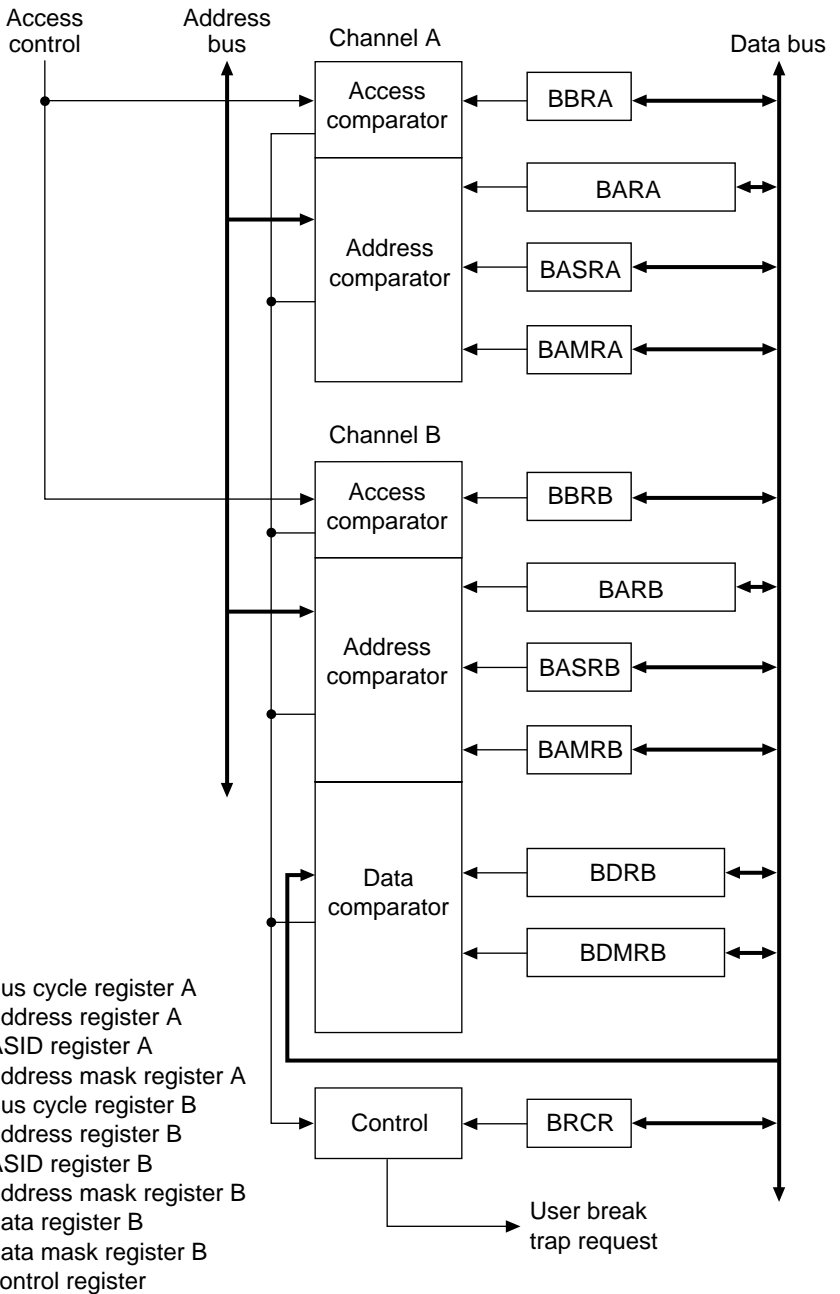


Figure 8.1 Block Diagram of User Breakpoint Controller

8.1.3 Register Set

Table 8.1 shows the register set for the user break controller.

Table 8.1 UBC Register Set

Channel	Register	Abbr.	R/W	Initial Value* ¹	Access Size	Access Address
A	Break address register A	BARA	R/W	Undefined	Longword	H'FFFFFFB0
	Break ASID register A	BASRA	R/W	Undefined	Byte	H'FFFFFFE4
	Break address mask register A	BAMRA	R/W	Undefined	Byte	H'FFFFFFB4
	Break bus cycle register A	BBRA	R/W	H'0000* ²	Word	H'FFFFFFB8
B	Break address register B	BARB	R/W	Undefined	Longword	H'FFFFFFA0
	Break address mask register B	BAMRB	R/W	Undefined	Byte	H'FFFFFFA4
	Break ASID register B	BASRB	R/W	Undefined	Byte	H'FFFFFFE8
	Break bus cycle register B	BBRB	R/W	H'0000* ²	Word	H'FFFFFFA8
	Break data register B	BDRB	R/W	Undefined	Longword	H'FFFFFF90
	Break data mask register B	BDMRB	R/W	Undefined	Longword	H'FFFFFF94
Both	Break control register	BRCR	R/W	H'0000* ²	Word	H'FFFFFF98

- Notes: 1. Holds values during standby.
2. Initialized by power-on reset or manual reset.

8.1.4 Setting Break Conditions and Registers

Break conditions and register settings are related as follows:

1. Channel A or B and the respective break conditions are set in registers.
2. Addresses are set in BARA and BARB. ASIDs are set in the BASRA and BASRB registers. The BAMA and BAMB bits of the BAMRA and BAMRB registers set whether to include addresses in the break conditions or whether to mask them. To include ASIDs in the conditions, set the BASMA and BASMB bits of the BAMRA and BAMRB registers.
3. The bus cycle break conditions are set in the BBRA and BBRB registers. Instruction fetch or data access, read or write, and the data access size are set. For an instruction fetch, use the PCBA and PCBB bits in the BRCR register to set to break before or after the instruction execution.
4. For channel B, data can be included in the break conditions. Set the data in the BDRB register. To mask data, set the BDMRB register. Use the DBEB bit of the BRCR register to set whether to include data in the break conditions.

5. To use channels A and B sequentially, set the SEQ bit in the BRCR register. When set for sequential use, a user break occurs when the channel A conditions are met and then the channel B conditions are met.
6. The CMFA and CMFB bits in the BRCR register are set to 1 when a user break occurs. To generate a break again, set CMFA and CMFB to 0.

8.2 Register Descriptions

8.2.1 Break Address Registers (BARA and BARB)

Break address registers A and B (BARA and BARB) are 32-bit read/write registers that specify the virtual address that is the channel A or channel B break condition. They are not initialized by manual resets; instead they hold their values.

Bits 31 to 0—Break Address A31 to A0 (BAA31 to BAA0), B31 to B0 (BAB31 to BAB0): These bits store the virtual address (bits 31 to 0) of the channel A or channel B break condition.

Bit:	31	30	29	28	27	26	25	24
Bit name:	BAA31/ BAB31	BAA30/ BAB30	BAA29/ BAB29	BAA28/ BAB28	BAA27/ BAB27	BAA26/ BAB26	BAA25/ BAB25	BAA24/ BAB24
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	23	22	21	20	19	18	17	16
Bit name:	BAA23/ BAB23	BAA22/ BAB22	BAA21/ BAB21	BAA20/ BAB20	BAA19/ BAB19	BAA18/ BAB18	BAA17/ BAB17	BAA16/ BAB16
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	15	14	13	12	11	10	9	8
Bit name:	BAA15/ BAB15	BAA14/ BAB14	BAA13/ BAB13	BAA12/ BAB12	BAA11/ BAB11	BAA10/ BAB10	BAA9/ BAB9	BAA8/ BAB8
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	BAA7/ BAB7	BAA6/ BAB6	BAA5/ BAB5	BAA4/ BAB4	BAA3/ BAB3	BAA2/ BAB2	BAA1/ BAB1	BAA0/ BAB0
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

8.2.2 Break Address Space Identification Registers A and B (BASRA and BASRB)

Break address space identification registers A and B (BASRA and BASRB) are 8-bit read/write registers that specify the ASID for the channel A or B break condition. They are compared to the

ASID field of the MMU's PTEH register. They are not initialized by manual resets; instead they hold their values.

Bits 31 to 0—Break ASID A7 to A0 (BASA7 to BASA0), B7 to B0 (BASB7 to BASB0): These bits store the ASID (bits 7 to 0) of the channel A or channel B break condition.

Bit:	7	6	5	4	3	2	1	0
Bit name:	BASA7/ BASB7	BASA6/ BASB6	BASA5/ BASB5	BASA4/ BASB4	BASA3/ BASB3	BASA2/ BASB2	BASA1/ BASB1	BASA0/ BASB0
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

8.2.3 Break Address Mask Register A (BAMRA)

Break address mask register A (BAMRA) is an 8-bit read/write registers that specifies the bits of the ASID set in the BASRA register and the break address set in the BARA register to be masked. It is not initialized by manual resets; instead they hold their values.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	—	BASMA	BAMA1	BAMA0
Initial value:	0	0	0	0	0	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 7–3—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 2—Break ASID Mask A (BASMA): Specifies which bits of the channel A break ASID7 to ASID0 (BASA7–BASA0) set in BASRA to mask.

Bit 2: BASMA	Description
0	Do not mask BASRA; include all bits in break conditions
1	Mask all BASRA bits; do not include ASID in break conditions

Bits 1–0—Break Address Mask A1–A0 (BAMA1–BAMA0): Specifies which bits of the channel A break address 31–0 (BAA31–BAA0) set in BARA to mask.

Bit 1: BAMA1	Bit 0: BAMA0	Description
0	0	No BARA bits are masked, entire 32-bit address is included in break conditions
	1	Lower-order 10 bits of BARA are masked
1	0	Lower-order 12 bits of BARA are masked
	1	All BARA bits are masked; address is not included in break conditions

8.2.4 Break Address Mask Register B (BAMRB)

The break address mask register for channel B. Bit configuration is the same as BAMRA.

8.2.5 Break Bus Cycle Register A (BBRA)

Break bus cycle register A (BBRA) is a read/write 16-bit register that sets (1) instruction fetch/data access, (2) read/write, and (3) operand size for the channel A break conditions. It is initialized to H'0000 by power-on resets and manual resets.

Bit:	15	14	13	12	11	10	9	8
BBRA/BBRB:	—	—	—	—	—	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R
Bit:	7	6	5	4	3	2	1	0
BBRA/BBRB:	—	—	IDA1	IDA0	RWA1	RWA0	SZA1	SZA0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15–6—Reserved: These bits are always read as 0. The write value should always be 0.

Bits 5–4—Instruction Fetch/Data Access A (IDA1, IDA0): Specify instruction fetch bus cycle or data access cycle for the channel A break condition.

Bit 5: IDA1	Bit 4: IDA0	Description
0	0	Conditions not compared (initial value)
	1	Break condition is instruction fetch cycle
1	0	Break condition is data access cycle
	1	Break condition is both instruction fetch cycle and data access cycle

Bits 3–2—Read/Write Select A (RWA1, RWA0): Specify read cycle or write cycle for the channel A break condition bus cycle.

Bit 3: RWA1	Bit 2: RWA0	Description
0	0	Conditions not compared (initial value)
	1	Break condition is read cycle
1	0	Break condition is write cycle
	1	Break condition is both read cycle and write cycle

Bits 1–0—Operand Size Select A (SZA1, SZA0): Specify operand size for the channel A break condition bus cycle.

Bit 1: SZA1	Bit 0: SZA0	Description
0	0	Operand size not included in comparison conditions (initial value)
	1	Break on byte access
1	0	Break on word access
	1	Break on longword access

8.2.6 Break Bus Cycle Register B (BBRB)

The break bus condition register for channel B. Bit configuration is the same as BBRA.

8.2.7 Break B Data Register (BDRB)

The Break B data register (BDRB) is a 32-bit read/write register that specifies the data (bits 31–0) that is the break condition for channel B data breaks. It is not initialized by a manual reset; instead, it holds its values.

Bits 31–0—Break Data B31–B0 (BDB31–BDB0): Holds the data that is the break condition for channel B data breaks (bits 31–0). When the SZB bit is set in the BBRB register, set the same byte data in bits BDB15–BDB8 as in BDB7–BDB0. When set for byte or word access, bits BDB31 to BDB16 are ignored.

When instruction fetch is specified as a break condition for channel B or 0 is specified in the BR CR's DBEB bit to not include the data bus in compared conditions, the BDRB register value is ignored.

Bit:	31	30	29	28	27	26	25	24
Bit name:	BDB31	BDB30	BDB29	BDB28	BDB27	BDB26	BDB25	BDB24
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	23	22	21	20	19	18	17	16
Bit name:	BDB23	BDB22	BDB21	BDB20	BDB19	BDB18	BDB17	BDB16
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	15	14	13	12	11	10	9	8
Bit name:	BDB15	BDB14	BDB13	BDB12	BDB11	BDB10	BDB9	BDB8
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	BDB7	BDB6	BDB5	BDB4	BDB3	BDB2	BDB1	BDB0
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

8.2.8 Break B Data Mask Register (BDMRB)

The Break B data mask register (BDMRB) is a 32-bit read/write register that provides a masking bit corresponding to each bit of BDRB. It is not initialized by a manual reset; instead, it holds its values.

Bit:	31	30	29	28	27	26	25	24
Bit name:	BDMB31	BDMB30	BDMB29	BDMB28	BDMB27	BDMB26	BDMB25	BDMB24
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	23	22	21	20	19	18	17	16
Bit name:	BDMB23	BDMB22	BDMB21	BDMB20	BDMB19	BDMB18	BDMB17	BDMB16
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	15	14	13	12	11	10	9	8
Bit name:	BDMB15	BDMB14	BDMB13	BDMB12	BDMB11	BDMB10	BDMB9	BDMB8
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	BDMB7	BDMB6	BDMB5	BDMB4	BDMB3	BDMB2	BDMB1	BDMB0
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 31–0—Break Data Mask B31–B0 (BDMB31–BDMB0): Specifies which bits in the channel B break data B31–B0 (BDB31–BDB0) set in BDRB to mask. When byte is specified for size, set the same values in BDMD15–BDMD8 as in BDMB7–BDMB0.

Bits 31–0: BDMBn	Description
0	Include break data BDBn in the channel B break conditions
1	Do not include break data BDBn in the channel B break conditions

n = 31–0

Cautions

- Specify the operand size when data bus values are included in the break conditions.

- When byte size is specified, set the same values in bits 15–8 and 7–0 of the BDRB and BDMRB registers.
- For word or byte sizes, bits 31–16 of the BDRB and BDMRB registers are ignored.

8.2.9 Break Control Register (BRCR)

The break control register (BRCR) is a 16-bit read/write register that controls user breaks. The BRCR sets (1) whether channels A and B use independent or sequential conditions, (2) whether breaks occur before or after instruction execution, and (3) whether the BDRB register is included in the channel B break conditions. It also has condition match flags. BRCR is cleared to H'0000 at a power-on reset or manual reset.

Bit:	15	14	13	12	11	10	9	8
Bit name:	CMFA	CMFB	—	—	—	PCBA	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R	R	R	R/W	R	R
Bit:	7	6	5	4	3	2	1	0
Bit name:	DBEB	PCBB	—	—	SEQ	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R	R	R/W	R	R	R

Bit 15—Conditions Met Flag A (CMFA): Set to 1 when the break conditions for channel A have been met. It is not cleared to 0. To use it again after it has been set, write 0 to clear it.

Bit 15: CMFA	Description
0	Channel A break conditions not met (initial value)
1	Channel A break conditions met

Bit 14—Conditions Met Flag B (CMFB): Set to 1 when the break conditions for channel B have been met. It is not cleared to 0. To use it again after it has been set, write 0 to clear it.

Bit 14: CMFB	Description
0	Channel B break conditions not met (initial value)
1	Channel B break conditions met

Bits 13–11—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 10—Program Counter Break A Trap (PCBA): Indicates if the trap for the channel A instruction fetch address break is taken before or after execution of the fetched instruction.

Bit 10: PCBA	Description
0	Breaks prior to execution of channel A PC break (initial value)
1	Breaks after execution of channel A PC break

Bits 9–8—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 7—Data Break Enable Bit (DBEB): Indicates if the data bus is included in the channel B break conditions, as follows:

Bit 7: DBEB	Description
0	Data bus conditions not included in channel B conditions (initial value)
1	Data bus conditions included in channel B conditions

Note: To include the data bus in the break conditions, set the IDB1–IDB0 field in the BBRB to 10 or 11.

Bit 6—Program Counter Break Select B (PCBB): Indicates if the trap for the channel B instruction fetch address break is taken before or after execution of the fetched instruction.

Bit 6: PCBB	Description
0	Breaks prior to execution of channel B PC break (initial value)
1	Breaks after execution of channel B PC break

Bits 5–4—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 3—Sequential Condition Select (SEQ): Indicates if the channel A and channel B break conditions are checked independently or in sequence. When set for sequential, the CMFB flag is set when channel B conditions are met after channel A conditions are met.

Bit 3: SEQ	Description
0	Channel A and channel B are compared independently (initial value)
1	Channel A and channel B are compared sequentially (channel A met before channel B)

Bits 2–0—Reserved: These bits are always read as 0. The write value should always be 0.

8.3 Operation

8.3.1 Flow of the User Break Operation

The flow from setting of break conditions to user break interrupt exception processing is described below:

1. The break addresses are set in the break address registers (BARA, BARB), the ASIDs corresponding to the space for the break are set in the break ASID registers (BASRA, BASRB), and the masked addresses and ASID mask method are set in the break address mask registers (BAMRA, BAMRB). When data bus values are included in break conditions, the break data is set in the break data register (BDRB) and the masked data is set in the break data mask register (BDMRB).
2. The breaking bus conditions are set in the break bus cycle registers (BBRA, BBRB). If one of the two registers BBRA and BBRB is set to 00 for instruction fetch/data access and read/write, no user break trap will be generated for the channel concerned. Set the break control register (BRCR) to specify breaking before or after execution in the case of instruction fetch, whether to include data bus values in the case of data access, independent or sequential conditions for channels A and B. Set the BBRA and BBRB registers after the other break-related registers have all been set. If breaks are enabled with the BBRA and BBRB registers with the registers for break address, data, masking and the like in their initial states after reset, breaks will occur in the wrong places.
3. When the set conditions are satisfied, the condition match flags (CMFA, CMFB) for the respective channels are set. Once set by a break condition match, they are not reset. To use them again, set them to 0.
4. When set for sequential conditions, a break occurs at the instruction that matches the channel B conditions if the channel A conditions have been previously matched. No break occurs if the channel B conditions are matched before or simultaneous to matching the channel A conditions. The condition match flag is only set for channel B when conditions match when set for sequential matching.

8.3.2 Break on Instruction Fetch Cycle

1. When instruction fetch/read/word is set in the break bus cycle registers (BBRA/BBRB), the break condition becomes the instruction fetch cycle. Whether it then breaks before or after the execution of the instruction can then be selected with the PCBA and PCBB bits of the break control register (BRCR).
2. The instruction fetch cycle always fetches 32 consecutive bits (two instructions) at once. Only one bus cycle occurs, but breaks can be placed on each instruction individually by setting the respective start addresses in the break address registers (BARA, BARB).
3. An instruction set for a break before execution breaks when it is confirmed that the instruction has been fetched and will be executed. This means this feature cannot be used on instructions

fetched by overrun (instructions fetched at a branch or during an exception transition, but not to be executed). When an exception occurs when the instruction of the break is fetched, the exception is processed and then the break occurs when the instruction is re-executed. Delay slot instructions and delayed branch instructions are executed as single instructions, so when break before execution is set for a delay slot instruction, the break occurs before the delay branch instruction. Break before execution cannot be specified for the RTE instruction's delay slot instruction.

4. When the condition stipulates after execution, the instruction set with the break condition is executed and then the break trap is generated prior to the execution of the next instruction. As with pre-execution breaks, this cannot be used with overrun fetch instructions. When this kind of break is set for a delayed branch instruction, the delay slot is executed and the break occurs before execution of the instruction at the end of the branch.
5. When an instruction fetch cycle is set for channel B, break data register B (BDRB) is ignored. There is thus no need to set break data for the break of the instruction fetch cycle.
6. Instruction fetch cycle breaks cannot be set after delayed branch instructions and delay slots.

8.3.3 Break on Data Access Cycle

1. When breaks occur on data access cycles, the specification for operand size in the break bus cycle registers (BBRA and BBRB) changes the bits of the address bus comparison as follows listed in table 8.2.

Table 8.2 Breaks on Data Access Cycles

Operand Size	Address Compared
Not included (00)	Compare address bits A31–A0 for byte access Compare address bits A31–A1 for word access Compare address bits A31–A2 for longword access
Byte (01)	Compare address bits A31–A0
Word (10)	Compare address bits A31–A1
Longword (11)	Compare address bits A31–A2

2. When the data value is included in the break conditions on Channel B, set the BR CR's DBEB bit to 1. In addition to address conditions, break data register B (BDRB) and break data mask register B (BDMRB) must both be set. When address and data conditions both match, a user break trap is generated. Set the IDB1–IDB0 field in the BBRB to 00 or 01. When specifying byte data, set the same data in the two bytes at bits 15–8 and bits 7–0 of the break data register B (BDRB) and break data mask register B (BDMRB). When word or byte is set, bits 31–16 of BDRB and BDMRB are ignored.

8.3.4 Program Counter (PC) Values Saved

1. Break on Instruction Fetch (Before Execution): The program counter (PC) value saved to the SPC in user break interrupt processing is the address of the instruction that matches the break condition. The user break interrupt is generated before the fetched instruction, which is not executed. In fetch cycles of instructions placed in the delay slots of delayed branch instructions, the break occurs before the branch, so the SPC value is the delayed branch instruction.
2. Break on Instruction Fetch (After Execution): The program counter (PC) value saved to the SPC in user break interrupt processing is the address of the instruction executed after the one that matches the break condition. The fetched instruction is executed and the user break interrupt is generated before the next instruction. If a break condition is set on a delayed branch instruction, the delay slot instruction is executed and the user break occurs before the instruction at the end of the branch is executed. The PC value saved to the SPC is the address of the delayed branch instruction.
3. Break on Data Access (Address Only): The address of the instruction after the one that matched the conditions is saved. The instruction is executed and the user break trap occurs before execution of the next instruction.
4. Break on Data Access (Address + Data): The top address of the instruction after the executed instruction when the user break trap processing started is saved. When data values are set as a break condition, the place where the break will occur cannot be specified exactly. The break will occur before execution of an instruction fetched near the data access that is to receive the break.

8.3.5 Examples

This section shows how register settings, already set conditions, and conditions set match.

Break on an Instruction Fetch Bus Cycle (Channels A and B Independent)

BRCR = H'0400: A and B channels independent, channel A after instruction execution, channel B before instruction execution.

Channel A	BASRA = H'80:	ASID H'80
	BARA = H'00000404:	Address = H'00000404
	BAMRA = H'00:	Address mask H'00
	BBRA = H'0014:	Bus cycle = Instruction fetch (after execution), read (operand size not included in conditions)
Channel B	BASRB = H'70:	ASID H'70
	BARB = H'00008010:	Address = H'00008010
	BAMRB = H'02:	Address mask H'02
	BBRB = H'0014:	Bus cycle = Instruction fetch (before execution), read (operand size not included in conditions)
	BDRB = H'00000000:	Data H'00000000
	BDMRB = H'00000000:	Data mask H'00000000

A user break will occur after the instruction at address H'00000404 with ASID=H'80 is executed, or a user break will be generated before the execution of the instruction at address H'00008000 to H'000083FE with ASID=H'70.

Break on an Instruction Fetch Bus Cycle (Channels A and B Sequential)

BRCR = H'0008: A and B channels sequential, channel A before instruction execution, channel B before instruction execution.

Channel A	BASRA = H'80:	ASID H'80
	BARA = H'00037226:	Address = H'00037226
	BAMRA = H'00:	Address mask H'00
	BBRA = H'0016:	Bus cycle = Instruction fetch (before execution), read, word
Channel B	BASRB = H'70:	ASID H'70
	BARB = H'0003722E:	Address = H'0003722E
	BAMRB = H'00:	Address mask H'00
	BBRB = H'0016:	Bus cycle = Instruction fetch (before execution), read, word
	BDRB = H'00000000:	Data H'00000000
	BDMRB = H'00000000:	Data mask H'00000000

The instruction at address H'00037226 with ASID=H'80 will be executed and then a user break will occur before the instruction at address H'0003722E with ASID=H'70 is executed.

Break on a Data Access Cycle

BRCR = H'0080: A and B channels independent, data break enabled.

Channel A	BASRA = H'80:	ASID H'80
	BARA = H'00123456:	Address = H'00123456
	BAMRA = H'00:	Address mask H'00
	BBRA = H'0024:	Bus cycle = Data access, read (operand size not included in conditions)
Channel B	BASRB = H'70:	ASID H'70
	BARB = H'000ABCDE:	Address = H'000ABCDE
	BAMRB = H'02:	Address mask H'02
	BBRB = H'002A:	Bus cycle = Data access, write, word
	BDRB = H'0000A512:	Data H'0000A512 (data break enabled)
	BDMRB = H'00000000:	Data mask H'00000000

For channel A, a user break interrupt occurs when it is read as longword at address H'00123454 with ASID=H'80, as word at address H'00123456 or as byte at address H'00123456. For channel B, a user break interrupt occurs when H'A512 is written as word anywhere between H'000AB000 and H'000ABFFE (inclusive) with ASID=H'70.

Break on an Instruction Fetch Cycle (Error in Settings)

BRCR = H'0000: A and B channels independent, channel A before instruction execution, channel B before instruction execution.

Channel A	BASRA = H'80:	ASID H'80
	BARA = H'00027128:	Address = H'00027128
	BAMRA = H'00:	Address mask H'00
	BBRA = H'001A:	Bus cycle = Instruction fetch (before execution), write, word
Channel B	BASRB = H'70:	ASID H'70
	BARB = H'00031415:	Address = H'00031415
	BAMRB = H'00:	Address mask H'00
	BBRB = H'0014:	Bus cycle = Instruction fetch (before execution), read (operand size not included in conditions)
		BDRB = H'00000000:
	BDMRB = H'00000000:	Data mask H'00000000

A user break trap is not generated for channel A since the instruction fetch is not a write cycle. A user break is not generated for channel B because the instruction fetch is for an odd address.

8.3.6 Cautions

1. When one channel has a break before execution set on an instruction and the other channel has a break after execution set on the same instruction, the break will occur before execution, but the condition match flags will be set for both.
2. Do not set a PC break on both a delayed branch instruction and a delay slot instruction consecutively.
3. When a PC break (after execution) is set on a TRAPA instruction, no break will occur, though the condition match flag will be set. The TRAPA instruction will be processed correctly.
4. When a break condition is set on a data access (address + data) and an exception occurs on the instruction after the break conditions are matched, no break will occur, though the condition match flag will be set. The exception occurring after the break will be processed correctly. Data breaks have priority, however, for delayed branch instructions.
5. When a break condition is set on a data access (address + data) and the instruction after the break conditions are matched is a SLEEP instruction, no break will occur, though the condition match flag will be set. The SLEEP instruction will be processed correctly.
6. When instruction fetch (halt after execution) is set for the break condition and the instruction after the break condition is matched detects a nonmaskable interrupt, no break will occur, though the condition match flag will be set. The nonmaskable interrupt will be processed correctly.
7. When set for a sequential break, conditions match when a match of channel B conditions occurs some time after the bus cycle in which a channel A match occurs. This means that the conditions will not be satisfied when set for a bus cycle in which channel A and channel B occur simultaneously. Since the CPU uses a pipeline structure, the order of the instruction fetch cycle and memory cycle is fixed by the pipeline, so sequential conditions means that the sequential conditions will be satisfied when the respective channel conditions are met in the order the bus cycles occur.
8. When the emulator is used, the UBC is used on the emulator system side to implement the emulator's break function. This means none of the UBC functions can be used when the emulator is being used.

Section 9 Power-Down Modes

9.1 Overview

In the power-down modes, all CPU and some on-chip supporting module functions are halted. This lowers power consumption.

9.1.1 Power-Down Modes

The SH7718R has three power-down modes:

1. Sleep mode
2. Standby mode
3. Module standby function (TMU, RTC, and SCI on-chip supporting modules)
4. Hardware standby mode

Table 9.1 shows the transition conditions for entering the modes from the program execution state, as well as the CPU and supporting module states in each mode and the procedures for canceling each mode.

Table 9.1 Power-Down Modes

Mode	Transition Conditions	State							Canceling Procedure
		CPG	CPU	CPU Reg-ister	On-Chip Memory	On-Chip Peripheral Modules	Pins	External Memory	
Sleep mode	Execute SLEEP instruction with STBY bit cleared to 0 in STBCR	Runs	Halts	Held	Held	Run	Held	Refresh	1. Interrupt 2. Reset
Standby mode	Execute SLEEP instruction with STBY bit set to 1 in STBCR	Halts	Halts	Held	Held	Halts* ¹	Held	Self-refresh	1. Interrupt 2. Reset
Hardware standby mode	Drive CA pin low	Halts	Halts	Held	Held	Halts* ³	Held	Self-refresh	Power-on reset
Module standby	Set MSTP bit of STBCR to 1	Runs	Runs	Held	Held	Specified module halts	* ²	Refresh	1. Clear MSTP bit to 0 2. Reset

- Notes:
1. The RTC still runs if the START bit in RCR2 is set to 1 (see section 12, Realtime Clock (RTC)). TMU still runs when output of the RTC is used as input to its counter (see section 11, Timer (TMU)).
 2. Depends on the on-chip supporting module.
TMU external pin: Held
SCI external pin: Reset
 3. The RTC still runs if the START bit in RCR2 is set to 1 (see section 12, Realtime Clock (RTC)). The TMU does not run.

9.1.2 Register Configuration

Table 9.2 shows the configuration of the control register for the power-down modes.

Table 9.2 Register Configuration

Name	Abbreviation	R/W	Initial Value	Address	Access Size
Standby control register	STBCR	R/W	H'00	H'FFFFFF82	Byte

9.1.3 Pin Configuration

Table 9.3 lists the pins used for the power-down modes.

Table 9.3 Pin Configuration

Processing Status 1 Pin (STATUS1)	Processing Status 0 Pin (STATUS0)	I/O	Processor Operating Status
High	High	O	Reset
	Low		Sleep mode
Low	High		Standby mode
	Low		Normal operation

9.2 Register Description

9.2.1 Standby Control Register (STBCR)

The standby control register (STBCR) is an 8-bit read/write register that sets the power-down mode. STBCR is initialized to H'00 by a power-on reset. Always set bits 6–3 to 0 when writing to the STBCR register.

Bit:	7	6	5	4	3	2	1	0
Bit name:	STBY	—	—	—	—	MSTP2	MSTP1	MSTP0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R	R	R	R	R/W	R/W	R/W

Bit 7—Standby (STBY): Specifies transition to standby mode.

Bit 7: STBY	Description
0	Executing SLEEP instruction puts the chip into sleep mode. (Initial value)
1	Executing SLEEP instruction puts the chip into standby mode.

Bits 6 to 3—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 2—Module Standby 2 (MSTP2): Specifies halting the clock supply to the timer unit TMU (an on-chip supporting module). When the MSTP2 bit is set to 1, the supply of the clock to the TMU is halted.

Bit 2: MSTP2	Description
0	TMU runs. (Initial value)
1	Clock supply to TMU is halted.

Bit 1—Module Standby 1 (MSTP1): Specifies halting the clock supply to the realtime clock RTC (an on-chip supporting module). When the MSTP1 bit is set to 1, the supply of the clock to RTC is halted. When the clock halts, all RTC registers become inaccessible, but the counter keeps running.

Bit 1: MSTP1	Description
0	RTC runs. (Initial value)
1	Clock supply to RTC is halted.

Bit 0—Module Standby 0 (MSTP0): Specifies halting the clock supply to the serial communication interface SCI (an on-chip supporting module). When the MSTP0 bit is set to 1, the supply of the clock to the SCI is halted.

Bit 0: MSTP0	Description
0	SCI operates. (Initial value)
1	Clock supply to SCI is halted.

9.3 Sleep Mode

9.3.1 Transition to Sleep Mode

Executing the SLEEP instruction when the STBY bit in STBCR is 0 causes a transition from the program execution state to sleep mode. Although the CPU halts immediately after executing the SLEEP instruction, the contents of its internal registers remain unchanged. The on-chip supporting modules continue to run during sleep mode and the clock continues to be output to the CKIO pin. In sleep mode, the STATUS1 pin is set high and the STATUS0 pin low. However, during a refresh cycle, the STATUS1 pin and STATUS0 pin are both set low.

9.3.2 Canceling Sleep Mode

Sleep mode is canceled by an interrupt (NMI, IRL, on-chip supporting module) or reset. Interrupts are accepted during sleep mode even when the BL bit in the SR register is 1.

Canceling with an Interrupt: When an NMI, IRL or on-chip supporting module interrupt occurs, sleep mode is canceled and interrupt exception handling is executed. A code indicating the interrupt source is set in the INTEVT register.

Canceling with a Reset: Sleep mode is canceled by a power-on reset or a manual reset.

9.4 Standby Mode

9.4.1 Transition to Standby Mode

To enter standby mode, set the STBY bit to 1 in STBCR, then execute the SLEEP instruction. The chip moves from the program execution state to standby mode. In standby mode, power consumption is greatly reduced by halting not only the CPU, but the clock and on-chip supporting modules as well. The clock output from the CKIO pin also halts. CPU and cache register contents are held, but some on-chip supporting modules are initialized. Table 9.4 lists the states of registers in standby mode.

Table 9.4 Register States in Standby Mode

Module	Registers Initialized	Registers Retaining Data
Interrupt controller	—	All registers
Break controller	—	All registers
Bus state controller	—	All registers
On-chip clock pulse generator	—	All registers
Timer unit	TSTR register	Registers other than TSTR
Realtime clock	—	All registers

The procedure for moving to standby mode is as follows:

1. Clear the TME bit in the WDT's timer control register (WTCSR) to 0 to stop the WDT. Set the WDT's timer counter (WTCNT) and the CKS2–CKS0 bits of the WTCSR register to appropriate values to secure the specified oscillation settling time.
2. When PLL circuit 1 is running in clock modes 3–6, clear the PSTBY and PLEN bits in the frequency control register (FRQCR) to 0 to stop PLL circuit 1.
3. After the STBY bit in the STBCR register is set to 1, a SLEEP instruction is executed.
4. Standby mode is entered and the clocks within the chip are halted. The STATUS1 pin output goes low and the STATUS0 pin output goes high.

9.4.2 Canceling Standby Mode

Standby mode is canceled by an interrupt (NMI, IRL, or on-chip supporting module) or a reset.

Canceling with an Interrupt: The on-chip WDT can be used for hot starts. When the chip detects an NMI, IRL,^{*1} or on-chip supporting module (except the interval timer)^{*2} interrupt, the clock will be supplied to the entire chip and standby mode canceled after the time set in the WDT's timer control/status register has elapsed. The STATUS1 and STATUS0 pins both go low. Interrupt handling then begins and a code indicating the interrupt source is set in the INTEVT register. Interrupts are accepted during standby mode even when the BL bit in the SR register is 1. Immediately after an interrupt is detected, the phase of the clock output of the CKIO pin may be unstable, until the processor starts interrupt handling. (The canceling condition is that the IRL3–IRL0 level is higher than the mask level in the I3–I0 bits in the SR register.)

- Notes:
1. When the RTC is being used, standby mode can be canceled using IRL3–IRL0.
 2. Standby mode can be canceled with an RTC or TMU (only when running on the RTC clock) interrupt.

Canceling with a Reset: Standby mode can be canceled with a reset (power-on or manual). Keep the RESET pin low until the clock oscillation settles. The internal clock will continue to be output to the CKIO pin.

9.4.3 Clock Pause Function

In standby mode, the clock input from the EXTAL pin or CKIO pin can be halted and the frequency can be changed. This function is used as follows:

1. Enter standby mode using the appropriate procedures.
2. Once standby mode is entered and the clock stopped within the chip, the STATUS1 pin output is low and the STATUS0 pin output is high.
3. Once the STATUS1 pin goes low and the STATUS0 pin goes high, the input clock is stopped or the frequency is changed.
4. When the frequency is changed, an NMI or IRL interrupt is input after the change. When the clock is stopped, the same interrupts are input after the clock is applied.
5. After the time set in the WDT has elapsed, the clock starts being applied internally within the chip, the STATUS1–STATUS0 pins both go low, interrupts are handled, and operation resumes.

9.5 Module Standby Function

9.5.1 Transition to Module Standby Function

Setting the standby control register MSTP2–MSTP0 bits to 1 halts the supply of clocks to the corresponding on-chip supporting modules. This function can be used to reduce the power consumption in sleep mode. The module standby function holds the status prior to halt of the external pins of the on-chip supporting modules. TMU external pins hold their status prior to the halt. SCI external pins go to the reset state. With a few exceptions, all registers hold their values.

Bit	Value	Description
MSTP2	0	TMU runs.
	1	Supply of clock to TMU is halted. Registers are initialized.*1
MSTP1	0	RTC runs.
	1	Supply of clock to RTC is halted. Register access is prohibited.*2
MSTP0	0	SCI operates.
	1	Supply of clock to SCI is halted.

Notes: 1. The registers initialized are the same as in standby mode (table 9.4).
2. The counter runs.

9.5.2 Clearing the Module Standby Function

The module standby function can be cleared by clearing the MSTP2–MSTP0 bits to 0, or by a power-on reset or manual reset.

9.6 Timing of STATUS Pin Changes

The timing of STATUS1 and STATUS0 pin changes is shown in figures 9.1 through 9.9.

The meaning of the STATUS descriptions is as follows:

- Reset: HH (STATUS1 high, STATUS0 high)
- Sleep: HL (STATUS1 high, STATUS0 low)
- Standby: LH (STATUS1 low, STATUS0 high)
- Normal: LL (STATUS1 low, STATUS0 low)

The meaning of the clock units is as follows:

- Bcyc: Bus clock cycle
- Pcyc: Peripheral clock cycle

9.6.1 Timing for Resets

Power-On Reset (Clock Modes 0, 1, 2, and 7):

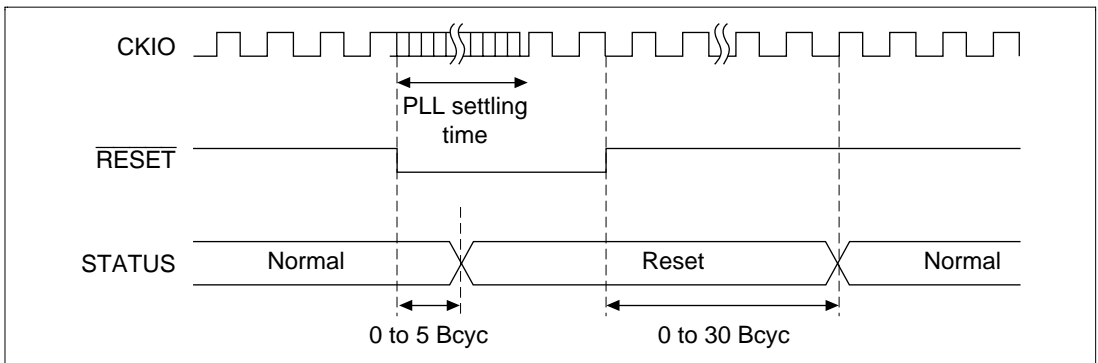


Figure 9.1 Power-On Reset (Clock Mode 0, 1, 2, and 7) STATUS Output

Power-On Reset (Clock Modes 3 and 4):

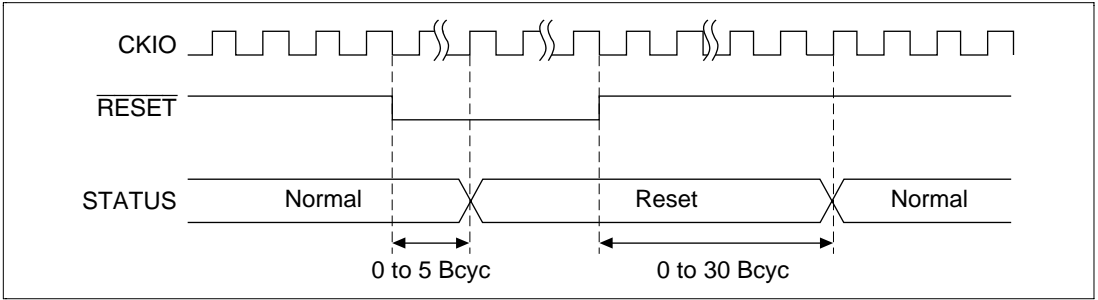


Figure 9.2 Power-On Reset (Clock Mode 3 and 4) STATUS Output

Manual Reset:

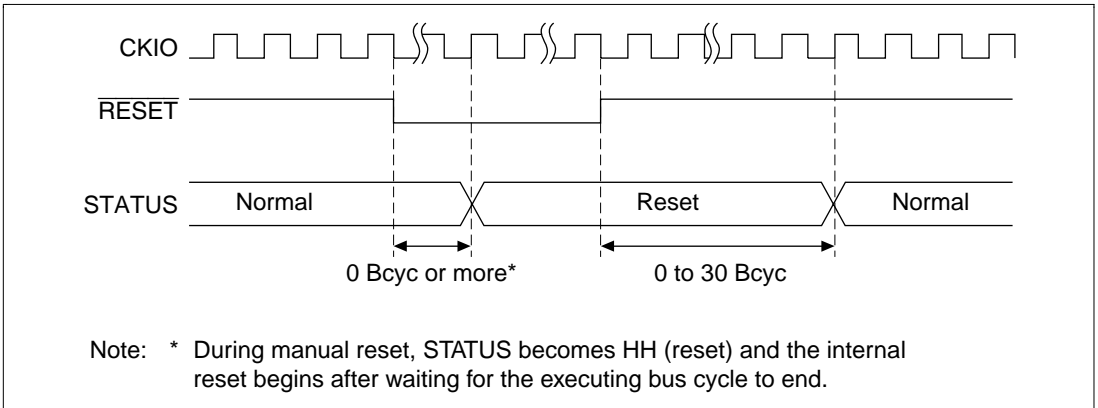


Figure 9.3 Manual Reset STATUS Output

9.6.2 Timing for Canceling Standbys

Standby to Interrupt:

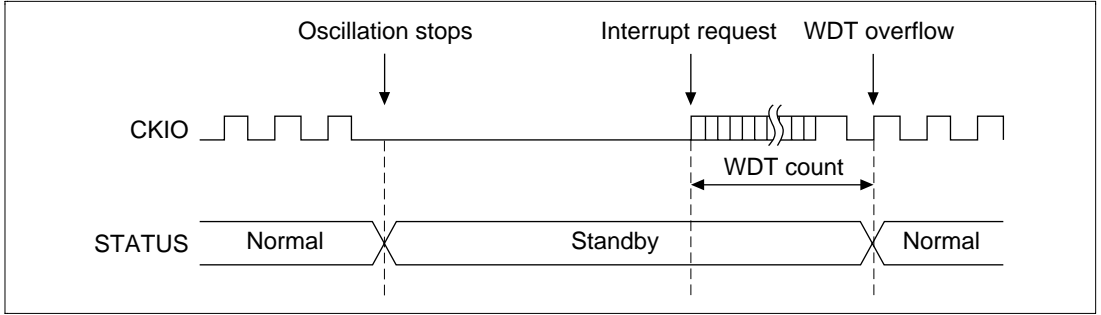


Figure 9.4 Standby to Interrupt STATUS Output

Standby to Power-On Reset:

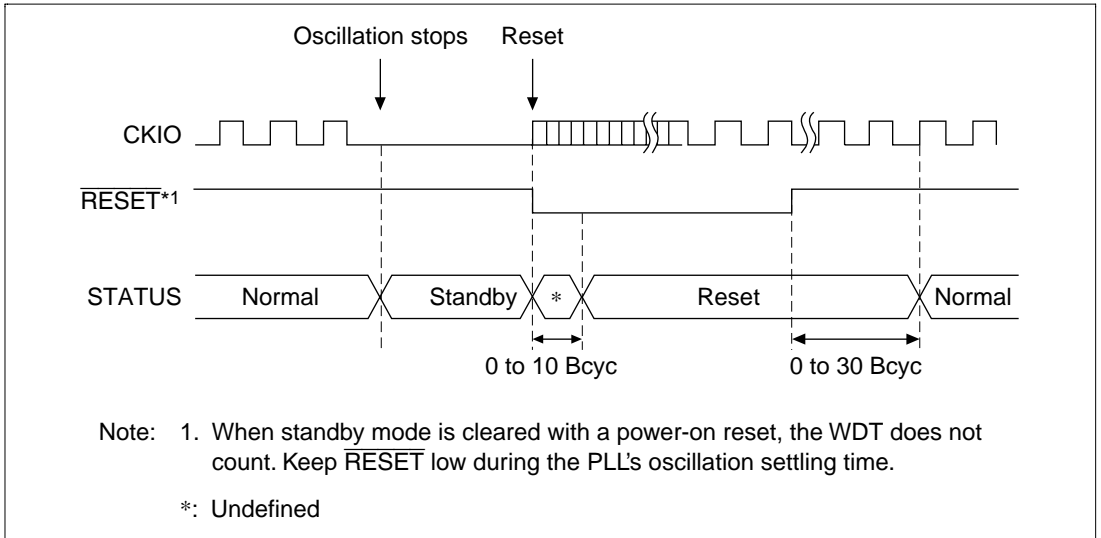


Figure 9.5 Standby to Power-On Reset STATUS Output

Standby to Manual Reset:

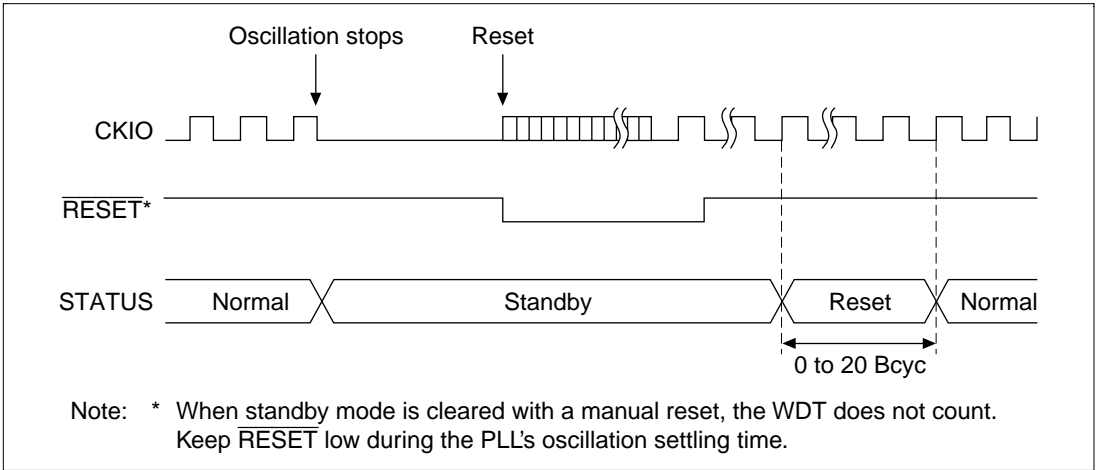


Figure 9.6 Standby to Manual Reset STATUS Output

9.6.3 Timing for Canceling Sleep Mode

Sleep to Interrupt:

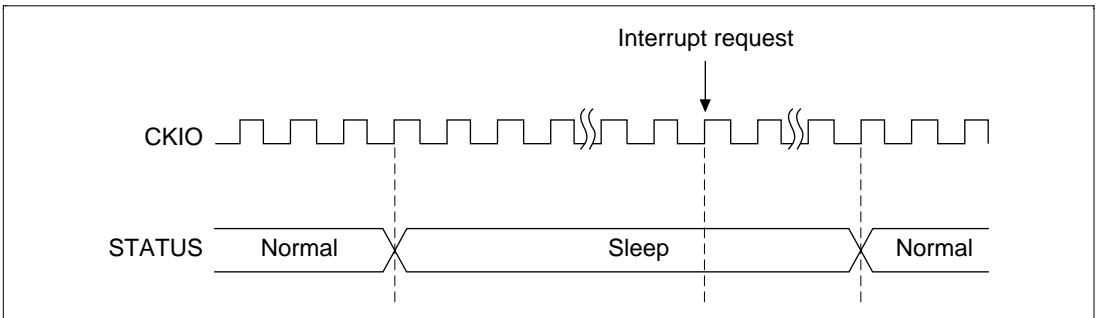


Figure 9.7 Sleep to Interrupt STATUS Output

Sleep to Power-On Reset:

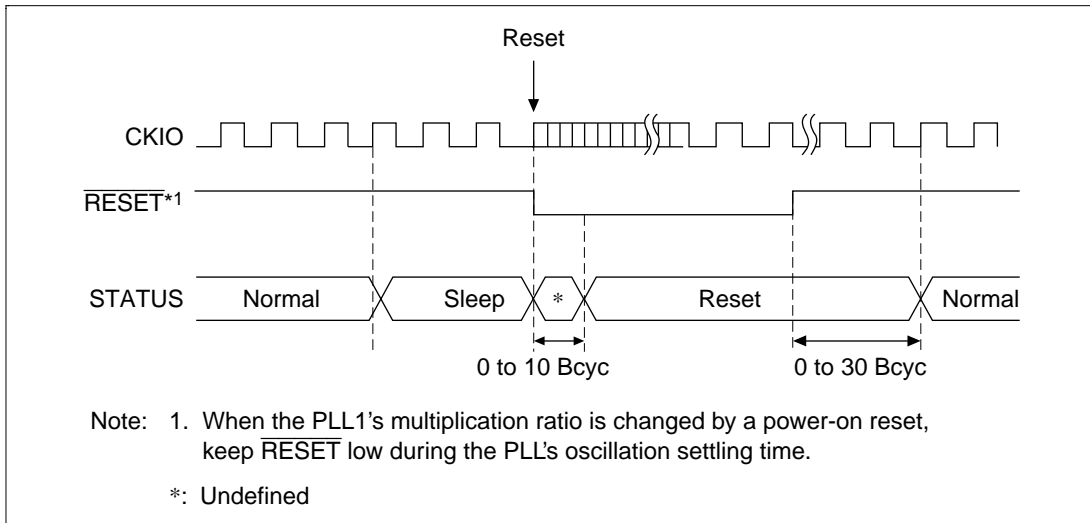


Figure 9.8 Sleep to Power-On Reset STATUS Output

Sleep to Manual Reset:

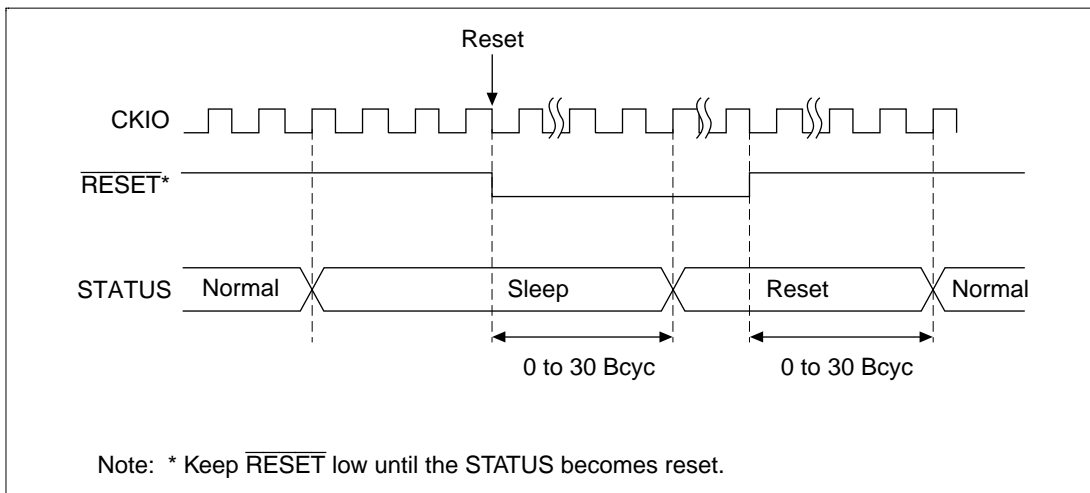


Figure 9.9 Sleep to Manual Reset STATUS Output

9.7 Hardware Standby Mode

9.7.1 Transition to Hardware Standby Mode

Driving the CA pin low causes a transition to hardware standby mode. In hardware standby mode, all modules except those operating on an RTC clock are halted, as in the standby mode entered on execution of a SLEEP instruction.

Hardware standby mode differs from standby mode as follows.

1. Interrupts and manual resets are not accepted.
2. The TCLK clock output is fixed low.
3. The TMU does not operate.
4. The RTC continues to operate even if power is not supplied to power supply pins other than those for RTC power. In this case, all output pins go to the non-drive state.

Operation when a low-level signal is input at the CA pin depends on the CPG state, as follows.

1. In standby mode
The clock remains stopped and the chip enters the hardware standby state. Acceptance of interrupts and manual resets is disabled, TCLK output is fixed low, and the TMU halts.
2. During WDT operation when standby mode is canceled by an interrupt
The chip enters hardware standby mode after standby mode is canceled and the CPU resumes operation.
3. In sleep mode
The chip enters hardware standby mode after sleep mode is canceled and the CPU resumes operation.
4. During PLL standby (see section 9.6 for the PLL standby function)
The chip enters hardware standby mode after forced implementation of the PLL OFF state.

Hold the CA pin low in hardware standby mode.

9.7.2 Canceling Hardware Standby Mode

Hardware standby mode can only be canceled by a power-on reset.

When the CA pin is driven high while the $\overline{\text{RESET}}$ pin is low and the $\overline{\text{BREQ}}$ pin is high, clock oscillation is started. Hold the $\overline{\text{RESET}}$ pin low until clock oscillation stabilizes. When the $\overline{\text{RESET}}$ pin is driven high, the CPU begins power-on reset processing.

Hardware standby mode cannot be canceled by an interrupt or manual reset.

9.7.3 Hardware Standby Mode Timing

Figures 9.10 and 9.11 show examples of pin timing in hardware standby mode.

The CA pin is sampled using EXTAL2 (32.768 kHz), and a hardware standby request is only recognized when the pin is low for two consecutive clock cycles.

The CA pin must be held low while the chip is in hardware standby mode.

Clock oscillation starts when the CA pin is driven high after the $\overline{\text{RESET}}$ pin is driven low.

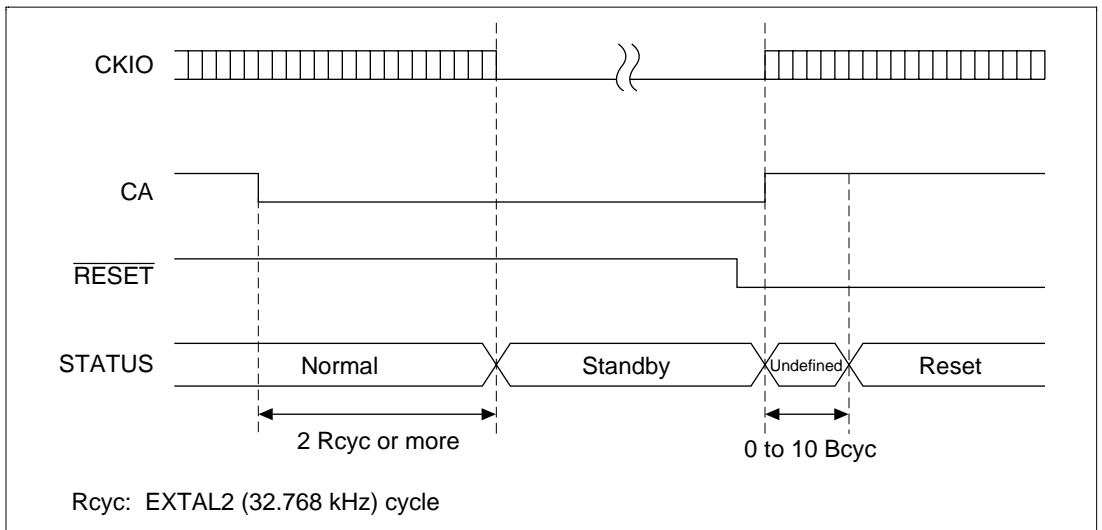


Figure 9.10 Hardware Standby Mode Timing (When CA Goes Low in Normal Operation)

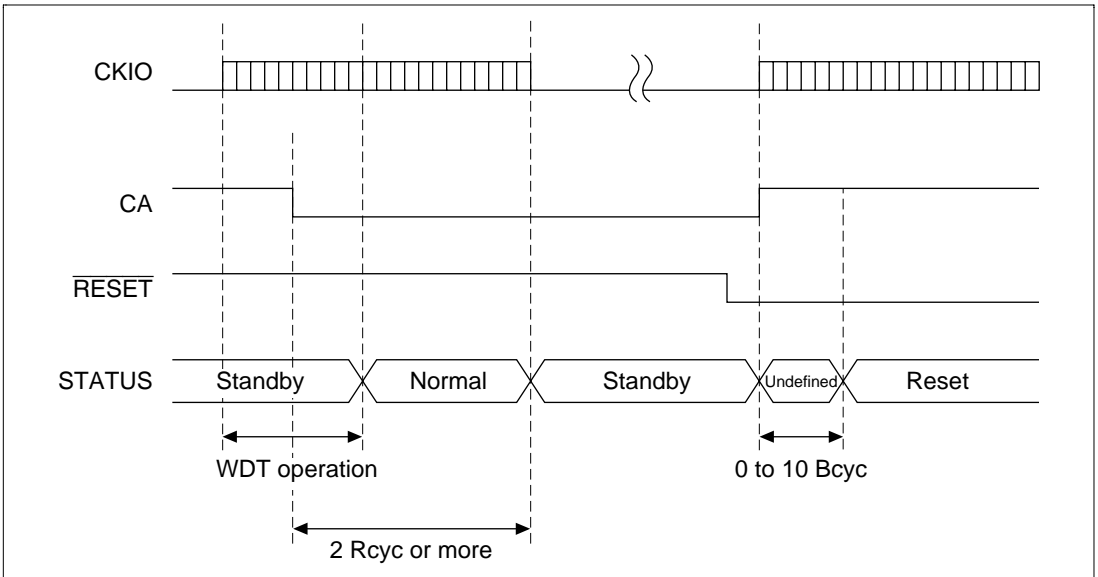


Figure 9.11 Hardware Standby Mode Timing (When CA Goes Low during WDT Operation on Standby Mode Cancellation)

Section 10 On-Chip Oscillation Circuits

10.1 Overview

The clock pulse generator (CPG) supplies all clocks to the processor and controls the power-down modes. The watchdog timer (WDT) is a single-channel timer that counts the clock settling time and is used when clearing standby mode and temporary standbys, such as frequency changes. It can also be used as an ordinary watchdog timer or interval timer.

10.1.1 Features

The CPG has the following features:

- Six clock modes: Selection of six clock modes for different frequency ranges, power consumption, direct crystal input, and external clock input.
- Three clocks generated independently: An internal clock for the CPU, cache, and TLB ($I\phi$); a peripheral clock ($P\phi$) for the on-chip supporting modules; and a bus clock (CKI0) for the external bus interface.
- Frequency change function: Internal and peripheral clock frequencies can be changed independently using the PLL circuit and divider circuit within the CPG. Frequencies are changed by software using frequency control register (FRQCR) settings.
- PLL on/off function: Power consumption can be decreased by stopping the PLL circuit when operating at low frequencies.
- Power-down mode control: The clock can be stopped for sleep mode and standby mode and specific modules can be stopped using the module standby function.

The WDT has the following features:

- Can be used to ensure the clock settling time: Use the WDT to cancel standby mode and the temporary standbys which occur when the clock frequency is changed.
- Can switch between watchdog timer mode and interval timer mode.
- Generates internal resets in watchdog timer mode: Internal resets occur after counter overflow. Selection of power-on reset or manual reset.
- Generates interrupts in interval timer mode: Internal timer interrupts occur after counter overflow.
- Selection of eight counter input clocks. Eight clocks ($\times 1$ to $\times 1/4096$) can be obtained by dividing the peripheral clock.

10.2 Overview of the CPG

10.2.1 CPG Block Diagram

A block diagram of the on-chip clock pulse generator is shown in figure 10.1.

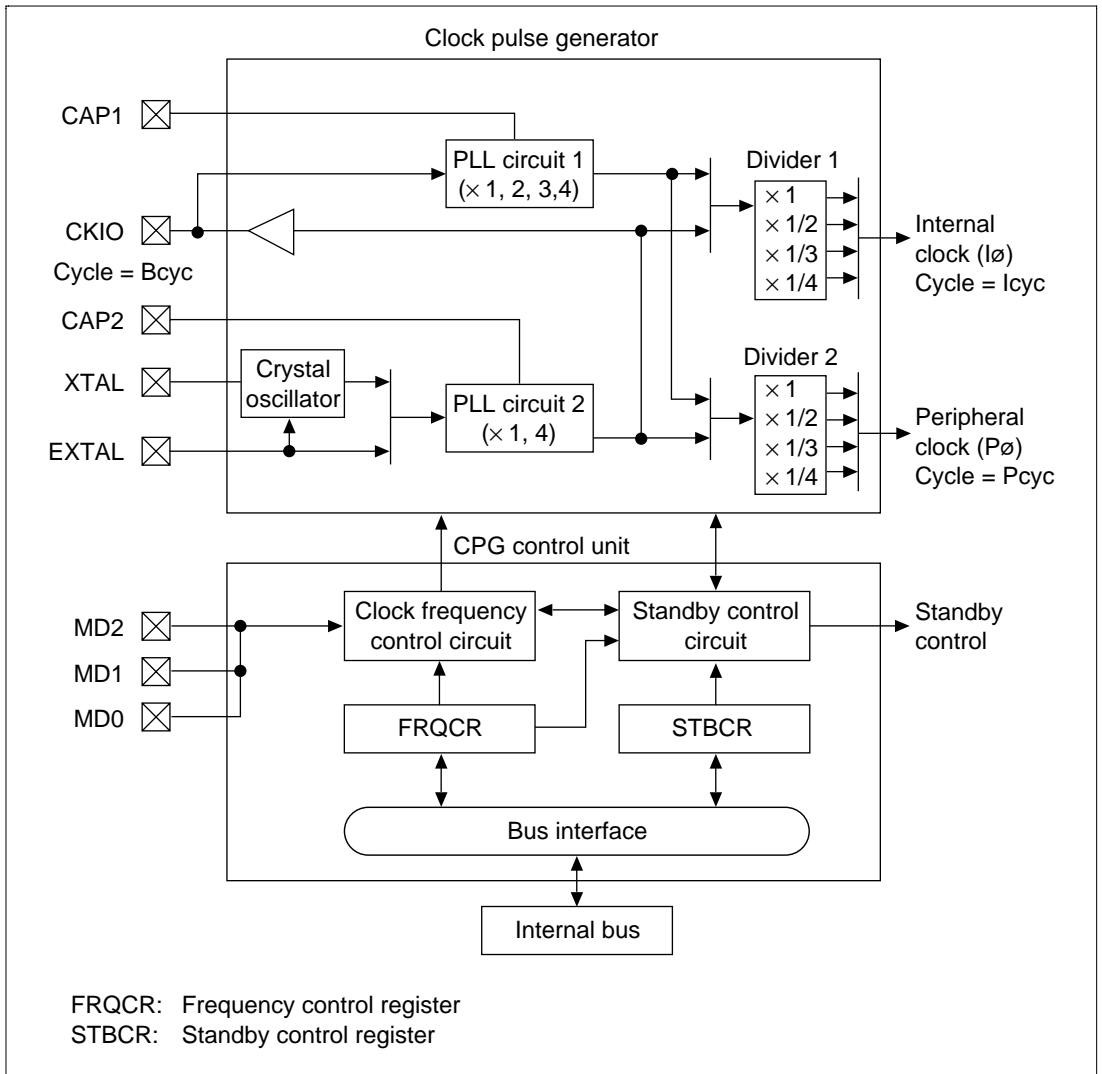


Figure 10.1 Block Diagram of Clock Pulse Generator

The clock pulse generator blocks function as follows:

1. PLL Circuit 1: PLL circuit 1 doubles, triples, quadruples, or leaves unchanged the input clock frequency from the CKIO terminal. The multiplication rate is set by the frequency control register. When this is done, the phase of the leading edge of the internal clock is controlled so that it will agree with the phase of the leading edge of the CKIO pin.
2. PLL Circuit 2: PLL circuit 2 leaves unchanged or quadruples the frequency of the crystal oscillator or the input clock frequency coming from the EXTAL pin. The multiplication ratio is fixed by the clock operation mode. The clock operation mode is set by pins MD0, MD1, and MD2. See table 10.3 for more information on clock operation modes.
3. Crystal Oscillator: This oscillator is used when a crystal oscillator element is connected to the XTAL and EXTAL pins. It operates according to the clock operating mode setting.
4. Divider 1: Divider 1 generates a clock at the operating frequency used by the internal clock. The operating frequency can be 1, 1/2, 1/3, or 1/4 times the output frequency of PLL circuit 1, as long as it stays at or above the clock frequency of the CKIO pin. The division ratio is set in the frequency control register.
5. Divider 2: Divider 2 generates a clock at the operating frequency used by the peripheral clock. The operating frequencies can be 1, 1/2, 1/3, or 1/4 times the output frequency of PLL Circuit 1 or the clock frequency of the CKIO pin, as long as it stays at or below the clock frequency of the CKIO pin. The division ratio is set in the frequency control register.
6. Clock Frequency Control Circuit: The clock frequency control circuit controls the clock frequency using the MD pin and the frequency control register.
7. Standby Control Circuit: The standby control circuit controls the status of the clock pulse generator and other modules during clock switching and sleep/standby modes.
8. Frequency Control Register: The frequency control register has control bits assigned for the following functions: clock output/non-output from the CKIO pin, on/off control of PLL circuit 1, PLL standby, the frequency multiplication ratio of PLL 1, and the frequency division ratio of the internal clock and the peripheral clock.
9. Standby Control Register: The standby control register has bits for controlling the power-down modes. See section 10, Power-Down Modes, for more information.

10.2.2 CPG Pin Configuration

Table 10.1 lists the CPG pins and their functions.

Table 10.1 Clock Pulse Generator Pins and Functions

Pin Name	Symbol	I/O	Description
Mode control pins	MD0	I	Set the clock operating mode.
	MD1	I	
	MD2	I	
Crystal I/O pins (clock input pins)	XTAL	O	Connects a crystal oscillator.
	EXTAL	I	Connects a crystal oscillator. Also used to input an external clock.
Clock I/O pin	CKIO	I/O	Inputs or outputs an external clock. Level can be fixed during output.
Capacitor connection pins for PLL	CAP1	I	Connects capacitor for PLL circuit 1 operation (recommended value 470 pF).
	CAP2	I	Connects capacitor for PLL circuit 2 operation (recommended value 470 pF).

10.2.3 CPG Register Configuration

Table 10.2 shows the CPG register configuration.

Table 10.2 Register Configuration

Register Name	Abbreviation	R/W	Initial Value	Address	Access Size
Frequency control register	FRQCR	R/W	H'0102	H'FFFFFF80	16

10.3 Clock Operating Modes

Table 10.3 shows the relationship between the mode control pin (MD2–MD0) combinations and the clock operating modes. Table 10.4 shows the usable frequency ranges in the clock operating modes.

Table 10.3 Clock Operating Modes

Mode	Pin Values			Clock I/O		PLL2 On/Off	Div- ider 3	PLL1 On/Off	Divider 1 Input	Divider 2 Input	CKIO Frequency
	MD2	MD1	MD0	Source	Output						
0	0	0	0	EXTAL	CKIO	On multi- plication ratio: 1	Off	ON	PLL1 output	PLL1	(EXTAL)
1	0	0	1	EXTAL	CKIO	On multi- plication ratio: 4	Off	ON	PLL1 output	PLL1	(EXTAL) × 4
2	0	1	0	Crystal oscillator	CKIO	On multi- plication ratio: 4	Off	On	PLL1 output	PLL1	(Crystal) × 4
3	0	1	1	EXTAL	CKIO	On multi- plication ratio: 1	Off	Off (initial value)	PLL2 output	PLL2	(EXTAL) × 1
								On	PLL1 output		
4	1	0	0	Crystal oscillator	CKIO	On multi- plication ratio: 1	Off	Off (initial value)	PLL2 output	PLL2	(Crystal) × 1
								On	PLL1 output		
7	1	1	1	CKIO	—	Off	Off	On	PLL1 output	PLL1	(CKIO)

Mode 0: An external clock is input from the EXTAL pin and undergoes waveform shaping by PLL circuit 2 before being supplied inside the SH7718R. PLL circuit 1 is constantly on, and there are no frequency range restrictions compared to mode 3. An input clock frequency of 16 MHz to 60 MHz can be used, and the CKIO frequency range is 16 MHz to 60 MHz.

As PLL circuit 1 compensates for fluctuations in the CKIO pin load, this mode is suitable for connection of synchronous DRAM.

Mode 1: An external clock is input from the EXTAL pin and its frequency is multiplied by 4 by PLL circuit 2 before being supplied inside the SH7718R, allowing a low-frequency external clock to be used. An input clock frequency of 5 MHz to 15 MHz can be used, and the CKIO frequency range is 20 MHz to 60 MHz.

As PLL circuit 1 compensates for fluctuations in the CKIO pin load, this mode is suitable for connection of synchronous DRAM.

Mode 2: The on-chip crystal oscillator operates, with the oscillation frequency being multiplied by 4 by PLL circuit 2 before being supplied inside the SH7718R, allowing a low crystal frequency to be used. A crystal oscillation frequency of 5 MHz to 15 MHz can be used, and the CKIO frequency range is 20 MHz to 60 MHz.

As PLL circuit 1 compensates for fluctuations in the CKIO pin load, this mode is suitable for connection of synchronous DRAM.

Mode 3: An external clock is input from the EXTAL pin and undergoes waveform shaping by PLL circuit 2 before being supplied inside the SH7718R. PLL circuit 1 is off in the default state at power-on reset, and PLL circuit 1 can be selected as on or off, enabling power consumption to be kept lower than in mode 0. An input clock frequency of 16 MHz to 25 MHz can be used, and the CKIO frequency range is 16 MHz to 25 MHz.

Mode 4: The on-chip crystal oscillator operates, with its output supplied inside the SH7718R as a square waveform by PLL circuit 2. PLL circuit 1 is off in the default state at power-on reset, and PLL circuit 1 can be selected as on or off, enabling power consumption to be reduced accordingly. A crystal oscillation frequency of 16 MHz to 25 MHz can be used, and the CKIO frequency range is 16 MHz to 25 MHz.

Mode 7: In this mode, the CKIO pin is an input, an external clock is input to this pin, and undergoes waveform shaping, and also frequency multiplication according to the setting, by PLL circuit 1 before being supplied to the SH7718R. In modes 0 to 6, the system clock is generated from the output of the SH7718R' CKIO pin. Consequently, if a large number of ICs are operating on the clock cycle, the CKIO pin load will be large. This mode, however, assumes a comparatively large-scale system. If a large number of ICs are operating on the clock cycle, a clock generator with a number of low-skew clock outputs can be provided, so that the ICs can operate synchronously by distributing the clocks to each one.

As PLL circuit 1 compensates for fluctuations in the CKIO pin load, this mode is suitable for connection of synchronous DRAM.

Table 10.4 Range of Usable Frequencies for Each Clock Operating Mode

clock mode	FRQCR	PLL1	PLL2	clock rate* ¹ (I:B:P)	input frequency range	CKIO frequency range
0	H'0100	ON (× 1)	ON (× 1)	1:1:1	16 MHz to 30 MHz	16 MHz to 30 MHz
	H'0101	ON (× 1)	ON (× 1)	1:1:1/2	16 MHz to 60 MHz	16 MHz to 60 MHz
	H'0102	ON (× 1)	ON (× 1)	1:1:1/4	16 MHz to 60 MHz	16 MHz to 60 MHz
	H'0111	ON (× 2)	ON (× 1)	2:1:1	16 MHz to 30 MHz	16 MHz to 30 MHz
	H'0112	ON (× 2)	ON (× 1)	2:1:1/2	16 MHz to 50 MHz	16 MHz to 50 MHz
	H'0115	ON (× 2)	ON (× 1)	1:1:1	16 MHz to 30 MHz	16 MHz to 30 MHz
	H'0116	ON (× 2)	ON (× 1)	1:1:1/2	16 MHz to 50 MHz	16 MHz to 50 MHz
	H'0122	ON (× 4)	ON (× 1)	4:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'0126	ON (× 4)	ON (× 1)	2:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'012A	ON (× 4)	ON (× 1)	1:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'A100	ON (× 3)	ON (× 1)	3:1:1	25 MHz to 30 MHz	25 MHz to 30 MHz
	H'E100	ON (× 3)	ON (× 1)	1:1:1	25 MHz to 30 MHz	25 MHz to 30 MHz
	H'E101	ON (× 3)	ON (× 1)	1:1:1/2	25 MHz to 33.3 MHz	25 MHz to 33.3 MHz
1, 2	H'0100	ON (× 1)	ON (× 4)	4:4:4	5 MHz to 7.5 MHz	20 MHz to 30 MHz
	H'0101	ON (× 1)	ON (× 4)	4:4:2	5 MHz to 15 MHz	20 MHz to 60 MHz
	H'0102	ON (× 1)	ON (× 4)	4:4:1	5 MHz to 15 MHz	20 MHz to 30 MHz
	H'0111	ON (× 2)	ON (× 4)	8:4:4	5 MHz to 7.5 MHz	20 MHz to 30 MHz
	H'0112	ON (× 2)	ON (× 4)	8:4:2	5 MHz to 12.5 MHz	20 MHz to 50 MHz
	H'0115	ON (× 2)	ON (× 4)	4:4:4	5 MHz to 7.5 MHz	20 MHz to 50 MHz
	H'0116	ON (× 2)	ON (× 4)	4:4:2	5 MHz to 12.5 MHz	20 MHz to 50 MHz
	H'A100	ON (× 3)	ON (× 4)	12:4:4	5 MHz to 7.5 MHz	20 MHz to 30 MHz
	H'E100	ON (× 3)	ON (× 4)	4:4:4	5 MHz to 7.5 MHz	20 MHz to 30 MHz
	H'E101	ON (× 3)	ON (× 4)	4:4:2	5 MHz to 8.3 MHz	20 MHz to 33.3 MHz
3	H'0100	OFF	ON (× 1)	1:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'0101	OFF	ON (× 1)	1:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'0102	OFF	ON (× 1)	1:1:1/4	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01D0	ON (× 2)	ON (× 1)	2:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01D1	ON (× 2)	ON (× 1)	2:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01D2	ON (× 2)	ON (× 1)	2:1:1/4	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01D4	ON (× 2)	ON (× 1)	1:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01D5	ON (× 2)	ON (× 1)	1:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
H'01D6	ON (× 2)	ON (× 1)	1:1:1/4	16 MHz to 25 MHz	16 MHz to 25 MHz	

Table 10.4 Range of Usable Frequencies for Each Clock Operating Mode (cont)

clock mode	FRQCR	PLL1	PLL2	clock rate* ¹ (I:B:P)	input frequency range	CKIO frequency range
3	H'81C0	ON (× 3)	ON (× 1)	3:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'81C1	ON (× 3)	ON (× 1)	3:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'C1C0	ON (× 3)	ON (× 1)	1:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'C1C1	ON (× 3)	ON (× 1)	1:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E0	ON (× 4)	ON (× 1)	4:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E1	ON (× 4)	ON (× 1)	4:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E4	ON (× 4)	ON (× 1)	2:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E5	ON (× 4)	ON (× 1)	2:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E6	ON (× 4)	ON (× 1)	2:1:1/4	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E8	ON (× 4)	ON (× 1)	1:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01E9	ON (× 4)	ON (× 1)	1:1:1/2	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'01EA	ON (× 4)	ON (× 1)	1:1:1/4	16 MHz to 25 MHz	16 MHz to 25 MHz
	4	H'0100	OFF	ON (× 1)	1:1:1	16 MHz to 20 MHz
H'0101		OFF	ON (× 1)	1:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'0102		OFF	ON (× 1)	1:1:1/4	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01D0		ON (× 2)	ON (× 1)	2:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01D1		ON (× 2)	ON (× 1)	2:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01D2		ON (× 2)	ON (× 1)	2:1:1/4	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01D4		ON (× 2)	ON (× 1)	1:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01D5		ON (× 2)	ON (× 1)	1:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01D6		ON (× 2)	ON (× 1)	1:1:1/4	16 MHz to 20 MHz	16 MHz to 20 MHz
H'81C0		ON (× 3)	ON (× 1)	3:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'81C1		ON (× 3)	ON (× 1)	3:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'C1C0		ON (× 3)	ON (× 1)	1:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'C1C1		ON (× 3)	ON (× 1)	1:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E0		ON (× 4)	ON (× 1)	4:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E1		ON (× 4)	ON (× 1)	4:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E4		ON (× 4)	ON (× 1)	2:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E5		ON (× 4)	ON (× 1)	2:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E6		ON (× 4)	ON (× 1)	2:1:1/4	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E8		ON (× 4)	ON (× 1)	1:1:1	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01E9		ON (× 4)	ON (× 1)	1:1:1/2	16 MHz to 20 MHz	16 MHz to 20 MHz
H'01EA	ON (× 4)	ON (× 1)	1:1:1/4	16 MHz to 20 MHz	16 MHz to 20 MHz	

Table 10.4 Range of Usable Frequencies for Each Clock Operating Mode (cont)

clock mode	FRQCR	PLL1	PLL2	clock rate* ¹ (I:B:P)	input frequency range	CKIO frequency range
7	H'0100	ON (× 1)	OFF	1:1:1	16 MHz to 30 MHz	16 MHz to 30 MHz
	H'0101	ON (× 1)	OFF	1:1:1/2	16 MHz to 60 MHz	16 MHz to 60 MHz
	H'0102	ON (× 1)	OFF	1:1:1/4	16 MHz to 60 MHz	16 MHz to 60 MHz
	H'0111	ON (× 2)	OFF	2:1:1	16 MHz to 30 MHz	16 MHz to 30 MHz
	H'0112	ON (× 2)	OFF	2:1:1/2	16 MHz to 50 MHz	16 MHz to 50 MHz
	H'0115	ON (× 2)	OFF	1:1:1	16 MHz to 30 MHz	16 MHz to 30 MHz
	H'0116	ON (× 2)	OFF	1:1:1/2	16 MHz to 50 MHz	16 MHz to 50 MHz
	H'0122	ON (× 4)	OFF	4:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'0126	ON (× 4)	OFF	2:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'012A	ON (× 4)	OFF	1:1:1	16 MHz to 25 MHz	16 MHz to 25 MHz
	H'A100	ON (× 3))	OFF	3:1:1	25 MHz to 30 MHz	25 MHz to 30 MHz
	H'E100	ON (× 3)	OFF	1:1:1	25 MHz to 30 MHz	25 MHz to 30 MHz
	H'E101	ON (× 3)	OFF	1:1:1/2	25 MHz to 33.3 MHz	25 MHz to 33.3 MHz

Notes: 1. Input clock frequency is 1

2. Max frequency : I \emptyset = 100MHz, B \emptyset = (CKIO) = 60MHz, P \emptyset = 30MHz

Cautions:

- When clock operating modes 3 and 4 are used:
 - The on/off state of PLL circuit 1 is set by the frequency control register.
 - PLL circuit 1 is initialized to the off state by a power-on reset.
 - Always turn PLL circuit 1 off before going into standby mode.
- The input to divider 1 becomes the output of:
 - PLL circuit 1 when PLL circuit 1 is on.
 - PLL circuit 2 when PLL circuit 1 is off and PLL circuit 2 is on.
 - Divider 3 when PLL circuit 1 is off and PLL circuit 2 is off.
- The input of divider 2 becomes the output of:
 - PLL circuit 1 when the clock operating mode is 0–2 or 7.
 - PLL circuit 2 when the clock operating mode is 3 and 4 and PLL circuit 2 is on.
 - Divider 3 when the clock operating mode is 3 and 4 and PLL circuit 2 is off.
- The frequency of the internal clock (I \emptyset) becomes:
 - The product of the frequency of the CKIO pin, the frequency multiplication ratio of PLL circuit 1, and the division ratio of divider 1 when PLL circuit 1 is on.
 - Equal to the frequency of CKIO pin when PLL circuit 1 is off.

- Do not set the internal clock frequency lower than the CKIO pin frequency.
5. The frequency of the peripheral clock (P ϕ) becomes:
 - The product of the frequency of the CKIO pin, the frequency multiplication ratio of PLL circuit 1, and the division ratio of divider 2 when the clock operating mode is 0–2 or 7.
 - The product of the frequency of the CKIO pin and the division ratio of divider 2 when the clock operating mode is 3 and 4.
 - The peripheral clock frequency should not be set higher than the frequency of the CKIO pin, higher than 33.3 MHz, or lower than 1/8 the internal clock (I ϕ).
 6. The output frequency of PLL circuit 1 is the product of the CKIO frequency and the multiplication ratio of PLL circuit 1. This frequency should be equal to or lower than 100 MHz.
 7. $\times 1$, $\times 2$, $\times 3$ or $\times 4$ can be used as the multiplication ratio of PLL circuit 1. $\times 1$, $\times 1/2$, and $\times 1/4$ can be selected as the division ratios of dividers 1 and 2. Set the rate in the frequency control register. The on/off state of PLL circuit 2 is determined by the mode.
 8. For more information about the range of usable frequencies for each clock operating mode, see table 10.4.

10.4 Register Descriptions

10.4.1 Frequency Control Register (FRQCR)

The frequency control register (FRQCR) is a 16-bit read/write register used to specify whether a clock is output from the CKIO pin, the on/off state of PLL circuit 1, PLL standby, the frequency multiplication ratio of PLL circuit 1, and the frequency division ratio of the internal clock and the peripheral clock.

Only word access can be used on the FRQCR register. FRQCR is initialized to H'0102 by a power-on reset, but retains its value in a manual reset and in standby mode.

FRQCR:

Bit:	15	14	13	12	11	10	9	8
Bit name:	STC2	IFC2	PFC2	—	—	—	—	CKOEN
Initial value:	0	0	0	0	0	0	0	1
R/W:	R/W	R/W	R/W	R	R	R	R	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	PLLEN	PSTBY	STC1	STC0	IFC1	IFC0	PFC1	PFC0
Initial value:	0	0	0	0	0	0	1	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15, 5 and 4—Frequency Multiplication Ratio (STC): These bits specify the frequency multiplication ratio of PLL circuit 1.

Bit 15: STC2	Bit 5: STC1	Bit 4: STC0	Description
0	0	0	× 1 (Initial value)
0	0	1	× 2
1	0	0	× 3
1	1	0	× 4

Note: Do not set the output frequency of PLL circuit 1 higher than 100MHz.

Bits 14, 3 and 2—Internal Clock Frequency Division Ratio (IFC): These bits specify the frequency division ratio of the internal clock with respect to the output frequency of PLL circuit 1. When PLL circuit 1 is off or in standby mode, set × 1.

Bit 14: IFC2	Bit 2: IFC1	Bit 1: IFC0	Description
0	0	0	× 1 (Initial value)
0	0	1	× 1/2
1	0	0	× 1/3
1	1	0	× 1/4

Note: Do not set the internal clock frequency lower than the CKIO frequency.

Bits 13, 1 and 0—Peripheral Clock Frequency Division Ratio (PFC): These bits specify the division ratio of the peripheral clock frequency with respect to the frequency of the output frequency of PLL circuit 1 or the frequency of the CKIO pin.

Bit 13: PFC2	Bit 1: PFC1	Bit 0: PFC0	Description
0	0	0	× 1
0	0	1	× 1/2
1	0	0	× 1/3
1	1	0	× 1/4

Note: Do not set the peripheral clock frequency higher than the frequency of the CKIO pin.

Bits 12 to 9—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 8—Clock Enable (CKOEN): Used to output a clock from the CKIO pin or to fix the level of the CKIO pin in clock operation modes 3 and 4. Even when the level is fixed, the SH7718R will operate internally at the frequency before the level was fixed. In case of clock operating mode 7, the CKIO pin becomes an input pin irrespective of the value of this bit.

Bit 8: CKOEN	Description
0	Fixes the level of CKIO terminal.
1	Outputs a clock from the CKIO pin. (Initial value)

Bit 7—PLL Circuit Enable (PLEN): Specifies the on/off state of PLL circuit 1. This bit is valid in clock operating modes 3 and 4. PLL circuit 1 goes on when the clock operating mode is 0–2 or 7 irrespective of the value of PLEN.

Bit 7: PLEN	Description
0	PLL circuit 1 is not used. (Initial value)
1	PLL circuit 1 is used.

Bit 6—PLL Standby (PSTBY): Specifies PLL standby. When PLL standby is active, PLL circuit 1 will be in standby mode at the frequency specified by the STC bit. This function is valid in clock operating modes 3 and 4.

Bit 6: PSTBY	Description
0	PLL is not in standby mode. (Initial value)
1	PLL is in standby mode.

10.5 Changing the Frequency

The frequency of the internal clock and peripheral clock can be changed either by changing the multiplication rate of PLL circuit 1 or by changing the division rates of dividers 1 and 2. All of these are controlled by software through the frequency control register. The methods are described below. In modes 3–6, the frequency can also be changed by turning PLL circuit 1 on and off, as described in section 10.6, PLL Standby Function.

10.5.1 Changing the Multiplication Rate

A PLL settling time is required when the multiplication rate of PLL circuit 1 is changed. The on-chip WDT counts the settling time.

1. In the initial state, the multiplication rate of PLL circuit 1 is 1.
2. Set a value that will become the specified oscillation settling time in the WDT and stop the WDT. The following must be set:
WTCSR register TME bit = 0: WDT stops
WTCSR register CKS2–CKS0 bits: Division ratio of WDT count clock
WTCNT counter: Initial counter value
3. Set the desired value in the STC2 and STC0 bits. The division ratio can also be set in the IFC2–IFC0 bits and PFC2–PFC0 bits.
4. The processor pauses internally and the WDT starts incrementing. In clock modes 0–2 and 7, the internal and peripheral clocks both stop. In clock modes 3 and 4, only the internal clock stops. The clock will continue to be output at the CKIO pin as long as the CKOEN bit in the FRQCR register is set to 1.
5. Supply of the clock that has been set begins at WDT count overflow, and the processor begins operating again. The WDT stops after it overflows.

10.5.2 Changing the Division Ratio

The WDT will not count unless the multiplication rate is changed simultaneously.

1. In the initial state, IFC2–IFC0 = 000 and PFC2–PFC0 = 010.
2. Set the IFC2–IFC0 and PFC2–PFC0 bits to the new division ratio. The values that can be set are limited by the clock mode and the multiplication rate of PLL circuit 1. Note that if the wrong value is set, the processor will malfunction.
3. The clock is immediately supplied at the new division ratio.

10.6 PLL Standby Function

10.6.1 Overview of the PLL Standby Function

When operating in clock modes 3 and 4, the internal clock can be controlled by turning the PLL1 circuit on and off. A long oscillation settling time is required, however, when the PLL circuit is started up from a complete halt. During this time, processor operation halts. To enable fast on/off switching of the PLL1 circuit, the PLL standby function is provided. This function is controlled by software using the frequency control register. The use of the PLL standby function is described below.

10.6.2 Usage

From Off to On:

1. Initially, PSTBY = 0, PLEN = 0, and PLL circuit 1 is stopped. The output of PLL circuit 2 is used for divider 1 input.
2. When the multiplication rate of PLL circuit 1 is set in the STC2–STC0 bits and PSTBY is set to 1, PLL circuit 1 begins oscillating at the specified multiplication rate. The input to divider 1 is still the output of PLL circuit 2 at this point.
3. After PLL circuit 1 oscillation has stabilized, the input of divider 1 switches when PLEN is set to 1 and the oscillation output of PLL circuit 1 is divided and becomes the internal clock. At this time, the division ratio can be changed by changing the settings of IFC2–IFC0 and PFC2–PFC0. For several cycles before and after the clock switches, the internal clock will be stopped, but the peripheral clock and CKIO output do not stop.

From On to Off:

1. When PLEN is set to 0, the input of divider 1 switches to the output of PLL circuit 2. At this time, the division ratio can be changed by changing the settings of IFC2–IFC0 and PFC2–PFC0.
2. When PSTBY is set to 0, PLL circuit 1 stops. This setting can be performed simultaneously (and with the same instruction as) the setting in 1 above.

- Notes:
1. There are some restrictions on the PLL standby state (PSTBY = 1, PLEN = 0) as follows: The settings of the frequency control register's CKOEN, STC2–STC0, IFC2–IFC0 and PFC2–PFC0 bits generally cannot be changed. In some cases, however, they can be changed if the PSTBY and PLEN bit settings are also changed simultaneously (figure 10.2). The SLEEP instruction cannot be executed.
 2. It is the responsibility of software to ensure the oscillation settling time. If PLEN is set to 1 before the oscillation has settled, malfunctions may be caused by an unstable clock.

3. In clock modes 3 and 4, the SH7718R cannot go to standby mode while PLL circuit 1 is on. Always set PSTBY and PLEN to 0 to stop PLL circuit 1 before going to standby mode.
4. When PSTBY and PLEN are both changed from 0 to 1 together, the WDT will automatically start counting and the clock will switch when the WDT overflows. See section 10.5, Changing the Frequency, for setting the WDT.

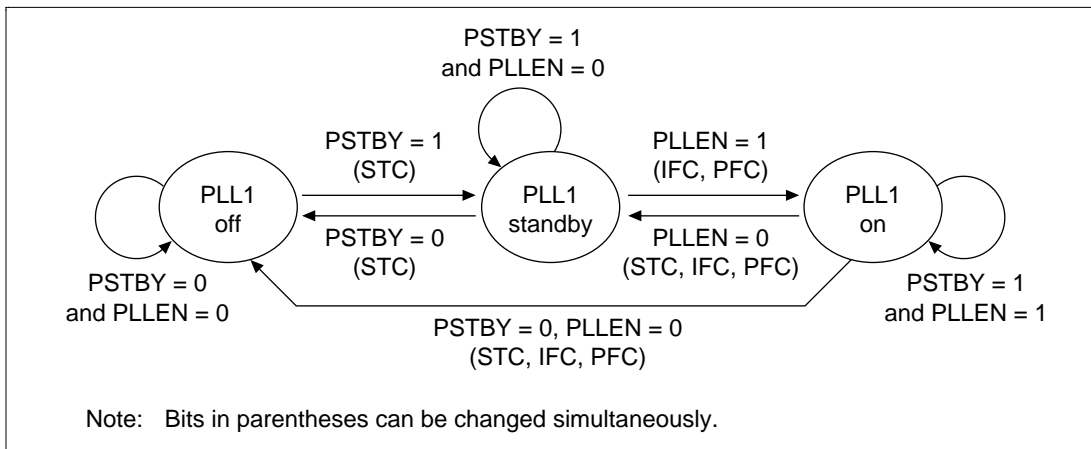


Figure 10.2 State Transitions for the PLL Standby Function

10.7 Controlling Clock Output

The CKOEN bit in the FRQCR register can be used to switch between outputting a clock to the CKIO pin or having the level fixed.

10.7.1 Clock Modes 0–2

The CKIO pin level cannot be fixed. Always set the CKOEN bit in FRQCR to 1 (clock output).

10.7.2 Clock Modes 3 and 4

The CKIO output changes as soon as the CKOEN bit is changed. When the WDT is started by simultaneously changing the multiplication rate of PLL circuit 1 or switching PLL circuit 1 on or off, the WDT starts running after the CKIO output is switched, and then the internal clock changes.

10.8 Overview of the Watchdog Timer (WDT)

10.8.1 Block Diagram of the WDT

Figure 10.3 shows a block diagram of the WDT.

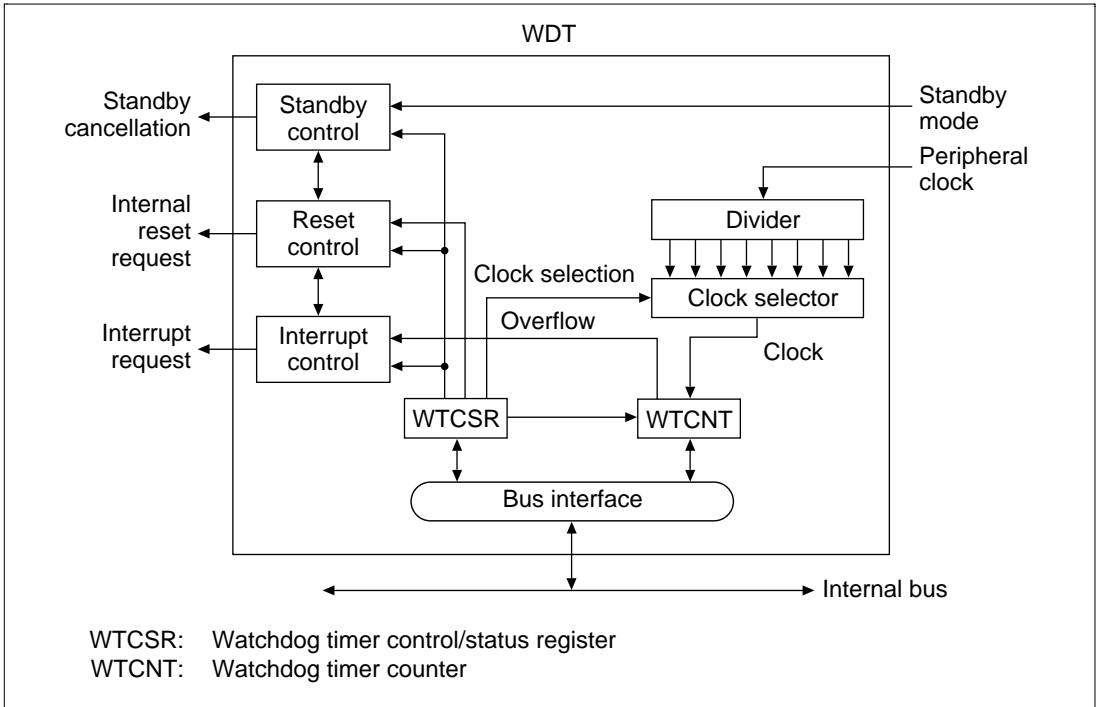


Figure 10.3 Block Diagram of the WDT

10.8.2 Register Configurations

The WDT has two registers that select the clock, switch the timer mode, and perform other functions. Table 10.5 shows the WDT register.

Table 10.5 Register Configuration

Name	Abbreviation	R/W	Size	Initial Value	Address
Watchdog timer counter	WTCNT	R/W*	R: byte; W: word*	H'00	H'FFFFFF84
Watchdog timer control/status register	WTCSR	R/W*	R: byte; W: word*	H'00	H'FFFFFF86

Note: * Write with a word access. Write H'5A and H'A5, respectively, in the upper bytes. Byte or longword writes are not possible. Read with a byte access.

10.9 WDT Registers

10.9.1 Watchdog Timer Counter (WTCNT)

The watchdog timer counter (WTCNT) is an 8-bit read/write counter that increments on the selected clock. When an overflow occurs, it generates a reset in watchdog timer mode and an interrupt in interval time mode. Its address is H'FFFFFF84. The WTCNT counter is initialized to H'00 only by a power-on reset through the RESET pin. Use a word access to write to the WTCNT counter, with H'5A in the upper byte. Use a byte access to read WTCNT.

Bit:	7	6	5	4	3	2	1	0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

10.9.2 Watchdog Timer Control/Status Register (WTCSR)

The watchdog timer control/status register (WTCSR) is an 8-bit read/write register composed of bits to select the clock used for the count, bits to select the timer mode, and overflow flags. Its address is H'FFFFFF86. The WTCSR register is initialized to H'00 only by a power-on reset through the RESET pin. When a WDT overflow causes an internal reset, the WTCSR retains its value. When used to count the clock settling time for canceling a standby, it retains its value after counter overflow. Use a word access to write to the WTCSR counter, with H'A5 in the upper byte. Use a byte access to read WTCSR.

Bit:	7	6	5	4	3	2	1	0
	TME	WT/ \bar{T}	RSTS	WOVF	IOVF	CKS2	CKS1	CKS0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 7—Timer Enable (TME): Starts and stops timer operation. Clear this bit to 0 when using the WDT in standby mode or when changing the clock frequency.

Bit 7: TME	Description
0	Timer disabled: Count-up stops and WTCNT value is retained
1	Timer enabled

Bit 6—Timer Mode Select (WT/IT̄): Selects whether to use the WDT as a watchdog timer or an interval timer.

Bit 6: WT/IT̄	Description
0	Use as interval timer (Initial value)
1	Use as watchdog timer

Note: If WT/IT̄ is modified when the WDT is running, the up-count may not be performed correctly.

Bit 5—Reset Select (RSTS): Selects the type of reset when the WTCNT overflows in watchdog timer mode. In interval timer mode, this setting is ignored.

Bit 5: RSTS	Description
0	Power-on reset (Initial value)
1	Manual reset

Bit 4—Watchdog Timer Overflow (WOVF): Indicates that the WTCNT has overflowed in watchdog timer mode. This bit is not set in interval timer mode.

Bit 4: WO VF	Description
0	No overflow (Initial value)
1	WTCNT has overflowed in watchdog timer mode

Bit 3—Interval Timer Overflow (IOVF): Indicates that the WTCNT has overflowed in interval timer mode. This bit is not set in watchdog timer mode.

Bit 3: IO VF	Description
0	No overflow (Initial value)
1	WTCNT has overflowed in interval timer mode

Bits 2 to 0—Clock Select 2–0 (CKS2–CKS0): These bits select the clock to be used for the WTCNT count from the eight types obtainable by dividing the peripheral clock. The overflow period in the table is the value when the peripheral clock (P_ϕ) is 15 MHz.

Bit 2: CKS2	Bit 1: CKS1	Bit 0: CKS0	Clock Division Ratio	Overflow Period (when P ₀ = 15 MHz)
0	0	0	1 (Initial value)	17 μs
		1	1/4	68 μs
	1	0	1/16	273 μs
		1	1/32	546 μs
1	0	0	1/64	1.09 ms
		1	1/256	4.36 ms
	1	0	1/1024	17.46 ms
		1	1/4096	69.84 ms

Note: If bits CKS2–CKS0 are modified when the WDT is running, the up-count may not be performed correctly. Ensure that these bits are modified only when the WDT is not running.

10.9.3 Notes on Register Access

The watchdog timer counter (WTCNT) and watchdog timer control/status register (WTCSR) are more difficult to write to than other registers. The procedure for writing to these registers are given below.

Writing to WTCNT and WTCSR: These registers must be written by a word transfer instruction. They cannot be written by a byte or longword transfer instruction. When writing to WTCNT, set the upper byte to H'5A and transfer the lower byte as the write data, as shown in figure 10.4. When writing to WTCSR, set the upper byte to H'A5 and transfer the lower byte as the write data. This transfer procedure writes the lower byte data to WTCNT or WTCSR.

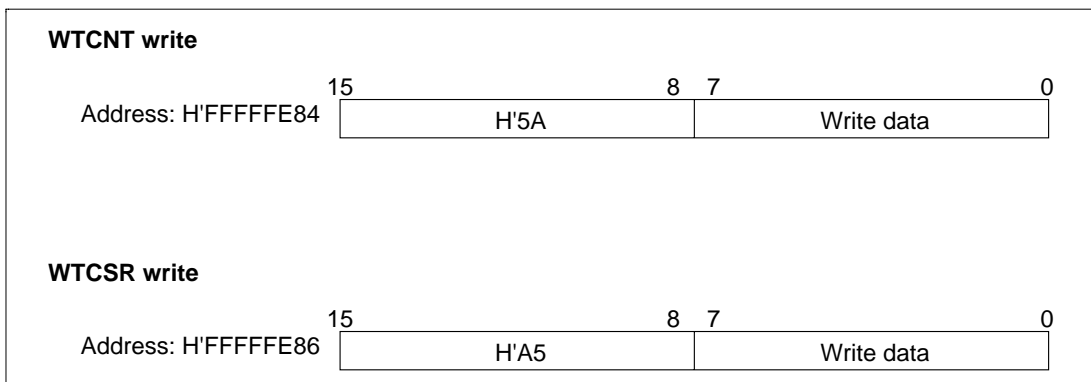


Figure 10.4 Writing to WTCNT and WTCSR

10.10 Using the WDT

10.10.1 Canceling Standbys

The WDT can be used to cancel standby mode with an NMI or other interrupts. The procedure is described below. (The WDT does not run when resets are used for canceling, so keep the RESET pin low until the clock stabilizes.)

1. Before transitioning to standby mode, always clear the TME bit in WTCSR to 0. When the TME bit is 1, an erroneous reset or interval timer interrupt may be generated when the count overflows.
2. Set the type of count clock used in the CKS2–CKS0 bits in WTCSR and the initial values for the counter in the WTCNT counter. These values should ensure that the time till count overflow is longer than the clock oscillation settling time.
3. Move to standby mode by executing a SLEEP instruction to stop the clock.
4. The WDT starts counting by detecting the edge change of the NMI signal or detecting interrupts.
5. When the WDT count overflows, the CPG starts supplying the clock and the processor resumes operation. The WOVF flag in WTCSR is not set when this happens.
6. The counter stops at the values H'00–H'01. The stop value depends on the clock ratio.

10.10.2 Changing the Frequency

To change the frequency used by the PLL, use the WDT. When changing the frequency only by switching the divider, do not use the WDT.

1. Before changing the frequency, always clear the TME bit in WTCSR to 0. When the TME bit is 1, an erroneous reset or interval timer interrupt may be generated when the count overflows.
2. Set the type of count clock used in the CKS2–CKS0 bits of WTCSR and the initial values for the counter in the WTCNT counter. These values should ensure that the time till count overflow is longer than the clock oscillation settling time.
3. When the frequency control register (FRQCR) is written, the clock stops and the processor enters standby mode temporarily. The WDT starts counting.
4. When the WDT count overflows, the CPG resumes supplying the clock and the processor resumes operation. The WOVF flag in WTCSR is not set when this happens.
5. The counter stops at the values H'00–H'01. The stop value depends on the clock ratio.

10.10.3 Using Watchdog Timer Mode

1. Set the $\overline{WT/IT}$ bit in the WTCSR register to 1, set the reset type in the RSTS bit, set the type of count clock in the CKS2–CKS0 bits, and set the initial value of the counter in the WTCNT counter.
2. Set the TME bit in WTCSR to 1 to start the count in watchdog timer mode.
3. While operating in watchdog timer mode, rewrite the counter periodically to H'00 to prevent the counter from overflowing.
4. When the counter overflows, the WDT sets the WOVF flag in WTCSR to 1 and generates the type of reset specified by the RSTS bit. The counter then resumes counting.

10.10.4 Using Interval Timer Mode

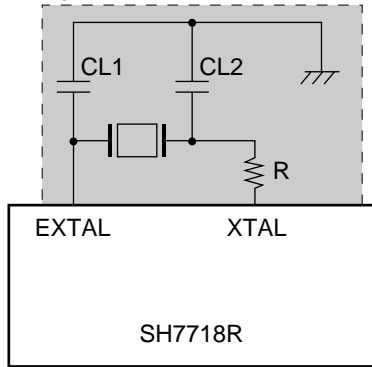
When operating in interval timer mode, interval timer interrupts are generated at every overflow of the counter. This enables interrupts to be generated at set periods.

1. Clear the $\overline{WT/IT}$ bit in the WTCSR register to 0, set the type of count clock in the CKS2–CKS0 bits, and set the initial value of the counter in the WTCNT counter.
2. Set the TME bit in WTCSR to 1 to start the count in interval timer mode.
3. When the counter overflows, the WDT sets the IOVF flag in WTCSR to 1 and an interval timer interrupt request is sent to INTC. The counter then resumes counting.

10.11 Notes on Board Design

When Using an External Crystal Resonator: Place the crystal resonator, capacitors CL1 and CL2, and damping resistor R close to the EXTAL and XTAL pins. To prevent induction from interfering with correct oscillation, use a common grounding point for the capacitors connected to the resonator, and do not locate a wiring pattern near these components.

Avoid crossing
signal lines



Note: The values for CL1, CL2, and the damping resistance should be determined after consultation with the crystal resonator manufacturer.

Figure 10.5 Points for Attention when Using Crystal Resonator

Decoupling Capacitors: As far as possible, insert a laminated ceramic capacitor of 0.01 to 0.1 μF as a passive capacitor for each $V_{\text{SS}}/V_{\text{CC}}$ pair. Mount the passive capacitors as close as possible to the LSI power supply pins, and use components with a frequency characteristic suitable for the LSI operating frequency, as well as a suitable capacitance value.

Digital system $V_{\text{SS}}/V_{\text{CC}}$ pairs: 6-7, 17-18, 19-20, 30-31, 41-42, 49-50, 54-55, 59-60, 68-69, 82-81,83, 100-102, 115-116, 121-122, 127-128, 144-139

On-chip oscillator $V_{\text{SS}}/V_{\text{CC}}$ pairs: 73-75, 76-78, 138-135

When Using a PLL Oscillator Circuit: Keep the wiring from the PLL V_{CC} and V_{SS} connection pattern to the power supply pins short, and make the pattern width large, to minimize the inductance component. Ground the oscillation stabilization capacitors C1 and C2 to V_{SS} (PLL1) and V_{SS} (PLL2), respectively. Place C1 and C2 close to the CAP1 and CAP2 pins and do not locate a wiring pattern in the vicinity. In clock mode 7, connect the EXTAL pin to V_{CC} or V_{SS} and leave the XTAL pin open.

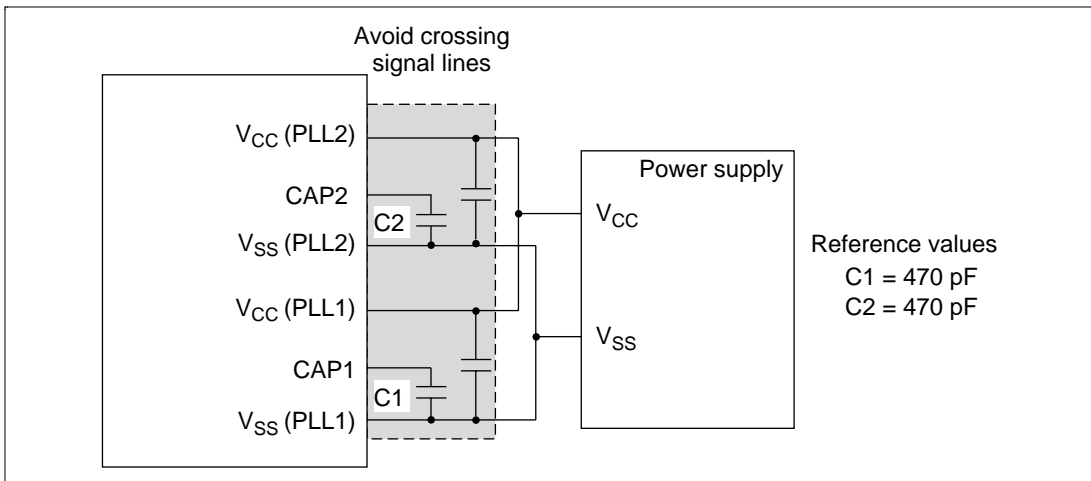


Figure 10.6 Points for Attention when Using PLL Oscillator Circuit

Power Supply Pin Wiring: To prevent mutual interference between power supply pins V_{CC} (PLL1), V_{CC} (PLL2) and power supply pins V_{SS} (PLL1), V_{SS} (PLL2), use independent wiring patterns for these two systems, and also other digital V_{CC} and V_{SS} pins, from the power supply source.

External Device Connection: When connecting a device such as synchronous DRAM that requires timing adjustment, since the AC characteristics are based on the connection of a 30 pF capacitive load to the CKIO output, the total capacitive load of CKIO should be 30 pF or less. If the total capacitive load of the CKIO output exceeds 30 pF, a device requiring timing adjustment should be connected directly to CKIO, while in the case of a device without stringent timing adjustment requirements, the CKIO output should be received by a buffer to allow the total capacitive load of the CKIO output to be reduced.

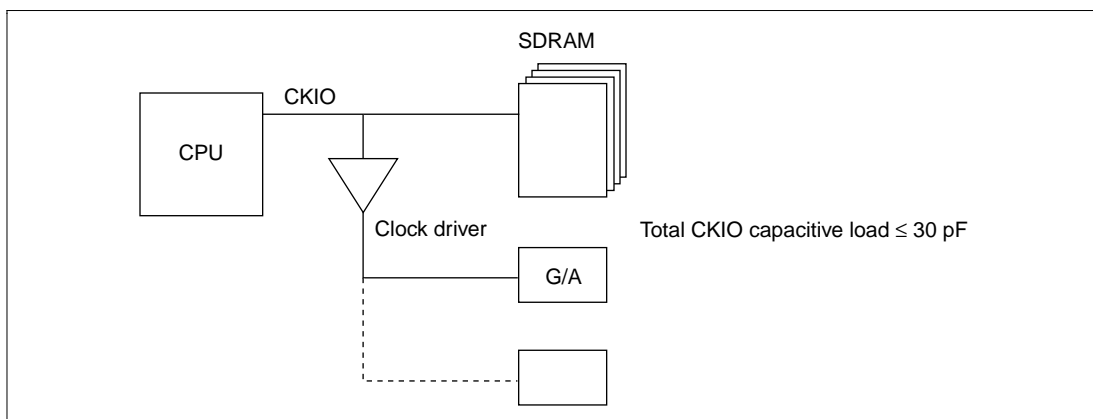


Figure 10.7 System Connection Example

Section 11 Bus State Controller (BSC)

11.1 Overview

The bus state controller (BSC) divides physical address space and outputs control signals for various types of memory and bus interface specifications. BSC functions enable the SH7718R to link directly with DRAM, synchronous DRAM, pseudo-SRAM, SRAM, ROM, and other memory storage devices without an external circuit. The BSC also allows direct connection to PCMCIA interfaces, simplifying system design and allowing high-speed data transfers in a compact system.

11.1.1 Features

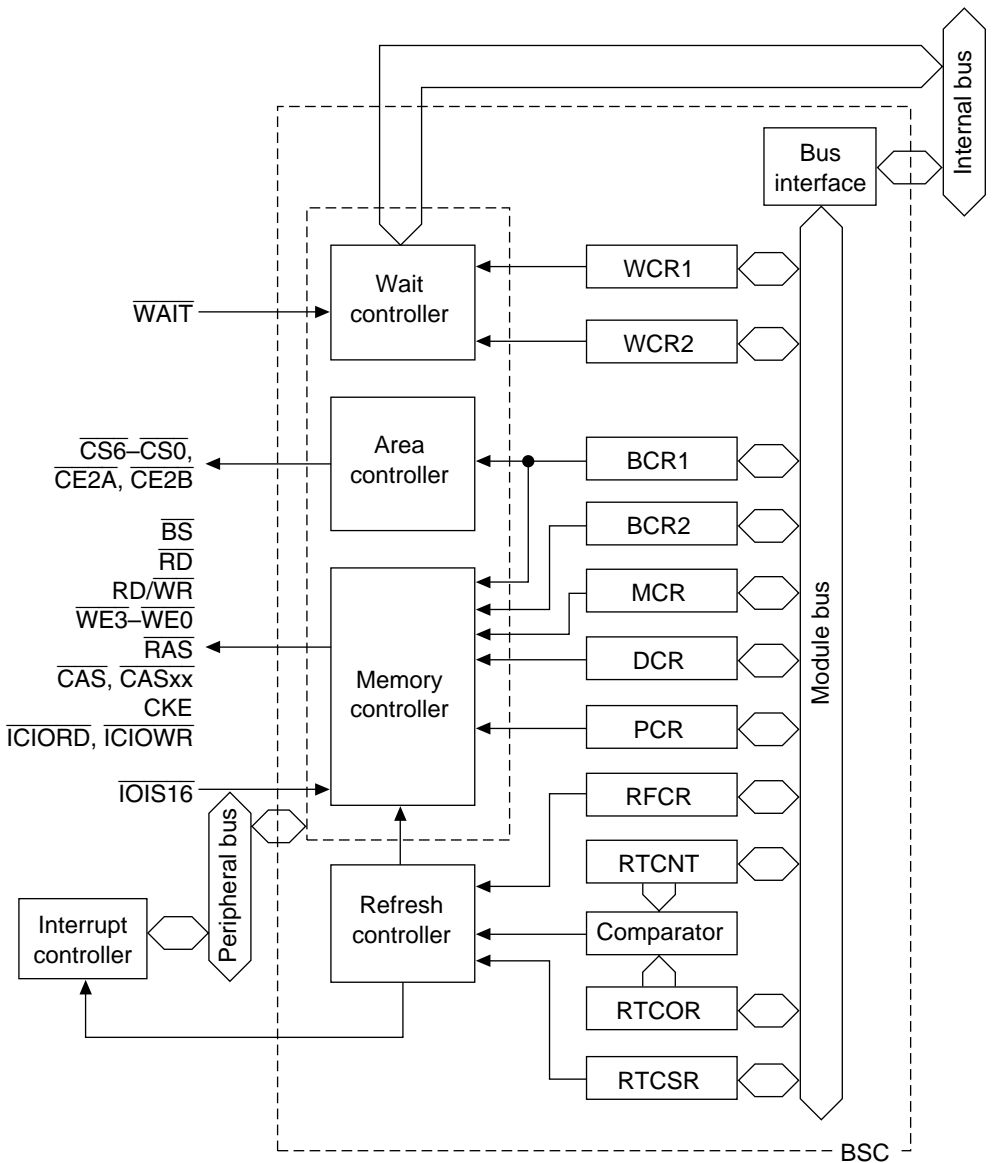
The BSC has the following features:

- Physical address space is divided into seven areas
 - A maximum 64 Mbytes for each of the seven areas, 0–6
 - Area bus width can be selected by register (area 0 is set by external pin)
 - Wait states can be inserted using the WAIT pin
 - Wait state insertion can be controlled through software. Register settings can be used to specify the insertion of 1–10 cycles independently for each area (areas 1 and 2 have a common setting)
 - The type of memory connected can be specified for each area, and control signals are output for direct memory connection
 - Wait cycles are automatically inserted to avoid data bus conflict for continuous memory accesses to different areas or writes directly following reads of the same area
- Direct interface to DRAM
 - Multiplexes row/column addresses according to DRAM capacity
 - Supports burst operation (high-speed page mode, hyper page mode)
 - Supports CAS-before-RAS refresh and self-refresh
 - Performs low power 4-CAS-system byte control
 - Controls timing of DRAM direct-connection control signals according to register settings
- Direct interface to synchronous DRAM
 - Multiplexes row/column addresses according to synchronous DRAM capacity
 - Supports burst operation
 - Has both auto-refresh and self-refresh functions
 - Controls timing of synchronous DRAM direct-connection control signals according to register setting

- Direct interface to pseudo-SRAM
 - Supports burst operation (static column mode)
 - Auto-refresh and self-refresh
- Burst ROM interface
 - Insertion of wait states controllable through software
 - Register setting control of burst transfers
- PCMCIA direct-connection interface
 - Insertion of wait states controllable through software
 - Burst operation (page mode)
 - Bus sizing function for I/O bus width (little-endian mode only)
- Fine refreshing control
 - Supports refresh operation immediately after self-refresh operation in low-power DRAM by means of refresh counter overflow interrupt function
- Refresh counter can be used as an interval timer
 - Interrupt request generated at compare-match
 - Interrupt request generated at refresh counter overflow

11.1.2 Block Diagram

Figure 11.1 shows a block diagram of the bus state controller.



WCR: Wait state control register
 BCR: Bus control register
 MCR: Memory control register
 DCR: DRAM control register
 PCR: PCMCIA control register

RFCR: Refresh count register
 RTCNT: Refresh timer count register
 RTCOR: Refresh time constant register
 RTCSR: Refresh timer control/status register

Figure 11.1 BSC Block Diagram

11.1.3 Pin Configuration

Table 11.1 lists the BSC pins.

Table 11.1 Pin Configuration

Pin Name	Signal	I/O	Description
Address bus	A25–A0	O	Address output
Data bus	D31–D24, D15–D0	I/O	Data I/O When port function is used, D31–D24 cannot be used. Leave these pins open.
Data bus/port	D23–D16/ PORT7–PORT0	I/O	When port function is not used, data I/O; when port function is used, port (I/O is set by register for each bit)
Bus cycle start	\overline{BS}	O	Shows start of bus cycle. During burst transfers, asserts every data cycle.
Chip select 6–0	$\overline{CS6}$ – $\overline{CS0}$	O	Chip select signal to indicate area being accessed. $\overline{CS5}$ and $\overline{CS6}$ can also be used as $\overline{CE1A}$ and $\overline{CE1B}$ of PCMCIA.
Read/write	RD/\overline{WR}	O	Data bus direction indicator signal. DRAM/synchronous DRAM/PCMCIA write indicator signal.
Row address strobe	$\overline{RAS}/\overline{CE}$	O	When DRAM/synchronous DRAM is used, RAS signal. When pseudo-SRAM is used, \overline{CE} signal.
Column address strobe	$\overline{CAS}/\overline{CASLL}/\overline{OE}$	O	When synchronous DRAM is used, \overline{CAS} signal. When DRAM is used, \overline{CAS} signal for D7–D0. When pseudo-SRAM is used, $\overline{OE}/RFSH$ signal.
Column address strobe LH	\overline{CASLH}	O	When DRAM is used, \overline{CAS} signal for D15–D8
Column address strobe HL	$\overline{CASHL}/\overline{CAS2L}$	O	When DRAM is used, \overline{CAS} signal for D23–D16. When the area 2 DRAM is being used, \overline{CAS} signal for D7–D0.
Column address strobe HH	$\overline{CASHH}/\overline{CAS2H}$	O	When DRAM is used, \overline{CAS} signal for D31–D24. When the area 2 DRAM is being used, \overline{CAS} signal for D15–D8.

Table 11.1 Pin Configuration (cont)

Pin Name	Signal	I/O	Description
Data enable 0	DQMLL/ $\overline{\text{WE0}}$	O	When synchronous DRAM is used, selects D7–D0. For other memory, D7–D0 write strobe signal.
Data enable 1	DQMLU/ $\overline{\text{WE1}}$	O	When synchronous DRAM is used, selects D15–D8. When PCMCIA is used, strobe signal that indicates the write cycle. For other memory, D15–D8 write strobe signal.
Data enable 2	DQMUL/ $\overline{\text{WE2}}$ / $\overline{\text{ICIORD}}$	O	When synchronous DRAM is used, selects D23–D16. For other memory, D23–D16 write strobe signal. For PCMCIA, strobe signal indicating I/O read.
Data enable 3	DQMUU/ $\overline{\text{WE3}}$ / $\overline{\text{ICIOWR}}$	O	When synchronous DRAM is used, selects D31–D24. For other memory, D31–D24 write strobe signal. For PCMCIA, strobe signal indicating I/O write.
Read	$\overline{\text{RD}}$	O	Strobe signal indicating read cycle
Wait	$\overline{\text{WAIT}}$	I	Wait state request signal
16-bit I/O	$\overline{\text{IOIS16}}$	I	Signal indicating PCMCIA 16-bit I/O. Valid only in little-endian mode. (Fix low in big-endian mode.)
Clock enable	CKE	O	Connected to clock enable control signal of synchronous DRAM
Bus release request	$\overline{\text{BREQ}}$	I	Bus release request signal
Bus release acknowledgment	$\overline{\text{BACK}}$	O	Bus release acknowledge signal
Area 0 bus width, PCMCIA card select	MD3/ $\overline{\text{CE2A}}^{*1}$, MD4/ $\overline{\text{CE2B}}^{*2}$	I	Signal controlling bus width of physical space area 0. When PCMCIA is used, $\overline{\text{CE2A}}$ and $\overline{\text{CE2B}}$.
Endian switching/ low address strobe	MD5/ $\overline{\text{RAS2}}^{*3}$	I/O	Signal setting endian for all spaces on reset. When area 2 DRAM is connected, area 2 DRAM RAS signal

- Notes: 1. MD3/ $\overline{\text{CE2A}}$ input/output switching is performed by BCR1.A5PCM. Output is selected when BCR1.A5PCM = 1.
2. MD4/ $\overline{\text{CE2B}}$ input/output switching is performed by BCR1.A6PCM. Output is selected when BCR1.A6PCM = 1.
3. MD5/ $\overline{\text{RAS2}}$ input/output switching is performed by BCR1.DRAMTP. Output is selected when BCR1.DRAMTP (2–0) = 101.

11.1.4 Register Configuration

The BSC has 11 registers (table 11.2). The synchronous DRAM also has a built-in synchronous DRAM mode register. These registers control direct connection interfaces to memory, wait states, refreshes, and PCMCIA devices.

Table 11.2 Register Configuration

Name	Abbr.	R/W	Initial Value	Address	Bus Width
Bus control register 1	BCR1	R/W	H'0000	H'FFFFFF60	16
Bus control register 2	BCR2	R/W	H'3FFC	H'FFFFFF62	16
Wait state control register 1	WCR1	R/W	H'3FFF	H'FFFFFF64	16
Wait state control register 2	WCR2	R/W	H'FFFF	H'FFFFFF66	16
Individual memory control register	MCR	R/W	H'0000	H'FFFFFF68	16
DRAM control register	DCR	R/W	H'0000	H'FFFFFF6A	16
PCMCIA control register	PCR	R/W	H'0000	H'FFFFFF6C	16
Refresh timer control/status register	RTCSR	R/W	H'0000	H'FFFFFF6E	16
Refresh timer counter	RTCNT	R/W	H'0000	H'FFFFFF70	16
Refresh time constant register	RTCOR	R/W	H'0000	H'FFFFFF72	16
Refresh count register	RFCR	R/W	H'0000	H'FFFFFF74	16
SDRAM mode register, area 2	SDMR	W	—	H'FFFD000– H'FFFDFFF	8
SDRAM mode register, area 3			—	H'FFFE000– H'FFFEFFF	

Note: For details see section 11.2.8, Synchronous DRAM Mode Register.

11.1.5 Area Overview

Space Allocation: The SH7718R architecture provides for a 32-bit virtual address space. The virtual space is divided into five areas by the value of the upper bits of the address. The physical space is divided into eight areas with a 29-bit address space.

Virtual space can be allocated at will to physical spaces using a memory management unit (MMU). For details, refer to section 3, Memory Management Unit, which describes area allocation for physical spaces.

As shown in table 11.4, the SH7718R can be connected directly to seven areas of memory/PC card, and it outputs chip select signals ($\overline{CS0}$ – $\overline{CS6}$, $\overline{CE2A}$, $\overline{CE2B}$) for each of them. $\overline{CS0}$ is asserted during area 0 access; $\overline{CS6}$ is asserted during area 6 access. When DRAM, synchronous DRAM, or pseudo-SRAM is connected to area 2 or 3, signals such as \overline{RAS} , \overline{CAS} , $\overline{RD}/\overline{WR}$, and \overline{DQM} are also asserted. When PCMCIA interface is selected in area 5 or 6, in addition to $\overline{CS5}/\overline{CS6}$, $\overline{CE2A}/\overline{CE2B}$ are asserted for the corresponding bytes accessed.

For virtual address spaces P0 and P3, when the memory management unit (MMU) is on, any physical address can be generated by the MMU for a virtual address. Consequently, figure 11.2 can be applied when the MMU is off, and when the MMU is on and the physical addresses corresponding to virtual addresses are identical except for the top 3 bits. When virtual addresses are translated to arbitrary physical addresses, refer to table 11.3, Physical Address Space Map.

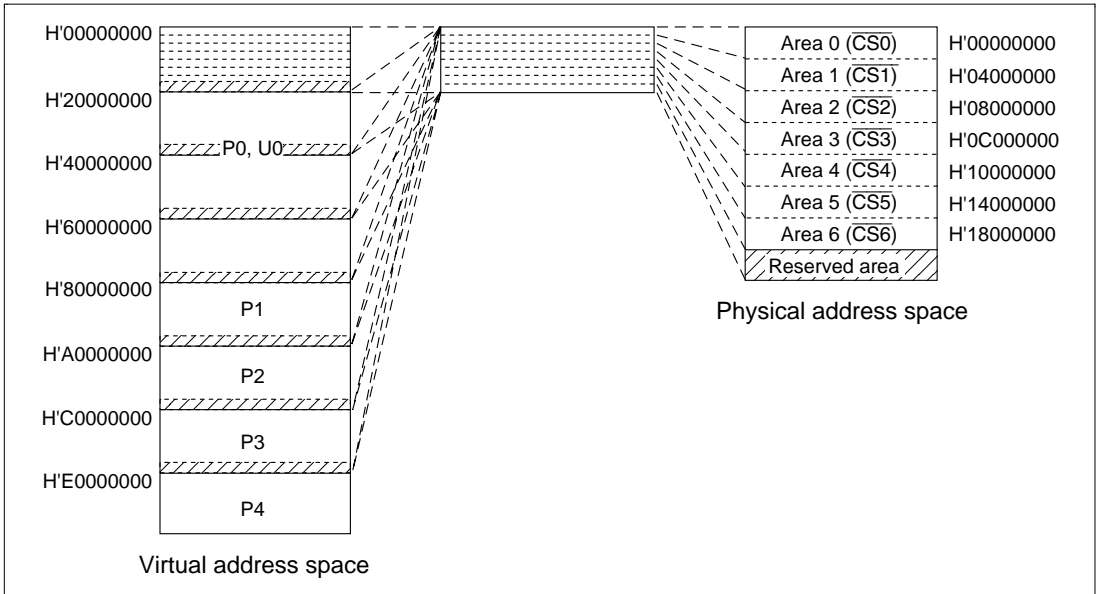


Figure 11.2 Correspondence between Virtual Address Space and Physical Address Space

Table 11.3 Physical Address Space Map

Area	Physical Address	Connectable Memory	Capacity	Access Size
0	H'00000000 to H'03FFFFFF	Normal memory* ¹ , burst ROM	64 Mbytes	8, 16, 32* ²
	H'00000000 + H'20000000 × n to H'03FFFFFF + H'20000000 × n		Shadow	n: 1–6
1	H'04000000 to H'07FFFFFF	Normal memory	64 Mbytes	8, 16, 32* ³
	H'04000000 + H'20000000 × n to H'07FFFFFF + H'20000000 × n		Shadow	n: 1–6
2	H'08000000 to H'0BFFFFFF	Normal memory* ¹ , synchronous DRAM, DRAM	64 Mbytes	8, 16, 32* ³ , * ⁴
	H'08000000 + H'20000000 × n to H'0BFFFFFF + H'20000000 × n		Shadow	n: 1–6
3	H'0C000000 to H'0FFFFFFF	Normal memory, synchronous DRAM, DRAM, pseudo-SRAM	64 Mbytes	8, 16, 32* ³ , * ⁵
	H'0C000000 + H'20000000 × n to H'0FFFFFFF + H'20000000 × n		Shadow	n: 1–6
4	H'10000000 to H'13FFFFFF	Normal memory	64 Mbytes	8, 16, 32* ³
	H'10000000 + H'20000000 × n to H'13FFFFFF + H'20000000 × n		Shadow	n: 1–6
5* ⁵	H'14000000 to H'15FFFFFF	Normal memory, PCMCIA, burst ROM	32 Mbytes	8, 16, 32* ³ , * ⁶
	H'16000000 to H'17FFFFFF		32 Mbytes	
	H'14000000 + H'20000000 × n to H'17FFFFFF + H'20000000 × n		Shadow	n: 1–6
6	H'18000000 to H'19FFFFFF	Normal memory, PCMCIA, burst ROM	32 Mbytes	8, 16, 32* ³ , * ⁶
	H'1A000000 to H'1BFFFFFF		32 Mbytes	
	H'18000000 + H'20000000 × n to H'1BFFFFFF + H'20000000 × n		Shadow	n: 1–6
7* ⁷	H'1C000000 + H'20000000 × n to H'1FFFFFFF + H'20000000 × n	Reserved area		n: 0–7

- Notes:
1. Memory with an SRAM, ROM, or similar interface
 2. Memory bus width specified by external pin
 3. Memory bus width specified by register
 4. With synchronous DRAM interface, bus width is 32 bits only.
With DRAM interface, bus width is 16 bits only.
 5. With synchronous DRAM interface, bus width is 32 bits only.
With DRAM and pseudo-SRAM interface, bus width is either 16 or 32 bits only. When areas 2 and 3 are both DRAM interface areas, bus width is 16 bits only.
 6. With PCMCIA interface, bus width is either 8 or 16 bits only.
 7. Do not access a reserved area, as operation cannot be guaranteed in this case.

Area 0: H'00000000	Normal memory/ burst ROM	
Area 1: H'04000000	Normal memory	
Area 2: H'08000000	Normal memory/ synchronous DRAM, DRAM	Only DRAM with a 16-bit bus can be connected to area 2
Area 3: H'0C000000	Normal memory/synchronous DRAM, DRAM, pseudo-SRAM	
Area 4: H'10000000	Normal memory	
Area 5: H'14000000	Normal memory/ burst ROM/PCMCIA	The PCMCIA interface is for the memory card only
Area 6: H'18000000	Normal memory/ burst ROM/PCMCIA	The PCMCIA interface is shared by the memory and I/O card

Figure 11.3 Physical Space Allocation

Memory Size: The memory size in the SH7718R can be set for each area. In area 0, an external pin can be used to select byte (8 bits), word (16 bits), or longword (32 bits). The relationship between the external pins (MD4 and MD3) and the bus width after a power-on reset is as follows.

MD4	MD3	Bus Width
0	0	Reserved (do not set)
	1	8 bits
1	0	16 bits
	1	32 bits

For areas 1–6, byte, word, and longword may be chosen for the bus width using bus control register 2 (BCR2) whenever normal memory, ROM, burst ROM, or the PCMCIA interface is used. When the DRAM or pseudo-SRAM interfaces are used, word or longword can be chosen as the bus width using the individual memory control register (MCR). Set the bus width to longword with MCR for synchronous DRAM interfaces.

When area 2 is used as a DRAM area, set the bus widths of areas 2 and 3 to word. When areas 5 and 6 are used as PCMCIA interfaces, set the bus width to byte or word. When using the port function, set each of the bus widths to byte or word for all areas. For more information, see section 11.2.2, Bus Control Register 2 (BCR2), and section 11.2.5, Individual Memory Control Register (MCR).

Shadow Space: Areas 0–6 are decoded by physical address bits A28–A26, which correspond to areas 000 to 110. Address bits 31–29 are ignored. This means that the range of area 0 addresses, for example, is H'00000000 to H'03FFFFFF, and its corresponding shadow space is the address space obtained by adding to it H'20000000 × n (n = 1–6). The address range for area 7, which is on-chip I/O space, is H'1C000000 to H'1FFFFFFF. The address space H'1C000000 + H'20000000 × n–H'1FFFFFFF + H'20000000 × n (n = 0–6) corresponding to the area 7 shadow space is reserved, so should not be used.

11.1.6 PCMCIA Support

The SH7718R supports PCMCIA standard interface specifications in physical space areas 5 and 6.

The interface supported is basically the IC memory card interface and I/O card interface defined by JEIDA Version 4.2 (PCMCIA 2.1). In addition, burst access is supported to enable high-speed access.

Physical space area 5 supports the IC memory card interface only; area 6 supports both the IC memory card interface and the I/O card interface.

Table 11.4 PCMCIA Interface Characteristics

Item	Characteristics
Access	Random access + burst access (ROM page mode correspondence added)
Data bus	8/16 bits
Memory type	Mask ROM, OTPROM, EPROM, EEPROM, flash memory, SRAM
Memory capacity	Maximum 32 Mbytes
I/O section capacity	Maximum 32 Mbytes
Other	Supports dynamic I/O bus sizing* and access to PCMCIA interface from both the address translation area and non-address translation area

Note: * Dynamic I/O bus sizing is supported only in little-endian mode.

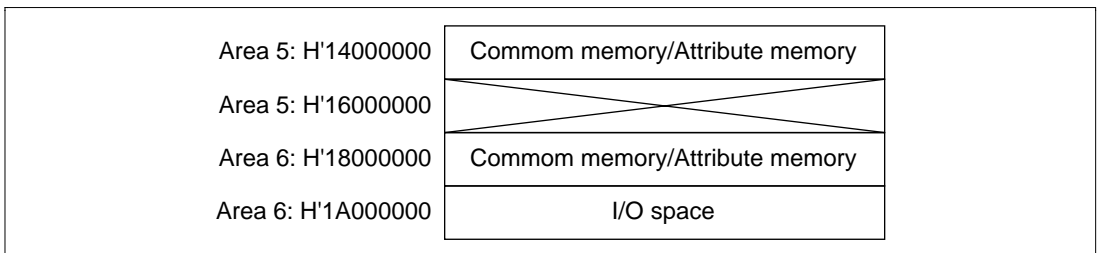


Figure 11.4 PCMCIA Space Allocation

Table 11.5 PCMCIA Support Interface

Pin	IC Memory Card Interface			I/O Card Interface			SH7718R Pin
	Signal	I/O	Function	Signal	I/O	Function	
1	GND	—	Ground	GND	—	Ground	—
2	D3	I/O	Data	D3	I/O	Data	D3
3	D4	I/O	Data	D4	I/O	Data	D4
4	D5	I/O	Data	D5	I/O	Data	D5
5	D6	I/O	Data	D6	I/O	Data	D6
6	D7	I/O	Data	D7	I/O	Data	D7
7	$\overline{CE1}$	I	Card enable	$\overline{CE1}$	I	Card enable	$\overline{CS5}$ or $\overline{CS6}$
8	A10	I	Address	A10	I	Address	A10
9	\overline{OE}	I	Output enable	\overline{OE}	I	Output enable	\overline{RD}
10	A11	I	Address	A11	I	Address	A11
11	A9	I	Address	A9	I	Address	A9
12	A8	I	Address	A8	I	Address	A8
13	A13	I	Address	A13	I	Address	A13
14	A14	I	Address	A14	I	Address	A14
15	$\overline{WE/PGM}$	I	Write enable	$\overline{WE/PGM}$	I	Write enable	$\overline{WE1}$
16	RDY/BSY	O	Ready/Busy	\overline{IREQ}	O	Interrupt request	Sensed at port
17	V_{CC}		Operation power	V_{CC}		Operation power	—
18	VPP1		Program power	VPP1		Program/ peripheral power	—
19	A16	I	Address	A16	I	Address	A16
20	A15	I	Address	A15	I	Address	A15
21	A12	I	Address	A12	I	Address	A12
22	A7	I	Address	A7	I	Address	A7
23	A6	I	Address	A6	I	Address	A6
24	A5	I	Address	A5	I	Address	A5
25	A4	I	Address	A4	I	Address	A4
26	A3	I	Address	A3	I	Address	A3
27	A2	I	Address	A2	I	Address	A2
28	A1	I	Address	A1	I	Address	A1
29	A0	I	Address	A0	I	Address	A0
30	D0	I/O	Data	D0	I/O	Data	D0

Table 11.5 PCMCIA Support Interface (cont)

Pin	IC Memory Card Interface			I/O Card Interface			SH7718R Pin
	Signal	I/O	Function	Signal	I/O	Function	
31	D1	I/O	Data	D1	I/O	Data	D1
32	D2	I/O	Data	D2	I/O	Data	D2
33	WP*	O	Write protect	$\overline{\text{IOIS16}}$	O	16 bit I/O port	$\overline{\text{IOIS16}}$
34	GND		Ground	GND		Ground	—
35	GND		Ground	GND		Ground	—
36	$\overline{\text{CD1}}$	O	Card detection	$\overline{\text{CD1}}$	O	Card detection	Sensed at port
37	D11	I/O	Data	D11	I/O	Data	D11
38	D12	I/O	Data	D12	I/O	Data	D12
39	D13	I/O	Data	D13	I/O	Data	D13
40	D14	I/O	Data	D14	I/O	Data	D14
41	D15	I/O	Data	D15	I/O	Data	D15
42	$\overline{\text{CE2}}$	I	Card enable	$\overline{\text{CE2}}$	I	Card enable	$\overline{\text{CE2A}}$ or $\overline{\text{CE2B}}$
43	RFSH	I	Refresh request	RFSH	I	Refresh request	Output from port
44	RFU		Reserved	$\overline{\text{IORD}}$	I	I/O read	$\overline{\text{ICIORD}}$
45	RFU		Reserved	$\overline{\text{IOWR}}$	I	I/O write	$\overline{\text{ICIOWR}}$
46	A17	I	Address	A17	I	Address	A17
47	A18	I	Address	A18	I	Address	A18
48	A19	I	Address	A19	I	Address	A19
49	A20	I	Address	A20	I	Address	A20
50	A21	I	Address	A21	I	Address	A21
51	V _{CC}		Power supply	V _{CC}		Power supply	—
52	VPP2		Program power	VPP2		Program/ peripheral power	—
53	A22	I	Address	A22	I	Address	A22
54	A23	I	Address	A23	I	Address	A23
55	A24	I	Address	A24	I	Address	A24
56	A25	I	Address	A25	I	Address	Output from port
57	RFU		Reserved	RFU		Reserved	—
58	RESET	I	Reset	RESET	I	Reset	Output from port

Table 11.5 PCMCIA Support Interface (cont)

Pin	IC Memory Card Interface			I/O Card Interface			SH7718R Pin
	Signal	I/O	Function	Signal	I/O	Function	
59	WAIT	O	Wait request	WAIT	O	Wait request	WAIT
60	RFU		Reserved	INPACK	O	Input acknowledge	—
61	REG	I	Attribute memory space select	REG	I	Attribute memory space select	Output from port
62	BVD2	O	Battery voltage detection	SPKR	O	Digital voice signal	Sensed at port
63	BVD1	O	Battery voltage detection	STSCHG	O	Card status change	Sensed at port
64	D8	I/O	Data	D8	I/O	Data	D8
65	D9	I/O	Data	D9	I/O	Data	D9
66	D10	I/O	Data	D10	I/O	Data	D10
67	CD2	O	Card detection	CD2	O	Card detection	Sensed at port
68	GND		Ground	GND		Ground	—

Note: The SH7718R does not provide WP support.

11.2 BSC Registers

11.2.1 Bus Control Register 1 (BCR1)

The bus control register 1 (BCR1) is a 16-bit read/write register that sets the functions and bus cycle status for each area. It is initialized to H'0000 by a power-on reset, but is not initialized by a manual reset or in standby mode. Do not access external memory outside area 0 until BCR1 register initialization is complete.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	HIZMEM	HIZCNT	ENDIAN	A0BST1	A0BST0	A5BST1
Initial value:	0	0	0	0	0/1*	0	0	0
R/W:	R	R	R/W	R/W	R/W	R/W	R/W	R/W

Bit:	7	6	5	4	3	2	1	0
Bit name:	A5BST0	A6BST1	A6BST0	DRAM TP2	DRAM TP1	DRAM TP0	A5PCM	A6PCM
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Note: * Samples the value of the external pin designating endian upon a power-on reset.

Bits 15 and 14—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 13—High-Z Memory Control (HIZMEM): Specifies the state of A25 to A0, BS, CS, RD/WR, WE/DQM, RD, MD3/CE2A, and MD4/CE2B in standby mode.

Bit 13: HIZMEM	Description
0	High-impedance (high-Z) in standby mode (Initial value)
1	Drive state in standby mode

Bit 12—High-Z Control (HIZCNT): Specifies the state of the RAS and CAS signals in the standby and bus-released states.

Bit 12: HIZCNT	Description
0	RAS and CAS signals become high-impedance (High-Z) in standby mode and in bus-released state. (Initial value)
1	RAS and CAS signals drive in standby mode and in bus-released state.

Bit 11—Endian Flag (ENDIAN): Samples the value of the external pin designating endian upon a power-on reset. Endian for all physical spaces is decided by this bit, which is read-only.

Bit 11: ENDIAN	Description
0	(On reset) Endian setting external pin (MD5) is low. Indicates the SH7718R is set as big-endian.
1	(On reset) Endian setting external pin (MD5) is high. Indicates the SH7718R is set as little-endian.

Bits 10 and 9—Area 0 Burst ROM Control (A0BST1–A0BST0): These bits specify whether to use burst ROM in physical space area 0. When burst ROM is used, they set the number of burst transfers.

Bit 10: A0BST1	Bit 9: A0BST0	Description
0	0	Access area 0 as normal memory. (Initial value)
	1	Access area 0 as burst ROM (4 consecutive accesses). Can be used when bus width is 8, 16, or 32.
1	0	Access area 0 as burst ROM (8 consecutive accesses). Can be used only when bus width is 8 or 16.
	1	Access area 0 as burst ROM (16 consecutive accesses). Can be used only when bus width is 8.

Bits 8 and 7—Area 5 Burst Enable (A5BST1–A5BST0): These bits specify whether to use burst ROM and PCMCIA burst mode in physical space area 5. When burst ROM and PCMCIA burst mode are used, they set the number of burst transfers.

Bit 8: A5BST1	Bit 7: A5BST0	Description
0	0	Access area 5 as normal memory. (Initial value)
	1	Burst access of area 5 (4 consecutive accesses). Can be used when bus width is 8, 16, or 32.
1	0	Burst access of area 5 (8 consecutive accesses). Can be used only when bus width is 8 or 16.
	1	Burst access of area 5 (16 consecutive accesses). Can be used only when bus width is 8.

Bits 6 and 5—Area 6 Burst Enable (A6BST1–A6BST0): These bits specify whether to use burst ROM and PCMCIA burst mode in physical space area 6. When burst ROM and PCMCIA burst mode are used, they set the number of burst transfers.

Bit 6: A6BST1	Bit 5: A6BST0	Description
0	0	Access area 6 as normal memory. (Initial value)
	1	Burst access of area 6 (4 consecutive accesses). Can be used when bus width is 8, 16, or 32.
1	0	Burst access of area 6 (8 consecutive accesses). Can be used only when bus width is 8 or 16.
	1	Burst access of area 6 (16 consecutive accesses). Can be used only when bus width is 8.

Bits 4 to 2—Area 2, Area 3 Memory Type (DRAMTP2, DRAMTP1, DRAMTP0): These bits designate the types of memory connected to physical space areas 2 and 3. Normal memory, such as ROM, SRAM, or flash RAM, can be directly connected. Pseudo-SRAM, DRAM, and synchronous DRAM can also be directly connected.

Bit 4: DRAMTP2	Bit 3: DRAMTP1	Bit 2: DRAMTP0	Description
0	0	0	Areas 2 and 3 are normal memory (Initial value)
		1	Area 2: normal memory; area 3: PSRAM
	1	0	Area 2: normal memory; area 3: SDRAM
		1	Areas 2 and 3 are SDRAM
1	0	0	Area 2: normal memory; area 3: DRAM
		1	Areas 2 and 3 are DRAM*
	1	0	Reserved (cannot be set)
		1	Reserved (cannot be set)

Note: * When selecting these bits, set the area 2 and 3 bus widths as word. The MD5 pin output is the RAS2 signal.

Bit 1—Area 5 Bus Type (A5PCM): Designates whether to access physical space area 5 as PCMCIA space.

Bit 1: A5PCM	Description
0	Access physical space area 5 as normal memory. (Initial value)
1	Access physical space area 5 as PCMCIA space.*

Note: * MD3 pin output is $\overline{CE2A}$.

Bit 0—Area 6 Bus Type (A6PCM): Designates whether to access physical space area 6 as PCMCIA space.

Bit 0: A6PCM	Description
0	Access physical space area 6 as normal memory. (Initial value)
1	Access physical space area 6 as PCMCIA space.*

Note: * MD4 pin output is $\overline{CE2B}$.

11.2.2 Bus Control Register 2 (BCR2)

Bus control register 2 (BCR2) is a 16-bit read/write register that selects the bus size of each area, and whether to use the 8-bit port. It is initialized to H'3FFC by a power-on reset, but is not initialized by a manual reset or in standby mode. Do not access external memory outside area 0 until BCR2 register initialization is complete.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	A6SZ1	A6SZ0	A5SZ1	A5SZ0	A4SZ1	A4SZ0
Initial value:	0	0	1	1	1	1	1	1
R/W:	R	R	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	A3SZ1	A3SZ0	A2SZ1	A2SZ0	A1SZ1	A1SZ0	—	PORTEN
Initial value:	1	1	1	1	1	1	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R	R/W

Bits 15, 14, and 1—Reserved: These bits are always read as 0. The write value should always be 0.

Bits $2n + 1$, $2n$ —Area n (1–6) Bus Size Specification (AnSZ1, AnSZ0): These bits specify the bus sizes of physical space area n ($n = 1$ to 6).

Bit $2n + 1$: AnSZ1	Bit $2n$: AnSZ0	Bit 0: PORTEN	Description
0	0	0	Reserved (not settable)
	1		Byte (8-bit) size
1	0	1	Word (16-bit) size
	1		Longword (32-bit) size (Initial value)
0	0	1	Reserved (not settable)
	1		Byte (8-bit) size
1	0	1	Word (16-bit) size
	1		Reserved (not settable)

Bit 0—Port Function Enable (PORTEN): Designates whether to use the D23–D16 pins as an 8-bit port. When using this function set the bus widths to word or byte in all areas.

Bit 0: PORTEN	Description
0	D23–D16 are not used as a port. (Initial value)
1	D23–D16 are used as a port.

11.2.3 Wait State Control Register 1 (WCR1)

Wait state control register 1 (WCR1) is a 16-bit read/write register that specifies the number of idle (wait) state cycles inserted for each area. For some memories, the drive of the data bus may not be turned off quickly even when the read signal from the external device is turned off. This can result in conflicts between data buses when consecutive memory accesses are to different memories or when a write immediately follows a memory read. The SH7718R automatically inserts idle states equal to the number set in WCR1 in those cases.

WCR1 is initialized to H'3FFF by a power-on reset. It is not initialized by a manual reset or in standby mode.

Bit:	15	14	13	12	11	10	9	8
Bit name:	WAITSEL*	—	A6IW1	A6IW0	A5IW1	A5IW0	A4IW1	A4IW0
Initial value:	0	0	1	1	1	1	1	1
R/W:	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	A3IW1	A3IW0	A2IW1	A2IW0	A1IW1	A1IW0	A0IW1	A0IW0
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Note: * A-mask version only

Bit 15—WAIT Signal Sampling Timing Specification (WAITSEL) [A-Mask Version Only]

Bit 15: WAITSEL	Description
0	WAIT signal is sampled at rise of CKIO In this case, the WAIT signal should be input synchronously (Initial value)
1	WAIT signal is sampled at fall of CKIO In this case, the WAIT signal can be input asynchronously

Bit 14—Reserved: This bit is always read as 0. The write value should always be 0.

Bits $2n + 1, 2n$ —Area n (6–0) Intercycle Idle Specification (AnIW1, AnIW0): These bits specify the number of idles inserted between bus cycles when switching between physical space area n (6–0) to another space or between a read access to a write access in the same physical space.

Bit $2n + 1$: AnIW1	Bit $2n$: AnIW0	Description
0	0	1 idle cycle inserted
	1	1 idle cycle inserted
1	0	2 idle cycles inserted
	1	3 idle cycles inserted (Initial value)

11.2.4 Wait State Control Register 2 (WCR2)

Wait state control register 2 (WCR2) is a 16-bit read/write register that specifies the number of wait state cycles inserted for each area. It also specifies the pitch of data access for burst memory accesses. This allows direct connection of even low-speed memories without an external circuit. WCR2 is initialized to H'FFFF by a power-on reset. It is not initialized by a manual reset or in standby mode.

Bit:	15	14	13	12	11	10	9	8
Bit name:	A6W2	A6W1	A6W0	A5W2	A5W1	A5W0	A4W2	A4W1
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	A4W0	A3W1	A3W0	A1-2W1	A1-2W0	A0W2	A0W1	A0W0
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15 to 13—Area 6 Wait Control (A6W2, A6W1, A6W0): These bits specify the number of wait states inserted in physical space area 6. They also specify the burst pitch for burst transfer.

			Description			
Bit 15: A6W2	Bit 14: A6W1	Bit 13: A6W0	First Cycle		Burst Cycle (Excluding First Cycle)	
			Inserted Wait States	$\overline{\text{WAIT}}$ Pin	Number of States Per Data Transfer	$\overline{\text{WAIT}}$ Pin
0	0	0	0	Ignored	2	Enabled
		1	1	Enabled	2	Enabled
	1	0	2	Enabled	3	Enabled
		1	3	Enabled	4	Enabled
1	0	0	4	Enabled	4	Enabled
		1	6	Enabled	6	Enabled
	1	0	8	Enabled	8	Enabled
		1	10 (Initial value)	Enabled	10	Enabled

Bits 12 to 10—Area 5 Wait Control (A5W2, A5W1, A5W0): These bits specify the number of wait states inserted in physical space area 5. They also specify the burst pitch for burst transfer.

			Description			
Bit 12: A5W2	Bit 11: A5W1	Bit 10: A5W0	First Cycle		Burst Cycle (Excluding First Cycle)	
			Inserted Wait States	$\overline{\text{WAIT}}$ Pin	Number of States Per Data Transfer	$\overline{\text{WAIT}}$ Pin
0	0	0	0	Ignored	2	Enabled
		1	1	Enabled	2	Enabled
	1	0	2	Enabled	3	Enabled
		1	3	Enabled	4	Enabled
1	0	0	4	Enabled	4	Enabled
		1	6	Enabled	6	Enabled
	1	0	8	Enabled	8	Enabled
		1	10 (Initial value)	Enabled	10	Enabled

Bits 9 to 7—Area 4 Wait Control (A4W2, A4W1, A4W0): These bits specify the number of wait states inserted in physical space area 4.

Bit 9: A4W2	Bit 8: A4W1	Bit 7: A4W0	Description	
			Inserted Wait States	WAIT Pin
0	0	0	0	Ignored
		1	1	Enabled
	1	0	2	Enabled
		1	3	Enabled
1	0	0	4	Enabled
		1	6	Enabled
	1	0	8	Enabled
		1	10	Enabled (Initial value)

Bits 6 and 5—Area 3 Wait Control (A3W1, A3W0): These bits specify the number of wait states inserted in physical space area 3. External wait input is enabled only when normal memory is used, and is ignored when DRAM, synchronous DRAM, or pseudo-SRAM is used.

- For Normal Memory

Bit 6: A3W0	Bit 5: A3W0	Description	
		Inserted Wait States	WAIT Pin
0	0	0	Ignored
	1	1	Enabled
1	0	2	Enabled
	1	3	Enabled (Initial value)

- For DRAM, SDRAM, Pseudo-SRAM

Bit 6: A3W1	Bit 5: A3N0	Description		
		DRAM: CAS Assert Period	SDRAM: CAS Latency	PSRAM: OE, WE Assert Period
0	0	1	1	1
	1	1	1	1
1	0	2	2	2
	1	3	3	3 (Initial value)

Bits 4 and 3—Areas 1 and 2 Wait Control (A1–2W1, A1–2W0): These bits specify the number of wait states inserted in physical space areas 1 and 2. External wait input is enabled only when normal memory is used, and is ignored when DRAM or synchronous DRAM is used.

- For Normal Memory

Bit 4: A1-2W0	Bit 3: A1-2W0	Description	
		Inserted Wait States	WAIT Pin
0	0	0	Ignored
	1	1	Enabled
1	0	2	Enabled
	1	3	Enabled (Initial value)

- For DRAM, Synchronous DRAM, Pseudo-SRAM

Bit 4: A1-2W0	Bit 3: A1-2W0	Description	
		DRAM: CAS Assert Period	SDRAM: CAS Latency
0	0	1	1
	1	1	1
1	0	2	2
	1	3	3 (Initial value)

Bits 2 to 0—Area 0 Wait Control (A0W2, A0W1, A0W0): These bits specify the number of wait states inserted in physical space area 0. They also specify the burst pitch for burst transfer.

Bit 2: A0W2	Bit 1: A0W1	Bit 0: A0W0	Description			
			First Cycle		Burst Cycle (Excluding First Cycle)	
			Inserted Wait States	WAIT Pin	Number of States Per Data Transfer	WAIT Pin
0	0	0	0	Ignored	2	Enabled
		1	1	Enabled	2	Enabled
	1	0	2	Enabled	3	Enabled
		1	3	Enabled	4	Enabled
1	0	0	4	Enabled	4	Enabled
		1	6	Enabled	6	Enabled
	1	0	8	Enabled	8	Enabled
		1	10 (Initial value)	Enabled	10	Enabled

11.2.5 Individual Memory Control Register (MCR)

The individual memory control register (MCR) is a 16-bit read/write register that specifies $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ timing and burst control for DRAM (area 3 only), synchronous DRAM (areas 2 and 3), and pseudo-SRAM, specifies address multiplexing, and controls refresh. This enables direct connection of DRAM, synchronous DRAM and pseudo-SRAM without external circuits.

MCR is initialized to H'0000 by a power-on reset, but is not initialized by a manual reset or in standby mode. Bits TPC1, TPC0, RCD1, RCD0, TRWL1, TRWL0, TRAS1, TRAS0, BE, SZ, AMX1, AMX0, and EDOMODE are written to in the initialization after a power-on reset and are not then modified again. When RFSH and RMODE are written to, write the same values to the other bits. When using DRAM, pseudo-SRAM, and synchronous DRAM, do not access areas 2 and 3 until this register is initialized.

Bit:	15	14	13	12	11	10	9	8
Bit name:	TPC1	TPC0	RCD1	RCD0	TRWL1	TRWL0	TRAS1	TRAS0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	—	BE	SZ	AMX1	AMX0	RFSH	RMODE	EDOMODE
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15 and 14—RAS Precharge Time (TPC1, TPC0): When DRAM interface is selected as connected memory, the TPC bits set the minimum number of cycles until the next $\overline{\text{RAS}}$ assertion after $\overline{\text{RAS}}$ negation. When synchronous DRAM interface is selected, they set the minimum number of cycles until output of the next bank-active command after precharge. When pseudo-SRAM interface is selected, they set the minimum number of cycles until the next $\overline{\text{CE}}$ assertion after $\overline{\text{CE}}$ negation.

Bit 15: TPC1	Bit 14: TPC0	Description	
		Normally	Immediately after Self-Refresh
0	0	1 cycle (Initial value)	2 cycles (Initial value)
	1	2 cycles	5 cycles
1	0	3 cycles	8 cycles
	1	4 cycles	11 cycles

Bits 13 and 12—RAS–CAS Delay (RCD1, RCD0): These bits set the $\overline{\text{RAS}}\text{--}\overline{\text{CAS}}$ assert delay time for the connected memory when DRAM interface is selected. When synchronous DRAM interface is selected, they set the bank active read/write command delay time. When pseudo-SRAM interface is selected, they set the $\overline{\text{CE}}\text{--}\overline{\text{OE}}$ and $\overline{\text{CE}}\text{--}\overline{\text{WE}}$ assert delay.

Bit 13: RCD1	Bit 12: RCD0	Description
0	0	1 cycle (Initial value)
	1	2 cycles
1	0	3 cycles
	1	4 cycles

Bits 11 and 10—Write-Precharge Delay (TRWL1, TRWL0): These bits set the synchronous DRAM write-precharge delay time. This designates the time between the end of a write cycle and the next bank-active command. This is valid only when synchronous DRAM is connected. After the write cycle, the next bank-active command is not issued for the period TPC + TRWL.

Bit 11: TRWL1	Bit 10: TRWL0	Description
0	0	1 cycle (Initial value)
	1	2 cycles
1	0	3 cycles
	1	Reserved (cannot be set)

Bits 9 and 8—CAS-Before-RAS Refresh RAS Assert Time (TRAS1, TRAS0): When DRAM interface is selected as connected memory, the TRAS bits set the $\overline{\text{RAS}}$ assertion period for $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refreshes. When pseudo-SRAM interface is selected, they set the $\overline{\text{OE}}/\overline{\text{RFSH}}$ assertion period for auto-refreshes. When synchronous DRAM interface is selected, no bank-active command is issued during the period TPC + TRAS after an auto-refresh command.

Bit 9: TRAS1	Bit 8: TRAS0	Description
0	0	2 cycles (Initial value)
	1	3 cycles
1	0	4 cycles
	1	5 cycles

Bit 7—Reserved: This bit is always read as 0. The write value should always be 0.

Bit 6—Burst Enable (BE): Specifies whether to conduct a burst access of DRAM or pseudo-SRAM. When accessing synchronous DRAM, burst access is always carried out, regardless of this bit's designation.

Bit 6: BE	Description	
0	Burst disabled	(Initial value)
1	With DRAM interface, high-speed page mode access With pseudo-SRAM interface, continuous data transfer in static column mode	

Bit 5—Memory Data Size (SZ): Specifies the memory data bus size for DRAM, synchronous DRAM, and pseudo-SRAM. Always set this bit to 1 when synchronous DRAM is used. Takes precedence over the BCR2 register designation.

Bit 5: SZ	Description	
0	Word (16-bit)	(Initial value)
1	Longword (32-bit)	

Bits 4 and 3—Address Multiplex (AMX1, AMX0): These bits specify address multiplexing for DRAM and synchronous DRAM. The actual address shift value differs between DRAM interface and synchronous DRAM interface.

For DRAM Interface:

Bit 4: AMX1	Bit 3: AMX0	Description	
0	0	8-bit column address product	(Initial value)
	1	9-bit column address product	
1	0	10-bit column address product	
	1	11-bit column address product	

For Synchronous DRAM Interface:

Bit 4: AMX1	Bit 3: AMX0	Description	
0	0	16-Mbit product (1M × 16 bits)	(Initial value)
	1	16-Mbit product (2M × 8 bits)	
1	0	16-Mbit product (4M × 4 bits)	
	1	4-Mbit product (256k × 16 bits)	

Bit 2—Refresh Control (RFSH): Determines whether or not refreshing of DRAM, synchronous DRAM, and pseudo-SRAM is performed. The timer for generation of the refresh request frequency can also be used as an interval timer.

Bit 2: RFSH	Description
0	No refresh (Initial value)
1	Refresh

Bit 1—Refresh Mode (RMODE): Selects whether to perform an ordinary refresh or a self-refresh when the RFSH bit is 1. When the RFSH bit is 1 and this bit is 0, a CAS-before-RAS refresh or an auto-refresh is performed on DRAM, synchronous DRAM or pseudo-SRAM at the period set by the refresh-related registers RTCNT, RTCOR and RTCSR. When a refresh request occurs during an external bus cycle, the bus cycle will be ended and the refresh cycle performed. When the RFSH bit is 1 and this bit is also 1, the DRAM, synchronous DRAM or pseudo-SRAM will wait for the end of any executing external bus cycle before going into a self-refresh. All refresh requests to memory that is in the self-refresh state are ignored.

Bit 1: RMODE	Description
0	CAS-before-RAS refresh (RFSH must be 1) (Initial value)
1	Self-refresh (RFSH must be 1)

Bit 0— Extended Data Out (EDOMODE): Specifies the timing of data sampling during data reads when using DRAM in EDO mode. Operating timing of memory other than DRAM does not change even if this bit is set. This bit is valid only for DRAM connected to area 3. Do not set this bit to 1 when using synchronous DRAM or pseudo-SRAM.

Bit 0: EDOMODE	Description
0	Set when using normal DRAM. Data is sampled during read cycle on the falling edge of CKIO. (Initial value)
1	Set when using EDO mode DRAM. Data is sampled during read cycle on the rising edge of CKIO. Also, RAS signal negation is delayed 1/2 a CKIO machine cycle.

11.2.6 DRAM Control Register (DCR)

The DRAM area control register (DCR) is a 16-bit read/write register that specifies $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ timing and burst control for DRAM connected to area 2. It also specifies address multiplexing and controls refreshing. When DRAM is connected to area 2, the bus width is fixed at 16 bits. In such cases, set the area 3 bus width to 16 bits as well. Other areas should be 8 bits or 16 bits. DCR is initialized to H'0000 by a power-on reset, but is not initialized by a manual resets or in standby mode. Do not access external memory outside area 2 until initialization of this register is complete.

Bit:	15	14	13	12	11	10	9	8
Bit name:	TPC1	TPC0	RCD1	RCD0	—	—	TRAS1	TRAS0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R	R	R/W	R/W

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	BE	—	AMX1	AMX0	RFSH	RMODE	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R/W	R	R/W	R/W	R/W	R/W	R

Bits 15 and 14—RAS Precharge Time (TPC1, TPC0): These bits set the RAS precharge time for the DRAM connected to area 2.

Bit 15: TPC1	Bit 14: TPC0	Description	
		Normally	Immediately after Self-Refresh
0	0	1 cycle (Initial value)	2 cycles (Initial value)
	1	2 cycles	5 cycles
1	0	3 cycles	8 cycles
	1	4 cycles	11 cycles

Bits 13 and 12—RAS–CAS Delay (RCD1, RCD0): These bits set the RAS–CAS delay time for the DRAM connected to area 2.

Bit 13: RCD1	Bit 12: RCD0	Description
0	0	1 cycle (Initial value)
	1	2 cycles
1	0	3 cycles
	1	4 cycles

Bits 9 and 8—CAS-Before-RAS Refresh RAS Assert Time (TRAS1, TRAS0): These bits set the RAS assert period for CAS-before-RAS refreshing of the DRAM connected to area 2.

Bit 9: TRAS1	Bit 8: TRAS0	Description
0	0	2 cycles (Initial value)
	1	3 cycles
1	0	4 cycles
	1	5 cycles

Bit 6—Burst Enable (BE): Specifies whether to conduct a burst access of the DRAM connected to area 2.

Bit 6: BE	Description
0	Burst disabled (Initial value)
1	High-speed page mode access

Bits 4 and 3—Address Multiplex (AMX1, AMX0): These bits specify address multiplexing for the DRAM connected to area 2.

Bit 4: AMX1	Bit 3: AMX0	Description
0	0	8-bit column address product (Initial value)
	1	9-bit column address product
1	0	10-bit column address product
	1	11-bit column address product

Bit 2—Refresh Control (RFSH): Determines whether or not refreshing of the DRAM connected to area 2 is performed.

Bit 2: RFSH	Description
0	No refresh (Initial value)
1	Refresh

Bit 1—Refresh Mode (RMODE): Selects the refresh mode for the DRAM connected to area 2.

Bit 1: RMODE	Description
0	CAS-before-RAS refresh (RFSH must be 1) (Initial value)
1	Self-refresh (RFSH must be 1)

Bits 11, 10, 7, 5, and 0—Reserved: These bits are always read as 0. The write value should always be 0.

11.2.7 PCMCIA Control Register (PCR)

The PCMCIA control register (PCR) is a 16-bit read/write register that specifies the \overline{OE} and \overline{WE} signal assert/negate timing for PCMCIA interfaces connected to areas 5 and 6. The \overline{OE} and \overline{WE} signal assert pulse widths are designated by the WCR2 wait control bits. This register is initialized to H'0000 by a power-on reset, but is not initialized by a manual reset or in standby mode.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R
Bit:	7	6	5	4	3	2	1	0
Bit name:	A5TED1	A5TED0	A6TED1	A6TED0	A5TEH1	A5TEH0	A6TEH1	A6TEH0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15 to 8—Reserved: These bits are always read as 0. The write value should always be 0.

Bits 7 and 6—Area 5 Address $\overline{OE}/\overline{WE}$ Assert Delay (A5TED1, A5TED0): These bits specify the address to $\overline{OE}/\overline{WE}$ assert delay time for the PCMCIA interface connected to area 5.

Bit 7: A5TED1	Bit 6: A5TED0	Description
0	0	0.5 cycle delay (Initial value)
	1	1.5 cycle delay
1	0	2.5 cycle delay
	1	3.5 cycle delay

Bits 5 and 4—Area 6 $\overline{OE}/\overline{WE}$ Assert Delay (A6TED1, A6TED0): These bits specify the address to $\overline{OE}/\overline{WE}$ assert delay time for the PCMCIA interface connected to area 6.

Bit 5: A6TED1	Bit 4: A6TED0	Description
0	0	0.5 cycle delay (Initial value)
	1	1.5 cycle delay
1	0	2.5 cycle delay
	1	3.5 cycle delay

Bits 3 and 2—Area 5 $\overline{OE}/\overline{WE}$ Negate Address Delay (A5TEH1, A5TEH0): These bits specify the $\overline{OE}/\overline{WE}$ negate address delay time for the PCMCIA interface connected to area 5.

Bit 3: A5TEH1	Bit 2: A5TEH0	Description
0	0	0.5 cycle delay (Initial value)
	1	1.5 cycle delay
1	0	2.5 cycle delay
	1	3.5 cycle delay

Bits 1 and 0—Area 6 $\overline{OE}/\overline{WE}$ Negate Address Delay (A6TEH1, A6TEH0): These bits specify the $\overline{OE}/\overline{WE}$ negate address delay time for the PCMCIA interface connected to area 6.

Bit 1: A6TEH1	Bit 0: A6TEH0	Description
0	0	0.5 cycle delay (Initial value)
	1	1.5 cycle delay
1	0	2.5 cycle delay
	1	3.5 cycle delay

11.2.8 Synchronous DRAM Mode Register (SDMR)

The synchronous DRAM mode register (SDMR) is written to via the synchronous DRAM address bus and is a virtual 8-bit write-only register. It sets synchronous DRAM mode for areas 2 and 3. SDMR settings must be made before synchronous DRAM is accessed.

Writes to the synchronous DRAM mode register use the address bus rather than the data bus. If the value to be set is X and the SDMR address is Y, the value X is written in the synchronous DRAM mode register by writing in address X + Y. Since A0 of the synchronous DRAM is connected to A2 of the chip and A1 of the synchronous DRAM is connected to A3 of the chip, the value actually written to the synchronous DRAM is the X value shifted two bits right. For example, when H'0230 is written to the SDMR register of area 2, random data is written to the address

H'FFFD000 (address Y) + H'08C0 (value X), or H'FFFFD8C0. As a result, H'0230 is written to the SDMR register. When H'0230 is written to the SDMR register of area 3, random data is written to the address H'FFFE000 (address Y) + H'08C0 (value X) or H'FFFFE8C0. As a result, H'0230 is written to the SDMR register. The range for value X is H'000 to H'0FFC.

		Address bits							
Bit:	31				12	11	10	9	8
Bit name:	SDMR address								
Initial value:	—			—	—	—	—	—
R/W:	—			—	W*	W*	W	W
Bit:	7	6	5	4	3	2	1	0	
Bit name:									
Initial value:	—	—	—	—	—	—	—	—	
R/W:	W	W	W	W	W	W	—	—	

Note: Depending on the type of synchronous DRAM.

11.2.9 Refresh Timer Control/Status Register (RTCSR)

The refresh timer control/status register (RTSCR) is a 16-bit read/write register that specifies the refresh cycle, whether to generate an interrupt, and the cycle of that interrupt. RTSCR is initialized to H'0000 by a power-on reset, but is not initialized by a manual reset or in standby mode.

Note: The method for writing to RTCOR is different from that for general registers to prevent inadvertent overwriting. Using a word transfer instruction, place B'10100101 in the upper byte and the write data in the lower byte. For details, see section 10.2.13, Cautions on Accessing Refresh Control Related Registers.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R
Bit:	7	6	5	4	3	2	1	0
Bit name:	CMF	CMIE	CKS2	CKS1	CKS0	OVF	OVIE	LMTS
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15 to 8—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 7—Compare Match Flag (CMF): Status flag that indicates that the values of RTCNT and RTCOR match.

Bit 7: CMF	Description
0	The values of RTCNT and RTCOR do not match. Clearing condition: When a refresh is performed after 0 has been written in CMF and RFSH = 1 and RMODE = 0 (to perform a CBR refresh). (Initial value)
1	The values of RTCNT and RTCOR match. Setting condition: RTCNT = RTCOR

Bit 6—Compare Match Interrupt Enable (CMIE): Enables or disables an interrupt request caused when the CMF bit in RTCSR is set to 1. Do not set this bit to 1 when using CAS-before-RAS refreshing or auto-refreshing.

Bit 6: CMIE	Description
0	Disables the interrupt request caused by CMF (Initial value)
1	Enables the interrupt request caused by CMF

Bits 5 to 3—Clock Select Bits (CKS2–CKS0): These bits select the clock input to RTCNT. The source clock is the external bus clock (BCLK). The RTCNT count clock is CKIO scaled by the specified ratio.

Bit 5: CKS2	Bit 4: CKS1	Bit 3: CKS0	Description
0	0	0	Disables clock input (Initial value)
		1	Bus clock (CKIO)/4
	1	0	CKIO/16
		1	CKIO/64
1	0	0	CKIO/256
		1	CKIO/1024
	1	0	CKIO/2048
		1	CKIO/4096

Bit 2—Refresh Count Overflow Flag (OVF): Status flag that indicates when the number of refresh requests indicated in the refresh count register (RFCR) exceeds the limit set in the LMTS bit in RTCSR.

Bit 2: OVF	Description
0	RFCR has not exceeded the count limit value set in LMTS Clearing Condition: When 0 is written to OVF (Initial value)
1	RFCR has exceeded the count limit value set in LMTS Setting Condition: When the RFCR value has exceeded the count limit value set in LMTS*

Note: * Contents do not change when 1 is written to OVF.

Bit 1—Refresh Count Overflow Interrupt Enable (OVIE): Selects whether to suppress generation of interrupt requests by OVF when the OVF bit of RTCSR is set to 1.

Bit 1: OVIE	Description
0	Disables interrupt requests caused by OVF (Initial value)
1	Enables interrupt requests caused by OVF

Bit 0—Refresh Count Overflow Limit Select (LMTS): Indicates the count limit value to be compared to the number of refreshes indicated in the refresh count register (RFCR). When the value RFCR exceeds the value specified by LMTS, the OVF flag is set.

Bit 0: LMTS	Description
0	Count limit value is 1024 (Initial value)
1	Count limit value is 512

11.2.10 Refresh Timer Counter (RTCNT)

RTCNT is a 16-bit read/write register containing an 8-bit counter that counts up on an input clock. The clock select bits (CKS2–CKS0) in RTCSR select the input clock. When RTCNT matches RTCOR, the OVF bit in RTCSR is set and RTCNT is cleared. RTCNT is initialized to H'00 by a power-on reset; it continues incrementing after a manual reset; it is not initialized in standby mode, but retains its contents.

Note: The method for writing to RTCOR is different from that for general registers to prevent inadvertent overwriting. Using a word transfer instruction, place B'10100101 in the upper byte and the write data in the lower byte. For details, see section 11.2.13, Cautions on Accessing Refresh Control Related Registers.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R

Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

11.2.11 Refresh Time Constant Register (RTCOR)

The refresh time constant register (RTCOR) is a 16-bit read/write register. The values of RTCOR and RTCNT (lower 8 bits) are constantly compared. When the values match, the compare match flag (CMF) in RTCSR is set and RTCNT is cleared to 0. When the refresh bit (RFSH) in the individual memory control register (MCR) is set to 1 and the refresh mode is set to CAS-before-RAS refresh, a memory refresh cycle occurs when the CMF bit is set. RTCOR is initialized to H'00 by a power-on reset. It is not initialized by a manual reset or in standby mode, but retains its contents.

Note: The method for writing to RTCOR is different from that for general registers to prevent inadvertent overwriting. Using a word transfer instruction, place B'10100101 in the upper byte and the write data in the lower byte. For details, see section 11.2.13, Cautions on Accessing Refresh Control Related Registers.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—	—	—
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R

Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

11.2.12 Refresh Count Register (RFCR)

The refresh count register (RFCR) is a 16-bit read/write register containing a 10-bit counter that increments every time RTCOR and RTCNT match. When RFCR exceeds the count limit value set

by the LMCTS bit in RTCSR, the OVF bit in RTCSR is set and RFCR is cleared. RFCR is initialized to H'0000 by a power-on reset. It is not initialized by a manual reset or in standby mode, but retains its contents.

Note: The method for writing to RFCR is different from that for general registers to prevent inadvertent overwriting. Using a word transfer instruction, place B'101001 in the top 6 bits of the upper byte, and the write data in the remaining bits. For details, see section 11.2.13, Cautions on Accessing Refresh Control Related Registers.

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—		
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R/W	R/W

Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

11.2.13 Cautions on Accessing Refresh Control Related Registers

RFCR, RTCSR, RTCNT, and RTCOR require that a specific code be appended to the data when it is written to prevent data from being mistakenly overwritten by program overruns or other write operations (figure 11.5). Perform reads and writes using the following methods:

1. When writing to RFCR, RTCSR, RTCNT, or RTCOR, use only word transfer instructions. Byte transfer instructions cannot be used. When writing to RTCNT, RTCSR, or RTCOR, place B'10100101 in the upper byte and the write data in the lower byte. When writing to RFCR, place B'101001 in the top 6 bits and the write data in the remaining bits, as shown in figure 11.5.
2. When reading from RFCR, RTCSR, RTCNT, or RTCOR, use a 16-bit access. 0 is read from undefined bits.

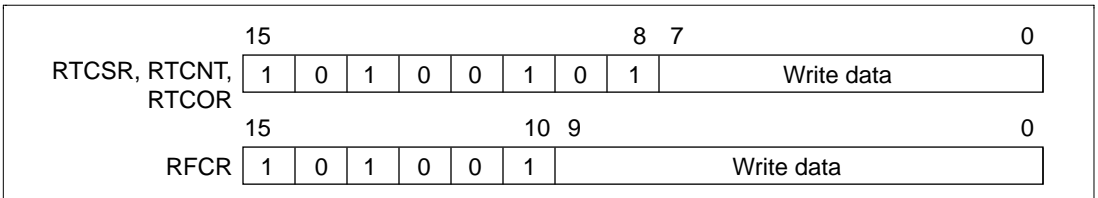


Figure 11.5 Writing to RFCR, RTCSR, RTCNT, and RTCOR

11.3 BSC Operation

11.3.1 Endian/Access Size and Data Alignment

The SH7718R supports both big-endian mode, in which the 0 address is the most significant byte in the byte data, and little-endian mode, in which the 0 address is the least significant byte. Switching between the two is designated by an external pin (MD5 pin) at the time of a power-on reset. After a power-on reset, big-endian mode is set when MD5 is low, and little-endian mode is set when MD5 is high.

Three data bus widths are available for normal memory (byte, word, longword) and two data bus widths (word and longword) for DRAM and pseudo-SRAM. Only longword is available for synchronous DRAM. For the PCMCIA interface, choose from byte and word. This means data alignment is done by matching the device's data width and endian. The access unit must also be matched to the device's bus width. This also means that when longword data is read from a byte-width device, four read operations must be executed. In the SH7718R, data alignment and conversion of data length is performed automatically between the respective interfaces.

Tables 11.6 through 11.11 show the relationship between endian, device data width, and access unit.

Table 11.6 32-Bit External Device/Big Endian Access and Data Alignment

Operation	Data Bus				Strobe Signal			
	D31– D24	D23– D16	D15–D8	D7–D0	$\overline{\text{WE3}}$, CASHH, DQMUU	$\overline{\text{WE2}}$, CASHL, DQMUL	$\overline{\text{WE1}}$, CASLH, DQMLU	$\overline{\text{WE0}}$, CASLL, DQMLL
Address 0 byte access	Data 7–0	—	—	—	Asserted	—	—	—
Address 1 byte access	—	Data 7–0	—	—	—	Asserted	—	—
Address 2 byte access	—	—	Data 7–0	—	—	—	Asserted	—
Address 3 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 0 word access	Data 15–8	Data 7–0	—	—	Asserted	Asserted	—	—
Address 2 word access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted
Address 0 longword access	Data 31–24	Data 23–16	Data 15–8	Data 7–0	Asserted	Asserted	Asserted	Asserted

Table 11.7 16-Bit External Device/Big Endian Access and Data Alignment

Operation	Data Bus				Strobe Signal				
	D31–D24	D23–D16	D15–D8	D7–D0	$\overline{WE3}$, \overline{CASHH} , \overline{DQMUU}	$\overline{WE2}$, \overline{CASHL} , \overline{DQMUL}	$\overline{WE1}$, \overline{CASLH} , \overline{DQMLU}	$\overline{WE0}$, \overline{CASLL} , \overline{DQMLL}	
Address 0 byte access	—	—	Data 7–0	—	—	—	Asserted	—	
Address 1 byte access	—	—	—	Data 7–0	—	—	—	Asserted	
Address 2 byte access	—	—	Data 7–0	—	—	—	Asserted	—	
Address 3 byte access	—	—	—	Data 7–0	—	—	—	Asserted	
Address 0 word access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted	
Address 2 word access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted	
Address 0 longword access	1st time (address 0)	—	—	Data 31–24	Data 23–16	—	—	Asserted	Asserted
	2nd time (address 2)	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted

Table 11.8 8-Bit External Device/Big Endian Access and Data Alignment

Operation	Data Bus				Strobe Signal			
	D31–D24	D23–D16	D15–D8	D7–D0	$\overline{\text{WE3}},$ CASHH, DQMUU	$\overline{\text{WE2}},$ CASHL, DQMUL	$\overline{\text{WE1}},$ CASLH, DQMLU	$\overline{\text{WE0}},$ CASLL, DQMLL
Address 0 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 1 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 2 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 3 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 0 word access	1st time (address 0)	—	—	Data 15–8	—	—	—	Asserted
	2nd time (address 1)	—	—	Data 7–0	—	—	—	Asserted
Address 2 word access	1st time (address 2)	—	—	Data 15–8	—	—	—	Asserted
	2nd time (address 3)	—	—	Data 7–0	—	—	—	Asserted
Address 0 longword access	1st time (address 0)	—	—	Data 31–24	—	—	—	Asserted
	2nd time (address 1)	—	—	Data 23–16	—	—	—	Asserted
	3rd time (address 2)	—	—	Data 15–8	—	—	—	Asserted
	4th time (address 3)	—	—	Data 7–0	—	—	—	Asserted

Table 11.9 32-Bit External Device/Little Endian Access and Data Alignment

Operation	Data Bus				Strobe Signal			
	D31–D24	D23–D16	D15–D8	D7–D0	$\overline{WE3}$, \overline{CASHH} , \overline{DQMUU}	$\overline{WE2}$, \overline{CASHL} , \overline{DQMUL}	$\overline{WE1}$, \overline{CASLH} , \overline{DQMLU}	$\overline{WE0}$, \overline{CASLL} , \overline{DQMLL}
Address 0 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 1 byte access	—	—	Data 7–0	—	—	—	Asserted	—
Address 2 byte access	—	Data 7–0	—	—	—	Asserted	—	—
Address 3 byte access	Data 7–0	—	—	—	Asserted	—	—	—
Address 0 word access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted
Address 2 word access	Data 15–8	Data 7–0	—	—	Asserted	Asserted	—	—
Address 0 longword access	Data 31–24	Data 23–16	Data 15–8	Data 7–0	Asserted	Asserted	Asserted	Asserted

Table 11.10 16-Bit External Device/Little Endian Access and Data Alignment

Operation	Data Bus				Strobe Signal			
	D31– D24	D23– D16	D15–D8	D7–D0	$\overline{\text{WE3}}$, $\overline{\text{CASHH}}$, $\overline{\text{DQMUU}}$	$\overline{\text{WE2}}$, $\overline{\text{CASHL}}$, $\overline{\text{DQMUL}}$	$\overline{\text{WE1}}$, $\overline{\text{CASLH}}$, $\overline{\text{DQMLU}}$	$\overline{\text{WE0}}$, $\overline{\text{CASLL}}$, $\overline{\text{DQMLL}}$
Address 0 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 1 byte access	—	—	Data 7–0	—	—	—	Asserted	—
Address 2 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 3 byte access	—	—	Data 7–0	—	—	—	Asserted	—
Address 0 word access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted
Address 2 word access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted
Address 0 longword access	—	—	Data 15–8	Data 7–0	—	—	Asserted	Asserted
2nd time (address 2)	—	—	Data 31–24	Data 23–16	—	—	Asserted	Asserted

Table 11.11 8-Bit External Device/Little Endian Access and Data Alignment

Operation	Data Bus				Strobe Signal			
	D31– D24	D23– D16	D15–D8	D7–D0	$\overline{\text{WE3}}$, CASHH, DQMUU	$\overline{\text{WE2}}$, CASHL, DQMUL	$\overline{\text{WE1}}$, CASLH, DQMLU	$\overline{\text{WE0}}$, CASLL, DQMLL
Address 0 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 1 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 2 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 3 byte access	—	—	—	Data 7–0	—	—	—	Asserted
Address 0 word access	1st time (address 0)	—	—	Data 7–0	—	—	—	Asserted
	2nd time (address 1)	—	—	Data 15–8	—	—	—	Asserted
Address 2 word access	1st time (address 2)	—	—	Data 7–0	—	—	—	Asserted
	2nd time (address 3)	—	—	Data 15–8	—	—	—	Asserted
Address 0 longword access	1st time (address 0)	—	—	Data 7–0	—	—	—	Asserted
	2nd time (address 1)	—	—	Data 15–8	—	—	—	Asserted
	3rd time (address 2)	—	—	Data 23–16	—	—	—	Asserted
	4th time (address 3)	—	—	Data 31–24	—	—	—	Asserted

11.3.2 Description of Areas

Area 0: Area 0 physical address bits A28–A26 are 000. Address bits A31–A29 are ignored and the address range is $H'00000000 + H'20000000 \times n - H'03FFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Normal memories such as SRAM, ROM, and burst ROM can be connected to this space. Byte, word, or longword can be selected as the bus width using external pins. When the Area 0 space is accessed, the $\overline{CS0}$ signal is asserted. The \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are also asserted. The number of bus cycles is selected between 0 and 10 wait cycles using the A0W2–A0W0 bits in WCR2. Also, any number of waits can be inserted in each bus cycle by means of the external wait pin (\overline{WAIT}). When the burst function is used, the bus cycle pitch of the burst cycle is determined within a range of 2–10 according to the number of waits.

Area 1: Area 1 physical address bits A28–A26 are 001. Address bits A31–A29 are ignored and the address range is $H'04000000 + H'20000000 \times n - H'07FFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Only normal memories like SRAM and ROM can be connected to this space. Byte, word, or longword can be selected as the bus width using the A1SZ1–A1SZ0 bits in BCR2. When the Area 1 space is accessed, the $\overline{CS1}$ signal is asserted. The \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are also asserted. The number of bus cycles is selected between 0 and 3 wait cycles using the A12W1–A12W0 bits in WCR2. Also, any number of waits can be inserted in each bus cycle by means of the external wait pin (\overline{WAIT}).

Area 2: Area 2 physical address bits A28–A26 are 010. Address bits A31–A29 are ignored and the address range is $H'08000000 + H'20000000 \times n - H'0BFFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Normal memories like SRAM and ROM, as well as DRAM and synchronous DRAM, can be connected to this space. Byte, word, or longword can be selected as the bus width using the A2SZ1–A2SZ0 bits in BCR2 for normal memory. For synchronous DRAM, set longword using the SZ bit in MCR. When DRAM is connected to area 2, the bus width is fixed at 16 bits. The bus width for area 3 also needs to be 16 bits, while all other areas must be either 8 bits or 16 bits.

When the area 2 space is accessed, the $\overline{CS2}$ signal is asserted. When normal memories are connected, the \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are also asserted and the number of bus cycles is selected between 0 and 3 wait cycles using the A12W1 to A12W0 bits in WCR2. When normal memory is connected, only, any number of waits can be inserted in each bus cycle by means of the external wait pin (\overline{WAIT}).

When synchronous DRAM is connected, the \overline{RAS} signal, \overline{CAS} signal, RD/\overline{WR} signal, and byte control signals DQM_{HH}, DQM_{HL}, DQML_H, and DQML_L are all asserted and addresses multiplexed. Control of \overline{RAS} , \overline{CAS} , data timing, and address multiplexing is set with MCR.

When DRAM is connected, the $\overline{RAS2}$ signal, $\overline{CAS2H}$ signal, $\overline{CAS2L}$ signal, and RD/\overline{WR} signal are all asserted and addresses multiplexed. Control of $\overline{RAS2}$, \overline{CAS} , data timing, and address multiplexing is set with DCR.

Area 3: Area 3 physical address bits A28–A26 are 011. Address bits A31–A29 are ignored and the address range is $H'0C000000 + H'20000000 \times n - H'0FFFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Normal memories like SRAM and ROM, as well as DRAM, pseudo-SRAM, and synchronous DRAM, can be connected to this space. Byte, word or longword can be selected as the bus width using the A3SZ1–A3SZ0 bits in BCR2 for normal memory. For DRAM and pseudo-SRAM, word or longword can be selected using the SZ bit in MCR. When synchronous DRAM is connected, set to longword using the SZ bit in MCR.

When area 3 space is accessed, $\overline{CS3}$ is asserted.

When normal memories are connected, the \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are asserted and the number of bus cycles is selected between 0 and 3 wait cycles using the A3W1–A3W0 bits in WCR2. When normal memory is connected, only, any number of waits can be inserted in each bus cycle by means of the external wait pin (\overline{WAIT}).

When synchronous DRAM is connected, the \overline{RAS} signal, \overline{CAS} signal, RD/\overline{WR} signal, and byte control signals DQM_{HH}, DQM_{HL}, DQML_H, and DQML_L are all asserted and addresses multiplexed. When DRAM is connected, the \overline{RAS} signal, \overline{CASHH} signal, \overline{CASHL} signal, \overline{CASLH} signal, \overline{CASLL} signal, and RD/\overline{WR} signal are all asserted and addresses multiplexed. When pseudo-SRAM is connected, the \overline{CE} signal, $\overline{OE/RFSH}$ signal, and $\overline{WE0}$, $\overline{WE1}$, $\overline{WE2}$, and $\overline{WE3}$ signals are asserted. For all of these, control of \overline{RAS} , \overline{CAS} , and data timing and of address multiplexing is set with MCR.

Area 4: Area 4 physical address bits A28–A26 are 100. Address bits A31–A29 are ignored and the address range is $H'10000000 + H'20000000 \times n - H'13FFFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Only normal memories like SRAM and ROM can be connected to this space. Byte, word, or longword can be selected as the bus width using the A4SZ1–A4SZ0 bits in BCR2. When the area 4 space is accessed, the $\overline{CS4}$ signal is asserted. The \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are also asserted. The number of bus cycles is selected between 0 and 10 wait cycles using the A4W2–A4W0 bits in WCR2. Also, any number of waits can be inserted in each bus cycle by means of the external wait pin (\overline{WAIT}).

Area 5: Area 5 physical address bits A28–A26 are 101. Address bits A31–A29 are ignored and the address range is the 64 Mbytes at $H'14000000 + H'20000000 \times n - H'17FFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Normal memories like SRAM and ROM as well as burst ROM and PCMCIA interfaces can be connected to this space. PCMCIA interfaces only use their IC memory card interface, so the address range becomes the 32 Mbytes at $H'14000000 + H'20000000 \times n - H'15FFFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

For normal memory and burst ROM, byte, word, or longword can be selected as the bus width using the A5SZ1–A5SZ0 bits in BCR2. For the PCMCIA interface, byte, and word can be selected as the bus width using the A5SZ1–A5SZ0 bits in BCR2.

When the area 5 space is accessed and normal memory is connected, the $\overline{CS5}$ signal is asserted. The \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are also asserted. When the PCMCIA interface is used, the $\overline{CE1}$ signal, $\overline{CE2}$ signal, \overline{OE} signal, and \overline{WE} signal are asserted.

The number of bus cycles is selected between 0 and 10 wait cycles using the A5W2–A5W0 bits in WCR2. Also, any number of waits can be inserted in each bus cycle by means of the external wait pin (WAIT). When a burst function is used, the bus cycle pitch of the burst cycle is determined within a range of 2–10 according to the number of waits. The setup and hold times of address/ $\overline{CE1A}$ / $\overline{CE2A}$ for the read/write strobe signals can be set within a range of 0.5–3.5 cycles using the A5TED1–A5TED0 and A5TEH1–A5TEH0 bits in the PCR register.

Area 6: Area 6 physical address bits A28–A26 are 101. Address bits A31–A29 are ignored and the address range is the 64 Mbytes at $H'18000000 + H'20000000 \times n - H'1BFFFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

Normal memories like SRAM and ROM as well as burst ROM and PCMCIA interfaces can be connected to this space. When the PCMCIA interface is used, the IC memory card interface address range is the 32 Mbytes at $H'18000000 + H'20000000 \times n - H'19FFFFFFF + H'20000000 \times n$ and the I/O card interface address range is the 32 Mbytes at $H'1A000000 + H'20000000 \times n - H'1BFFFFFFF + H'20000000 \times n$ ($n = 0-6$, $n = 1-6$ is the shadow space).

For normal memory and burst ROM, byte, word, or longword can be selected as the bus width using the A6SZ1–A6SZ0 bits in BCR2. For the PCMCIA interface, byte, and word can be selected as the bus width using the A6SZ1–A6SZ0 bits in BCR2.

When the area 6 space is accessed and normal memory is connected, the $\overline{CS6}$ signal is asserted. The \overline{RD} signal that can be used as \overline{OE} and the $\overline{WE0}$ – $\overline{WE3}$ signals for write control are also asserted. When the PCMCIA interface is used, the $\overline{CE1B}$ signal, $\overline{CE2B}$ signal, \overline{OE} signal, and $\overline{WE1}$, \overline{ICORD} , and \overline{ICOWR} signals are asserted.

The number of bus cycles is selected between 0 and 10 wait cycles using the A6W2–A6W0 bits in WCR2. Also, any number of waits can be inserted in each bus cycle by means of the external wait pin ($\overline{\text{WAIT}}$). When the burst function is used, the bus cycle pitch of the burst cycle is determined within a range of 2–10 according to the number of waits. The setup and hold times of address/ $\overline{\text{CE1B}}$ / $\overline{\text{CE2B}}$ for the read/write strobe signals can be set within a range of 0.5–3.5 cycles using A6TED1–A6TED0 and A6TEH1–A6TEH0.

11.3.3 Basic Interface

Basic Timing: The basic interface of the SH7718R uses strobe signal output because mainly SRAM will be directly connected. Figure 11.6 shows the basic timing of normal space accesses. A no-wait normal access is completed in two cycles. The $\overline{\text{BS}}$ signal is asserted for one cycle to indicate the start of a bus cycle. The $\overline{\text{CSn}}$ signal is negated on the T2 clock falling edge to secure the negation period. Therefore, at minimum pitch, there is a half-cycle negation period.

There is no access size specification when reading. The correct access start address is output in the least significant bit of the address, but since there is no access size specification, 32 bits are always read in a 32-bit device, and 16 bits in a 16-bit device. When writing, only the $\overline{\text{WE}}$ signal for the byte to be written is asserted. For details, see section 11.3.1, Endian/Access Size and Data Alignment.

Read/write for cache fill or copy-back follows the set bus width and transfers a total of 16 bytes continuously. The bus is not released during this transfer. For cache misses that occur during byte or word operand accesses or branching to odd word boundaries, the fill is always performed by longword accesses on the chip-external interface. Write-through area write access and noncacheable read/write access is based on the actual address size.

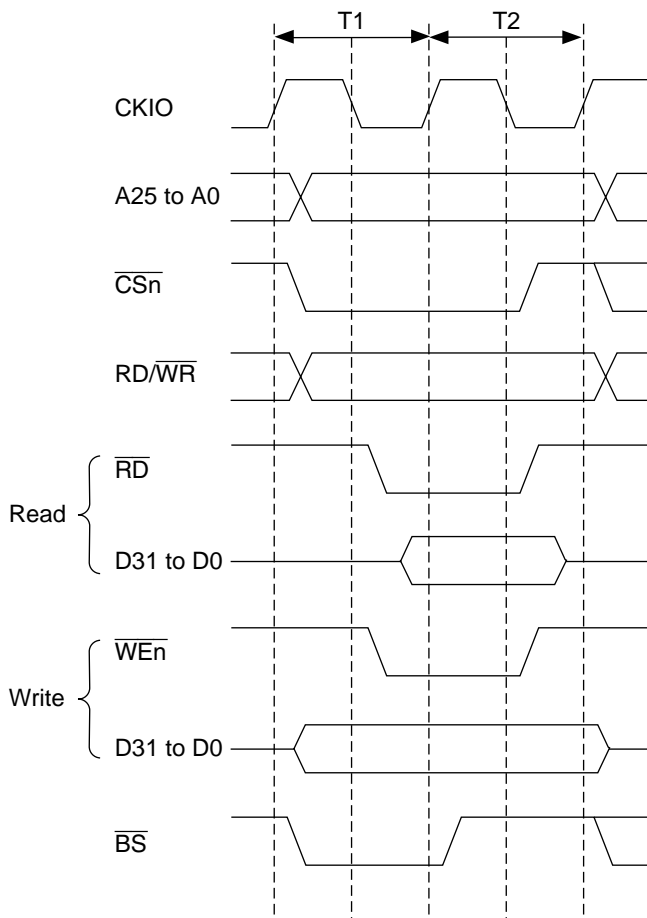


Figure 11.6 Basic Timing of Basic Interface

Figures 11.7, 11.8, and 11.9 show examples of connection to 32-, 16-, and 8-bit data width SRAM.

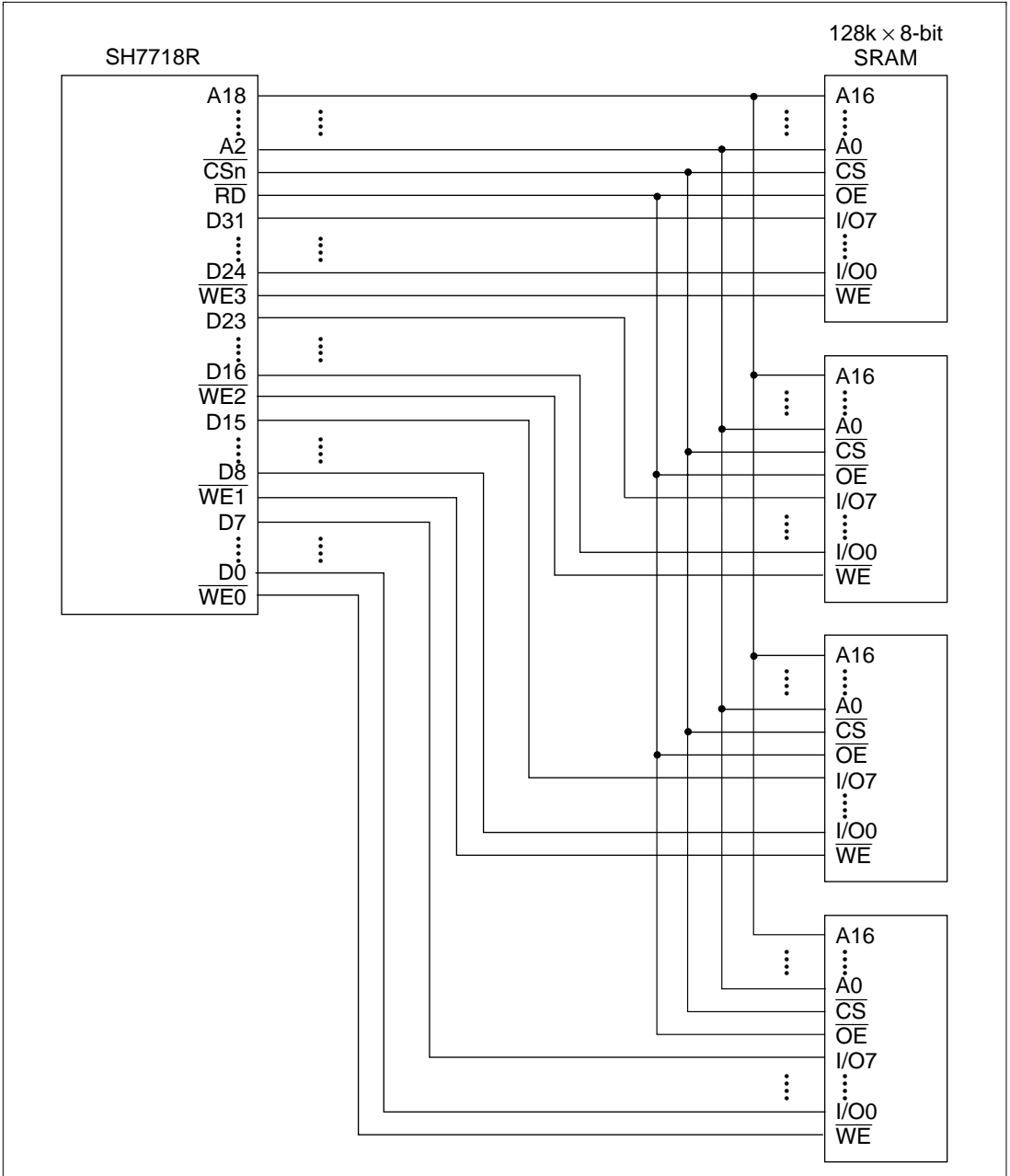


Figure 11.7 Example of 32-Bit Data Width SRAM Connection

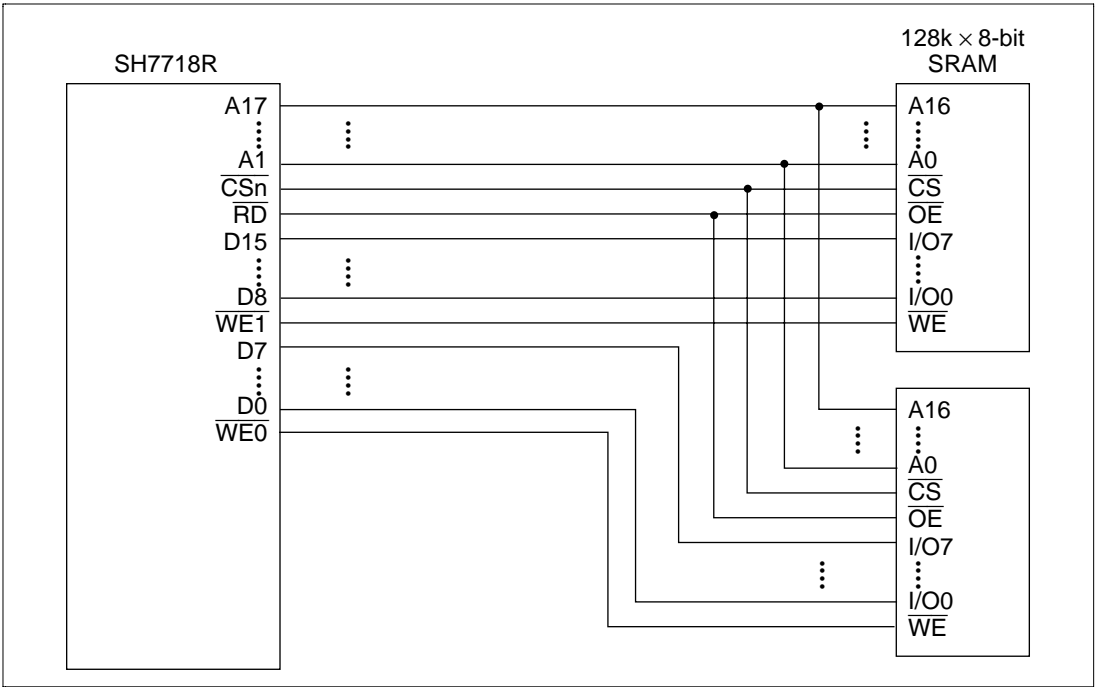


Figure 11.8 Example of 16-Bit Data Width SRAM Connection

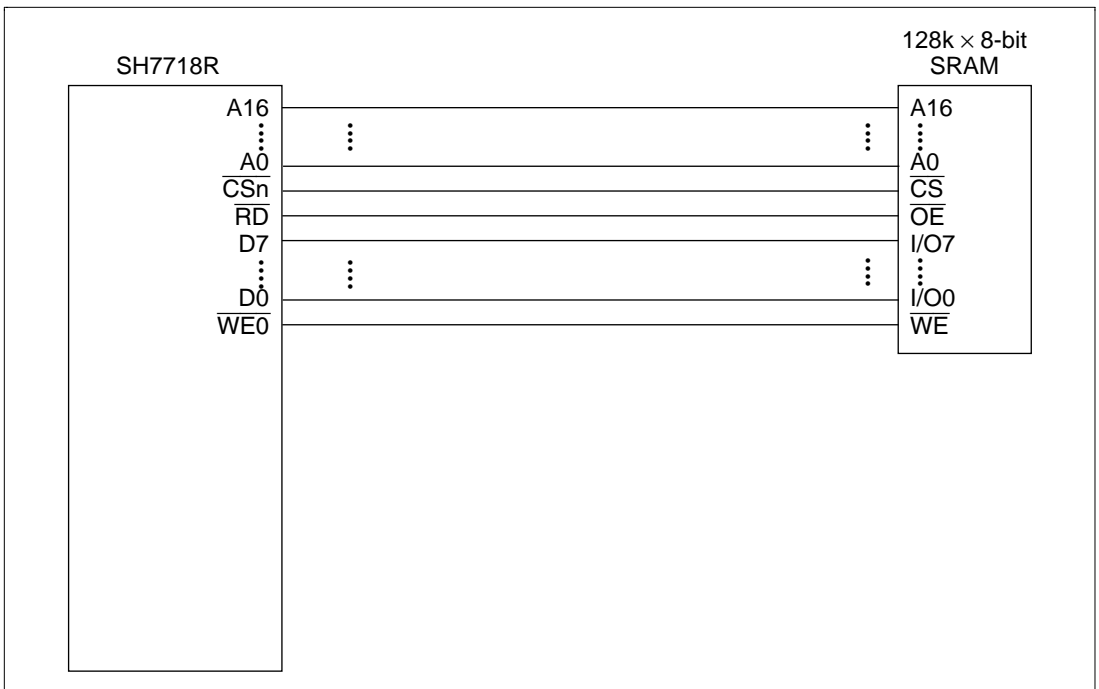


Figure 11.9 Example of 8-Bit Data Width SRAM Connection

Wait State Control: Wait state insertion on the basic interface can be controlled by the WCR2 settings. If the WCR2 wait specification bits corresponding to a particular area are not zero, a software wait is inserted in accordance with that specification. For details, see section 11.2.4, Wait Control Register 2 (WCR2).

The specified number of T_w cycles is inserted as wait cycles using the basic interface wait timing shown in figure 11.10.

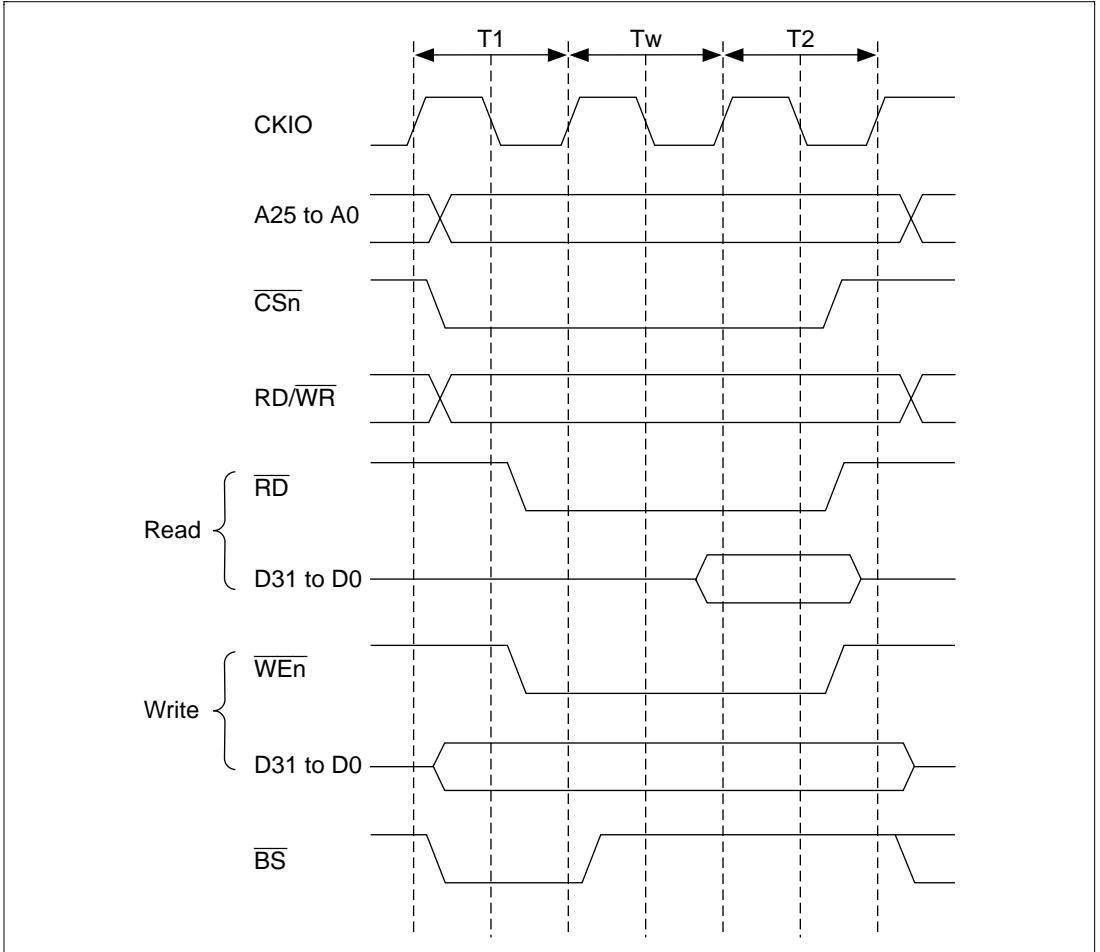


Figure 11.10 Basic Interface Wait Timing (Software Wait Only)

When software wait insertion is specified by WCR2, the external wait input $\overline{\text{WAIT}}$ signal is also sampled. $\overline{\text{WAIT}}$ pin sampling is shown in figure 11.11. A 2-cycle wait is specified as a software wait. Sampling is performed at the transition from the Tw state to the T2 state; therefore, the $\overline{\text{WAIT}}$ signal has no effect if asserted in the T1 cycle or the first Tw cycle. The $\overline{\text{WAIT}}$ signal is sampled on the rising edge of the clock.

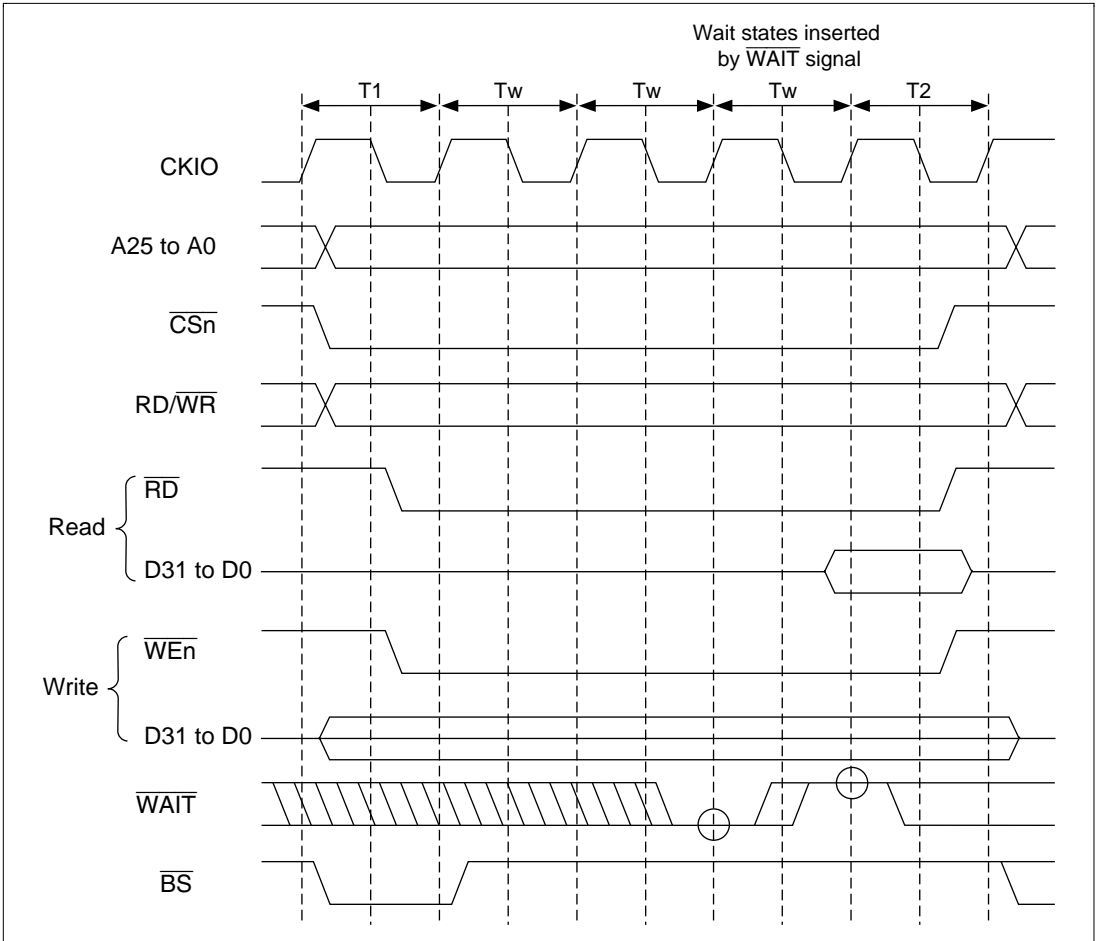


Figure 11.11 Basic Interface Wait State Timing (Wait State Insertion by $\overline{\text{WAIT}}$ Signal)

11.3.4 DRAM Interface

DRAM Connection Method: When the memory type bits (DRAMTP2–DRAMTP0) in BCR1 are set to 100, area 3 becomes DRAM space; when set to 101, area 2 and area 3 become DRAM space. The DRAM interface function can then be used to connect the SH7718R directly to DRAM.

16 or 32 bits can be selected as the interface data width for area 3 when bits DRAMTP2 to DRAMTP0 are set to 100, and 16 bits can be used for both area 2 and area 3 when bits DRAMTP2 to DRAMTP0 are set to 101.

2-CAS 16-bit DRAMs can be connected, since $\overline{\text{CAS}}$ is used to control byte access.

Signals used for connection when DRAM is connected to area 3 are $\overline{\text{RAS}}$, $\overline{\text{CASHH}}$, $\overline{\text{CASHL}}$, $\overline{\text{CASLH}}$, $\overline{\text{CASLL}}$, and $\text{RD}/\overline{\text{WR}}$. $\overline{\text{CASHH}}$ and $\overline{\text{CASHL}}$ are not used when the data width is 16 bits. When DRAM is connected to areas 2 and 3, the signals for area 2 DRAM connection are $\overline{\text{RAS2}}$, $\overline{\text{CAS2H}}$, $\overline{\text{CAS2L}}$, and $\text{RD}/\overline{\text{WR}}$, and those for area 3 DRAM connection are $\overline{\text{RAS}}$, $\overline{\text{CASLH}}$, $\overline{\text{CASLL}}$, and $\text{RD}/\overline{\text{WR}}$.

In addition to normal read and write access modes, high-speed page mode is supported for burst access. Also, for DRAM connected to area 3, EDO mode, which enables the DRAM access time to be increased by delaying the data sampling timing by 1/2 clock when reading, is supported in addition to normal read and write access for burst mode.

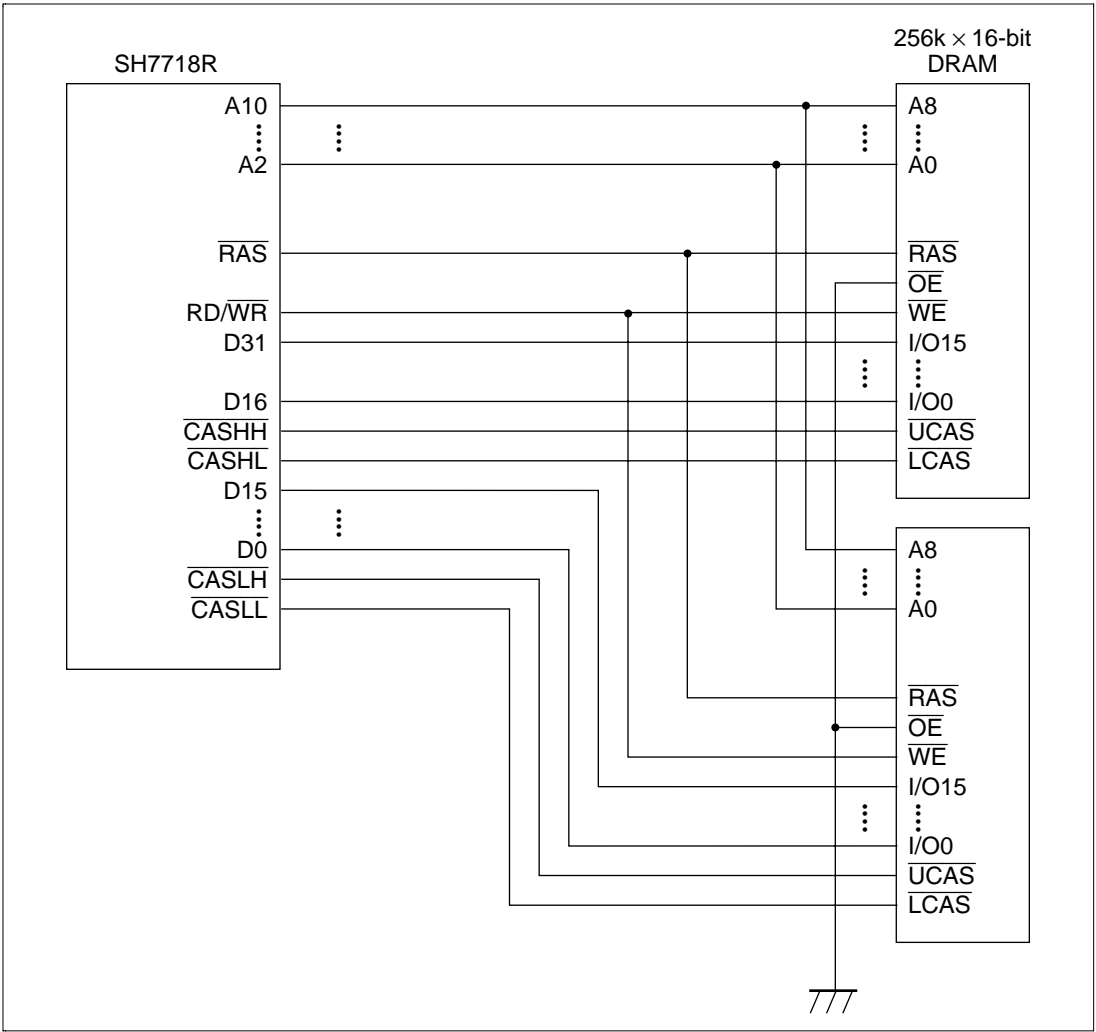


Figure 11.13 Example of DRAM Connection (32-Bit Data Width)

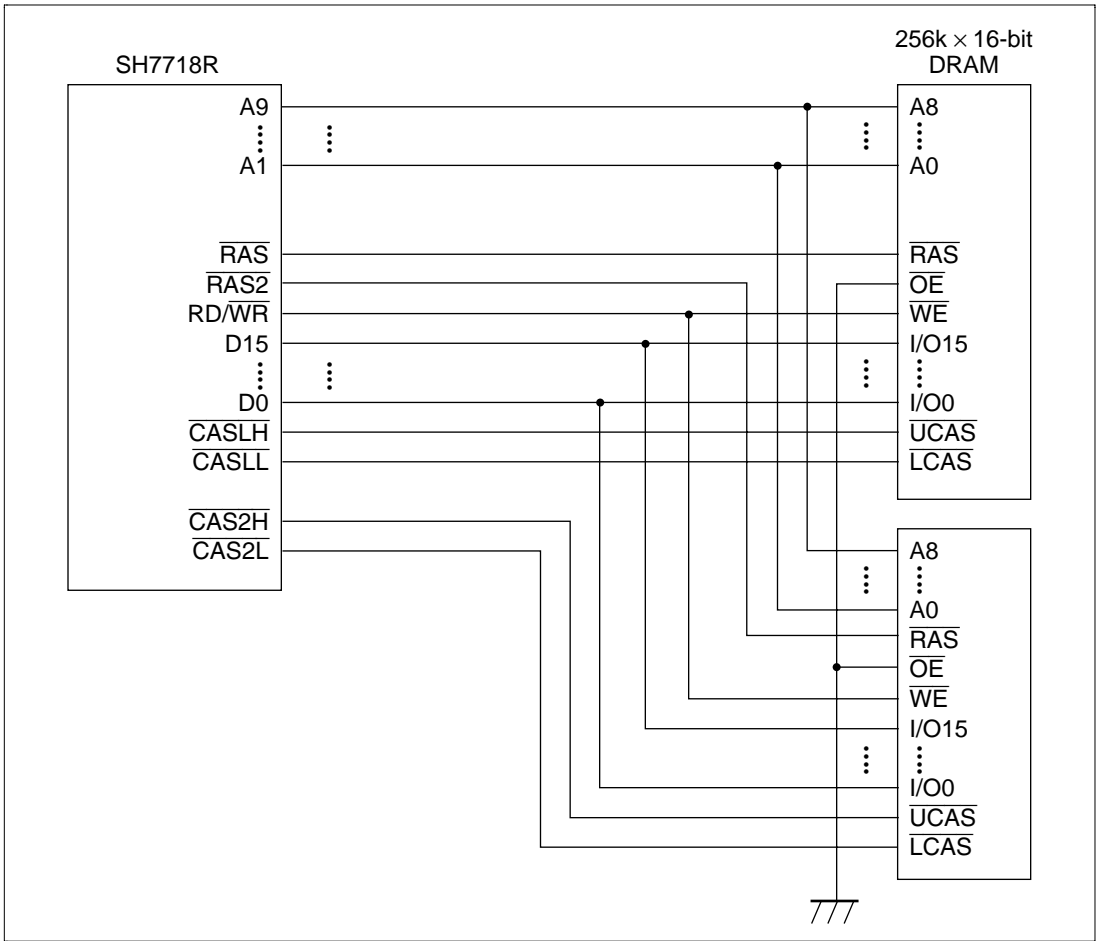


Figure 11.14 Example of DRAM Connection (16-Bit Data Width)

Address Multiplexing: When areas 2 and 3 are designated as DRAM space, address multiplexing is always performed in accesses to DRAM. This enables DRAM, which requires row and column address multiplexing, to be connected directly to the SH7718R without using an external address multiplexer circuit. Any of the four multiplexing methods shown below can be selected by setting bits AMX1 and AMX0 in MCR for area 3 DRAM, or bits AMX1 and AMX0 in DCR for area 2 DRAM. The relationship between bits AMX1 and AMX0 and address multiplexing is shown in table 11.12. The address output pins subject to address multiplexing are A15 to A1. Pins A25 to A16 carry the original address.

Table 11.12 Relationship between AMX1-0 and Address Multiplexing

Setting		Number of Column Address Bits	Output Timing	External Address Pins	
AMX1	AMX0				
0	0	8 bits	Column address	A1 to A14	A15
			Row address	A9 to A22	A23
0	1	9 bits	Column address	A1 to A14	A15
			Row address	A10 to A23	A24
1	0	10 bits	Column address	A1 to A14	A15
			Row address	A11 to A24	A25
1	1	11 bits	Column address	A1 to A14	A15
			Row address	A12 to A25	A15

Basic Timing: Figure 11.15 shows the basic timing for DRAM access is 3 cycles. T_{pc} is the precharge cycle, T_r the \overline{RAS} assert cycle, T_{c1} the \overline{CAS} assert cycle, and T_{c2} the read data latch cycle.

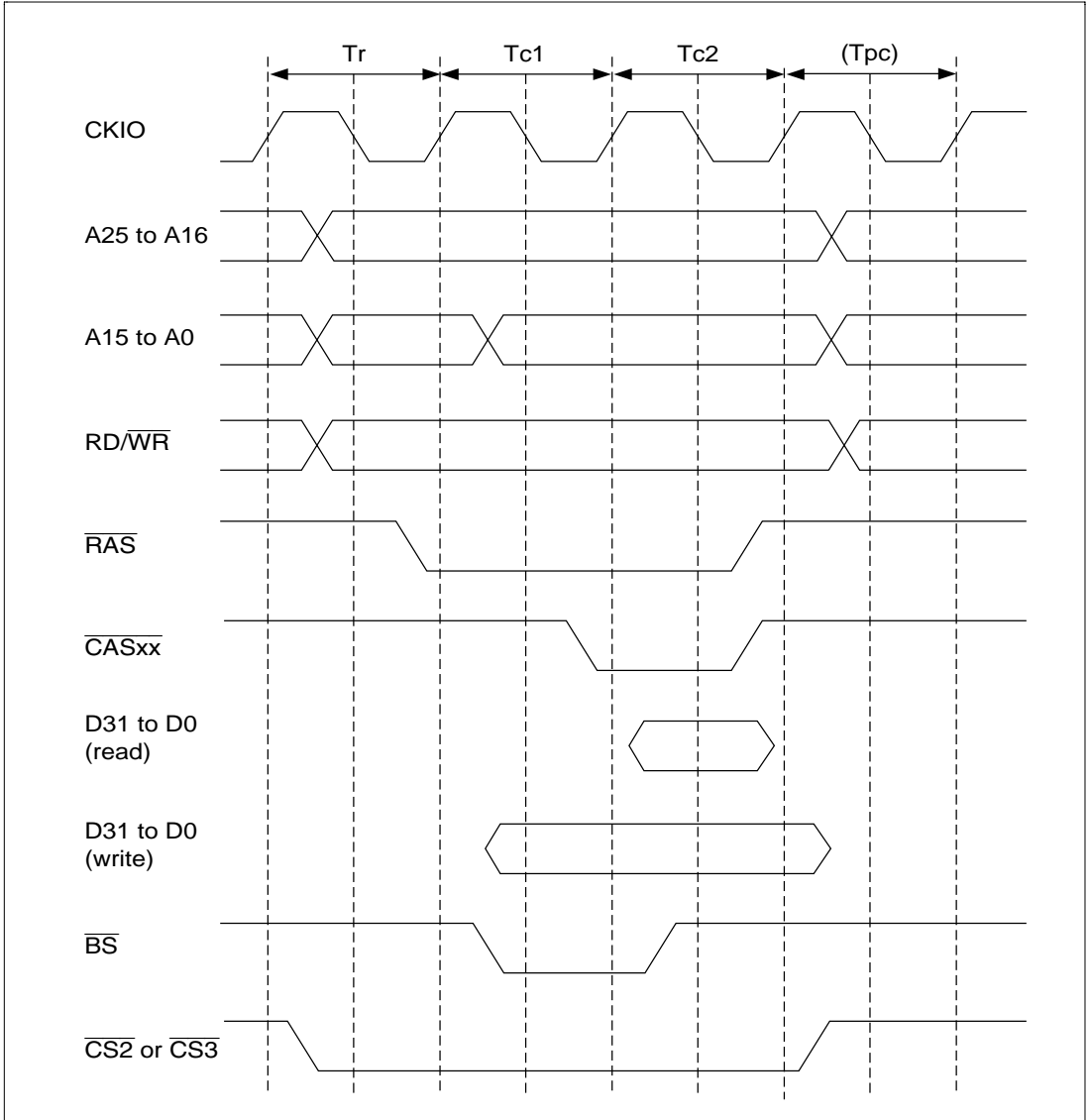


Figure 11.15 Basic Timing for DRAM Access

Wait State Control: As the clock frequency increases, it becomes impossible to complete all states in one cycle as in basic access. Therefore, provision is made for state extension by using the setting bits in WCR2, MCR, and DCR. The timing with state extension using these settings is shown in figure 11.16. Up to four additional Tpc cycles (cycles used to secure the RAS precharge time) can be inserted by means of the TPC bits in MCR and DCR. The number of cycles from $\overline{\text{RAS}}$ assertion to $\overline{\text{CAS}}$ assertion can be set to between 1 and 4 by inserting Trw cycles by means of the RCD bits in MCR and DCR. The number of cycles from $\overline{\text{CAS}}$ assertion to the end of the access can be varied between 1 and 3 according to the setting of A1-2W (1,0) or A3W (1,0) in WCR2.

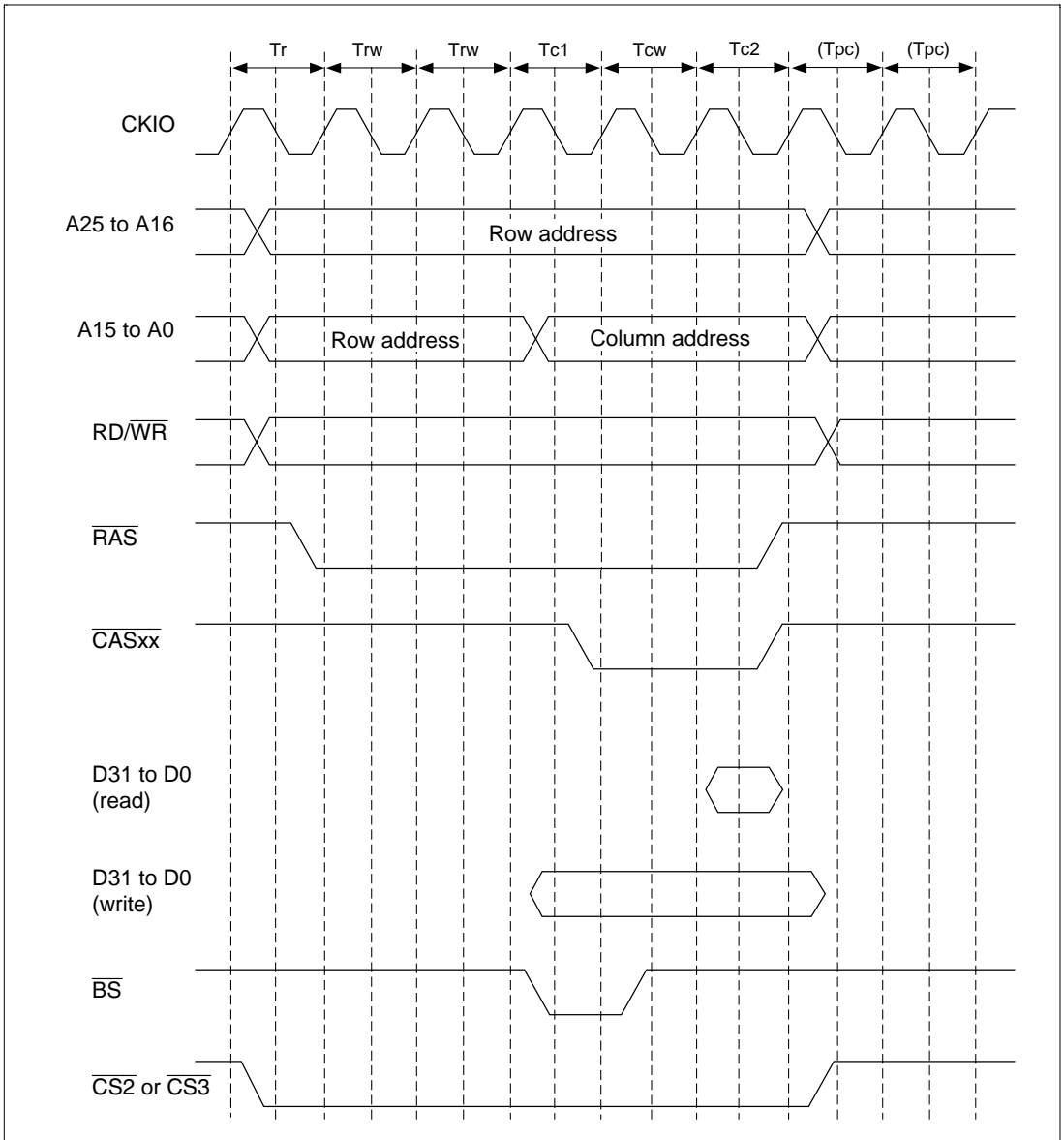


Figure 11.16 DRAM Wait State Timing

Burst Access: In addition to the normal DRAM access mode in which a row address is output in each data access, a high-speed page mode is also provided in cases where consecutive accesses are made to the same row. This mode allows fast access to data by outputting the row address only once, then changing only the column address for each subsequent access. Normal access or burst access using high-speed page mode can be selected by means of the burst enable (BE) bit in MCR and DCR. The timing for burst access using high-speed page mode is shown in figure 11.17.

In burst transfer, 4 (longword access) or 16 (cache fill or cache write-back) bytes of data are burst-transferred in a 16-bit bus size. With a 32-bit bus size, 16 bytes of data are burst-transferred (cache fill or cache write-back). In a 16-byte burst transfer (cache fill), the first access comprises a longword that includes the data requiring access. The remaining accesses are performed on 16-byte boundary data that includes the relevant data. In burst transfer (cache write-back), sequential writing is performed in first-to-last order for 16-byte boundary data.

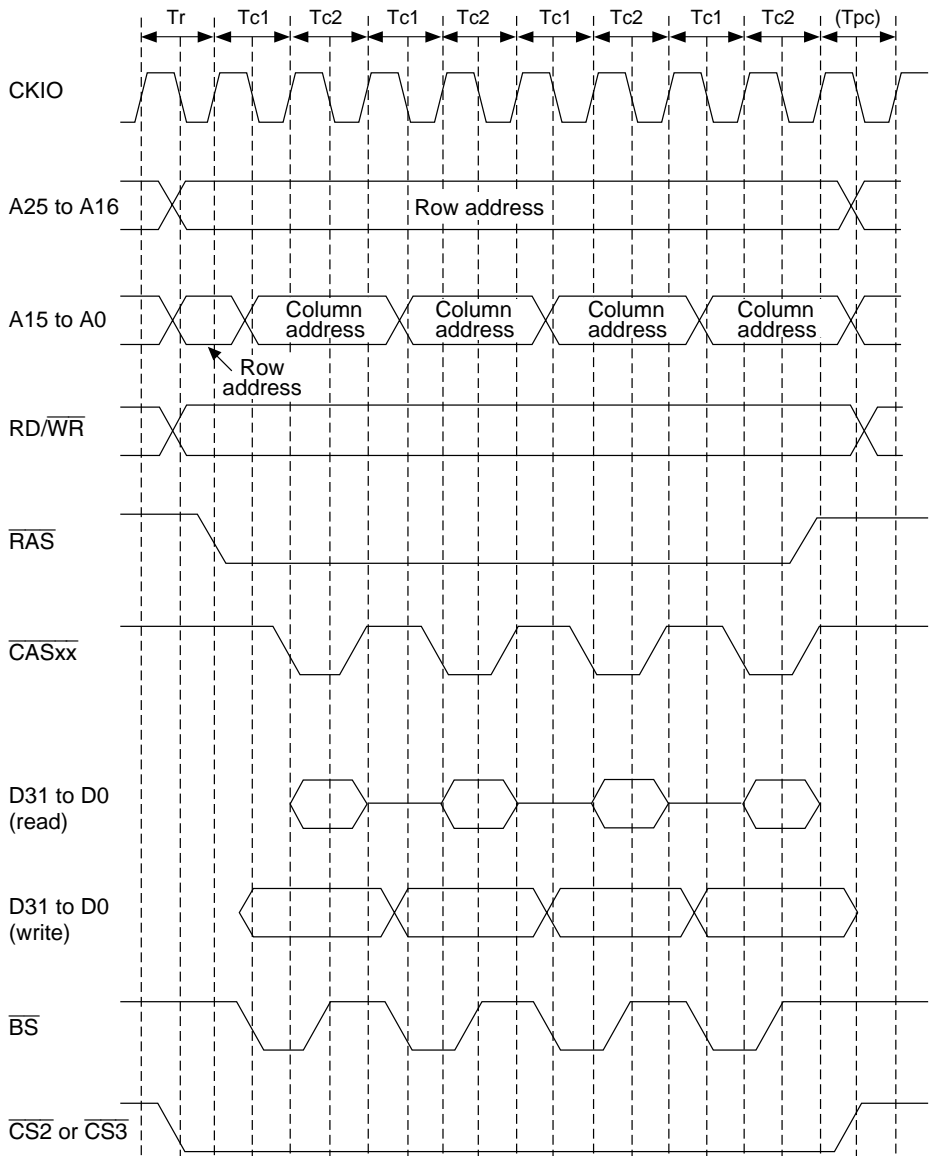


Figure 11.17 DRAM Burst Access Timing

EDO Mode: In DRAM, an extended data out (EDO) mode is also provided in which, once the $\overline{\text{CAS}}$ signal is asserted while the $\overline{\text{RAS}}$ signal is asserted, even if the $\overline{\text{CAS}}$ signal is negated, data is output to the data bus until the $\overline{\text{CAS}}$ signal is next asserted. (This is in addition to the mode in which data is output to the data bus only while the $\overline{\text{CAS}}$ signal is asserted in a data read cycle.) In the SH7718R, the EDO mode bit (EDOMODE) in MCR enables selection, for area 3 DRAM only, of either normal access/burst access using high-speed page mode or EDO mode normal access/burst access. EDO mode normal access is shown in figure 11.18, and burst access in figure 11.19.

In EDO mode, the timing for data output to the data bus in a read cycle is extended as far as the next assertion of the $\overline{\text{CAS}}$ signal. This delays the data latch timing by 1/2 cycle to the rising edge of the CKIO clock, enabling the DRAM access time to be increased.

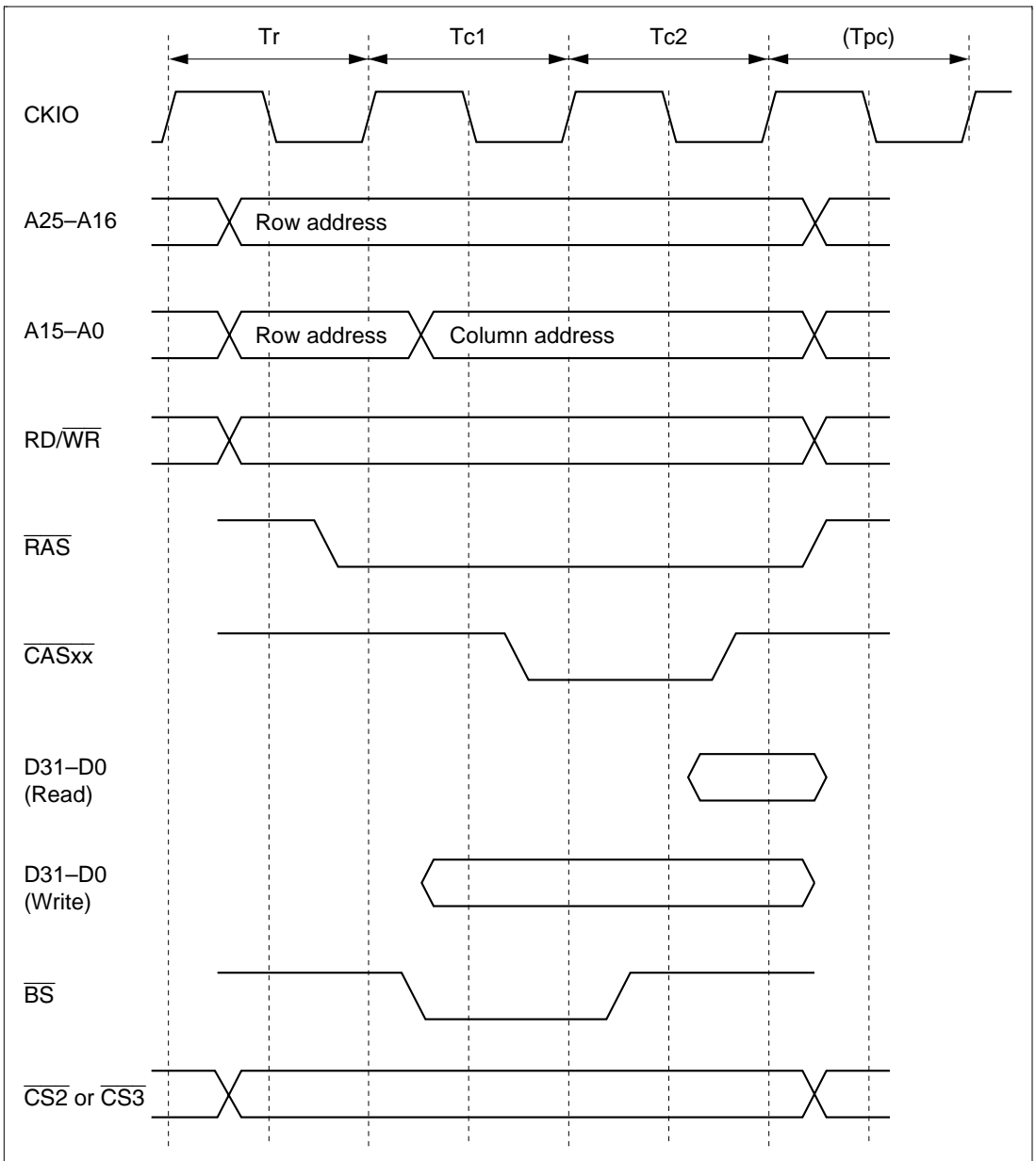


Figure 11.18 Normal Access Timing in DRAM EDO Mode

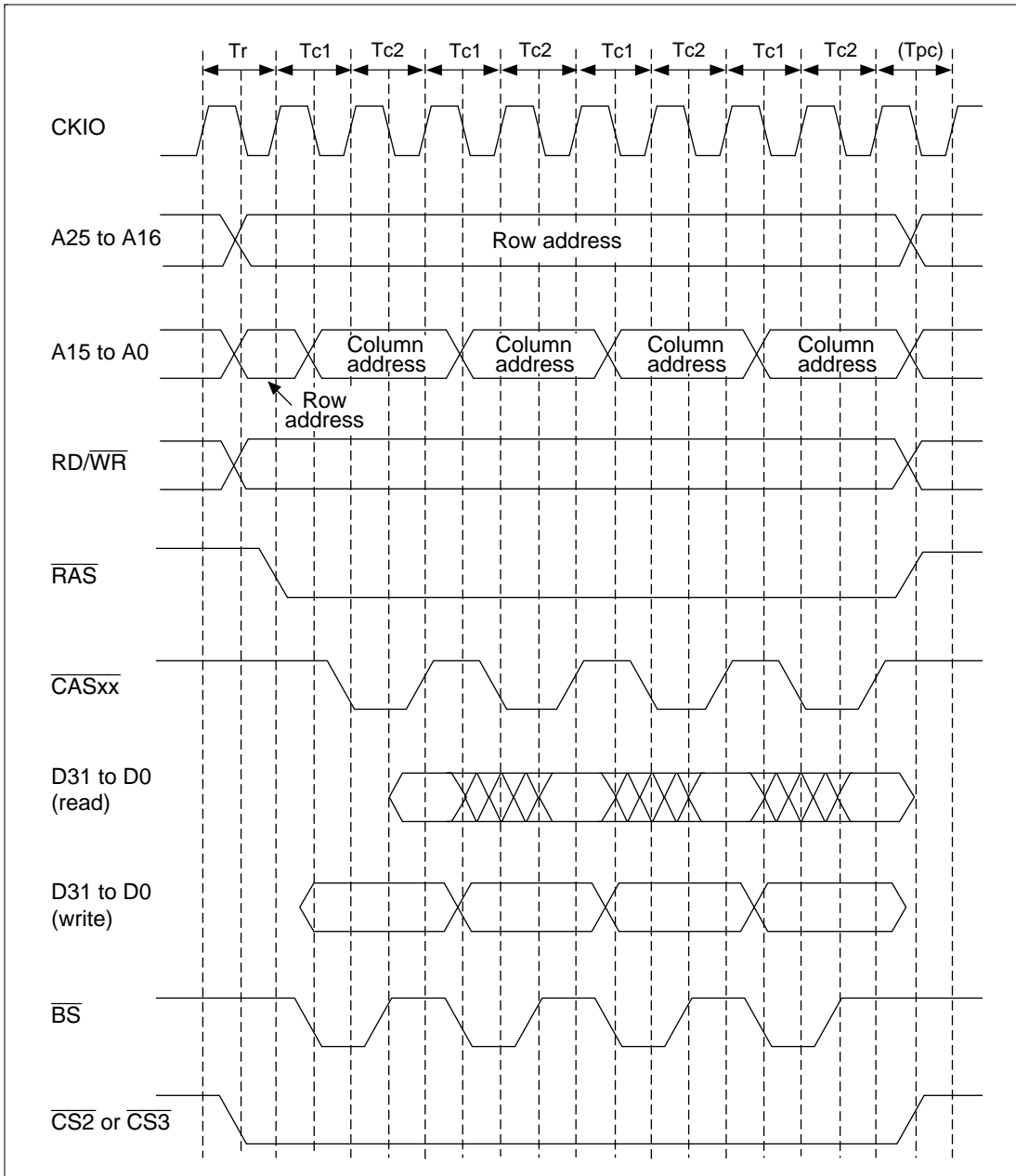


Figure 11.19 Burst Access Timing in DRAM EDO Mode

Refresh Timing: The bus state controller includes a function for controlling DRAM refreshing. Refreshing using a CAS-before-RAS cycle can be performed by clearing the RMODE bit to 0 and setting the RFSH bit to 1 in MCR for area 3 DRAM, or by clearing the RMODE bit to 0 and setting the RFSH bit to 1 in DCR for area 2 DRAM.

When CAS-before-RAS refresh cycles are executed, refreshing is performed at intervals determined by the input clock selected by bits CKS2–CKS0 in RTCSR, and the value set in RTCOR. The value of bits CKS2–CKS0 in RTCOR should be set so as to satisfy the stipulation for the DRAM refresh interval. First make the settings for RTCOR, RTCNT, and the RMODE and RFSH bits in MCR, then make the CKS2–CKS0 setting. When the clock is selected by CKS2 to CKS0, RTCNT starts counting up from the value at that time. The RTCNT value is constantly compared with the $\overline{\text{RTCOR}}$ value, and if the two values are the same, a refresh request is generated and the $\overline{\text{IRQOUT}}$ pin goes low. If the SH7718R' external bus can be used, CAS-before-RAS refreshing is performed, and if there is no other interrupt request the $\overline{\text{IRQOUT}}$ pin goes high. At the same time, RTCNT is cleared to zero and the count-up is restarted. Figure 11.20 shows the operation of CAS-before-RAS refreshing.

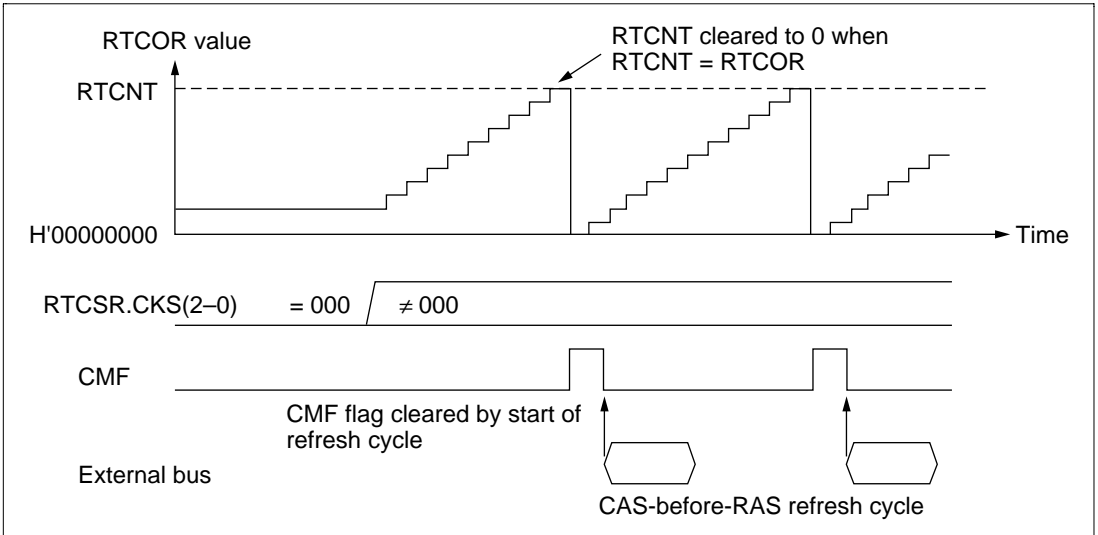


Figure 11.20 CAS-Before-RAS Refresh Operation

Figure 11.21 shows the timing of the CAS-before-RAS refresh cycle.

The number of $\overline{\text{RAS}}$ assert cycles in the refresh cycle is specified by the TRAS bits in MCR and DCR. The specification of the RAS precharge time in the refresh cycle is determined by the setting of the TPC bits in MCR and DCR in the same way as for normal access.

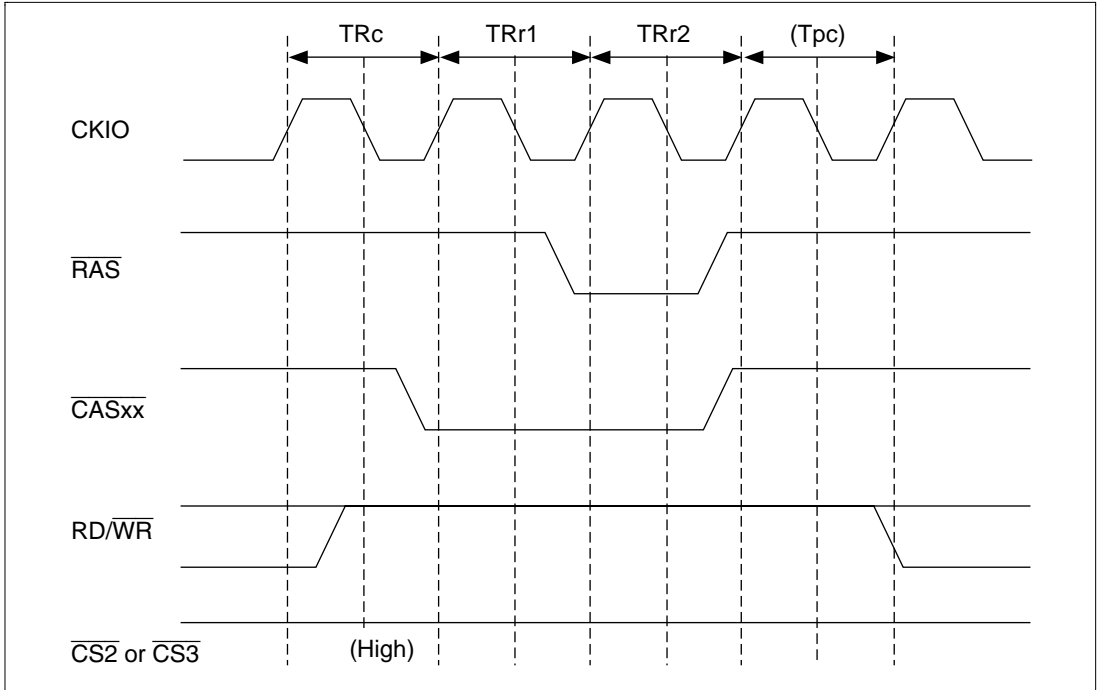


Figure 11.21 DRAM CAS-Before-RAS Refresh Cycle Timing

The self-refreshing supported by the SH7718R is shown in figure 11.22.

After the self-refresh is cleared, the refresh controller immediately generates a refresh request. The RAS precharge time immediately after the end of the self-refreshing can be set by the TPC bits in MCR and DCR.

DRAMs include low-power products (L versions) with a long refresh cycle time (for example, the L version of the HM51W4160AL has a refresh cycle of 1024 cycles/128 ms compared with 1024 cycles/16 ms for the normal version). With these DRAMs, however, the same refresh cycle as the normal version is requested only when refreshing immediately after self-refreshing. Therefore, to ensure efficient DRAM refreshing, an overflow interrupt is generated and the refresh cycle is restored to its proper value. This occurs after the necessary CAS-before-RAS refreshing has been performed following self-refreshing of an L-version DRAM, using RFCR and the OVF, OVIE, and LMTS bits in RTCSR. The procedure is as follows.

1. Normally, set the refresh counter count value to the optimum value for the L version (e.g. 1024 cycles/128 ms).
2. When a transition is made to self-refreshing:
 - a. Provide an interrupt handler to restore the refresh counter count value to the optimum value for the L version (e.g. 1024 cycles/128 ms) when a refresh counter overflow interrupt is generated.
 - b. Reset the refresh counter count value to the requested short cycle (e.g. 1024 cycles/16 ms), set refresh controller overflow interruption, and clear the refresh count register (RFCR) to 0.
 - c. Set self-refresh mode.

This procedure causes refreshing immediately following a self-refresh to occur in a short cycle. When adequate refreshing ends, an interrupt is generated and the setting can be restored to the original refresh cycle.

CAS-before-RAS refreshing is performed in normal operation, in sleep mode, and in a manual reset.

Self-refreshing is performed in normal operation, in sleep mode, in standby mode, and in a manual reset.

When the bus has been released in response to a bus arbitration request, or when a transition is made to standby mode, signals generally become high-impedance. Controlling the $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ signals to become high-impedance or continue to be output is performed with the HIZCNT bit in BCR1. This enables the DRAM to be kept in the self-refreshing state.

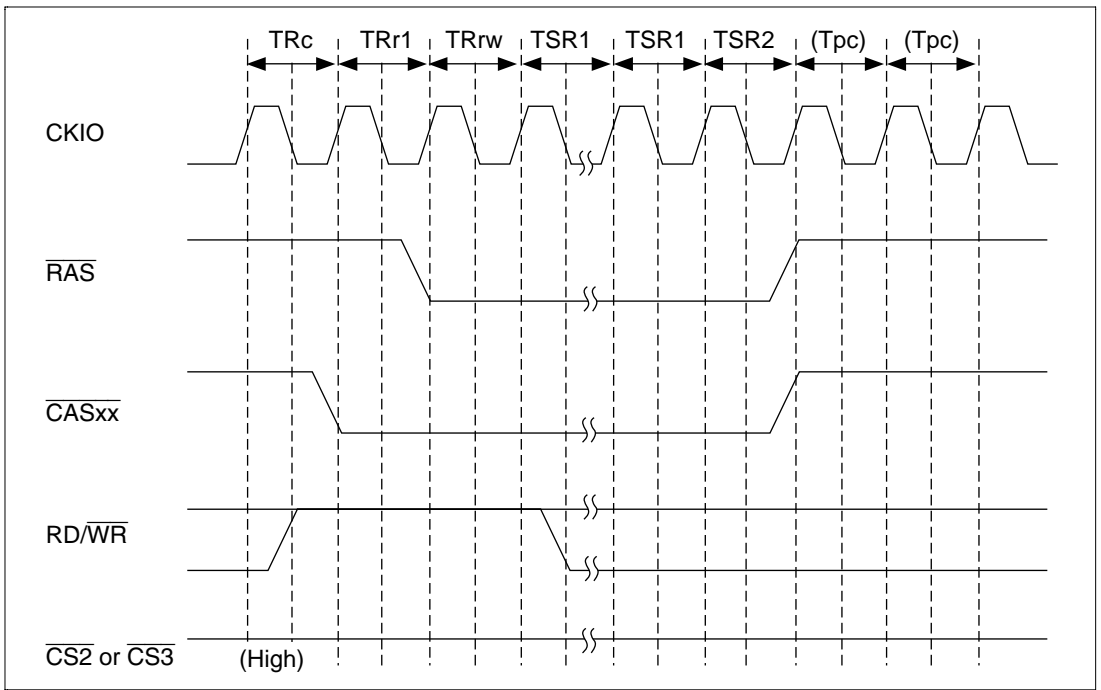


Figure 11.22 DRAM Self-Refresh Cycle Timing

Power-On Sequence: For DRAM after powering on, a minimum wait time of 100 μ s or 200 μ s, or more during which no access can be performed, should be provided, followed by the prescribed number (usually 8 or more) of dummy CAS-before-RAS refresh cycles. As the bus state controller does not perform any special operations for a power-on reset, the power-on sequence must be carried out by the initialization program executed after a power-on reset.

11.3.5 Synchronous DRAM Interface

Synchronous DRAM Direct Connection: Since synchronous DRAM can be selected by the \overline{CS} signal, physical space areas 2 and 3 can be connected using \overline{RAS} and other control signals in common. If the memory type bits (DRAMTP2–DRAMTP0) in BCR1 are set to 010, area 2 is normal memory space and area 3 is synchronous DRAM space; if set to 011, areas 2 and 3 are both synchronous DRAM space.

With the SH7718R, burst length 1 burst read/single write mode is supported as the synchronous DRAM operating mode. The data bus width is fixed at 32 bits, and the size bit (SZ) in MCR must be set to 1. The burst enable bit (BE) in MCR is ignored, a 16-bit burst transfer is performed in a cache fill/copy-back cycle, and only one access is performed in a write-through area write or a noncacheable area read/write.

The control signals for direct connection of synchronous DRAM are \overline{RAS} , \overline{CAS} , RD/\overline{WR} , $\overline{CS2}$ or $\overline{CS3}$, DQM_{UU}, DQM_{MU}, DQM_{LU}, DQM_{LL}, and CKE. All the signals other than $\overline{CS2}$ and $\overline{CS3}$ are common to all areas, and signals other than CKE are valid and fetched to the synchronous DRAM only when $\overline{CS2}$ or $\overline{CS3}$ is asserted. Synchronous DRAM can therefore be connected in parallel to a number of areas. CKE is negated (low) only when self-refreshing is performed, otherwise it is asserted (high).

Commands for synchronous DRAM are specified by \overline{RAS} , \overline{CAS} , RD/\overline{WR} , and special address signals. The commands are NOP, auto-refresh (REF), self-refresh (SELF), precharge all banks (PALL), precharge specified bank (PRE), row address strobe bank active (ACTV), read (READ), read with precharge (READA), write (WRIT), write with precharge (WRITA), and mode register write (MRS).

Byte specification is performed by DQM_{UU}, DQM_{MU}, DQM_{LU}, and DQM_{LL}. A read/write is performed for the byte for which the corresponding DQM is low. In big-endian mode, DQM_{UU} specifies an access to address $4n$, and DQM_{LL} specifies an access to address $4n + 3$. In little-endian mode, DQM_{UU} specifies an access to address $4n + 3$, and DQM_{LL} specifies an access to address $4n$.

Figure 11.23 shows an example of the connection of $256k \times 16$ -bit synchronous DRAMs.

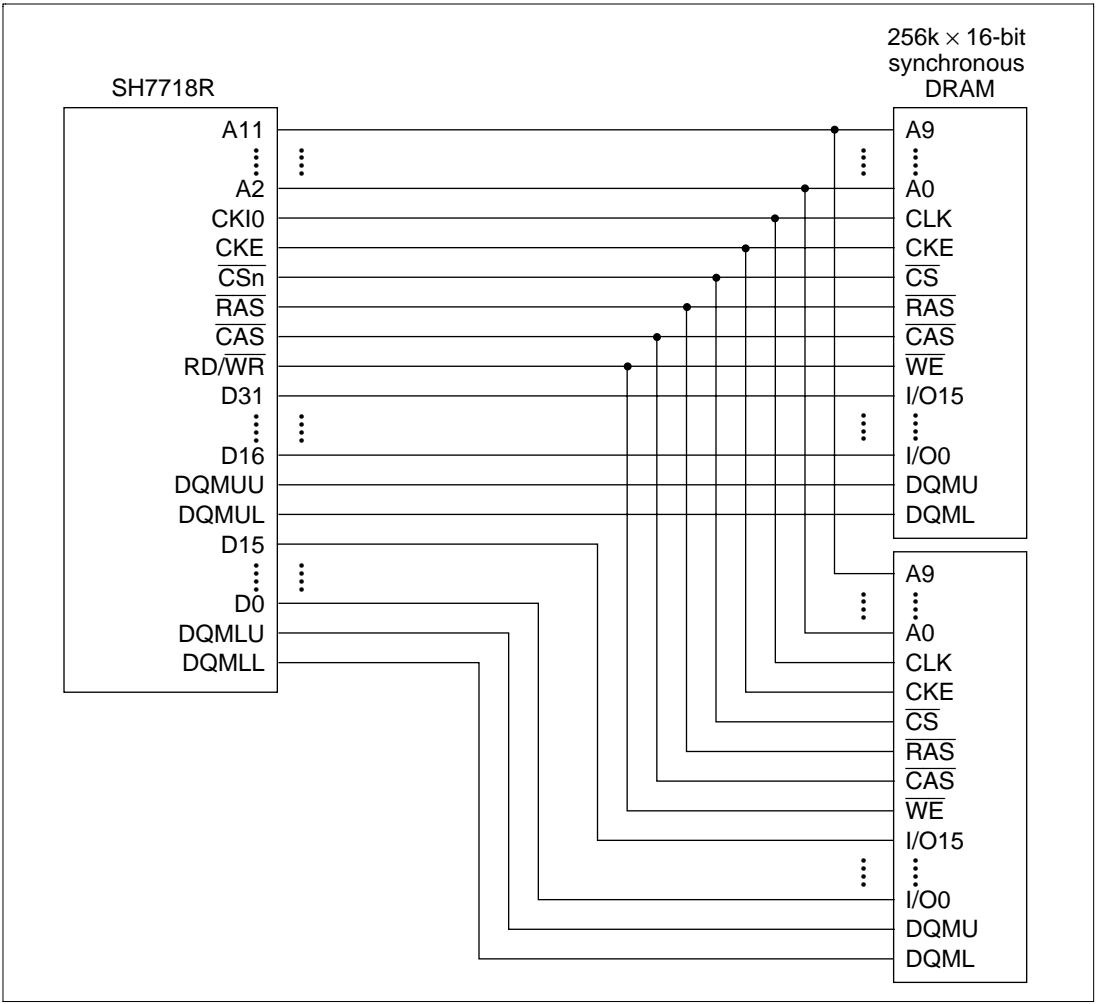


Figure 11.23 Example of Synchronous DRAM Connection

Address Multiplexing: Synchronous DRAM can be connected without external multiplexing circuitry in accordance with the address multiplex specification bits AMX1 and AMX0 in MCR. Table 11.13 shows the relationship between the address multiplex specification bits and the bits output at the address pins.

A25–A16 and A0 are not multiplexed; the original values are always output at these pins.

When A0, the LSB of the synchronous DRAM address, is connected to the SH7718R, it performs longword address specification. Connection should therefore be made in this order: connect pin A0 of the synchronous DRAM to pin A2 of the SH7718R, then connect pin A1 to pin A3. Table 11.14 shows the example of correspondence between SH7718R and synchronous DRAM address pins.

Table 11.13 Relationship between SZ, AMX, and Address Multiplex Output

Setting		Output Timing	External Address Pins							
AMX1	AMX0		A1 to A8	A9	A10	A11	A12	A13	A14	A15
0	0	Column address	A1 to A8	A9	A10	A11	A12*1	A13*2	A14	A15
		Row address	A9 to A16	A17	A18	A19	A20	A21*2	A22	A23
0	1	Column address	A1 to A8	A9	A10	A11	L/H*1	A22*2	A14	A15
		Row address	A10 to A17	A18	A19	A20	A21	A22*2	A23	A24
1	0	Column address	A1 to A8	A9	A120	A11	L/H*1	A23*2	A14	A15
		Row address	A11 to A18	A19	A20	A21	A22	A23*2	A24	A25
1	1	Column address	A1 to A8	A9	L/H*1	A19*2	A12	A13	A14	A15
		Row address	A9 to A16	A17	A18	A19*2	A20	A21	A22	A23

Notes: 1. L/H is a bit used in the command specification; it is fixed at L or H according to the access mode.

2. Bank address specification.

Table 11.14 Example of Correspondence between SH7718R and Synchronous DRAM Address Pins (AMX (1-0) = 11)

	SH7718R Address Pin		Synchronous DRAM Address Pin	Function
	RAS Cycle	CAS Cycle		
A11	A19	A19	A9	BANK select bank address
A10	A18	L/H	A8	Address precharge setting
A9	A17	A9	A7	Address
A8	A16	A8	A6	
A7	A15	A7	A5	
A6	A14	A6	A4	
A5	A13	A5	A3	
A4	A12	A4	A2	
A3	A11	A3	A1	
A2	A10	A2	A0	
A1	A9	A1	Not used	
A0	A0	A0	Not used	

Burst Read: The timing chart for a burst read is shown in figure 11.24. In the following example it is assumed that four $2M \times 8$ -bit synchronous DRAMs are connected and a 32-bit data width is used, and the burst length is 1. Following the T_r cycle in which ACTV command output is performed, a READ command is issued in the T_{c1} , T_{c2} , and T_{c3} cycles, and a READA command in the T_{c4} cycle. The read data is then accepted on the rising edge of the external command clock (CKIO) from cycle T_{d1} to cycle T_{d4} . The T_{pc} cycle is used to wait for completion of auto-precharge based on the READA command inside the synchronous DRAM; no new access command can be issued to the same bank during this cycle, but access to synchronous DRAM for another area is possible. In the SH7718R, the number of T_{pc} cycles is determined by the TPC bit specification in MCR, and commands cannot be issued for the same synchronous DRAM during this interval.

The example in figure 11.24 shows the basic timing. To connect slower synchronous DRAM, the cycle can be extended by setting the WCR2 and MCR bits. The number of cycles from the ACTV command output cycle, T_r , to the READ command output cycle, T_{c1} , can be specified by the RCD bit in MCR, with a value of 0 to 3 specifying 1 to 4 cycles, respectively. For 2 or more cycles, a T_{rw} cycle, in which an NOP command is issued for the synchronous DRAM, is inserted between the T_r cycle and the T_c cycle. The number of cycles from READ and READA command output cycles T_{c1} – T_{c4} to the first read data latch cycle, T_{d1} , can be specified as 1 to 3 cycles independently for areas 2 and 3 by means of A1–2W1 and A1–2W0 or A3W1 and A3W0 in WCR2. This number of cycles corresponds to the number of synchronous DRAM CAS latency cycles.

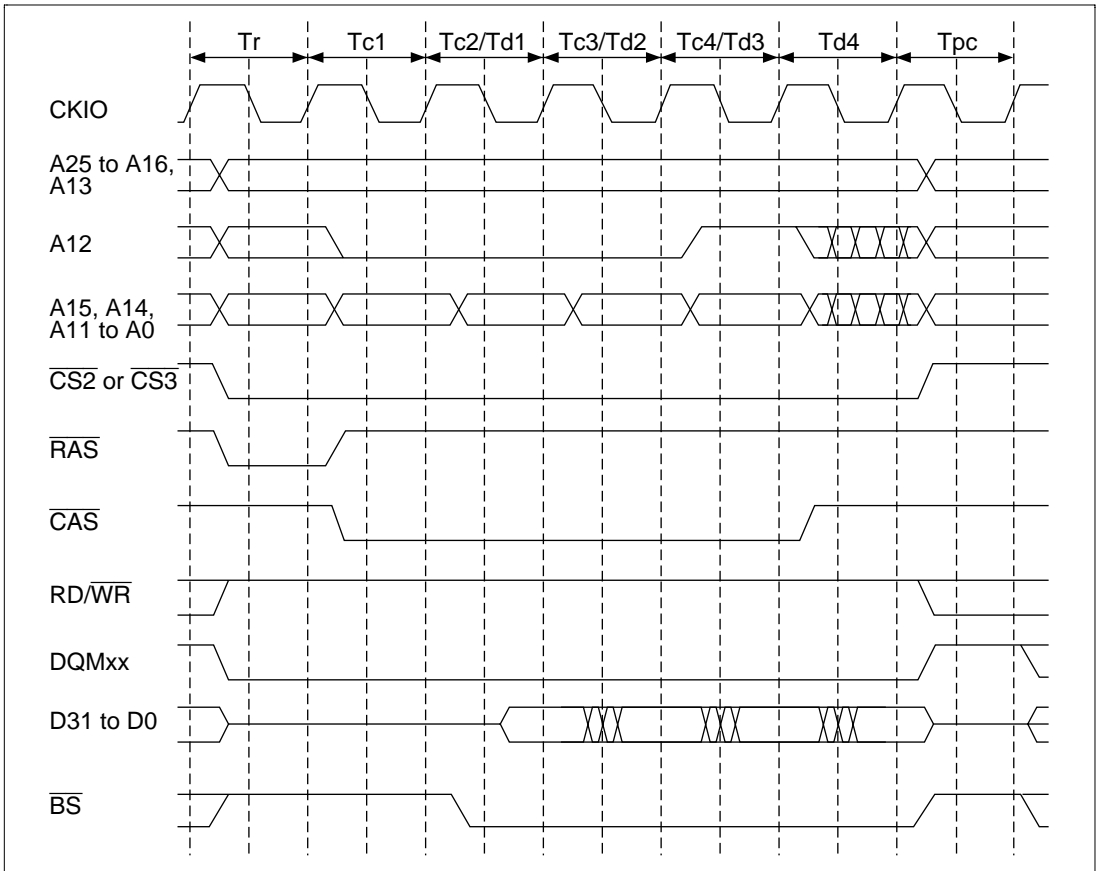


Figure 11.24 Basic Timing for Synchronous DRAM Burst Read

Figure 11.25 shows the burst read timing when RCD is set to 1, A3W1 and A3W0 are set to 11, and TPC is set to 1.

The \overline{BS} cycle, which is asserted for one cycle at the start of a bus cycle for normal access space, is asserted in each of cycles Td1–Td4 in a synchronous DRAM cycle. When a burst read is performed, the address is updated each time \overline{CAS} is asserted. As the unit of burst transfer is 16 bytes, address updating is performed for A3 and A2 only. In a fill operation in the event of a cache miss, the order of access is is: the missed data is read first, then 16-byte boundary data including the missed data is read in wraparound mode.

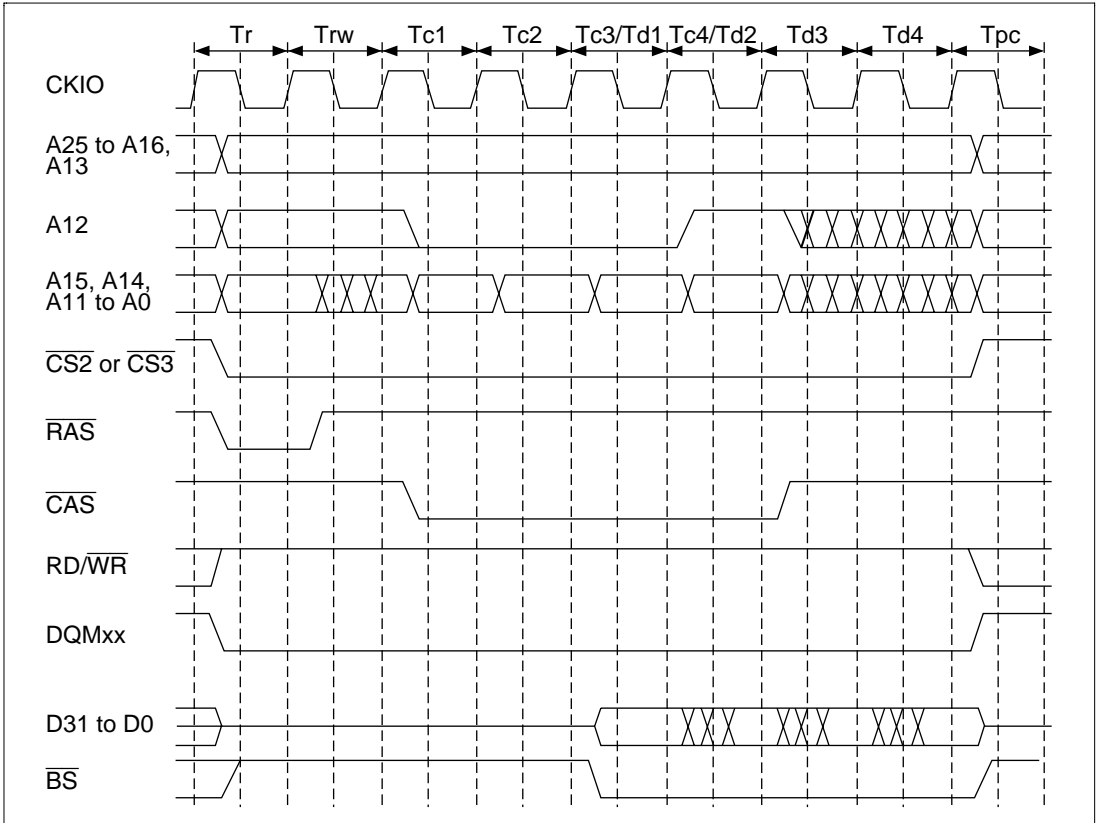


Figure 11.25 Synchronous DRAM Burst Read Wait Specification Timing

Single Read: Figure 11.26 shows the timing when a single address read is performed. As the burst length is set to 1 in synchronous DRAM burst read/single write mode, only the required data is output. Consequently, no unnecessary bus cycles are generated even when a cache-through area is accessed.

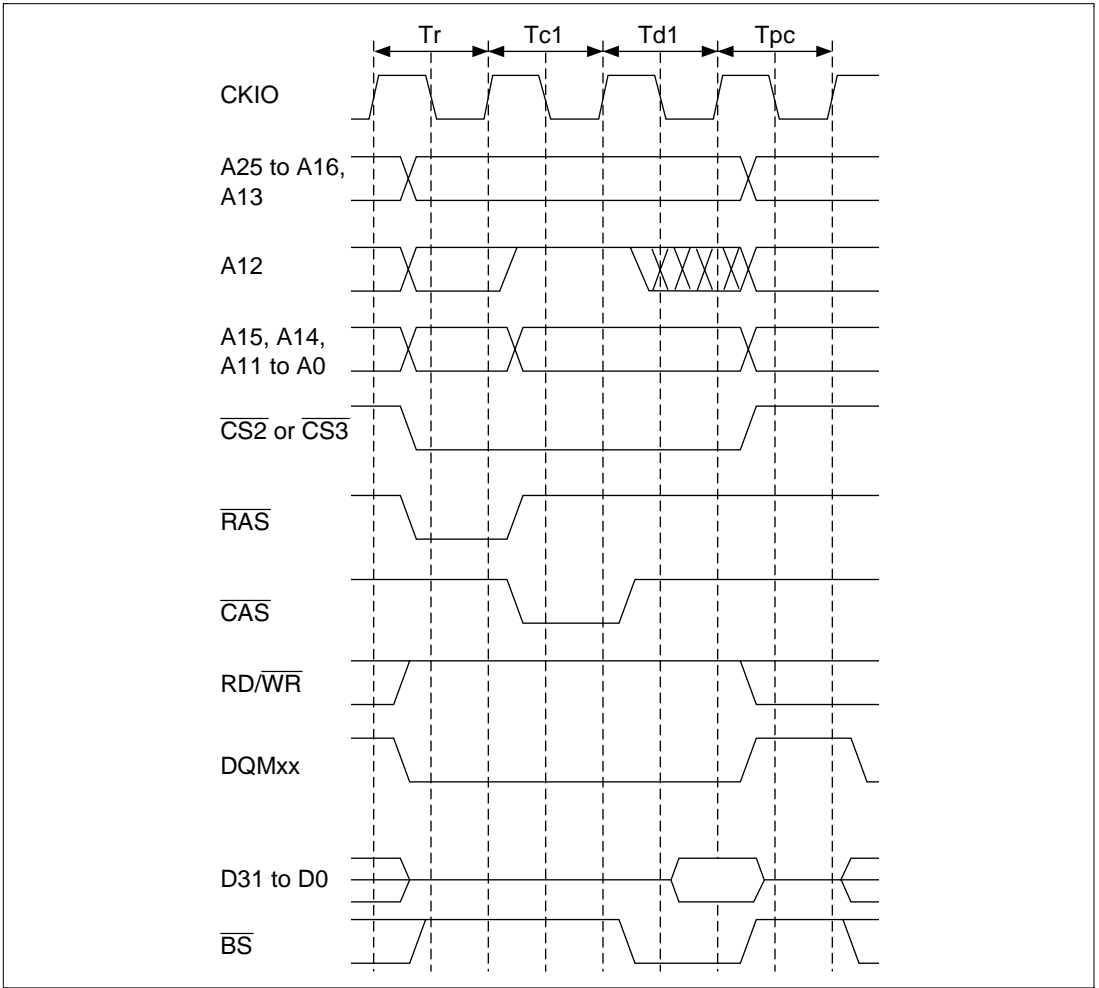


Figure 11.26 Basic Timing for Synchronous DRAM Single Read

Burst Write: The timing chart for a burst write is shown in figure 11.27. In the SH7718R, a burst write occurs only in the event of cache copy-back. In a burst write operation, following the Tr cycle in which ACTV command output is performed, a WRIT command is issued in the Tc1, Tc2, and Tc3 cycles, and a WRITA command that performs auto-precharge is issued in the Tc4 cycle. In the write cycle, the write data is output at the same time as the write command. For the write with auto-precharge command, precharging of the relevant bank is performed in the synchronous DRAM after completion of the write command, and therefore no command can be issued for the same bank until precharging is completed. Consequently, in addition to the precharge wait cycle, Tpc, used in a read access, cycle Trwl is added as a wait interval until precharging is started, following the write command. Issuance of a new command for the same bank is postponed during this interval. The number of Trwl cycles can be specified by the TRWL bit in MCR.

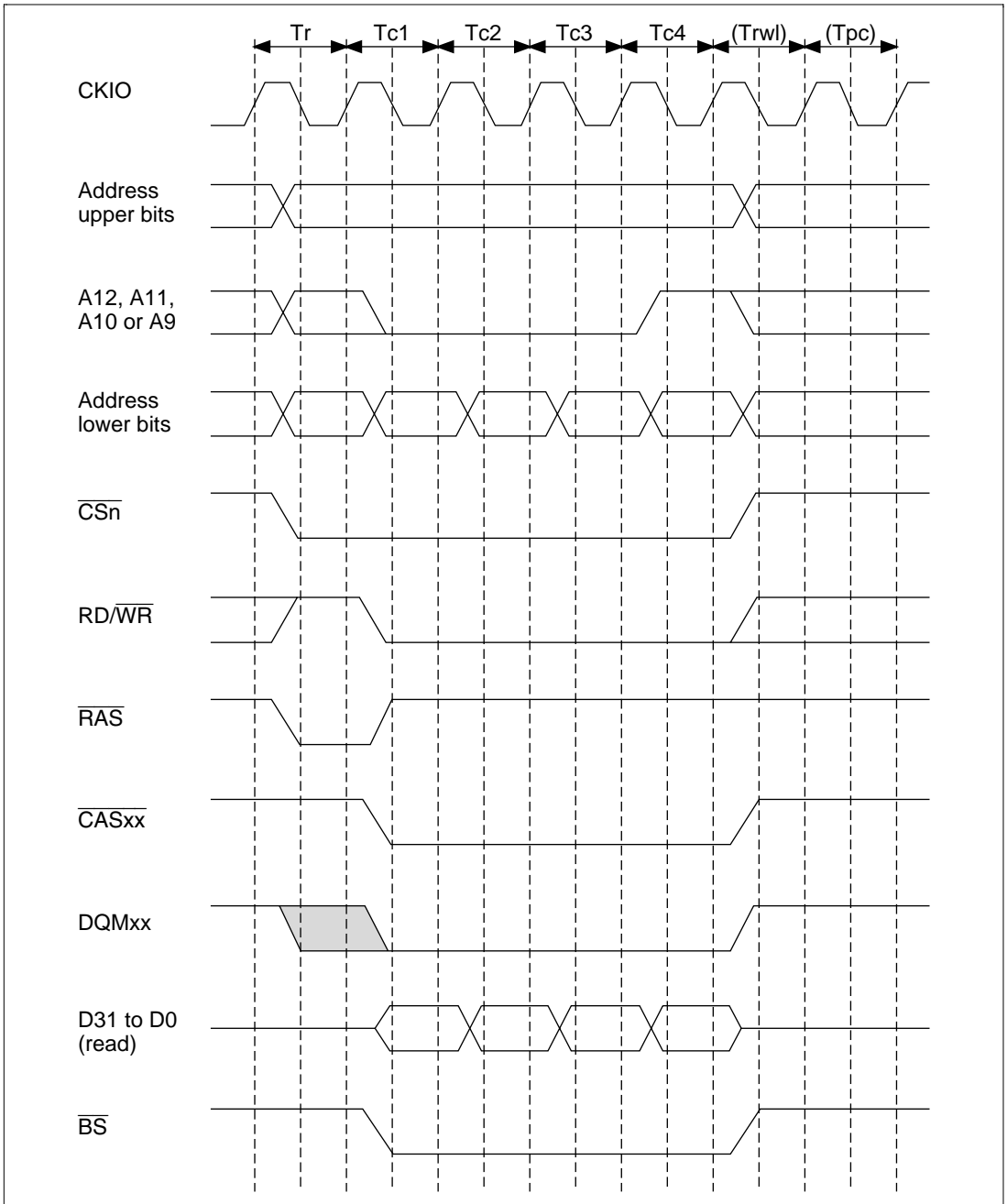


Figure 11.27 Basic Timing for Synchronous DRAM Burst Write

Single Write: The basic timing chart for write access is shown in figure 11.28. In a single write operation, following the T_r cycle in which ACTV command output is performed, a WRITA command that performs auto-precharge is issued in the T_{c1} cycle. In the write cycle, the write data is output at the same time as the write command. For the write with auto-precharge command, precharging of the relevant bank is performed in synchronous DRAM after completion of the write command, and therefore no command can be issued for the same bank until precharging is completed. Consequently, in addition to the precharge wait cycle, T_{pc} , used in a read access, cycle T_{rwl} is also added as a wait interval until precharging is started following the write command. Issuance of a new command for the same bank is postponed during this interval. The number of T_{rwl} cycles can be specified by the TRWL bit in MCR.

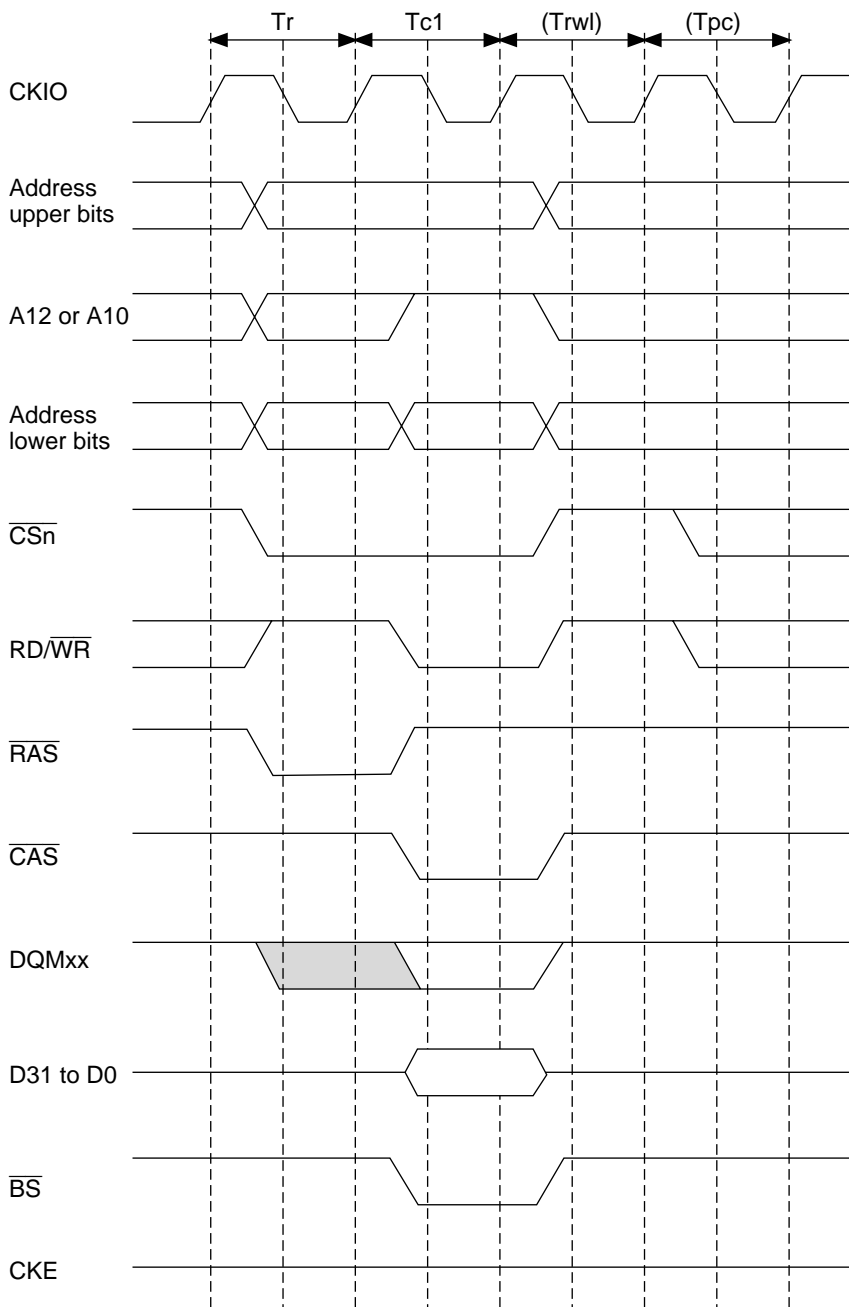


Figure 11.28 Basic Timing for Synchronous DRAM Single Write

Refreshing: The bus state controller is provided with a function for controlling synchronous DRAM refreshing. Auto-refreshing can be performed by clearing the RMODE bit to 0 and setting the RFSH bit to 1 in MCR. If synchronous DRAM is not accessed for a long period, self-refresh mode, in which the power consumption for data retention is low, can be activated by setting both the RMODE bit and the RFSH bit to 1.

1. Auto-Refreshing

Refreshing is performed at intervals determined by the input clock selected by bits CKS2–CKS0 in RTCSR, and the value set in RTCOR. The value of bits CKS2–CKS0 in RTCOR should be set so as to satisfy the refresh interval stipulation for the synchronous DRAM used. First make the settings for RTCOR, RTCNT, and the RMODE and RFSH bits in MCR, then make the CKS2 to CKS0 setting. When the clock is selected by CKS2–CKS0, RTCNT starts counting up from the value at that time. The RTCNT value is constantly compared with the RTCOR value, and if the two values are the same, a refresh request is generated and an auto-refresh is performed. At the same time, RTCNT is cleared to zero and the count-up is restarted. Figure 11.29 shows the auto refresh operation. Figure 11.30 shows the auto-refresh cycle timing.

First, an REF command is issued in the TRr cycle. After the TRr cycle, new command output cannot be performed for the duration of the number of cycles specified by the TRAS bits in MCR plus the number of cycles specified by the TPC bits in MCR. The TRAS and SPC bits must be set to satisfy the synchronous DRAM refresh cycle time stipulation (active/active command delay time).

Auto-refreshing is performed in normal operation, in sleep mode, and in a manual reset.

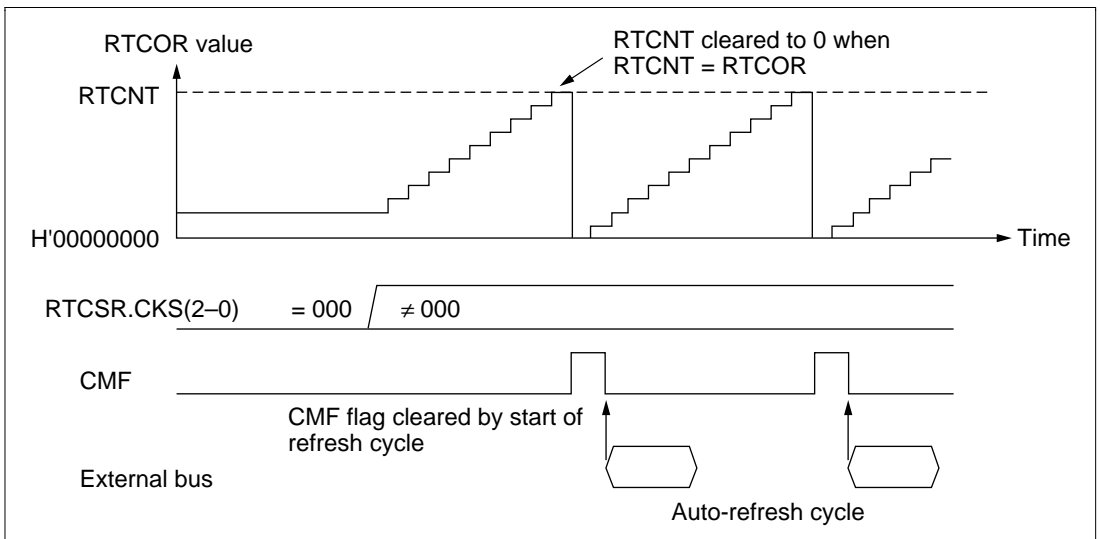


Figure 11.29 Auto-Refresh Operation

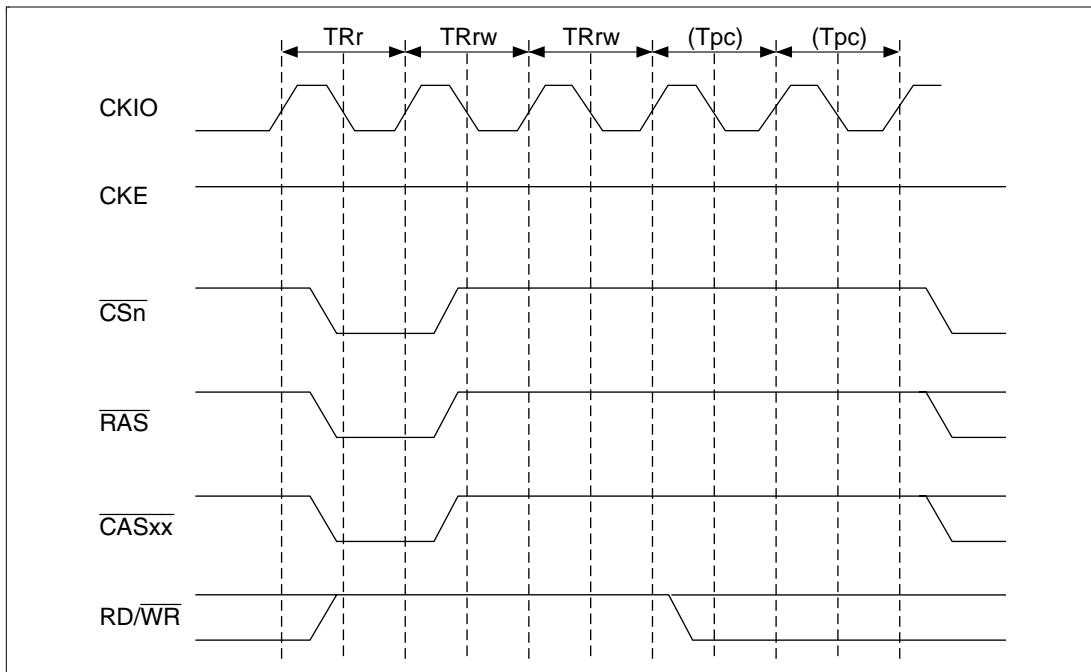


Figure 11.30 Synchronous DRAM Auto-Refresh Timing

2. Self-Refreshing

Self-refresh mode is a kind of standby mode in which the refresh timing and refresh addresses are generated within the synchronous DRAM. Self-refreshing is activated by setting both the RMODE bit and the RFSH bit to 1. The self-refresh state is maintained while the CKE signal is low. Synchronous DRAM cannot be accessed while in the self-refresh state. Self-refresh mode is cleared by clearing the RMODE bit to 0. After self-refresh mode has been cleared, command issuance is disabled for the number of cycles specified by the TPC bits in MCR. Self-refresh timing is shown in figure 11.31. Settings must be made so that self-refresh clearing and data retention are performed correctly, and auto-refreshing is performed at the correct intervals. When self-refreshing is activated from the state in which auto-refreshing is set, or when exiting standby mode other than through a power-on reset, auto-refreshing is restarted if RFSH is set to 1 and RMODE is cleared to 0 when self-refresh mode is cleared. If the transition from clearing of self-refresh mode to the start of auto-refreshing takes time, this time should be taken into consideration when setting the initial value of RTCNT. Making the RTCNT value 1 less than the RTCOR value will enable refreshing to be started immediately.

After self-refreshing has been set, the self-refresh state continues even if the chip standby state is entered using the SH7718R's standby function, and is maintained even after recovery from standby mode other than through a power-on reset. For a power-on reset, the bus state controller's registers are initialized, thereby clearing the self-refresh state.

Self-refreshing is performed in normal operation, in sleep mode, in standby mode, and in a manual reset.

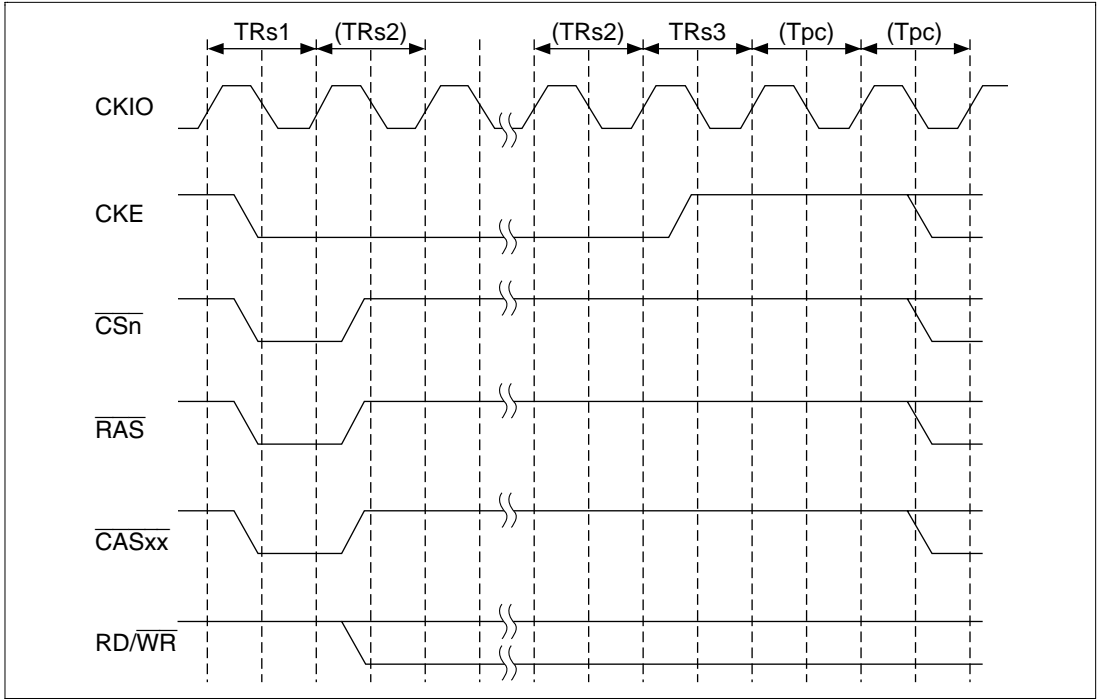


Figure 11.31 Synchronous DRAM Self-Refresh Timing

3. Relationship between refresh requests and bus cycle requests

If a refresh request is generated during execution of a bus cycle, execution of the refresh is deferred until the bus cycle is completed. If a refresh request occurs when the bus has been released by the bus arbiter, refresh execution is deferred until the bus is acquired. If a match between RTCNT and RTCOR occurs while a refresh is waiting to be executed, thereby generating a new refresh request, the previous refresh request is eliminated. To perform normal refreshing, ensure that no bus cycle or bus mastership occurs that is longer than the refresh interval. When a refresh request is generated, the $\overline{\text{IRQOUT}}$ pin is asserted (driven low). Therefore, normal refreshing can be performed by having the $\overline{\text{IRQOUT}}$ pin monitored by a bus master other than the SH7718R requesting the bus, or the bus arbiter, and returning the bus to the SH7718R. When refreshing is started, and if no other interrupt request has been generated, the $\overline{\text{IRQOUT}}$ pin is negated (driven high).

Power-On Sequence: In order to use synchronous DRAM, mode setting must first be performed after powering on. To perform synchronous DRAM initialization correctly, the bus state controller registers must first be set, followed by a write to the synchronous DRAM mode register. In synchronous DRAM mode register setting, the address signal value at that time is latched by a combination of the $\overline{\text{RAS}}$, $\overline{\text{CAS}}$, and $\overline{\text{RD/WR}}$ signals. If the value to be set is X, the bus state controller provides for value X to be written to the synchronous DRAM mode register by performing a write to address $\text{H'FFFFD000} + \text{X}$ for area 2 synchronous DRAM, and to address $\text{H'FFFFE000} + \text{X}$ for area 3 synchronous DRAM. In this operation the data is ignored, but the mode write is performed as a byte-size access. To set burst read/write, CAS latency 1 to 3, wrap type = sequential, and burst length 1 supported by the SH7718R, arbitrary data is written in a byte-size access to the following addresses:

	Area 2	Area 3
CAS latency 1	FFFFD840	FFFFE840
CAS latency 2	FFFFD880	FFFFE880
CAS latency 3	FFFFD8C0	FFFFE8C0

Mode register setting timing is shown in figure 11.32.

As a result of the write to address $\text{H'FFFFD000} + \text{X}$ or $\text{H'FFFFE000} + \text{X}$, a precharge all banks (PALL) command is first issued in the TRp1 cycle, then a mode register write command is issued in the TMw1 cycle.

Before mode register setting, a 100 μs idle time (depending on the memory manufacturer) must be guaranteed after powering on requested by the synchronous DRAM. If the reset signal pulse width is greater than this idle time, there is no problem in performing mode register setting immediately. The number of dummy auto-refresh cycles specified by the manufacturer (usually 8) or more must be executed. This is usually achieved automatically through various initialization methods after auto-refresh setting. However, a more dependable method is to set a short refresh request generation interval just as these dummy cycles are being executed. With simple read or write access, the address counter in the synchronous DRAM used for auto-refreshing is not initialized, and so the cycle must always be an auto-refresh cycle.

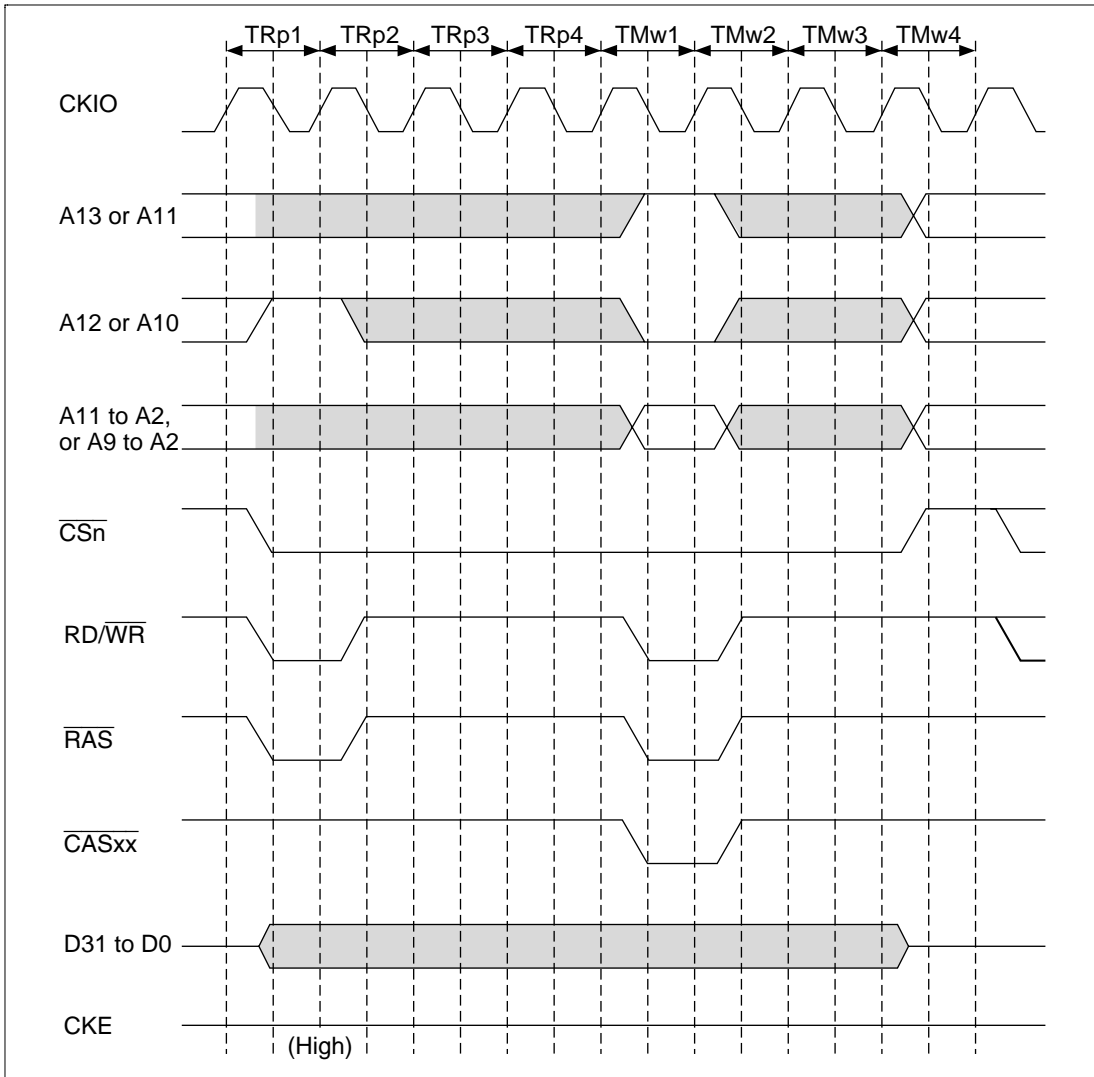


Figure 11.32 Synchronous DRAM Mode Write Timing

11.3.6 Pseudo-SRAM Direct Connection

When the memory type bits (DRAMTP2-0) in BCR1 are set to 001, physical space area 3 becomes pseudo-SRAM and the pseudo-SRAM interface function that allows pseudo-SRAM to be connected directly to the SH7718R can be used. An interface data width of 16 or 32 bits can be selected.

With directly connected pseudo-SRAM, the refresh signal and output enable signal are multiplexed. The signals used for connection are \overline{CE} , $\overline{OE/RFSH}$, $\overline{WE3}$, $\overline{WE2}$, $\overline{WE1}$, and $\overline{WE0}$. $\overline{WE3}$ and $\overline{WE2}$ are not used with a 16-bit data width.

As access modes, burst access using the static column access function is supported in addition to ordinary read/write access.

Figure 11.33 shows an example of connection of 4M pseudo-SRAMs with multiplexed \overline{OE} and \overline{RFSH} signals, using a 32-bit data width.

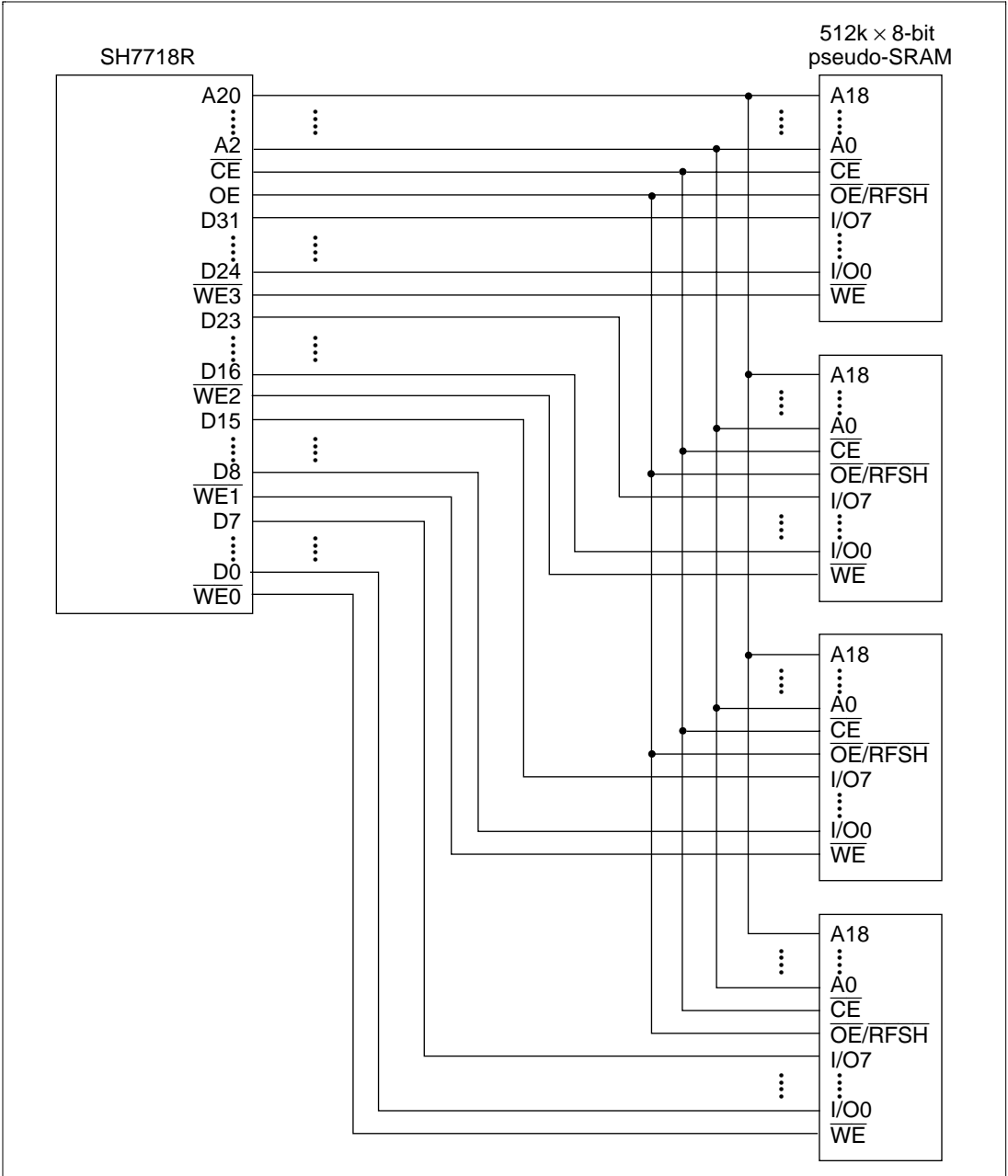


Figure 11.33 Example of Pseudo-SRAM Connection (4M-Bit Devices)

Basic Timing: Figure 11.34 shows the basic timing for pseudo-SRAM. T_{pc} is the precharge cycle, and T_r is the \overline{CE} assert cycle. T_{c1} is the write data cycle, \overline{BS} the assert cycle, and T_{c2} the read data latch cycle.

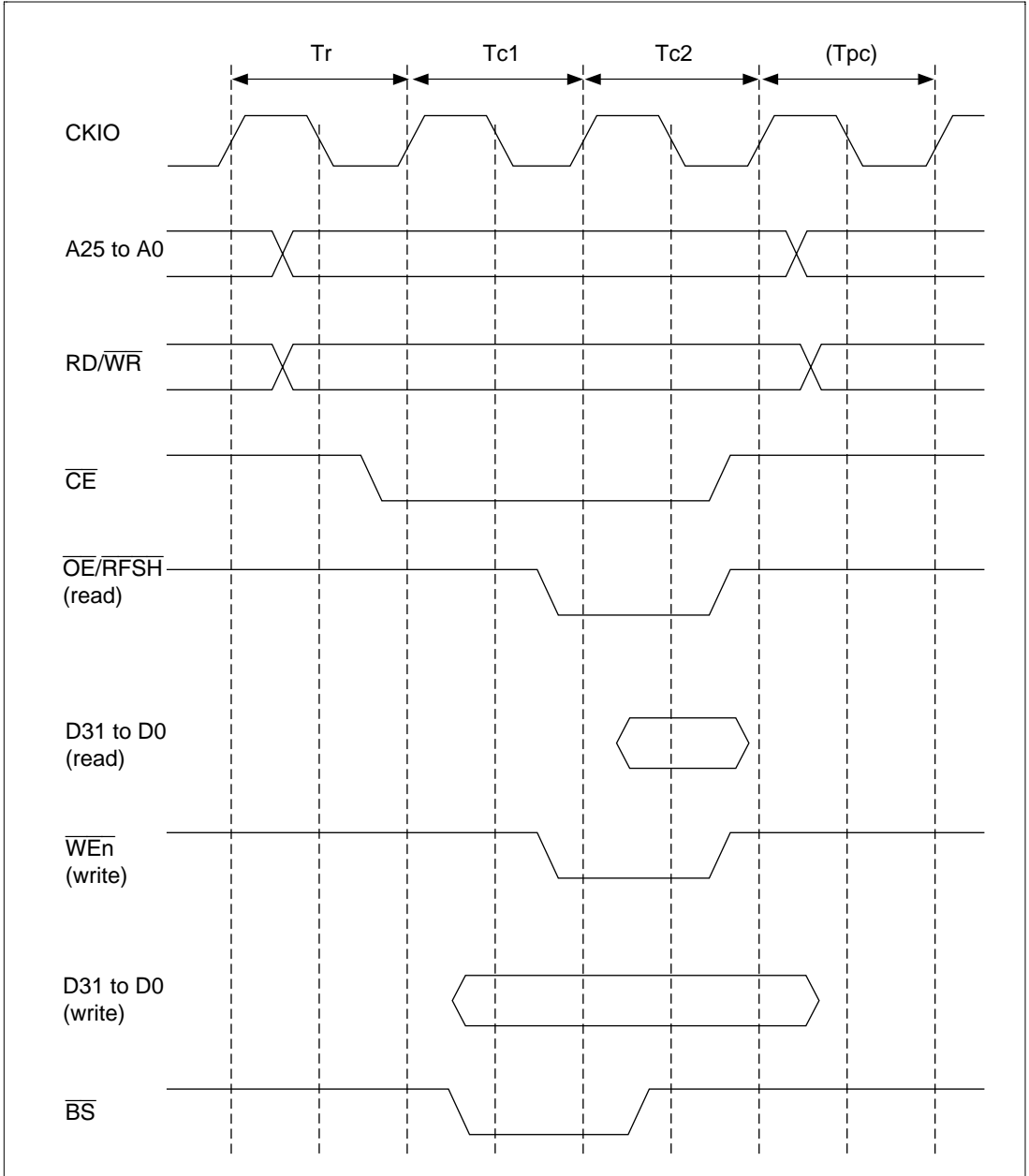


Figure 11.34 Basic Access Timing for Pseudo-SRAM

Wait State Control: As the clock frequency increases, it becomes impossible to complete all states in one cycle as in basic access. Therefore, provision is made for state extension by using the setting bits in WCR2 and MCR. The timing with state extension using these settings is shown in figure 11.35. Additional Tpc cycles (cycles used to secure the $\overline{\text{CE}}$ precharge time) can be inserted by means of the TPC bits in MCR. The number of $\overline{\text{OE}}$ and $\overline{\text{WE}}$ n assert cycles from RAS assertion to CAS assertion can be varied between 1 and 3 according to the setting of A3W1 and A3W0 in WCR2. Trw cycles can be inserted by means of the RCD bits in MCR, and the number of cycles from $\overline{\text{CE}}$ assertion to $\overline{\text{BS}}$ assertion and write data output can be varied between 1 and 4.

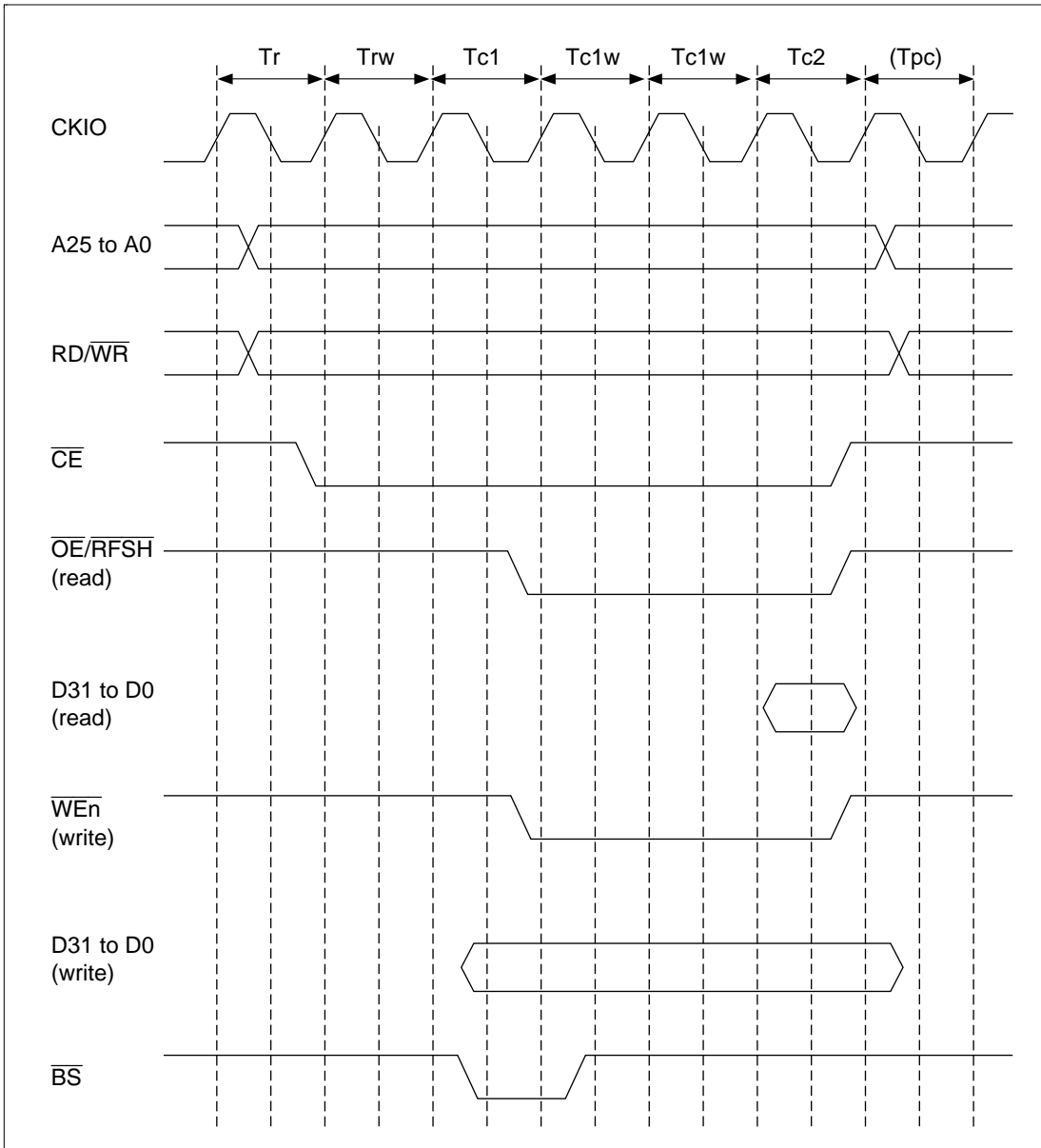


Figure 11.35 Pseudo-SRAM Wait State Timing

Burst Access: In addition to the normal access mode in which \overline{CE} is asserted and negated in each access, some pseudo-SRAMs are provided with a static column mode for the case where consecutive accesses are made to the same row address. This mode allows fast access to data by keeping \overline{CE} asserted and changing only the column address. Normal access or burst access using static column mode can be selected by means of the burst enable (BE) bit in MCR. The timing for burst access in static column mode is shown in figure 11.36. Cycles can also be inserted by the wait state control function when burst access is performed.

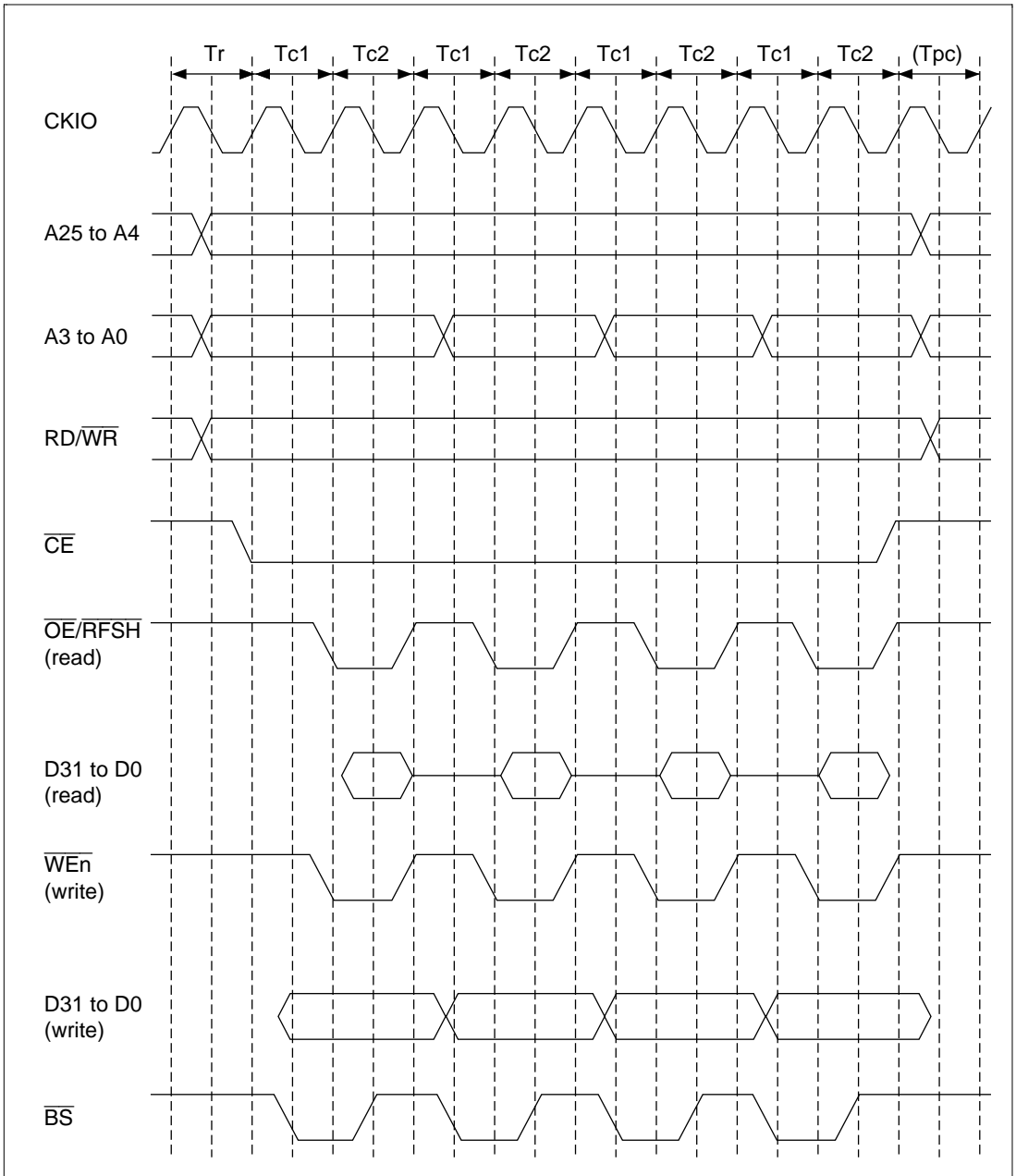


Figure 11.36 Pseudo-SRAM Static Column Mode

Refreshing: The bus state controller includes a function for controlling pseudo-SRAM refreshing. Distributed refreshing by means of auto-refresh cycles can be performed by clearing the RMODE bit to 0 and setting the RFSH bit to 1 in MCR.

Refreshing is performed at intervals determined by the input clock selected by bits CKS2–CKS0 in RTCSR, and the value set in RTCOR. The value of bits CKS2–CKS0 in RTCOR should be set so as to satisfy the refresh interval stipulation for the pseudo-SRAM used. First set the RTCOR, RTCNT, and the RMODE and RFSH bits in MCR, then set the CKS2–CKS0. When the clock is selected by CKS2–CKS0, RTCNT starts counting up from the value at that time. The RTCNT value is constantly compared with the RTCOR value, and if the two values are the same, a refresh request is generated and an auto-refresh is performed. At the same time, RTCNT is cleared to zero and the count-up is restarted. Figure 11.37 shows the auto-refresh cycle timing.

The number of $\overline{\text{OE}}$ assert cycles for auto-refreshing is specified by the TRAS bits in MCR. The precharge time from $\overline{\text{OE}}$ negation until the next assertion of $\overline{\text{CE}}$ is determined by the setting of the TPC bits in MCR.

Auto-refreshing is performed in normal operation, in sleep mode, and in a manual reset.

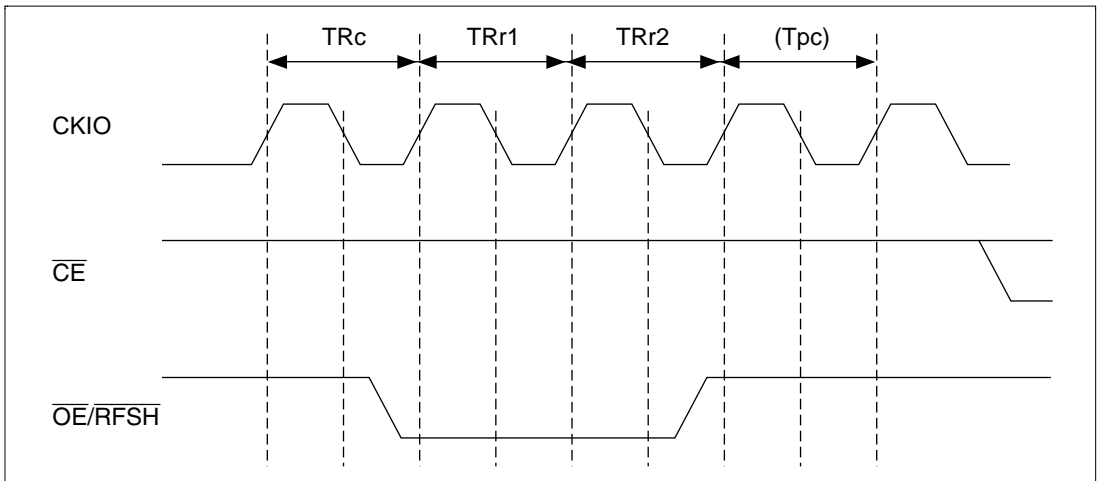


Figure 11.37 Pseudo-SRAM Auto-Refreshing

With pseudo-SRAM, self-refresh mode is entered by holding the $\overline{\text{RFSH}}$ signal low for at least the prescribed time. Self-refreshing is activated by setting both the RMODE bit and the RFSH bit to 1. The self-refresh state is maintained while the CKE signal is low. Pseudo-SRAM cannot be accessed while in self-refresh state. Self-refresh mode is cleared by clearing the RMODE bit to 0. After self-refresh mode has been cleared, access to pseudo-SRAM is disabled for the number of cycles specified by the TPC bits in MCR, but if the refresh reset time needed to return from self-refreshing is longer than this interval, coding must be provided to ensure that no access—including auto-refresh—is made to pseudo-SRAM. Self-refresh timing is shown in figure 11.38. Settings must be made so that self-refresh clearing and data retention is performed correctly after self-refresh mode is cleared, and auto-refreshing is performed at the correct intervals. If the transition from clearing of self-refresh mode to the start of auto-refreshing takes time, this time should be taken into consideration when setting the initial value of RTCNT.

Self-refreshing is performed in normal operation, in sleep mode, in standby mode, and in a manual reset.

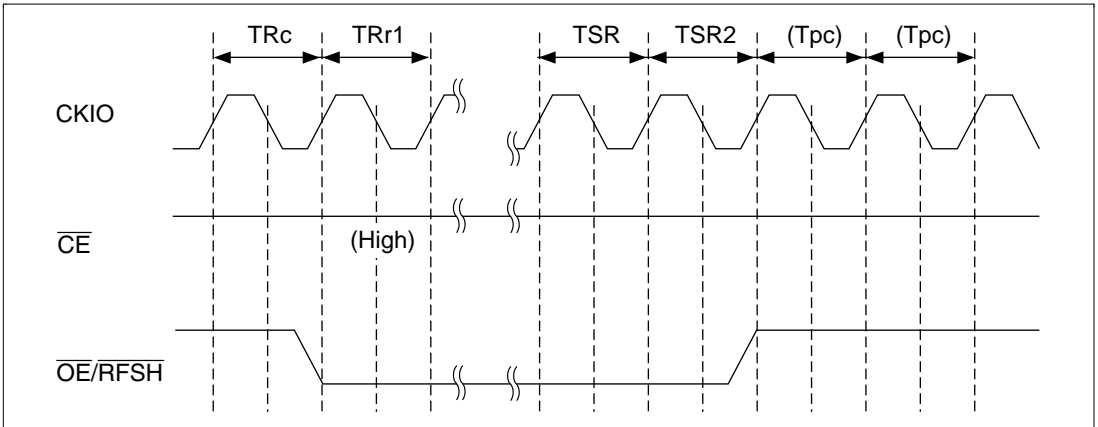


Figure 11.38 Pseudo-SRAM Self-Refreshing

Power-On Sequence: After powering pseudo-SRAM on, a minimum wait time of 100 μs is requested during which no access can be performed, followed by the prescribed number (usually 8 or more) of dummy auto-refresh cycles. As the bus state controller does not perform any special operations for a power-on reset, the power-on sequence must be carried out by the initialization program executed after a power-on reset.

11.3.7 Burst ROM Interface

Setting bits A0BST (1,0), A5BST (1,0), and A6BST (1,0) in BCR1 to a non-zero value allows burst ROM to be connected to areas 0, 5, and 6. The burst ROM interface provides high-speed access to ROM that has a nibble access function. The timing for nibble access to burst ROM is shown in figure 11.39. Two wait cycles are set. Basically, access is performed in the same way as for normal space, but when the first cycle ends, the $\overline{CS0}$ signal is not negated, and only the address is changed before the next access is executed. When 8-bit ROM is connected, the number of consecutive accesses can be set as 4, 8, or 16 by bits A0BST (1,0), A5BST (1,0), or A6BST (1,0). When 16-bit ROM is connected, 4 or 8 can be set in the same way. When 32-bit ROM is connected, only 4 can be set.

\overline{WAIT} pin sampling is performed in the first access if one or more wait states are set, and is always performed in the second and subsequent accesses.

The second and subsequent access cycles also comprise two cycles when a burst ROM setting is made and the wait specification is 0. The timing in this case is shown in figure 11.40.

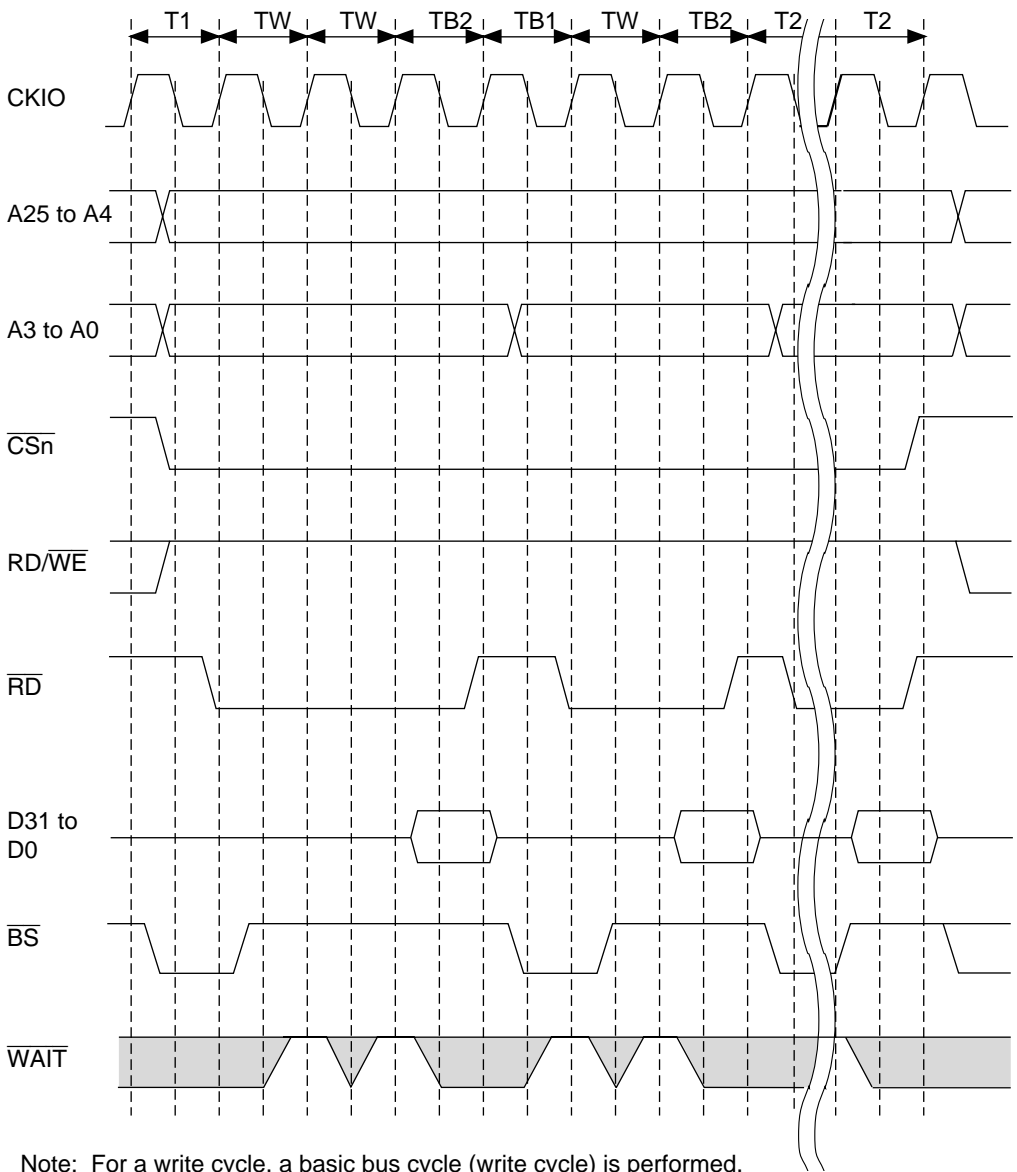
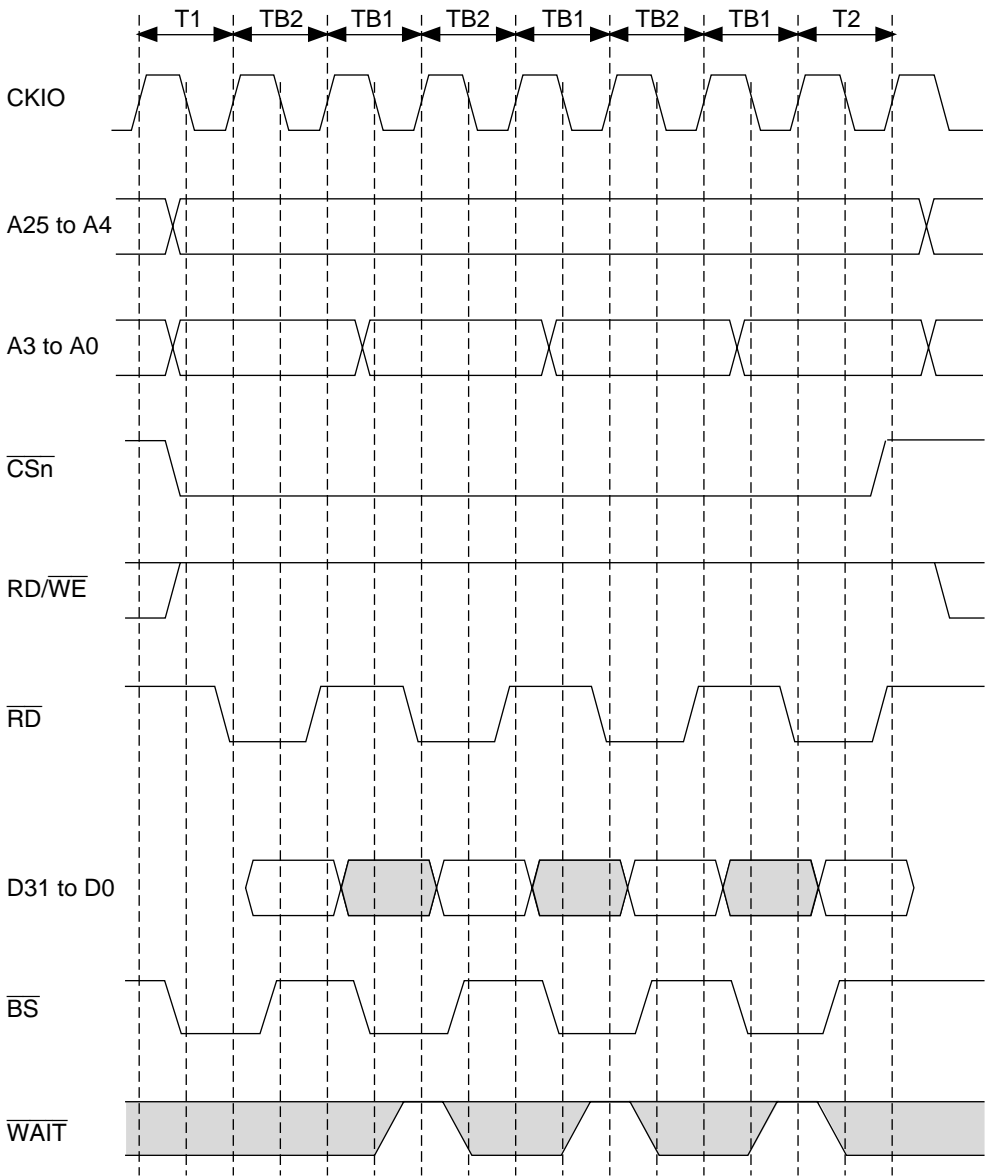


Figure 11.39 Burst ROM Wait Access Timing



Note: For a write cycle, a basic bus cycle (write cycle) is performed.

Figure 11.40 Burst ROM Basic Access Timing

11.3.8 PCMCIA Interface

In the SH7718R, setting the A5PCM bit in BCR1 to 1 makes the bus interface for physical space area 5 an IC memory card interface as stipulated in JEIDA version 4.2 (PCMCIA2.1). Setting the A6PCM bit to 1 makes the bus interface for physical space area 6 an IC memory card and I/O card interface as stipulated in JEIDA version 4.2. When the IC memory card interface is selected, a BCR1 register setting enables page mode burst access mode to be used. This burst access mode is not stipulated in JEIDA version 4.2, but allows high-speed data access using ROM provided with a burst mode, etc.

When the PCMCIA interface is used, a bus size of 8 or 16 bits can be set by bits A5SZ1 and A5SZ0, or A6SZ1 and A6SZ0, in BCR2.

Figure 11.41 shows an example of PCMCIA card connection to the SH7718R. To enable active insertion of the PCMCIA cards (i.e. insertion or removal while system power is being supplied), a 3-state buffer must be connected between the SH7718R's bus interface and the PCMCIA cards.

As operation in big-endian mode is not explicitly stipulated in the JEIDA/PCMCIA specifications, the PCMCIA interface for the SH7718R in big-endian mode is stipulated independently.

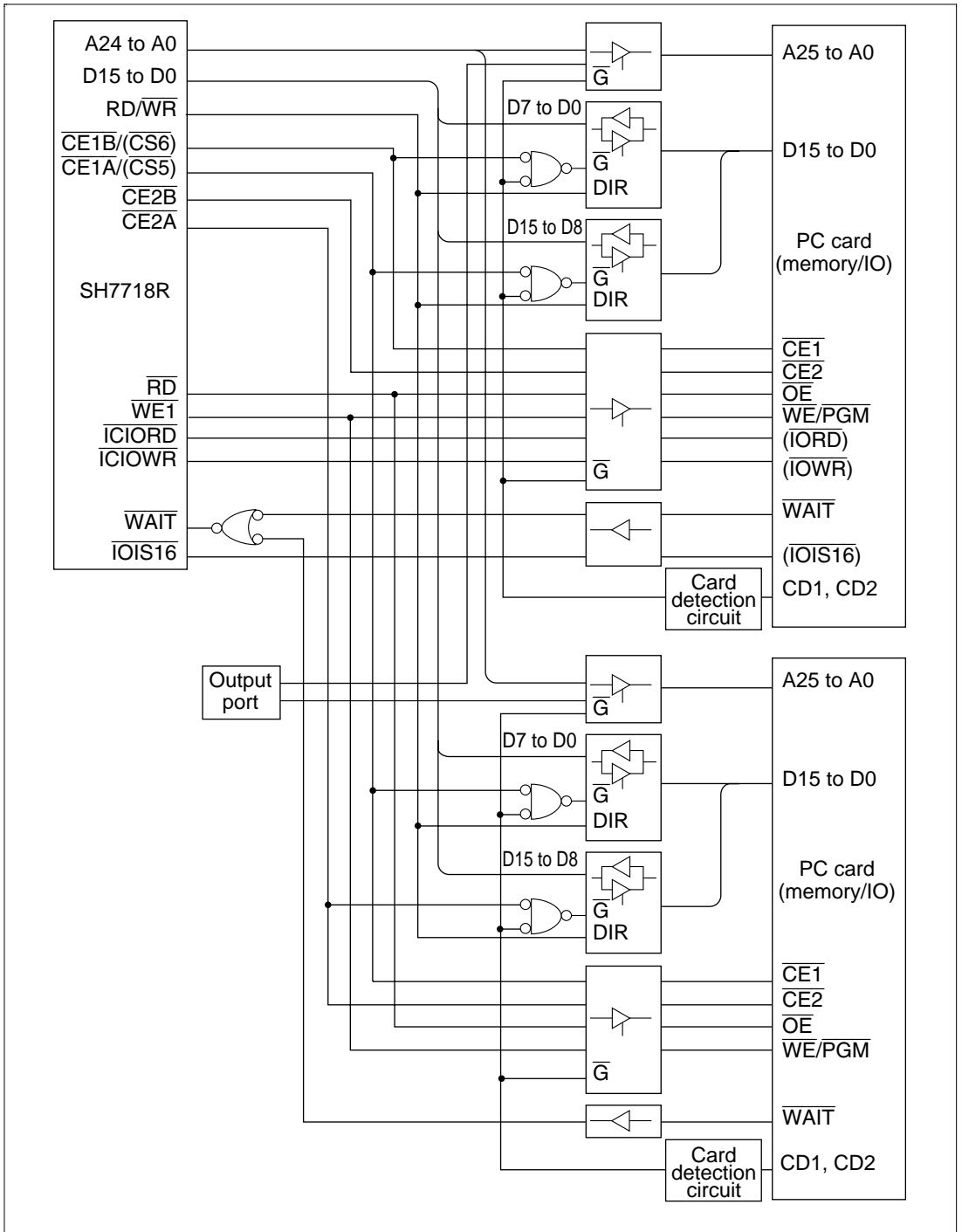


Figure 11.41 Example of PCMCIA Interface

Memory Card Interface Basic Timing: Figure 11.42 shows the basic timing for the PCMCIA IC memory card interface. When physical space areas 5 and 6 are designated as PCMCIA interface areas, bus accesses are automatically performed as IC memory card interface accesses when the lower address 32 Mbyte space of each area is accessed.

With a high external bus frequency ($CKIO$), the setup and hold times for the address ($A_{24}-A_0$), card enable ($\overline{CS5}$, $\overline{CE2A}$, $\overline{CS6}$, $\overline{CE2B}$), and write data ($D_{15}-D_0$) in a write cycle, become insufficient with respect to \overline{RD} and \overline{WR} (the $\overline{WE1}$ pin in the SH7718R). The SH7718R provides for this by enabling setup and hold times to be set for physical space areas 5 and 6 in the PCR register. Also, software waits by means of a WCR2 register setting and hardware waits by means of the \overline{WAIT} pin can be inserted in the same way as for the basic interface. Figure 11.43 shows the PCMCIA memory bus wait timing.

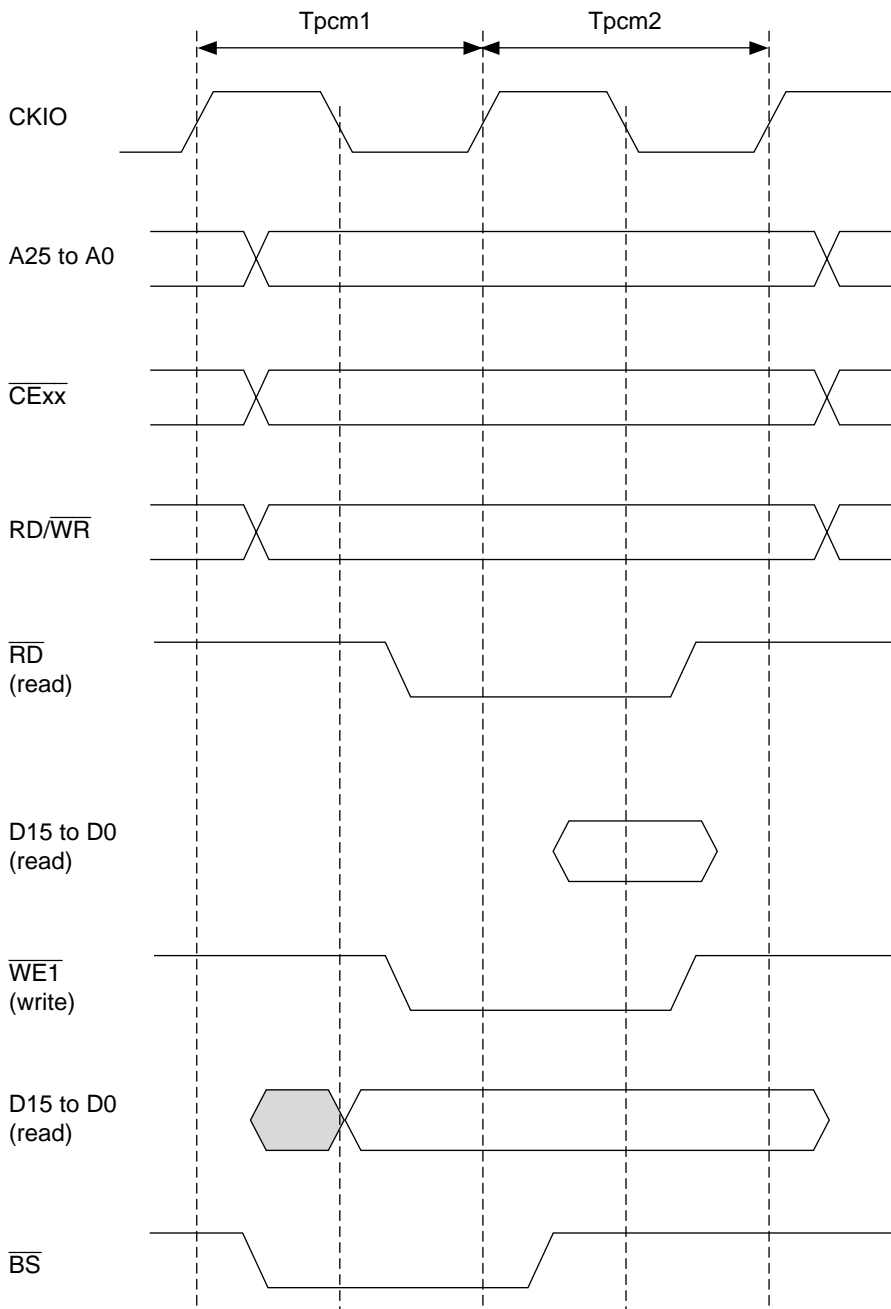


Figure 11.42 Basic Timing for PCMCIA Memory Card Interface

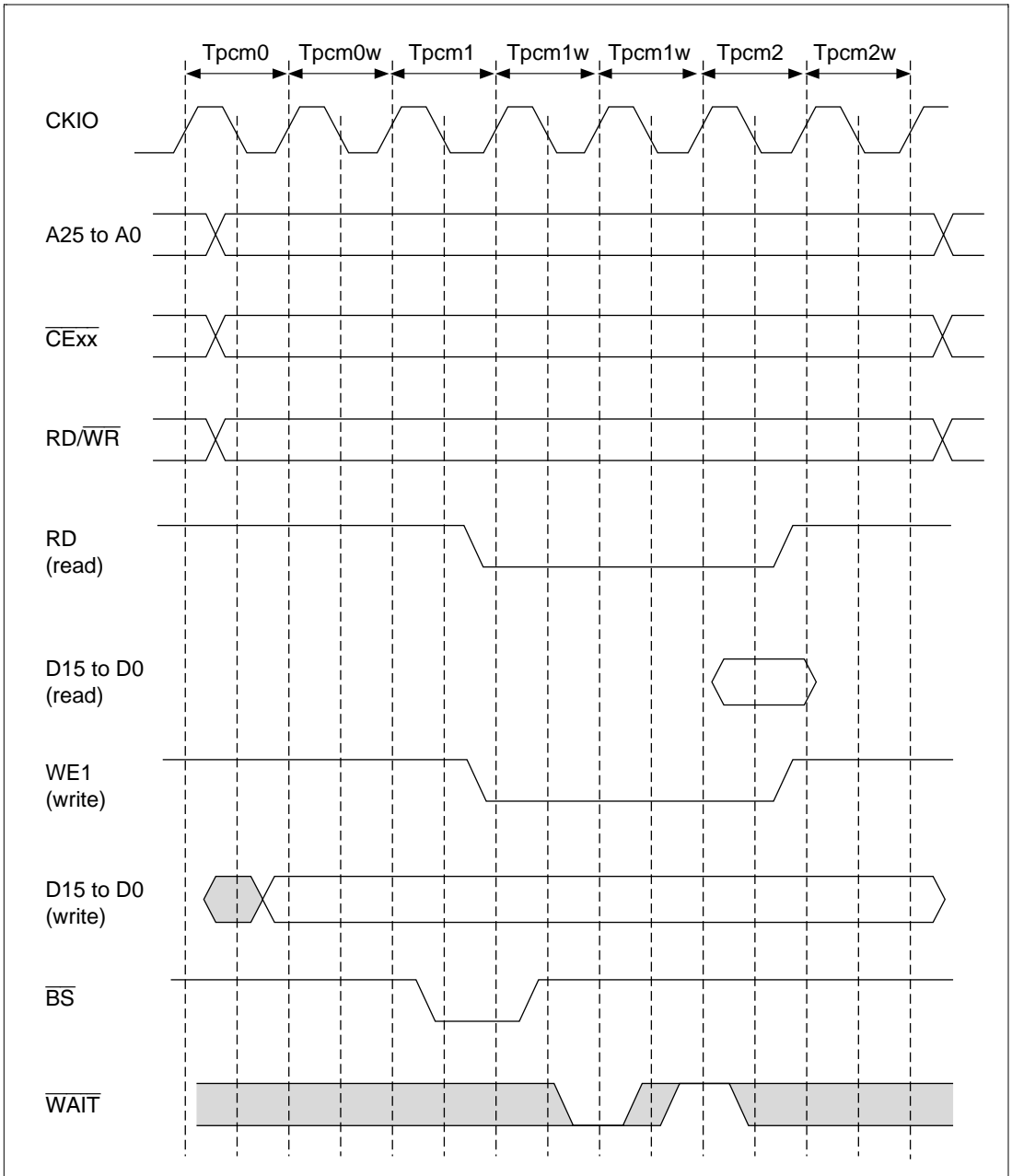


Figure 11.43 Wait Timing for PCMCIA Memory Card Interface

Memory Card Interface Burst Timing: In the SH7718R, when the IC memory card interface is selected, page mode burst access mode can be used, for read access only, by setting bits A5BST1 and A5BST0 in BCR for physical space area 5, or bits A6BST1 and A6BST0 for area 6. This burst access mode is not stipulated in JEIDA version 4.2 (PCMCIA2.1), but allows high-speed data access using ROM provided with a burst mode, etc.

Burst access mode timing is shown in figures 11.44 and 11.45.

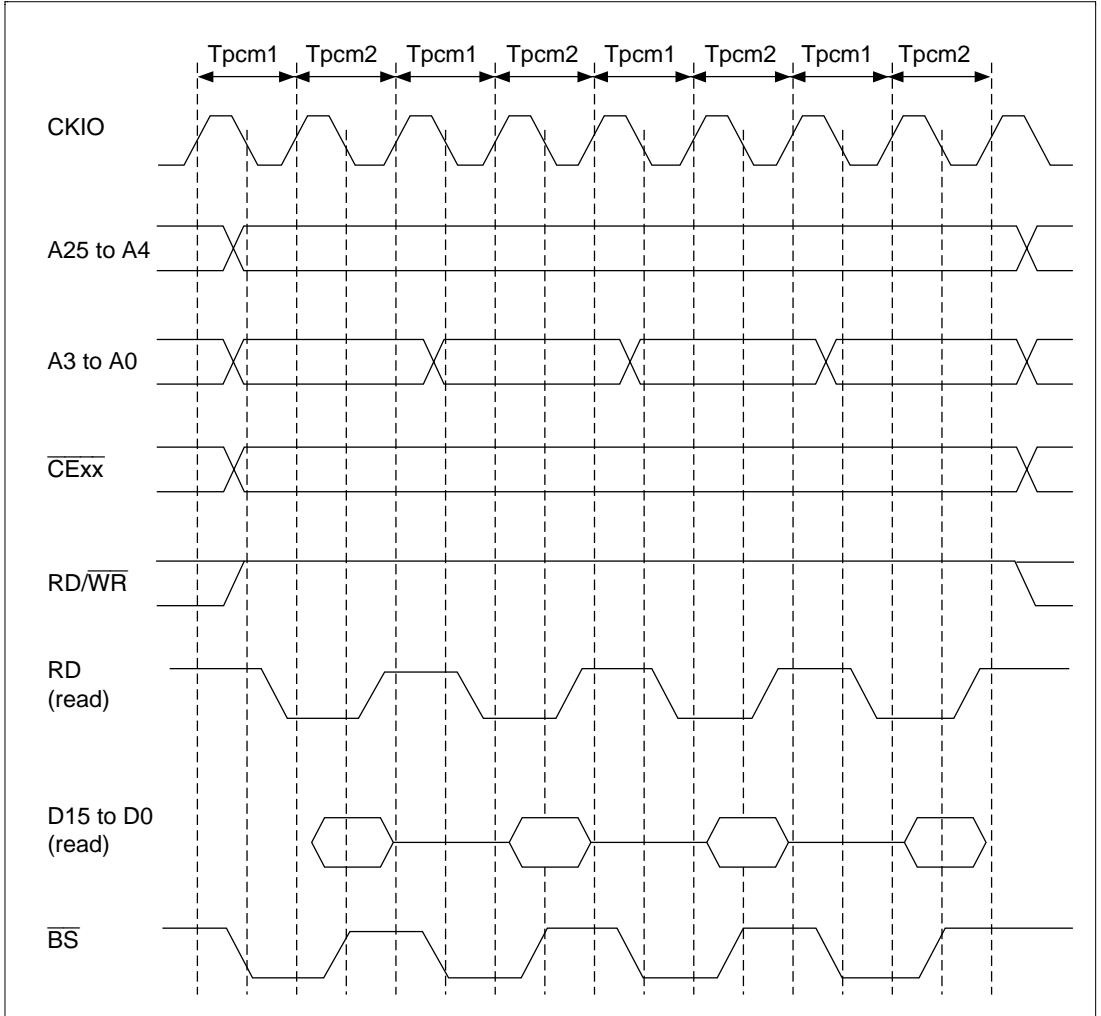


Figure 11.44 Basic Timing for PCMCIA Memory Card Interface Burst Access

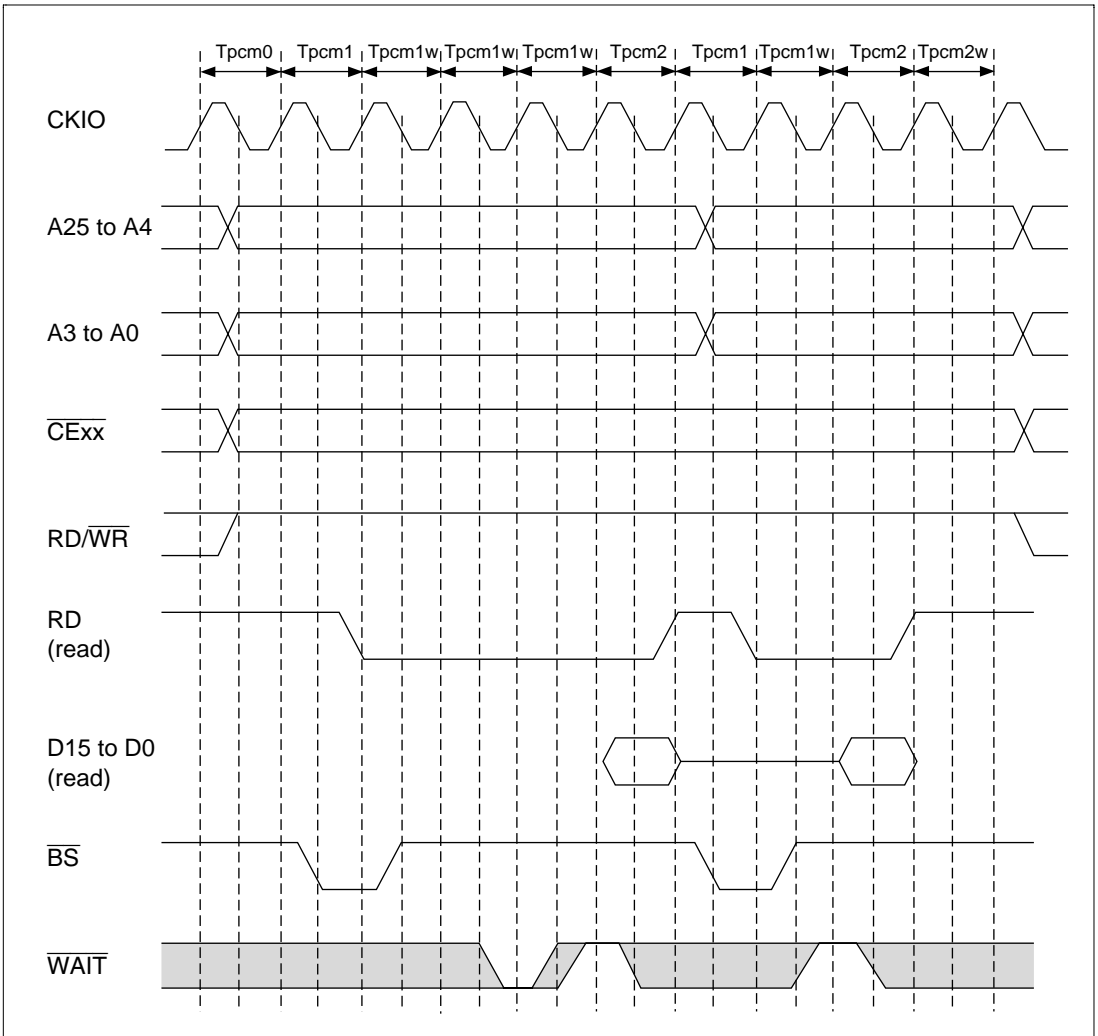


Figure 11.45 Wait Timing for PCMCIA Memory Card Interface Burst Access

When the entire 32-Mbyte memory space is used as IC memory card interface space, the common memory/attribute memory switching signal $\overline{\text{REG}}$ is generated using a port, etc. If 16-Mbytes or less of memory space is sufficient, using 16M bytes of memory space as common memory space and 16 Mbytes as attribute memory space enables the A24 pin to be used for the $\overline{\text{REG}}$ signal.

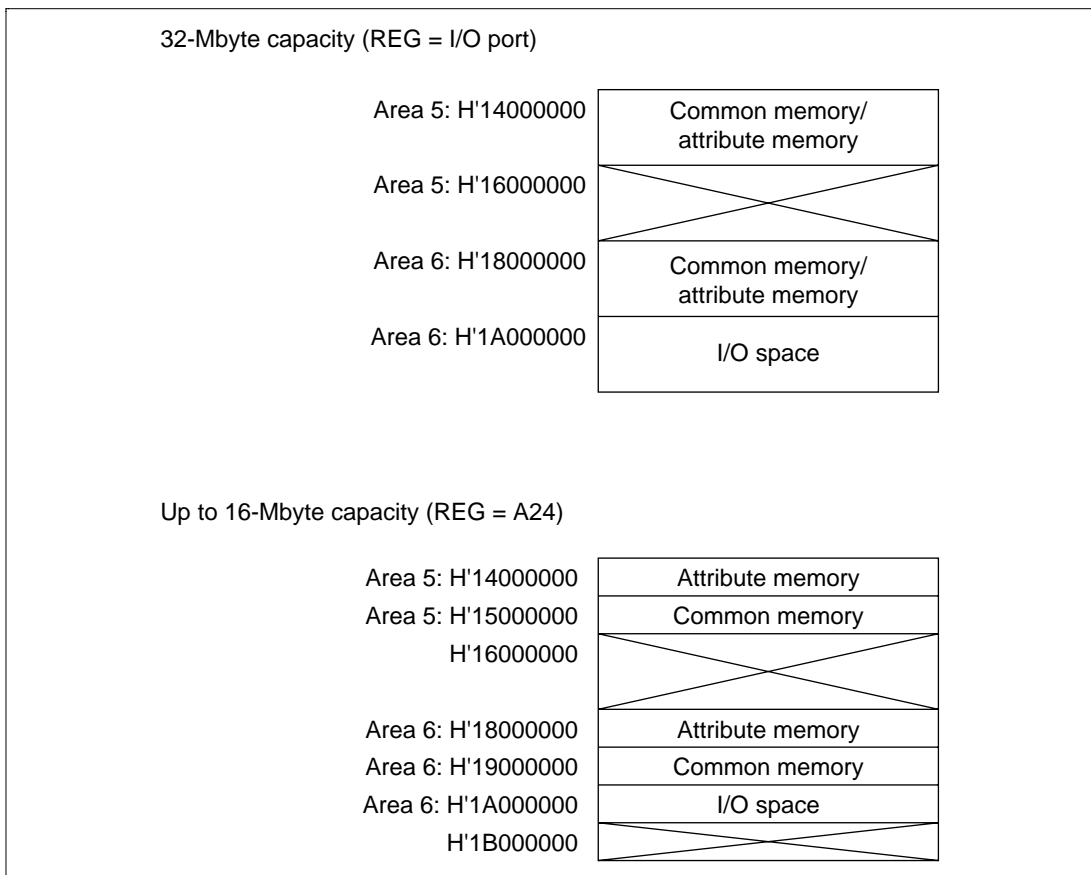


Figure 11.46 PCMCIA Space Allocation

I/O Card Interface Timing: Figures 11.47 and 11.48 show the timing for the PCMCIA I/O card interface.

The I/O card interface is supported only for physical space area 6. Switching between the I/O card interface and the IC memory card interface is performed according to the accessed address. When PCMCIA is designated for physical space area 6, the bus access is automatically performed as an I/O card interface access when a physical address from H'1A000000 to H'1BFFFFFFF is accessed.

When accessing a PCMCIA I/O card, the access should be performed using a noncacheable area in virtual space (P2 or P3 space) or an area specified as noncacheable by the MMU.

When an I/O card interface access is made to a PCMCIA card in little-endian mode, dynamic sizing of the I/O bus width is possible using the $\overline{\text{IOIS16}}$ pin. When a 16-bit bus width is set for area 6, if the $\overline{\text{IOIS16}}$ signal is high during a word-size I/O bus cycle, the I/O port is recognized as being 8 bits in width. In this case, a data access for only 8 bits is performed in the I/O bus cycle being executed, followed automatically by a data access for the remaining 8 bits.

Figure 11.49 shows the basic timing for dynamic bus sizing.

In big-endian mode, the $\overline{\text{IOIS16}}$ signal is not supported, and is ignored.

In big-endian mode, the $\overline{\text{IOIS16}}$ signal should be fixed low.

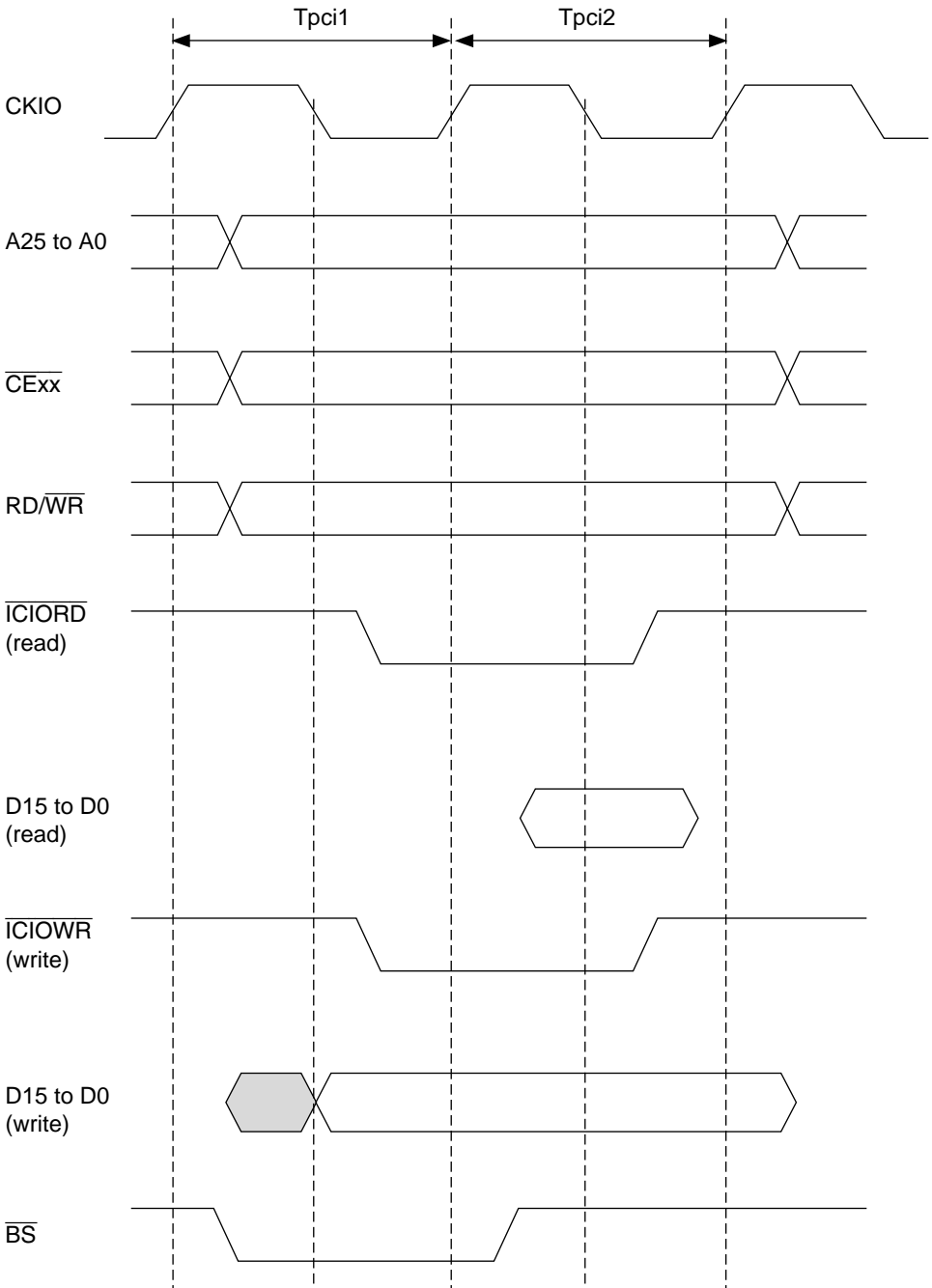


Figure 11.47 Basic Timing for PCMCIA I/O Card Interface

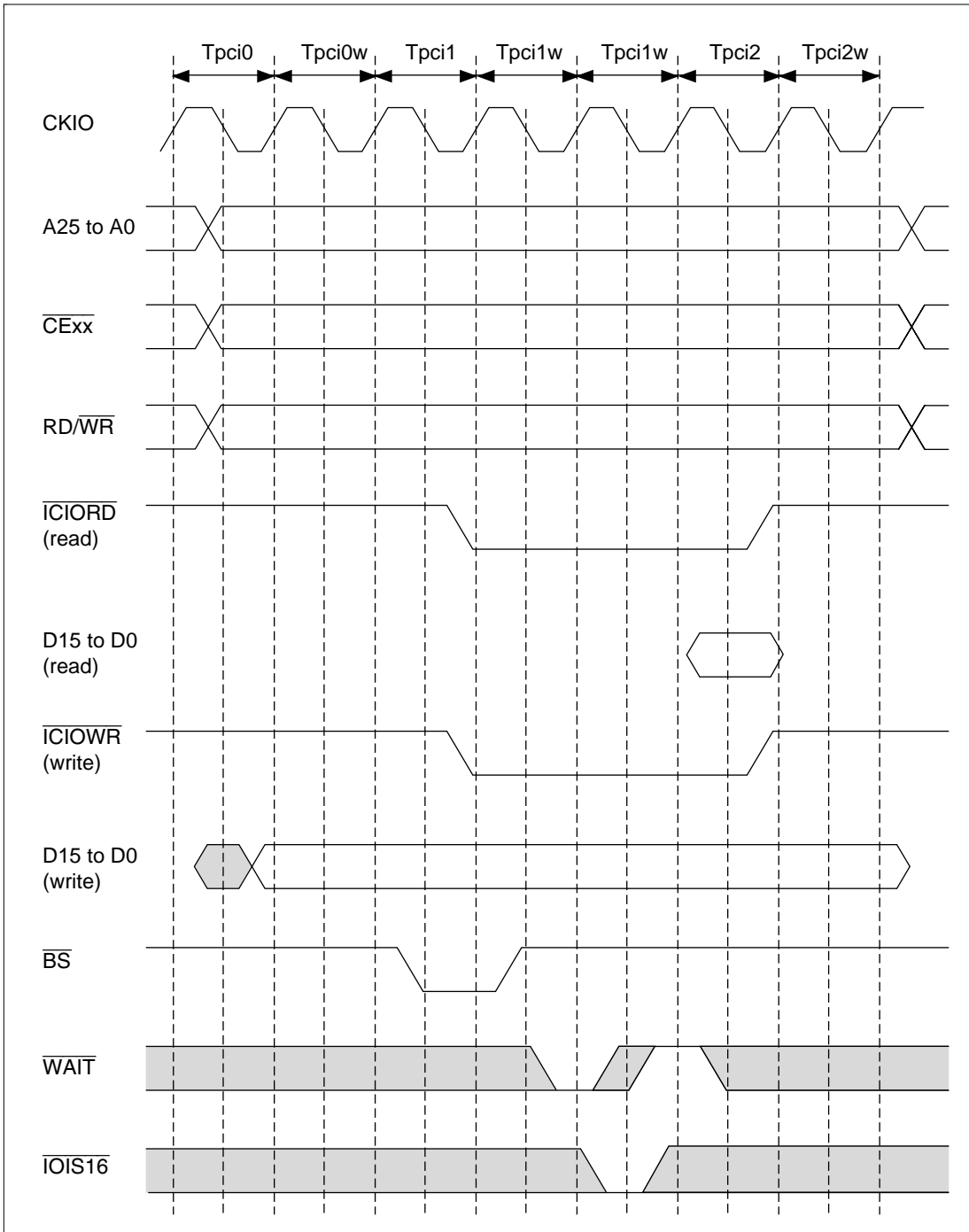


Figure 11.48 Wait Timing for PCMCIA I/O Card Interface

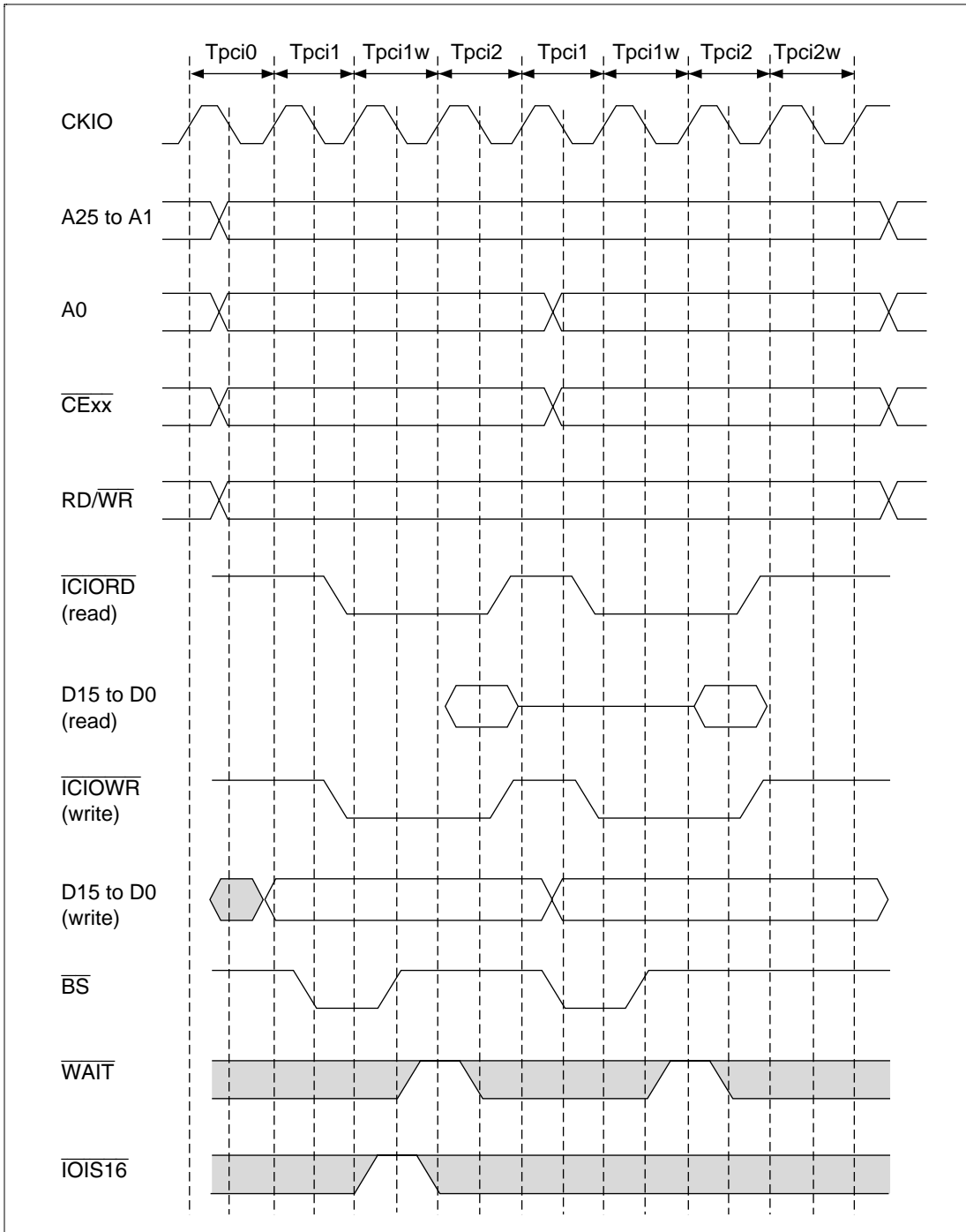


Figure 11.49 Dynamic Bus Sizing Timing for PCMCIA I/O Card Interface

11.3.9 Waits between Access Cycles

A problem associated with higher external memory bus operating frequencies is that data buffer turn-off on completion of a read from a low-speed device may be too slow, causing a collision with data in the next access. This results in lower reliability or incorrect operation. To avoid this problem, a data collision prevention feature has been provided. This memorizes the preceding access area and the kind of read/write. If there is a possibility of a bus collision when the next access is started, a wait cycle is inserted before the access cycle thus preventing a data collision. There are two cases in which a wait cycle is inserted: when an access is followed by an access to a different area, and when a read access is followed by a write access from the SH7718R. When the SH7718R performs consecutive write cycles, the data transfer direction is fixed (from the SH7718R to other memory) and there is no problem. With read accesses to the same area, in principle, data is output from the same data buffer, and wait cycle insertion is not performed. Bits AnIW1 and AnIW0 ($n = 0-6$) in WCR1 specify the number of idle cycles to be inserted between access cycles when a physical space area is followed by an access to another area, or when the SH7718R performs a write access after a read access to physical space area n . If there is originally space between accesses, the number of idle cycles inserted is the specified number of idle cycles minus the number of empty cycles.

Waits are not inserted between accesses when bus arbitration is performed, since empty cycles are inserted for arbitration purposes.

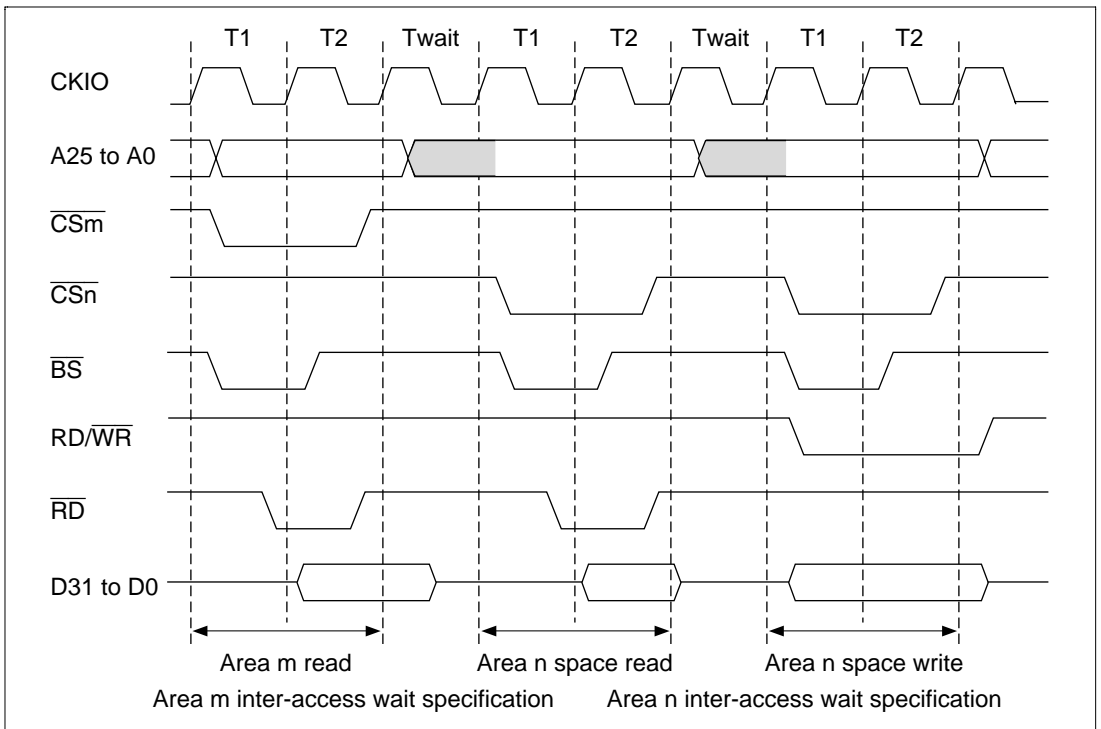


Figure 11.50 Waits between Access Cycles

11.3.10 Bus Arbitration

When a bus release request ($\overline{\text{BREQ}}$) is received from an external device, buses are released after the bus cycle being executed is completed and a bus grant signal ($\overline{\text{BACK}}$) is output. The bus is not released during burst transfers for cache fills. At the negation of $\overline{\text{BREQ}}$, $\overline{\text{BACK}}$ is negated and bus use is restarted. See Appendix B, Pin States, for the pin status when the bus is released.

The SH7718R sometimes needs to retrieve a bus it has released. For example, when memory generates a refresh request or an interrupt request internally, the SH7718R must perform the appropriate processing. The SH7718R has a bus request signal ($\overline{\text{IRQOUT}}$) for this purpose. When it must retrieve the bus, it asserts the $\overline{\text{IRQOUT}}$ signal. Devices asserting an external bus release request receive the assertion of the $\overline{\text{IRQOUT}}$ signal and negate the $\overline{\text{BREQ}}$ signal to release the bus. The SH7718R retrieves the bus and carries out the processing.

$\overline{\text{IRQOUT}}$ Pin Assertion Conditions:

- When a memory refresh request has been generated but the refresh cycle has not yet begun
- When an interrupt is generated with an interrupt request level higher than the setting of the interrupt mask bits (I3–I0) in the status register (SR). (This does not depend on the SR.BL bit.)

11.4 Usage Notes

11.4.1 When Area 6 is Designated for PCMCIA, with a 16-Bit Bus Width

In the case of consecutive word and byte accesses, or consecutive longword and byte accesses, in area 6, CE1B and CE2B are asserted simultaneously in the byte access. As a result, a byte write becomes a word-size write. In a byte read, the byte data at the specified address is read correctly.

Use one of the following methods to avoid this problem.

1. Do not use area 6 PCMCIA.
2. Use an 8-bit bus width for area 6 PCMCIA.
3. If a 16-bit bus width is used for area 6 PCMCIA, do not perform byte-size write accesses.
4. In consecutive accesses a. and b. below

- a. Word access → byte access (write)
- b. Longword access → byte access (write)

in which this problem arises, the problem can be avoided by performing a dummy read in a non-cacheable area as shown in (a') and (b') below.

- a'. Word access → dummy read → byte access (write)
- b'. Longword access → dummy read → byte access (write)

11.4.2 Self-Refreshing

If the refresh mode bit (the RMODE bit in registers MCR and DCR) is to be changed while the refresh control bit (the RFSH bit in registers MCR and DCR) is set to 1, use the procedure shown in a. and b. below.

- a. Clear the refresh control bit to 0.
- b. When refreshing is not being performed, set the refresh control bit to 1 again and then change the refresh mode.

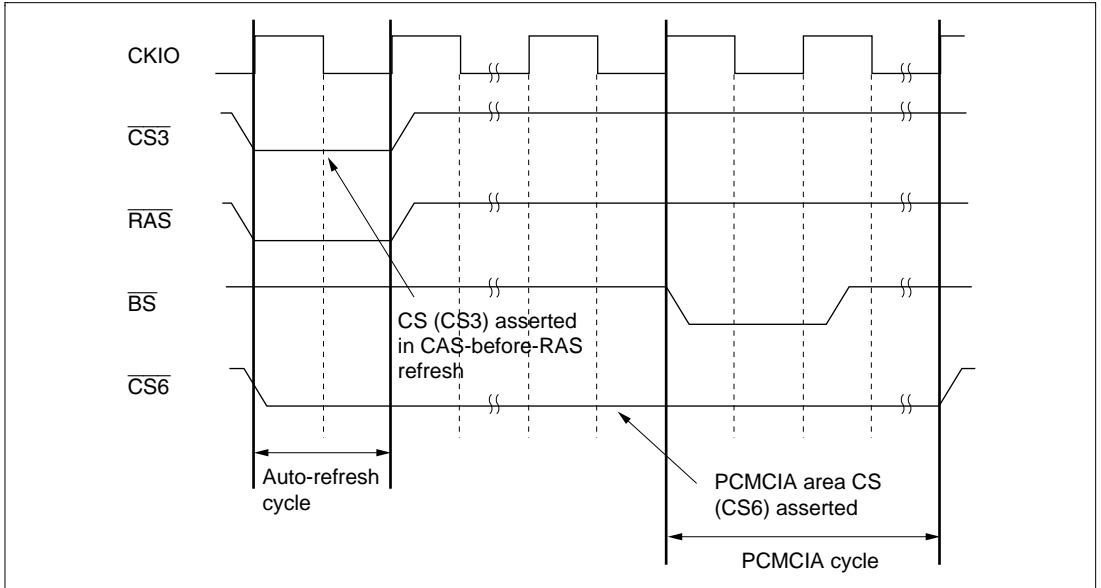
11.4.3 PCMCIA Area Access

If an SDRAM auto-refresh (CAS-before-RAS) request occurs during an area 6 PCMCIA area access, CS6 is simultaneously asserted, in addition to the CS signal for the area to be accessed, when the auto-refresh is performed.

If the following specifications are made, CS3 and CS6 will be asserted simultaneously:

Area 3: SDRAM
Area 6: PCMCIA

CS6 remains asserted until the end of the following PCMCIA bus cycle.



Restrictions: When using PCMCIA in area 6 and also using SDRAM, the area 6 CS signal (CS6) may be asserted earlier than usual, at the same time as the preceding auto-refresh cycle.

Remedy: This anomaly occurs only in area 6. There is no problem with area 5.

Therefore, if use of both SDRAM and PCMCIA in the system is being considered, area 5 should be used.

If area 6 is used, the system design should allow for CS to be asserted early without causing any problems.

Section 12 Timer (TMU)

12.1 Overview

The SH7718R uses a three-channel 32-bit timer unit (TMU).

12.1.1 Features

The TMU has the following features:

- Each channel is provided with an auto-reload 32-bit down counter
- Channel 2 is provided with an input capture function
- All channels are provided with 32-bit constant registers and 32-bit down counters that can be read or written to at any time
- All channels generate interrupt requests when the 32-bit down counter underflows (H'00000000 → H'FFFFFFF)
- Allows selection between 6 counter input clocks: External clock (TCLK), on-chip RTC output clock (16 kHz), $P\phi/4$, $P\phi/16$, $P\phi/64$, $P\phi/256$. ($P\phi$ is the internal clock for peripheral modules and can be selected as 1/4, 1/2, or the same frequency as that of the CPU operating clock ϕ .) See section 10, On-Chip Oscillation Circuits, for more information on the clock pulse generator.
- All channels can operate when the SH7718R is in standby mode: When the RTC output clock is being used as the counter input clock, the SH7718R is still able to count in standby mode.
- Synchronized read: TCNT is a sequentially changing 32-bit register. Since the peripheral module used has an internal bus width of 16 bits, a time lag can occur between the time when the upper 16 bits and lower 16 bits are read. To correct the discrepancy in the counter read value caused by this time lag, a synchronization circuit is built into the TCNT so that the entire 32-bit data in the TCNT can be read at once.
- The maximum operating frequency of the 32-bit counter is 2 MHz on all channels: Operate the SH7718R so that the clock input to the timer counters of each channel (obtained by dividing the external clock and internal clock with the prescaler) does not exceed the maximum operating frequency.

12.1.2 Block Diagram

Figure 12.1 shows a block diagram of the TMU.

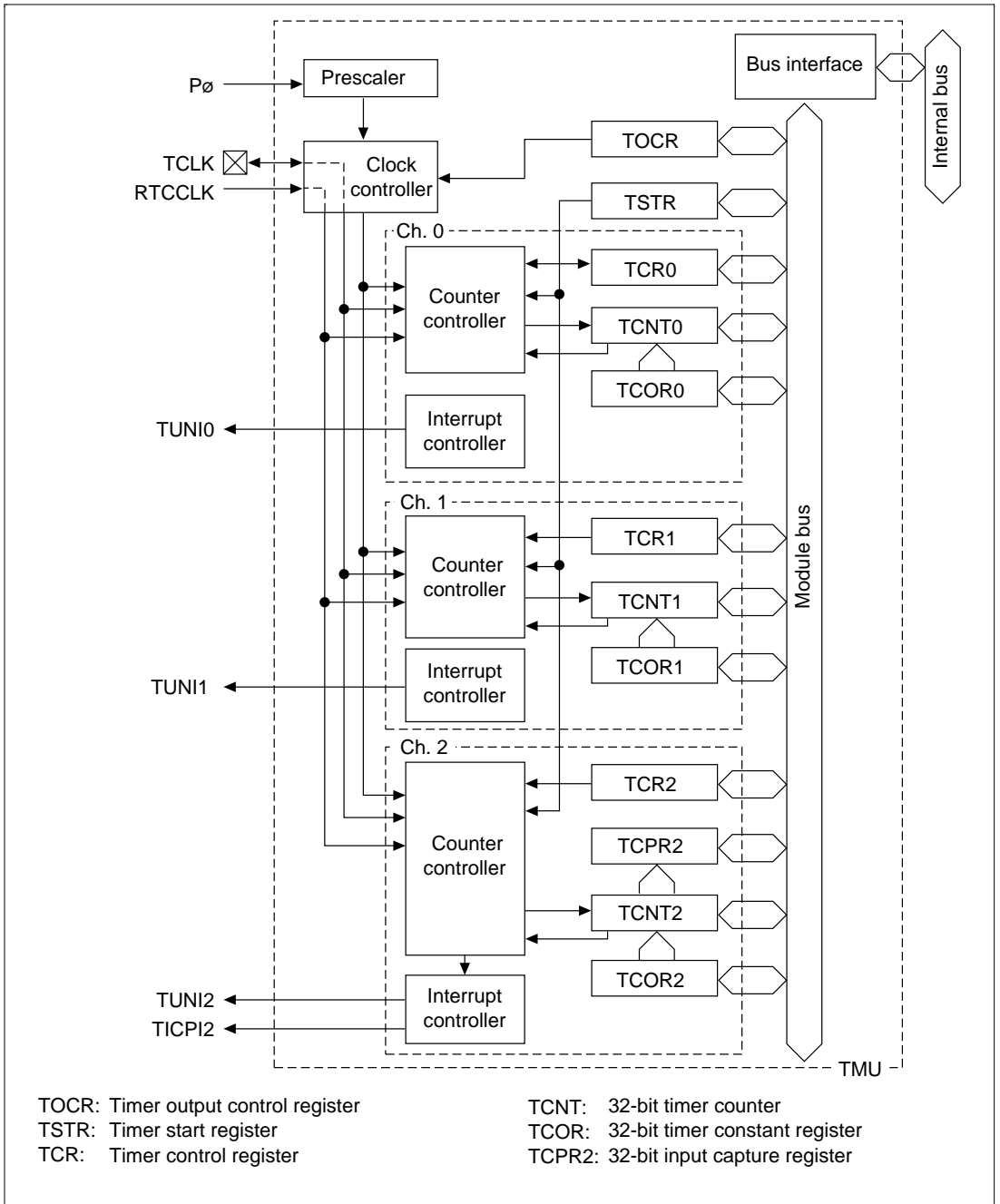


Figure 12.1 TMU Block Diagram

12.1.3 Pin Configuration

Table 12.1 shows the pin configuration of the TMU.

Table 12.1 Pin Configuration

Channel	Pin	I/O	Description
Clock input/clock output	TCLK	I/O	External clock input pin/input capture control input pin/realtime clock (RTC) output pin

12.1.4 Register Configuration

Table 12.2 shows the TMU register configuration.

Table 12.2 TMU Register Configuration

Channel	Register	Abbreviation	R/W	Initial Value	Address	Access Size
Common	Timer output control register	TOCR	R/W	H'00	H'FFFFFFE90	8
	Timer start register	TSTR	R/W	H'00	H'FFFFFFE92	8
0	Timer constant register 0	TCOR0	R/W	H'FFFFFFFF	H'FFFFFFE94	32
	Timer counter 0	TCNT0	R/W	H'FFFFFFFF	H'FFFFFFE98	32
	Timer control register 0	TCR0	R/W	H'0000	H'FFFFFFE9C	16
1	Timer constant register 1	TCOR1	R/W	H'FFFFFFFF	H'FFFFFFEA0	32
	Timer counter 1	TCNT1	R/W	H'FFFFFFFF	H'FFFFFFEA4	32
	Timer control register 1	TCR1	R/W	H'0000	H'FFFFFFEA8	16
2	Timer constant register 2	TCOR2	R/W	H'FFFFFFFF	H'FFFFFFEAC	32
	Timer counter 2	TCNT2	R/W	H'FFFFFFFF	H'FFFFFFEB0	32
	Timer control register 2	TCR2	R/W	H'0000	H'FFFFFFEB4	16
	Input capture register 2	TCPR2	R/W	Undefined	H'FFFFFFEB8	32

12.2 TMU Registers

12.2.1 Timer Output Control Register (TOCR)

TOCR is an 8-bit read/write register that selects whether to use the external TCLK pin as an external clock or an input capture control usage input pin, or an output pin for the on-chip RTC output clock. TOCR is initialized to H'00 by a power-on reset or manual reset, but is not initialized in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	—	—	—	TCOE
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R/W

Bits 7 to 1—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 0—Timer Clock Pin Control (TCOE): Selects use of the timer clock pin (TCLK) as an external clock input pin or input pin for input capture control for the on-chip timer, or as an output pin for the on-chip RTC output clock.

Bit 0: TCOE	Description
0	Timer clock pin (TCLK) used as external clock input or input capture control input pin for the on-chip timer (Initial value)
1	Timer clock pin (TCLK) used as output pin for on-chip RTC output clock

12.2.2 Timer Start Register (TSTR)

TSTR is an 8-bit read/write register that selects whether to run or halt the timer counters (TCNT) for channels 0–2. TSTR is initialized to H'00 by a power-on reset or manual reset. In standby mode, when the PLL1 multiplication factor is changed in clock mode 0, 1, 2, or 7, or when the MSTP2 bit is set to 1 in STBCR, TSTR is initialized only when the input clock selected for the channel is an external clock (TCLK) or the peripheral clock (P ϕ).

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	—	STR2	STR1	STR0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R/W	R/W	R/W

Bits 7 to 3—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 2—Counter Start 2 (STR2): Selects whether to run or halt timer counter 2 (TCNT2).

Bit 2: STR2	Description
0	Halt TCNT2 count (Initial value)
1	Start TCNT2 counting

Bit 1—Counter Start 1 (STR1): Selects whether to run or halt timer counter 1 (TCNT1).

Bit 1: STR1	Description
0	Halt TCNT1 count (Initial value)
1	Start TCNT1 counting

Bit 0—Counter Start 0 (STR0): Selects whether to run or halt timer counter 0 (TCNT0).

Bit 0: STR0	Description
0	Halt TCNT0 count (Initial value)
1	Start TCNT0 counting

12.2.3 Timer Control Register (TCR)

The timer control registers (TCR) control the timer counters (TCNT) and interrupts. The TMU has three TCR, registers one for each channel.

The TCR registers are 16-bit read/write registers that control the issuance of interrupts when the flag indicating timer counter (TCNT) underflow has been set to 1, and also carry out counter clock selection. When the external clock has been selected, they also select its edge. Additionally, TCR2 controls the channel 2 input capture function and the issuance of interrupts during input capture. The TCRs are initialized to H'0000 by a power-on reset and manual reset. In standby mode, when the PLL1 multiplication factor is changed in clock mode 0, 1, 2, or 7, or when the MSTP2 bit is set to 1 in STBCR, the TCRs retain their contents when the input clock selected for the channel is an external clock (TCLK) or the peripheral clock (P ϕ), and continue operating when the selected clock is the on-chip RTC output clock (RTCCLK).

Channel 0 and 1 TCR Bit Configuration:

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—	—	UNF
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R/W

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	UNIE	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R/W	R/W	R/W	R/W	R/W	R/W

Channel 2 TCR Bit Configuration:

Bit:	15	14	13	12	11	10	9	8
Bit name:	—	—	—	—	—	—	ICPF	UNF
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R/W	R/W

Bit:	7	6	5	4	3	2	1	0
Bit name:	ICPE1	ICPE0	UNIE	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 15 to 10, 9 (except TCR2), 7, and 6 (except TCR2)—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 9—Input Capture Interrupt Flag (ICPF): A function of channel 2 only: the flag is set when input capture is requested via the TCLK pin.

Bit 9: ICPF	Description
0	No input capture request has been issued. Clearing condition: When 0 is written to ICPF (Initial value)
1	Input capture has been requested via the TCLK pin. Setting condition: When an input capture is requested via the TCLK pin*

Note: * Contents do not change when 1 is written to ICPF.

Bit 8—Underflow Flag (UNF): Status flag that indicates occurrence of a TCNT underflow.

Bit 8: UNF	Description
0	TCNT has not underflowed. Clearing condition: When 0 is written to UNF (Initial value)
1	TCNT has underflowed (H'00000000 → H'FFFFFFF). Setting condition: When TCNT underflows*

Note: * Contents do not change when 1 is written to UNF.

Bits 7 and 6—Input Capture Control (ICPE1, ICPE0): A function of channel 2 only: determines whether the input capture function can be used, and when used, whether or not to enable interrupts.

When using this input capture function it is necessary to set the TCLK pin to input mode with the TCOE bit in the TOCR register. Additionally, use the CKEG bit to designate use of either the rising or falling edge of the TCLK pin to set the value in TNCT2 in the input capture register (TCPR2).

Bit 7: ICPE1	Bit 6: ICPE0	Description
0	0	Input capture function is not used. (Initial value)
	1	Reserved (cannot be set)
1	0	Input capture function is used. Interrupts due to ICPF are not enabled.
	1	Input capture function is used. Interrupts due to ICPF are enabled.

Bit 5—Underflow Interrupt Control (UNIE): Controls enabling of interrupt generation when the status flag (UNF) indicating TCNT underflow has been set to 1.

Bit 5: UNIE	Description
0	Interrupts due to UNF are not enabled. (Initial value)
1	Interrupts due to UNF are enabled.

Bits 4 and 3—Clock Edge 1, 0 (CKEG1, CKEG0): These bits select the external clock edge when the external clock is selected, or when the input capture function is used.

Bit 4: CKEG1	Bit 3: CKEG0	Description
0	0	Count/capture register set on rising edge (Initial value)
	1	Count/capture register set on falling edge
1	—	Count/capture register set on both rising and falling edge

Bits 2 to 0—Timer Prescalers 2–0 (TPSC2–TPSC0): These bits select the TCNT count clock.

Bit 2: TPSC2	Bit 1: TPSC1	Bit 0: TPSC0	Description
0	0	0	Internal clock: count on $P\phi/4$ (Initial value)
		1	Internal clock: count on $P\phi/16$
	1	0	Internal clock: count on $P\phi/64$
		1	Internal clock: count on $P\phi/256$
1	0	0	Internal clock: count on clock output of on-chip RTC (RTCCLK)
		1	External clock: count on TCLK pin input
	1	0	Reserved
		1	Reserved

12.2.4 Timer Constant Register (TCOR)

The timer constant registers are 32-bit registers. The TMU has three TCOR registers, one for each of the three channels.

TCOR is a 32-bit read/write register. When a TCNT count-down results in an underflow, the TCOR value is set in TCNT and the count-down continues from that value. TCOR is initialized to H'FFFFFFFF by a power-on reset or manual reset; it is not initialized in standby mode, and retains its contents.

TCOR:

Bit:	31	30	29	28	27	26	25	24
Bit name:								
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	23	22	21	20	19	18	17	16
Bit name:								
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	15	14	13	12	11	10	9	8
Bit name:								
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

12.2.5 Timer Counters (TCNT)

The timer counters are 32-bit read/write registers. The TMU has three timer counters, one for each channel.

TCNT counts down upon input of a clock. The clock input is selected using the TPSC2–TPSC0 bits in the timer control register (TCR).

When a TCNT count-down results in an underflow (H'00000000 → H'FFFFFFF), the underflow flag (UNF) in the timer control register (TCR) of the relevant channel is set. The TCOR value is simultaneously set in TCNT itself and the count-down continues from that value.

Because the internal bus for the SH7718R on-chip supporting modules is 16 bits wide, a time lag can occur between the time when the upper 16 bits and lower 16 bits are read. Since TCNT counts sequentially, this time lag can create discrepancies between the data in the upper and lower halves. To correct the discrepancy, a buffer register is connected to TCNT so that upper and lower halves are not read separately. The entire 32-bit data in TCNT can thus be read at once.

TCNT is initialized to H'FFFFFFF by a power-on reset or manual reset. In standby mode, when the PLL1 multiplication factor is changed in clock mode 0, 1, 2, or 7, or when the MSTP2 bit is set to 1 in STBCR, TCNT retains its contents when the input clock selected for the channel is an external clock (TCLK) or the peripheral clock (P ϕ), and continues operating when the selected clock is the on-chip RTC output clock (RTCCLK).

TCNT:

Bit:	31	30	29	28	27	26	25	24
Bit name:								

Initial value: 1 1 1 1 1 1 1 1

R/W: R/W R/W R/W R/W R/W R/W R/W R/W

Bit:	23	22	21	20	19	18	17	16
Bit name:								

Initial value: 1 1 1 1 1 1 1 1

R/W: R/W R/W R/W R/W R/W R/W R/W R/W

Bit:	15	14	13	12	11	10	9	8
Bit name:								

Initial value: 1 1 1 1 1 1 1 1

R/W: R/W R/W R/W R/W R/W R/W R/W R/W

Bit:	7	6	5	4	3	2	1	0
Bit name:								

Initial value: 1 1 1 1 1 1 1 1

R/W: R/W R/W R/W R/W R/W R/W R/W R/W

12.2.6 Input Capture Register (TCPR2)

The input capture register (TCPR2) is a read-only 32-bit register built only into timer 2. Control of TCPR2 setting conditions due to the TCLK pin is affected by the input capture function bits (ICPE1/ICPE2 and CKEG1/CKEG0) in TCR2. When a TCPR2 setting indication due to the TCLK pin occurs, the value of TCNT2 is copied into TCPR2.

TCNT2 is not initialized by a power-on reset or manual reset, or in standby mode.

TCPR2:

Bit:	31	30	29	28	27	26	25	24
Bit name:								
Initial value:	—	—	—	—	—	—	—	—
R/W:	R	R	R	R	R	R	R	R
Bit:	23	22	21	20	19	18	17	16
Bit name:								
Initial value:	—	—	—	—	—	—	—	—
R/W:	R	R	R	R	R	R	R	R
Bit:	15	14	13	12	11	10	9	8
Bit name:								
Initial value:	—	—	—	—	—	—	—	—
R/W:	R	R	R	R	R	R	R	R
Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	—	—	—	—	—	—	—	—
R/W:	R	R	R	R	R	R	R	R

12.3 TMU Operation

12.3.1 Overview

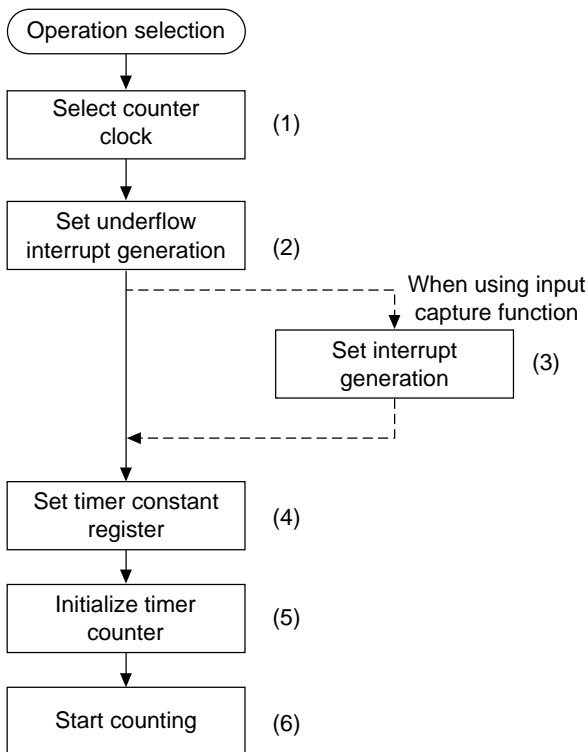
Each of the three channels has a 32-bit timer counter (TCNT) and a 32-bit timer constant register. The TCNT counts down. The auto-reload function enables synchronized counting and counting by external events. Channel 2 has an input capture function.

12.3.2 Basic Functions

Counter Operation: When the STR0–STR2 bits in the timer start register (TSTR) are set, the corresponding timer counter (TCNT) starts counting. When a TCNT underflows (H'00000000 → H'FFFFFFF), the UNF flag of the corresponding timer control register (TCR) is set. At this time, if the UNIE bit in TCR is 1, an interrupt request is sent to the CPU. Also at this time, the value is copied from TCOR to TCNT and the down-count operation is continued.

The count operation is set as follows (figure 12.2):

1. Select the counter clock with the TPSC2–TPSC0 bits in the timer control register (TCR). If the external clock is selected, set the TCLK pin to input mode with the TOCE bit in TOCR, and select its edge with the CKEG1 and CKEG0 bits in TCR.
2. Use the UNIE bit in TCR to set whether to generate an interrupt when TCNT underflows.
3. When using the input capture function, set the ICPE bits in TCR, including the choice of whether or not to use the interrupt function (channel 2 only).
4. Set a value in the timer constant register (TCOR) (the cycle is the set value plus 1).
5. Set the initial value in the timer counter (TCNT).
6. Set the STR bit in the timer start register (TSTR) to 1 to start operation.



Note: When an interrupt has been generated, clear the flag in the interrupt handler that caused it. If interrupts are enabled without clearing the flag, another interrupt will be generated.

Figure 12.2 Setting the Count Operation

Auto-Reload Count Operation: Figure 12.3 shows the TCNT auto-reload operation.

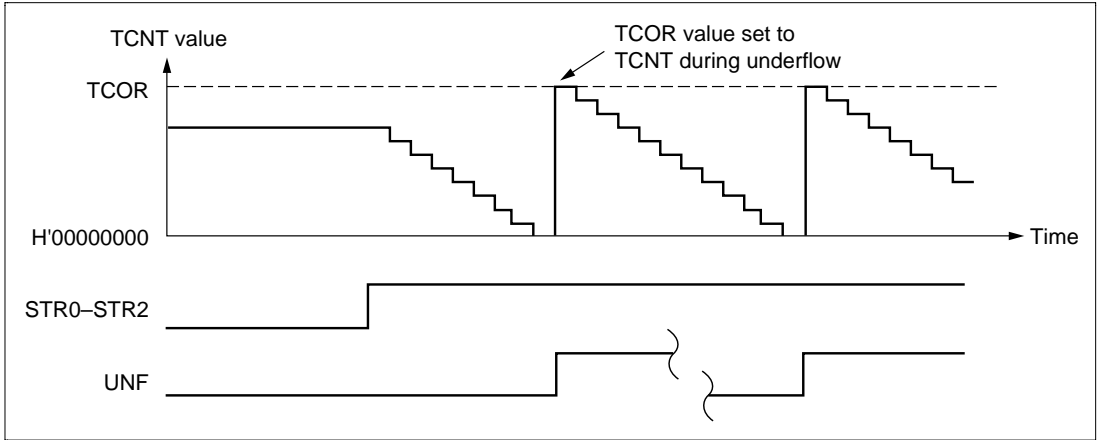


Figure 12.3 Auto-Reload Count Operation

TCNT Count Timing:

- Internal Clock Operation: Set the TPSC2-TPSC0 bits in TCR to select whether peripheral module clock $P\phi$ or one of the four internal clocks created by dividing it is used ($P\phi/4$, $P\phi/16$, $P\phi/64$, $P\phi/256$). Figure 12.4 shows the timing.

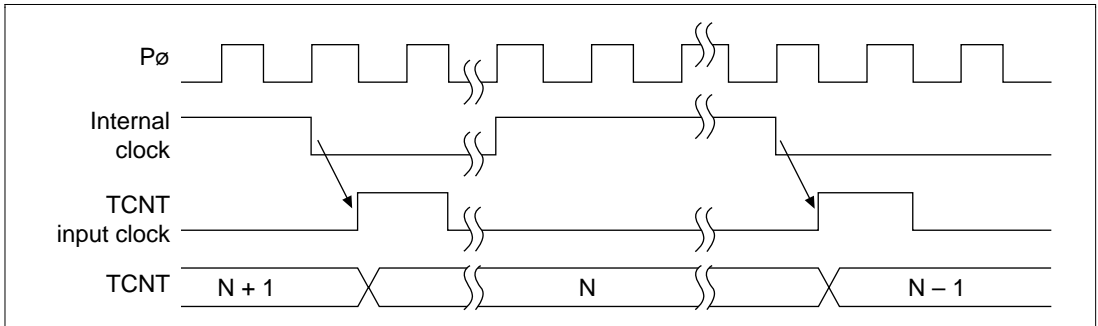


Figure 12.4 Count Timing when Internal Clock Is Operating

- External Clock Operation: Set the TPSC2-TPSC0 bits in TCR to select the external clock (TCLK) as the timer clock. Use the CKEG1 and CKEG0 bits in TCR to select the detection edge. Rise, fall or both may be selected. The pulse width of the external clock must be at least 1.5 peripheral module clock cycles for single edges or 2.5 peripheral module clock cycles for both edges. A shorter pulse width will result in accurate operation. Figure 12.5 shows the timing for both-edge detection.

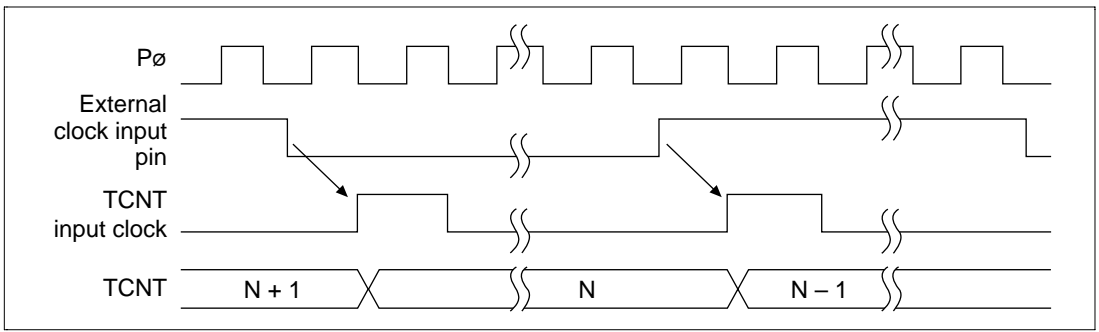


Figure 12.5 Count Timing when External Clock Is Operating (Both Edges Detected)

- On-Chip RTC Clock Operation: Set the TPSC2–TPSC0 bits in TCR to select the on-chip RTC clock as the timer clock. Figure 12.6 shows the timing.

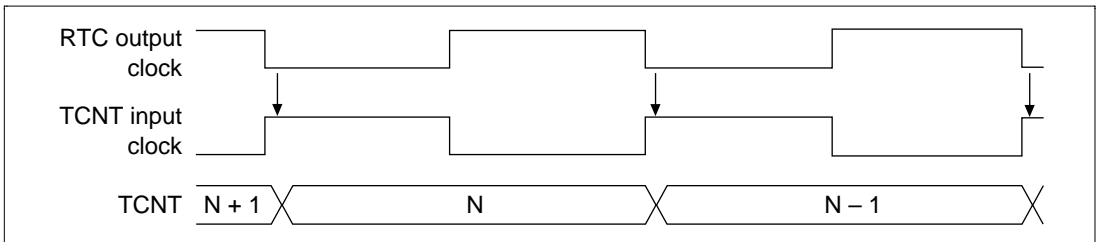


Figure 12.6 Count Timing when On-Chip RTC Clock Is Operating

Input Capture Function: Channel 2 has an input capture function (figure 12.7). When using the input capture function, set the TCLK pin to input mode with the TCOE bit in the timer output control register (TOCR) and set the timer operation clock to internal clock or on-chip RTC clock with the TPSC2–TPSC0 bits in the timer control register (TCR). Also, designate use of the input capture function and whether to generate interrupts on using it with the IPCE1–IPCE0 bits in TCR, and designate the use of either the rising or falling edge of the TCLK pin to set the timer counter (TNCT) value into the input capture register (TCPR) with the CKEG1–CKEG0 bits in TCR.

The input capture function cannot be used in standby mode.

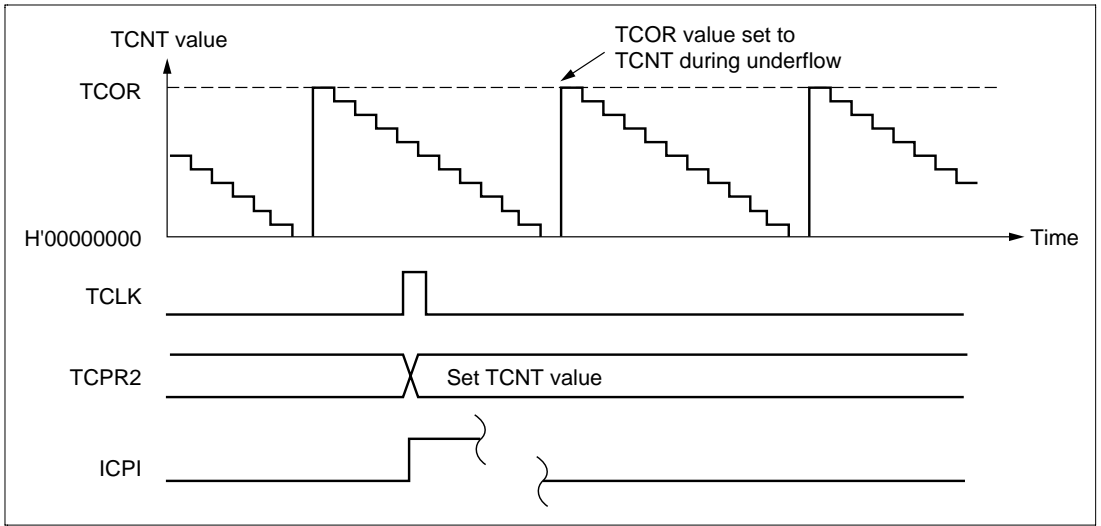


Figure 12.7 Operation Timing when Using the Input Capture Function (Using TCLK Rising Edge)

12.4 Interrupts

There are two sources of TMU interrupts: underflow interrupts and interrupts when using the input capture function.

12.4.1 Status Flag Set Timing

UNF is set to 1 when the TCNT underflows. Figure 12.8 shows the timing.

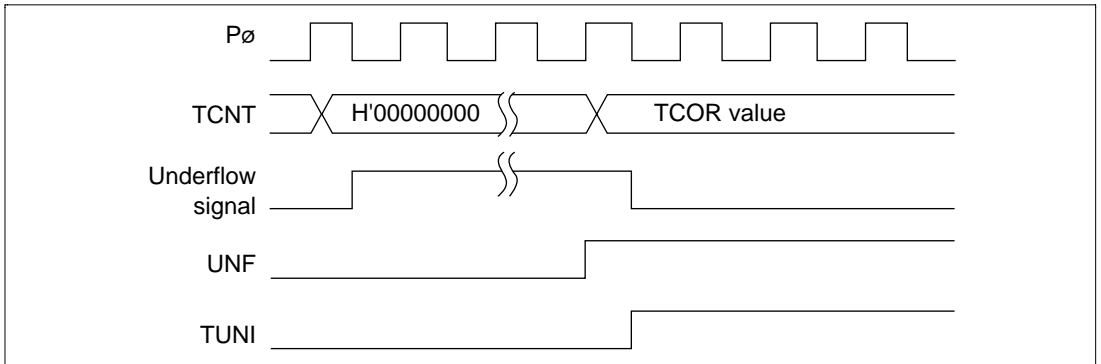


Figure 12.8 UNF Set Timing

12.4.2 Status Flag Clear Timing

The status flag can be cleared by writing a 0 from the CPU. Figure 12.9 shows the timing.

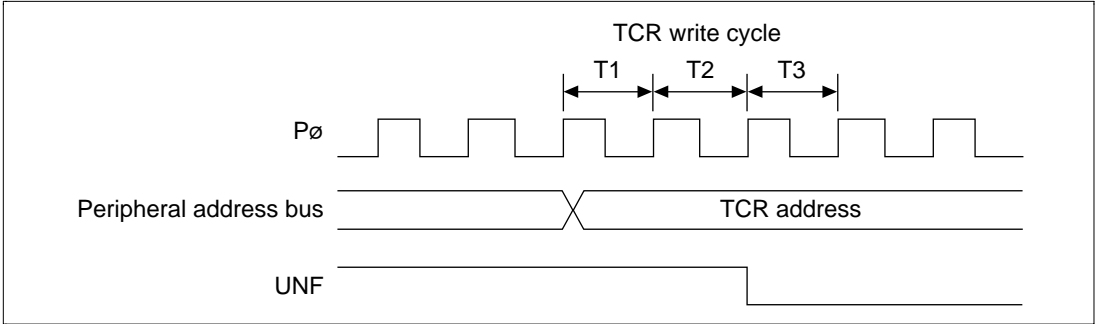


Figure 12.9 Status Flag Clear Timing

12.4.3 Interrupt Sources and Priorities

The TMU produces underflow interrupts for each channel. When the interrupt request flag and interrupt enable bit are both set to 1, the interrupt is requested. Codes are set in the exception source register (INTEVT) for these interrupts and interrupt handling occurs according to the codes.

The relative priorities of channels can be changed using the interrupt controller (see section 6, Interrupt Controller). Table 12.3 lists TMU interrupt sources.

Table 12.3 TMU Interrupt Sources

Channel	Interrupt Source	Description	Priority
0	TUNI0	Underflow interrupt 0	High
1	TUNI1	Underflow interrupt 1	↑
2	TUNI2	Underflow interrupt 2	
	TICPI2	Input capture interrupt 2	Low

12.5 Usage Notes

12.5.1 Writing to Registers

Synchronization processing is not performed for timer counting during register writes. When writing to registers, always clear the appropriate start bits for the channel (STR2–STR0) in the timer start register (TSTR) to halt timer counting.

12.5.2 Reading Registers

Synchronization processing is performed for timer counting during register reads. When timer counting and register read processing are performed simultaneously, the register value before TCNT counting down (with synchronization processing) is read.

Section 13 Realtime Clock (RTC)

13.1 Overview

The SH7718R has a realtime clock (RTC) with its own 32.768-kHz crystal oscillator.

13.1.1 Features

- Clock and calendar functions (BCD display): seconds, minutes, hours, date, day of the week, month, and year
- 1-Hz to 64-Hz timer (binary display)
- Start/stop function
- 30-second adjust function
- Alarm interrupt: frame comparison of seconds, minutes, hours, date, day of the week, and month can be used as conditions for the alarm interrupt
- Cyclic interrupts: the interrupt cycle may be 1/256 second, 1/64 second, 1/16 second, 1/4 second, 1/2 second, 1 second, or 2 seconds
- Carry interrupt: a carry interrupt indicates when a carry occurs during a counter read
- Automatic leap year correction

13.1.2 Block Diagram

The following abbreviations are used in the block diagram of the RTC (figure 13.1):

R64CNT: 64-Hz counter	RSECAR: Second alarm register
RSECCNT: Second counter	RMINAR: Minute alarm register
RMINCNT: Minute counter	RHRAR: Hour alarm register
RHRCNT: Hour counter	RWKAR: Day of the week alarm register
RWKCNT: Day of the week counter	RDAYAR: Date alarm register
RDAYCNT: Date counter	RMONAR: Month alarm register
RMONCNT: Month counter	RCR1: RTC control register 1
RYRCNT: Year counter	RCR2: RTC control register 2

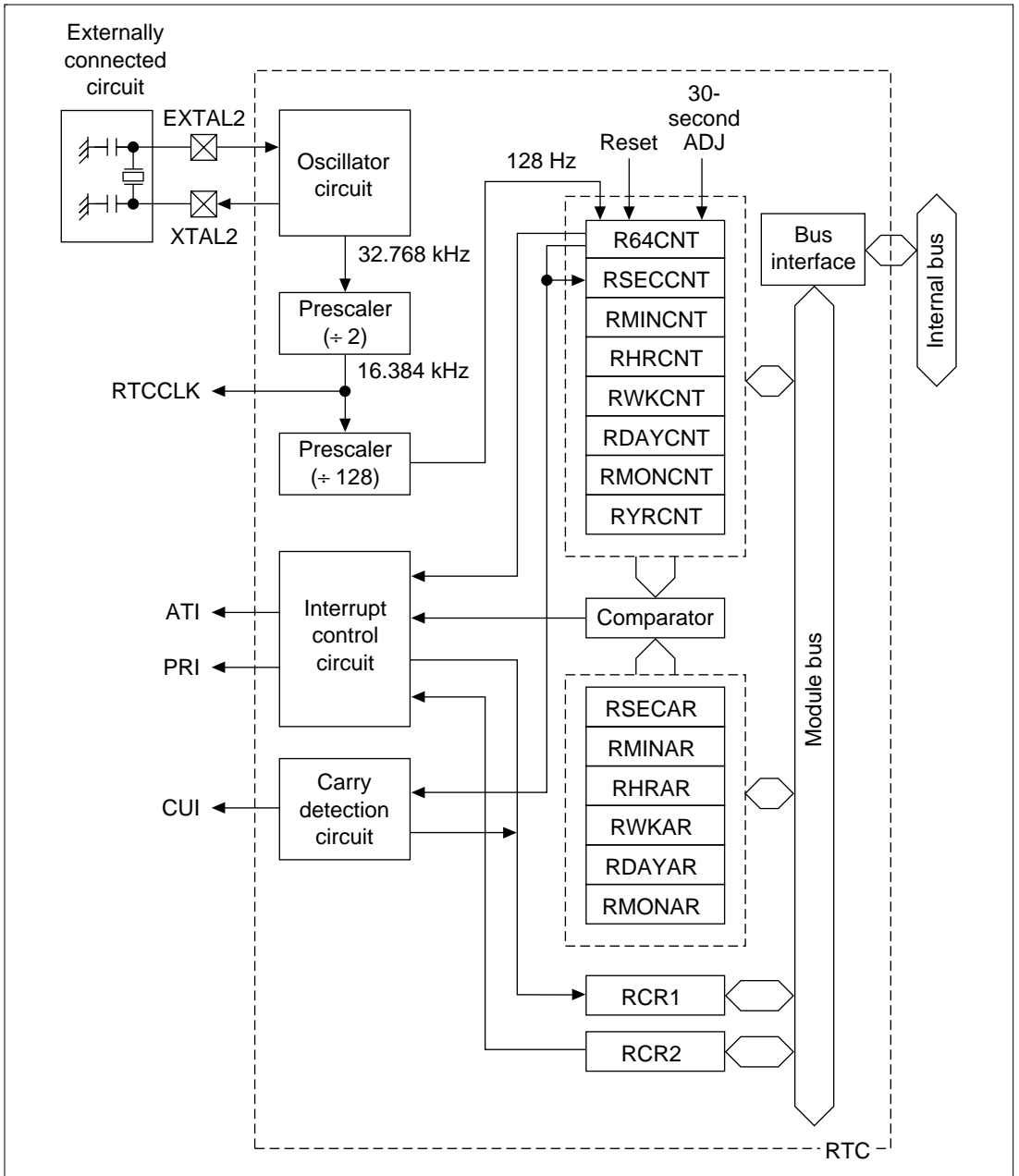


Figure 13.1 RTC Block Diagram

13.1.3 Pin Configuration

Table 13.1 shows the RTC pin configuration.

Table 13.1 RTC Pin Configuration

Pin	Abbreviation	I/O	Description
RTC oscillator crystal pin	EXTAL2	I	Connects crystal to RTC oscillator
RTC oscillator crystal pin	XTAL2	O	Connects crystal to RTC oscillator
Clock input/clock output	TCLK	I/O	External clock input pin/input capture control input pin/realtime clock (RTC) output pin (shared by TMU)
Dedicated power-supply pin for RTC	$V_{CC}(\text{RTC})$	—	Dedicated power-supply pin for RTC*
Dedicated GND pin for RTC	$V_{SS}(\text{RTC})$	—	Dedicated GND pin for RTC*

Note: Except in hardware standby mode, connect all V_{CC} and V_{SS} pins to the system power supply (power should be supplied constantly). In hardware standby mode, power should be supplied at least to $V_{CC}(\text{RTC})$ and $V_{SS}(\text{RTC})$. If power is not supplied to V_{CC} and V_{SS} pins other than $V_{CC}(\text{RTC})$ and $V_{SS}(\text{RTC})$, hold the CA pin low.

13.1.4 RTC Register Configuration

Table 13.2 shows the RTC register configuration.

Table 13.2 RTC Registers

Name	Abbreviation	R/W	Initial Value	Address	Access Size
64-Hz counter	R64CNT	R	Undefined	H'FFFFFFE0	8
Second counter	RSECCNT	R/W	Undefined	H'FFFFFFE2	8
Minute counter	RMINCNT	R/W	Undefined	H'FFFFFFE4	8
Hour counter	RHRCNT	R/W	Undefined	H'FFFFFFE6	8
Day of week counter	RWKCNT	R/W	Undefined	H'FFFFFFE8	8
Date counter	RDAYCNT	R/W	Undefined	H'FFFFFFEA	8
Month counter	RMONCNT	R/W	Undefined	H'FFFFFFEC	8
Year counter	RYRCNT	R/W	Undefined	H'FFFFFFEE	8
Second alarm register	RSECAR	R/W	Undefined*	H'FFFFFFED0	8
Minute alarm register	RMINAR	R/W	Undefined*	H'FFFFFFED2	8
Hour alarm register	RHRAR	R/W	Undefined*	H'FFFFFFED4	8
Day of week alarm register	RWKAR	R/W	Undefined*	H'FFFFFFED6	8
Date alarm register	RDAYAR	R/W	Undefined*	H'FFFFFFED8	8
Month alarm register	RMONAR	R/W	Undefined*	H'FFFFFFEDA	8
RTC control register 1	RCR1	R/W	H'00	H'FFFFFFEDC	8
RTC control register 2	RCR2	R/W	H'09	H'FFFFFFEDE	8

Note: * Only the ENB bits of each register are initialized.

13.2 RTC Registers

13.2.1 64-Hz Counter (R64CNT)

The 64-Hz counter (R64CNT) is an 8-bit read-only register that indicates the status of the RTC divider circuit between 64 Hz and 1 Hz.

R64CNT is reset to H'00 by setting the RESET bit in RTC control register 2 (RCR2) or the ADJ bit in RCR2 to 1.

R64CNT is not initialized by a power-on reset or manual reset, or in standby mode.

Bit 7 always reads 0.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	1Hz	2Hz	4Hz	8Hz	16Hz	32Hz	64Hz
Initial value:	0	—	—	—	—	—	—	—
R/W:	R	R	R	R	R	R	R	R

13.2.2 Second Counter (RSECCNT)

The second counter (RSECCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded second section of the RTC. The count operation is performed by a carry for each second of the 64 Hz counter.

The range that can be set is 00–59 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RSECCNT is not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	10 seconds			1 second			
Initial value:	0	—	—	—	—	—	—	—
R/W:	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W

13.2.3 Minute Counter (RMINCNT)

The minute counter (RMINCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded minute section of the RTC. The count operation is performed by a carry for each minute of the second counter.

The range that can be set is 00–59 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RMINCNT is not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	10 minutes			1 minute			
Initial value:	0	—	—	—	—	—	—	—
R/W:	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W

13.2.4 Hour Counter (RHRCNT)

The hour counter (RHRCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded hour section of the RTC. The count operation is performed by a carry for each 1 hour of the minute counter.

The range that can be set is 00–23 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RHRCNT is not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	10 hours		1 hour			
Initial value:	0	0	—	—	—	—	—	—
R/W:	R	R	R/W	R/W	R/W	R/W	R/W	R/W

13.2.5 Day of the Week Counter (RWKCNT)

The day of the week counter (RWKCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded day of week section of the RTC. The count operation is performed by a carry for each day of the date counter.

The range that can be set is 0–6 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RWKCNT is not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	—	Day of week		
Initial value:	0	0	0	0	0	—	—	—
R/W:	R	R	R	R	R	R/W	R/W	R/W

Days of the week are coded as shown in table 13.3.

Table 13.3 Day-of-Week Codes (RWKCNT)

Day of Week	Code
Sunday	0
Monday	1
Tuesday	2
Wednesday	3
Thursday	4
Friday	5
Saturday	6

13.2.6 Date Counter (RDAYCNT)

The date counter (RDAYCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded date section of the RTC. The count operation is performed by a carry for each day of the hour counter.

The range that can be set is 01–31 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RDAYCNT is not initialized by a power-on reset or manual reset, or in standby mode.

The RDAYCNT range that can be set changes with each month and in leap years. Please confirm the correct setting.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	10 days		1 day			
Initial value:	0	0	—	—	—	—	—	—
R/W:	R	R	R/W	R/W	R/W	R/W	R/W	R/W

13.2.7 Month Counter (RMONCNT)

The month counter (RMONCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded month section of the RTC. The count operation is performed by a carry for each month of the date counter.

The range that can be set is 00–12 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RMONCNT is not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	10 months	1 month			
Initial value:	0	0	0	—	—	—	—	—
R/W:	R	R	R	R/W	R/W	R/W	R/W	R/W

13.2.8 Year Counter (RYRCNT)

The year counter (RYRCNT) is an 8-bit read/write register used for setting/counting in the BCD-coded year section of the RTC. The least significant 2 digits of the western calendar year are displayed. The count operation is performed by a carry for each year of the month counter.

The range that can be set is 00–99 (decimal). Errant operation will result if any other value is set. Carry out write processing after halting the count operation with the START bit in RCR2.

RYRCNT is not initialized by a power-on reset or manual reset, or in standby mode.

Leap years are recognized by dividing the year counter value by 4 and obtaining a fractional result of 0.

Bit:	7	6	5	4	3	2	1	0
Bit name:	10 years				1 year			
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

13.2.9 Second Alarm Register (RSECAR)

The second alarm register (RSECAR) is an 8-bit read/write register, and an alarm register corresponding to the BCD-coded second section counter RSECCNT of the RTC. When the ENB bit is set to 1, a comparison with the RSECCNT value is performed. From among the RSECAR/RMINAR/RHRAR/RWKAR/RDAYAR/RMONAR registers, the counter and alarm register comparison is performed only on those with ENB bits set to 1, and if each of those coincide, an RTC alarm interrupt is generated.

The range that can be set is 00–59 (decimal) + ENB bit. Errant operation will result if any other value is set.

The ENB bit in RSECAR is initialized to 0 by a power-on reset. The remaining RSECAR fields are not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	ENB	10 seconds			1 second			
Initial value:	0	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

13.2.10 Minute Alarm Register (RMINAR)

The minute alarm register (RMINAR) is an 8-bit read/write register, and an alarm register corresponding to the BCD-coded minute section counter RMINCNT of the RTC. When the ENB bit is set to 1, a comparison with the RMINCNT value is performed. From among the RSECAR/RMINAR/RHRAR/RWKAR/RDAYAR/RMONAR registers, the counter and alarm register comparison is performed only on those with ENB bits set to 1, and if each of those coincide, an RTC alarm interrupt is generated.

The range that can be set is 00–59 (decimal) + ENB bit. Errant operation will result if any other value is set.

The ENB bit in RMINAR is initialized by a power-on reset. The remaining RMINAR fields are not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	ENB	10 minutes			1 minute			
Initial value:	0	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

13.2.11 Hour Alarm Register (RHRAR)

The hour alarm register (RHRAR) is an 8-bit read/write register, and an alarm register corresponding to the BCD-coded hour section counter RHRCNT of the RTC. When the ENB bit is set to 1, a comparison with the RHRCNT value is performed. From among the RSECAR/RMINAR/RHRAR/RWKAR/RDAYAR/RMONAR registers, the counter and alarm register comparison is performed only on those with ENB bits set to 1, and if each of those coincide, an RTC alarm interrupt is generated.

The range that can be set is 00–23 (decimal) + ENB bit. Errant operation will result if any other value is set.

The ENB bit in RHRAR is initialized by a power-on reset. The remaining RHRAR fields are not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	ENB	—	10 hours		1 hour			
Initial value:	0	0	—	—	—	—	—	—
R/W:	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W

13.2.12 Day of the Week Alarm Register (RWKAR)

The day of the week alarm register (RWKAR) is an 8-bit read/write register, and an alarm register corresponding to the BCD-coded day of week section counter RWKCNT of the RTC. When the ENB bit is set to 1, a comparison with the RWKCNT value is performed. From among the RSECAR/RMINAR/RHRAR/RWKAR/RDAYAR/RMONAR registers, the counter and alarm register comparison is performed only on those with ENB bits set to 1, and if each of those coincide, an RTC alarm interrupt is generated.

The range that can be set is 0–6 (decimal) + ENB bit. Errant operation will result if any other value is set.

The ENB bit in RWKAR is initialized by a power-on reset. The remaining RWKAR fields are not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	ENB	—	—	—	—	Day of week		
Initial value:	0	0	0	0	0	—	—	—
R/W:	R/W	R	R	R	R	R/W	R/W	R/W

Days of the week are coded as shown in table 13.4.

Table 13.4 Day-of-Week Codes (RWKAR)

Day of Week	Code
Sunday	0
Monday	1
Tuesday	2
Wednesday	3
Thursday	4
Friday	5
Saturday	6

13.2.13 Date Alarm Register (RDAYAR)

The date alarm register (RDAYAR) is an 8-bit read/write register, and an alarm register corresponding to the BCD-coded date section counter RDAYCNT of the RTC. When the ENB bit is set to 1, a comparison with the RDAYCNT value is performed. From among the registers RSECAR, RMINAR, RHRAR, RWKAR, RDAYAR, RMONAR, the counter and alarm register comparison is performed only on those with ENB bits set to 1, and if each of those coincide, an RTC alarm interrupt is generated.

The range that can be set is 01–31 (decimal) + ENB bit. Errant operation will result if any other value is set. The RDAYCNT range that can be set changes with some months and in leap years. Please confirm the correct setting.

The ENB bit in RDAYAR is initialized by a power-on reset. The remaining RDAYAR fields are not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	ENB	—	10 days		1 day			
Initial value:	0	0	—	—	—	—	—	—
R/W:	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W

13.2.14 Month Alarm Register (RMONAR)

The month alarm register (RMONAR) is an 8-bit read/write register, and an alarm register corresponding to the BCD-coded month section counter RMONCNT of the RTC. When the ENB bit is set to 1, a comparison with the RMONCNT value is performed. From among the registers RSECAR, RMINAR, RHRAR, RWKAR, RDAYAR, RMONAR, the counter and alarm register comparison is performed only on those with ENB bits set to 1, and if each of those coincide, an RTC alarm interrupt is generated.

The range that can be set is 01–12 (decimal) + ENB bit. Errant operation will result if any other value is set.

The ENB bit in RMONAR is initialized by a power-on reset. The remaining RMONAR fields are not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	ENB	—	—	10 months	1 month			
Initial value:	0	0	0	—	—	—	—	—
R/W:	R/W	R	R	R/W	R/W	R/W	R/W	R/W

13.2.15 RTC Control Register 1 (RCR1)

The RTC control register 1 (RCR1) is an 8-bit read/write register that affects carry flags and alarm flags. It also selects whether to generate interrupts for each flag. Because flags are sometimes set after an operand read, do not use this register in read-modify-write processing.

RCR1 is initialized to H'00 by a power-on reset. In a manual reset, all bits are initialized to 0 except for the CF flag, which is undefined. When using the CF flag, it must be initialized beforehand. This register is not initialized in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	CF	—	—	CIE	AIE	—	—	AF
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R	R	R/W	R/W	R	R	R/W

Bit 7—Carry Flag (CF): Status flag that indicates that a carry has occurred. CF is set to 1 when a count-up to R64CNT or RSECCNT occurs. A count register value read at this time cannot be guaranteed; another read is required.

Bit 7: CF	Description
0	No count up of R64CNT or RSECCNT. Clearing condition: When 0 is written to CF (Initial value)
1	Count up of R64CNT or RSECCNT. Setting condition: When 1 is written to CF

Bits 6, 5, 2, and 1—Reserved: These bits always read 0. The write value should always be 0.

Bit 4—Carry Interrupt Enable Flag (CIE): When the carry flag (CF) is set to 1, the CIE bit enables interrupts.

Bit 4: CIE	Description
0	A carry interrupt is not generated when the CF flag is set to 1 (Initial value)
1	A carry interrupt is generated when the CF flag is set to 1

Bit 3—Alarm Interrupt Enable Flag (AIE): When the alarm flag (AF) is set to 1, the AIE bit allows interrupts.

Bit 3: AIE	Description
0	An alarm interrupt is not generated when the AF flag is set to 1 (Initial value)
1	An alarm interrupt is generated when the AF flag is set to 1

Bit 0—Alarm Flag (AF): The AF flag is set to 1 when the alarm time set in an alarm register (only registers with ENB bit set to 1) matches the clock and calendar time.

Bit 0: AF	Description
0	Clock/counter and alarm register have not matched since last reset to 0. Clearing condition: When 0 is written to AF (Initial value)
1	Setting condition: Clock/counter and alarm register have matched (only registers with ENB set)*

Note: * Contents do not change when 1 is written to AF.

13.2.16 RTC Control Register 2 (RCR2)

The RTC control register 2 (RCR2) is an 8-bit read/write register for periodic interrupt control, 30-second adjustment ADJ, divider circuit RESET, and RTC count start/stop control. It is initialized to H'09 by a power-on reset. It is not initialized by a manual reset or in standby mode, and retains its contents.

Bit:	7	6	5	4	3	2	1	0
Bit name:	PEF	PES2	PES1	PES0	RTCEN	ADJ	RESET	START
Initial value:	0	0	0	0	1	0	0	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 7—Periodic Interrupt Flag (PEF): Indicates interrupt generation with the period designated by the PES bits. When set to 1, PEF generates periodic interrupts.

Bit 7: PEF	Description
0	Interrupts not generated with the period designated by the PES bits. Clearing condition: When 0 is written to PEF (Initial value)
1	Interrupts generated with the period designated by the PES bits. Setting condition: When 1 is written to PEF

Bits 6–4—Periodic Interrupt Flags (PES2–PES0): These bits specify the periodic interrupt.

Bit 6: PES2	Bit 5: PES1	Bit 4: PES0	Description
0	0	0	No periodic interrupts generated (Initial value)
		1	Periodic interrupt generated every 1/256 second
	1	0	Periodic interrupt generated every 1/64 second
		1	Periodic interrupt generated every 1/16 second
1	0	0	Periodic interrupt generated every 1/4 second
		1	Periodic interrupt generated every 1/2 second
	1	0	Periodic interrupt generated every 1 second
		1	Periodic interrupt generated every 2 seconds

Bit 3—RTCEN: Controls the operation of the crystal oscillator for the RTC.

Bit 3: RTCEN	Description
0	Halts the crystal oscillator for the RTC.
1	Runs the crystal oscillator for the RTC. (Initial value)

Bit 2—30-Second Adjustment (ADJ): When 1 is written to the ADJ bit, times of 29 seconds or less will be rounded to 00 seconds and 30 seconds or more to 1 minute. The divider circuit will be simultaneously reset. This bit always reads 0.

Bit 2: ADJ	Description	
0	Runs normally.	(Initial value)
1 (write)	30-second adjustment.	

Bit 1—Reset (RESET): When 1 is written, initializes the divider circuit. This bit always reads 0.

Bit 1: RESET	Description	
0	Runs normally.	(Initial value)
1 (write)	Divider circuit is reset.	

Bit 0—Start Bit (START): Halts and restarts the counter (clock).

Bit 0: START	Description	
0	Second/minute/hour/day/week/month/year counter halts.	
1	Second/minute/hour/day/week/month/year counter runs normally.	(Initial value)

Note: The 64-Hz counter always runs unless stopped with the RTCEN bit.

13.3 RTC Operation

13.3.1 Initial Settings of Registers after Power-On

All the registers should be set after the power is turned on.

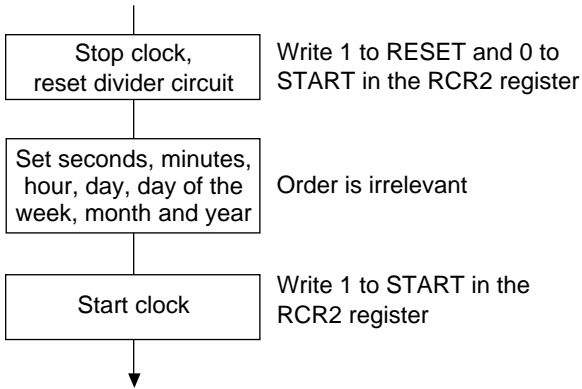
13.3.2 Setting the Time

Part (a) in figure 13.2 shows how to set the time when the clock is stopped. This works when the entire calendar or clock is to be set.

Part (b) in figure 13.2 describes how to set the clock when the clock is running. This works when only part of the calendar or clock needs to be reset (e.g., changing only the seconds or only the hour). The write status is checked using the carry flags. When there is a carry during the writing of new data, the new data is automatically updated. Since this causes errors in the data, the data must be rewritten if the carry flag is set to 1.

The interrupt function can be used to determine the status of the carry flag.

a. To reset the divider circuit and set the counter



b. To set the seconds-year counter

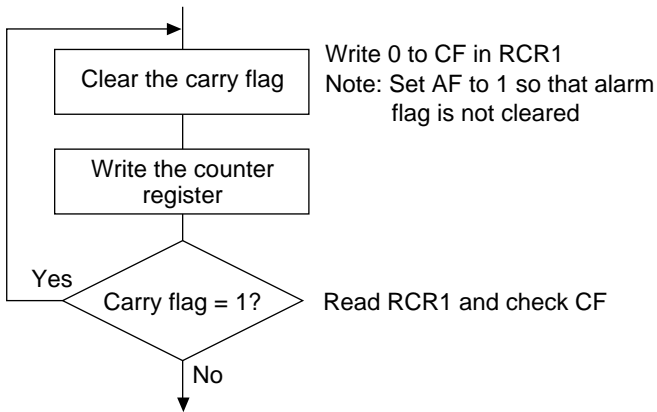


Figure 13.2 Setting the Time

13.3.3 Reading the Time

Figure 13.3 shows how to read the time. If a carry occurs while reading the time, the correct time will not be obtained, so it must be read again. Part (a) in figure 13.3 shows the method of reading the time without using interrupts; part (b) in figure 13.3 shows the method using carry interrupts. To keep programming simple, method (a) should normally be used.

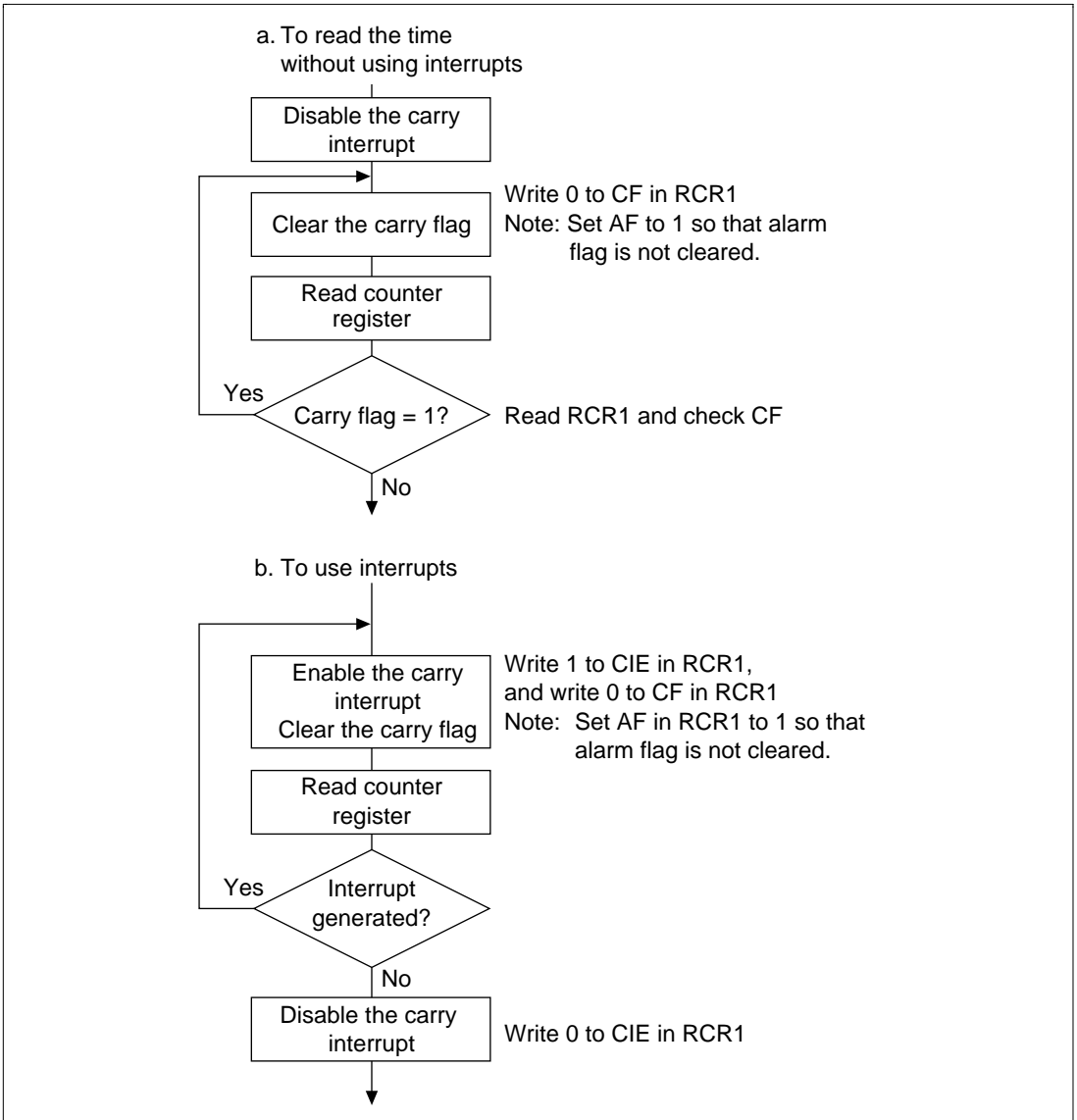


Figure 13.3 Reading the Time

13.3.4 Alarm Function

Figure 13.4 shows how to use the alarm function.

Alarms can be generated using seconds, minutes, hours, day of the week, date, month, or any combination of these. Set the ENB bit (bit 7) in the register on which the alarm is placed to 1, and then set the alarm time in the lower bits. Clear the ENB bit in the register on which the alarm is placed to 0.

When the clock and alarm times match, a 1 is set in the AF bit (bit 0) in RCR1. Alarm detection can be checked by reading this bit, but normally it is done by interrupt. If 1 is placed in the AIE bit (bit 3) in RCR1, an interrupt is generated when an alarm occurs.

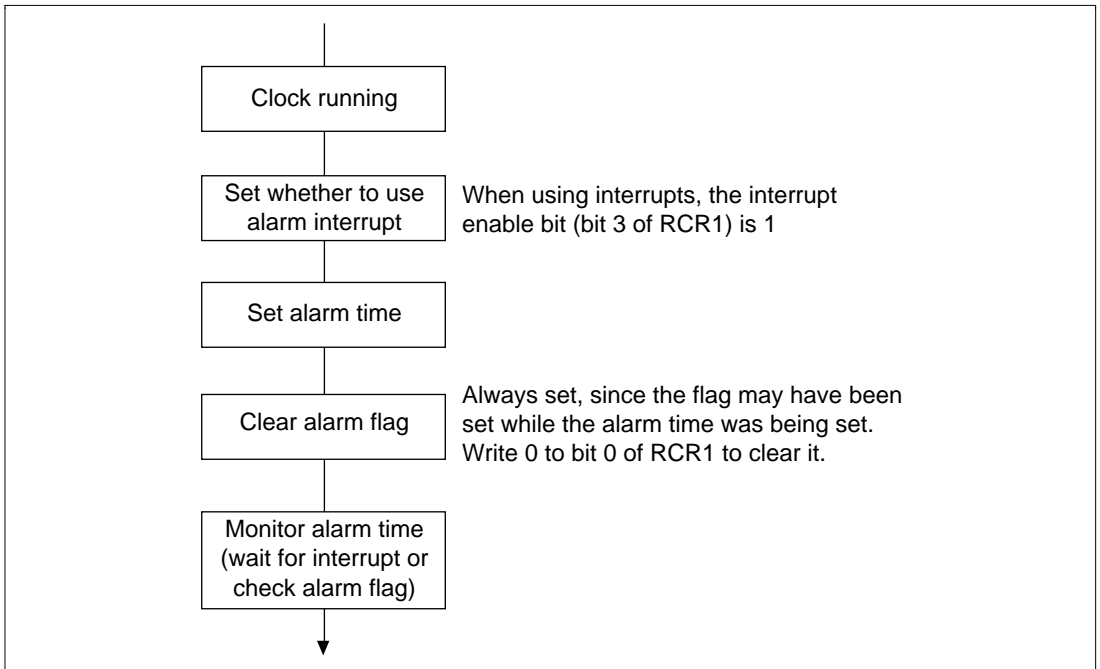


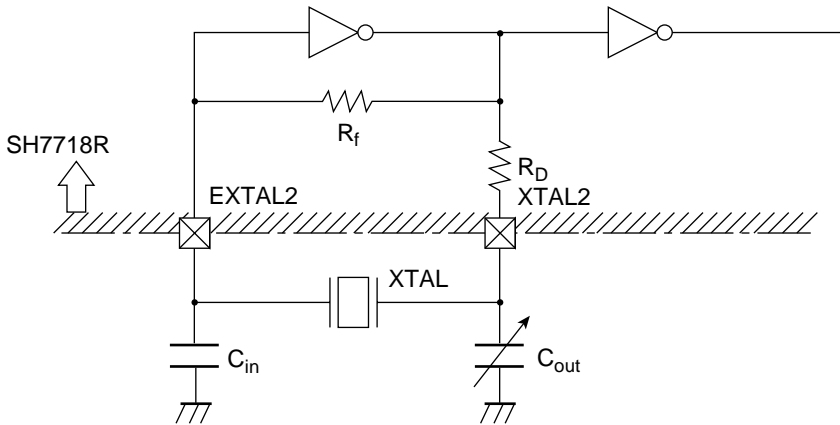
Figure 13.4 Using the Alarm Function

13.3.5 Crystal Resonator Circuit

Crystal resonator circuit constants (recommended values) are shown in table 13.5, and the RTC crystal resonator circuit in figure 13.5.

Table 13.5 Recommended Resonator Circuit Constants (Recommended Values)

fosc	Cin	Cout
32.768 kHz	10 to 22 pF	10 to 22 pF



- Notes :
1. Select either the Cin or Cout side for the frequency adjustment variable capacitor according to requirements such as the adjustment range, degree of stability, etc.
 2. Built-in resistance value Rf (typ. value) = 10 MΩ, RD (typ. value) = 400 kΩ
 3. Cin and Cout values include floating capacitance due to the wiring. Take care when using a solid-earth board.
 4. The crystal resonator stabilization time depends on the mounted circuit constants, floating capacitance, etc., and should be decided after consultation with the crystal resonator manufacturer.
 5. Place the crystal resonator and load capacitors Cin and Cout as close as possible to the chip.
(Correct oscillation may not be possible if there is externally induced noise in the EXTAL2 and XTAL2 pins.)
 6. Ensure that the crystal resonator connection pin (EXTAL2 and XTAL2) wiring is routed as far away as possible from other power lines (except GND) and signal lines.

Figure 13.5 Example of Crystal Resonator Circuit Connection

13.4 Usage Notes

13.4.1 Register Writes during RTC Count

The following RTC registers cannot be written to while the RTC is counting (bit 0 of RCR2 = 1):

RSECCNT, RMINCNT, RHRCNT, RDAYCNT, RWKCNT, RMONCNT, RYRCNT

The RTC count must be stopped before writing to any of these registers.

Section 14 Serial Communication Interface (SCI)

14.1 Overview

The SH7718R has an on-chip serial communication interface (SCI) that supports both asynchronous and synchronous serial communication. It also has a multiprocessor communication function for serial communication among two or more processors. The SCI supports a smart card interface, which is a serial communications feature for IC card interfaces that conforms to the ISO/IEC standard 7816-3 for identification cards. See section 14, Smart Card Interface, for more information.

14.1.1 Features

SCI features are listed below.

- Asynchronous or synchronous can be selected as the serial communication mode.
- Asynchronous mode:
 - Serial data communication is synchronized in start-stop mode in character units. The SCI can communicate with a universal asynchronous receiver/transmitter (UART), an asynchronous communication interface adapter (ACIA), or any other communications chip that employs a standard asynchronous serial system. It can also communicate with two or more other processors using the multiprocessor communication function. The maximum bit rate is 937.5 kbps. There are twelve selectable serial data communication formats.
 - Data length: Seven or eight bits
 - Stop bit length: One or two bits
 - Parity: Even, odd, or none
 - Multiprocessor bit: 1 or 0
 - Receive error detection: Parity, overrun, and framing errors
 - Break detection: By reading the RxD level directly from the serial port register (SCSPTR) when a framing error occurs
- Synchronous mode:
 - Serial data communication is synchronized with a clock signal. The SCI can communicate with other chips having a synchronous communication function. The maximum bit rate is 5 Mbps. There is one serial data communication format.
 - Data length: Eight bits
 - Receive error detection: Overrun errors
- Full duplex communication: The transmitting and receiving sections are independent, so the SCI can transmit and receive simultaneously. Both sections use double buffering, so continuous data transfer is possible in both the transmit and receive directions.
- On-chip baud rate generator with selectable bit rates

- Internal or external transmit/receive clock source: From either baud rate generator (internal) or SCK pin (external)
- Four types of interrupts: Transmit-data-empty, transmit-end, receive-data-full, and receive-error interrupts are requested independently.
- When the SCI is not in use, it can be stopped by halting the clock supplied to it, saving power.

14.1.2 Block Diagram

Figure 14.1 shows a block diagram of the SCI.

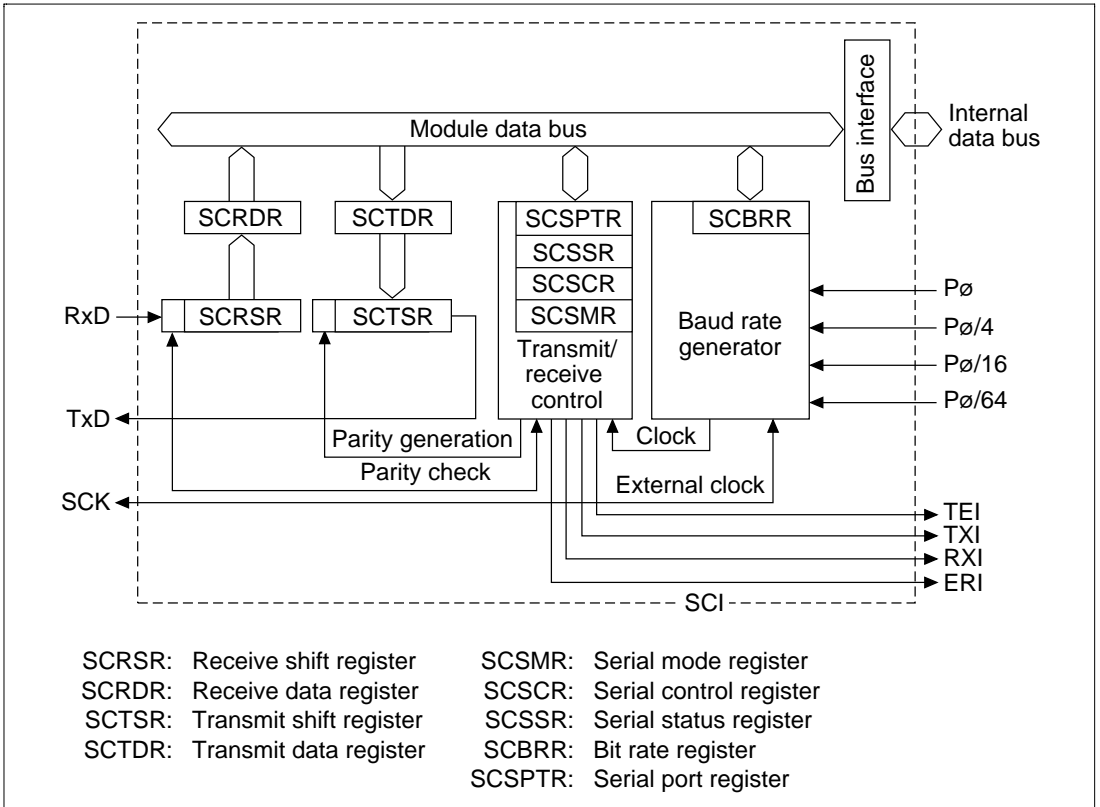


Figure 14.1 SCI Block Diagram

14.1.3 Pin Configuration

The SCI has the serial pins summarized in table 14.1.

Table 14.1 SCI Pins

Pin Name	Abbreviation	Input/Output	Function
Serial clock pin	SCK	Input/output	Clock input/output
Receive data pin	RxD	Input	Receive data input
Transmit data pin	TxD	Output	Transmit data output

Note: These pins function as mode input pins MD0–MD02 after a power-on reset. They are made to function as serial pins by performing SCI operation settings with the TE, RE, CKEI, and CKE0 bits in SCSCR and the C/ \bar{A} bit in SCSMR. Break status transmission and detection can be performed by means of the SCI's SCSPTR register.

14.1.4 Register Configuration

Table 14.2 summarizes the SCI internal registers. These registers select the communication mode (asynchronous or synchronous), specify the data format and bit rate, and control the transmitter and receiver sections.

Table 14.2 Registers

Name	Abbreviation	R/W	Initial Value* ²	Address	Access Size
Serial mode register	SCSMR	R/W	H'00	H'FFFFFFE80	8
Bit rate register	SCBRR	R/W	H'FF	H'FFFFFFE82	8
Serial control register	SCSCR	R/W	H'00	H'FFFFFFE84	8
Transmit data register	SCTDR	R/W	H'FF	H'FFFFFFE86	8
Serial status register	SCSSR	R/(W)* ¹	H'84	H'FFFFFFE88	8
Receive data register	SCRDR	R	H'00	H'FFFFFFE8A	8
Serial port register	SCSPTR	R/W	* ³	H'FFFFFFF7C	8

Notes: 1. Only 0 can be written, to clear the flags.
2. Initialized by a power-on reset and manual reset.
3. Initialized to H'00 except bit 2 and 0. Bit 2 and 0 are undefined.

14.2 Register Descriptions

14.2.1 Receive Shift Register (SCRSR)

The receive shift register (SCRSR) receives serial data. Data input at the RxD pin is loaded into SCRSR in the order received, LSB (bit 0) first, converting the data to parallel form. When one byte has been received, it is automatically transferred to SCRDR. The CPU cannot read or write SCRSR directly.

Bit:	7	6	5	4	3	2	1	0
Bit name:								
R/W:	—	—	—	—	—	—	—	—

14.2.2 Receive Data Register (SCRDR)

The receive data register (SCRDR) stores serial receive data. The SCI completes the reception of one byte of serial data by moving the received data from the receive shift register (SCRSR) into SCRDR for storage. SCRSR is then ready to receive the next data. This double buffering allows the SCI to receive data continuously.

The CPU can read but not write to SCRDR. SCRDR is initialized to H'00 by a reset and in standby or module standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	0	0	0	0	0	0	0	0
R/W:	R	R	R	R	R	R	R	R

14.2.3 Transmit Shift Register (SCTSR)

The transmit shift register (SCTSR) transmits serial data. The SCI loads transmit data from the transmit data register (SCTDR) into SCTSR, then transmits the data serially from the TxD pin, LSB (bit 0) first. After transmitting one data byte, the SCI automatically loads the next transmit data from SCTDR into SCTSR and starts transmitting again. If the TDRE bit in SCSSR is 1, however, the SCI does not load the SCTDR contents into SCTSR. The CPU cannot read or write to SCTSR directly.

Bit:	7	6	5	4	3	2	1	0
Bit name:								
R/W:	—	—	—	—	—	—	—	—

14.2.4 Transmit Data Register (SCTDR)

The transmit data register (SCTDR) is an 8-bit register that stores data for serial transmission. When the SCI detects that the transmit shift register (SCTSR) is empty, it moves transmit data written in SCTDR into SCTSR and starts serial transmission. Continuous serial transmission is possible by writing the next transmit data in SCTDR during serial transmission from SCTSR.

The CPU can always read and write to SCTDR. SCTDR is initialized to H'FF by a reset and in standby or module standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

14.2.5 Serial Mode Register (SCSMR)

The serial mode register (SCSMR) is an 8-bit register that specifies the SCI serial communication format and selects the clock source for the baud rate generator.

The CPU can always read and write to SCSMR. SCSMR is initialized to H'00 by a reset and in standby or module standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	C/ \bar{A}	CHR	PE	O/ \bar{E}	STOP	MP	CKS1	CKS0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 7—Communication Mode (C/ \bar{A}): Selects whether the SCI operates in asynchronous or synchronous mode.

Bit 7: C/ \bar{A}	Description
0	Asynchronous mode (Initial value)
1	Synchronous mode

Bit 6—Character Length (CHR): Selects 7-bit or 8-bit data in asynchronous mode. In synchronous mode, the data length is always 8 bits, regardless of the CHR setting.

Bit 6: CHR	Description
0	8-bit data (Initial value)
1	7-bit data. (When 7-bit data is selected, the MSB (bit 7) of the transmit data register is not transmitted.)

Bit 5—Parity Enable (PE): Selects whether to add a parity bit to transmit data and to check the parity of receive data, in asynchronous mode. In synchronous mode, a parity bit is neither added nor checked, regardless of the PE setting.

Bit 5: PE	Description
0	Parity bit not added or checked (Initial value)
1	Parity bit added and checked. When PE is set to 1, an even or odd parity bit is added to transmit data, depending on the parity mode (O/\bar{E}) setting. Receive data parity is checked according to the even/odd (O/\bar{E}) mode setting.

Bit 4—Parity Mode (O/\bar{E}): Selects even or odd parity when parity bits are added and checked. The O/\bar{E} setting is used only in asynchronous mode and only when the parity enable bit (PE) is set to 1 to enable parity addition and checking. The O/\bar{E} setting is ignored in synchronous mode, and in asynchronous mode when parity addition and checking is disabled.

Bit 4: O/\bar{E}	Description
0	Even parity (Initial value) If even parity is selected, the parity bit is added to transmit data to make an even number of 1s in the transmitted character and parity bit combined. Receive data is checked to see if it has an even number of 1s in the received character and parity bit combined.
1	Odd parity If odd parity is selected, the parity bit is added to transmit data to make an odd number of 1s in the transmitted character and parity bit combined. Receive data is checked to see if it has an odd number of 1s in the received character and parity bit combined.

Bit 3—Stop Bit Length (STOP): Selects one or two bits as the stop bit length in asynchronous mode. This setting is used only in asynchronous mode. It is ignored in synchronous mode because no stop bits are added.

In receiving, only the first stop bit is checked, regardless of the STOP bit setting. If the second stop bit is 1, it is treated as a stop bit, but if the second stop bit is 0, it is treated as the start bit of the next incoming character.

Bit 3: STOP	Description
0	One stop bit (Initial value) In transmitting, a single 1-bit is added at the end of each transmitted character.
1	Two stop bits In transmitting, two 1-bits are added at the end of each transmitted character.

Bit 2—Multiprocessor Mode (MP): Selects multiprocessor format. When multiprocessor format is selected, settings of the parity enable (PE) and parity mode ($O\bar{E}$) bits are ignored. The MP bit setting is used only in asynchronous mode; it is ignored in synchronous mode. For the multiprocessor communication function, see section 14.3.3, Multiprocessor Communication.

Bit 2: MP	Description
0	Multiprocessor function disabled (Initial value)
1	Multiprocessor format selected

Bits 1 and 0—Clock Select 1 and 0 (CKS1 and CKS0): These bits select the internal clock source of the on-chip baud rate generator. Four clock sources are available: $P\phi$, $P\phi/4$, $P\phi/16$ and $P\phi/64$. For further information on the clock source, bit rate register settings, and baud rate, see section 14.2.9, Bit Rate Register.

Bit 1: CKS1	Bit 0: CKS0	Description
0	0	$P\phi$ (Initial value)
	1	$P\phi/4$
1	0	$P\phi/16$
	1	$P\phi/64$

Note: $P\phi$: Peripheral clock

14.2.6 Serial Control Register (SCSCR)

The serial control register (SCSCR) operates the SCI transmitter/receiver, selects the serial clock output in asynchronous mode, enables/disables interrupt requests, and selects the transmit/receive clock source. The CPU can always read and write to SCSCR. SCSCR is initialized to H'00 by a reset and in standby or module standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 7—Transmit Interrupt Enable (TIE): Enables or disables the transmit-data-empty interrupt (TXI) requested when the transmit data register empty bit (TDRE) in the serial status register (SCSSR) is set to 1 due to transfer of serial transmit data from SCTDR to SCTSR.

Bit 7: TIE	Description
0	Transmit-data-empty interrupt request (TXI) is disabled. (Initial value) The TXI interrupt request can be cleared by reading TDRE after it has been set to 1, then clearing TDRE to 0, or by clearing TIE to 0.
1	Transmit-data-empty interrupt request (TXI) is enabled.

Bit 6—Receive Interrupt Enable (RIE): Enables or disables the receive-data-full interrupt (RXI) requested when the receive data register full bit (RDRF) in the serial status register (SCSSR) is set to 1 due to transfer of serial receive data from SCRSR to SCRDR. It also enables or disables receive-error interrupt (ERI) requests.

Bit 6: RIE	Description
0	Receive-data-full interrupt (RXI) and receive-error interrupt (ERI) requests are disabled. (Initial value) RXI and ERI interrupt requests can be cleared by reading the RDRF flag or error flag (FER, PER, or ORER) after it has been set to 1, then clearing the flag to 0, or by clearing RIE to 0.
1	Receive-data-full interrupt (RXI) and receive-error interrupt (ERI) requests are enabled.

Bit 5—Transmit Enable (TE): Enables or disables the SCI serial transmitter.

Bit 5: TE	Description
0	Transmitter disabled (Initial value) The transmit data register empty bit (TDRE) in the serial status register (SCSSR) is locked at 1.
1	Transmitter enabled Serial transmission starts when the transmit data register empty (TDRE) bit in the serial status register (SCSSR) is cleared to 0 after writing of transmit data into SCTDR. Select the transmit format in SCSMR before setting TE to 1.

Bit 4—Receive Enable (RE): Enables or disables the SCI serial receiver.

Bit 4: RE	Description
0	Receiver disabled (Initial value) Clearing RE to 0 does not affect the receive flags (RDRF, FER, PER, ORER). These flags retain their previous values.
1	Receiver enabled Serial reception starts when a start bit is detected in asynchronous mode, or synchronous clock input is detected in synchronous mode. Select the receive format in SCSMR before setting RE to 1.

Bit 3—Multiprocessor Interrupt Enable (MPIE): Enables or disables multiprocessor interrupts. The MPIE setting is used only in asynchronous mode, and only if the multiprocessor mode bit (MP) in the serial mode register (SCSMR) is set to 1 during reception. The MPIE setting is ignored in synchronous mode or when the MP bit is cleared to 0.

Bit 3: MPIE	Description
0	Multiprocessor interrupts are disabled (normal receive operation). (Initial value) MPIE is cleared to 0 by writing 0 to it, or when the multiprocessor bit (MPB) is set to 1 in receive data.
1	Multiprocessor interrupts are enabled. Receive-data-full interrupt requests (RXI), receive-error interrupt requests (ERI), and setting of the RDRF, FER, and ORER status flags in the serial status register (SCSSR) are disabled until data with a multiprocessor bit of 1 is received. The SCI does not transfer receive data from SCSSR to SCRDR, does not detect receive errors, and does not set the RDRF, FER, and ORER flags in the serial status register (SCSSR). When it receives data that includes MPB = 1, the SCSSR's MPB flag is set to 1, and the SCI automatically clears MPIE to 0, generates RXI and ERI interrupts (if the TIE and RIE bits in SCSMR are set to 1), and allows the FER and ORER bits to be set.

Bit 2—Transmit-End Interrupt Enable (TEIE): Enables or disables the transmit-end interrupt (TEI) requested if SCTDR does not contain new transmit data when the MSB is transmitted.

Bit 2: TEIE	Description
0	Transmit-end interrupt (TEI) requests are disabled.* (Initial value)
1	Transmit-end interrupt (TEI) requests are enabled.*

Note: The TEI request can be cleared by reading the TDRE bit in the serial status register (SCSSR) after it has been set to 1, then clearing TDRE to 0 and clearing the transmit end (TEND) bit to 0, or by clearing the TEIE bit to 0.

Bits 1 and 0—Clock Enable 1 and 0 (CKE1 and CKE0): These bits select the SCI clock source and enable or disable clock output from the SCK pin. Depending on the combination of CKE1 and CKE0, the SCK pin can be used for serial clock output or serial clock input.

The CKE0 setting is valid only in asynchronous mode, and only when the SCI is internally clocked (CKE1 = 0). The CKE0 setting is ignored in synchronous mode, or when an external clock source is selected (CKE1 = 1). Before selecting the SCI operating mode in the serial mode register (SCSMR), set CKE1 and CKE0. For further details on selection of the SCI clock source, see table 14.9 in section 14.3, Operation.

Bit 1: Bit 0:

CKE1	CKE0	Description
0	0	Asynchronous mode Internal clock, SCK pin used for input pin (input signal is ignored) (Initial value)
		Synchronous mode Internal clock, SCK pin used for serial clock output (Initial value)
1	1	Asynchronous mode Internal clock, SCK pin used for clock output* ¹
		Synchronous mode Internal clock, SCK pin used for serial clock output
1	0	Asynchronous mode External clock, SCK pin used for clock input* ²
		Synchronous mode External clock, SCK pin used for serial clock input
1	1	Asynchronous mode External clock, SCK pin used for clock input* ²
		Synchronous mode External clock, SCK pin used for serial clock input

Notes: 1. The output clock frequency is the same as the bit rate.

2. The input clock frequency is 16 times the bit rate.

14.2.7 Serial Status Register (SCSSR)

The serial status register (SCSSR) is an 8-bit register containing multiprocessor bit values, and status flags that indicate the SCI operating status.

The CPU can always read and write to SCSSR, but cannot write 1 in the status flags (TDRE, RDRF, ORER, PER, and FER). These flags can be cleared to 0 only if they have first been read (after being set to 1). Bits 2 (TEND) and 1 (MPB) are read-only bits that cannot be written. SCSSR is initialized to H'84 by a reset and in standby or module standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	TDRE	RDRF	ORER	FER	PER	TEND	MPB	MPBT
Initial value:	1	0	0	0	0	1	0	0
R/W:	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R	R	R/W

Note: * Only 0 can be written, to clear the flag.

Bit 7—Transmit Data Register Empty (TDRE): Indicates that the SCI has loaded transmit data from SCTDR into SCTSR and new serial transmit data can be written in SCTDR.

Bit 7: TDRE	Description
0	SCTDR contains valid transmit data. TDRE is cleared to 0 when software reads TDRE after it has been set to 1, then writes 0 in TDRE, or data is written in SCTDR.
1	SCTDR does not contain valid transmit data. (Initial value) TDRE is set to 1 when the chip is reset or enters standby mode, the TE bit in the serial control register (SCSCR) is cleared to 0, or SCTDR contents are loaded into SCTSR, so new data can be written in SCTDR.

Bit 6—Receive Data Register Full (RDRF): Indicates that SCRDR contains received data.

Bit 6: RDRF	Description
0	SCRDR does not contain valid received data. (Initial value) RDRF is cleared to 0 when the chip is reset or enters standby mode, software reads RDRF after it has been set to 1, then writes 0 in RDRF, or data is read from SCRDR.
1	SCRDR contains valid received data. RDRF is set to 1 when serial data is received normally and transferred from SCRSR to SCRDR.

Note: SCRDR and RDRF are not affected by detection of receive errors or by clearing of the RE bit to 0 in the serial control register. They retain their previous contents. If RDRF is still set to 1 when reception of the next data ends, an overrun error (ORER) occurs and the receive data is lost.

Bit 5—Overrun Error (ORER): Indicates that data reception aborted due to an overrun error.

Bit 5: ORER	Description
0	Receiving is in progress or has ended normally. (Initial value) Clearing the RE bit to 0 in the serial control register does not affect the ORER bit, which retains its previous value. ORER is cleared to 0 when the chip is reset or enters standby mode or software reads ORER after it has been set to 1, then writes 0 in ORER.
1	A receive overrun error occurred. SCRDR continues to hold the data received before the overrun error, so subsequent receive data is lost. Serial receiving cannot continue while ORER is set to 1. In synchronous mode, serial transmitting is also disabled. ORER is set to 1 if reception of the next serial data ends when RDRF is set to 1.

Bit 4—Framing Error (FER): Indicates that data reception aborted due to a framing error in asynchronous mode.

Bit 4: FER	Description
0	Receiving is in progress or has ended normally. (Initial value) Clearing the RE bit to 0 in the serial control register does not affect the FER bit, which retains its previous value. FER is cleared to 0 when the chip is reset or enters standby mode or software reads FER after it has been set to 1, then writes 0 in FER.
1	A receive framing error occurred. When the stop bit length is two bits, only the first bit is checked. The second stop bit is not checked. When a framing error occurs, the SCI transfers the receive data into SCRDR but does not set RDRF. Serial receiving cannot continue while FER is set to 1. In synchronous mode, serial transmitting is also disabled. FER is set to 1 if the stop bit at the end of receive data is checked and found to be 0.

Bit 3—Parity Error (PER): Indicates that data reception (with parity) aborted due to a parity error in asynchronous mode.

Bit 3: PER	Description
0	Receiving is in progress or has ended normally. (Initial value) Clearing the RE bit to 0 in the serial control register does not affect the PER bit, which retains its previous value. PER is cleared to 0 when the chip is reset or enters standby mode or software reads PER after it has been set to 1, then writes 0 in PER.
1	A receive parity error occurred. When a parity error occurs, the SCI transfers the receive data into SCRDR but does not set RDRF. Serial receiving cannot continue while PER is set to 1. In synchronous mode, serial transmitting is also disabled. PER is set to 1 if the number of 1s in receive data, including the parity bit, does not match the even or odd parity setting of the parity mode bit (O/E) in the serial mode register (SCSMR).

Bit 2—Transmit End (TEND): Indicates that when the last bit of a serial character was transmitted, SCTDR did not contain valid data, so transmission has ended. TEND is a read-only bit and cannot be written.

Bit 2: TEND	Description
0	Transmission is in progress. TEND is cleared to 0 when software reads TDRE after it has been set to 1, then writes 0 in TDRE, or data is written in SCTDR.
1	End of transmission. (Initial value) TEND is set to 1 when the chip is reset or enters standby mode, TE is cleared to 0 in the serial control register (SCSCR), or TDRE is 1 when the last bit of a one-byte serial character is transmitted.

Bit 1—Multiprocessor Bit (MPB): Stores the value of the multiprocessor bit in receive data when a multiprocessor format is selected for receiving in asynchronous mode. MPB is a read-only bit and cannot be written.

Bit 1: MPB	Description
0	Multiprocessor bit value in receive data is 0. (Initial value) If RE is cleared to 0 when a multiprocessor format is selected, the MPB retains its previous value.
1	Multiprocessor bit value in receive data is 1.

Bit 0—Multiprocessor Bit Transfer (MPBT): Stores the value of the multiprocessor bit added to transmit data when a multiprocessor format is selected for transmitting in asynchronous mode. The MPBT setting is ignored in synchronous mode, when a multiprocessor format is not selected, or when the SCI is not transmitting.

Bit 0: MPBT	Description
0	Multiprocessor bit value in transmit data is 0. (Initial value)
1	Multiprocessor bit value in transmit data is 1.

14.2.8 Serial Port Register (SCSPTR)

The serial port register (SCSPTR) is an 8-bit register that the CPU can always read and write. It controls I/O and data of the port multiplexed with the serial communications interface (SCI) pins. Input data can be read from the RxD pin and output data can be transmitted to the TxD pin; this controls breaks for serial transmission and reception.

SCSPTR is initialized to H'00 by a power-on reset. It is not initialized by a manual reset or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	SPB1IO	SPB1DT	SPB0IO	SPB0DT
Initial value:	0	0	0	0	0	—	0	—
R/W:	R	R	R	R	R/W	R/W	R/W	R/W

Bits 7 to 4—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 3—Serial Port Clock Port I/O (SPB1IO): Specifies serial port SCK pin input/output. When the SCK pin is actually set as a port output pin and outputs the value set by the SPB1DT bit, the C/\bar{A} bit in SCSMR and the CKE1 and CKE0 bits in SCSCR should be cleared to 0.

Bit 3: SPB1IO	Description
---------------	-------------

0	The SPB1IO value is not output to the SCK pin. (Initial value)
1	The SPB1IO bit value is output to the TxD pin.

Bit 2—Serial Port Clock Port Data (SPB1DT): Specifies the serial port SCK pin input/output data. Input or output is specified by the SPB1IO bit (see the description of SPB1IO for details). When output is specified, the value of the SPB1DT bit is output to the SCK pin. The SCK pin value is read from the SPB1DT bit regardless of the value of the SPB1IO bit. The initial value of this bit after a power-on reset is undefined.

Bit 2: SPB1DT	Description
---------------	-------------

0	I/O data level is low. (Initial value)
1	I/O data level is high.

Bit 1—Serial Port Break I/O (SPB0IO): Specifies the serial port TxD pin output condition. When the TxD pin is actually set as a port output pin and outputs the value set by the SPB0DT bit, the TE bit in SCSCR should be cleared to 0.

Bit 1: SPB0IO	Description
0	The SPB0DT bit value is not output to the TxD pin. (Initial value)
1	The SPB0DT bit value is output to the TxD pin.

Bit 0—Serial Port Break Data (SPB0DT): Specifies the serial port I/O data. Use the SPB0IO bit to specify input or output of TxD pin. SPB0DT bit is output to the TxD pin when specified as output. The RxD pin value is read from the SPB0IO bit regardless of the SPB0IO bit value. The initial value is undefined.

Bit 0 : SPB0DT	Description
0	I/O data level is low. (Initial value)
1	I/O data level is high.

Block diagrams of the SCI I/O port pins are shown in figures 16.2 to 16.4 in section 16, I/O Ports.

14.2.9 Bit Rate Register (SCBRR)

The bit rate register (SCBRR) is an 8-bit register that, together with the baud rate generator clock source selected by the CKS1 and CKS0 bits in the serial mode register (SCSMR), determines the serial transmit/receive bit rate.

The CPU can always read and write to SCBRR. SCBRR is initialized to H'FF by a reset and in module standby or standby mode. Each channel has independent baud rate generator control, so different values can be set in the two channels.

Bit:	7	6	5	4	3	2	1	0
Bit name:								
Initial value:	1	1	1	1	1	1	1	1
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

The SCBRR setting is calculated as follows:

$$\text{Asynchronous mode: } N = [P_{\phi} / (64 \times 2^{2n-1} \times B)] \times 10^6 - 1$$

$$\text{Synchronous mode: } N = [P_{\phi} / (8 \times 2^{2n-1} \times B)] \times 10^6 - 1$$

B: Bit rate (bit/s)

N: SCBRR setting for baud rate generator ($0 \leq N \leq 255$)

P_{ϕ} : Operating frequency for peripheral modules (MHz)

n: Baud rate generator clock source ($n = 0, 1, 2, 3$) (for the clock sources and values of n, see table 14.3.)

Table 14.3 SCSMR Settings

n	Clock Source	SCSMR Settings	
		CKS1	CKS0
0	P ϕ	0	0
1	P ϕ /4	0	1
2	P ϕ /16	1	0
3	P ϕ /64	1	1

Note: The bit rate error for asynchronous mode is given by the following formula:

$$\text{Error (\%)} = \{P(\phi \times 10^6) / [(N + 1) \times B \times 64 \times 2^{2n - 1}] - 1\} \times 100$$

Table 14.4 lists examples of SCBRR settings in asynchronous mode; table 14.5 lists examples of SCBRR settings in synchronous mode.

Table 14.4 Bit Rates and SCBRR Settings in Asynchronous Mode

Bit Rate (Bit/s)	P ϕ (MHz)								
	2			2.097152			2.4576		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	1	141	0.03	1	148	-0.04	1	174	-0.26
150	1	103	0.16	1	108	0.21	1	127	0.00
300	0	207	0.16	0	217	0.21	0	255	0.00
600	0	103	0.16	0	108	0.21	0	127	0.00
1200	0	51	0.16	0	54	-0.70	0	63	0.00
2400	0	25	0.16	0	26	1.14	0	31	0.00
4800	0	12	0.16	0	13	-2.48	0	15	0.00
9600	0	6	-6.99	0	6	-2.48	0	7	0.00
19200	0	2	8.51	0	2	13.78	0	3	0.00
31250	0	1	0.00	0	1	4.86	0	1	22.88
38400	0	1	-18.62	0	1	-14.67	0	1	0.00

Table 14.4 Bit Rates and SCBRR Settings in Asynchronous Mode (cont)

Bit Rate (Bit/s)	P _ϕ (MHz)								
	3			3.6864			4		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	1	212	0.03	2	64	0.70	2	70	0.03
150	1	155	0.16	1	191	0.00	1	207	0.16
300	1	77	0.16	1	95	0.00	1	103	0.16
600	0	155	0.16	0	191	0.00	0	207	0.16
1200	0	77	0.16	0	95	0.00	0	103	0.16
2400	0	38	0.16	0	47	0.00	0	51	0.16
4800	0	19	-2.34	0	23	0.00	0	25	0.16
9600	0	9	-2.34	0	11	0.00	0	12	0.16
19200	0	4	-2.34	0	5	0.00	0	6	-6.99
31250	0	2	0.00	—	—	—	0	3	0.00
38400	—	—	—	0	2	0.00	0	2	8.51

Bit Rate (Bit/s)	P _ϕ (MHz)								
	4.9152			5			6		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	2	86	0.31	2	88	-0.25	2	106	-0.44
150	1	255	0.00	2	64	0.16	2	77	0.16
300	1	127	0.00	1	129	0.16	1	155	0.16
600	0	255	0.00	1	64	0.16	1	77	0.16
1200	0	127	0.00	0	129	0.16	0	155	0.16
2400	0	63	0.00	0	64	0.16	0	77	0.16
4800	0	31	0.00	0	32	-1.36	0	38	0.16
9600	0	15	0.00	0	15	1.73	0	19	-2.34
19200	0	7	0.00	0	7	1.73	0	9	-2.34
31250	0	4	-1.70	0	4	0.00	0	5	0.00
38400	0	3	0.00	0	3	1.73	0	4	-2.34

Table 14.4 Bit Rates and SCBRR Settings in Asynchronous Mode (cont)

Bit Rate (Bit/s)	P_{θ} (MHz)								
	6.144			7.3728			8		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	2	108	0.08	2	130	-0.07	2	141	0.03
150	2	79	0.00	2	95	0.00	2	103	0.16
300	1	159	0.00	1	191	0.00	1	207	0.16
600	1	79	0.00	1	95	0.00	1	103	0.16
1200	0	159	0.00	0	191	0.00	0	207	0.16
2400	0	79	0.00	0	95	0.00	0	103	0.16
4800	0	39	0.00	0	47	0.00	0	51	0.16
9600	0	19	0.00	0	23	0.00	0	25	0.16
19200	0	9	0.00	0	11	0.00	0	12	0.16
31250	0	5	2.40	0	6	5.33	0	7	0.00
38400	0	4	0.00	0	5	0.00	0	6	-6.99

Bit Rate (Bit/s)	P_{θ} (MHz)											
	9.8304			10			12			12.288		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	2	174	-0.26	2	177	-0.25	2	212	0.03	2	217	0.08
150	2	127	0.00	2	129	0.16	2	155	0.16	2	159	0.00
300	1	255	0.00	2	64	0.16	2	77	0.16	2	79	0.00
600	1	127	0.00	1	129	0.16	1	155	0.16	1	159	0.00
1200	0	255	0.00	1	64	0.16	1	77	0.16	1	79	0.00
2400	0	127	0.00	0	129	0.16	0	155	0.16	0	159	0.00
4800	0	63	0.00	0	64	0.16	0	77	0.16	0	79	0.00
9600	0	31	0.00	0	32	-1.36	0	38	0.16	0	39	0.00
19200	0	15	0.00	0	15	1.73	0	19	0.16	0	19	0.00
31250	0	9	-1.70	0	9	0.00	0	11	0.00	0	11	2.40
38400	0	1	0.00	0	7	1.73	0	9	-2.34	0	9	0.00

Table 14.4 Bit Rates and SCBRR Settings in Asynchronous Mode (cont)

Bit Rate (Bit/s)	P ₀ (MHz)											
	14.7456			16			19.6608			20		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	3	64	0.70	3	70	0.03	3	86	0.31	3	88	-0.25
150	2	191	0.00	2	207	0.16	2	255	0.00	3	64	0.16
300	2	95	0.00	2	103	0.16	2	127	0.00	2	129	0.16
600	1	191	0.00	1	207	0.16	1	255	0.00	2	64	0.16
1200	1	95	0.00	1	103	0.16	1	127	0.00	1	129	0.16
2400	0	191	0.00	0	207	0.16	0	255	0.00	0	64	0.16
4800	0	95	0.00	0	103	0.16	0	127	0.00	0	129	0.16
9600	0	47	0.00	0	51	0.16	0	63	0.00	0	64	0.16
19200	0	23	0.00	0	25	0.16	0	31	0.00	0	32	-1.36
31250	0	14	-1.70	0	15	0.00	0	19	-1.70	0	19	0.00
38400	0	11	0.00	0	12	0.16	0	15	0.00	0	15	1.73

Bit Rate (Bit/s)	P ₀ (MHz)											
	24			24.576			28.7			30		
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	3	106	-0.44	3	108	0.08	3	126	0.31	3	132	0.13
150	3	77	0.16	3	79	0.00	3	92	0.46	3	97	-0.35
300	2	155	0.16	2	159	0.00	2	186	-0.08	2	194	0.16
600	2	77	0.16	2	79	0.00	2	92	0.46	2	97	-0.35
1200	1	155	0.16	1	159	0.00	1	186	-0.08	1	194	0.16
2400	1	77	0.16	1	79	0.00	1	92	0.46	1	97	-0.35
4800	0	155	0.16	0	159	0.00	0	186	-0.08	0	194	-1.36
9600	0	77	0.16	0	79	0.00	0	92	0.46	0	97	-0.35
19200	0	38	0.16	0	39	0.00	0	46	-0.61	0	48	-0.35
31250	0	23	0.00	0	24	-1.70	0	28	-1.03	0	29	0.00
38400	0	19	-2.34	0	19	0.00	0	22	1.55	0	23	1.73

Table 14.5 Bit Rates and SCBRR Settings in Synchronous Mode

Bit Rate (Bit/s)	P ₀ (MHz)									
	4		8		16		28.7		30	
	n	N	n	N	n	N	n	N	n	N
110	—	—	—	—	—	—	—	—	—	—
250	2	249	3	124	3	249	—	—	—	—
500	2	124	2	249	3	124	3	223	3	233
1k	1	249	2	124	2	249	3	111	3	116
2.5k	1	99	1	199	2	99	2	178	2	187
5k	0	199	1	99	1	199	2	89	2	93
10k	0	99	0	199	1	99	1	178	1	187
25k	0	39	0	79	0	159	1	71	1	74
50k	0	19	0	39	0	79	0	143	0	149
100k	0	9	0	19	0	39	0	71	0	74
250k	0	3	0	7	0	15	—	—	0	29
500k	0	1	0	3	0	7	—	—	0	14
1M	0	0*	0	1	0	3	—	—	—	—
2M	—	—	0*	0	0	1	—	—	—	—

Note: Settings with an error of 1% or less are recommended.

Legend

Blank: No setting possible

—: Setting possible, but error occurs

*: Continuous transmit/receive operation not possible

Table 14.6 shows the maximum bit rates in asynchronous mode when the baud rate generator is being used. Tables 14.7 and 14.8 list the maximum rates for external clock input.

Table 14.6 Maximum Bit Rates for Various Frequencies with Baud Rate Generator (Asynchronous Mode)

P ₀ (MHz)	Maximum Bit Rate (Bit/s)	Settings	
		n	N
2	62500	0	0
2.097152	65536	0	0
2.4576	76800	0	0
3	93750	0	0
3.6864	115200	0	0
4	125000	0	0
4.9152	153600	0	0
8	250000	0	0
9.8304	307200	0	0
12	375000	0	0
14.7456	460800	0	0
16	500000	0	0
19.6608	614400	0	0
20	625000	0	0
24	750000	0	0
24.576	768000	0	0
28.7	896875	0	0
30	937500	0	0

Table 14.7 Maximum Bit Rates during External Clock Input (Asynchronous Mode)

P_φ (MHz)	External Input Clock (MHz)	Maximum Bit Rate (Bit/s)
2	0.5000	31250
2.097152	0.5243	32768
2.4576	0.6144	38400
3	0.7500	46875
3.6864	0.9216	57600
4	1.0000	62500
4.9152	1.2288	76800
8	2.0000	125000
9.8304	2.4576	153600
12	3.0000	187500
14.7456	3.6864	230400
16	4.0000	250000
19.6608	4.9152	307200
20	5.0000	312500
24	6.0000	375000
24.576	6.1440	384000
28.7	7.1750	448436
30	7.5000	468750

Table 14.8 Maximum Bit Rates during External Clock Input (Synchronous Mode)

P_φ (MHz)	External Input Clock (MHz)	Maximum Bit Rate (Bit/s)
8	1.3333	1333333.3
16	2.6667	2666666.7
24	4.0000	4000000.0
28.7	4.7833	4783333.3
30	5.0000	5000000.0

14.3 Operation

14.3.1 Overview

For serial communication, the SCI has an asynchronous mode in which characters are synchronized individually, and a synchronous mode in which communication is synchronized with clock pulses. Asynchronous/synchronous mode and the transmission format are selected in the serial mode register (SCSMR), as shown in table 14.9. The SCI clock source is selected by the combination of the C/\bar{A} bit in the serial mode register (SCSMR) and the CKE1 and CKE0 bits in the serial control register (SCSCR), as shown in table 14.10.

Asynchronous Mode:

- Data length is selectable: seven or eight bits.
- Parity and multiprocessor bits are selectable, as is the stop bit length (one or two bits). The combination of the preceding selections constitutes the communication format and character length.
- In receiving, it is possible to detect framing errors (FER), parity errors (PER), overrun errors (ORER) and breaks.
- An internal or external clock can be selected as the SCI clock source.
 - When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and can output a serial clock signal with a frequency matching the bit rate.
 - When an external clock is selected, the external clock input must have a frequency 16 times the bit rate. (The on-chip baud rate generator is not used.)

Synchronous Mode:

- The transmission/reception format has a fixed eight-bit data length.
- In receiving, it is possible to detect overrun errors (ORER).
- An internal or external clock can be selected as the SCI clock source.
 - When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and outputs a serial clock to external devices.
 - When an external clock is selected, the SCI operates on the input serial clock. The on-chip baud rate generator is not used.

Table 14.9 Serial Mode Register Settings and SCI Communication Formats

Mode	SCSMR Settings					SCI Communication Format			
	Bit 7 C/A	Bit 6 CHR	Bit 5 PE	Bit 2 MP	Bit 3 STOP	Data Length	Parity Bit	Multipro- cessor Bit	Stop Bit Length
Asynchronous	0	0	0	0	0	8-bit	Not used	Not used	1 bit
					1				2 bits
			1	0	0	7-bit	Not used	1 bit	
					1			2 bits	
	1	0	1	0	0	7-bit	Not used	Not used	1 bit
					1				2 bits
			1	1	0	7-bit	Used	1 bit	
					1			2 bits	
Asynchronous (multiprocessor format)	0	*	1	0	8-bit	Not used	Used	1 bit	
				1				2 bits	
			1	*	0	7-bit	Not used	1 bit	
					1			2 bits	
Synchronous	1	*	*	*	8-bit	Not used	Not used	None	
				*				None	

Note: Asterisks (*) indicate don't-care bits.

Table 14.10 SCSMR and SCSCR Settings and SCI Clock Source Selection

Mode	SCSMR	SCSCR Settings		SCI Transmit/Receive Clock	
	Bit 7 C/A	Bit 1 CKE1	Bit 0 CKE0	Clock Source	SCK Pin Function
Asynchronous mode	0	0	0	Internal	SCI does not use the SCK pin
			1		Outputs a clock with frequency matching the bit rate
		1	0	External	Inputs a clock with frequency 16 times the bit rate
			1		
Synchronous mode	1	0	0	Internal	Outputs the serial clock
			1		
		1	0	External	Inputs the serial clock
			1		

14.3.2 Operation in Asynchronous Mode

In asynchronous mode, each transmitted or received character begins with a start bit and ends with a stop bit. Serial communication is synchronized one character at a time.

The transmitting and receiving sections of the SCI are independent, so full-duplex communication is possible. The transmitter and receiver are both double-buffered, so data can be written and read while transmitting and receiving are in progress, enabling continuous transmitting and receiving.

Figure 14.2 shows the general format of asynchronous serial communication. In asynchronous serial communication, the communication line is normally held in the mark (high) state. The SCI monitors the line and starts serial communication when the line goes to the space (low) state, indicating a start bit. One serial character consists of a start bit (low), data (LSB first), parity bit (high or low), and stop bit (high), in that order.

When receiving in asynchronous mode, the SCI synchronizes on the falling edge of the start bit. The SCI samples each data bit on the eighth pulse of a clock with a frequency 16 times the bit rate. Receive data is latched at the center of each bit.

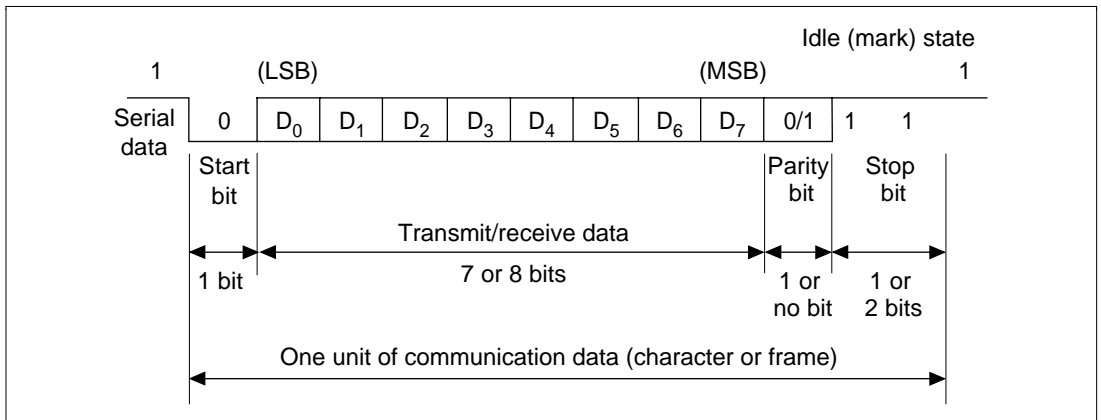


Figure 14.2 Data Format in Asynchronous Communication (Example: 8-Bit Data with Parity and 2 Stop Bits)

Transmit/Receive Formats: Table 14.11 lists the 12 communication formats that can be selected in asynchronous mode. The format is selected by settings in the serial mode register (SCSMR).

Table 14.11 Serial Communication Formats (Asynchronous Mode)

SCSMR Bits				Serial Transmit/Receive Format and Frame Length												
CHR	PE	MP	STOP	1	2	3	4	5	6	7	8	9	10	11	12	
0	0	0	0	S	8-bit data								STOP			
0	0	0	1	S	8-bit data								STOP	STOP		
0	1	0	0	S	8-bit data								P	STOP		
0	1	0	1	S	8-bit data								P	STOP	STOP	
1	0	0	0	S	7-bit data							STOP				
1	0	0	1	S	7-bit data							STOP	STOP			
1	1	0	0	S	7-bit data							P	STOP			
1	1	0	1	S	7-bit data							P	STOP	STOP		
0	—	1	0	S	8-bit data								MPB	STOP		
0	—	1	1	S	8-bit data								MPB	STOP	STOP	
1	—	1	0	S	7-bit data							MPB	STOP			
1	—	1	1	S	7-bit data							MPB	STOP	STOP		

Legend

- : Don't care bits
- S: Start bit
- STOP: Stop bit
- P: Parity bit
- MPB: Multiprocessor bit

Clock: An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected as the SCI transmit/receive clock. The clock source is selected by the C/\bar{A} bit in the serial mode register (SCSMR) and bits CKE1 and CKE0 in the serial control register (SCSCR) (table 14.10).

When an external clock is input at the SCK pin, it must have a frequency equal to 16 times the desired bit rate.

When the SCI operates on an internal clock, it can output a clock signal at the SCK pin. The frequency of this output clock is equal to the bit rate. The phase is aligned as shown in figure 14.3 so that the rising edge of the clock occurs at the center of each transmit data bit.

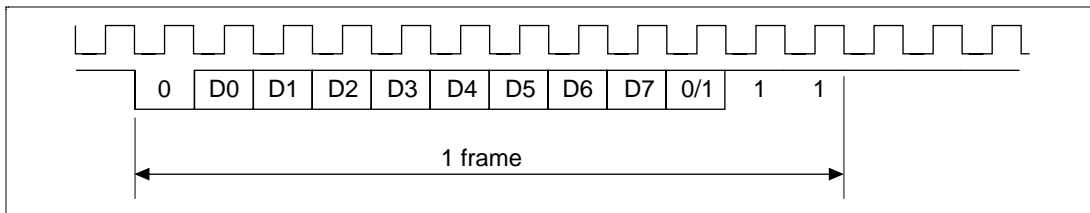


Figure 14.3 Output Clock and Serial Data Timing (Asynchronous Mode)

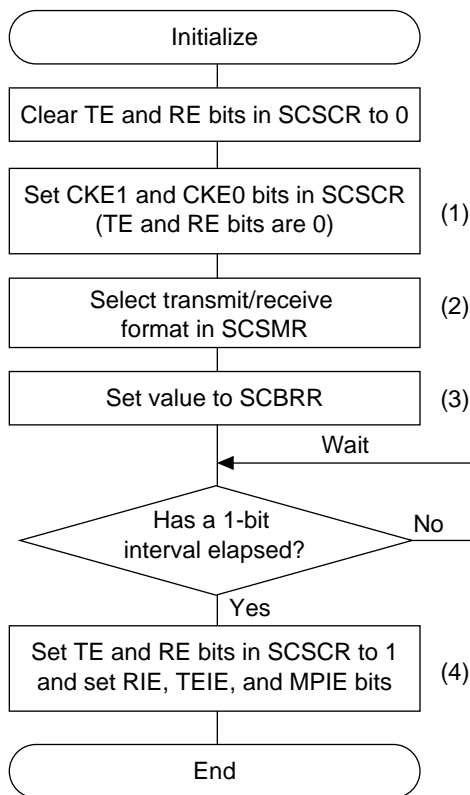
Transmitting and Receiving Data (SCI Initialization (Asynchronous Mode)): Before transmitting or receiving, clear the TE and RE bits to 0 in the serial control register (SCSCR), then initialize the SCI as follows.

When changing the operation mode or communication format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 sets TDRE to 1 and initializes the transmit shift register (SCTSR). Clearing RE to 0, however, does not initialize the RDRF, PER, FER, and ORER flags or receive data register (SCRDR), which retain their previous contents.

When an external clock is used, the clock should not be stopped during initialization or subsequent operation. SCI operation becomes unreliable if the clock is stopped.

Figure 14.4 is a sample flowchart for initializing the SCI. The procedure for initializing the SCI is:

1. Select the clock source in the serial control register (SCSCR). Leave RIE, TIE, TEIE, MPIE, TE, and RE cleared to 0. If clock output is selected in asynchronous mode, clock output starts immediately after the setting is made in SCSCR.
2. Select the communication format in the serial mode register (SCSMR).
3. Write the value corresponding to the bit rate in the bit rate register (SCBRR) unless an external clock is used.
4. Wait for at least the interval required to transmit or receive one bit, then set TE or RE in the serial control register (SCSCR) to 1. Also set RIE, TIE, TEIE, and MPIE as necessary. Setting TE or RE enables the SCI to use the TxD or RxD pin. The initial states are the mark transmit state, and the idle receive state (waiting for a start bit).

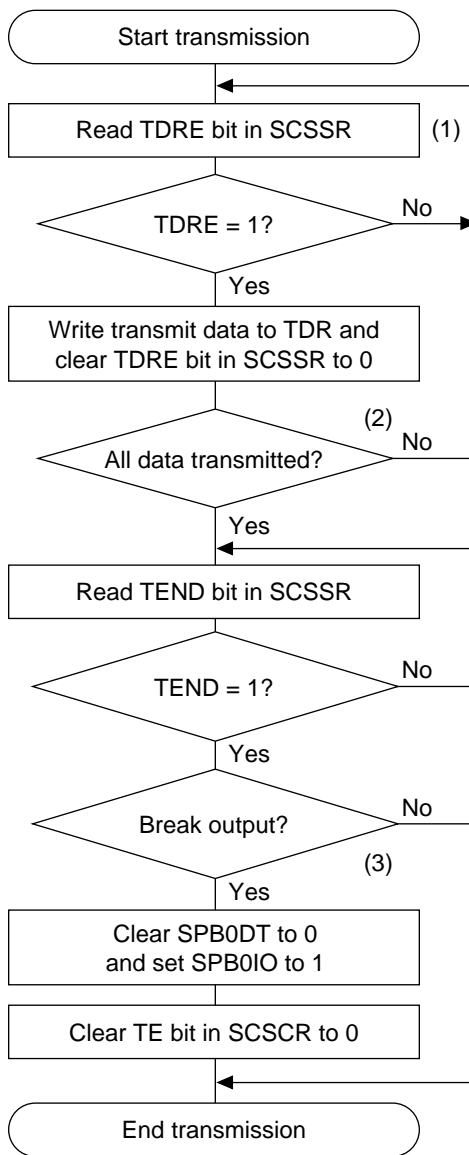


Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.4 Sample Flowchart for SCI Initialization

Transmitting Serial Data (Asynchronous Mode): Figure 14.5 shows a sample flowchart for transmitting serial data. The procedure for transmitting serial data is:

1. SCI status check and transmit data write: Read the serial status register (SCSSR), check that the TDRE bit is 1, then write transmit data in the transmit data register (SCTDR) and clear TDRE to 0.
2. To continue transmitting serial data: Read the TDRE bit to check whether it is safe to write (if it reads 1); if so, write data in SCTDR, then clear TDRE to 0.
3. To output a break at the end of serial transmission: Clear the SPB0DT bit in the SCSPTR, set the SPB0IO bit to 1 and then clear the TE bit to 0 in SCSCR.



Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.5 Sample Flowchart for Transmitting Serial Data

In transmitting serial data, the SCI operates as follows:

1. The SCI monitors the TDRE bit in SCSSR. When TDRE is cleared to 0, the SCI recognizes that the transmit data register (SCTDR) contains new data, and loads this data from SCTDR into the transmit shift register (SCTSR).
2. After loading the data from SCTDR into SCTSR, the SCI sets the TDRE bit to 1 and starts transmitting. If the transmit-data-empty interrupt enable bit (TIE) is set to 1 in SCSCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time. Serial transmit data is transmitted in the following order from the TxD pin:
 - a. Start bit: One 0 bit is output.
 - b. Transmit data: Seven or eight bits of data are output, LSB first.
 - c. Parity bit or multiprocessor bit: One parity bit (even or odd parity) or one multiprocessor bit is output. Formats in which neither a parity bit nor a multiprocessor bit is output can also be selected.
 - d. Stop bit: One or two 1 bits (stop bits) are output.
 - e. Marking: Output of 1 bits continues until the start bit of the next transmit data.
3. The SCI checks the TDRE bit when it outputs the stop bit. If TDRE is 0, the SCI loads new data from SCTDR into SCTSR, outputs the stop bit, then begins serial transmission of the next frame. If TDRE is 1, the SCI sets the TEND bit to 1 in SCSSR, outputs the stop bit, then continues output of 1 bits (marking). If the transmit-end interrupt enable bit (TEIE) in SCSCR is set to 1, a transmit-end interrupt (TEI) is requested.

Figure 14.6 shows an example of SCI transmit operation in asynchronous mode.

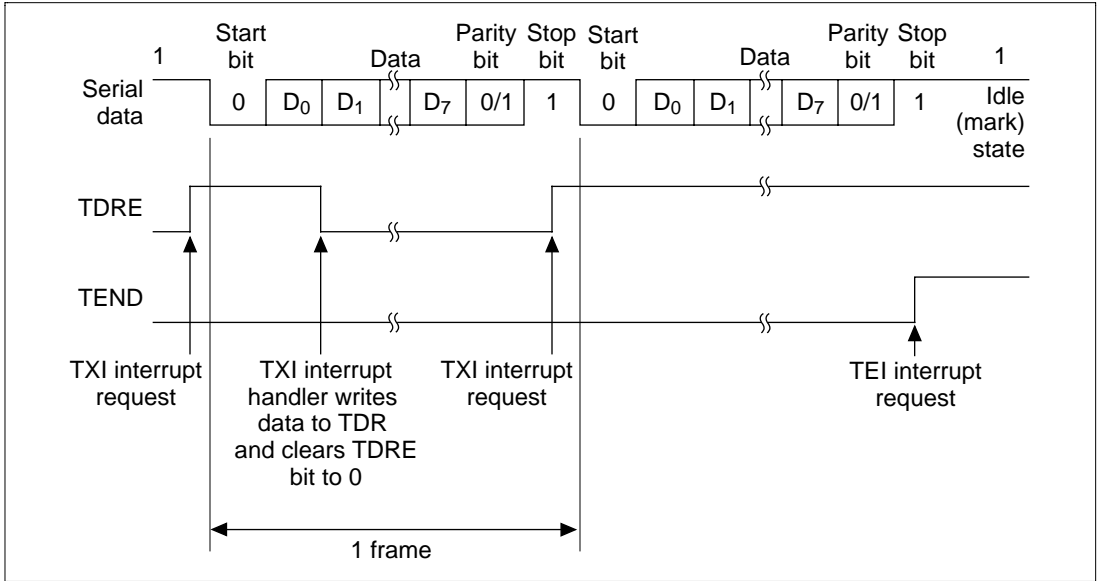
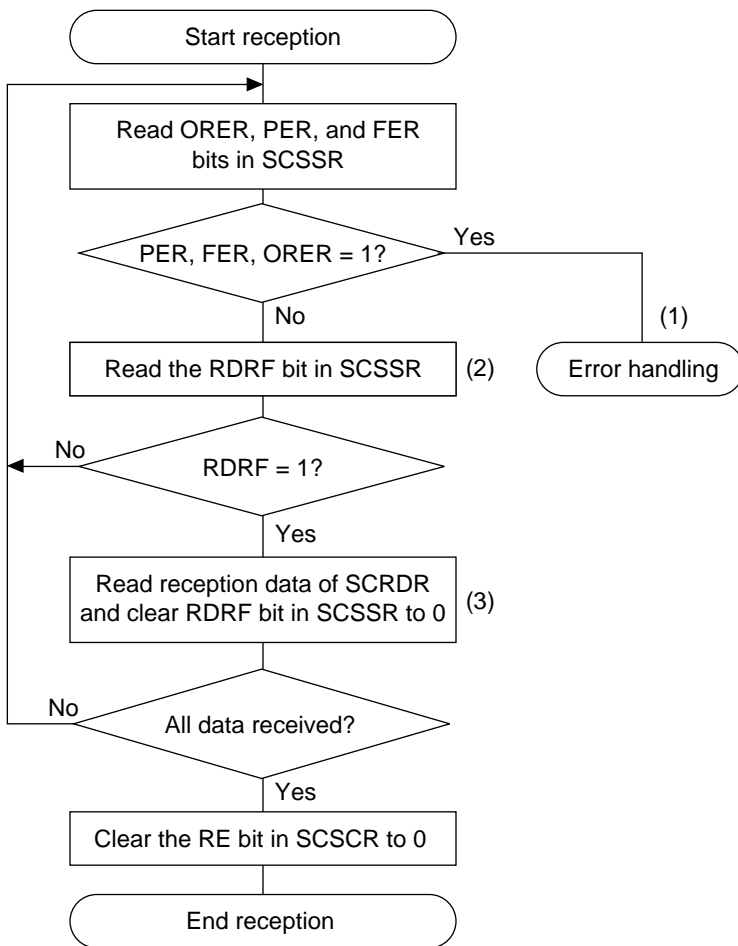


Figure 14.6 SCI Transmit Operation in Asynchronous Mode (Example: 8-Bit Data with Parity and One Stop Bit)

Receiving Serial Data (Asynchronous Mode): Figure 14.7 and 14.8 shows a sample flowchart for receiving serial data. The procedure for receiving serial data after enabling the SCI for reception is:

1. Receive error handling and break detection: If a receive error occurs, read the ORER, PER and FER bits in SCSSR to identify the error. After executing the necessary error handling, clear ORER, PER and FER all to 0. Receiving cannot resume if ORER, PER or FER remain set to 1. When a framing error occurs, the RxD pin can be read to detect the break state.
2. SCI status check and receive-data read: Read the serial status register (SCSSR), check that RDRF is set to 1, then read receive data from the receive data register (SCRDR) and clear RDRF to 0. The RXI interrupt can also be used to determine if the RDRF bit has changed from 0 to 1.
3. To continue receiving serial data: Read the RDRF and SCRDR bits and clear RDRF to 0 before the stop bit of the current frame is received.



Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.7 Sample Flowchart for Receiving Serial Data

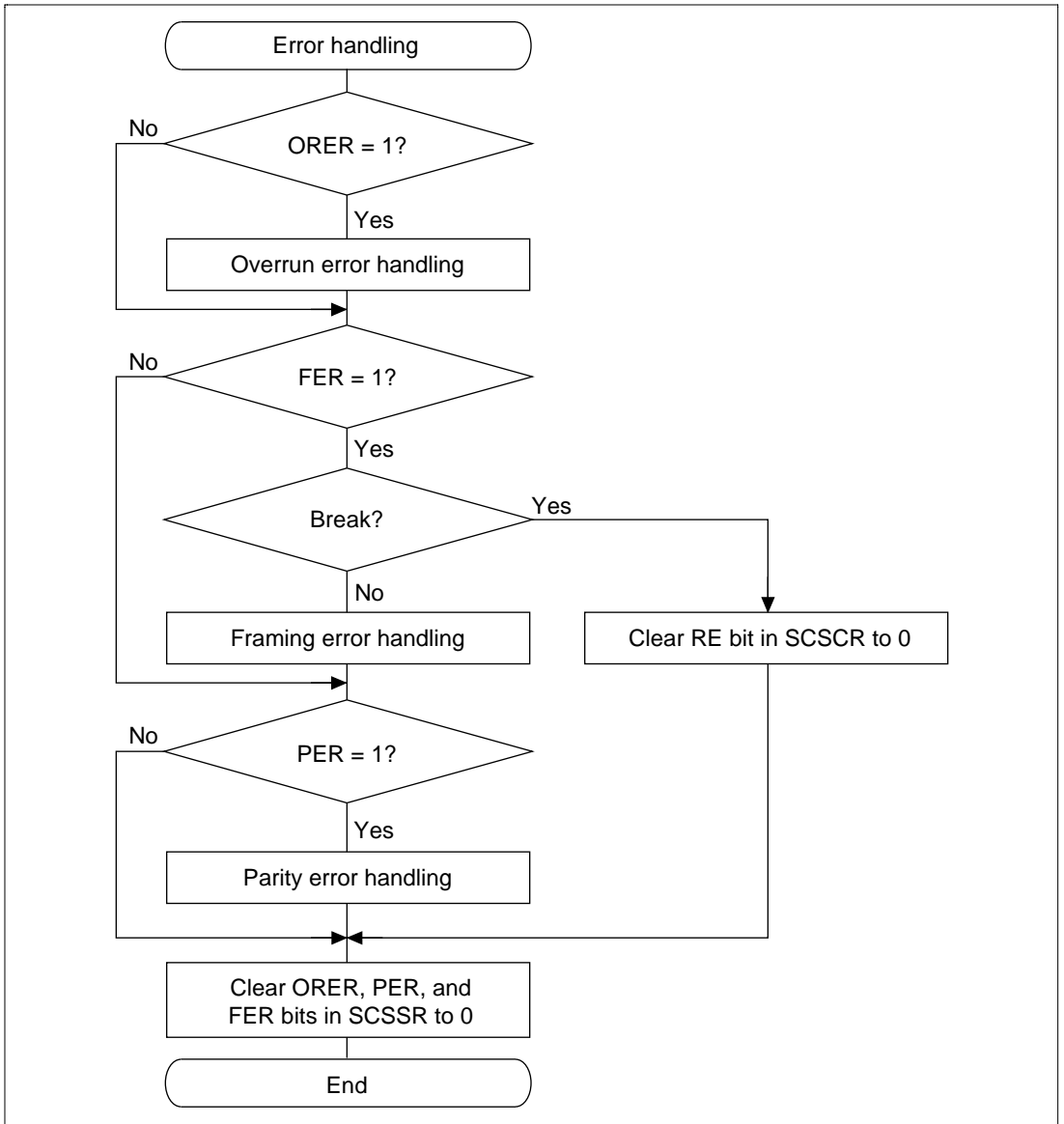


Figure 14.8 Sample Flowchart for Receiving Serial Data (cont)

In receiving, the SCI operates as follows:

1. The SCI monitors the communication line. When it detects a start bit (0), the SCI synchronizes internally and starts receiving.
2. Receive data is shifted into SCRSR in order from the LSB to the MSB.
3. The parity bit and stop bit are received. After receiving these bits, the SCI makes the following checks:
 - a. Parity check: The number of 1s in the receive data must match the even or odd parity setting of the O/ \bar{E} bit in SCSMR.
 - b. Stop bit check: The stop bit value must be 1. If there are two stop bits, only the first stop bit is checked.
 - c. Status check: RDRF must be 0 so that receive data can be loaded from SCRSR into SCRDR.

If these checks all pass, the SCI sets RDRF to 1 and stores the received data in SCRDR. If one of the checks fails (receive error), the SCI operates as indicated in table 14.12.

Note: When a receive error flag is set, further receiving is disabled. The RDRF bit is not set to 1. Be sure to clear the error flags.
4. After setting RDRF to 1, if the receive-data-full interrupt enable bit (RIE) is set to 1 in SCSCR, the SCI requests a receive-data-full interrupt (RXI). If one of the error flags (ORER, PER, or FER) is set to 1 and the receive-data-full interrupt enable bit (RIE) in SCSCR is also set to 1, the SCI requests a receive-error interrupt (ERI).

Table 14.12 Receive Error Conditions and SCI Operation

Receive Error	Abbreviation	Condition	Data Transfer
Overrun error	ORER	Receiving of next data ends while RDRF is still set to 1 in SCSSR	Receive data not loaded from SCRSR into SCRDR
Framing error	FER	Stop bit is 0	Receive data loaded from SCRSR into SCRDR
Parity error	PER	Parity of receive data differs from even/odd parity setting in SCSMR	Receive data loaded from SCRSR into SCRDR

Figure 14.9 shows an example of SCI receive operation in asynchronous mode.

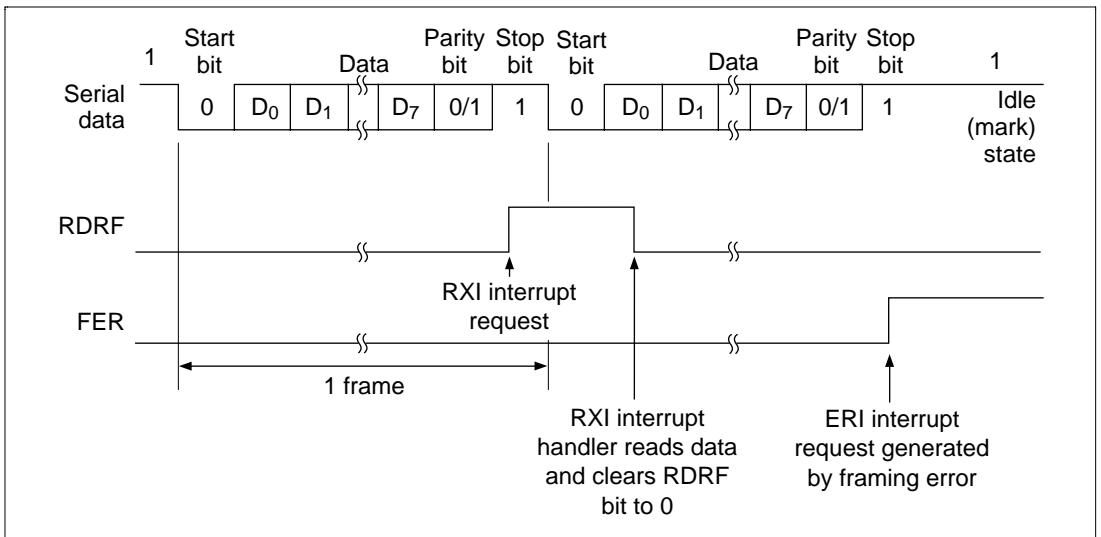


Figure 14.9 SCI Receive Operation (Example: 8-bit Data with Parity and One Stop Bit)

14.3.3 Multiprocessor Communication

The multiprocessor communication function enables several processors to share a single serial communication line. The processors communicate in asynchronous mode using a format with an additional multiprocessor bit (multiprocessor format).

In multiprocessor communication, each receiving processor is addressed by a unique ID. A serial communication cycle consists of an ID-sending cycle that identifies the receiving processor, and a data-sending cycle. The multiprocessor bit distinguishes ID-sending cycles from data-sending cycles. The transmitting processor starts by sending the ID of the receiving processor with which it wants to communicate as data with the multiprocessor bit set to 1. Next the transmitting processor sends transmit data with the multiprocessor bit cleared to 0.

Receiving processors skip incoming data until they receive data with the multiprocessor bit set to 1. When they receive data with the multiprocessor bit set to 1, receiving processors compare the data with their IDs. The receiving processor with a matching ID continues to receive further incoming data. Processors with IDs not matching the received data skip further incoming data until they again receive data with the multiprocessor bit set to 1. Multiple processors can send and receive data in this way.

Figure 14.10 shows an example of communication among processors using the multiprocessor format.

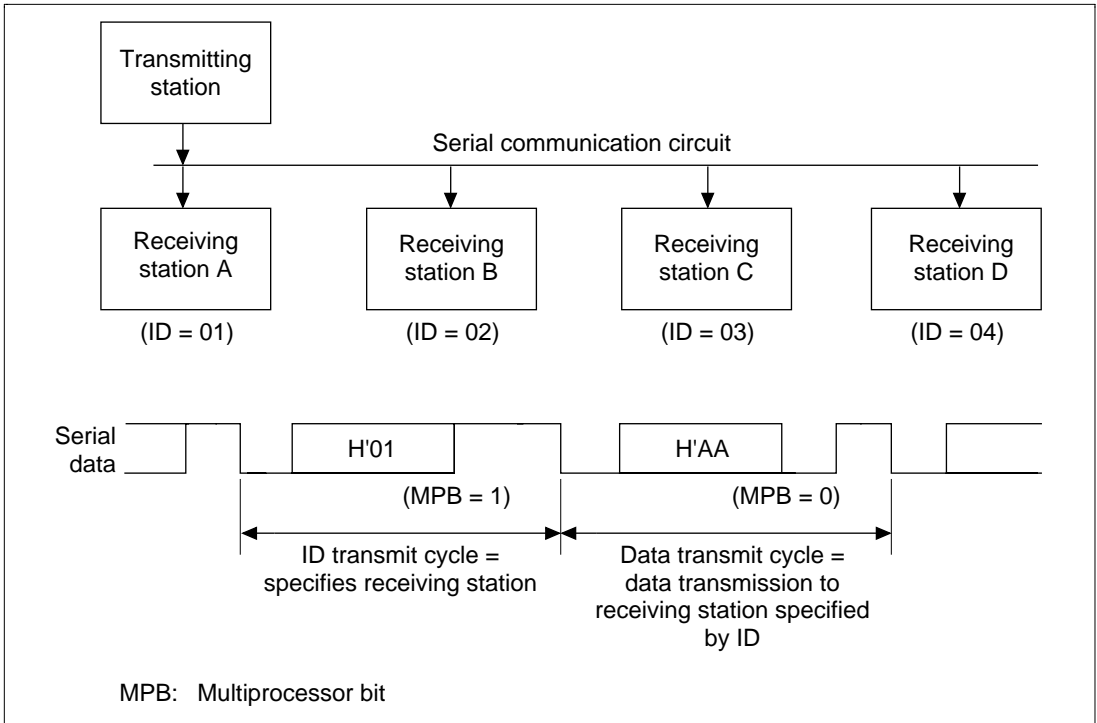


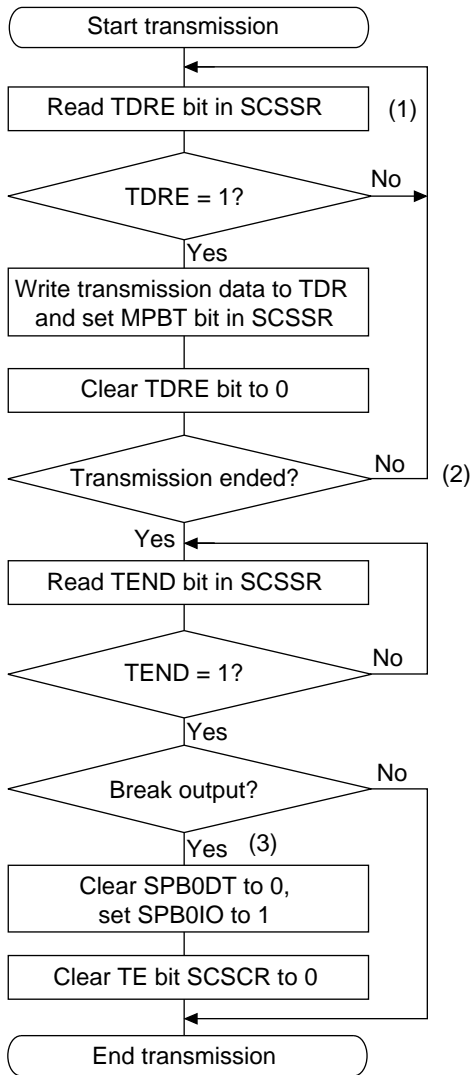
Figure 14.10 Communication Among Processors Using Multiprocessor Format (Example: Sending Data H'AA to Receiving Processor A)

Communication Formats: Four formats are available. Parity-bit settings are ignored when the multiprocessor format is selected. For details see table 14.11.

Clock: See the description in the asynchronous mode section.

Transmitting Multiprocessor Serial Data: Figure 14.11 shows a sample flowchart for transmitting multiprocessor serial data. The procedure for transmitting multiprocessor serial data is:

1. SCI status check and transmit data write: Read the serial status register (SCSSR), check that the TDRE bit is 1, then write transmit data in the transmit data register (SCTDR). Also set MPBT (multiprocessor bit transfer) to 0 or 1 in SCSSR. Finally, clear TDRE to 0.
2. To continue transmitting serial data: Read the TDRE bit to check whether it is safe to write (if it reads 1); if so, write data in SCTDR, then clear TDRE to 0.
3. To output a break at the end of serial transmission: Set the SPB0DT bit in the SCSPTR register to 0, set SPB0IO to 1, then clear TE to 0 in SCSCR.



Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.11 Sample Flowchart for Transmitting Multiprocessor Serial Data

In transmitting serial data, the SCI operates as follows:

1. The SCI monitors the TDRE bit in SCSSR. When TDRE is cleared to 0 the SCI recognizes that the transmit data register (SCTDR) contains new data, and loads this data from SCTDR into the transmit shift register (SCTSR).
2. After loading the data from SCTDR into SCTSR, the SCI sets the TDRE bit to 1 and starts transmitting. If the transmit-data-empty interrupt enable bit (TIE) in the SCSCR is set to 1, the SCI requests a transmit-data-empty interrupt (TXI) at this time. Serial transmit data is transmitted in the following order from the TxD pin:
 - a. Start bit: One 0 bit is output.
 - b. Transmit data: Seven or eight bits are output, LSB first.
 - c. Multiprocessor bit: One multiprocessor bit (MPBT value) is output.
 - d. Stop bit: One or two 1 bits (stop bits) are output.
 - e. Marking: Output of 1 bits continues until the start bit of the next transmit data.
3. The SCI checks the TDRE bit when it outputs the stop bit. If TDRE is 0, the SCI loads data from SCTDR into SCTSR, outputs the stop bit, then begins serial transmission of the next frame. If TDRE is 1, the SCI sets the TEND bit in SCSSR to 1, outputs the stop bit, then continues output of 1 bits in the mark state. If the transmit-end interrupt enable bit (TEIE) in the SCSCR is set to 1, a transmit-end interrupt (TEI) is requested at this time.

Figure 14.12 shows SCI transmission with the multiprocessor format.

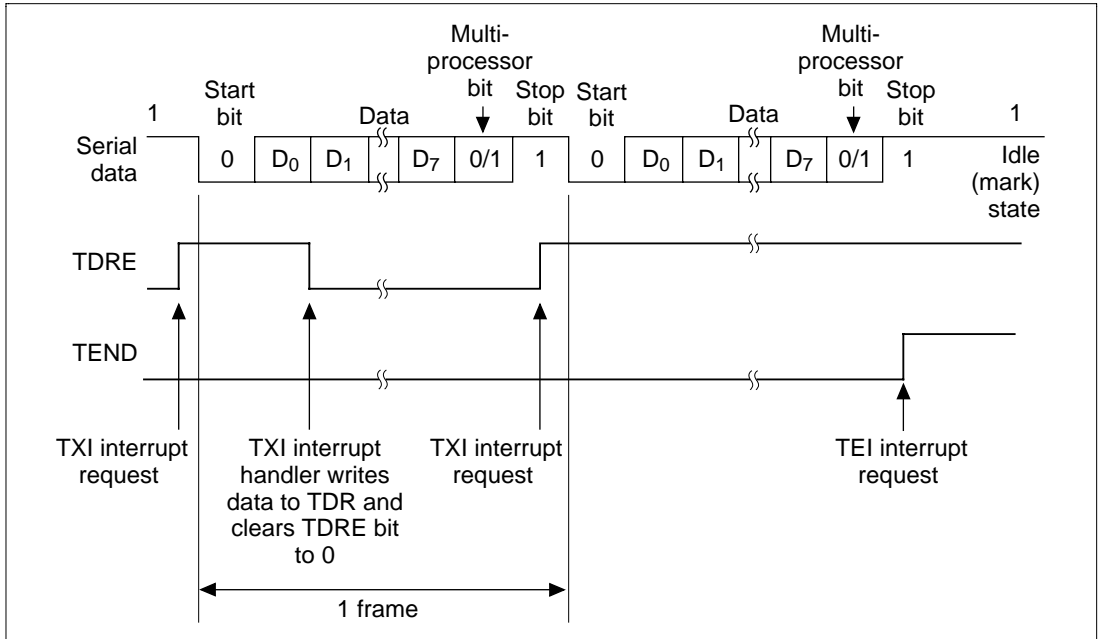
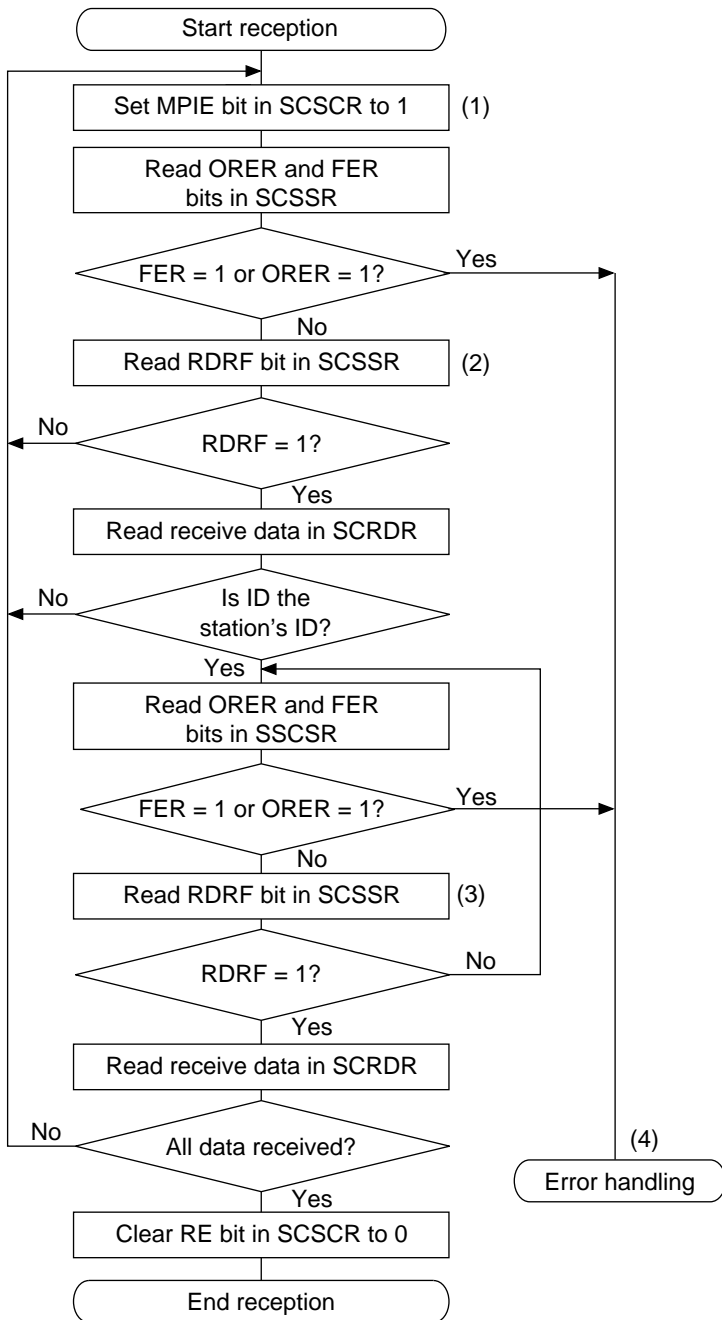


Figure 14.12 SCI Multiprocessor Transmit Operation (Example: 8-Bit Data with Multiprocessor Bit and One Stop Bit)

Receiving Multiprocessor Serial Data: Figure 14.13 shows a sample flowchart for receiving multiprocessor serial data. The procedure for receiving multiprocessor serial data is:

1. ID receive cycle: Set the MPIE bit in the serial control register (SCSCR) to 1.
2. SCI status check and compare to ID reception: Read the serial status register (SCSSR), check that RDRF is set to 1, then read data from the receive data register (SCRDR) and compare with the processor's own ID. If the ID does not match the receive data, set MPIE to 1 again and clear RDRF to 0. If the ID matches the receive data, clear RDRF to 0.
3. SCI status check and data receiving: Read SCSSR, check that RDRF is set to 1, then read data from the receive data register (SCRDR).
4. Receive error handling and break detection: If a receive error occurs, read the ORER and FER bits in SCSSR to identify the error. After executing the necessary error handling, clear both ORER and FER to 0. Receiving cannot resume if ORER or FER remain set to 1. When a framing error occurs, the RxD pin can be read to detect the break state.



Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.13 Sample Flowchart for Receiving Multiprocessor Serial Data

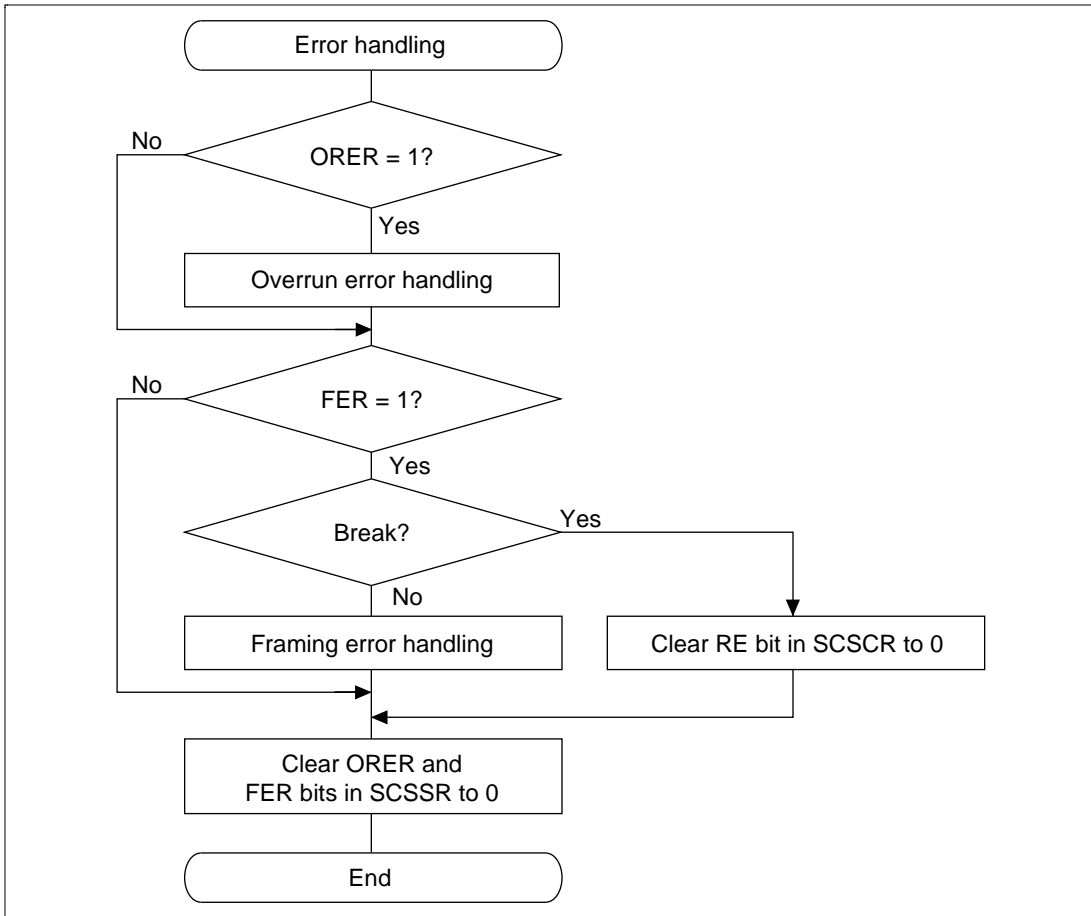


Figure 14.14 Sample Flowchart for Receiving Multiprocessor Serial Data (cont)

Figures 14.15 and 14.16 show examples of SCI receive operation using a multiprocessor format.

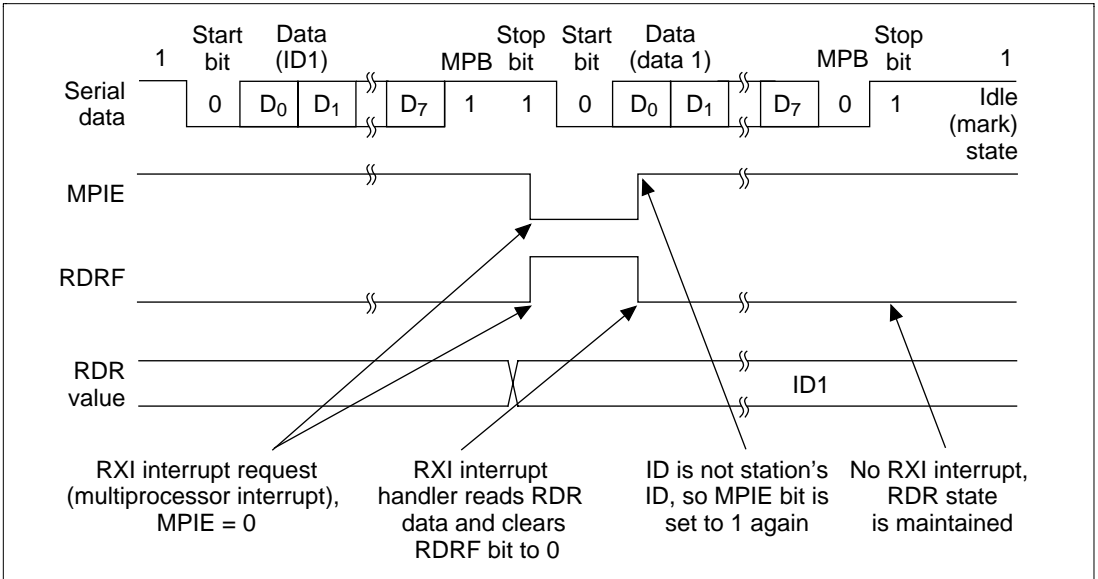


Figure 14.15 Example of SCI Receive Operation: Own ID Does Not Match Data (8-Bit Data with Multiprocessor Bit and One Stop Bit)

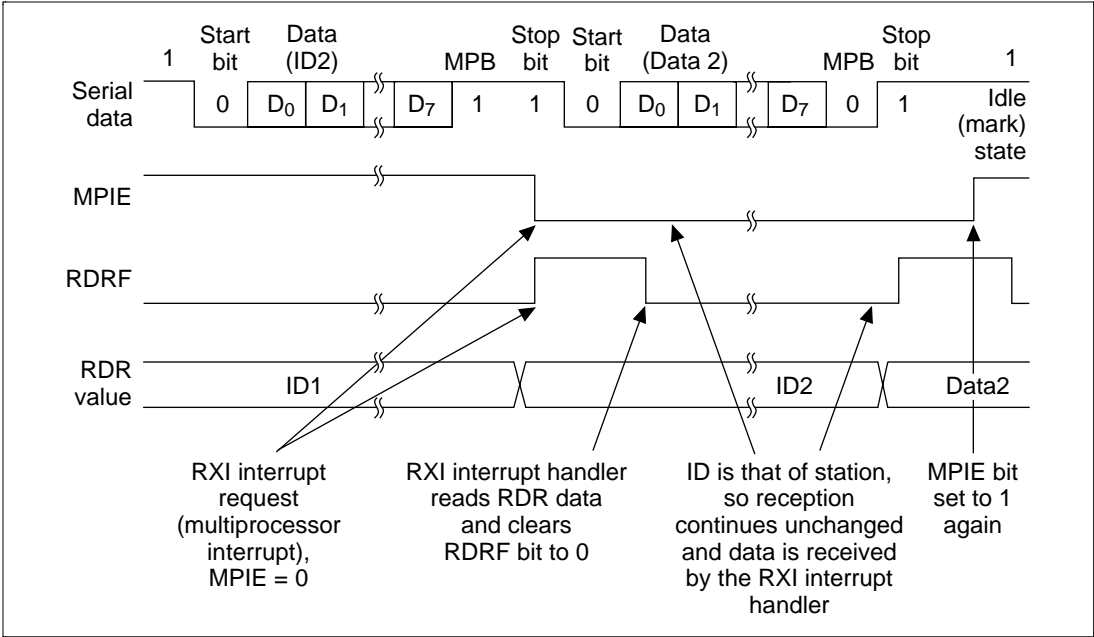


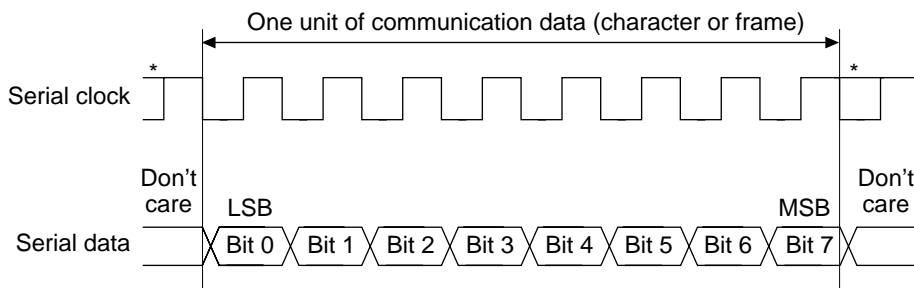
Figure 14.16 Example of SCI Receive Operation: Own ID Matches Data (8-Bit Data with Multiprocessor Bit and One Stop Bit)

14.3.4 Synchronous Operation

In synchronous mode, the SCI transmits and receives data in synchronization with clock pulses. This mode is suitable for high-speed serial communication.

The SCI transmitter and receiver are independent, so full-duplex communication is possible while sharing the same clock. The transmitter and receiver are also double-buffered, so continuous transmitting or receiving is possible by reading or writing data while transmitting or receiving is in progress.

Figure 14.17 shows the general format in synchronous serial communication.



Note: High except in continuous transmitting or receiving

Figure 14.17 Data Format in Synchronous Communication

In synchronous serial communication, each data bit is output on the communication line from one falling edge of the serial clock to the next. Data is guaranteed valid at the rising edge of the serial clock. In each character, the serial data bits are transmitted in order from the LSB (first) to the MSB (last). After output of the MSB, the communication line remains in the state of the MSB. In synchronous mode, the SCI transmits or receives data by synchronizing with the falling edge of the serial clock.

Communication Format: The data length is fixed at eight bits. No parity bit or multiprocessor bit can be added.

Clock: An internal clock generated by the on-chip baud rate generator or an external clock input from the $\overline{\text{SCK}}$ pin can be selected as the SCI transmit/receive clock. The clock source is selected by the $\overline{\text{C/A}}$ bit in the serial mode register (SCSMR) and bits CKE1 and CKE0 in the serial control register (SCSCR). See table 14.10.

When the SCI operates on an internal clock, it outputs the clock signal at the SCK pin. Eight clock pulses are output per transmitted or received character. When the SCI is not transmitting or receiving, the clock signal remains in the high state. When only receiving, the SCI receives in 2-character units, so a 16 pulse synchronization clock is output. To receive in 1-character units, select an external clock source.

Transmitting and Receiving Data: SCI Initialization (synchronous mode). Before transmitting, receiving, or changing the mode or communication format, the software must clear the TE and RE bits to 0 in the serial control register (SCSCR), then initialize the SCI. Clearing TE to 0 sets TDRE to 1 and initializes the transmit shift register (SCTSR). Clearing RE to 0, however, does not initialize the RDRF, PER, FER, and ORER flags and receive data register (SCRDR), which retain their previous contents.

Figure 14.18 is a sample flowchart for initializing the SCI. The procedure for initializing the SCI is:

1. Select the clock source in the serial control register (SCSCR). Leave RIE, TIE, TEIE, MPIE, TE and RE cleared to 0.
2. Select the communication format in the serial mode register (SCSMR).
3. Write the value corresponding to the bit rate in the bit rate register (SCBRR) unless an external clock is used.
4. Wait for at least the interval required to transmit or receive one bit, then set TE or RE in the serial control register (SCSCR) to 1. Also set RIE, TIE, TEIE and MPIE. Setting TE and RE allows use of the TxD and RxD pins.

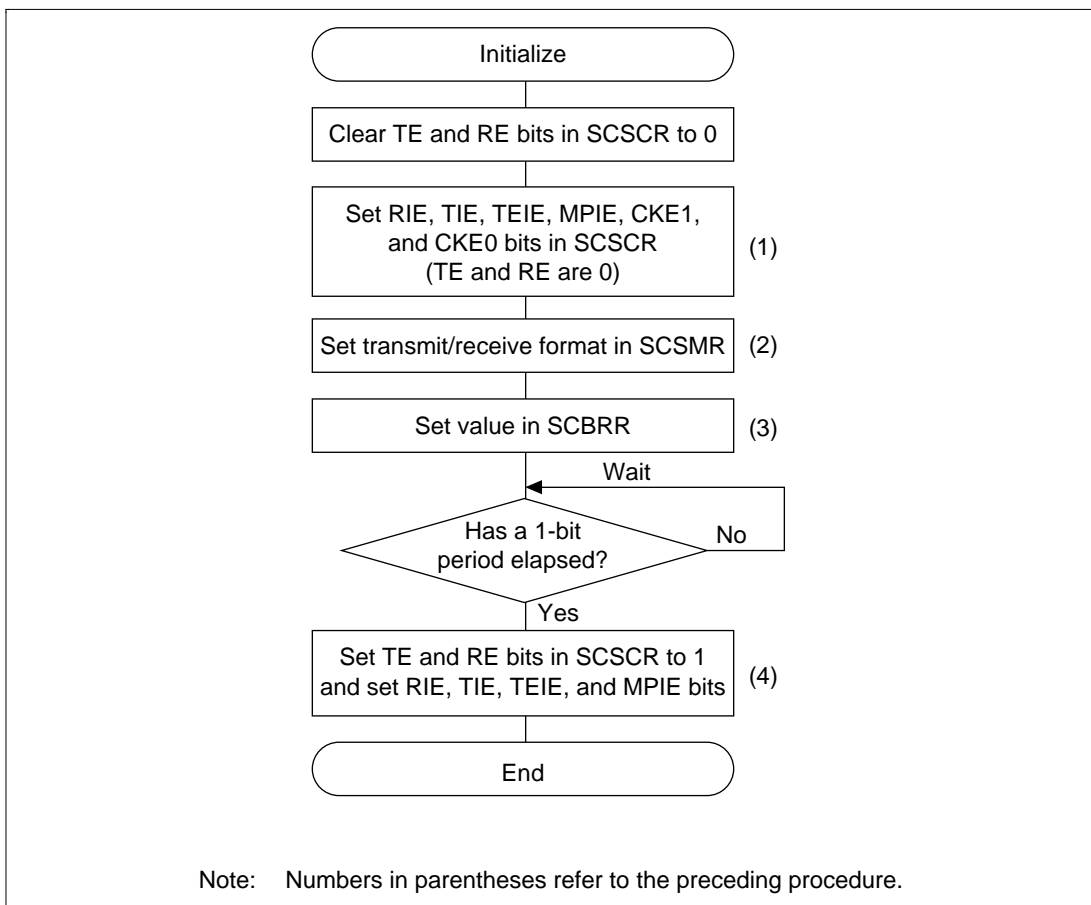
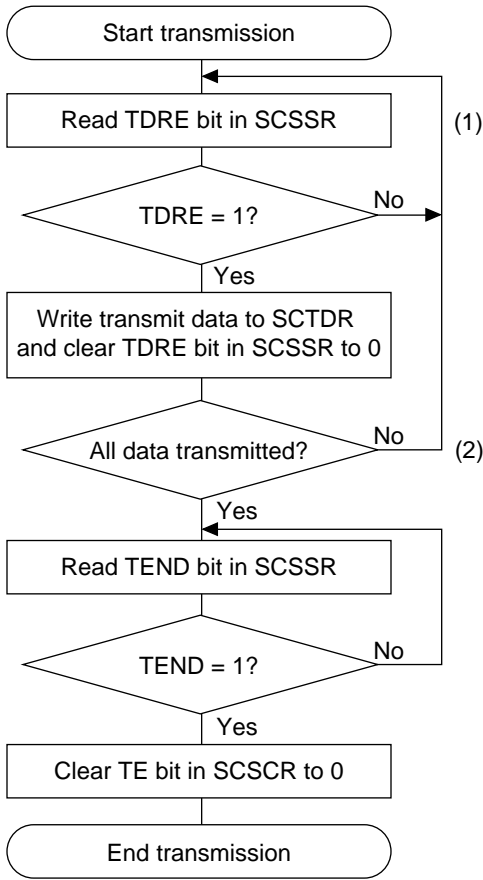


Figure 14.18 Sample Flowchart for SCI Initialization

Transmitting Serial Data (Synchronous Mode): Figure 14.19 shows a sample flowchart for transmitting serial data. The procedure for transmitting serial data is:

1. SCI status check and transmit data write: Read the serial status register (SCSSR), check that the TDRE bit is 1, then write transmit data in the transmit data register (SCTDR) and clear TDRE to 0.
2. To continue transmitting serial data: Read the TDRE bit to check whether it is safe to write (if it reads 1); if so, write data in SCTDR, then clear TDRE to 0.



Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.19 Sample Flowchart for Serial Transmitting

In transmitting serial data, the SCI operates as follows:

1. The SCI monitors the TDRE bit in SCSSR. When TDRE is cleared to 0 the SCI recognizes that the transmit data register (SCTDR) contains new data and loads this data from SCTDR into the transmit shift register (SCTSR).
2. After loading the data from SCTDR into SCTSR, the SCI sets the TDRE bit to 1 and starts transmitting. If the transmit-data-empty interrupt enable bit (TIE) in SCSCR is set to 1, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

If clock output mode is selected, the SCI outputs eight synchronous clock pulses. If an external clock source is selected, the SCI outputs data in synchronization with the input clock. Data is output from the TxD pin in order from the LSB (bit 0) to the MSB (bit 7).

3. The SCI checks the TDRE bit when it outputs the MSB (bit 7). If TDRE is 0, the SCI loads data from SCTDR into SCTSR, then begins serial transmission of the next frame. If TDRE is 1, the SCI sets the TEND bit in SCSSR to 1, transmits the MSB, then holds the transmit data pin (TxD) in the MSB state. If the transmit-end interrupt enable bit (TEIE) in the SCSCR is set to 1, a transmit-end interrupt (TEI) is requested at this time.
4. After the end of serial transmission, the SCK pin is held in the high state.

Figure 14.20 shows an example of SCI transmit operation.

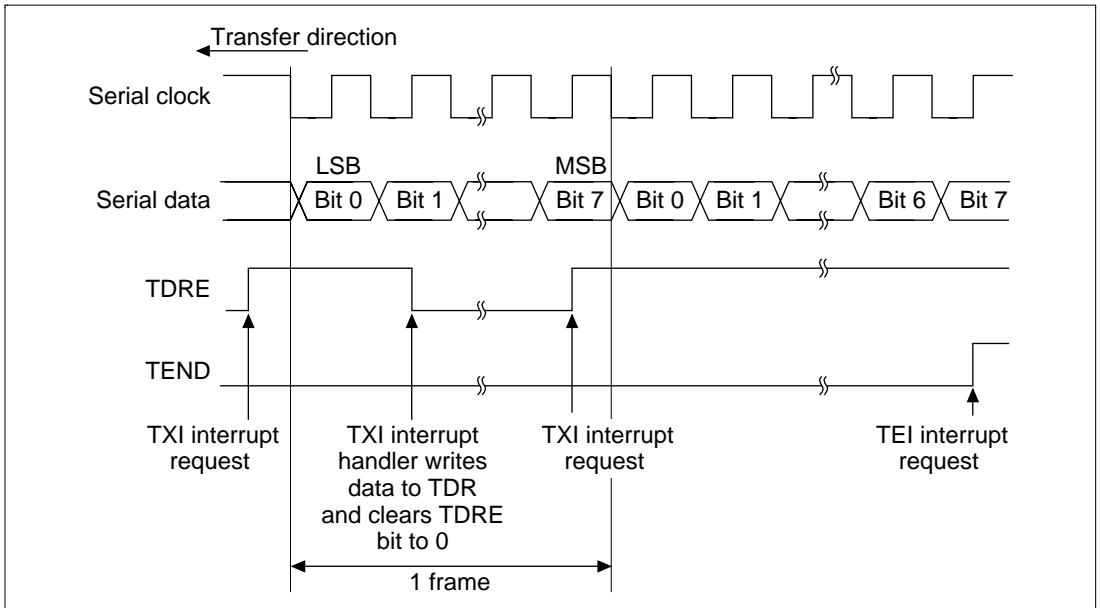
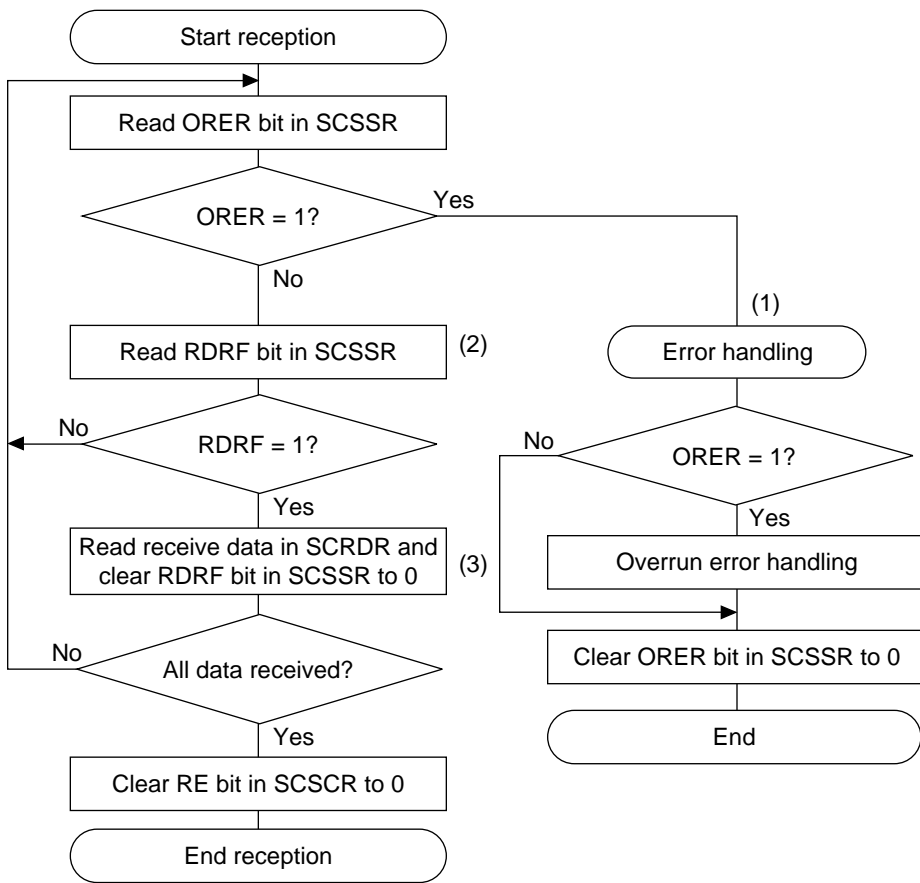


Figure 14.20 Example of SCI Transmit Operation

Receiving Serial Data (Synchronous Mode): Figure 14.21 shows a sample flowchart for receiving serial data. When switching from asynchronous mode to synchronous mode, make sure that ORER, PER, and FER are cleared to 0. If PER or FER is set to 1, the RDRF bit will not be set and both transmitting and receiving will be disabled.

The procedure for receiving serial data is:

1. Receive error handling and break detection: If a receive error occurs, read the ORER bit in SCSSR to identify the error. After executing the necessary error handling, clear ORER to 0. Transmitting/receiving cannot resume if ORER remains set to 1.
2. SCI status check and receive data read: Read the serial status register (SCSSR), check that RDRF is set to 1, then read receive data from the receive data register (SCRDR) and clear RDRF to 0. The RXI interrupt can also be used to determine if the RDRF bit has changed from 0 to 1.
3. To continue receiving serial data: Read SCRDR, and clear RDRF to 0 before the MSB (bit 7) of the current frame is received.



Note: Numbers in parentheses refer to the preceding procedure.

Figure 14.21 Sample Flowchart for Serial Receiving

In receiving, the SCI operates as follows:

1. The SCI synchronizes with serial clock input or output and initializes internally.
2. Receive data is shifted into SCSSR in order from the LSB to the MSB. After receiving the data, the SCI checks that RDRF is 0 so that receive data can be loaded from SCSSR into SCRDR. If this check is passed, the SCI sets RDRF to 1 and stores the received data in SCRDR. If the check is not passed (receive error), the SCI operates as indicated in table 14.12. This state prevents further transmission or reception. While receiving, the RDRF bit is not set to 1. Be sure to clear the error flag.
3. After setting RDRF to 1, if the receive-data-full interrupt enable bit (RIE) is set to 1 in SCSCR, the SCI requests a receive-data-full interrupt (RXI). If the ORER bit is set to 1 and the receive-data-full interrupt enable bit (RIE) in SCSCR is also set to 1, the SCI requests a receive-error interrupt (ERI).

Figure 14.22 shows an example of the SCI receive operation.

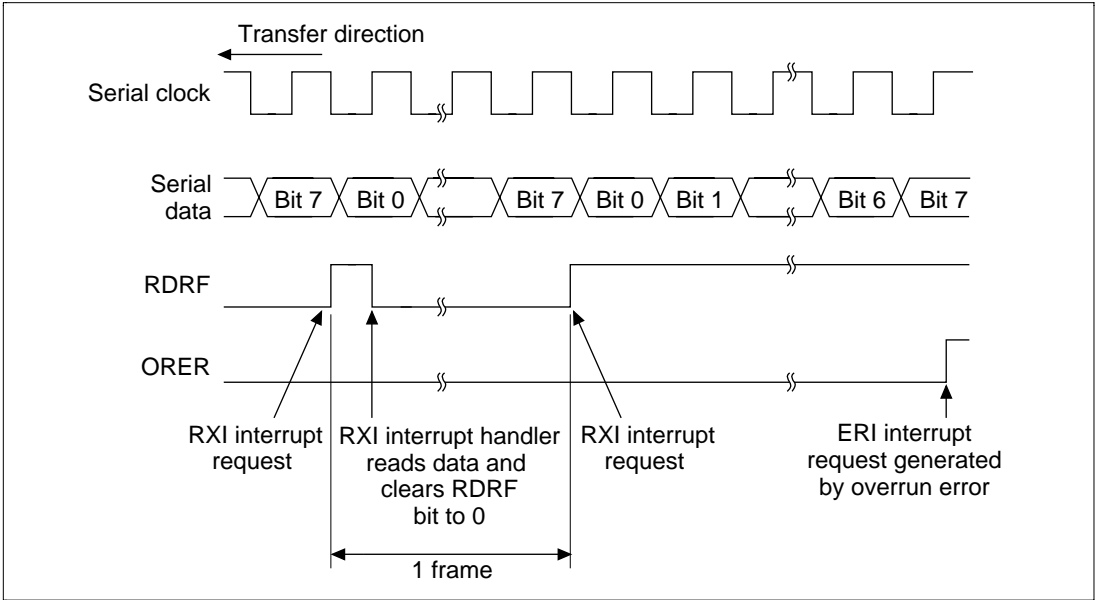
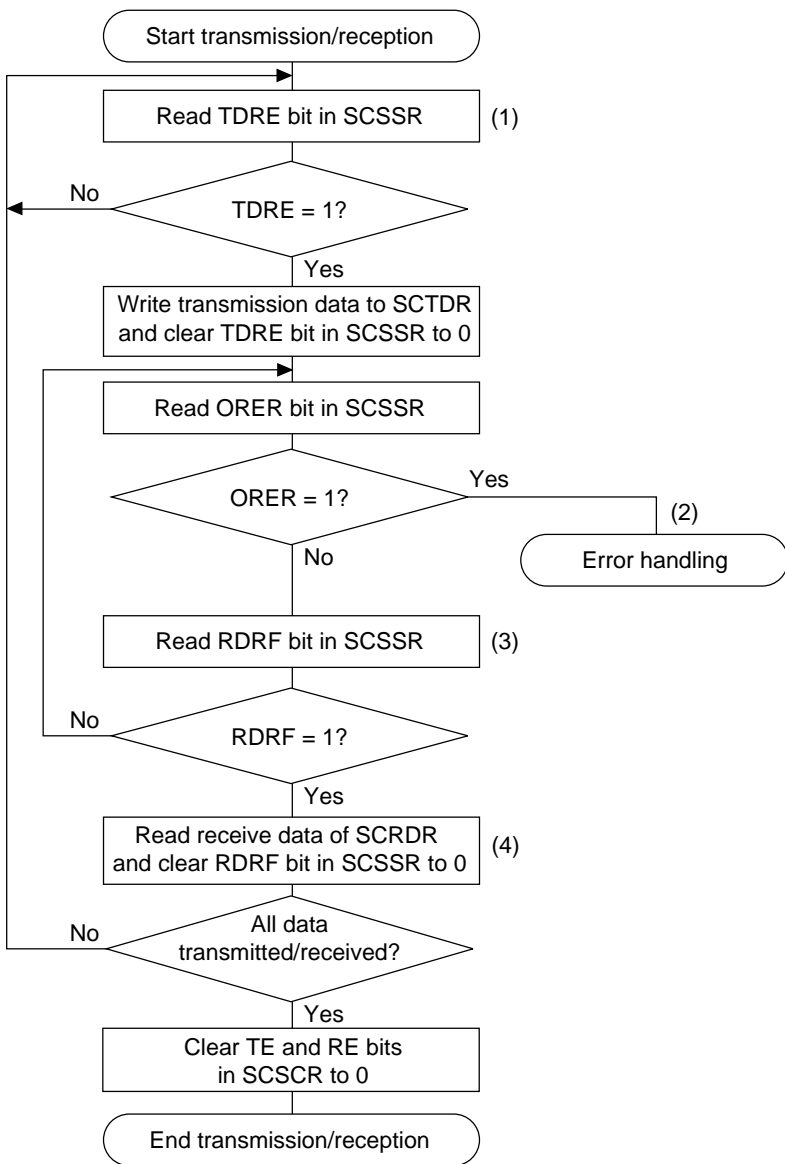


Figure 14.22 Example of SCI Receive Operation

Transmitting and Receiving Serial Data Simultaneously (Synchronous Mode): Figure 14.20 shows a sample flowchart for transmitting and receiving serial data simultaneously. The procedure for setting the SCI to transmit and receive serial data simultaneously is:

1. SCI status check and transmit data write: Read the serial status register (SCSSR), check that the TDRE bit is 1, then write transmit data in the transmit data register (SCTDR) and clear TDRE to 0. The TXI interrupt can also be used to determine if the TDRE bit has changed from 0 to 1.
2. Receive error handling: If a receive error occurs, read the ORER bit in SCSSR to identify the error. After executing the necessary error handling, clear ORER to 0. Transmitting/receiving cannot resume if ORER remains set to 1.
3. SCI status check and receive data read: Read the serial status register (SCSSR), check that RDRF is set to 1, then read receive data from the receive data register (SCRDR) and clear RDRF to 0. The RXI interrupt can also be used to determine if the RDRF bit has changed from 0 to 1.
4. To continue transmitting and receiving serial data: Read the RDRF bit and SCRDR, and clear RDRF to 0 before the MSB (bit 7) of the current frame is received. Also read the TDRE bit to check whether it is safe to write (if it reads 1); if so, write data in SCTDR, then clear TDRE to 0 before the MSB (bit 7) of the current frame is transmitted.



- Notes: 1. When switching from transmitting or receiving to simultaneous transmitting and receiving, simultaneously clear TE and RE to 0, then simultaneously set TE and RE to 1.
 2. Numbers in parentheses refer to the preceding procedure.

Figure 14.23 Sample Flowchart for Serial Transmitting

14.4 SCI Interrupt Sources

The SCI has four interrupt sources in each channel: transmit-end (TEI), receive-error (ERI), receive-data-full (RXI), and transmit-data-empty (TXI). Table 14.13 lists the interrupt sources and indicates their priority. These interrupts can be enabled and disabled by the TIE, RIE, and TEIE bits in the serial control register (SCSCR). Each interrupt request is sent separately to the interrupt controller.

TXI is requested when the TDRE bit in SCSSR is set to 1. TDRE is automatically cleared to 0 when data is written in the transmit data register (SCTDR).

RXI is requested when the RDRF bit in SCSSR is set to 1. RDRF is automatically cleared to 0 when the receive data register (SCRDR) is read.

ERI is requested when the ORER, PER, or FER bit in SCSSR is set to 1.

TEI is requested when the TEND bit in SCSSR is set to 1. Where the TXI interrupt indicates that transmit data writing is enabled, the TEI interrupt indicates that the transmit operation is complete.

Table 14.13 SCI Interrupt Sources

Interrupt Source	Description	Priority When Reset Is Cleared
ERI	Receive error (ORER, PER, or FER)	High
RXI	Receive data full (RDRF)	
TXI	Transmit data empty (TDRE)	↑
TEI	Transmit end (TEND)	Low

See section 4, Exception Handling, for information on the priority order and relationship to non-SCI interrupts.

14.5 Usage Notes

Note the following points when using the SCI.

SCTDR Write and TDRE Flags: The TDRE bit in the serial status register (SCSSR) is a status flag indicating loading of transmit data from SCTDR into SCTSR. The SCI sets TDRE to 1 when it transfers data from SCTDR to SCTSR. Data can be written to SCTDR regardless of the TDRE bit status. If new data is written in SCTDR when TDRE is 0, however, the old data stored in SCTDR will be lost because the data has not yet been transferred to SCTSR. Before writing transmit data to SCTDR, be sure to check that TDRE is set to 1.

Simultaneous Multiple Receive Errors: Table 14.14 shows the state of the SCSSR status flags when multiple receive errors occur simultaneously. When an overrun error occurs, the SCRSR contents cannot be transferred to SCRDR, so receive data is lost.

Table 14.14 SCSSR Status Flags and Transfer of Receive Data

Receive Error Status	SCSSR Status Flags				Receive Data Transfer
	RDRF	ORER	FER	PER	SCRSR → SCRDR
Overrun error	1	1	0	0	X
Framing error	0	0	1	0	O
Parity error	0	0	0	1	O
Overrun error + framing error	1	1	1	0	X
Overrun error + parity error	1	1	0	1	X
Framing error + parity error	0	0	1	1	O
Overrun error + framing error + parity error	1	1	1	1	X

O: Receive data is transferred from SCRSR to SCRDR.

X: Receive data is not transferred from SCRSR to SCRDR.

Break Detection and Processing: Break signals can be detected by reading the RxD pin directly when a framing error (FER) is detected. In the break state, the input from the RxD pin consists of all 0s, so FER is set and the parity error flag (PER) may also be set. In the break state, the SCI receiver continues to operate, so if the FER bit is cleared to 0, it will be set to 1 again.

Sending a Break Signal: The input/output direction and level of the TxD pin can be set using the SPB0IO and SPB0DT bits in the serial port register (SCSPTR). Use these bits to send breaks. After initialization, the pin will not function as a TxD pin until the TE bit is set to 1 (enabling transmission). Through this period, the value of the SPB0DT bit substitutes for the mark state. For this reason, the SPB0IO and SPB0DT bits are initially set to 1 (output, high level). To send a break during serial transmission, clear the SPB0DT bit to 0 (low level), then clear TE to 0 (halting transmission). When the TE bit is cleared to 0, the transmitter is initialized without regard to the current transmission status, and 0 is output from the TxD pin.

Receive Error Flags and Transmitter Operation (Synchronous Mode Only): When a receive error flag (ORER, PER, or FER) is set to 1, the SCI will not start transmitting even if TDRE is set to 1. Be sure to clear the receive error flags to 0 before starting to transmit. Note that clearing RE to 0 does not clear the receive error flags.

Receive Data Sampling Timing and Receive Margin in Asynchronous Mode: In asynchronous mode, the SCI operates on a base clock of 16 times the transfer rate frequency. In receiving, the SCI synchronizes internally with the falling edge of the start bit, which it samples on the base clock. Receive data is latched on the rising edge of the eighth base clock pulse (figure 14.24).

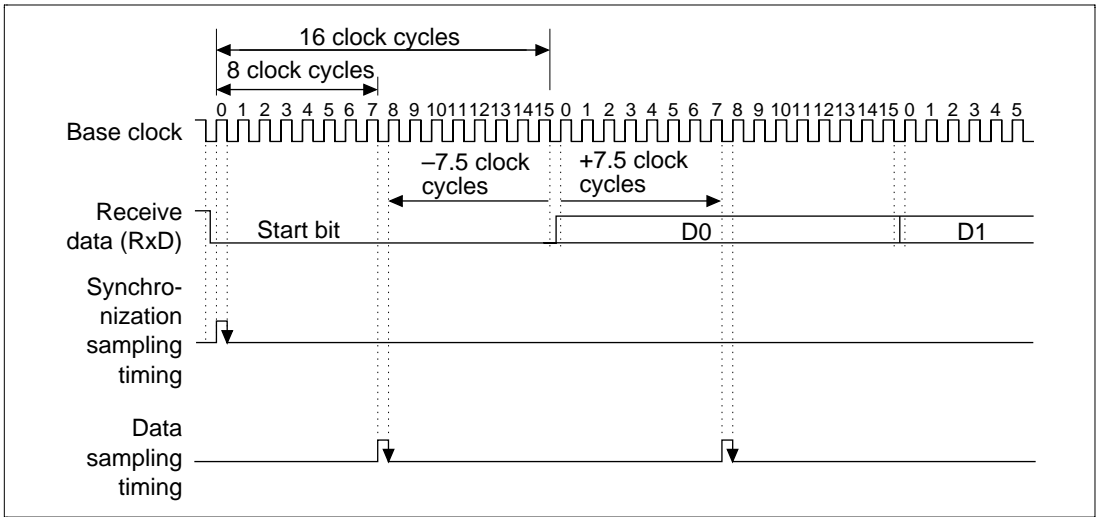


Figure 14.24 Receive Data Sampling Timing in Asynchronous Mode

The receive margin in the asynchronous mode can therefore be expressed as shown in equation 1.

Equation 1:

$$M = \left| \left(0.5 - \frac{1}{2N} \right) - (L - 0.5)F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\%$$

Where:

M = Receive margin (%)

N = Ratio of clock frequency to bit rate (N = 16)

D = Clock duty cycle (D = 0–1.0)

L = Frame length (L = 9–12)

F = Absolute deviation of clock frequency

From equation (1), if F = 0 and D = 0.5, the receive margin is 46.875%, as shown in equation 2.

Equation 2:

$$\begin{aligned} M &= (0.5 - 1/(2 \times 16)) \times 100\% \\ &= 46.875\% \end{aligned}$$

This is a theoretical value. A reasonable margin to allow in system designs is 20–30%.

Cautions on Use of Clock Synchronous External Clock Mode:

- Set TE = RE = 1 only when the external clock SCK is 1.
- Do not set TE = RE = 1 until at least four peripheral operating clock cycles after the external clock SCK has changed from 0 to 1.
- When receiving, RDRF is 1 when RE is set to zero 2.5–3.5 peripheral operating clock cycles after the rising edge of the RxD D7 bit SCK input, but it cannot be copied to SCRDR.

Caution on Use of Clock Synchronous Internal Clock Mode: When receiving, RDRF is 1 when RE is set to zero 1.5 peripheral operating clock cycles after the rising edge of the RxD D7 bit SCK output, but it cannot be copied to SCRDR.

Section 15 Smart Card Interface

15.1 Overview

As an added serial communications interface function, the SCI supports an IC card (smart card) interface that conforms to the ISO/IEC standard 7816-3 for identification of cards. Register settings are used to switch between the ordinary serial communication interface and the smart card interface.

15.1.1 Features

The smart card interface has the following features:

- Asynchronous mode
 - Data length: Eight bits
 - Parity bit generation and check
 - Receive mode error signal detection (parity error)
 - Transmit mode error signal detection and automatic re-transmission of data
 - Supports both direct convention and inverse convention
- Bit rate can be selected using on-chip baud rate generator.
- Three types of interrupts: Transmit-data-empty, receive-data-full, and communication-error interrupts are requested independently.

15.1.2 Block Diagram

Figure 15.1 shows a block diagram of the smart card interface.

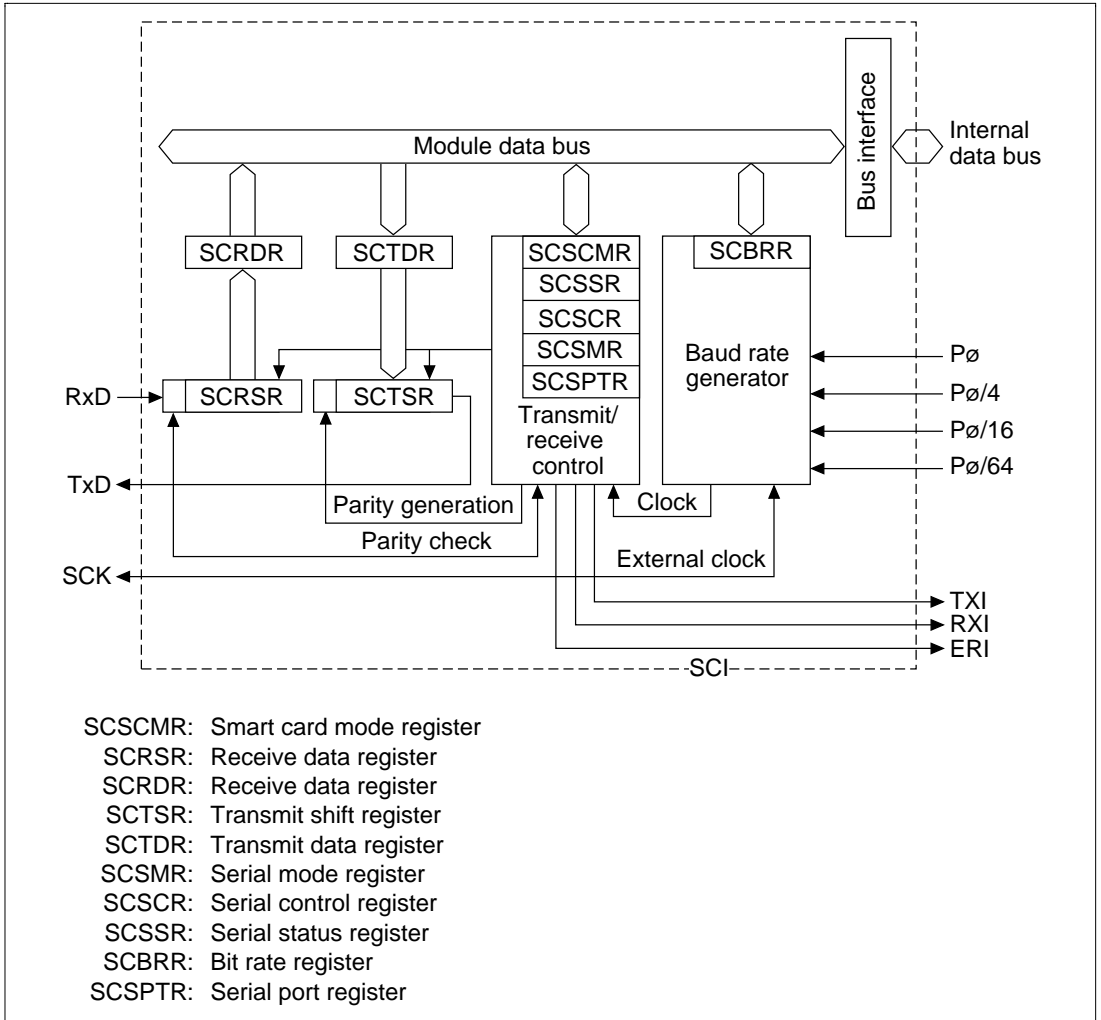


Figure 15.1 Smart Card Interface Block Diagram

15.1.3 Pin Configuration

Table 15.1 summarizes the smart card interface pins.

Table 15.1 SCI Pins

Pin Name	Abbreviation	Input/Output	Function
Serial clock pin	SCK	Output	Clock output
Receive data pin	RxD	Input	Receive data input
Transmit data pin	TxD	Output	Transmit data output

15.1.4 Register Configuration

Table 15.2 summarizes the registers used by the smart card interface. The SCSMR, SCBRR, SCSCR, SCTDR, and SCRDR registers are the same as in the ordinary SCI function. They are described in section 13, Serial Communication Interface.

Table 15.2 Registers

Name	Abbreviation	R/W	Initial Value* ³	Address	Access Size
Serial mode register	SCSMR	R/W	H'00	H'FFFFFFE80	8
Bit rate register	SCBRR	R/W	H'FF	H'FFFFFFE82	8
Serial control register	SCSCR	R/W	H'00	H'FFFFFFE84	8
Transmit data register	SCTDR	R/W	H'FF	H'FFFFFFE86	8
Serial status register	SCSSR	R/(W)* ¹	H'84	H'FFFFFFE88	8
Receive data register	SCRDR	R	H'00	H'FFFFFFE8A	8
Smart card mode register	SCSCMR	R/W	* ²	H'FFFFFFE8C	8

Notes: 1. Only 0 can be written, to clear the flags.

2. Bits 0, 2, and 3 are cleared. The value of the other bits is undefined.

3. Initialized by a power-on or manual reset.

15.2 Register Descriptions

This section describes the registers added for the smart card interface and the bits whose functions are changed.

15.2.1 Smart Card Mode Register (SCSCMR)

The smart card mode register (SCSCMR) is an 8-bit read/write register that selects smart card interface functions. SCSCMR bits 0, 2, and 3 are initialized to 0 by a reset and in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	SDIR	SINV	—	SMIF
Initial value:	*	*	*	*	0	0	*	0
R/W:	R	R	R	R	R/W	R/W	R	R/W

Note: * Undefined

Bits 7 to 4 and 1—Reserved: An undefined value will be returned if these bits are read.

Bit 3—Smart Card Data Transfer Direction (SDIR): Selects the serial/parallel conversion format.

Bit 3: SDIR	Description
0	Contents of SCTDR are transferred LSB first, receive data is stored in SCRDR LSB first. (Initial value)
1	Contents of SCTDR are transferred MSB first, receive data is stored in SCRDR MSB first.

Bit 2—Smart Card Data Inversion (SINV): Specifies whether to invert the logic level of the data. This function is used in combination with bit 3 for transmitting and receiving with an inverse convention card. SINV does not affect the logic level of the parity bit. See section 15.3.4, Register Settings, for information on how parity is set.

Bit 2: SINV	Description
0	Contents of SCTDR are transferred unchanged, receive data is stored in SCRDR unchanged. (Initial value)
1	Contents of SCTDR are inverted before transfer, receive data is inverted before storage in SCRDR.

Bit 0—Smart Card Interface Mode Select (SMIF): Enables the smart card interface function.

Bit 0 : SMIF	Description
0	Smart card interface function disabled (Initial value)
1	Smart card interface function enabled

15.2.2 Serial Status Register (SCSSR)

In the smart card interface mode, the function of SCSSR bit 4 is changed. The setting conditions for bit 2, the TEND bit, are also changed.

Bit:	7	6	5	4	3	2	1	0
Bit name:	TDRE	RDRF	ORER	FER/ERS	PER	TEND	MPB	MPBT
Initial value:	1	0	0	0	0	1	0	0
R/W:	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R	R	R/W

Note: * Only 0 can be written, to clear the flag.

Bits 7 to 5: These bits have the same function as in the ordinary SCI. See section 13, Serial Communication Interface, for more information.

Bit 4—Error Signal Status (ERS): In the smart card interface mode, bit 4 indicates the status of the error signal returned from the receiving side during transmission. The smart card interface cannot detect framing errors.

Bit 4: ERS	Description
0	Receiving ended normally with no error signal. (Initial value) ERS is cleared to 0 when the chip is reset or enters standby mode, or when software reads ERS after it has been set to 1, then writes 0 in ERS.
1	An error signal indicating a parity error was transmitted from the receiving side. ERS is set to 1 if the error signal sampled is low.

Note: The ERS flag maintains its status even when the TE bit in SCSCR is cleared to 0.

Bits 3 to 0: These bits have the same function as in the ordinary SCI. See section 13, Serial Communication Interface, for more information. The setting conditions for bit 2, the transmit end bit (TEND), are changed as follows.

Bit 2: TEND	Description
0	Transmission is in progress. TEND is cleared to 0 when software reads TDRE after it has been set to 1, then writes 0 in TDRE, or when data is written in SCTDR.
1	End of transmission. (Initial value) TEND is set to 1 when: <ul style="list-style-type: none"> • the chip is reset or enters standby mode, • the TE bit in SCSCR is 0 and the FER/ERS bit is also 0, • the C/\bar{A} bit in SCSMR is 0, and TDRE = 1 and FER/ERS = 0 (normal transmission) 2.5 etu after a one-byte serial character is transmitted, or • the C/\bar{A} bit in SCSMR is 1, and TDRE = 1 and FER/ERS = 0 (normal transmission) 1.0 etu after a one-byte serial character is transmitted.

Note: etu is an abbreviation of elementary time unit, which is the period for the transfer of 1 bit.

15.3 Operation

15.3.1 Overview

The primary functions of the smart card interface are described below.

1. Each frame consists of 8 data bits and 1 parity bit.
2. During transmission, the card leaves a guard time of at least 2 etu (elementary time units: the period for 1 bit to transfer) from the end of the parity bit to the start of the next frame.
2. During reception, the card outputs an error signal low level for 1 etu after 10.5 etu has elapsed from the start bit if a parity error was detected.
4. During transmission, it automatically transmits the same data after allowing at least 2 etu from the time the error signal is sampled.
5. Only start-stop type asynchronous communication functions are supported; no synchronous communication functions are available.

15.3.2 Pin Connections

Figure 15.2 shows the pin connection diagram for the smart card interface. During communication with an IC card, transmission and reception are both carried out over the same data transfer line, so connect the TxD and RxD pins on the chip. Pull up the data transfer line to the power supply V_{CC} side with a resistor.

When using the clock generated by the smart card interface on an IC card, input the SCK pin output to the IC card's CLK pin. This connection is not necessary when the internal clock is used on the IC card.

Use the chip's port output as the reset signal. Apart from these pins, the power and ground pin connections are usually also required.

Note: When the IC card is not connected and both RE and TE are set to 1, closed communication is possible and auto-diagnosis can be performed.

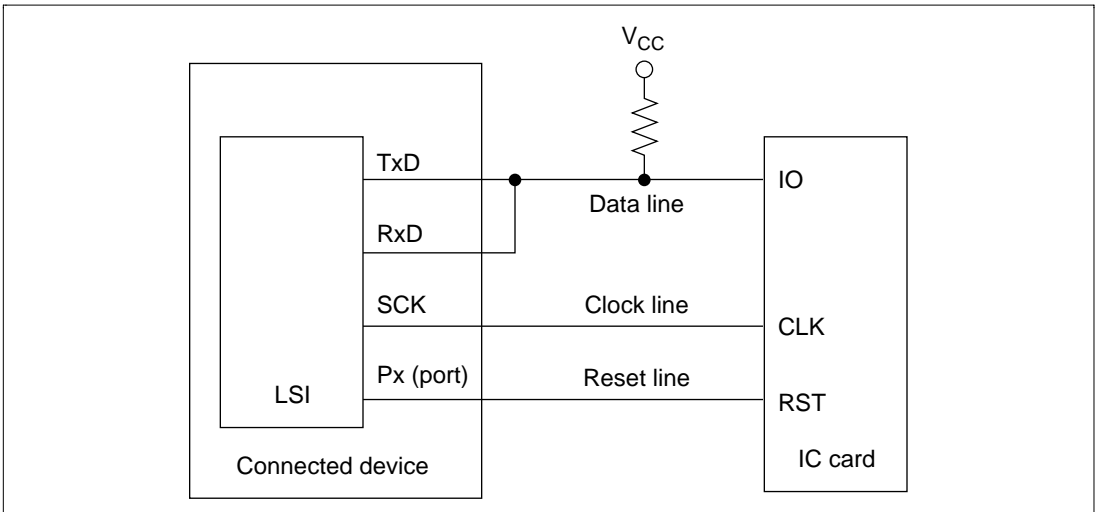


Figure 15.2 Pin Connection Diagram for the Smart Card Interface

15.3.3 Data Format

Figure 15.3 shows the data format for the smart card interface. In this mode, parity is checked every frame while receiving and error signals sent to the transmitting side whenever an error is detected so that data can be re-transmitted. During transmission, error signals are sampled and data re-transmitted whenever an error signal is detected.

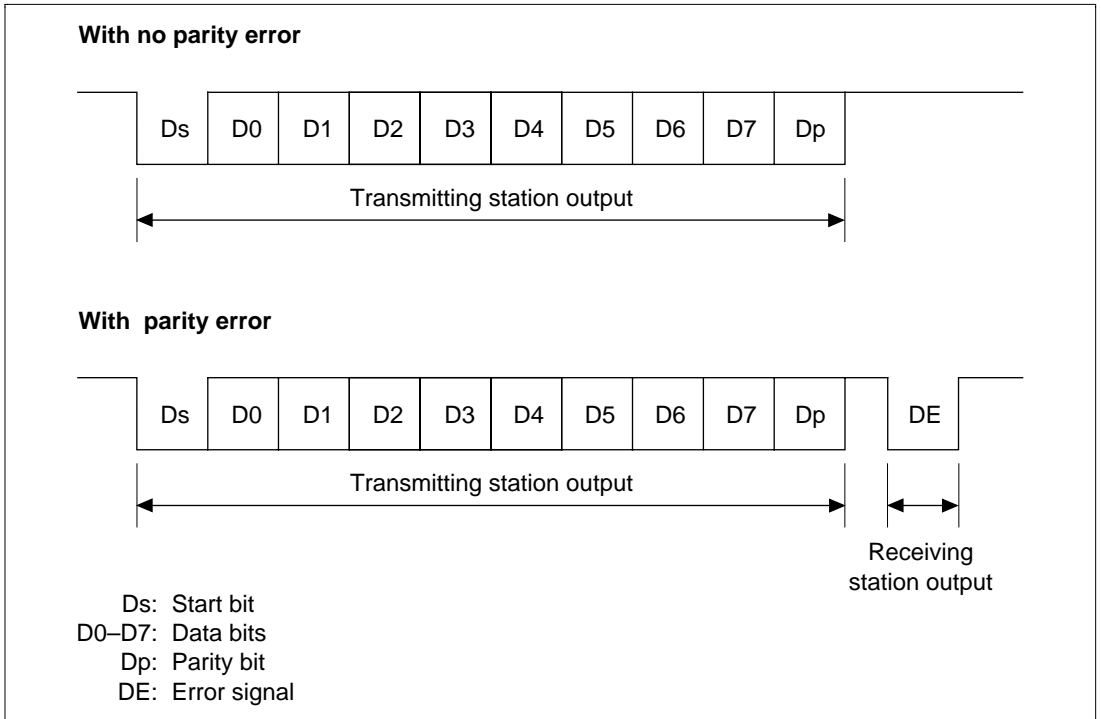


Figure 15.3 Data Format for Smart Card Interface

The operating sequence is:

1. The data line is high impedance when not in use and is fixed high with a pull-up resistor.
2. The transmitting side starts one frame of data transmission. The data frame starts with a start bit (Ds, low level). The start bit is followed by eight data bits (D0–D7) and a parity bit (Dp).
3. On the smart card interface, the data line returns to high impedance after this. The data line is pulled high with a pull-up resistor.
4. The receiving side checks parity. When the data is received normally with no parity errors, the receiving side then waits to receive the next data. When a parity error occurs, the receiving side outputs an error signal (DE, low level) and requests re-transfer of data. The receiving station returns the signal line to high impedance after outputting the error signal for a specified period. The signal line is pulled high with a pull-up resistor.
5. The transmitting side transmits the next frame of data unless it receives an error signal. If it does receive an error signal, it returns to step 2 to re-transmit the erroneous data.

15.3.4 Register Settings

Table 15.3 shows the bit map of the registers that the smart card interface uses. Bits shown as 1 or 0 must be set to the indicated value. The settings for the other bits are described below.

Table 15.3 Register Settings for the Smart Card Interface

Register	Address	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SCSMR	H'FFFFFFE80	C/ \bar{A}	0	1	O/ \bar{E}	1	0	CKS1	CKS0
SCBRR	H'FFFFFFE82	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0
SCSCR	H'FFFFFFE84	TIE	RIE	TE	RE	0	0	CKE1	CKE0
SCTDR	H'FFFFFFE86	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0
SCSSR	H'FFFFFFE88	TDRE	RDRF	ORER	FER/ ERS	PER	TEND	0	0
SCRDR	H'FFFFFFE8A	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0
SCSCMR	H'FFFFFFE8C	—	—	—	—	SDIR	SINV	—	SMIF

Note: Dashes indicate unused bits.

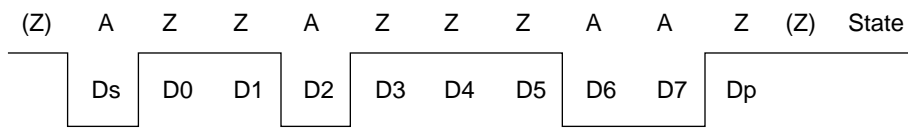
1. Setting the serial mode register (SCSMR): Set the O/\bar{E} bit to 0 when the IC card uses the direct convention or to 1 when it uses the inverse convention. Select the on-chip baud rate generator clock source with the CKS1 and CKS0 bits (see section 15.3.5, Clock).
2. Setting the bit rate register (SCBRR): Set the bit rate. See section 15.3.5, Clock, to see how to calculate the set value.
3. Setting the serial control register (SCSCR): The TIE, RIE, TE and RE bits function as they do for the ordinary SCI. See section 13, Serial Communication Interface, for more information. The CKE0 bit specifies the clock output. When no clock is output, set 0; when a clock is output, set 1.
4. Setting the smart card mode register (SCSCMR): The SDIR and SINV bits are both set to 0 for IC cards that use the direct convention and both to 1 when the inverse convention is used. The SMIF bit is set to 1 for the smart card interface.

Figure 15.4 shows sample waveforms for register settings of the two types of IC cards (direct convention and inverse convention) and their start characters.

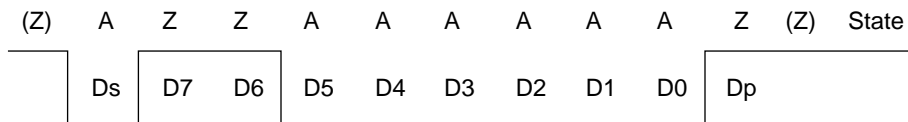
In the direct convention type, the logical 1 level is state Z, the logical 0 level is state A, and communication is LSB first. The start character data is H'3B. The parity bit is even (from the smart card standards), and thus a 1.

In the inverse convention type, the logical 1 level is state A, the logical 0 level is state Z, and communication is MSB first. The start character data is H'3F. The parity bit is even (from the smart card standards), and thus a 0, which corresponds to state Z.

Only data bits D7–D0 are inverted by the SINV bit. To invert the parity bit, set the O/\bar{E} bit in SCSMR to odd parity mode. This applies to both transmission and reception.



a. Direct convention (SDIR, SINV, and O/\bar{E} are all 0)



b. Inverse convention (SDIR, SINV, and O/\bar{E} are all 1)

Figure 15.4 Waveform of Start Character

15.3.5 Clock

Only the internal clock generated by the on-chip baud rate generator can be used as the communication clock in the smart card interface. The bit rate for the clock is set by the bit rate register (SCBRR) and the CKS1 and CKS0 bits in the serial mode register (SCSMR), and is calculated using the equation below. Table 15.5 shows sample bit rates. If clock output is then selected by setting CKE0 to 1, a clock with a frequency 372 times the bit rate is output from the SCK0 pin.

$$B = \frac{P\phi}{1488 \times 2^{2n-1} \times (N + 1)} \times 10^6$$

Where:

N = Value set in SCBRR ($0 \leq N \leq 255$)

B = Bit rate (bit/s)

$P\phi$ = Peripheral module operating frequency (MHz)*

n = 0–3 (table 15.4)

Table 15.4 Relationship of n to CKS1 and CKS0

n	CKS1	CKS0
0	0	0
1	0	1
2	1	0
3	1	1

Table 15.5 Examples of Bit Rate B (Bit/s) for SCBRR Settings (n = 0)

N	P ϕ (MHz)						
	7.1424	10.00	10.7136	13.00	14.2848	16.00	18.00
0	9600.0	13440.9	14400.0	17473.1	19200.0	21505.4	24193.5
1	4800.0	6720.4	7200.0	8736.6	9600.0	10752.7	12096.8
2	3200.0	4480.3	4800.0	5824.4	6400.0	7168.5	8064.5

Note: The bit rate is rounded to two decimal places.

Calculate the value to be set in the bit rate register (SCBRR) from the operating frequency and the bit rate. N is an integer in the range $0 \leq N \leq 255$, specifying a smallish error.

$$N = \frac{P\phi}{1488 \times 2^{2n-1} \times B} \times 10^6 - 1$$

Table 15.6 Examples of SCBRR Settings for Bit Rate B (Bit/s) (n = 0)

ϕ (MHz) (9600 Bits/s)													
7.1424		10.00		10.7136		13.00		14.2848		16.00		18.00	
N	Error	N	Error	N	Error	N	Error	N	Error	N	Error	N	Error
0	0.00	1	30.00	1	25.00	1	8.99	1	0.00	1	12.01	2	15.99

Table 15.7 Maximum Bit Rates for Frequencies (Smart Card Interface Mode)




Pϕ (MHz)	Maximum Bit Rate (Bit/s)	N	n
7.1424	9600	0	0
10.00	13441	0	0
10.7136	14400	0	0
13.00	17473	0	0
14.2848	19200	0	0
16.00	21505	0	0
18.00	24194	0	0

The bit rate error is found as follows:

$$\text{Error(\%)} = \left(\frac{P\phi}{1488 \times 2^{2n-1} \times B \times (N + 1)} \times 10^6 - 1 \right) \times 100$$

Table 15.8 shows the relationship between transmit/receive clock register set values and output states on the smart card interface.

Table 15.8 Register Set Values and SCK Pin

Setting	Register Value				SCK Pin	
	SMIF	C/A	CKE1	CKE0	Output	State
1*1	1	0	0	0	Port	Determined by setting of port register SPB1IO and SPB1DT bits
	1	0	0	1		SCK (serial clock) output state
2*2	1	1	0	0	Low output	Low output state
	1	1	0	1		SCK (serial clock) output state
3*2	1	1	1	0	High output	High output state
	1	1	1	1		SCK (serial clock) output state

- Notes: 1. The SCK output state changes as soon as the CKE0 bit is modified. The CKE1 bit should be cleared to 0.
2. The clock duty remains constant despite stopping and starting of the clock by modification of the CKE0 bit.

15.3.6 Data Transmission and Reception

Initialization: Initialize the SCI using the following procedure before sending or receiving data. Initialization is also required for switching from transmit mode to receive mode or from receive mode to transmit mode. Figure 15.5 shows a flowchart of the initialization process.

1. Clear TE and RE in the serial control register (SCSCR) to 0.
2. Clear error flags FER/ERS, PER, and ORER to 0 in the serial status register (SCSSR).
3. Set the C/\bar{A} bit, parity bit (O/\bar{E} bit), and baud rate generator select bits (CKS1 and CKS0 bits) in the serial mode register (SCSMR). At this time also clear the CHR and MP bits to 0 and set the STOP and PE bits to 1.
4. Set the SMIF, SDIR, and SINV bits in the smart card mode register (SCSCMR). When the SMIF bit is set to 1, the TxD and RxD pins both switch from ports to SCI pins and become high impedance.
5. Set the value corresponding to the bit rate in the bit rate register (SCBRR).
6. Set the clock source select bits (CKE1 and CKE0 bits) in the serial control register (SCSCR). Clear the TIE, RIE, TE, RE, MPIE, and TEIE bits to 0. When the CKE0 bit is set to 1, a clock is output from the SCK0 pin.
7. After waiting at least 1 bit, set the TIE, RIE, TE, and RE bits in SCSCR. Do not set the TE and RE bits simultaneously unless performing auto-diagnosis.

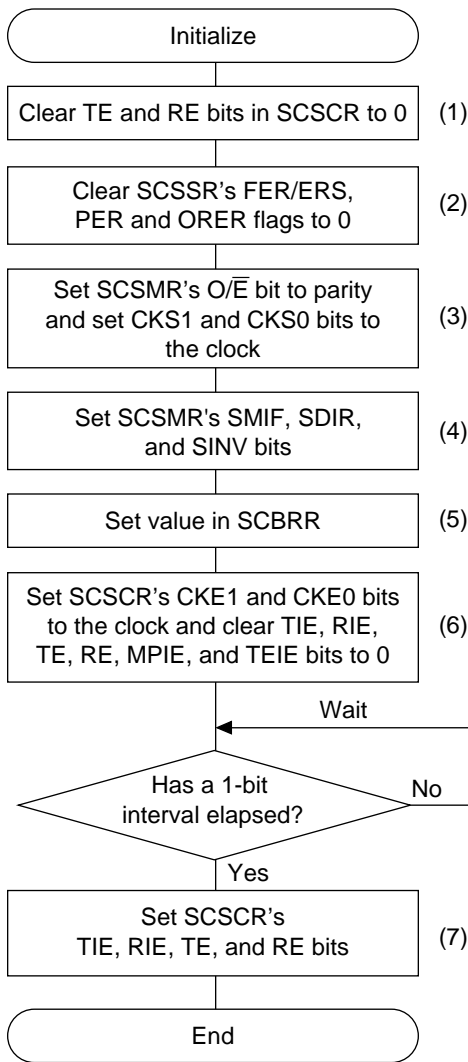


Figure 15.5 Initialization Flowchart (Example)

Serial Data Transmission: The handling procedures in the smart card mode differ from ordinary SCI processing because data is retransmitted when an error signal is sampled during a data transmission. This results in the transmission processing flowchart shown in figure 15.6.

1. Initialize the smart card interface mode as described in initialization above.
2. Check that the FER/ERS bit in SCSSR is cleared to 0.
3. Repeat steps 2 and 3 until the TEND flag in SCSSR is set to 1.
4. Write the transmit data into SCTDR, clear the TDRE flag to 0 and start transmitting. The TEND flag will be cleared to 0.
5. To transmit more data, return to step 2.
6. To end transmission, clear the TE bit to 0.

This processing can be interrupted. When the TIE bit is set to 1 and interrupt requests are enabled, a transmit-data-empty interrupt (TXI) will be requested when the TEND flag is set to 1 at the end of the transmission. When the RIE bit is set to 1 and interrupt requests are enabled, a communication error interrupt (ERI) will be requested when the ERS flag is set to 1 when an error occurs in transmission. See Interrupt Operation below for more information.

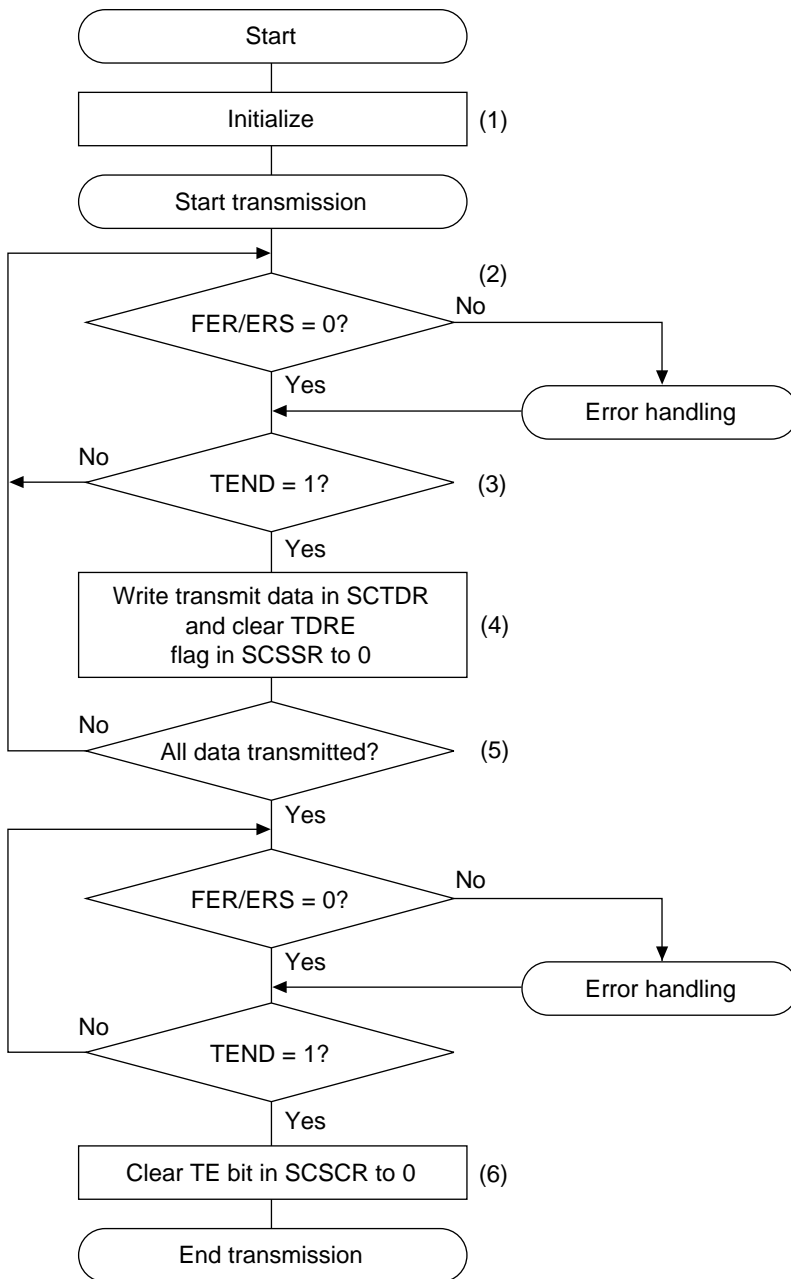


Figure 15.6 Transmission Flowchart

Serial Data Reception: The handling procedures in the smart card mode are the same as in ordinary SCI processing. The reception processing flowchart is shown in figure 15.7.

1. Initialize the smart card interface mode as described above in Initialization and in figure 15.5.
2. Check that the ORER and PER flags in SCSSR are cleared to 0. If either flag is set, clear both to 0 after performing the appropriate error handling procedures.
3. Repeat steps 2 and 3 until the RDRF flag is set to 1.
4. Read the receive data from SCRDR.
5. To receive more data, clear the RDRF flag to 0 and return to step 2.
6. To end reception, clear the RE bit to 0.

This processing can be interrupted. When the RIE bit is set to 1 and interrupt requests are enabled, a receive-data-full interrupt (RXI) will be requested when the RDRF flag is set to 1 at the end of the reception. When an error occurs during reception and either the ORER or PER flag is set to 1, a communication error interrupt (ERI) will be requested. See Interrupt Operation, below, for more information.

The received data will be transferred to SCRDR even when a parity error occurs during reception and PER is set to 1, so this data can still be read.

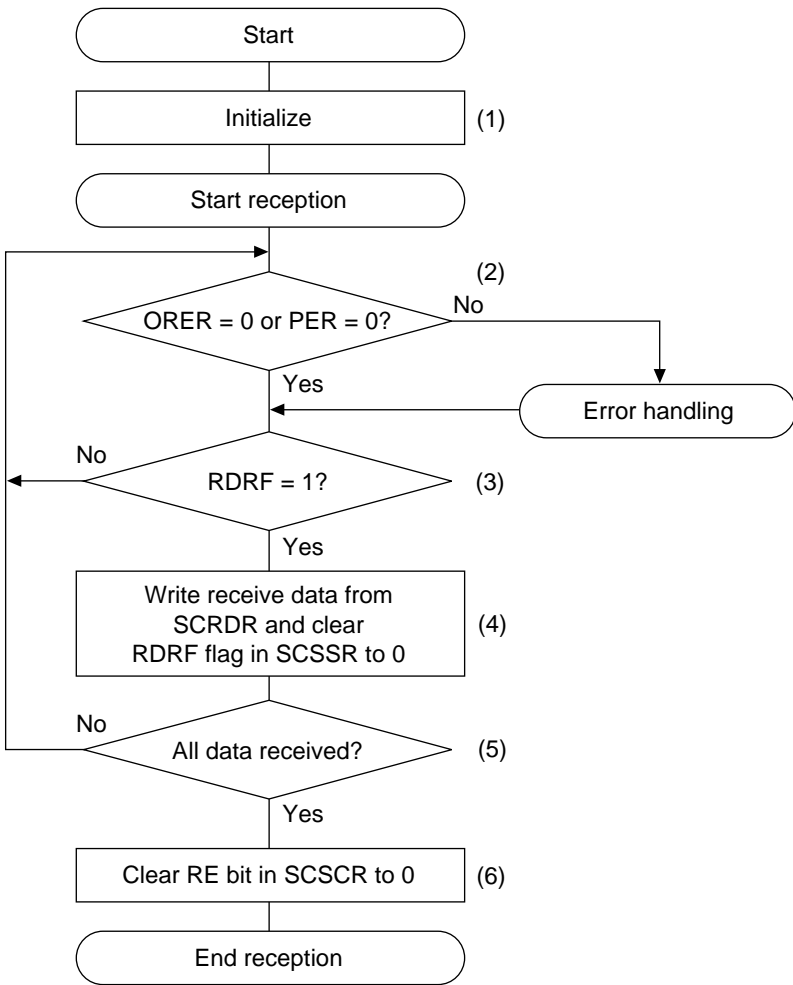


Figure 15.7 Reception Flowchart (Example)

Switching Modes: When switching from receive mode to transmit mode, check that the receive operation is completed before starting initialization and setting RE to 0 and TE to 1. The RDRF, PER, and ORER flags can be used to check if reception is completed. When switching from transmit mode to receive mode, check that the transmit operation is completed before starting initialization and setting TE to 0 and RE to 1. The TEND flag can be used to check if transmission is completed.

Interrupt Operation: In the smart card interface mode, there are three types of interrupts: transmit-data-empty (TXI), communication error (ERI) and receive-data-full (RXI). In this mode, the transmit-end interrupt (TEI) cannot be requested.

Set the TEND flag in SCSSR to 1 to request a TXI interrupt. Set the RDRF flag in SCSSR to 1 to request an RXI interrupt. Set the ORER, PER, or FER/ERS flag in SCSSR to 1 to request an ERI interrupt (table 15.9).

Table 15.9 Smart Card Mode Operating Status and Interrupt Sources

Mode	Status	Flag	Mask Bit	Interrupt Source
Transmit mode	Normal	TEND	TIE	TXI
	Error	FER/ERS	RIE	ERI
Receive mode	Normal	RDRF	RIE	RXI
	Error	PER, ORER	RIE	ERI

15.4 Usage Notes

When the SCI is used as a smart card interface, be sure that all criteria in sections 15.4.1 and 15.4.2 are applied.

15.4.1 Receive Data Timing and Receive Margin in Asynchronous Mode

In asynchronous mode, the SCI runs on a basic clock with a frequency of 372 times the transfer rate. During reception, the SCI samples the fall of the start bit using the base clock to achieve internal synchronization. Receive data is latched internally on the rising edge of the 186th basic clock cycle (figure 15.8).

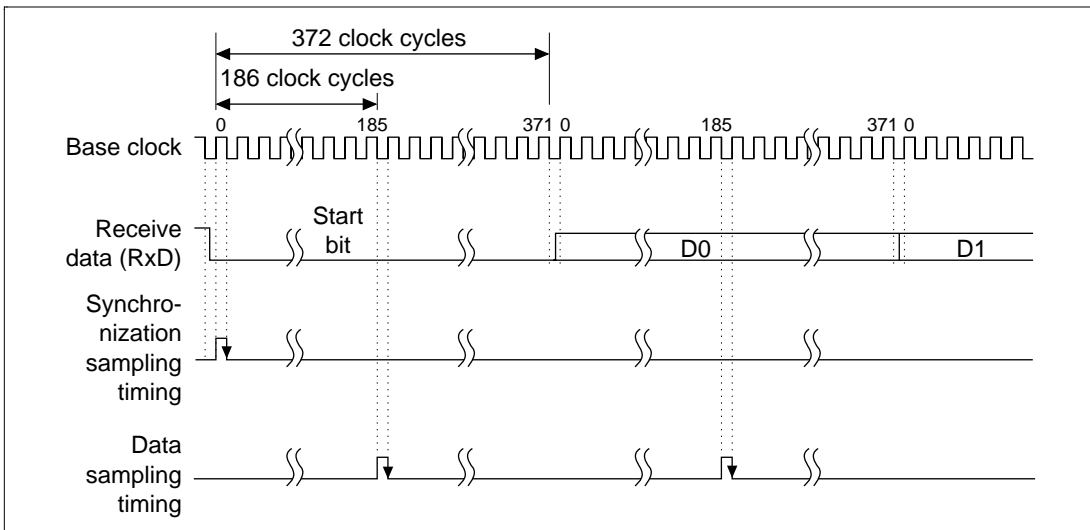


Figure 15.8 Receive Data Sampling Timing in Smart Card Mode

The receive margin is found from the following equation:

For smart card mode:

$$M = \left| \left(0.5 - \frac{1}{2N} \right) - (L - 0.5)F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\%$$

Where:

M = Receive margin (%)

N = Ratio of bit rate to clock (N = 372)

D = Clock duty (D = 0 to 1.0)

L = Frame length (L = 10)

F = Absolute value of clock frequency deviation

Using this equation, the receive margin when F = 0 and D = 0.5 is as follows:

$$M = (0.5 - 1/2 \times 372) \times 100\% = 49.866\%$$

15.4.2 Retransmission (Receive and Transmit Modes)

Retransmission by the SCI in Receive Mode: Figure 15.9 shows the retransmission operation in the SCI receive mode.

1. When the received parity bit is checked and an error is found, the PER bit in SCSSR is automatically set to 1. If the RIE bit in SCSCR is enabled at this time, an ERI interrupt is requested. Be sure to clear the PER bit before the next parity bit is sampled.
2. The RDRF bit in SCSSR is not set in the frame that caused the error.
3. When the received parity bit is checked and no error is found, the PER bit in SCSSR is not set.
4. When the received parity bit is checked and no error is found, reception is considered to have been completed normally and the RDRF bit in SCSSR is automatically set to 1. If the RIE bit in SCSCR is enabled at this time, an RXI interrupt is requested.
5. When a normal frame is received, the pin maintains a three-state status when it transmits the error signal.

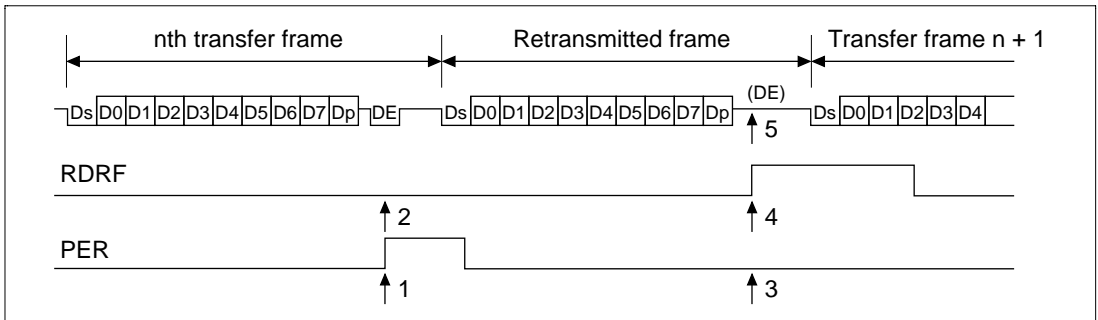


Figure 15.9 Retransmission in SCI Receive Mode

Retransmission by the SCI in Transmit Mode: Figure 15.10 shows the retransmission operation in the SCI transmit mode.

1. After transmission of one frame is completed, the FER/ERS bit in SCSSR is set to 1 when an error signal is returned from the receiving side. If the RIE bit in SCSCR is enabled at this time, an ERI interrupt is requested. Be sure to clear the FER/ERS bit before the next parity bit is sampled.
2. The TEND bit in SCSSR is not set in the frame that received the error signal that indicated the error.
3. The FER/ERS bit in SCSCR is not set when no error signal is returned from the receiving side.
4. When no error signal is returned from the receiving side, the TEND bit in SCSSR is set to 1 when the transmission of the frame that includes the retransmission is considered completed. If the TIE bit in SCSCR is enabled at this time, a TXI interrupt will be requested.

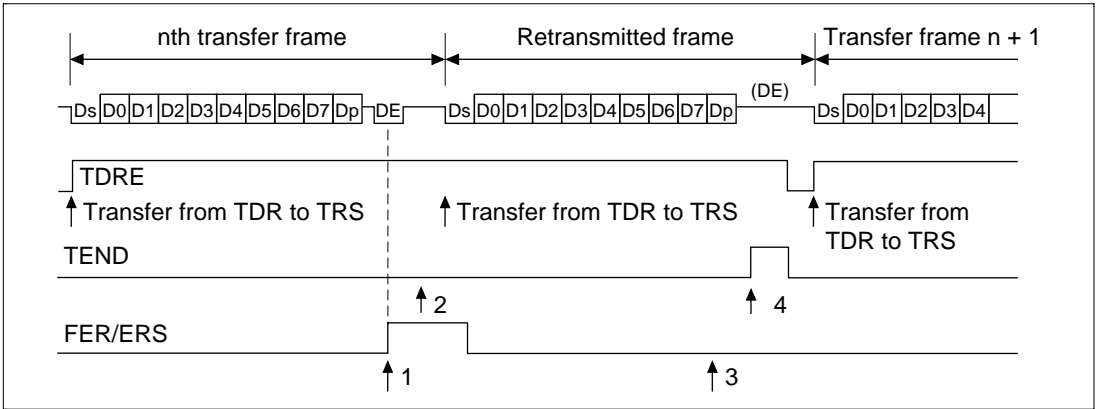


Figure 15.10 Retransmission in SCI Transmit Mode

Section 16 I/O Ports

16.1 Overview

The has an on-chip 8-bit general-purpose I/O port and an on-chip I/O port for the serial communication interface (SCI).

16.1.1 Features

The general-purpose I/O port has the following features:

- Direction of each bit of the 8-bit I/O port can be set independently
- When each bit is set for input mode, it is possible to set each bit for independent pull-up
- Ports can be used as I/O ports or as data bus lines, for a maximum data bus width of 32 bits, by setting the PORTEN bit in bus control register 2 (BCR2)

The SCI I/O port has the following features:

- When the I/O port is set to output and the SCI is not enabled, data can be output. This allows transmission of the break status. SCK pin control is also possible.
- The value of the RxD pin can be read at any time. This enables break detection.

16.1.2 Block Diagram

Figure 16.1 shows a block diagram of the 8-bit general-purpose I/O port.

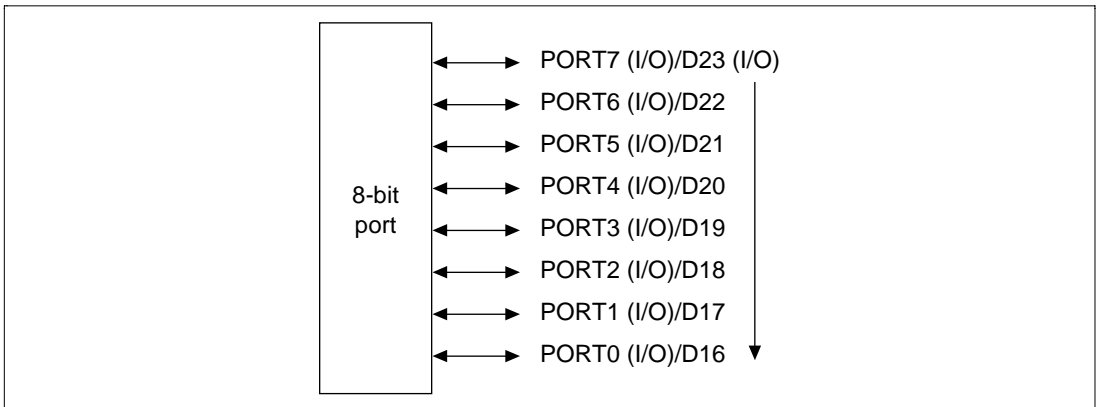


Figure 16.1 8-Bit I/O Port

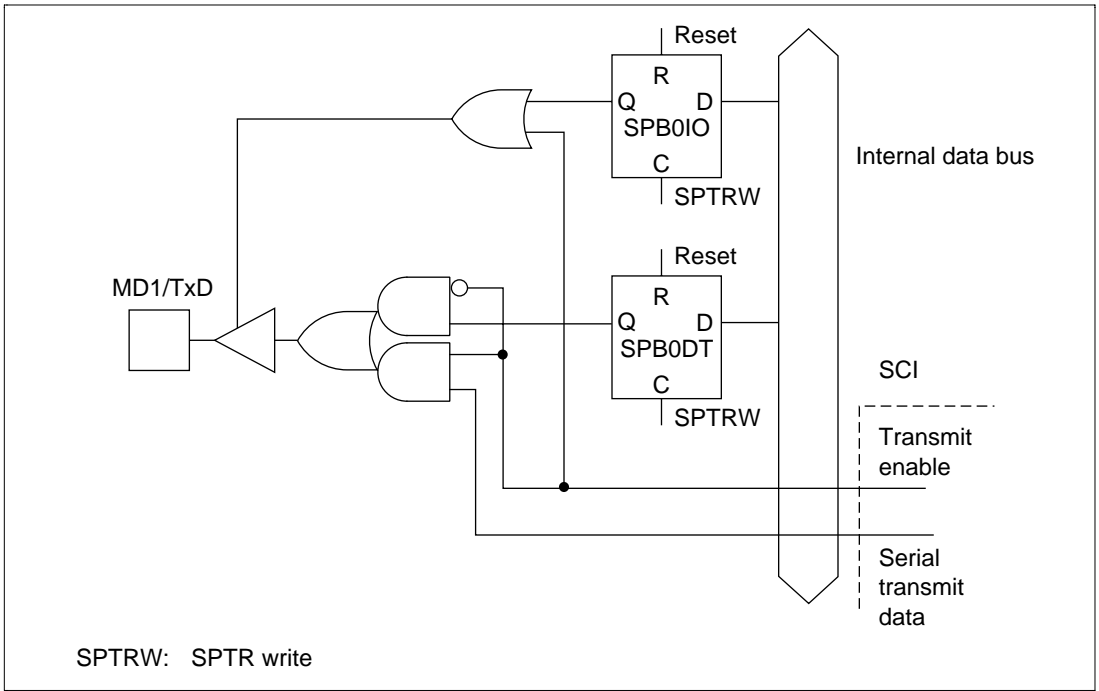


Figure 16.3 SCI I/O Port: MD1/TxD Pin

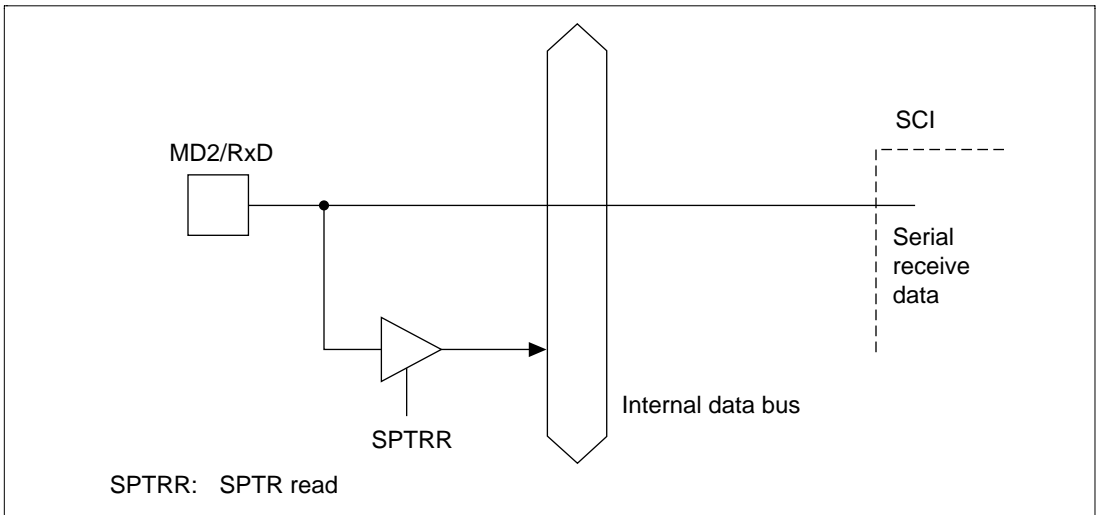


Figure 16.4 SCI I/O Port: MD2/RxD Pin

16.1.3 Pin Configuration

Table 16.1 shows the pin configuration of the 8-bit general-purpose I/O port.

Table 16.1 Pin Configuration

Pin	Signal	I/O	Function
Port 7	PORT7	I/O	I/O port
Port 6	PORT6	I/O	I/O port
Port 5	PORT5	I/O	I/O port
Port 4	PORT4	I/O	I/O port
Port 3	PORT3	I/O	I/O port
Port 2	PORT2	I/O	I/O port
Port 1	PORT1	I/O	I/O port
Port 0	PORT0	I/O	I/O port

Table 16.2 shows the pin configuration of the SCI I/O port.

Table 16.2 Pin Configuration

Pin	Signal	I/O	Function
Serial transmission	TxD	O	Serial data transmission and break status transmission
Serial reception	RxD	I	Serial data reception and break status detection
Serial clock	SCK	I/O	Serial clock input/output and I/O port

Note: These pins function as mode input pins MD0–MD2 after a power-on reset. They are made to function as serial pins by performing SCI operation settings with the TE, RE, CKEI, and CKE0 bits in SCSCR and the C/\bar{A} bit in SCSMR. Break status transmission and detection can be performed by means of the SCI's SCSPTR register.

16.1.4 Register Configuration

Table 16.3 shows the configuration of the two registers of the 8-bit general-purpose I/O port (PCTR and PDTR) and the one register of the SCI I/O port (SCSPTR).

Table 16.3 Register Configuration

Register	Symbol	R/W	Initial Value	Address	Access Size
Port control register	PCTR	R/W	H'0000	H'FFFFFF76	16
Port data register	PDTR	R/W	Undefined	H'FFFFFF78	8
Serial port register	SCSPTR	R/W	Undefined	H'FFFFFF7C	8

Note: Initialized to H'00 except bit 2 and 0. Bit 2 and 0 are undefined.

16.2 Register Descriptions

16.2.1 Port Control Register (PCTR)

The port control register (PCTR) is a 16-bit read/write register that controls the input/output direction and pull-up for each bit in the 8-bit port. As the initial value of the port data register (PDR) is undefined, all the bits in the 8-bit port should be set to output with PCTR after writing a value to the PDTR register.

PCTR is initialized to H'0000 by a power-on reset. It is not initialized by a manual reset or in standby mode, and retains its contents.

Bit:	15	14	13	12	11	10	9	8
Bit name:	PB7 PUP	PB7 IO	PB6 PUP	PB6 IO	PB5 PUP	PB5 IO	PB4 PUP	PB4 IO
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit:	7	6	5	4	3	2	1	0
Bit name:	PB3 PUP	PB3 IO	PB2 PUP	PB2 IO	PB1 PUP	PB1 IO	PB0 PUP	PB0 IO
Initial value:	0	0	0	0	0	0	0	0
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 2n + 1 (n = 0–7): Port Pull-Up Control (PBnPUP): Controls the pull-up of each bit in the 8-bit port by means of built-in resistors. This setting is valid even if the port pin is set to output by the PBnIO bit. Therefore, to avoid unnecessary power consumption and ensure the reliability of the chip, a pull-up setting should not be made when the corresponding port pin has been set to output.

Bit 2n + 1: PBnPUP Description

0	Bit n (n = 0–7) of the 8-bit port is pulled up.	(Initial value)
1	Bit n (n = 0–7) of the 8-bit port is not pulled up.	

Bit 2n (n = 0–7)—Port I/O Control (PBnDIR): Controls whether each bit of 8-bit port is an input or an output.

Bit 2n: PBnIO Description

0	Bit n (n = 0–7) of the 8-bit port is an input.	(Initial value)
1	Bit n (n = 0–7) of the 8-bit port is an output.	

16.2.2 Port Data Register (PDTR)

The port data register (PDTR) is an 8-bit read/write register used as data latches for each bit of the 8-bit port. When a bit is set to be used as an output, the value written into PDTR is output from the external pin. When a value is read from PDTR, the external pin value sampled on the external bus clock is returned.

PDTR is not initialized by a power-on reset or manual reset, or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	PB7DT	PB6DT	PB5DT	PB4DT	PB3DT	PB2DT	PB1DT	PB0DT
Initial value:	—	—	—	—	—	—	—	—
R/W:	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

16.2.3 Serial Port Register (SCSPTR)

The serial port register (SCSPTR) is an 8-bit register that the CPU can always read and write. It controls I/O and data of the port multiplexed with the serial communication interface (SCI) pins. Input data can be read from the RxD pin and output data can be transmitted to the TxD pin; this controls breaks for serial transmission and reception. In addition, SCK pin data reading and output data writing can be performed by means of bits 3 and 2.

All SCSPTR bits except bits 2 and 0 are initialized to 0 by a power-on reset; the value of bits 2 and 0 is undefined. SCSPTR is not initialized by a manual reset or in standby mode.

Bit:	7	6	5	4	3	2	1	0
Bit name:	—	—	—	—	SPB1IO	SPB1DT	SPB0IO	SPB0DT
Initial value:	0	0	0	0	0	—	0	—
R/W:	R	R	R	R	R/W	R/W	R/W	R/W

Bits 7 to 4—Reserved: These bits are always read as 0. The write value should always be 0.

Bit 3—Serial Port Clock Port I/O (SPB1IO): Specifies serial port SCK pin input/output. When the SCK pin is actually set as a port output pin and outputs the value set by the SPB1DT bit, the C/\overline{A} bit in SCSMR and the CKE1 and CKE0 bits in SCSCR should be cleared to 0.

Bit 3: SPB1IO Description

Bit	Description	(Initial value)
0	The SPB1IO value is not output to the SCK pin.	(Initial value)
1	The SPB1IO bit value is output to the TxD pin.	

Bit 2—Serial Port Clock Port Data (SPB1DT): Specifies the serial port SCK pin input/output data. Input or output is specified by the SPB1IO bit (see the description of SPB1IO for details). When output is specified, the value of the SPB1DT bit is output to the SCK pin. The SCK pin value is read from the SPB1DT bit regardless of the value of the SPB1IO bit. The initial value of this bit after a power-on reset is undefined.

Bit 2: SPB1DT Description

Bit	Description	(Initial value)
0	I/O data level is low.	(Initial value)
1	I/O data level is high.	

Bit 1—Serial Port Break I/O (SPB0IO): Specifies the serial port TxD pin output condition. When the TxD pin is actually set as a port output pin and outputs the value set by the SPB0DT bit, the TE bit in SCSCR should be cleared to 0.

Bit 1: SPB0IO	Description
0	The SPB0DT bit value is not output to the TxD pin. (Initial value)
1	The SPB0DT bit value is output to the TxD pin.

Bit 0—Serial Port Break Data (SPB0DT): Specifies serial port RxD pin input data and TxD pin output data. The TxD pin output condition is set with the SPB0IO bit (see the description of SPB0IO above). When the TxD pin is set as an output, the value of the SPB0DT bit is output to the TxD pin. The RxD pin value is always read from the SPB0DT bit, regardless of the value of the SPB0IO bit. The initial value of this bit after a power-on reset is undefined.

Bit 0 : SPB0DT	Description
0	I/O data level is low. (Initial value)
1	I/O data level is high.

Section 17 Electrical Characteristics

17.1 Absolute Maximum Ratings

Table 17.1 Absolute Maximum Ratings

Item	Symbol	Ratings	Units
Power supply voltage	V_{CC}	-0.3 to 4.6	V
Input voltage	V_{in}	-0.3 to $V_{CC} + 0.3$	V
Operating temperature	T_{opr}	-20 to + 75	°C
Storage temperature	T_{stg}	-55 to + 125	°C

Note: Operating the SH7718R above maximum ratings can damage or destroy it.

17.2 DC Characteristics

Table 17.2 DC Characteristics ($T_a = -20$ to $+75^\circ\text{C}$)

Item		Symbol	Min	Typ	Max	Unit	Remarks
Power supply voltage		V_{CC}	3.15	3.3	3.6	V	In normal operation, sleep mode, and standby mode
Current	Normal operation	I_{CC}	—	120 ^{*1}	200 ^{*1}	mA	*1 $V_{CC} = 3.3$ V $I_0 = 100$ MHz $B_0 = 50$ MHz
	In sleep mode		—	75 ^{*2}	100 ^{*2}		*2 $B_0 = 60$ MHz $P_0 = 30$ MHz
	In standby mode		—	0.1 ^{*3}	1 ^{*3}	mA	*3 $V_{CC} = 3.3$ V/ $T_a = 25^\circ\text{C}$
Input voltage	RESET, NMI	V_{IH}	$V_{CC} \times 0.9$	—	$V_{CC} + 0.3$	V	
	BREQ, IRL3–IRL0, MD5–MD0		$V_{CC} - 0.5$	—	$V_{CC} + 0.3$		Standby mode
	EXTAL, CKIO		$V_{CC} - 0.7$	—	$V_{CC} + 0.3$		Normal operation
	Other input pins		2.0	—	$V_{CC} + 0.3$		
	RESET, NMI	V_{IL}	-0.3	—	$V_{CC} \times 0.1$		
	BREQ, IRL3–IRL0, MD5–MD0		-0.3	—	0.5		Standby mode
	Other input pins		-0.3	—	$V_{CC} \times 0.2$		Normal operation
	Other input pins		-0.3	—	$V_{CC} \times 0.2$		
Input leak current	All input pins	$ I_{in} $	—	—	1.0	μA	$V_{in} = 0.5$ to $V_{CC} - 0.5$ V
Three-state leak current	I/O, output, all pins (off condition)	$ I_{TSI} $	—	—	1.0	μA	$V_{in} = 0.5$ to $V_{CC} - 0.5$ V

Table 17.2 DC Characteristics ($T_a = -20$ to $+75^\circ\text{C}$) (cont)

Item		Symbol	Min	Typ	Max	Unit	Remarks
Output voltage	All output pins	V_{OH}	2.4	—	—	V	$V_{CC} = 3.0\text{ V}$, $I_{OH} = -200\ \mu\text{A}$
			2.0	—	—		$V_{CC} = 3.0\text{ V}$, $I_{OH} = -2\text{ mA}$
		V_{OL}	—	—	0.55	$V_{CC} = 3.6\text{ V}$, $I_{OL} = 1.6\text{ mA}$	
Pull-up resistance	Port pins	R_{pull}	30	60	120	$k\Omega$	
Terminal capacitance	All pins	C	—	—	20	pF	

- Notes: 1. Regardless of whether PLL or RTC is used, connect $V_{CC}(\text{PLL})$, $V_{CC}(\text{RTC})$ to V_{CC} , and $V_{SS}(\text{PLL})$, $V_{SS}(\text{RTC})$ to V_{SS} .
2. Current condition is $V_{IH\ min} = V_{CC} - 0.5\text{ V}$, $V_{IL\ max} = 0.5\text{ V}$, and all output pins unloaded.

Table 17.3 Permissible Output Current Values ($V_{CC} = 3.3 \pm 0.3\text{ V}$, $T_a = -20$ to $+75^\circ\text{C}$)

Item	Symbol	Min	Typ	Max	Unit
Permissible output low current (per pin)	I_{OL}	—	—	2.0	mA
Permissible output low current (total)	ΣI_{OL}	—	—	120	
Permissible output high current (per pin)	$-I_{OH}$	—	—	2.0	
Permissible output high current (total)	$\Sigma (-I_{OH})$	—	—	40	

Note: To ensure reliability, output current must not exceed the maximum values listed.

17.3 AC Characteristics

Input for the LSI should, as a rule, be clock synchronous. Keep to the setup and hold times for each input signal unless otherwise directed.

Table 17.4 LSI Clock Values ($T_a = -20$ to $+75^\circ\text{C}$)

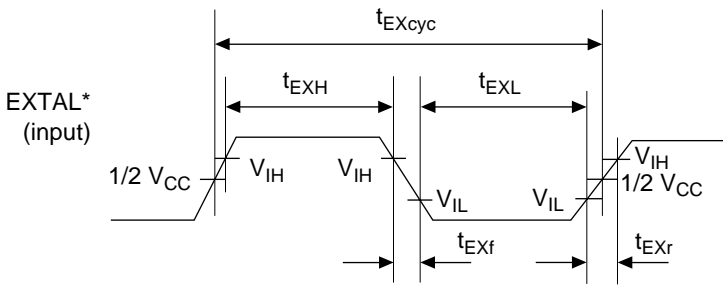
Item		Symbol	Max	Unit
Operating frequency	CPU, cache, TLB	f	100	MHz
	External bus		60	
	Peripheral modules		33.3	

17.3.1 Clock Timing

Table 17.5 Clock Timing ($V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20\text{ to } +75^\circ\text{C}$, Maximum External Bus Operating Frequency: 60 MHz)

Item	Symbol	Min	Max	Unit	Figure
EXTAL clock input frequency	f_{EX}	5	60	MHz	17.1
EXTAL clock input cycle time	t_{EXcyc}	16.7	200	ns	
EXTAL clock input low-level pulse width	t_{EXL}	4^{*1} or 10^{*2}	—	ns	
EXTAL clock input high-level pulse width	t_{EXH}	4^{*1} or 10^{*2}	—	ns	
EXTAL clock input rise time	t_{EXr}	—	2	ns	
EXTAL clock input fall time	t_{EXf}	—	2	ns	
CKIO clock frequency (input)	f_{CKI}	16	60	MHz	17.2
CKIO clock cycle time (input)	t_{CKIcyc}	16.7	62.5	ns	
CKIO clock low-level pulse width (input)	t_{CKIL}	4	—	ns	
CKIO clock high-level pulse width (input)	t_{CKIH}	4	—	ns	
CKIO clock rise time (input)	t_{CKIr}	—	2	ns	
CKIO clock fall time (input)	t_{CKIf}	—	2	ns	
CKIO clock output frequency (output)	f_{OP}	16	60	MHz	17.3
CKIO clock cycle time (output)	t_{cyc}	16.7	62.5	ns	
CKIO clock low-level pulse width (output)	t_{CKOL}	3	—	ns	
CKIO clock high-level pulse width (output)	t_{CKOH}	3	—	ns	
CKIO clock rise time (output)	t_{CKOr}	—	5	ns	
CKIO clock fall time (output)	t_{CKOf}	—	5	ns	
Power-on oscillation settling time	t_{OSC1}	10	—	ms	17.4
Power-on oscillation settling time/mode setting	t_{OSCMD}	10	—	ms	
\overline{BREQ} reset hold time	t_{BREQRH}	0	—	ns	
\overline{RESET} set-up time	t_{RESS}	20	—	ns	
\overline{BREQ} set-up time	t_{BREQS}	20	—	ns	
MD reset hold time	t_{MDRH}	20	—	ns	
Reset assert time	t_{RESW}	20	—	tcyc	17.4, 17.5
Standby return oscillation settling time 1	t_{OSC2}	10	—	ms	17.5
Standby return oscillation settling time 2	t_{OSC3}	10	—	ms	17.6
Standby return oscillation settling time 3	t_{OSC4}	11	—	ms	17.7
PLL synchronization settling time	t_{PLL}	100	—	μs	17.8, 17.9, 17.10
IRL interrupt decision time (using RTC and in standby mode)	t_{IRLSTB}	100	—	μs	17.10

Notes: 1. PLL circuit 2 in operation.
2. PLL circuit 2 not in operation.



Note: * The clock input from the EXTAL pin.

Figure 17.1 EXTAL Clock Input Timing

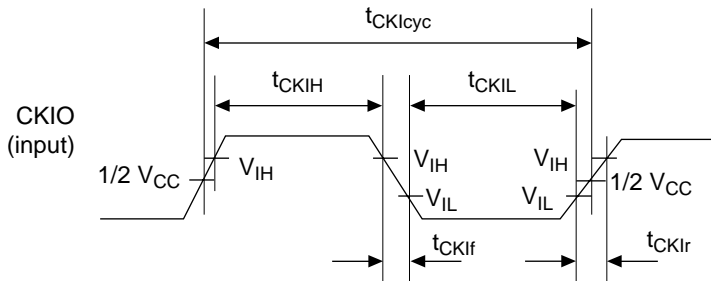


Figure 17.2 CKIO Clock Input Timing

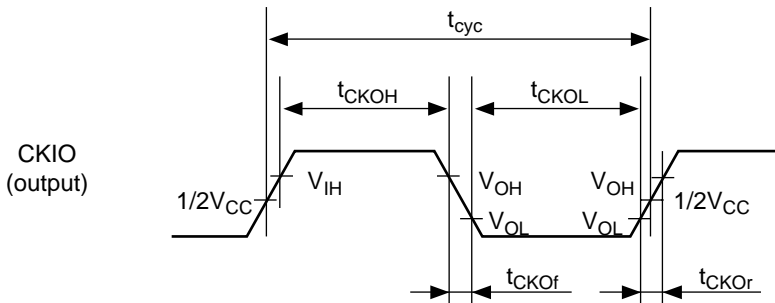
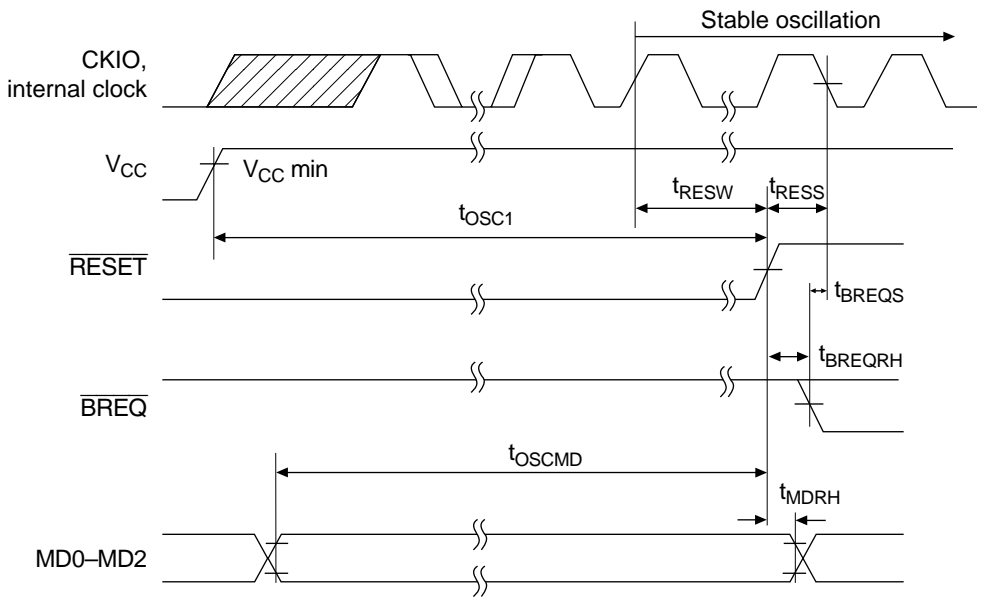
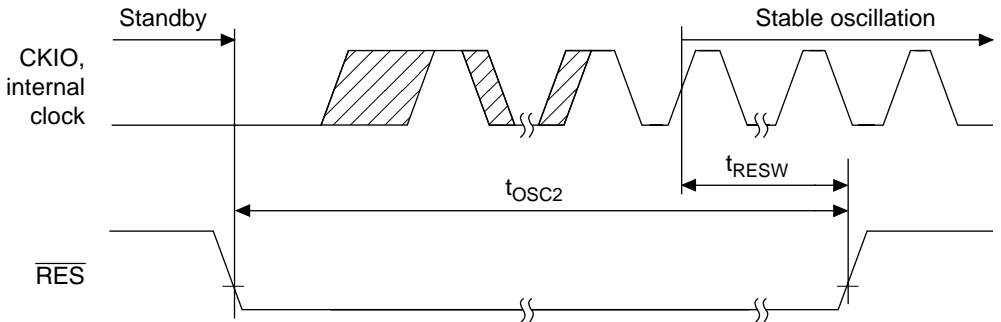


Figure 17.3 CKIO Clock Output Timing



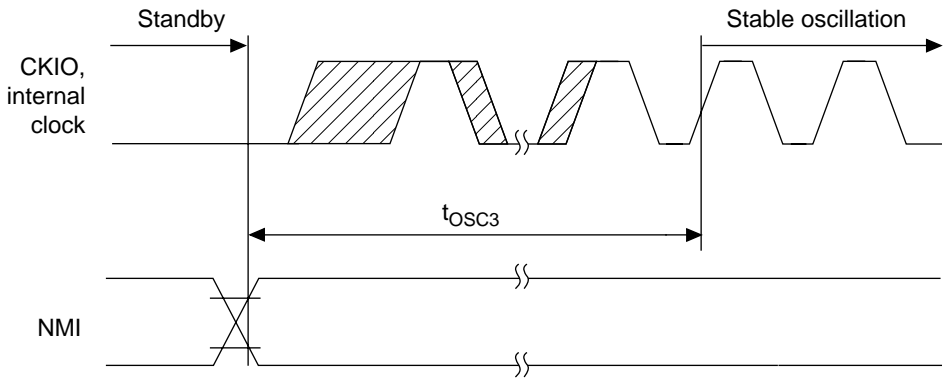
Note: Oscillation settling time when built-in oscillator is used

Figure 17.4 Power-On Oscillation Settling Time



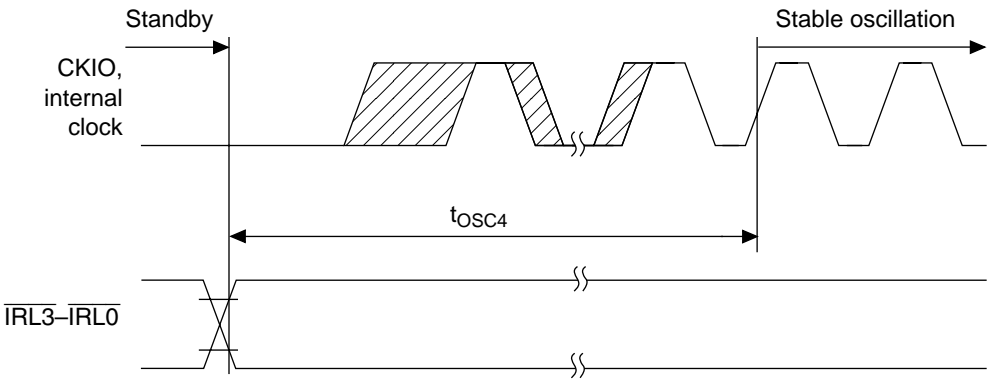
Note: Oscillation settling time when built-in oscillator is used

Figure 17.5 Standby Return Oscillation Settling Time (Return by RESET)



Note: Oscillation settling time when built-in oscillator is used

Figure 17.6 Standby Return Oscillation Settling Time (Return by NMI)



Note: Oscillation settling time when built-in oscillator is used

Figure 17.7 Standby Return Oscillation Settling Time (Return by $\overline{IRL3-IRL0}$)

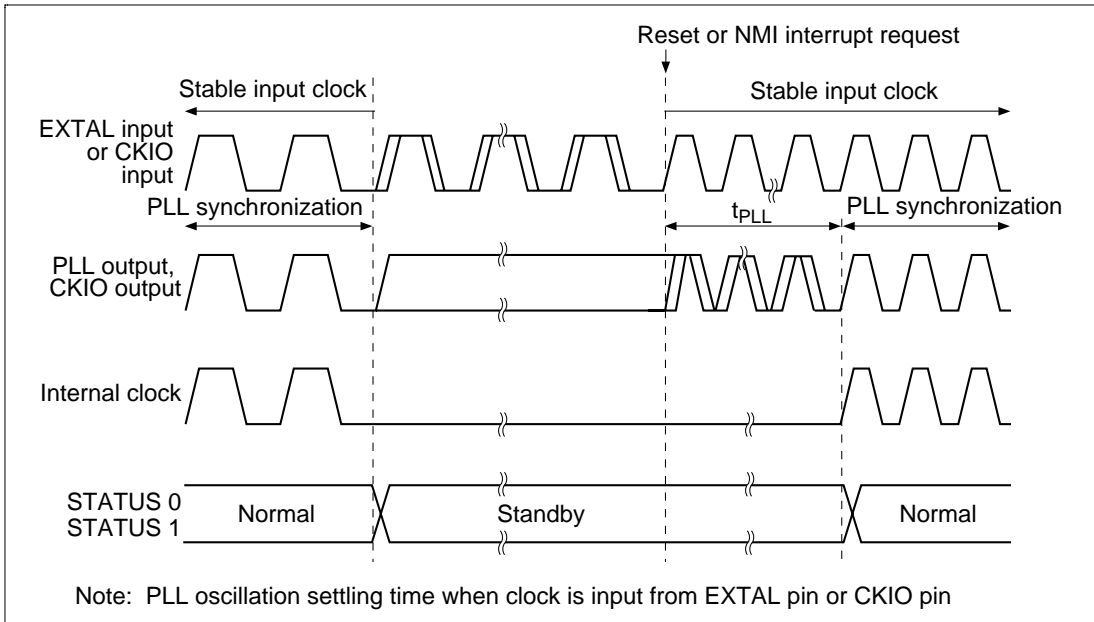


Figure 17.8 PLL Synchronization Settling Time in Case of Reset or NMI Interrupt

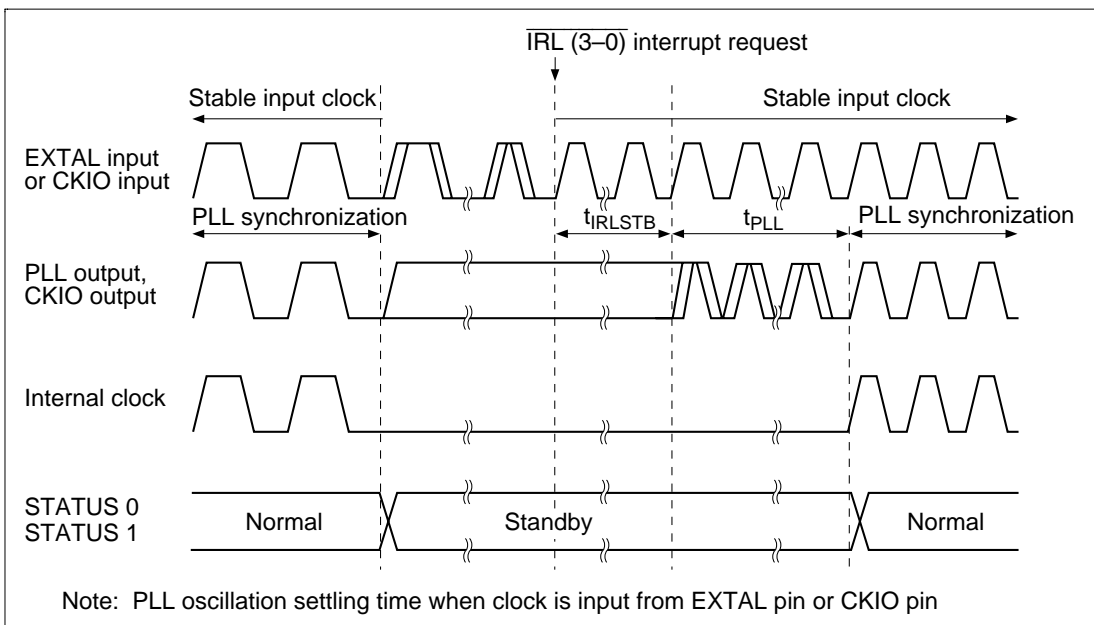


Figure 17.9 PLL Synchronization Settling Time in Case of IRL Interrupt

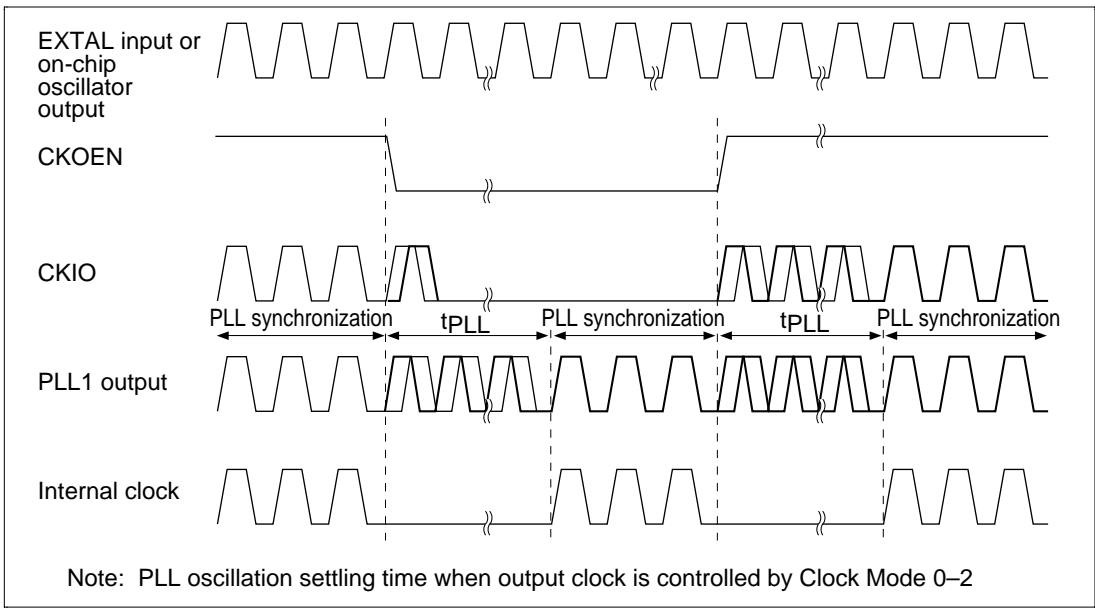


Figure 17.10 PLL Synchronization Settling Time in Case of CKOEN Bit Manipulation

17.3.2 Control Signal Timing

Table 17.6 Control Signal Timing ($V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20\text{ to } +75^\circ\text{C}$)

Item	Symbol	-60*2		Unit	Figure
		Min	Max		
$\overline{\text{RESET}}$ pulse width	t_{RESW}	20	—	tcyc	17.11, 17.13,
$\overline{\text{RESET}}$ setup time	t_{RESS}	23	—	ns	17.15
$\overline{\text{RESET}}$ hold time	t_{RESH}	2	—	ns	
$\overline{\text{BREQ}}$ setup time	t_{BREQS}	12	—	ns	
$\overline{\text{BREQ}}$ hold time	t_{BREQH}	3	—	ns	
$\overline{\text{BREQ}}$ reset setup time	t_{BREQRS}	17	—	ns	
$\overline{\text{BREQ}}$ reset hold time	t_{BREQRH}	16	—	ns	
MD reset setup time	t_{MDRS}	20	—	tcyc	17.12
MD reset hold time	t_{MDRH}	16	—	ns	
NMI setup time*1	t_{NMIS}	15	—	ns	17.13
$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$ setup time*1	t_{IRLS}	10	—	ns	
NMI hold time	t_{NMIH}	4	—	ns	
$\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$ hold time	t_{IRLH}	4	—	ns	
$\overline{\text{IRQOUT}}$ delay time	t_{IRQOD}	—	12	ns	17.14
$\overline{\text{BACK}}$ delay time	t_{BACKD}	—	12	ns	17.15, 17.16
STATUS1, STATUS0 delay time	t_{STD}	—	16	ns	
Bus tri-state delay time 1	t_{BOFF1}	0	16	ns	
Bus tri-state delay time 2	t_{BOFF2}	0	16	ns	
Bus buffer on time 1	t_{BON1}	0	16	ns	
Bus buffer on time 2	t_{BON2}	0	16	ns	

Notes: 1. $\overline{\text{RESET}}$, NMI, and $\overline{\text{IRL3}}$ to $\overline{\text{IRL0}}$ are asynchronous. Changes are detected at the clock fall when the setup shown is used. When the setup cannot be used, detection can be delayed until the next clock fall.

2. Upper limit of external bus clock is 60 MHz.

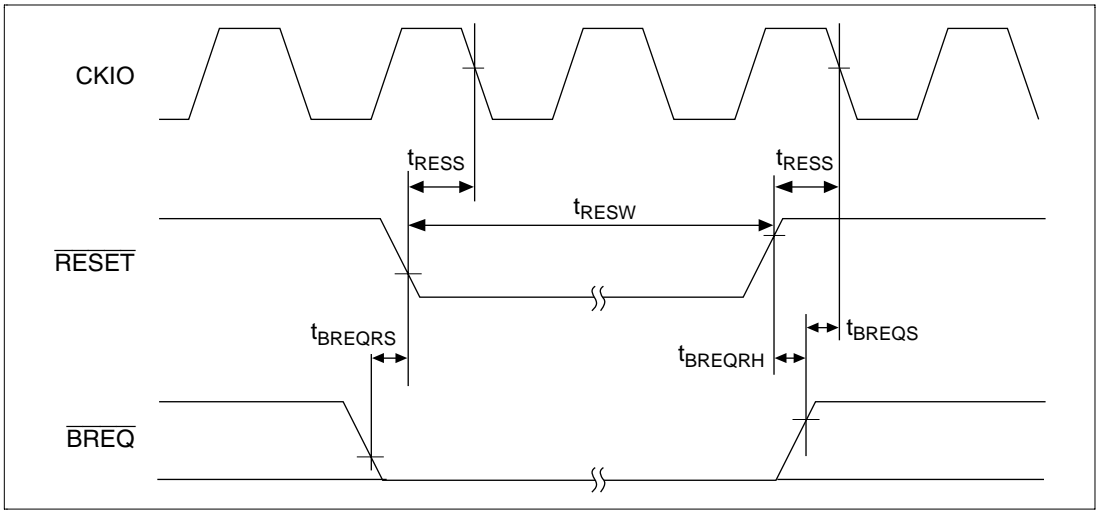


Figure 17.11 Manual Reset Input Timing

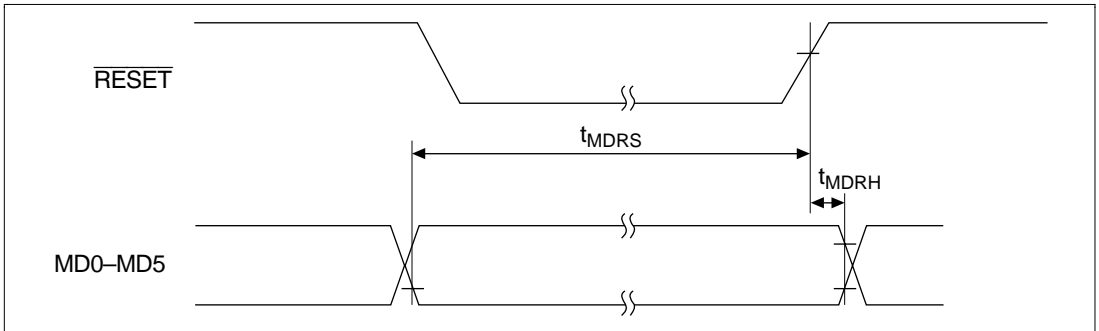


Figure 17.12 Mode Input Timing

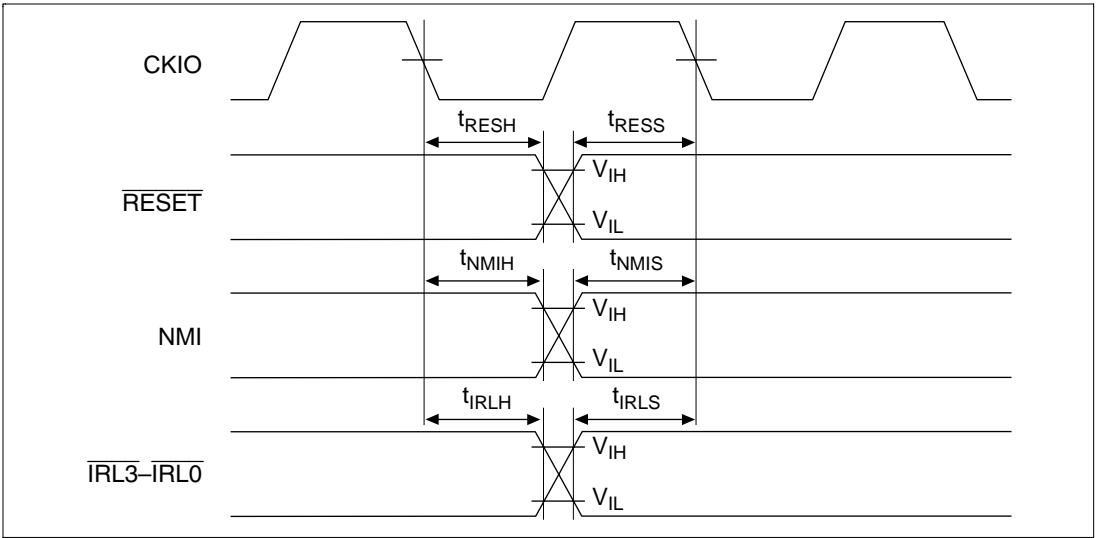


Figure 17.13 Interrupt Signal Input Timing

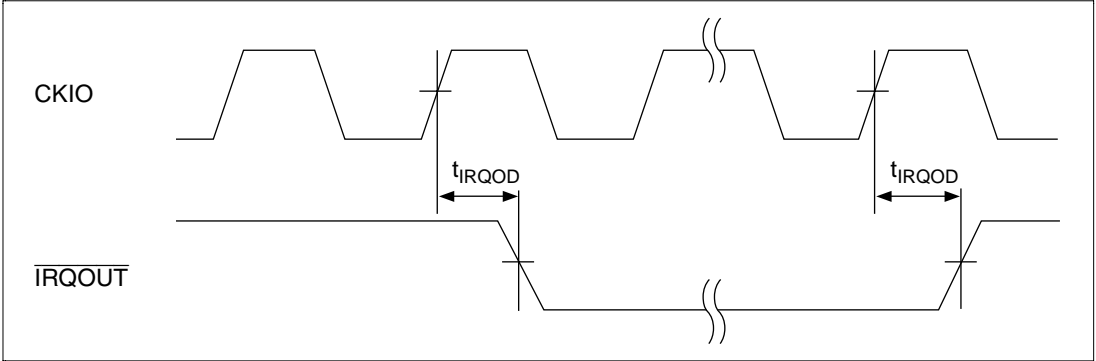


Figure 17.14 \overline{IRQOUT} Timing

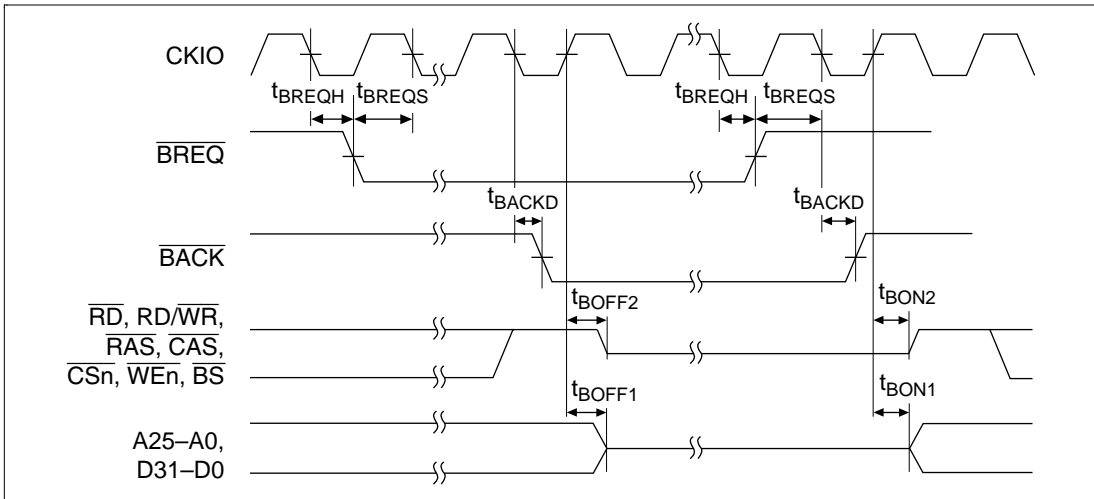


Figure 17.15 Bus Release Timing

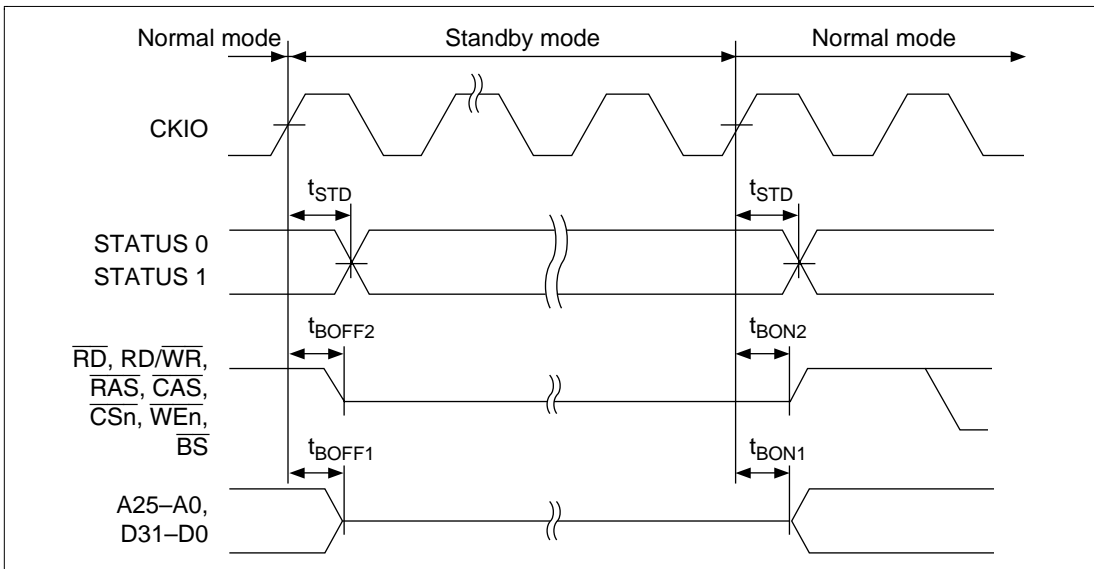


Figure 17.16 Pin Drive Timing for Standby Mode

17.3.3 AC Bus Timing Specifications

Table 17.7 Bus Timing (Conditions: Clock Mode 0/1/2/7, $V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20$ to $+75^\circ\text{C}$)

Item	Symbol	-60^{*1}		Unit	Figure
		Min	Max		
Address delay time	t_{AD}	1.5	13	ns	17.17–17.30, 17.34–17.41, 17.44–17.48, 17.52–17.58
Address setup time	t_{AS}	0	—	ns	17.23–17.30, 17.45–17.48
Address hold time	t_{AH}	0	—	ns	17.17–17.30, 17.45–17.48
\overline{BS} delay time	t_{BSD}	—	12	ns	17.17–17.30, 17.34–17.41, 17.45–17.48, 17.52–17.58
\overline{CS} delay time 1	t_{CSD1}	1.5	12	ns	17.17–17.30, 17.34–17.44, 17.52–17.58
\overline{CS} delay time 2	t_{CSD2}	—	12	ns	17.17–17.22
Read write delay time	t_{RWD}	1.5	12	ns	17.17–17.48, 17.52–17.56
Read write setup time	t_{RWS}	0	—	ns	17.45–17.48
Read write hold time	t_{RWH}	0	—	ns	17.17–17.30, 17.45–17.48
Read strobe delay time	t_{RSD}	—	12	ns	17.17–17.22, 17.52–17.56
Read data setup time 1	t_{RDS1}	12	—	ns	17.17–17.26, 17.45–17.48, 17.52–17.58
Read data setup time 2	t_{RDS2}	8	—	ns	17.27–17.30, 17.34–17.37, 17.41
Read data hold time 1	t_{RDH1}	0	—	ns	17.17–17.26, 17.45–17.48, 17.52–17.58
Read data hold time 2	t_{RDH2}	3	—	ns	17.27–17.30, 17.34–17.37, 17.41
Write enable delay time	t_{WED}	—	12	ns	17.17–17.19, 17.45–17.48, 17.52, 17.53
Write data delay time 1	t_{WDD1}	—	15	ns	17.17–17.19, 17.52, 17.53, 17.56–17.58
Write data delay time 2	t_{WDD2}	—	13	ns	17.23–17.30, 17.38–17.40, 17.45–17.48, 17.58
Write data setup time	t_{WDS}	0	—	ns	17.23–17.30, 17.45–17.48
Write data hold time 1	t_{WDH1}	0	—	ns	17.17–17.19, 17.23–17.30, 17.45–17.48, 17.52–17.57
Write data hold time 2	t_{WDH2}	1.5	—	ns	17.38–17.40
Write data hold time 3	t_{WDH3}	0	—	ns	17.17–17.19, 17.23–17.30, 17.45–17.48, 17.58
Write data hold time 4	t_{WDH4}	0	—	ns	17.52, 17.53, 17.56–17.58

Table 17.7 Bus Timing (Conditions: Clock Mode 0/1/2/7, $V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20$ to $+75^\circ\text{C}$) (cont)

Item	Symbol	-60* ¹		Unit	Figure
		Min	Max		
$\overline{\text{WAIT}}$ setup time * ²	t_{WTS}	12	—	ns	17.18–17.22, 17.53, 17.55, 17.57, 17.58
$\overline{\text{WAIT}}$ hold time * ²	t_{WTH}	4	—	ns	17.18–17.22, 17.53, 17.55, 17.57, 17.58
$\overline{\text{RAS}}$ delay time 1	t_{RASD1}	—	13	ns	17.23–17.33
$\overline{\text{RAS}}$ delay time 2	t_{RASD2}	1.5	13	ns	17.27–17.30, 17.34–17.44
$\overline{\text{CAS}}$ delay time 1	t_{CASD1}	—	13	ns	17.23–17.33
$\overline{\text{CAS}}$ delay time 2	t_{CASD2}	1.5	13	ns	17.34–17.44
DQM delay time	t_{DQMD}	1.5	12	ns	17.34–17.41
CKE delay time	t_{CKED}	—	12	ns	17.43
$\overline{\text{CE}}$ delay time	t_{CED}	—	13	ns	17.45–17.48
$\overline{\text{OE}}$, $\overline{\text{RFSH}}$ delay time	t_{OED}	—	13	ns	17.45–17.51
$\overline{\text{ICIOR}}$ delay time	t_{ICRSD}	—	12	ns	17.56–17.58
$\overline{\text{ICIOR}}$ delay time	t_{ICWSD}	—	12	ns	17.56–17.58
$\overline{\text{IOIS16}}$ setup time	t_{IO16S}	12	—	ns	17.57, 17.58
$\overline{\text{IOIS16}}$ hold time	t_{IO16H}	4	—	ns	17.57, 17.58

Notes: 1. Upper limit of external bus clock is 60 MHz.

2. $\overline{\text{WAIT}}$ is a synchronous signal. Operation cannot be guaranteed if the setup times shown here are not observed.

Table 17.8 Bus Timing (Conditions: Clock Mode 3/4, $V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20$ to $+75^\circ\text{C}$)

Item	Symbol	Min	Max	Unit	Figure
Address delay time	t_{AD}	1.5	20	ns	17.17–17.30, 17.34–17.41, 17.44–17.48, 17.52–17.58
Address setup time	t_{AS}	0	—	ns	17.23–17.30, 17.45–17.48
Address hold time	t_{AH}	20	—	ns	17.17–17.30, 17.45–17.48
\overline{BS} delay time	t_{BSD}	—	19	ns	17.17–17.30, 17.34–17.41, 17.45–17.48, 17.52–17.58
\overline{CS} delay time 1	t_{CSD1}	1.5	19	ns	17.17–17.30, 17.34–17.44, 17.52–17.58
\overline{CS} delay time 2	t_{CSD2}	—	20	ns	17.17–17.22
Read write delay time	t_{RWD}	1.5	19	ns	17.17–17.48, 17.52–17.56
Read write setup time	t_{RWS}	0	—	ns	17.45–17.48
Read write hold time	t_{RWH}	0	—	ns	17.17–17.30, 17.45–17.48
Read strobe delay time	t_{RSD}	—	20	ns	17.17–17.22, 17.52–17.56
Read data setup time 1	t_{RDS1}	12	—	ns	17.17–17.26, 17.45–17.48, 17.52–17.58
Read data setup time 2	t_{RDS2}	12	—	ns	17.27–17.30, 17.34–17.37, 17.41
Read data hold time 1	t_{RDH1}	0	—	ns	17.17–17.26, 17.45–17.48, 17.52–17.58
Read data hold time 2	t_{RDH2}	8	—	ns	17.27–17.30, 17.34–17.37, 17.41
Write enable delay time	t_{WED}	—	20	ns	17.17–17.19, 17.45–17.48, 17.52, 17.53
Write data delay time 1	t_{WDD1}	—	25	ns	17.17–17.19, 17.52, 17.53, 17.56–17.58
Write data delay time 2	t_{WDD2}	—	19	ns	17.23–17.30, 17.38–17.40, 17.45–17.48, 17.58
Write data setup time	t_{WDS}	0	—	ns	17.23–17.30, 17.45–17.48
Write data hold time 1	t_{WDH1}	0	—	ns	17.17–17.19, 17.23–17.30, 17.45–17.48, 17.52–17.57
Write data hold time 2	t_{WDH2}	1.5	—	ns	17.38–17.40
Write data hold time 3	t_{WDH3}	0	—	ns	17.17–17.19, 17.23–17.30, 17.45–17.48, 17.58
Write data hold time 4	t_{WDH4}	0	—	ns	17.52, 17.53, 17.56–17.58

Table 17.8 Bus Timing (Conditions: Clock Mode 3/4, $V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20$ to $+75^\circ\text{C}$) (cont)

Item	Symbol	Min	Max	Unit	Figure
WAIT setup time	t_{WTS}	12	—	ns	17.18–17.22, 17.53, 17.55, 17.57, 17.58
WAIT hold time	t_{WTH}	8	—	ns	17.18–17.22, 17.53, 17.55, 17.57, 17.58
$\overline{\text{RAS}}$ delay time 1	t_{RASD1}	—	20	ns	17.23–17.33
$\overline{\text{RAS}}$ delay time 2	t_{RASD2}	1.5	19	ns	17.27–17.30, 17.34–17.44
$\overline{\text{CAS}}$ delay time 1	t_{CASD1}	—	20	ns	17.23–17.33
$\overline{\text{CAS}}$ delay time 2	t_{CASD2}	1.5	19	ns	17.34–17.44
DQM delay time	t_{DQMD}	1.5	19	ns	17.34–17.41
CKE delay time	t_{CKED}	—	19	ns	17.43
$\overline{\text{CE}}$ delay time	t_{CED}	—	20	ns	17.45–17.48
$\overline{\text{OE}}$, $\overline{\text{RFSH}}$ delay time	t_{OED}	—	20	ns	17.45–17.51
$\overline{\text{ICIOR}}\overline{\text{D}}$ delay time	t_{ICRSD}	—	20	ns	17.56–17.58
$\overline{\text{ICIOR}}\overline{\text{W}}\overline{\text{R}}$ delay time	t_{ICWSD}	—	20	ns	17.56–17.58
$\overline{\text{IOIS16}}$ setup time	t_{IO16S}	12	—	ns	17.57, 17.58
$\overline{\text{IOIS16}}$ hold time	t_{IO16H}	8	—	ns	17.57, 17.58

17.3.4 Basic Timing

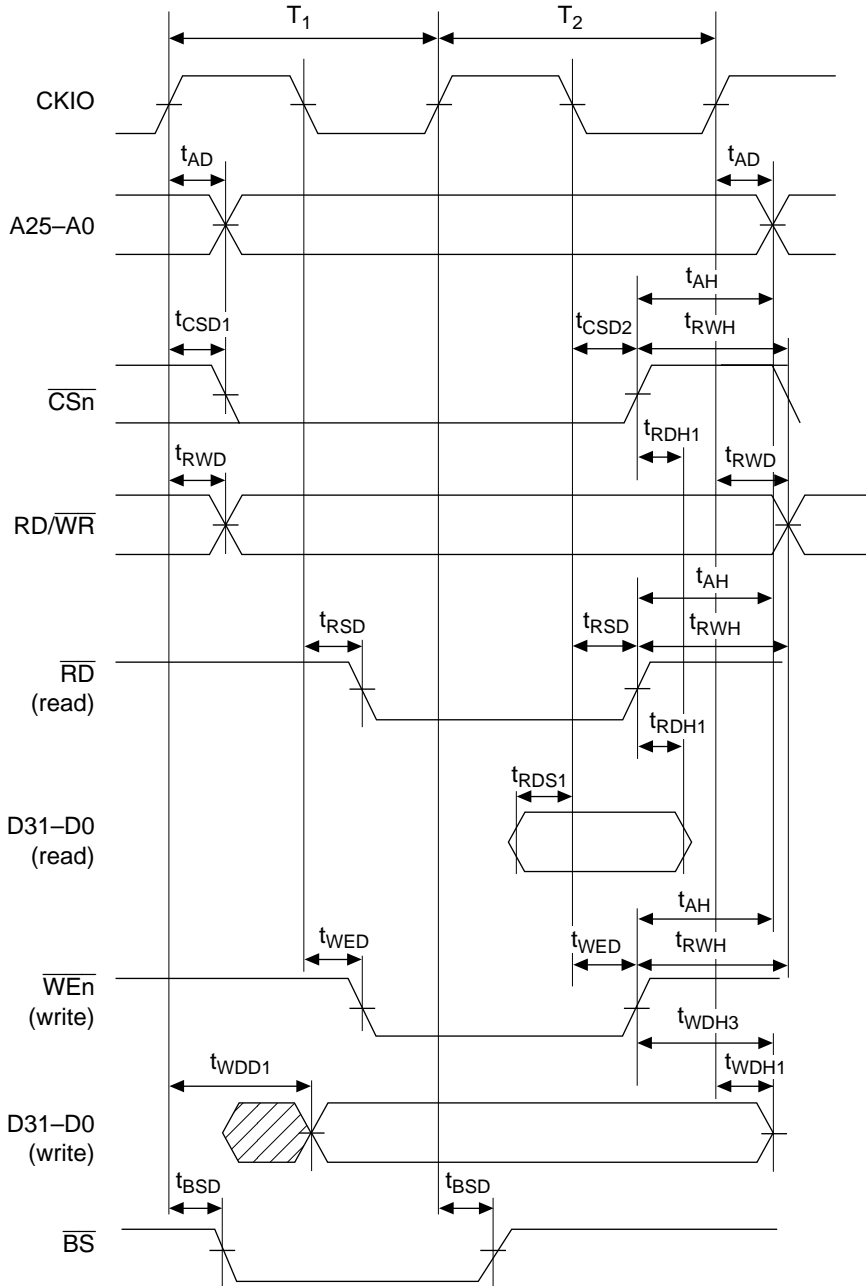


Figure 17.17 Basic Bus Cycle (No Wait)

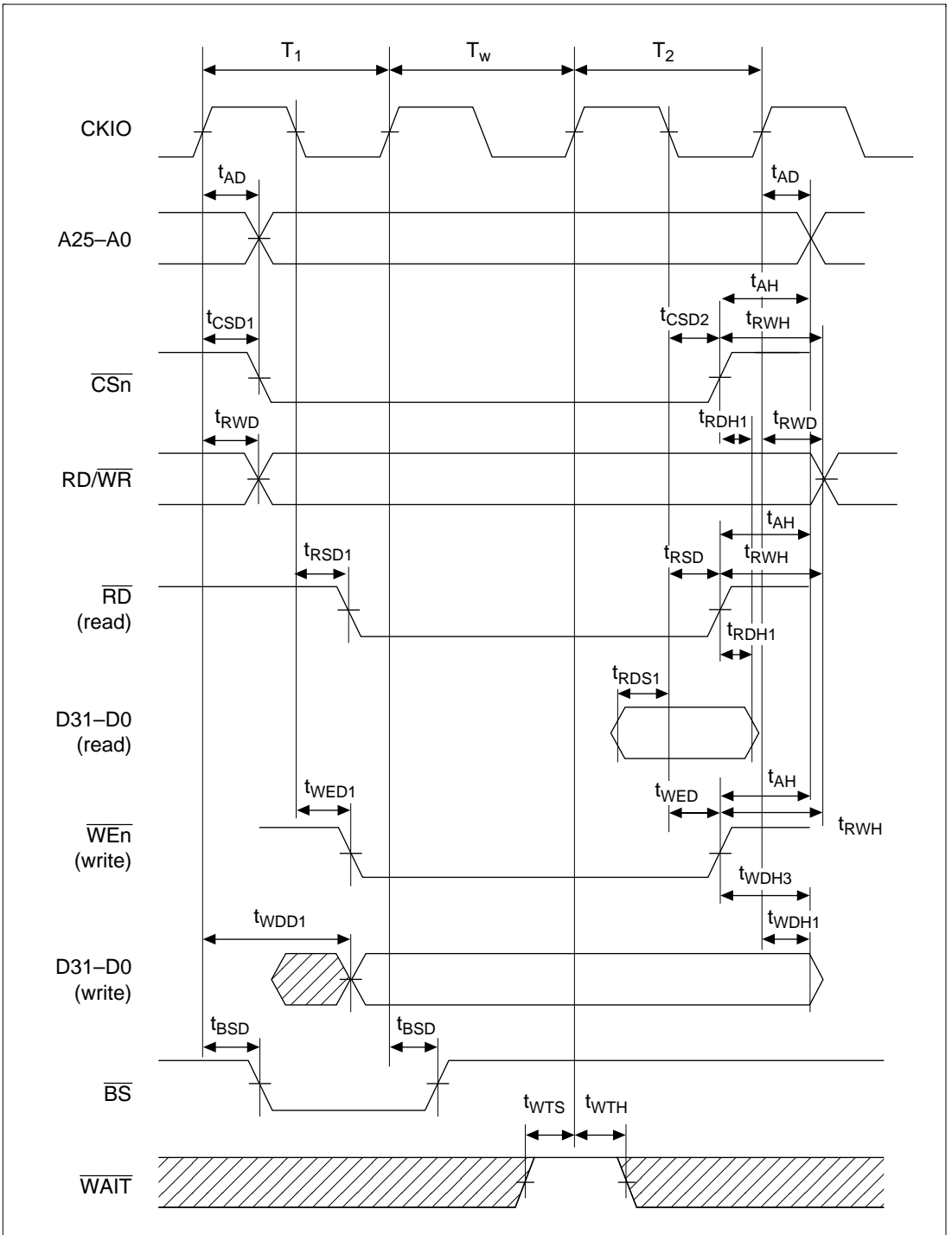


Figure 17.18 Basic Bus Cycle (1 Wait)

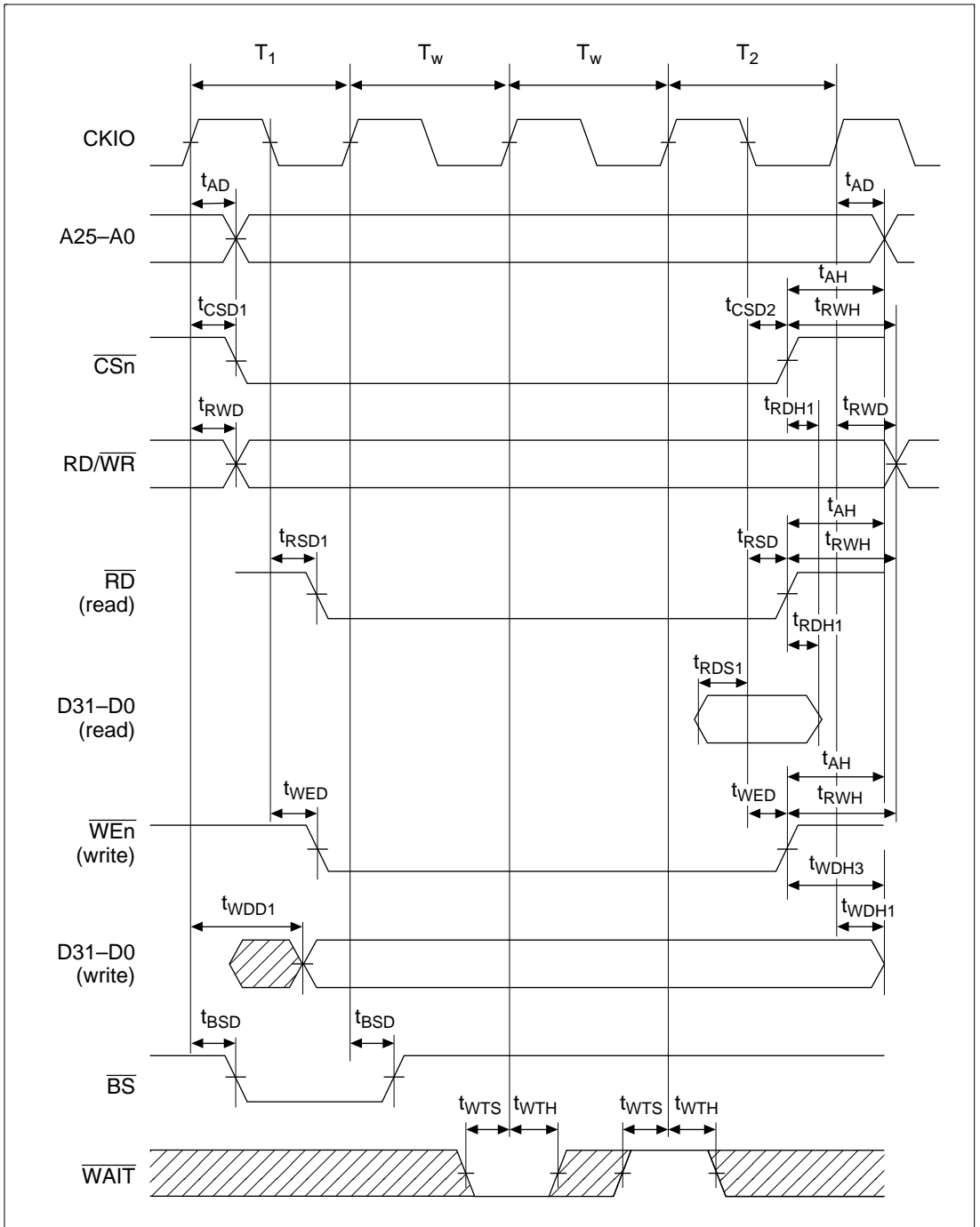
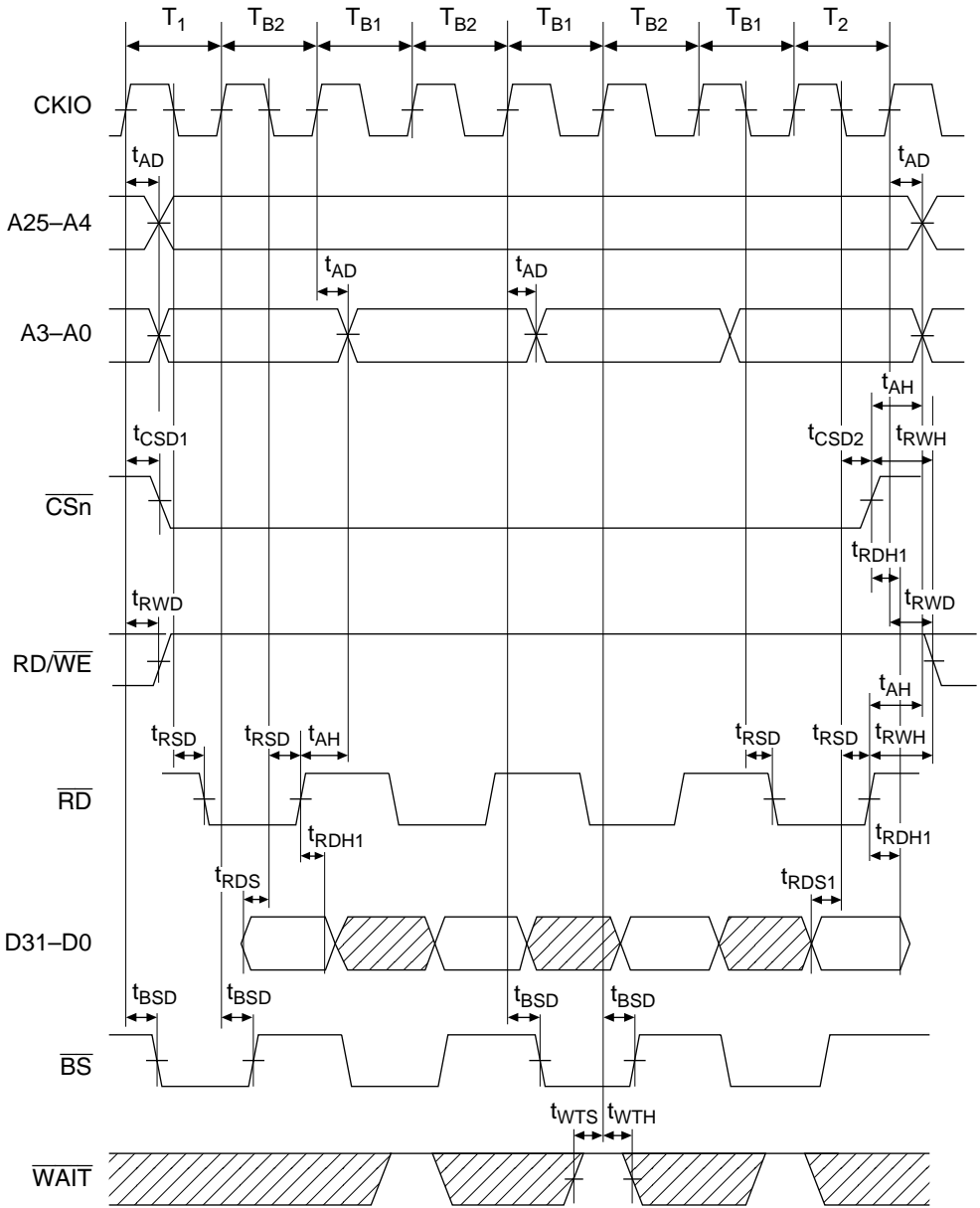


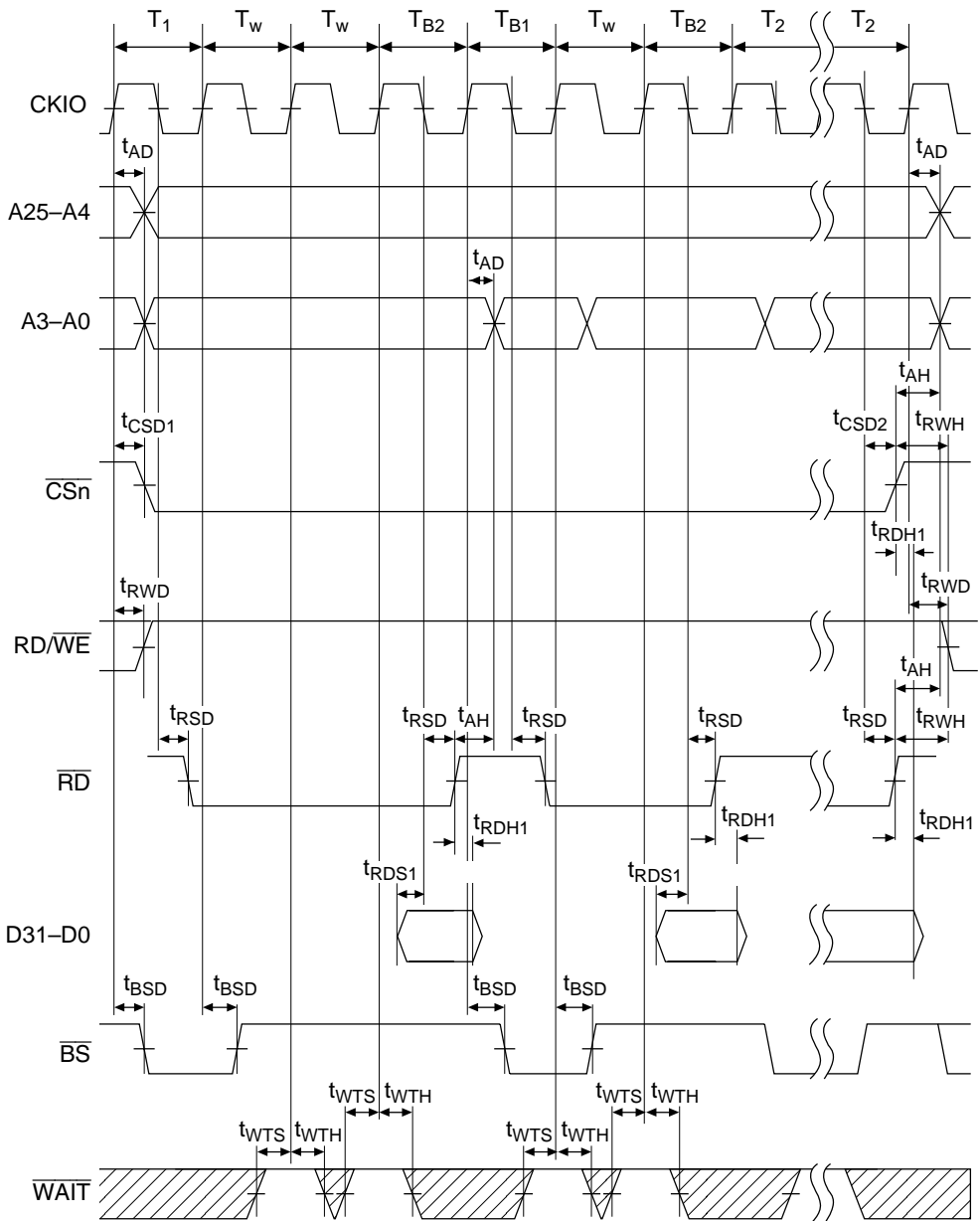
Figure 17.19 Basic Bus Cycle (External Wait)

17.3.5 Burst ROM Timing



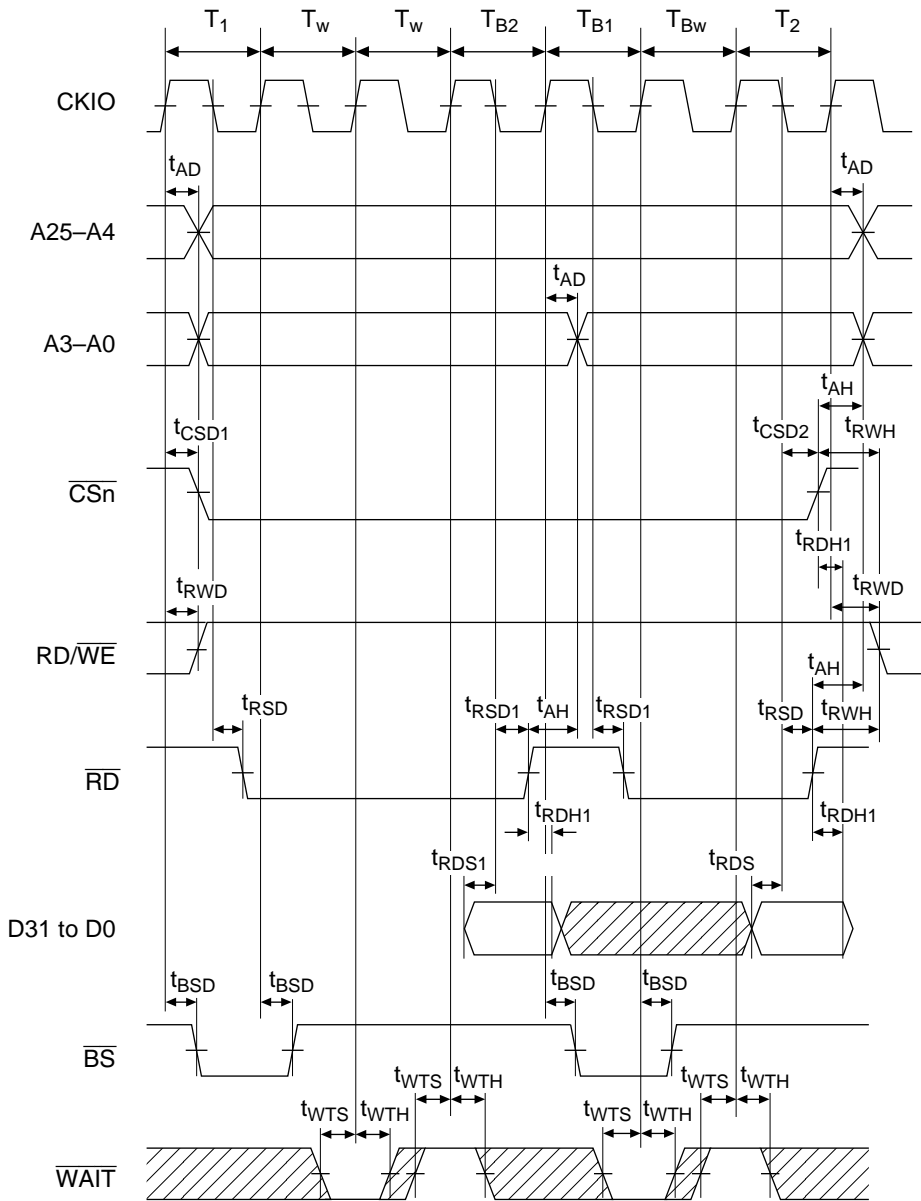
Note: In the write cycle, the basic bus cycle is performed.

Figure 17.20 Burst ROM Bus Cycle (No Wait)



Note: In the write cycle, the basic bus cycle is performed.

Figure 17.21 Burst ROM Bus Cycle (2 Waits)



Note: In the write cycle, the basic bus cycle is performed.

Figure 17.22 Burst ROM Bus Cycle (External Wait Input)

17.3.6 DRAM Timing

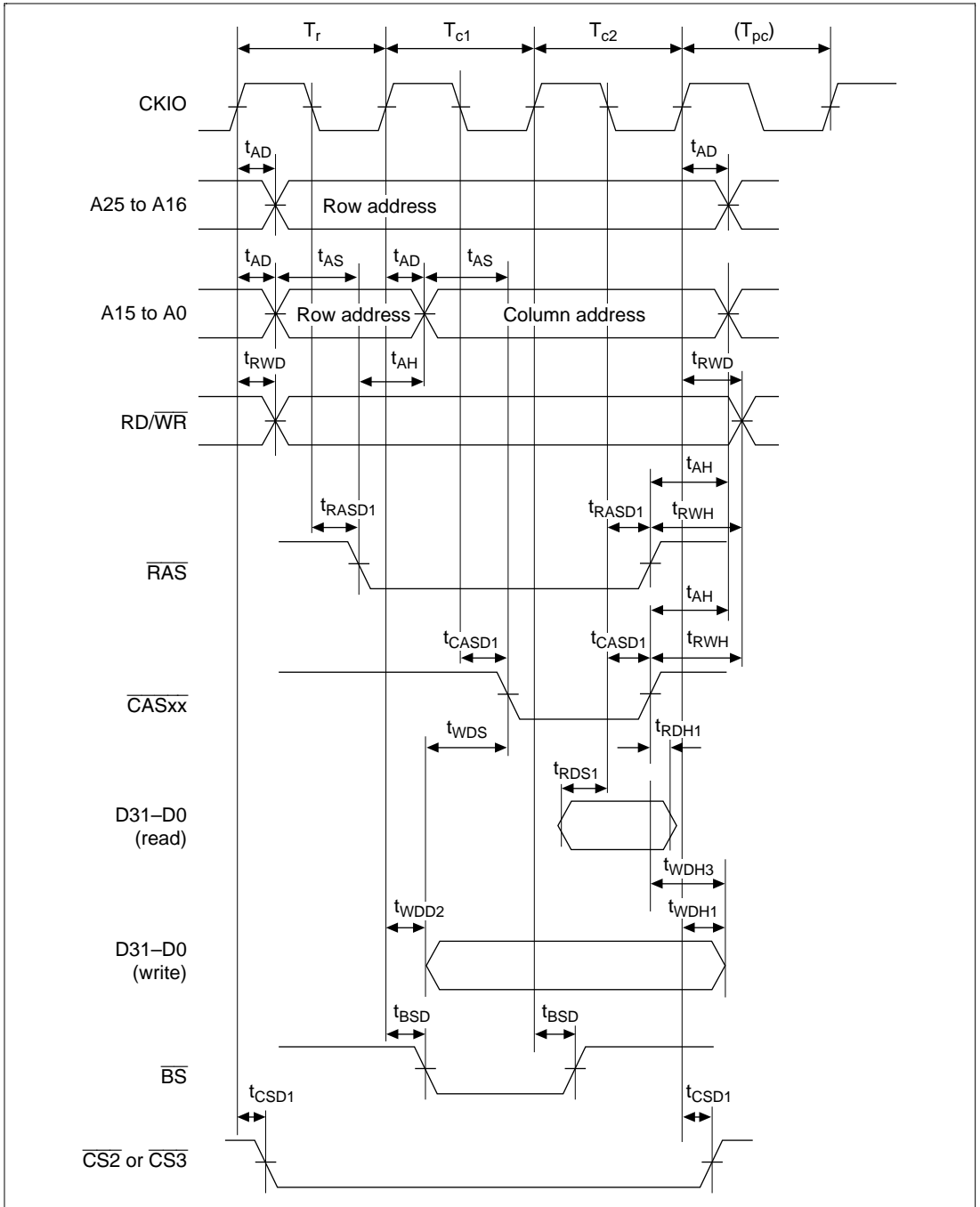


Figure 17.23 DRAM Bus Cycle (RCD = 0, AnW = 1, TPC = 0)

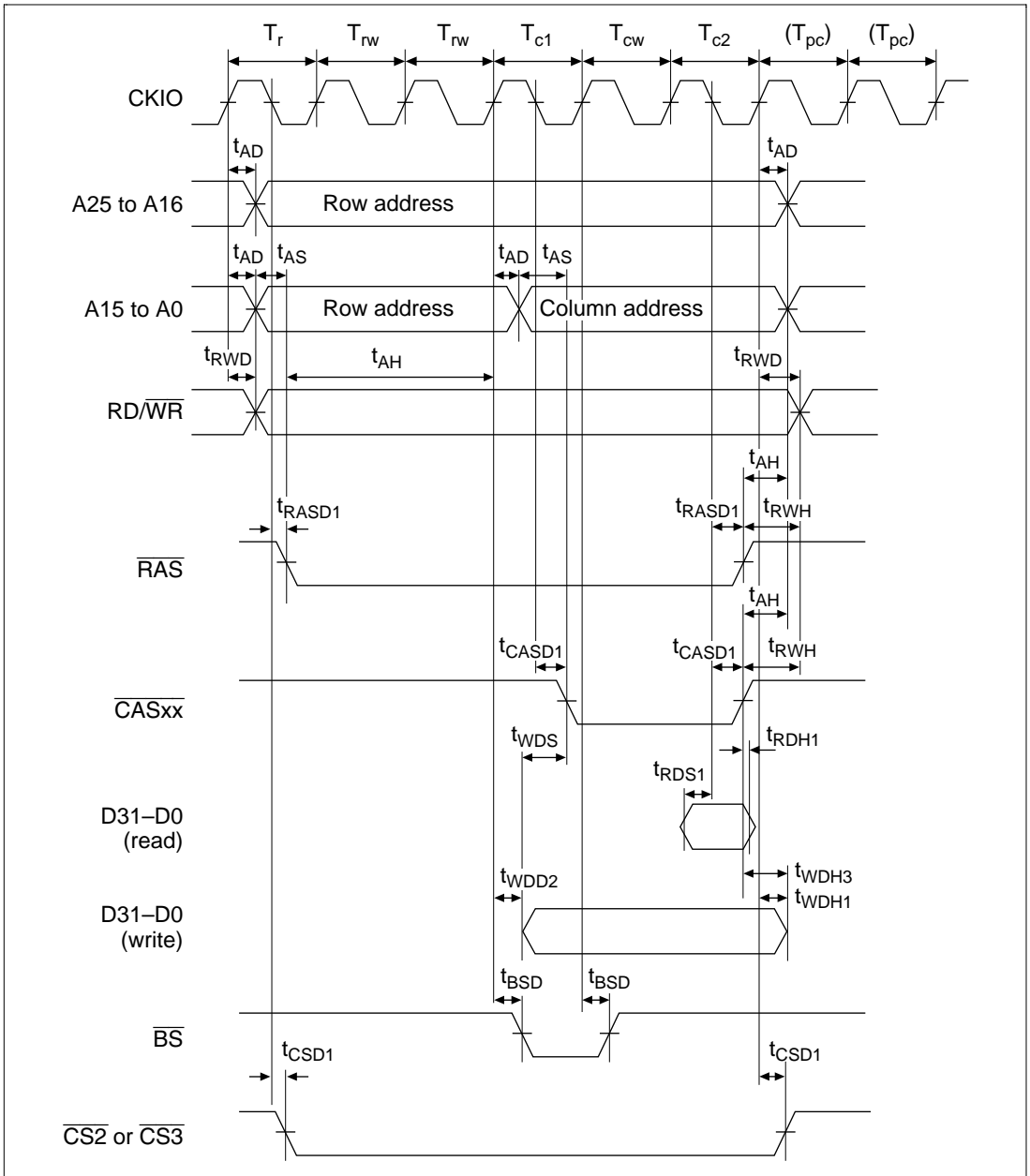


Figure 17.24 DRAM Bus Cycle (RCD = 2, AnW = 2, TPC = 1)

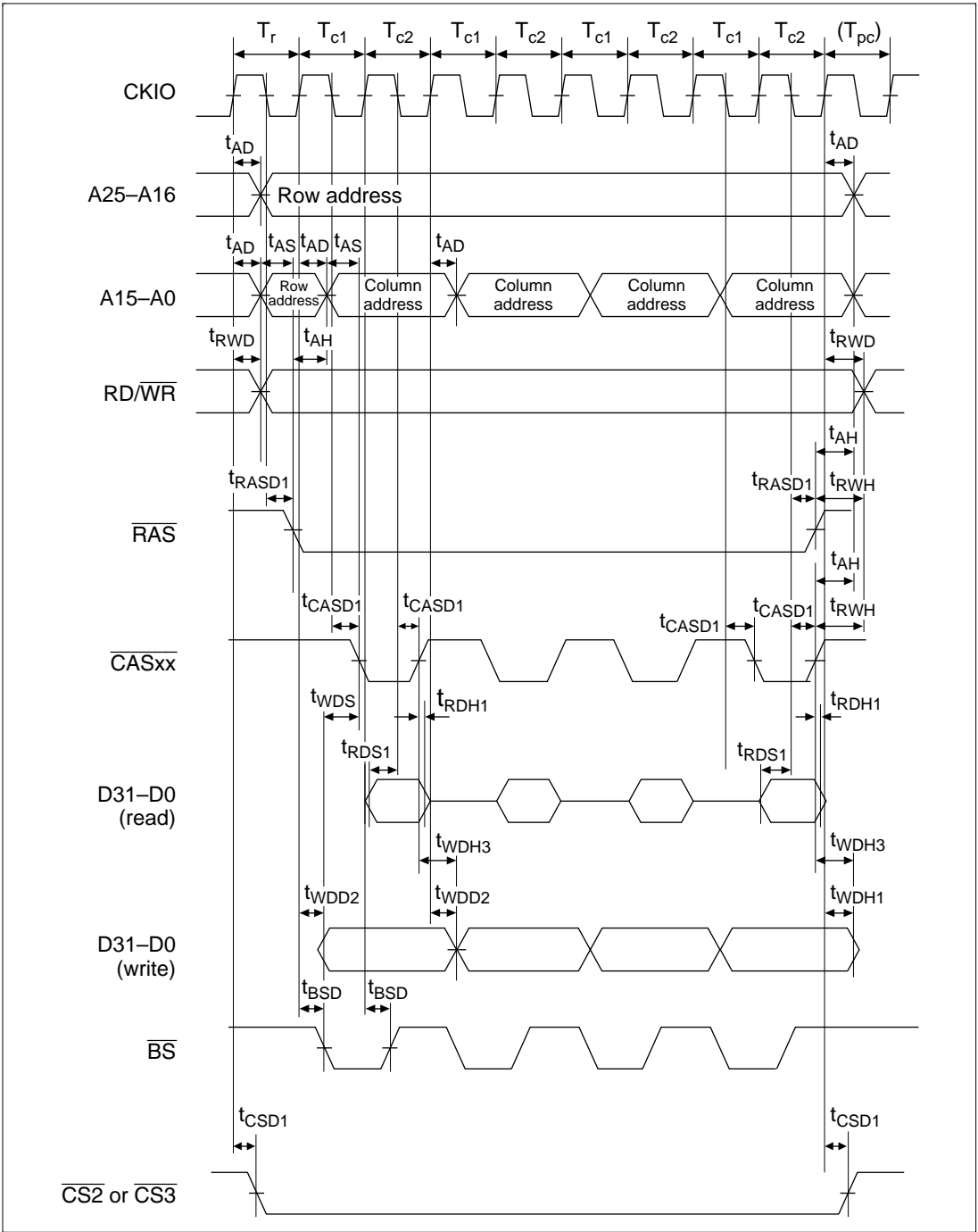


Figure 17.25 DRAM Burst Bus Cycle (RCD = 0, AnW = 1, TPC = 0)

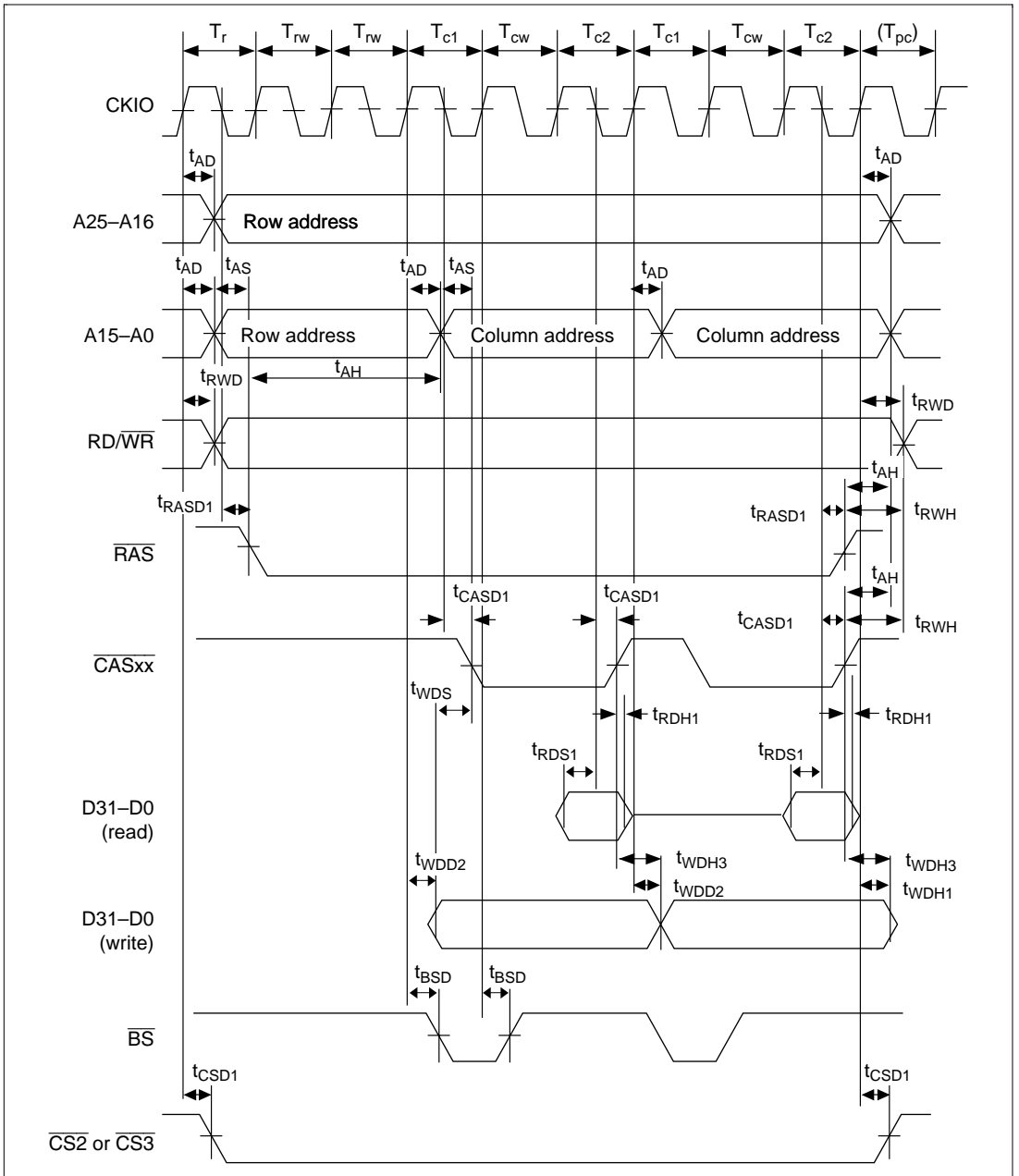


Figure 17.26 DRAM Burst Bus Cycle (RCD = 2, AnW = 2, TPC = 0)

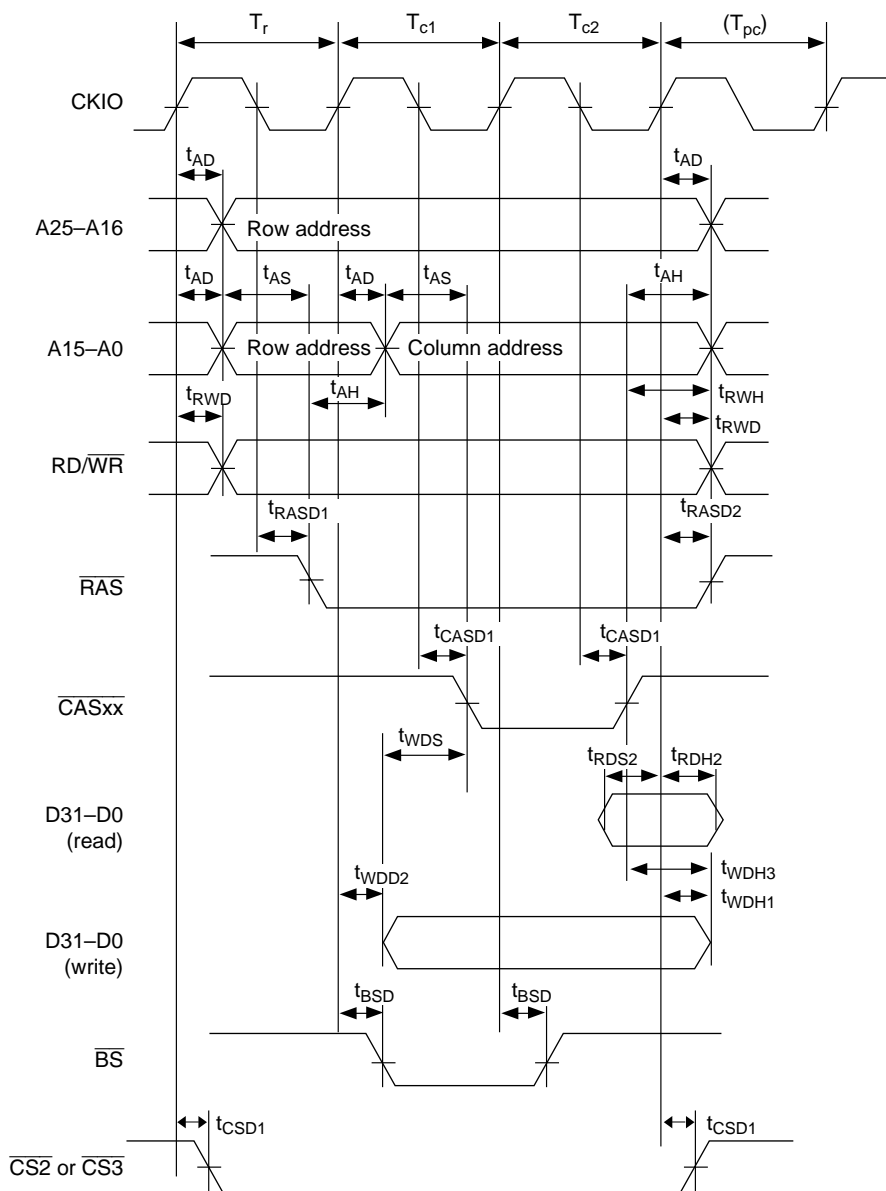


Figure 17.27 DRAM Bus Cycle (EDO Mode, RCD = 0, AnW = 1, TPC = 0)

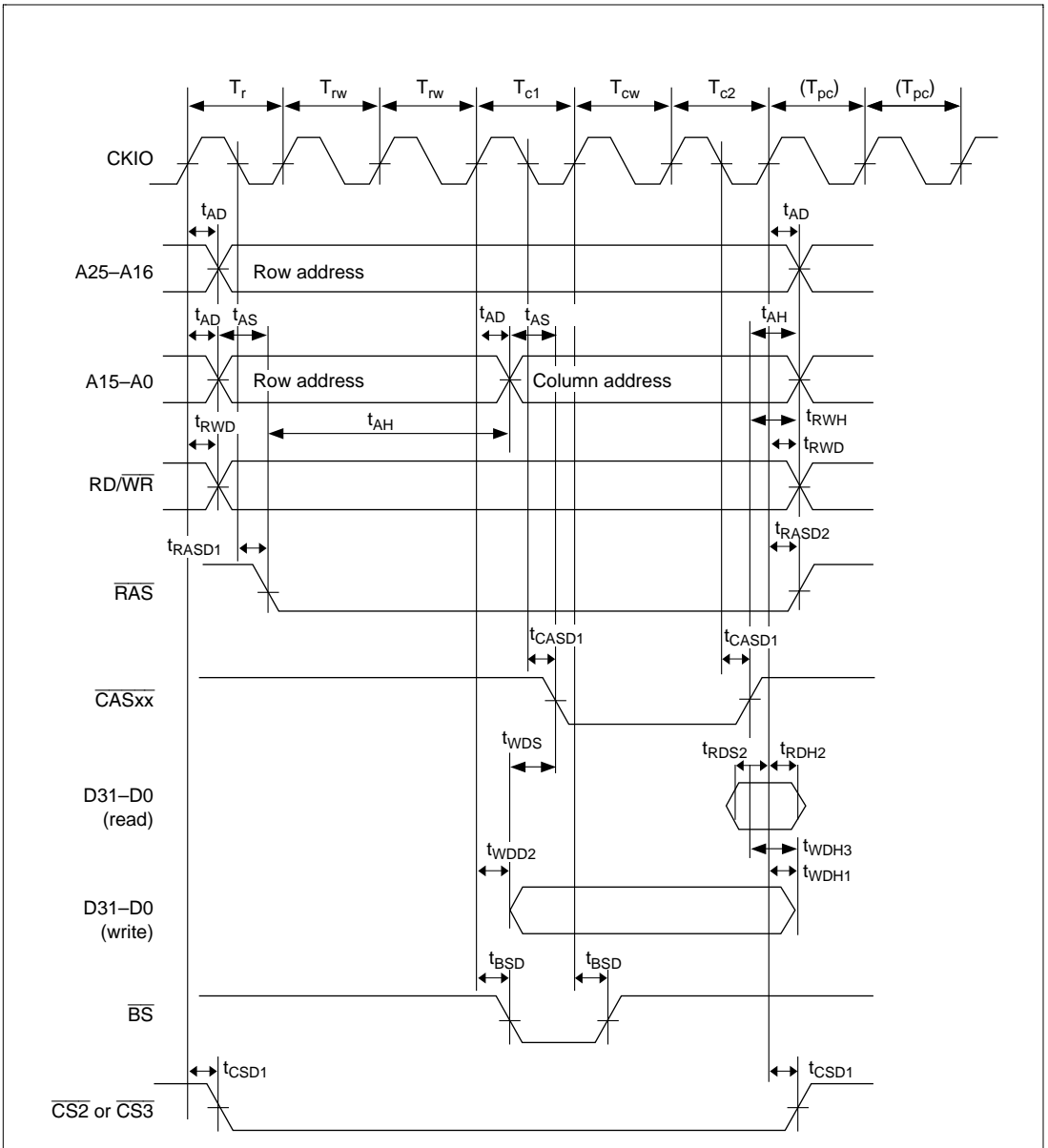


Figure 17.28 DRAM Bus Cycle (EDO Mode, RCD = 2, AnW = 2, TPC = 1)

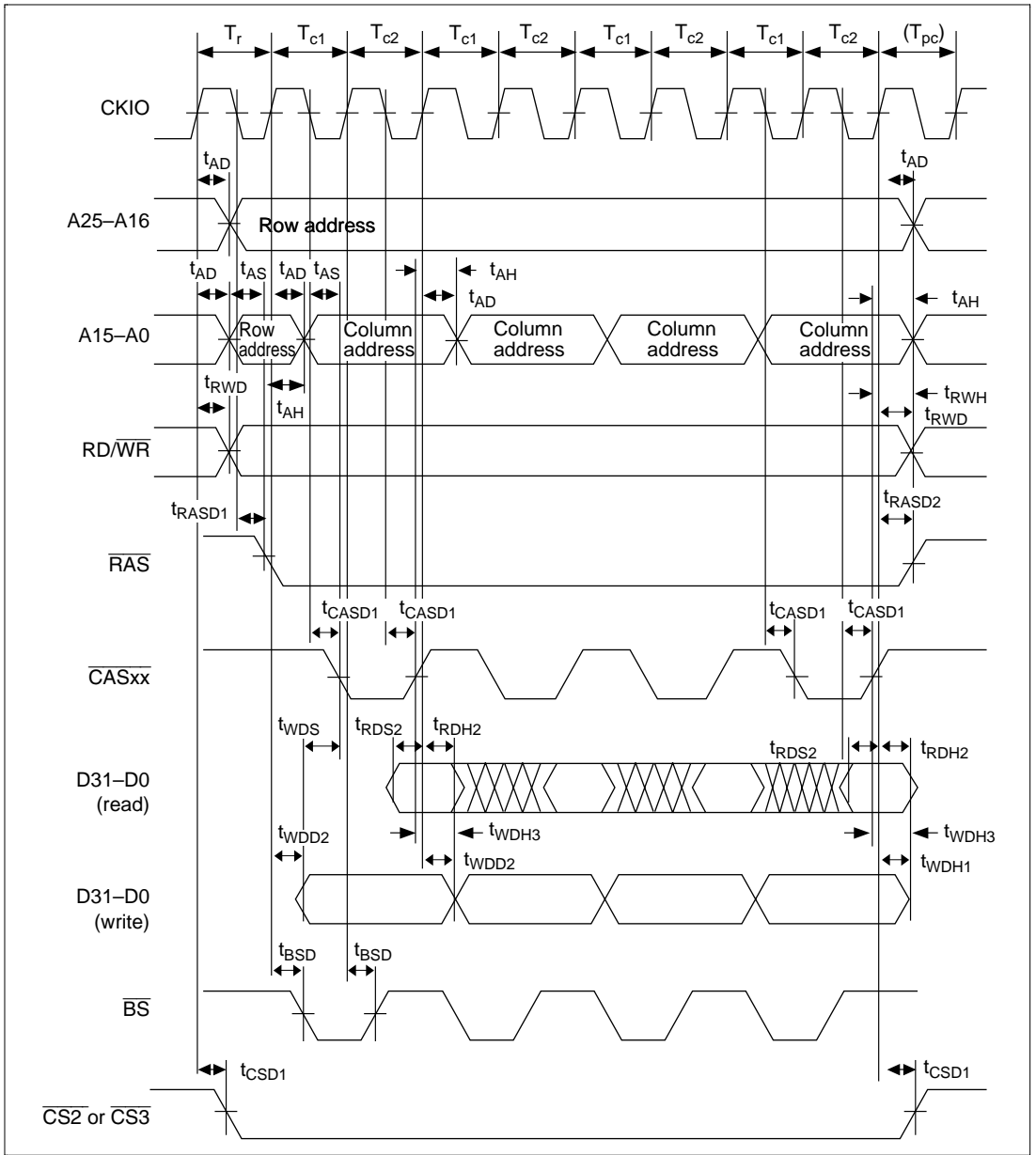


Figure 17.29 DRAM Burst Bus Cycle (EDO Mode, RCD = 0, AnW = 1, TPC = 0)

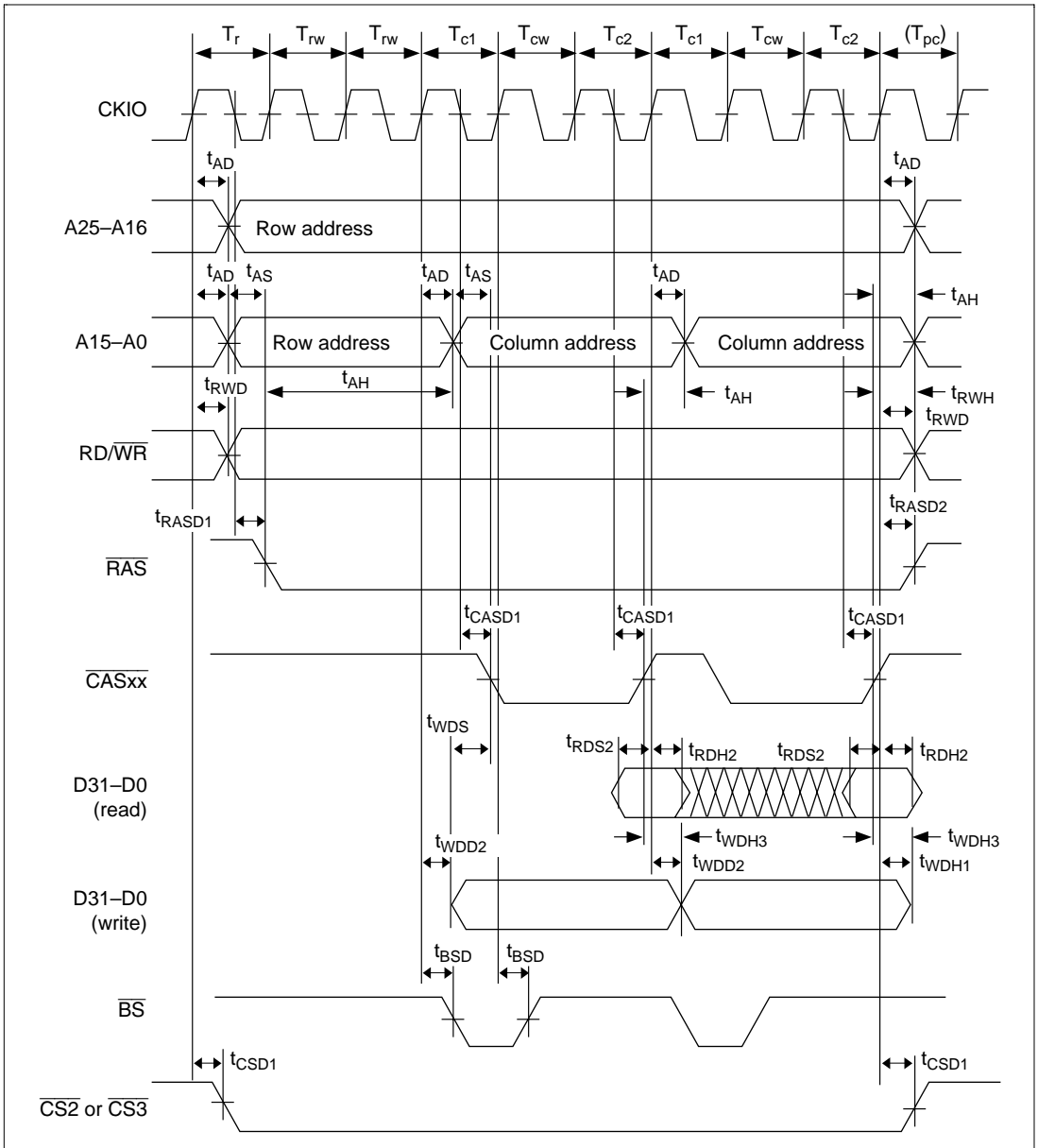


Figure 17.30 DRAM Burst Bus Cycle (EDO Mode, RCD = 2, AnW = 2, TPC = 0)

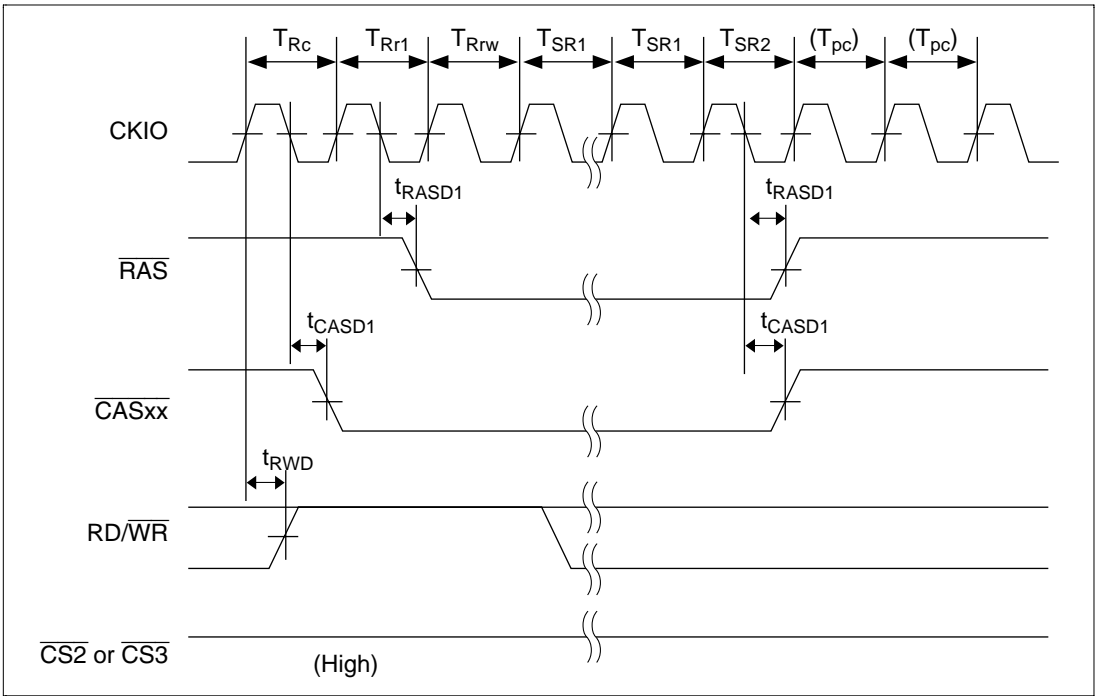


Figure 17.33 DRAM Self-Refresh Cycle (TPC = 0)

17.3.7 Synchronous DRAM Timing

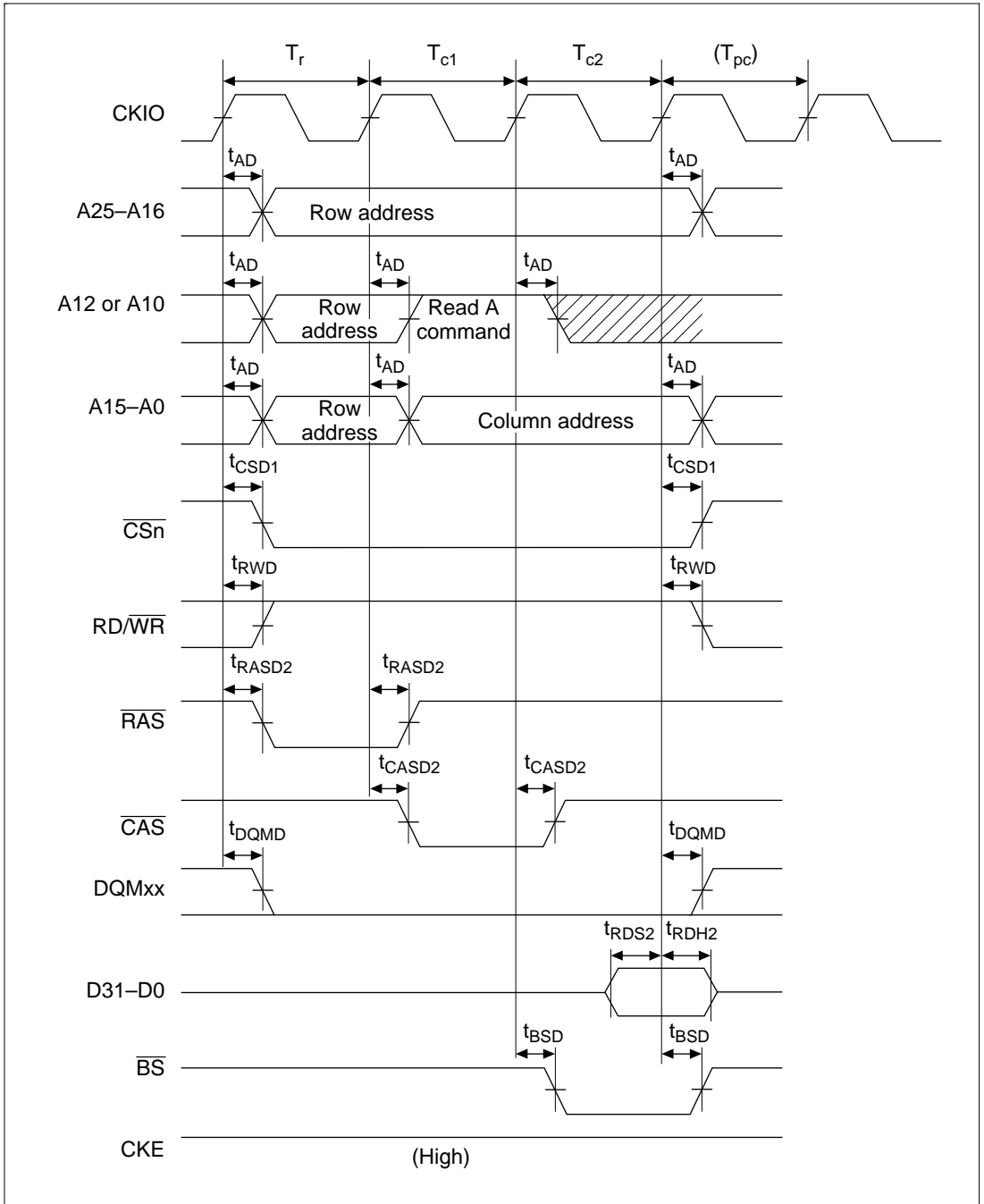


Figure 17.34 Synchronous DRAM Read Bus Cycle (RCD = 0, CAS Latency = 1, TPC = 0)

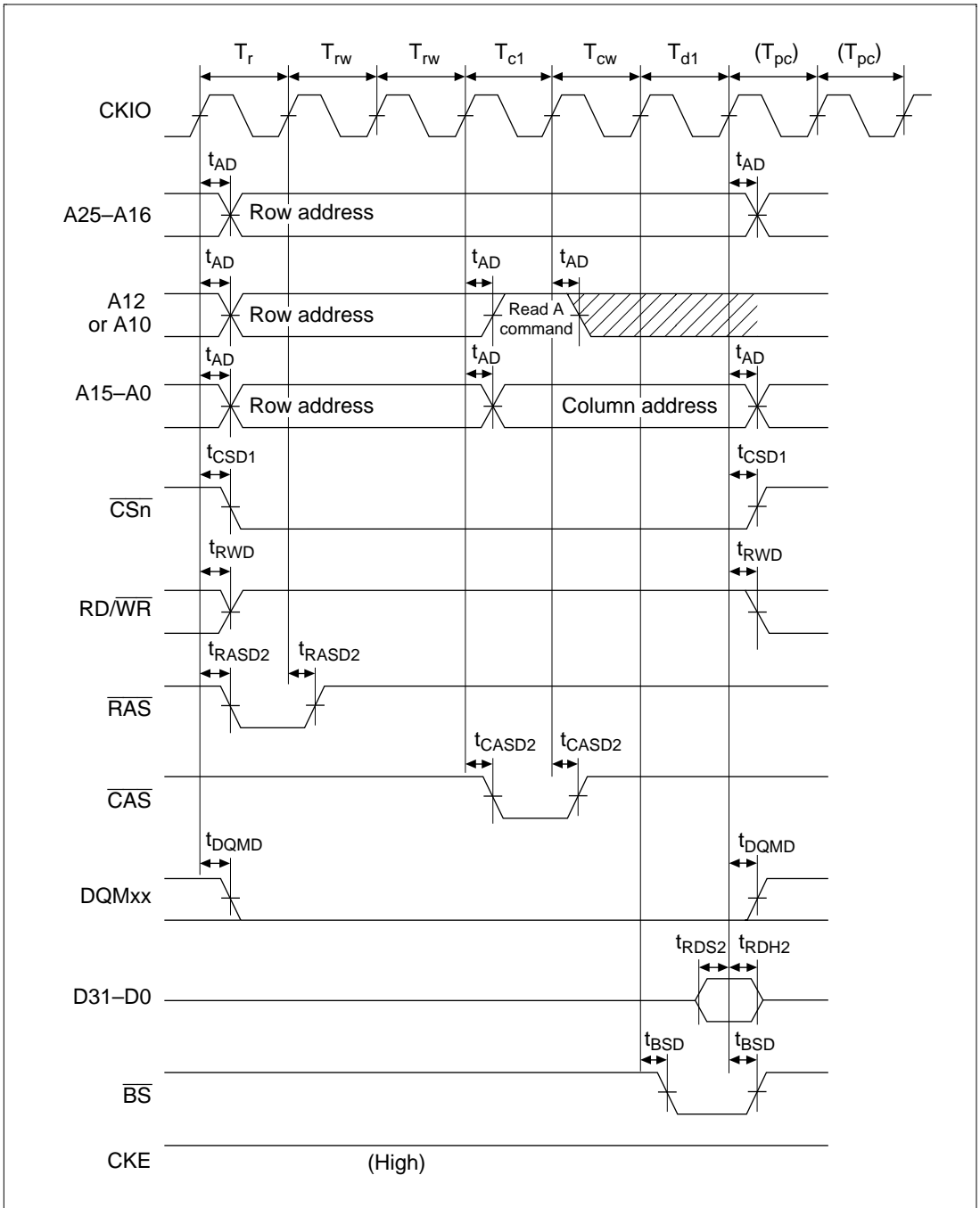


Figure 17.35 Synchronous DRAM Read Bus Cycle (RCD = 2, CAS Latency = 2, TPC = 1)

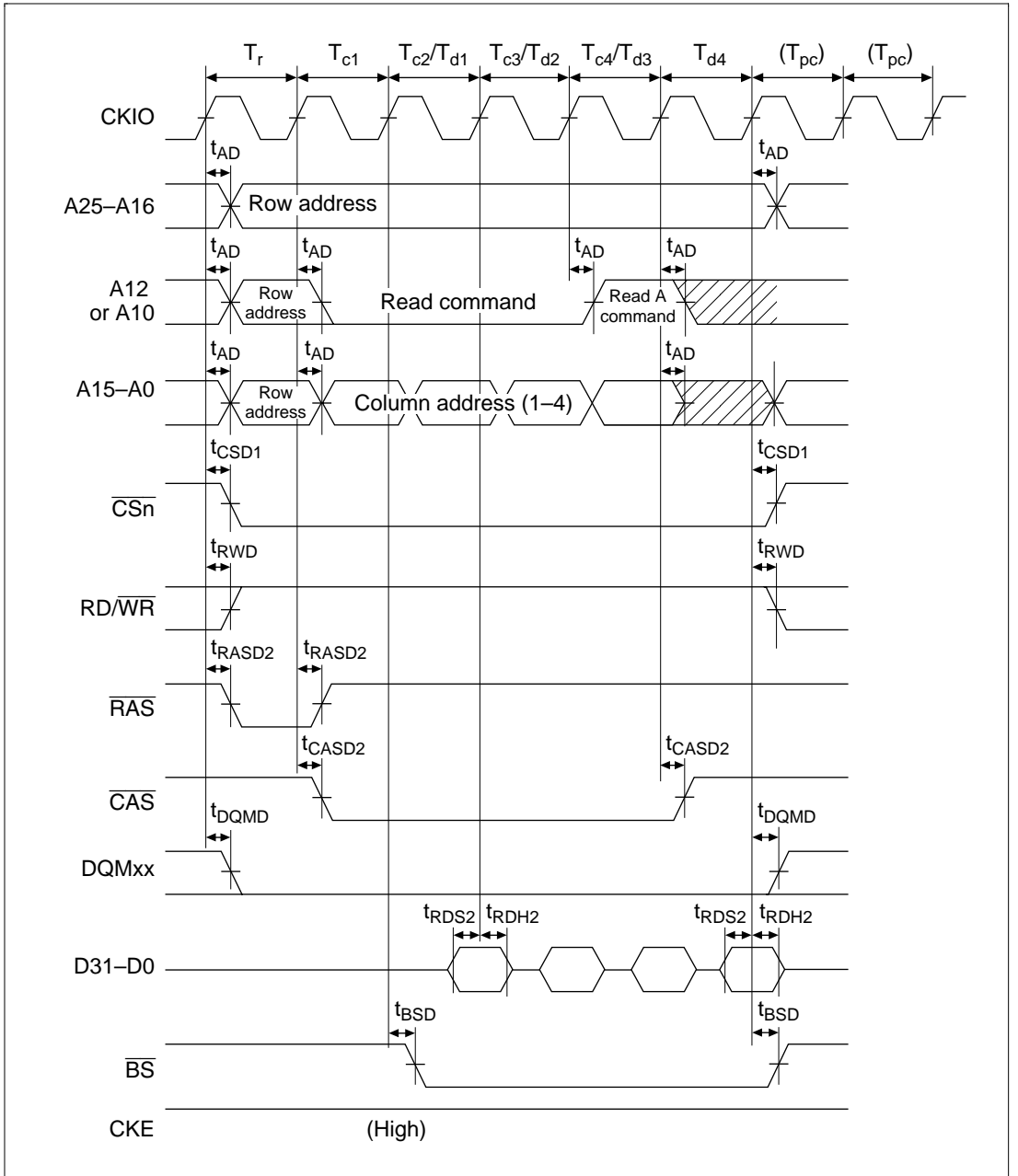


Figure 17.36 Synchronous DRAM Read Bus Cycle (Burst Read (Single Read × 4), RCD = 0, CAS Latency = 1, TPC = 1)

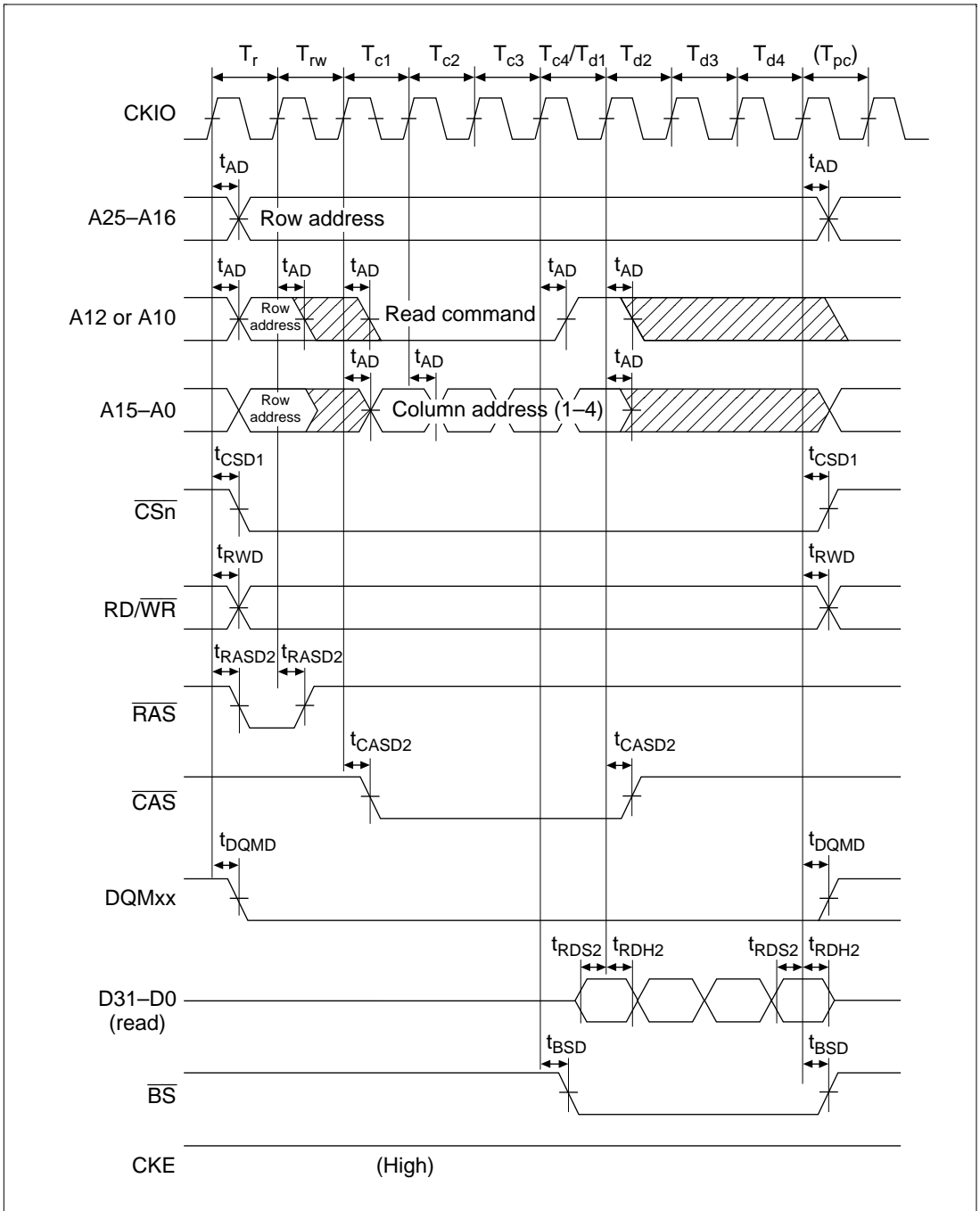


Figure 17.37 Synchronous DRAM Read Bus Cycle (Burst Read (Single Read \times 4), RCD = 1, CAS Latency = 3, TPC = 0)

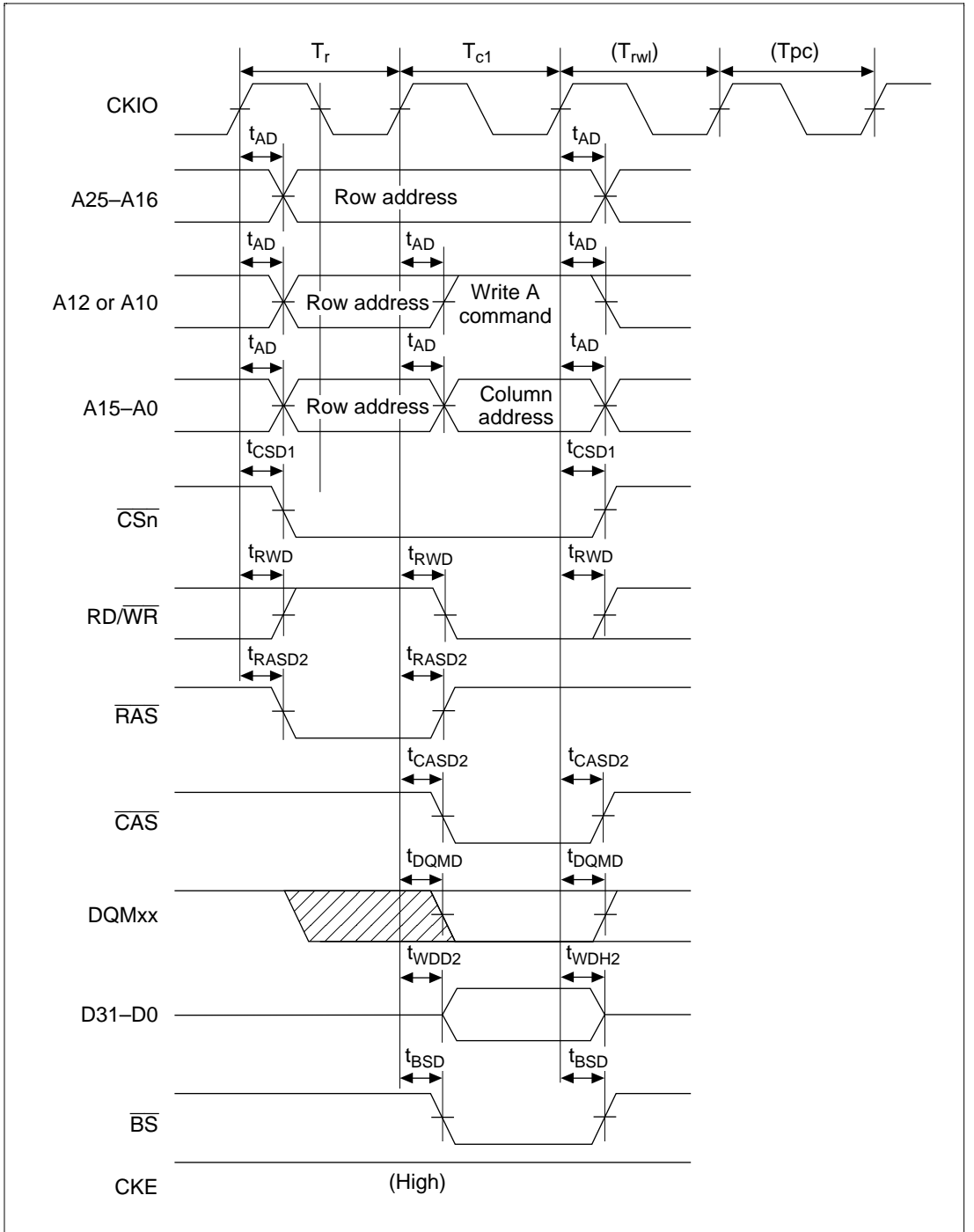


Figure 17.38 Synchronous DRAM Write Bus Cycle (RCD = 0, TPC = 0, TRWL = 0)

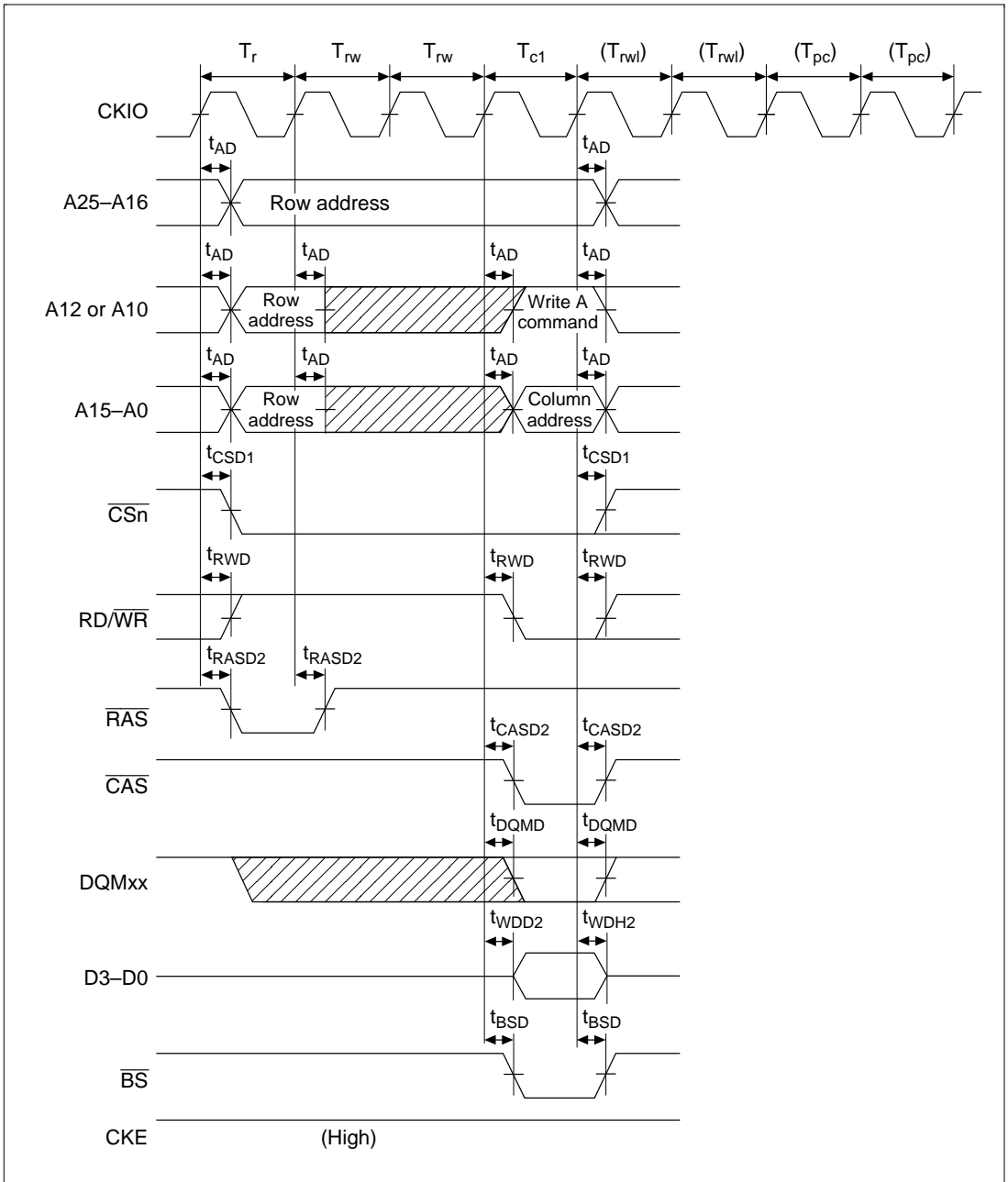


Figure 17.39 Synchronous DRAM Write Bus Cycle (RCD = 2, TPC = 1, TRWL = 1)

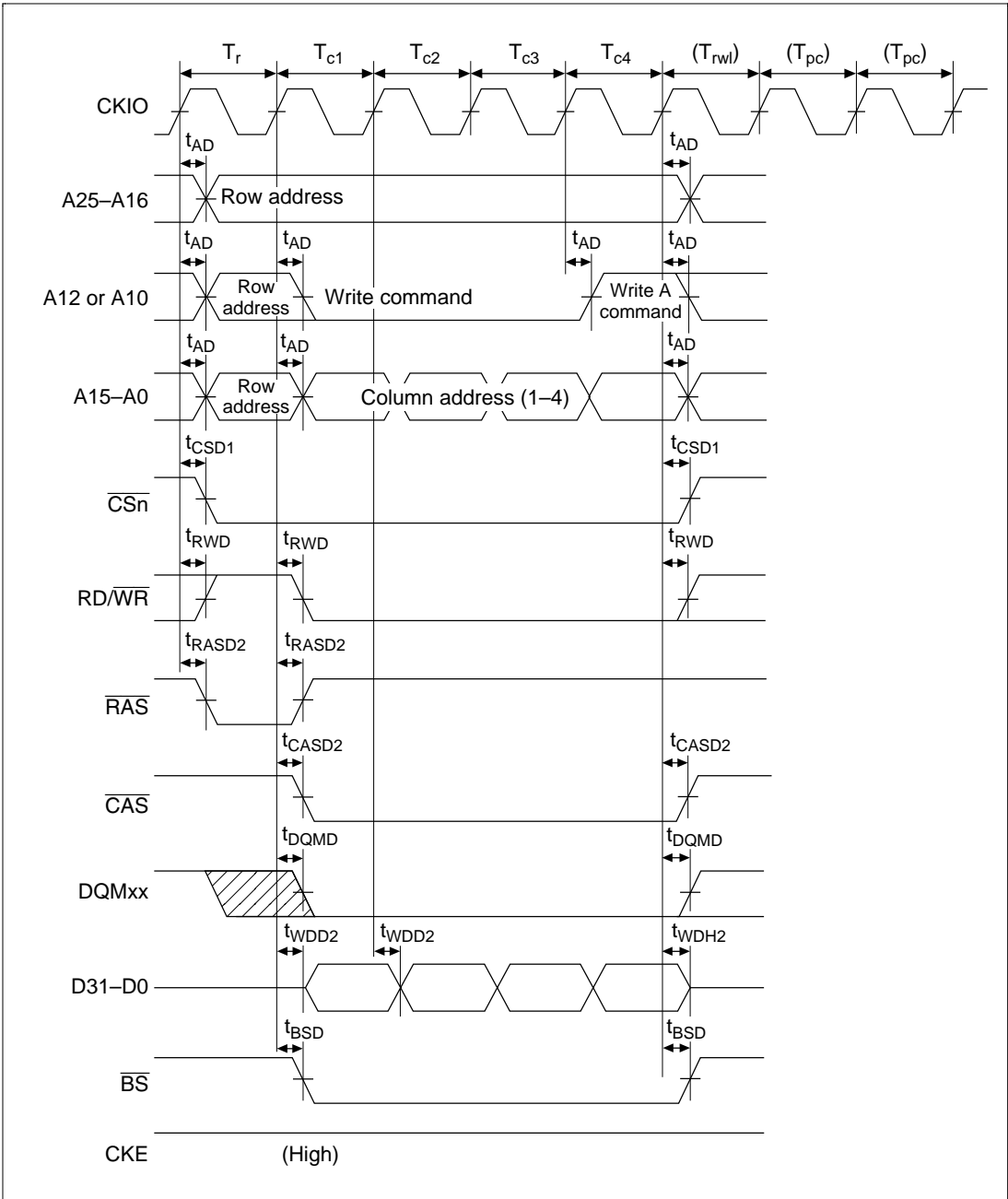


Figure 17.40 Synchronous DRAM Write Bus Cycle (Burst Mode (Single Write × 4), RCD = 0, TPC = 1, TRWL = 0)

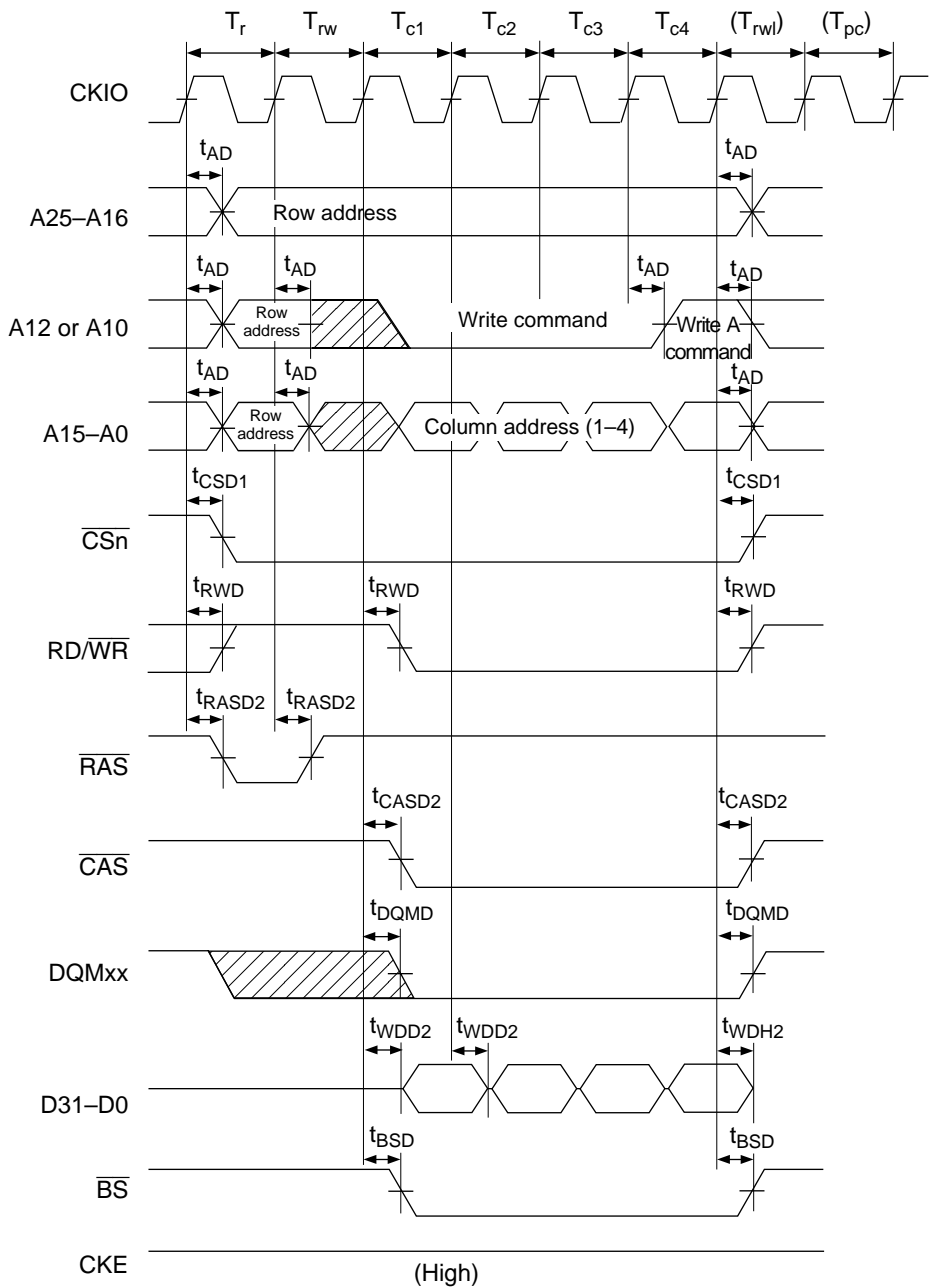


Figure 17.41 Synchronous DRAM Write Bus Cycle (Burst Mode (Single Write × 4), RCD = 1, TPC = 0, TRWL = 0)

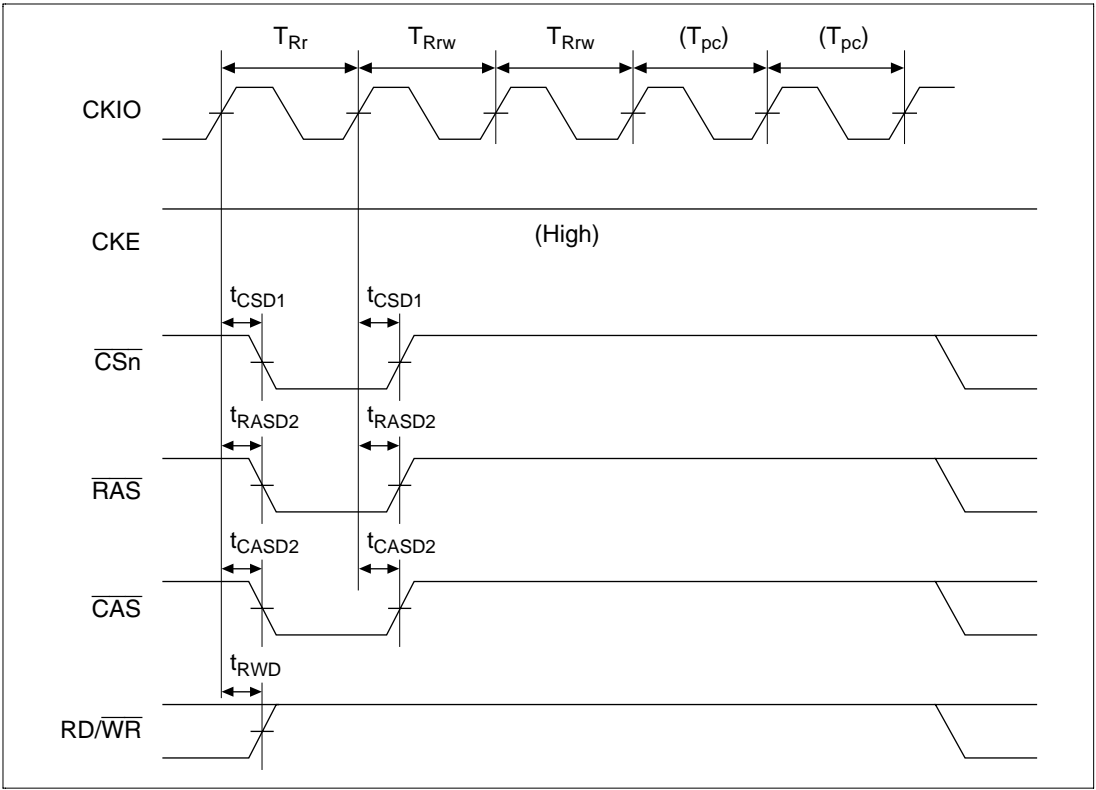


Figure 17.42 Synchronous DRAM Auto-Refresh Cycle (TRAS = 1, TPC = 1)

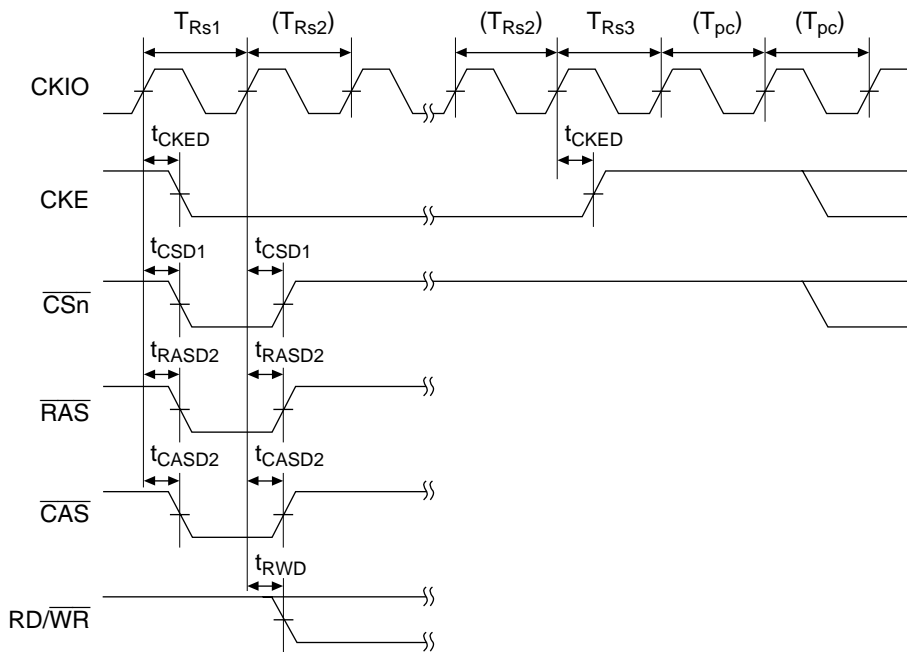


Figure 17.43 Synchronous DRAM Self-Refresh Cycle (TPC = 0)

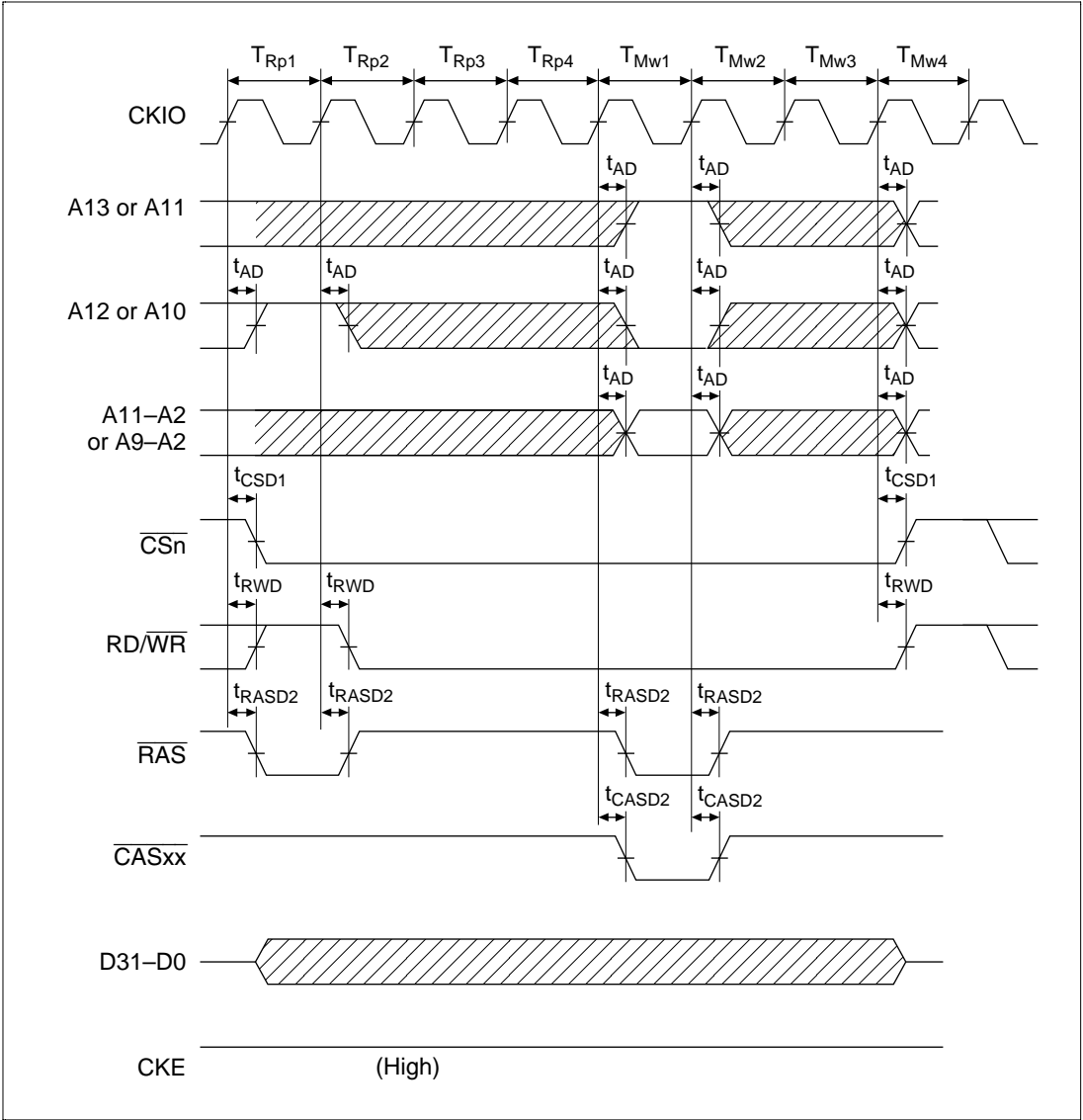


Figure 17.44 Synchronous DRAM Mode Register Write Cycle

17.3.8 Pseudo-SRAM Timing

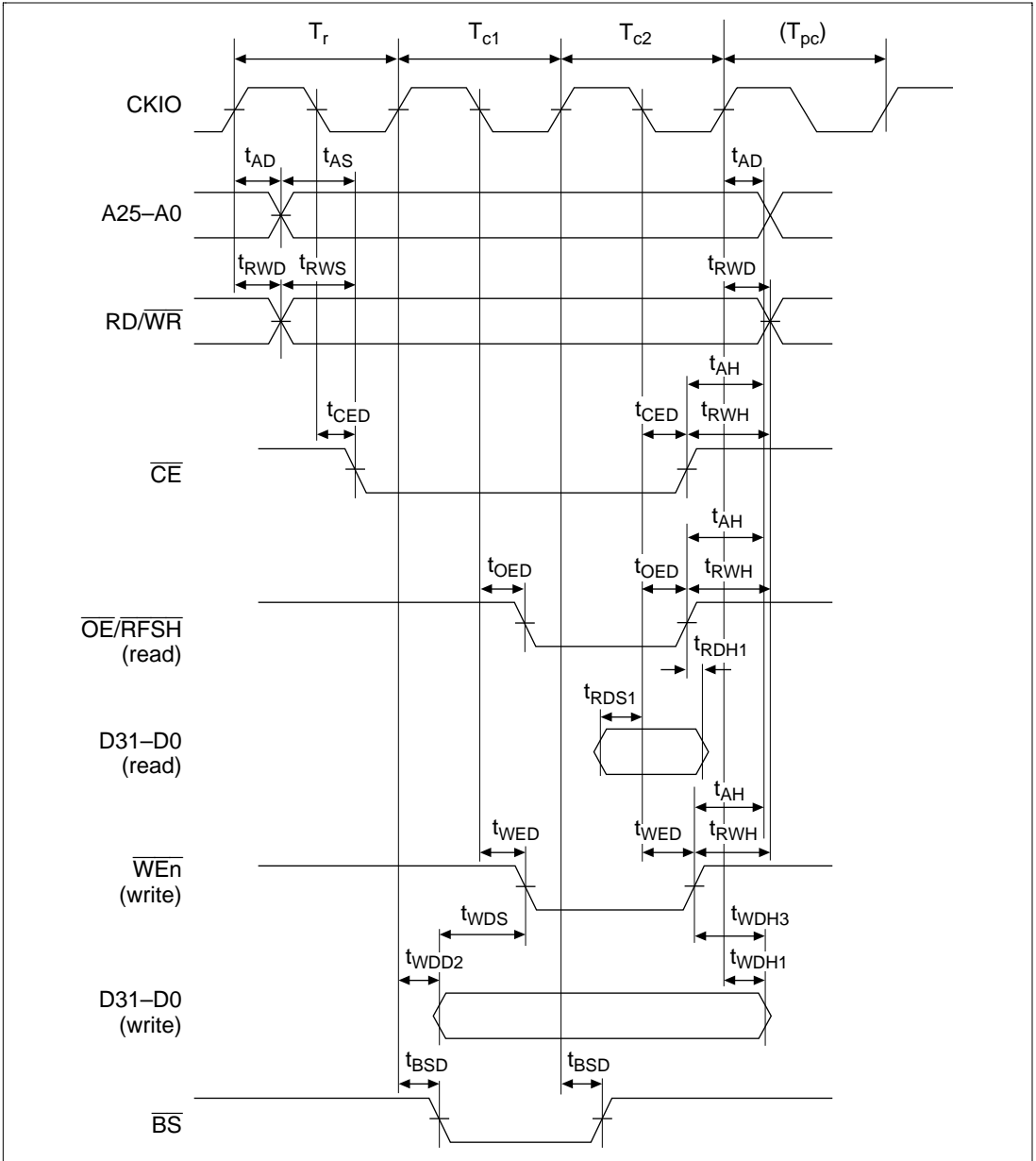


Figure 17.45 Pseudo-SRAM Bus Cycle (RCD = 0, A3W = 1, TPC = 0)

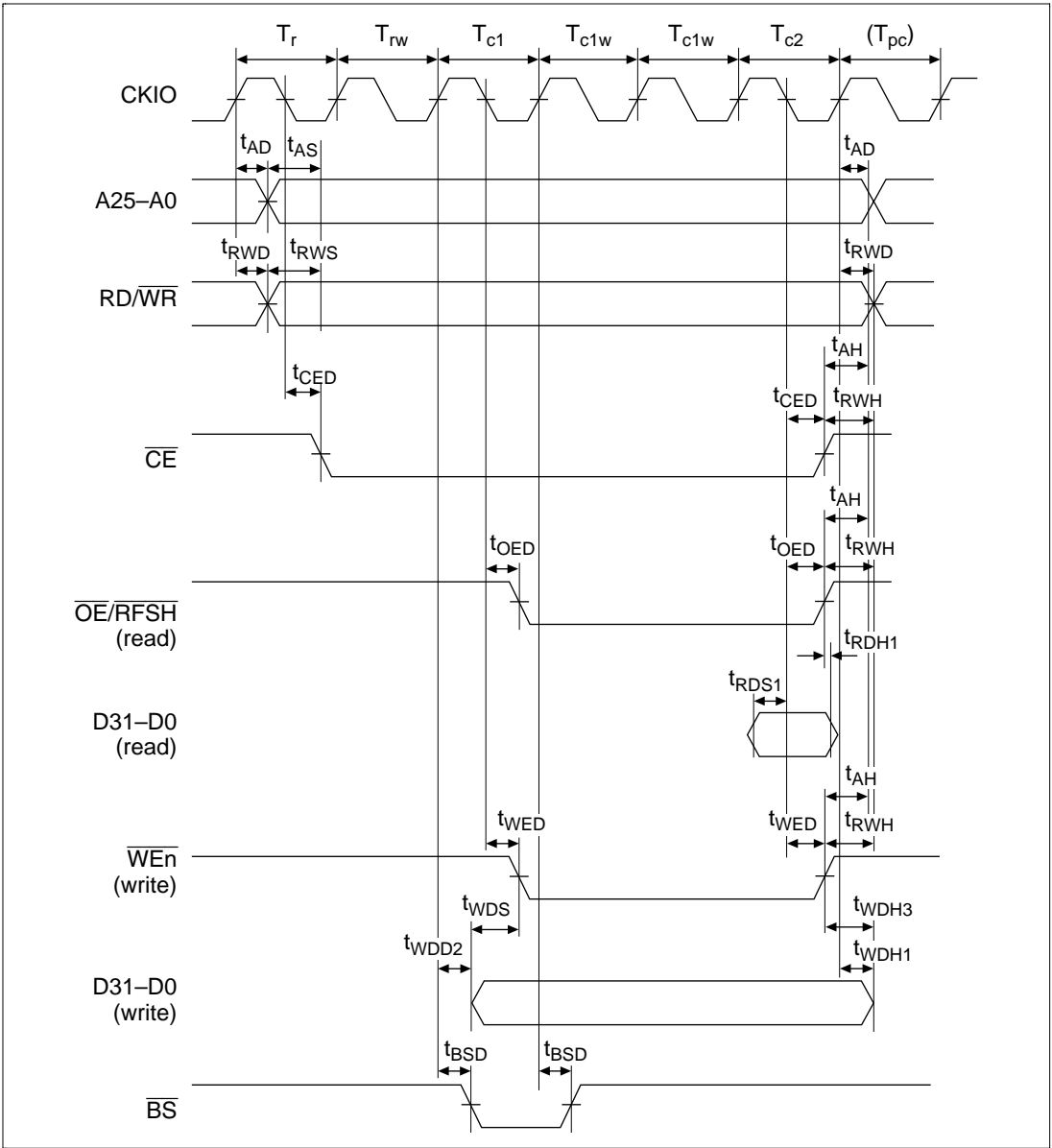


Figure 17.46 Pseudo-SRAM Read Cycle (RCD = 1, A3W = 3, TPC = 0)

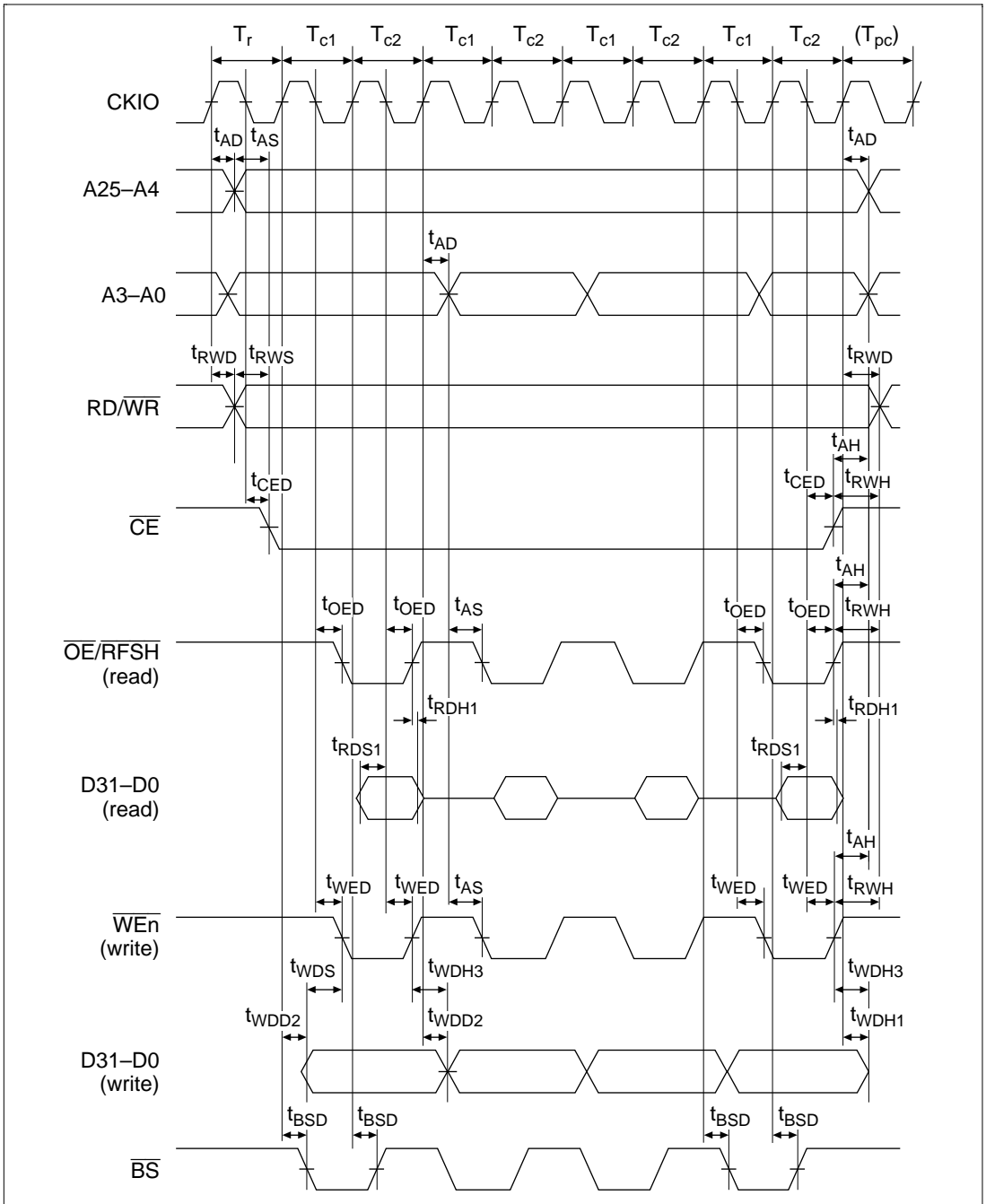


Figure 17.47 Pseudo-SRAM Bus Cycle (Static Column Mode, RCD = 0, A3W = 1, TPC = 0)

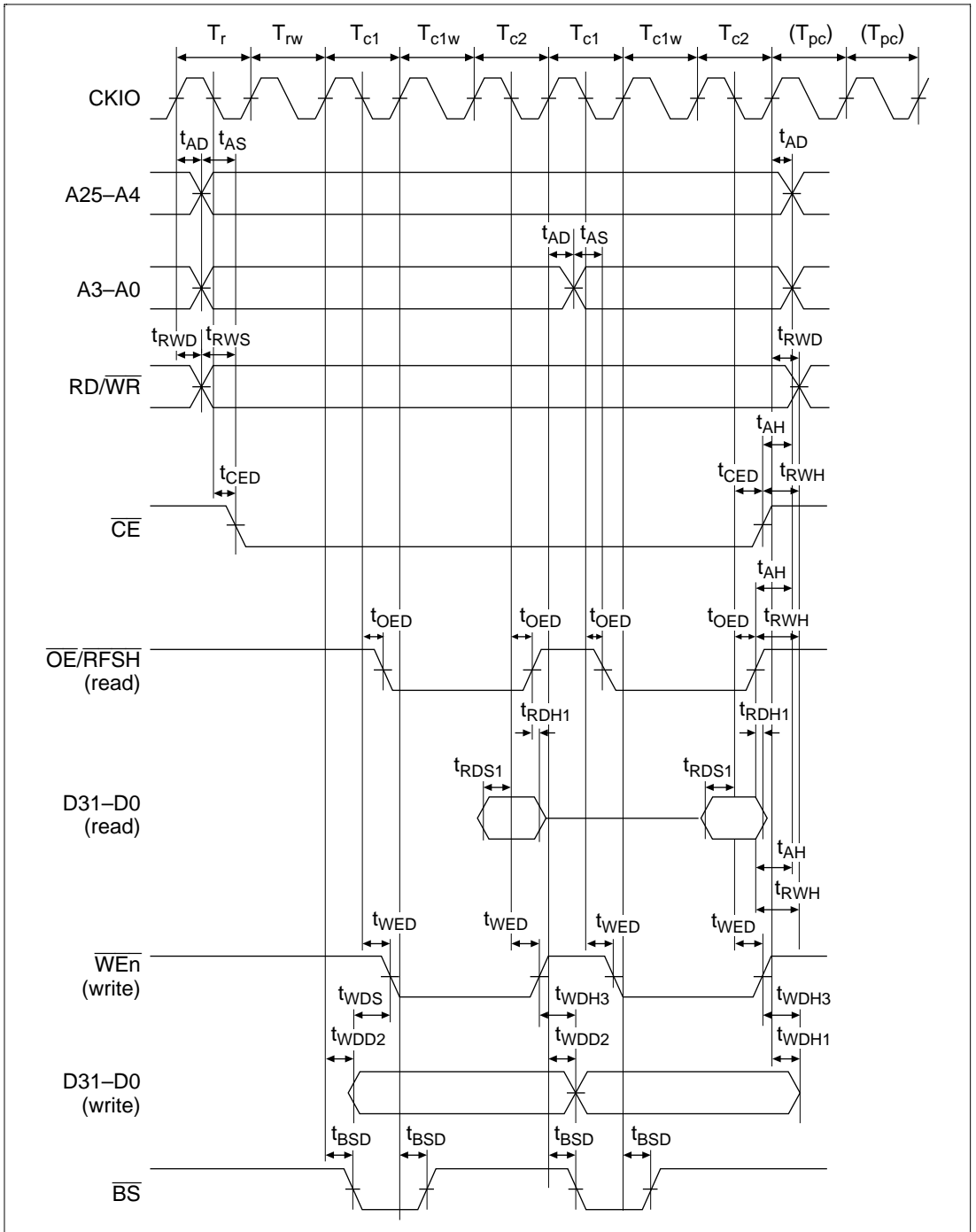


Figure 17.48 Pseudo-SRAM Bus Cycle (Static Column Mode, RCD = 1, A3W = 2, TPC = 1)

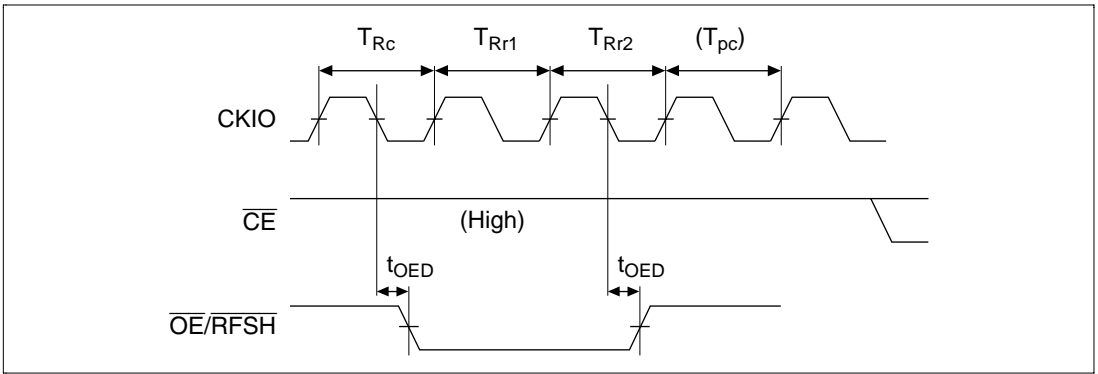


Figure 17.49 Pseudo-SRAM Auto-Refresh Cycle ($TRAS = 1$, $TPC = 1$)

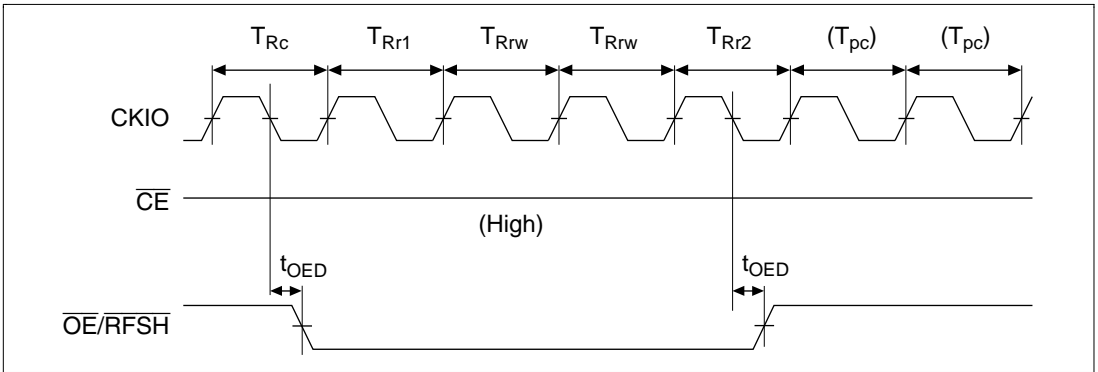


Figure 17.50 Pseudo-SRAM Auto-Refresh Cycle ($TRAS = 2$, $TPC = 1$)

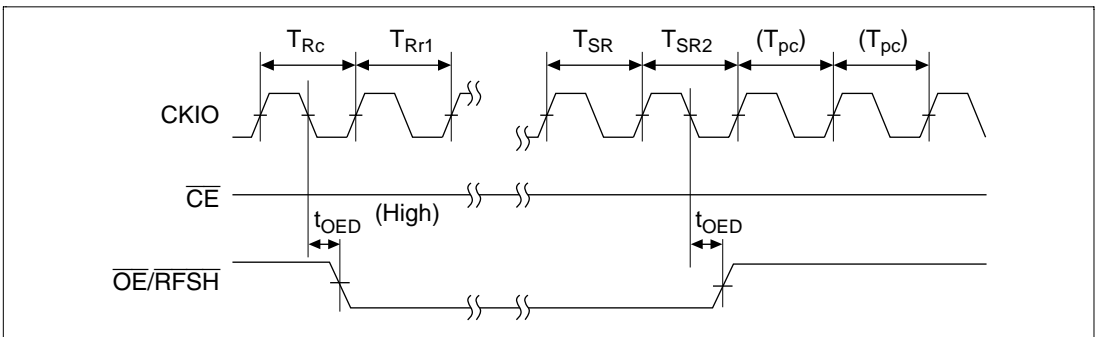


Figure 17.51 Pseudo-SRAM Self-Refresh Cycle ($TPC = 0$)

17.3.9 PCMCIA Timing

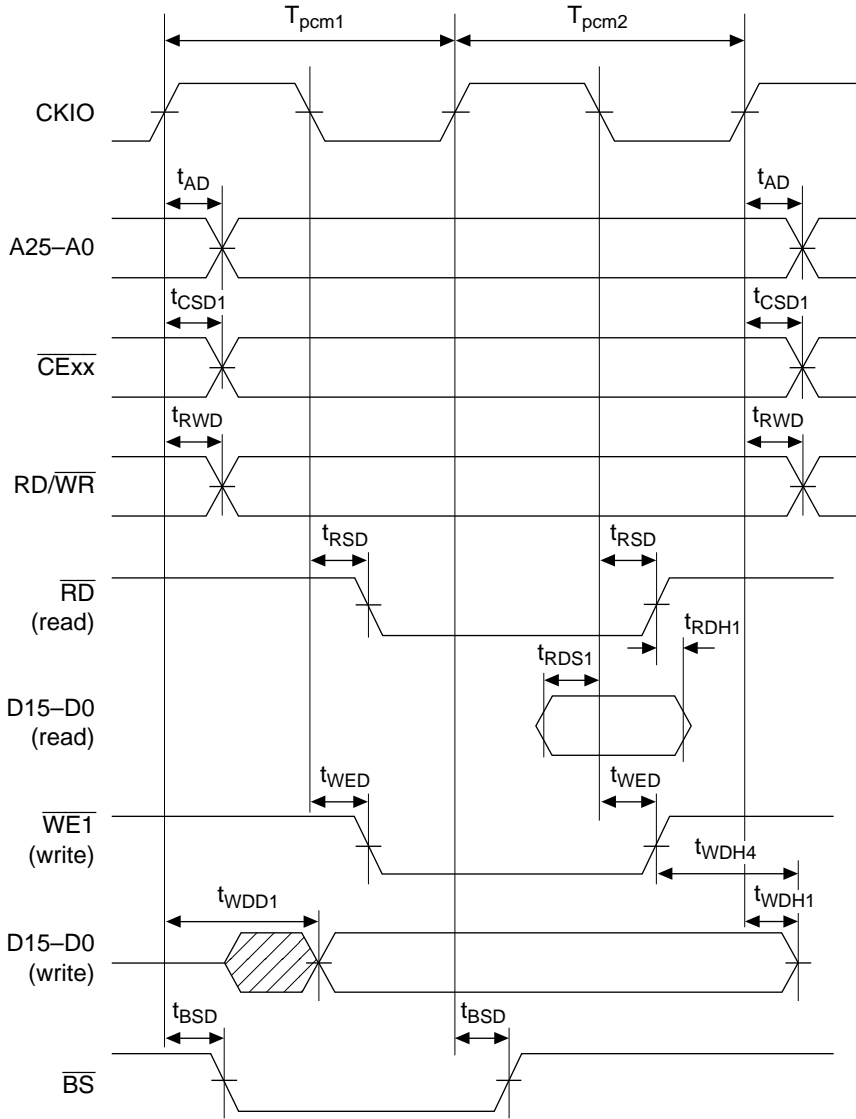


Figure 17.52 PCMCIA Memory Bus Cycle ($TED = 0$, $TEH = 0$, No Wait)

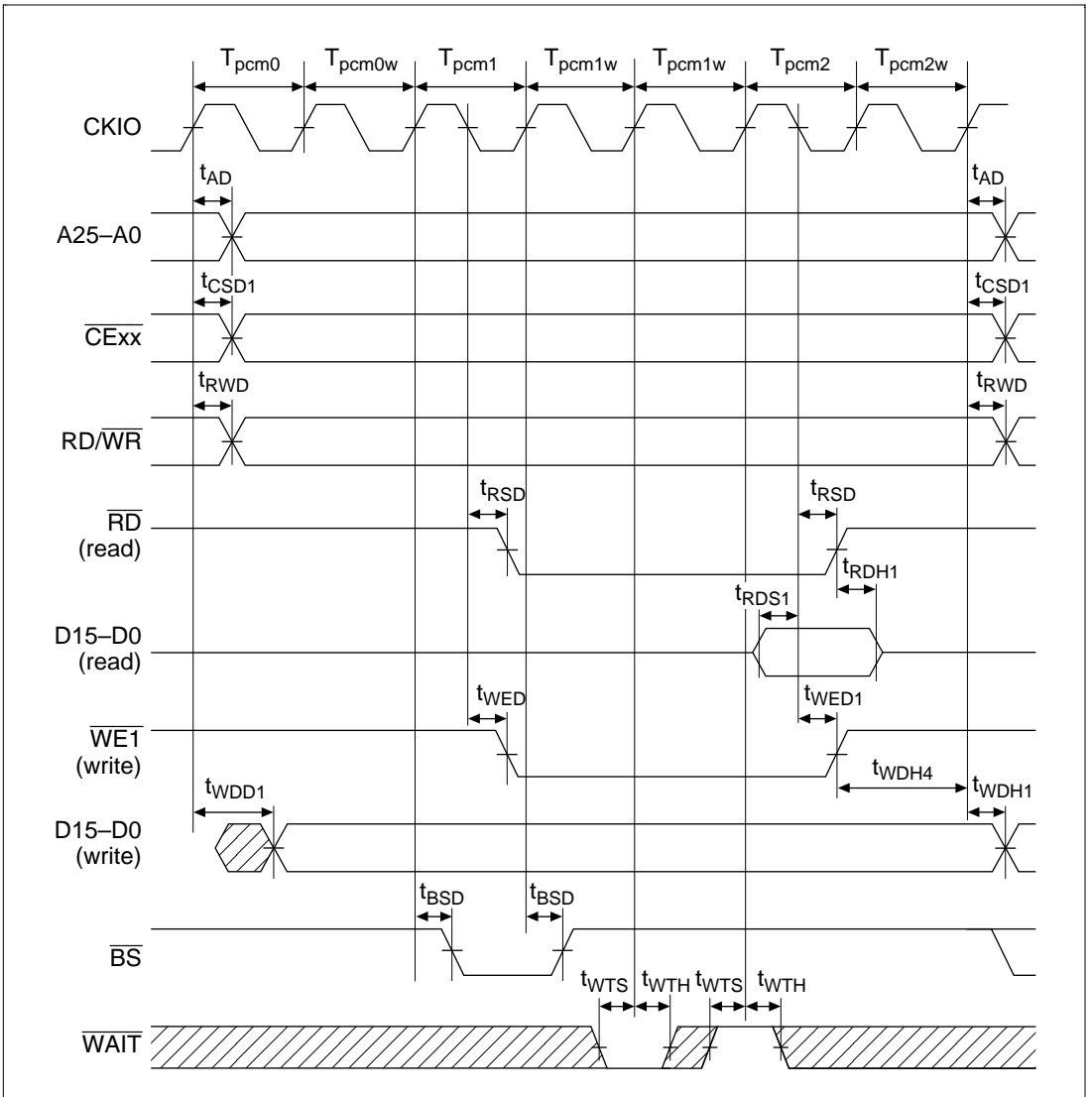
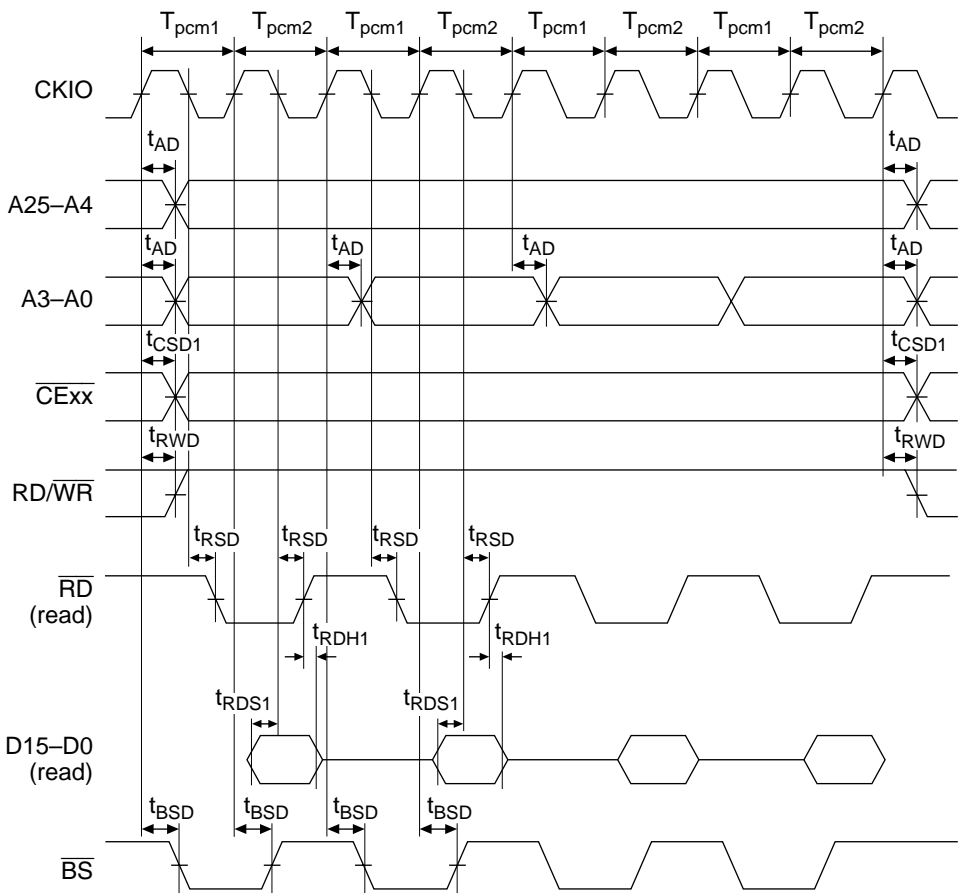
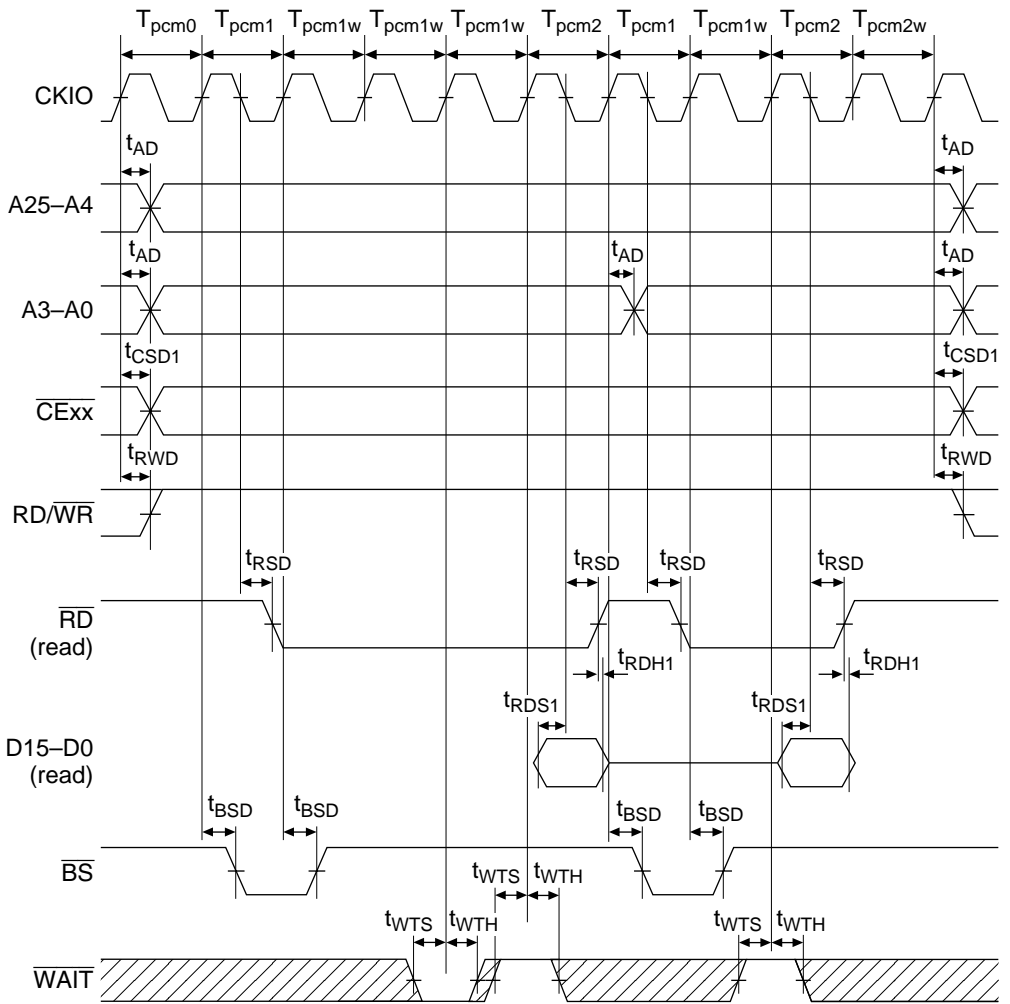


Figure 17.53 PCMCIA Memory Bus Cycle (TED = 2, TEH = 1, 1 Wait, External Wait)



Note: Even though burst mode is set, write cycle operation is the same as in normal mode.

Figure 17.54 PCMCIA Memory Bus Cycle (Burst Read, TED = 0, TEH = 0, No Wait)



Note: Even though burst mode is set, the write cycle operation is the same as in normal mode.

Figure 17.55 PCMCIA Memory Bus Cycle (Burst Read, TED = 1, TEH = 1, 2 Waits, Burst Pitch = 3)

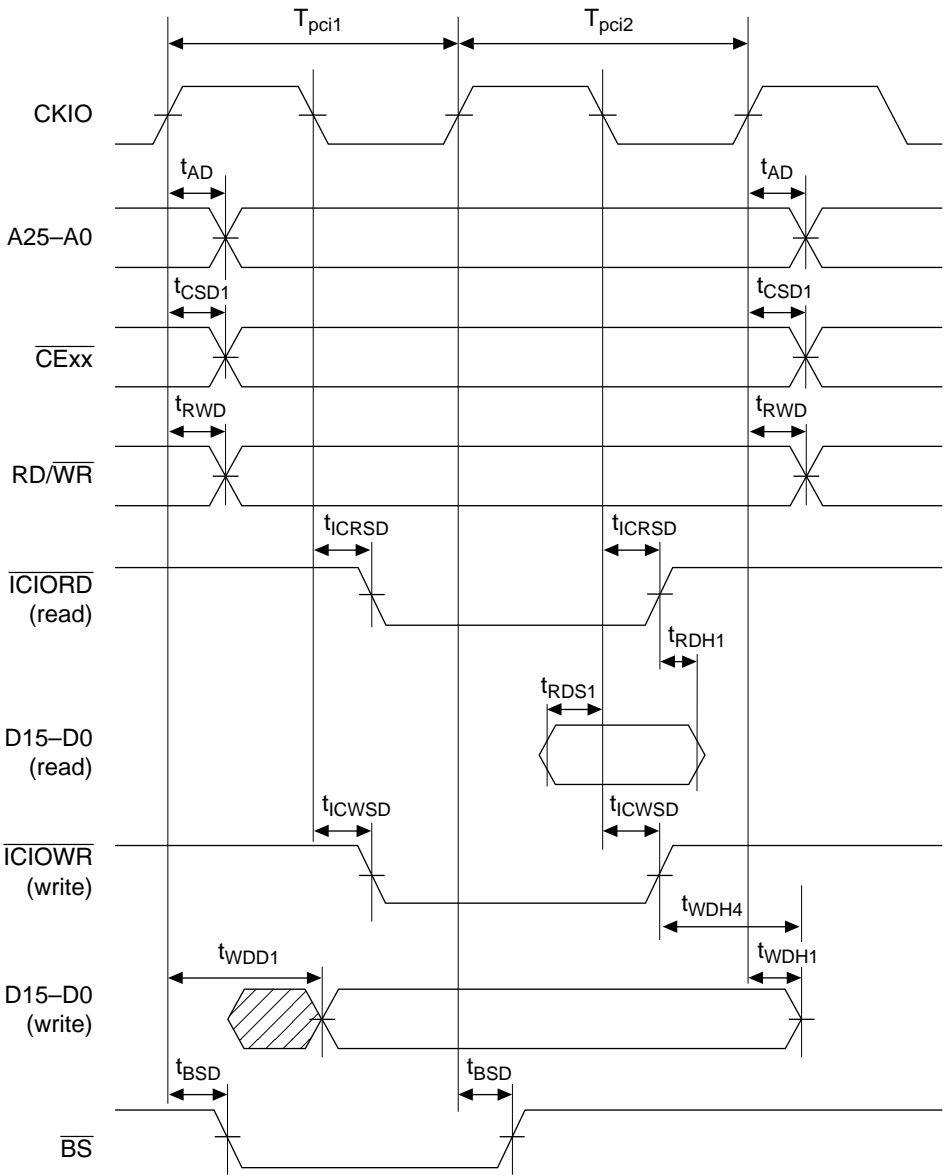


Figure 17.56 PCMCIA I/O Bus Cycle (TED = 0, TEH = 0, No Wait)

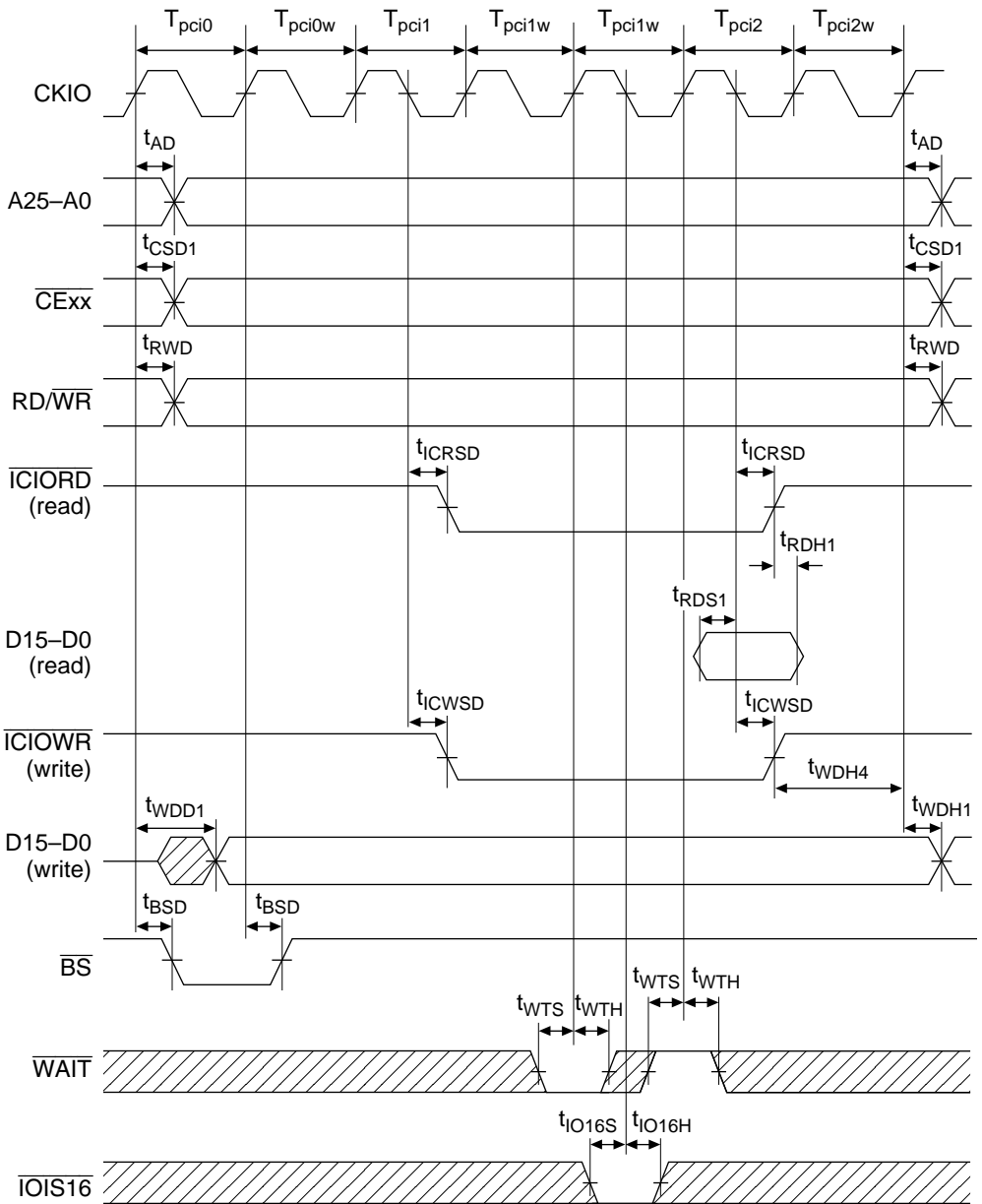


Figure 17.57 PCMCIA I/O Bus Cycle (TED = 2, TEH = 1, 1 Wait, External Wait)

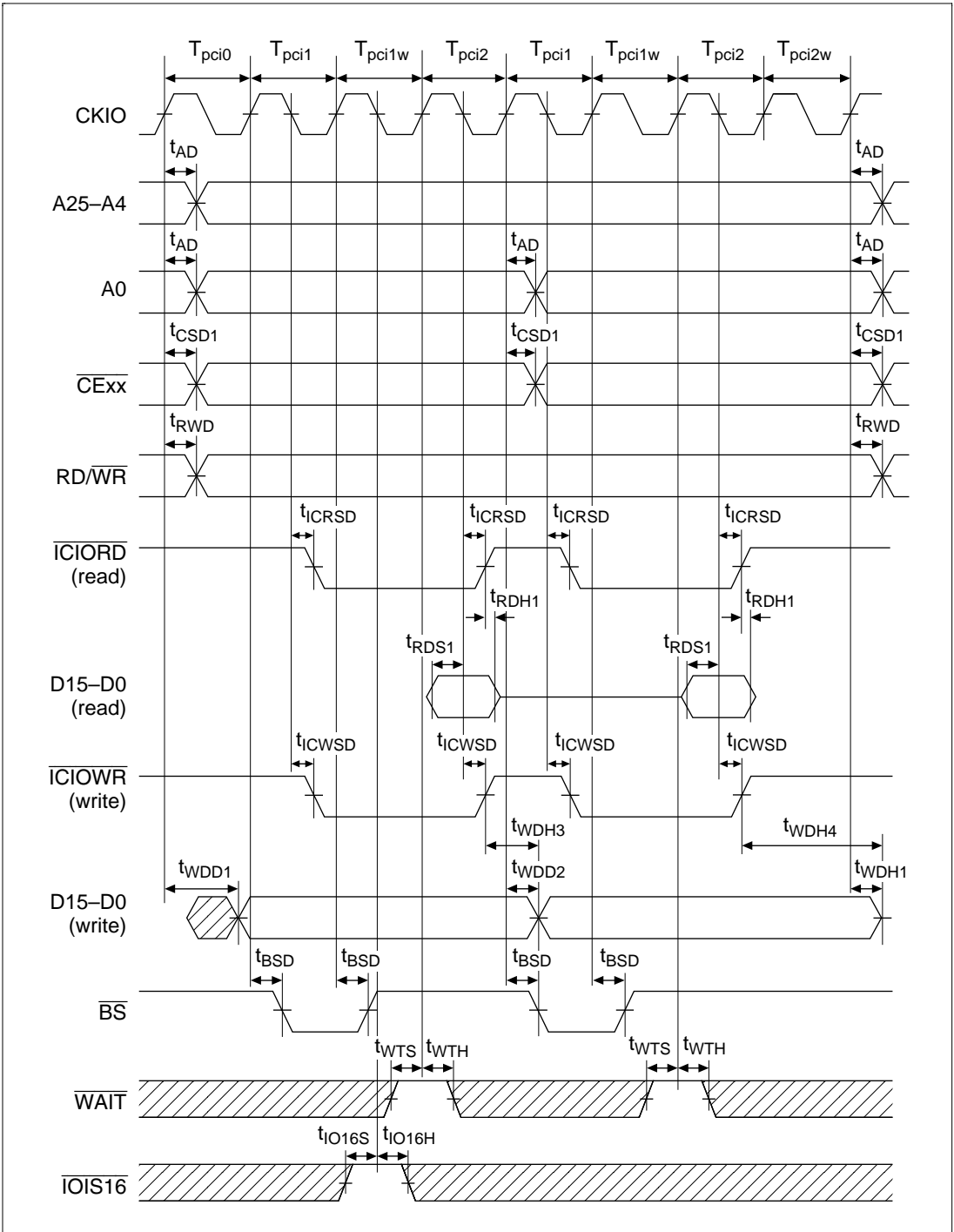


Figure 17.58 PCMCIA I/O Bus Cycle (TED = 1, TEH = 1, 1 Wait, Bus Sizing)

17.3.10 Peripheral Module Signal Timing

Table 17.9 Peripheral Module Signal Timing (Conditions: $V_{CC} = 3.15\text{--}3.6\text{ V}$, $T_a = -20\text{ to }+75^\circ\text{C}$)

Module	Item	Symbol	-60		Unit	Figure	
			Min	Max			
TMU, RTC	Timer input setup time	t_{CLKS1}	12	—	ns	17.59	
	Timer clock input setup time	t_{CKS}	12	—	ns	17.60	
	Timer clock pulse width	Single edge	t_{TCKWH}	1.5	—	tcyc	17.60
		Both edges	t_{TCKWL}	2.5	—	tcyc	17.60
	Oscillation settling time	t_{ROSC}	—	3	s	17.61	
SCI	Input clock cycle	Asynchronous	t_{Scyc}	4	—	tcyc	17.62, 17.63
		synchronous		6	—	tcyc	17.62, 17.63
	Input clock rise time	t_{SCKr}	—	1.5	tcyc	17.62	
	Input clock fall time	t_{SCKf}	—	1.5	tcyc	17.62	
	Input clock pulse width	t_{SCKw}	0.4	0.6	tscyc	17.62	
	Transmit data delay time	t_{TXD}	—	100	ns	17.63	
	Receive data setup time (synchronous)	t_{RXS}	100	—	ns	17.63	
	Receive data hold time (synchronous)	t_{RXH}	100	—	ns	17.63	
Port	Output data delay time	t_{PORTD}	—	15	ns	17.64	
	Input data setup time	t_{PORTS}	12	—	ns	17.64	
	Input data hold time	t_{PORTH}	5	—	ns	17.64	

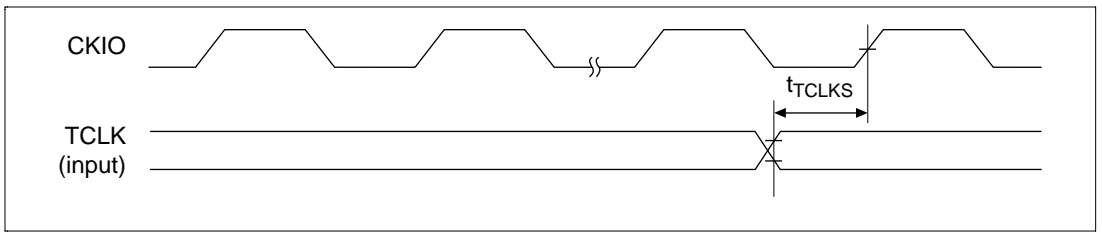


Figure 17.59 TCLK Input Timing

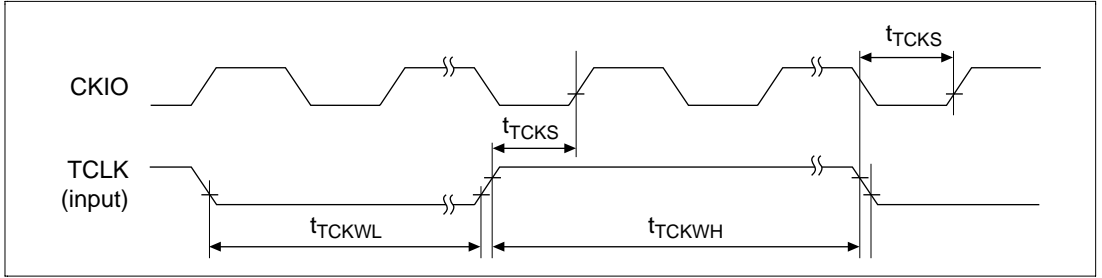


Figure 17.60 TCLK Clock Input Timing

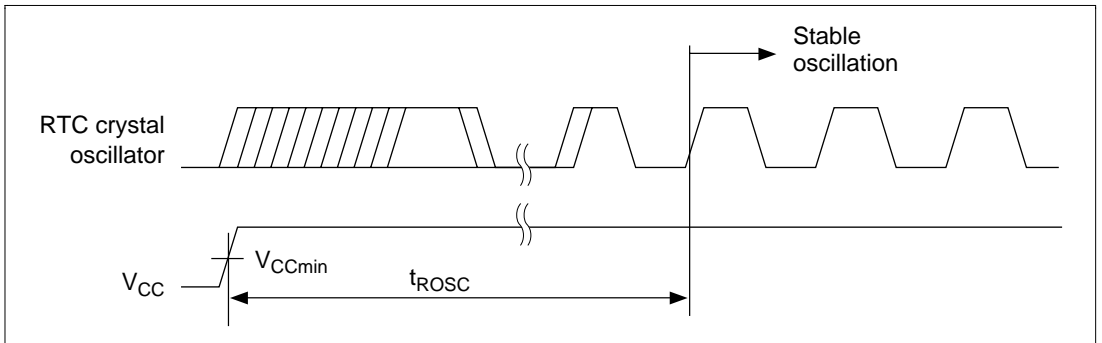


Figure 17.61 RTC Crystal Oscillator Power-On Oscillation Settling Time

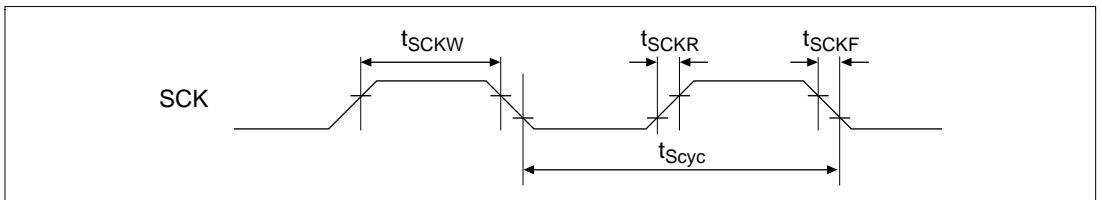


Figure 17.62 SCK Input Clock Timing

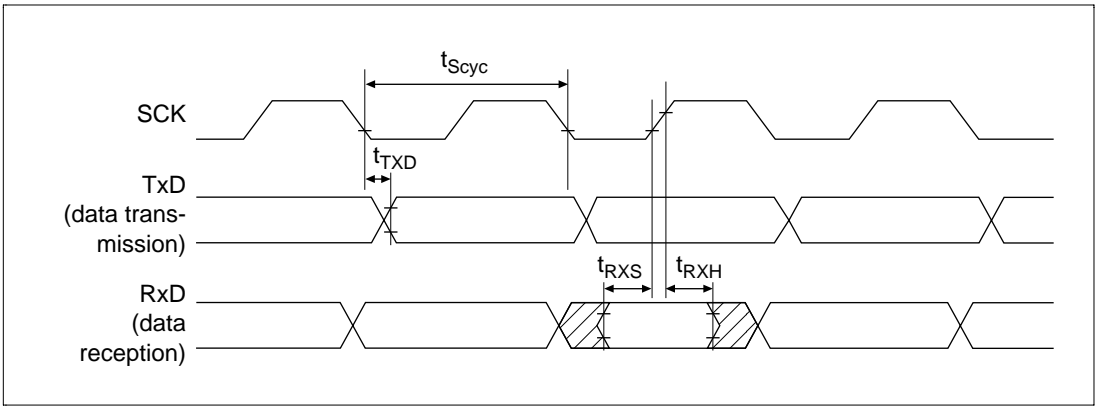


Figure 17.63 Synchronous Mode SCI Input/Output Timing

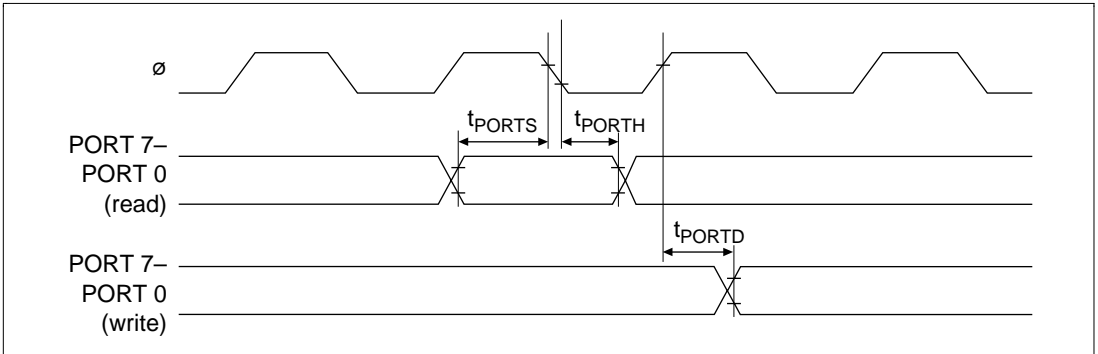
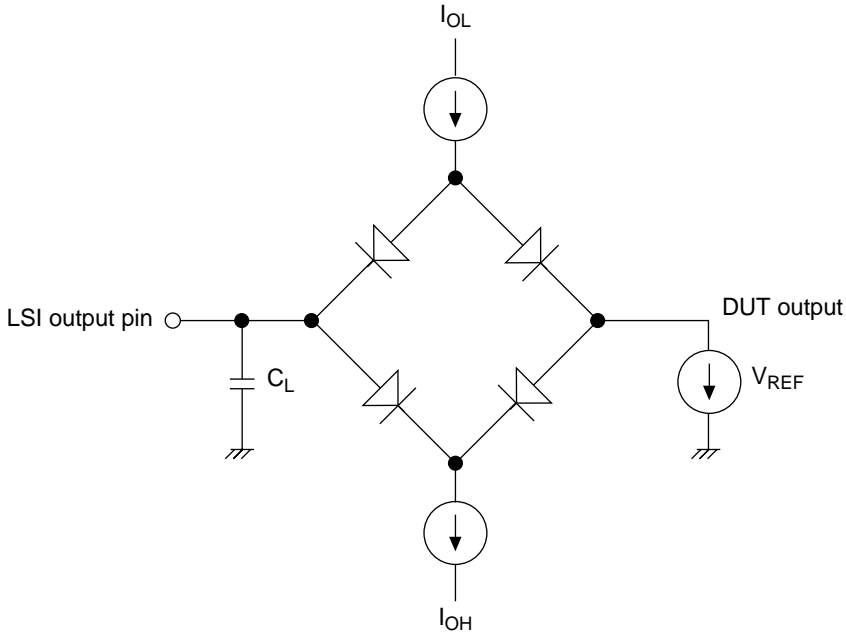


Figure 17.64 I/O Port Input/Output Timing

17.3.11 AC Characteristics Test Conditions

- Input/output signal reference level: 1.5 V ($V_{CC} = 3.3\text{--}3.6$ V).
- Input pulse level: V_{SS} to 3.0 V (when $\overline{\text{RESET}}$, $\overline{\text{BREQ}}$, $\overline{\text{NMI}}$, $\overline{\text{IRL3}}\text{--}\overline{\text{IRL0}}$, CKIO, MD5–MD0 are V_{SS} to V_{CC}).
- Input rise/fall time: 1 ns



- Notes:
1. C_L is the total capacitance including the test jig probe, as shown below:
30 pF: CKIO, RAS, CASxx, CS0–CS6, CE2A, CE2B, BACK
50 pF: All other pins
 2. I_{OL} and I_{OH} are the values shown in table 17.3

Figure 17.65 Output Load Circuit

Appendix A Pin Functions

A.1 Pin States

Table A.1 shows pin states during resets, power-down states, and the bus-released state.

Table A.1 Pin States during Resets, Power-Down States, and Bus-Released State

Category	Pin	Power-On Reset	Manual Reset	Power-Down State		Bus-Released State
				Standby	Sleep	
Clock	CKIO	IO ^{*1}	IO ^{*1}	IO ^{*1}	IO ^{*1}	IO ^{*1}
	EXTAL	I ^{*1}	I ^{*1}	I ^{*1}	I ^{*1}	I ^{*1}
	XTAL	O ^{*1}	O ^{*1}	O ^{*1}	O ^{*1}	O ^{*1}
	EXTAL2	I	I	I	I	I
	XTAL2	O	O	O	O	O
System control	RESET	I	I	I	I	I
	BREQ	I	I	I	I	I
	BACK	O	O	O	O	L
	CA	I	I	I	I	I
	STATUS0, STATUS1	O	O	O	O	O
	MD0/SCK	I	I	I	IO ^{*2}	IO ^{*2}
	MD1/TXD	I	I	I	IO ^{*3}	IO ^{*3}
	MD2/RXD	I	I	I	I	I
	MD3/CE2A	I	IH ^{*4}	IZH ^{*5}	IH ^{*4}	IZ ^{*4}
	MD4/CE2B	I	IH ^{*4}	IZH ^{*5}	IH ^{*4}	IZ ^{*4}
	MD5/RAS2	I	IO ^{*6}	IZO ^{*7}	IO ^{*6}	IZO ^{*7}
Interrupt	NMI	I	I	I	I	I
	IRL3 to IRL0	I	I	I	I	I
	IRQOUT	O	O	O	O	O

Table A.1 Pin States during Resets, Power-Down States, and Bus-Released State (cont)

Category	Pin	Power-On Reset	Manual Reset	Power-Down State		Bus-Released State
				Standby	Sleep	
Address Bus	A25 to A0	O	O	Z	O	Z
Data Bus	D31 to D30	Z	ZO ^{*8}	ZO ^{*8}	ZO ^{*8}	ZO ^{*8}
	D29 to D24	Z	Z	Z	Z	Z
	D23 to D16/ PORT7 to PORT0	Z	ZK ^{*10}	ZK ^{*10}	ZK ^{*10}	ZK ^{*10}
	D15 to D0	Z	I	Z	I	Z
Bus Control	$\overline{CS0}$ to $\overline{CS4}$	H	O	ZH ^{*11}	H	Z
	$\overline{CS5}/\overline{CE1A}$	H	O	ZH ^{*11}	H	Z
	$\overline{CS6}/\overline{CE1B}$	H	O	ZH ^{*11}	H	Z
	\overline{BS}	H	O	ZH ^{*11}	H	Z
	$\overline{RAS}/\overline{CE}$	H	O	ZO ^{*12}	O	ZO ^{*12}
	$\overline{CASL}/\overline{CAS}/\overline{OE}$	H	O	ZO ^{*12}	O	ZO ^{*12}
	\overline{CASLH}	H	O	ZO ^{*12}	O	ZO ^{*12}
	$\overline{CASHL}/\overline{CAS2L}$	H	O	ZO ^{*12}	O	ZO ^{*12}
	$\overline{CASHH}/\overline{CAS2H}$	H	O	ZO ^{*12}	O	ZO ^{*12}
	$\overline{DQMLL}/\overline{WE0}$	H	O	ZH ^{*11}	H	Z
	$\overline{DQMLU}/\overline{WE1}$	H	O	ZH ^{*11}	H	Z
	$\overline{DQMUL}/\overline{WE2}/$ \overline{ICIORD}	H	O	ZH ^{*11}	H	Z
	$\overline{DQMUU}/\overline{WE3}/$ \overline{ICIOWR}	H	O	ZH ^{*11}	H	Z
	$\overline{RD}/\overline{WR}$	H	O	Z	H	Z
	\overline{RD}	H	O	Z	H	Z
	CKE	H	O	O	O	O
WAIT	Z	I	Z	I	Z	
$\overline{IOIS16}$	Z	I	Z	I	Z	
TMU/RTC	TCLK	Z	I	IO ^{*13}	IO ^{*14}	IO ^{*14}
PLL	CAP1, CAP2	IO	IO	IO	IO	IO

I: Input

O: Output

H: High-level output

L: Low-level output

Z: High impedance

K: Input pin is high impedance, output pin holds its state

- Notes:
1. Dependent on the clock mode (MD2–MD0 setting).
 2. When SCI and port are not used, I. When used, I or O depending on register setting.
 3. When SCI and port are not used, I. When used, O.
 4. When PCMCIA is not used, I. When used, H or Z.
 5. When PCMCIA is not used, I. When used, Z or H depending on register setting.
 6. When area 2 DRAM is not used, I. When used, O.
 7. When area 2 DRAM is not used, I. When used, Z or O depending on register setting.
 8. O when the port function is used.
 9. Z when the port function is used.
 10. When the port function is used, K depending on register setting.
 11. Z or H depending on register setting.
 12. Z or O depending on register setting.
 13. In standby mode, I or O depending on register setting. In hardware standby mode, I or L depending on register setting.
 14. I or O depending on register setting.

A.2 Pin Specifications

Table A.2 shows the pin specifications.

Table A.2 Pin Specifications

Pin	Pin No.	I/O	Function
MD5/ $\overline{\text{RAS2}}$	130	I/O	Operating mode pin (endian switching)/ $\overline{\text{RAS}}$ (for DRAM). MD signal is fetched in at power-on reset. Switched to $\overline{\text{RAS}}$ on area 2 DRAM enabling by register.
MD4/ $\overline{\text{CE2B}}$	103	I/O	Operating mode pin (area 0 bus width)/PCMCIA $\overline{\text{CE}}$ pin. MD signal is fetched in at power-on reset. Switched to $\overline{\text{CE2B}}$ on area 6 PCMCIA enabling by register.
MD3/ $\overline{\text{CE2A}}$	104	I/O	Operating mode pin (area 0 bus width)/PCMCIA $\overline{\text{CE}}$ pin. MD signal is fetched in at power-on reset. Switched to $\overline{\text{CE2A}}$ on area 5 PCMCIA enabling by register.
MD2/RXD	84	I	Operating mode pin/serial data input. MD signal is fetched in at power-on reset. Switched to RXD on SCI enabling by register.
MD1/TXD	85	I/O	Operating mode pin/serial data output. MD signal is fetched in at power-on reset. Switched to TXD on SCI enabling by register.
MD0/SCK	86	I/O	Operating mode pin/serial clock. MD signal is fetched in at power-on reset. Switched to SCK on SCI enabling by register.
STATUS1	97	O	Processor status
STATUS0	98	O	Processor status
A25 to A0	72 to 70, 67 to 61, 58 to 56, 53 to 51, 48 to 43, 40 to 37	O	Address bus
D31 to D24	140 to 143, 1 to 4	I/O	Data bus
D23 to D16/ Port 7 to Port 0	5, 8 to 14	I/O	Data bus / I/O port

Table A.2 Pin Specifications (cont)

Pin	Pin No.	I/O	Function
D15 to D0	15 to 16, 21 to 29, 32 to 36	I/O	Data bus
$\overline{CS6}/\overline{CE1B}$	108	O	Chip select 6/PCMCIA \overline{CE}
$\overline{CS5}/\overline{CE1A}$	109	O	Chip select 5/PCMCIA \overline{CE}
$\overline{CS4}$ to $\overline{CS0}$	110 to 114	O	Chip select 4—chip select 0
\overline{BS}	105	O	Bus cycle start
$\overline{RAS}/\overline{CE}$	129	O	DRAM, synchronous DRAM \overline{RAS} /pseudo-SRAM \overline{CE}
$\overline{CASHH}/\overline{CAS2H}$	119	O	D31–D24 (DRAM \overline{CAS})/D15–D8 (area 2 DRAM \overline{CAS}) select signal
$\overline{CASHL}/\overline{CAS2L}$	120	O	D23–D16 (DRAM \overline{CAS})/D7–D0 (area 2 DRAM \overline{CAS}) select signal
\overline{CASLH}	125	O	D15–D8 select signal (DRAM \overline{CAS})
$\overline{CASLL}/\overline{CAS}/\overline{OE}$	126	O	D7–D0 select (DRAM \overline{CAS})/memory select signal (synchronous DRAM \overline{CAS} /pseudo-SRAM \overline{OE})
$\overline{WE3}/\overline{DQMUU}/\overline{ICIOWR}$	117	o	D31–D24 select signal (normal memory, pseudo-SRAM \overline{WE} /synchronous DRAM DQM)/IO write (PCMCIA, PCMCIB)
$\overline{WE2}/\overline{DQMUL}/\overline{ICIORD}$	118	O	D23–D16 select signal (normal memory, pseudo-SRAM \overline{WE} /synchronous DRAM DQM)/IO write (PCMCIA, PCMCIB)
$\overline{WE1}/\overline{DQMLU}$	123	O	D15–D8 select signal (normal memory, pseudo-SRAM \overline{WE} /synchronous DRAM DQM)
$\overline{WE0}/\overline{DQMLL}$	124	O	D7–D0 select signal (normal memory, pseudo-SRAM \overline{WE} /synchronous DRAM DQM)
$\overline{RD}/\overline{WR}$	106	O	Read/write (synchronous DRAM/DRAM/PCMCIA)
\overline{RD}	107	O	Read pulse (PCMCIA/normal memory)
\overline{WAIT}	132	I	Hardware wait request
$\overline{IOIS16}$	94	I	IO16 bit indication (PCMCIA IO area)
\overline{BREQ}	87	I	Bus request
\overline{BACK}	96	O	Bus acknowledge
\overline{IRQOUT}	95	O	Interrupt request notification
\overline{RESET}	88	I	Reset
CA	81	I	Chip active Causes a transition to hardware standby mode when low. Drive high in a power-on reset.

Table A.2 Pin Specifications (cont)

Pin	Pin No.	I/O	Function
NMI	89	I	Nonmaskable interrupt request
IRL3 to IRL0	90 to 93	I	External interrupt source input
TCLK	134	I/O	Timer external clock input/RTC clock output
EXTAL	79	I	External clock/crystal resonator pin
XTAL	80	O	Crystal resonator pin
CAP1	74	O	External capacitance pin (for PLL1)
CAP2	77	O	External capacitance pin (for PLL2)
CKIO	101	I/O	System clock input/output
CKE	131	O	Clock enable control (for synchronous DRAM)
XTAL2	136	O	Crystal resonator pin (for on-chip RTC)
EXTAL2	137	I	Crystal resonator pin (for on-chip RTC)
NC	99	O	Leave unconnected
V_{CC}	7, 18, 20, 31, 42, 50, 55, 60, 69, 81, 83, 102, 116, 122, 128, 139	Power supply	Power supply (3.3 V)
V_{CC} (RTC)	135	Power supply	RTC oscillator power supply (3.3 V)
V_{CC} (PLL)	75, 78	Power supply	PLL power supply (3.3 V)
V_{SS}	6, 17, 19, 30, 41, 49, 54, 59, 68, 82, 100, 115, 121, 127, 133, 144	Power supply	Power supply (0 V)
V_{SS} (RTC)	138	Power supply	RTC oscillator power supply (0 V)
V_{SS} (PLL)	73, 76	Power supply	PLL power supply (0 V)

Note: Except in hardware standby mode, power must be supplied constantly to all power supply pins. In hardware standby mode, power should be supplied at least to the RTC power supply pins.

A.3 Handling of Unused Pins

- When RTC is not used
 - EXTAL2: Pull up
 - XTAL2: Leave unconnected
 - V_{CC} (RTC): Power supply (3.3 V)
 - V_{SS} (RTC): Power supply (0 V)
- When PLL1 is not used
 - CAP1: Leave unconnected
 - V_{CC} (PLL): Power supply (3.3 V)
 - V_{SS} (PLL): Power supply (0 V)
- When PLL2 is not used
 - CAP2: Leave unconnected
 - V_{CC} (PLL): Power supply (3.3 V)
 - V_{SS} (PLL): Power supply (0 V)
- When on-chip crystal oscillator is not used
 - XTAL: Leave unconnected

A.4 Pin States in Access to Each Address Space

Table A.3 Pin States (Normal Memory/Little-Endian)

Pin	8-Bit Bus Width		16-Bit Bus Width		
		Byte/Word/Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
CS6 to CS0		Enabled	Enabled	Enabled	Enabled
RD	R	Low	Low	Low	Low
	W	High	High	High	High
RD/WR	R	High	High	High	High
	W	Low	Low	Low	Low
BS		Enabled	Enabled	Enabled	Enabled
RAS/CE		High	High	High	High
CAS/CASLL/OE		High	High	High	High
CASLH		High	High	High	High
CASHL/CAS2L		High	High	High	High
CASHH/CAS2H		High	High	High	High
DQMLL/WE0	R	High	High	High	High
	W	Low	Low	High	Low
DQMLU/WE1	R	High	High	High	High
	W	High	High	Low	Low
DQMUL/WE2/ICIORD	R	High	High	High	High
	W	High	High	High	High
DQMUU/WE3/ICIOWR	R	High	High	High	High
	W	High	High	High	High
MD3/CE2A		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE		Disabled	Disabled	Disabled	Disabled
WAIT		Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
IOIS16		Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address
D7 to D0		Valid data	Valid data	Invalid data	Valid data
D15 to D8		High-Z	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24		High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

Table A.3 Pin States (Normal Memory/Little-Endian) (cont)

Pin	32-Bit Bus Width							Longword Access
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)		
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	Low	Low	Low	Low	Low	Low	Low
	W	High	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low	Low
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$	High	High	High	High	High	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$	High	High	High	High	High	High	High	High
\overline{CASLH}	High	High	High	High	High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High	High
	W	Low	High	High	High	Low	High	Low
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High	High
	W	High	Low	High	High	Low	High	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	High	High	High
	W	High	High	Low	High	High	Low	Low
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High	High
	W	High	High	High	Low	High	Low	Low
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
\overline{WAIT}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

Table A.3 Pin States (Normal Memory/Little-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D31 to D24	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2–0) ≠ 101, high-Z.
 4. When WCR2 register wait setting is 0, disabled.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 6. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.4 Pin States (Normal Memory/Big-Endian)

Pin	8-Bit Bus Width		16-Bit Bus Width		
		Byte/Word/Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
$\overline{CS6}$ to $\overline{CS0}$		Enabled	Enabled	High	Enabled
\overline{RD}	R	Low	Low	Low	Low
	W	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High
	W	Low	Low	Low	Low
\overline{BS}		Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$		High	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$		High	High	High	High
\overline{CASLH}		High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$		High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$		High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High
	W	Low	High	Low	Low
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High
	W	High	Low	High	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIORD}$	R	High	High	High	High
	W	High	High	High	High
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOWR}$	R	High	High	High	High
	W	High	High	High	High
$\overline{MD3}/\overline{CE2A}$		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
\overline{CKE}		Disabled	Disabled	Disabled	Disabled
\overline{WAIT}		Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
$\overline{IOIS16}$		Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address
D7 to D0		Valid data	Invalid data	Valid data	Valid data
D15 to D8		High-Z	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24		High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

Table A.4 Pin States (Normal Memory/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	Low	Low	Low	Low	Low	Low
	W	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$	High	High	High	High	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$	High	High	High	High	High	High	High
\overline{CASLH}	High	High	High	High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High
	W	High	High	High	Low	High	Low
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High
	W	High	High	Low	High	High	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	High	High
	W	High	Low	High	High	Low	High
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High
	W	Low	High	High	High	Low	High
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
\overline{WAIT}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

Table A.4 Pin States (Normal Memory/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D31 to D24	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2-0) ≠ 101, high-Z.
 4. When WCR2 register wait setting is 0, disabled.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register .
 6. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.5 Pin States (Burst ROM/Little-Endian)

Pin	8-Bit Bus Width		16-Bit Bus Width		
		Byte/Word/Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
CS6 to CS0		Enabled	Enabled	Enabled	Enabled
RD	R	Low	Low	Low	Low
	W	—	—	—	—
RD/WR	R	High	High	High	High
	W	—	—	—	—
BS		Enabled	Enabled	Enabled	Enabled
RAS/CE		High	High	High	High
CAS/CASLL/OE		High	High	High	High
CASLH		High	High	High	High
CASHL/CAS2L		High	High	High	High
CASHH/CAS2H		High	High	High	High
DQMLL/WE0	R	High	High	High	High
	W	—	—	—	—
DQMLU/WE1	R	High	High	High	High
	W	—	—	—	—
DQMUL/WE2/ICIORD	R	High	High	High	High
	W	—	—	—	—
DQMUU/WE3/ICIOWR	R	High	High	High	High
	W	—	—	—	—
MD3/CE2A		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE		Disabled	Disabled	Disabled	Disabled
WAIT		Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
IOIS16		Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address
D7 to D0		Valid data	Valid data	Invalid data	Valid data
D15 to D8		High-Z	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24		High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

Table A.5 Pin States (Burst ROM/Little-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	Low	Low	Low	Low	Low	Low
	W	—	—	—	—	—	—
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$	High	High	High	High	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$	High	High	High	High	High	High	High
\overline{CASLH}	High	High	High	High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
\overline{WAIT}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

Table A.5 Pin States (Burst ROM/Little-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D31 to D24	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2–0) ≠ 101, high-Z.
 4. When WCR2 register wait setting is 0, disabled.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 6. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.6 Pin States (Burst ROM/Big-Endian)

Pin	8-Bit Bus Width		16-Bit Bus Width		
		Byte/Word/Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
CS6 to CS0		Enabled	Enabled	Enabled	Enabled
RD	R	Low	Low	Low	Low
	W	—	—	—	—
RD/WR	R	High	High	High	High
	W	—	—	—	—
BS		Enabled	Enabled	Enabled	Enabled
RAS/CE		High	High	High	High
CAS/CASLL/OE		High	High	High	High
CASLH		High	High	High	High
CASHL/CAS2L		High	High	High	High
CASHH/CAS2H		High	High	High	High
DQMLL/WE0	R	High	High	High	High
	W	—	—	—	—
DQMLU/WE1	R	High	High	High	High
	W	—	—	—	—
DQMUL/WE2/ICIORD	R	High	High	High	High
	W	—	—	—	—
DQMUU/WE3/ICIOWR	R	High	High	High	High
	W	—	—	—	—
MD3/CE2A		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE		Disabled	Disabled	Disabled	Disabled
WAIT		Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
IOIS16		Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address
D7 to D0		Valid data	Invalid data	Valid data	Valid data
D15 to D8		High-Z	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24		High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

Table A.6 Pin States (Burst ROM/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
CS $\bar{6}$ to CS $\bar{0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RD	R	Low	Low	Low	Low	Low	Low
	W	—	—	—	—	—	—
RD/WR	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
BS	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RAS/CE	High	High	High	High	High	High	High
CAS/CASLL/OE	High	High	High	High	High	High	High
CASLH	High	High	High	High	High	High	High
CASHL/CAS2L	High	High	High	High	High	High	High
CASHH/CAS2H	High	High	High	High	High	High	High
DQMLL/WE $\bar{0}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
DQMLU/WE $\bar{1}$	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
DQMUL/WE $\bar{2}$ /ICIOR \bar{D}	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
DQMUU/WE $\bar{3}$ /ICIOR \bar{W}	R	High	High	High	High	High	High
	W	—	—	—	—	—	—
MD3/CE2A	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS $\bar{2}$	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
WAIT	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
IOIS16	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

Table A.6 Pin States (Burst ROM/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D31 to D24	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2-0) ≠ 101, high-Z.
 4. When WCR2 register wait setting is 0, disabled.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register .
 6. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.7 Pin States (DRAM/Little-Endian)

Pin	16-Bit Bus Width (Area 3)			16-Bit Bus Width (Area 2)			
		Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access
$\overline{CS6}$ to $\overline{CS0}$		Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low
\overline{BS}		Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$		Low	Low	Low	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$		Low	High	Low	High	High	High
\overline{CASLH}		High	Low	Low	High	High	High
$\overline{CASHL}/\overline{CAS2L}$		High	High	High	Low	High	Low
$\overline{CASHH}/\overline{CAS2H}$		High	High	High	High	Low	Low
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{MD3}/\overline{CE2A}$		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	Low	Low	Low
\overline{CKE}		Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
\overline{WAIT}		Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
$\overline{IOIS16}$		Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address	Address	Address
D7 to D0		Valid data	Invalid data	Valid data	Valid data	Invalid data	Valid data
D15 to D8		Invalid data	Valid data	Valid data	Invalid data	Valid data	Valid data

Table A.7 Pin States (DRAM/Little-Endian) (cont)

Pin	16-Bit Bus Width (Area 3)			16-Bit Bus Width (Area 2)		
	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access
D23 to D16/ PORT7 to PORT0	High-Z ⁴	High-Z ⁴	High-Z ⁴	High-Z ⁴	High-Z ⁴	High-Z ⁴
D31 to D24	High-Z ⁵	High-Z ⁵	High-Z ⁵	High-Z ⁵	High-Z ⁵	High-Z ⁵

Table A.7 Pin States (DRAM/Little-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
CS $\bar{6}$ to CS $\bar{0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RD	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
RD/WR	R	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low
BS	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RAS/CE	Low	Low	Low	Low	Low	Low	Low
CAS/CASLL/OE	Low	High	High	High	Low	High	Low
CASLH	High	Low	High	High	Low	High	Low
CASHL/CAS2L	High	High	Low	High	High	Low	Low
CASHH/CAS2H	High	High	High	Low	High	Low	Low
DQMLL/WE $\bar{0}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
DQMLU/WE $\bar{1}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
DQMUL/WE2/ICIORD	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
DQMUU/WE3/ICIOWR	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
MD3/CE2A	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
WAIT	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
IOIS16	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

Table A.7 Pin States (DRAM/Little-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D31 to D24	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2–0) ≠ 101, high-Z.
 4. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.8 Pin States (DRAM/Big-Endian)

Pin	16-Bit Bus Width (Area 3)			16-Bit Bus Width (Area 2)			
		Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access
$\overline{CS6}$ to $\overline{CS0}$		Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low
\overline{BS}		Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$		Low	Low	Low	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$		High	Low	Low	High	High	High
\overline{CASLH}		Low	High	Low	High	High	High
$\overline{CASHL}/\overline{CAS2L}$		High	High	High	High	Low	Low
$\overline{CASHH}/\overline{CAS2H}$		High	High	High	Low	High	Low
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{MD3}/\overline{CE2A}$		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	Low	Low	Low
\overline{CKE}		Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
\overline{WAIT}		Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
$\overline{IOIS16}$		Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address	Address	Address
D7 to D0		Invalid data	Valid data	Valid data	Invalid data	Valid data	Valid data
D15 to D8		Valid data	Invalid data	Valid data	Valid data	Invalid data	Valid data

Table A.8 Pin States (DRAM/Big-Endian) (cont)

Pin	16-Bit Bus Width (Area 3)			16-Bit Bus Width (Area 2)		
	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/ Longword Access
D23 to D16/ PORT7 to PORT0	High-Z ⁴	High-Z ⁴	High-Z ⁴	High-Z ⁴	High-Z ⁴	High-Z ⁴
D31 to D24	High-Z ⁵	High-Z ⁵	High-Z ⁵	High-Z ⁵	High-Z ⁵	High-Z ⁵

Table A.8 Pin States (DRAM/Big-Endian) (cont)

Pin	32-Bit Bus Width							Longword Access
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)		
CS $\bar{6}$ to CS $\bar{0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RD	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
RD/WR	R	High	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low	Low
BS	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RAS/CE	Low	Low	Low	Low	Low	Low	Low	Low
CAS/CASLL/OE	High	High	High	Low	High	Low	Low	Low
CASLH	High	High	Low	High	High	Low	Low	Low
CASHL/CAS2L	High	Low	High	High	Low	High	Low	Low
CASHH/CAS2H	Low	High	High	High	Low	High	Low	Low
DQMLL/WE $\bar{0}$	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
DQMLU/WE $\bar{1}$	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
DQMUL/WE2/ICIORD	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
DQMUU/WE3/ICIOWR	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
MD3/CE2A	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
WAIT	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
IOIS16	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data	Valid data

Table A.8 Pin States (DRAM/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D31 to D24	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2–0) ≠ 101, high-Z.
 4. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.9 Pin States (Synchronous DRAM/Little-Endian)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$	Low	Low	Low	Low	Low	Low	Low
$\overline{CAS}/\overline{CASLL}/\overline{OE}$	Low	Low	Low	Low	Low	Low	Low
\overline{CASLH}	High	High	High	High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	Low	High	High	High	Low	High
	W	Low	High	High	High	Low	High
$\overline{DQMLU}/\overline{WE1}$	R	High	Low	High	High	Low	High
	W	High	Low	High	High	Low	High
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	Low	High	High	Low
	W	High	High	Low	High	High	Low
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	Low	High	Low
	W	High	High	High	Low	High	Low
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z
\overline{CKE}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}
\overline{WAIT}	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address, command	Address, command	Address, command	Address, command	Address, command	Address, command	Address, command
D7 to D0	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

Table A.9 Pin States (Synchronous DRAM/Little-Endian)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D31 to D24	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. Normally high. Low in self-refreshing.

Table A.10 Pin States (Synchronous DRAM/Big-Endian)

Pin	32-Bit Bus Width							Longword Access
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)		
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low	Low
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$	Low	Low	Low	Low	Low	Low	Low	Low
$\overline{CAS}/\overline{CASLL}/\overline{OE}$	Low	Low	Low	Low	Low	Low	Low	Low
\overline{CASLH}	High	High	High	High	High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	Low	High	Low	Low
	W	Low	High	High	Low	High	Low	Low
$\overline{DQMLU}/\overline{WE1}$	R	High	High	Low	High	High	Low	Low
	W	High	High	Low	High	High	Low	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	Low	High	High	Low	High	Low
	W	High	Low	Low	High	Low	High	Low
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	Low	High	High	High	Low	High	Low
	W	Low	High	High	Low	Low	High	Low
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z
\overline{CKE}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}	High ^{*3}
\overline{WAIT}	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address, command	Address, command	Address, command	Address, command	Address, command	Address, command	Address, command	Address, command
D7 to D0	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data	Valid data

Table A.10 Pin States (Synchronous DRAM/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D31 to D24	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. Normally high. Low in self-refreshing.

Table A.11 Pin States (Pseudo-SRAM/Little-Endian)

Pin	16-Bit Bus Width			
		Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
CS6 to CS0		Enabled	Enabled	Enabled
RD	R	High	High	High
	W	High	High	High
RD/WR	R	High	High	High
	W	Low	Low	Low
BS		Enabled	Enabled	Enabled
RAS/CE		Low	Low	Low
CAS/CASLL/OE		Low	Low	Low
CASLH		High	High	High
CASHL/CAS2L		High	High	High
CASHH/CAS2H		High	High	High
DQMLL/WE0	R	High	High	High
	W	Low	High	Low
DQMLU/WE1	R	High	High	High
	W	High	Low	Low
DQMUL/WE2/ICIORD	R	High	High	High
	W	High	High	High
DQMUU/WE3/ICIOWR	R	High	High	High
	W	High	High	High
MD3/CE2A		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2		High-Z	High-Z	High-Z
CKE		Disabled	Disabled	Disabled
WAIT		Disabled	Disabled	Disabled
IOIS16		Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address
D7 to D0		Valid data	Invalid data	Valid data
D15 to D8		Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*3}	High-Z ^{*3}	High-Z ^{*3}
D31 to D24		High-Z ^{*4}	High-Z ^{*4}	High-Z ^{*4}

Table A.11 Pin States (Pseudo-SRAM/Little-Endian) (cont)

Pin	32-Bit Bus Width							Longword Access
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)		
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
\overline{RD}	R	High	High	High	High	High	High	High
	W	High	High	High	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low	Low
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$	Low	Low	Low	Low	Low	Low	Low	Low
$\overline{CAS}/\overline{CASL}/\overline{OE}$	Low	Low	Low	Low	Low	Low	Low	Low
\overline{CASLH}	High	High	High	High	High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High	High
	W	Low	High	High	High	Low	High	Low
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High	High
	W	High	Low	High	High	Low	High	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	High	High	High
	W	High	High	Low	High	High	Low	Low
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High	High
	W	High	High	High	Low	High	Low	Low
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z
\overline{CKE}	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
\overline{WAIT}	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

Table A.11 Pin States (Pseudo-SRAM/Little-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D31 to D24	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 4. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.12 Pin States (Pseudo-SRAM/Big-Endian)

Pin	16-Bit Bus Width			
		Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
$\overline{CS6}$ to $\overline{CS0}$		Enabled	Enabled	Enabled
\overline{RD}	R	High	High	High
	W	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High
	W	Low	Low	Low
\overline{BS}		Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$		Low	Low	Low
$\overline{CAS}/\overline{CASLL}/\overline{OE}$		Low	Low	Low
\overline{CASLH}		High	High	High
$\overline{CASHL}/\overline{CAS2L}$		High	High	High
$\overline{CASHH}/\overline{CAS2H}$		High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High
	W	High	Low	Low
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High
	W	Low	High	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIORD}$	R	High	High	High
	W	High	High	High
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOWR}$	R	High	High	High
	W	High	High	High
$\overline{MD3}/\overline{CE2A}$		High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
$\overline{MD4}/\overline{CE2B}$		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$		High-Z	High-Z	High-Z
\overline{CKE}		Disabled	Disabled	Disabled
\overline{WAIT}		Disabled	Disabled	Disabled
$\overline{IOIS16}$		Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address
D7 to D0		Invalid data	Valid data	Valid data
D15 to D8		Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*3}	High-Z ^{*3}	High-Z ^{*3}
D31 to D24		High-Z ^{*4}	High-Z ^{*4}	High-Z ^{*4}

Table A.12 Pin States (Pseudo-SRAM/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
CS $\bar{6}$ to CS $\bar{0}$	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RD	R	High	High	High	High	High	High
	W	High	High	High	High	High	High
RD/WR	R	High	High	High	High	High	High
	W	Low	Low	Low	Low	Low	Low
BS	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
RAS/CE	Low	Low	Low	Low	Low	Low	Low
CAS/CASLL/OE	Low	Low	Low	Low	Low	Low	Low
CASLH	High	High	High	High	High	High	High
CASHL/CAS2L	High	High	High	High	High	High	High
CASHH/CAS2H	High	High	High	High	High	High	High
DQMLL/WE $\bar{0}$	R	High	High	High	High	High	High
	W	High	High	High	Low	High	Low
DQMLU/WE $\bar{1}$	R	High	High	High	High	High	High
	W	High	High	Low	High	High	Low
DQMUL/WE $\bar{2}$ /ICIORD	R	High	High	High	High	High	High
	W	High	Low	High	High	Low	High
DQMUU/WE $\bar{3}$ /ICIOWR	R	High	High	High	High	High	High
	W	Low	High	High	High	Low	High
MD3/CE2A	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}
MD4/CE2B	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS $\bar{2}$	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z	High-Z
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
WAIT	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
IOIS16	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled
A25 to A0	Address	Address	Address	Address	Address	Address	Address
D7 to D0	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data	Valid data

Table A.12 Pin States (Pseudo-SRAM/Big-Endian) (cont)

Pin	32-Bit Bus Width						
	Byte Access (Address 4n)	Byte Access (Address 4n + 1)	Byte Access (Address 4n + 2)	Byte Access (Address 4n + 3)	Word Access (Address 4n)	Word Access (Address 4n + 2)	Longword Access
D15 to D8	Invalid data	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0	Invalid data	Valid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data
D31 to D24	Valid data	Invalid data	Invalid data	Invalid data	Valid data	Invalid data	Valid data

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 4. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.13 Pin States (PCMCIA/Little-Endian)

Pin	8-Bit Bus Width		16-Bit Bus Width		
		Byte/Word/Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
CS6 to CS0		Enabled	Enabled	High	Enabled
RD	R	Low	Low	Low	Low
	W	High	High	High	High
RD/WR	R	High	High	High	High
	W	Low	Low	Low	Low
BS		Enabled	Enabled	Enabled	Enabled
RAS/CE		High	High	High	High
CAS/CASLL/OE		High	High	High	High
CASLH		High	High	High	High
CASHL/CAS2L		High	High	High	High
CASHH/CAS2H		High	High	High	High
DQMLL/WE0	R	High	High	High	High
	W	High	High	High	High
DQMLU/WE1	R	High	High	High	High
	W	Low	Low	Low	Low
DQMUL/WE2/ICIORD	R	High	High	High	High
	W	High	High	High	High
DQMUU/WE3/ICIOWR	R	High	High	High	High
	W	High	High	High	High
MD3/CE2A		High	High	Low	Low
MD4/CE2B		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
MD5/RAS2		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
CKE		Disabled	Disabled	Disabled	Disabled
WAIT		Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
IOIS16		Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address
D7 to D0		Valid data	Valid data	Invalid data	Valid data
D15 to D8		High-Z	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24		High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

Table A.13 Pin States (PCMCIA/Little-Endian) (cont)

Pin	PCMCIA Memory Interface (Area 6)					PCMCIA/IO Interface (Area 6)				
	8-Bit Bus Width	16-Bit Bus Width			8-Bit Bus Width	16-Bit Bus Width				
		Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)	Access (Ad- dress 2n + 1)		Word/ Long- word Access	Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)	Access (Ad- dress 2n + 1)	Word/ Long- word Access
$\overline{CS6}$ to $\overline{CS0}$	Enabled	Enabled	High	Enabled	Enabled	Enabled	High	Enabled		
\overline{RD}	R	Low	Low	Low	Low	High	High	High	High	
	W	High	High	High	High	High	High	High	High	
$\overline{RD}/\overline{WR}$	R	High	High	High	High	High	High	High	High	
	W	Low	Low	Low	Low	Low	Low	Low	Low	
\overline{BS}	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	
$\overline{RAS}/\overline{CE}$	High	High	High	High	High	High	High	High	High	
$\overline{CAS}/\overline{CASLL}/\overline{OE}$	High	High	High	High	High	High	High	High	High	
\overline{CASLH}	High	High	High	High	High	High	High	High	High	
$\overline{CASHL}/\overline{CAS2L}$	High	High	High	High	High	High	High	High	High	
$\overline{CASHH}/\overline{CAS2H}$	High	High	High	High	High	High	High	High	High	
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High	High	High	High	High	
	W	High	High	High	High	High	High	High	High	
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High	High	High	High	High	
	W	Low	Low	Low	Low	High	High	High	High	
$\overline{DQMUL}/\overline{WE2}/\overline{ICIOR\overline{D}}$	R	High	High	High	High	Low	Low	Low	Low	
	W	High	High	High	High	High	High	High	High	
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOR\overline{W}}$	R	High	High	High	High	High	High	High	High	
	W	High	High	High	High	Low	Low	Low	Low	
$\overline{MD3}/\overline{CE2A}$	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	High-Z or high ^{*1}	
$\overline{MD4}/\overline{CE2B}$	High	High	Low	Low	High	High	Low	Low		
$\overline{MD5}/\overline{RAS2}$	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	
\overline{CKE}	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	
\overline{WAIT}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	
$\overline{IOIS16}$	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled ^{*5}	Disabled ^{*5}		
A25 to A0	Address	Address	Address	Address	Address	Address	Address	Address		

Table A.13 Pin States (PCMCIA/Little-Endian) (cont)

Pin	PCMCIA Memory Interface (Area 6)				PCMCIA/IO Interface (Area 6)			
	8-Bit Bus Width	16-Bit Bus Width			8-Bit Bus Width	16-Bit Bus Width		
		Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)	Byte Access (Ad- dress 2n + 1)		Word/ Long- word Access	Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)
	D7 to D0	Valid data	Valid data	Invalid data	Valid data	Valid data	Valid data	Invalid data
D15 to D8	High-Z	Invalid data	Valid data	Valid data	High-Z	Invalid data	Valid data	Valid data
D23 to D16/ PORT7 to PORT0	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}
D31 to D24	High-Z ^{*7}	High-Z ^{*7}	High-Z ^{*7}	High-Z ^{*7}	High-Z ^{*7}	High-Z ^{*7}	High-Z ^{*7}	High-Z ^{*7}

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2-0) ≠ 101, high-Z.
 4. When WCR2 register wait setting is 0, disabled.
 5. Drive high.
 6. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 7. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Table A.14 Pin States (PCMCIA/BIG-Endian)

Pin	8-Bit Bus Width		16-Bit Bus Width		
		Byte/Word/Longword Access	Byte Access (Address 2n)	Byte Access (Address 2n + 1)	Word/Longword Access
$\overline{CS6}$ to $\overline{CS0}$		Enabled	Enabled	High	Enabled
\overline{RD}	R	Low	Low	Low	Low
	W	High	High	High	High
$\overline{RD}/\overline{WR}$	R	High	High	High	High
	W	Low	Low	Low	Low
\overline{BS}		Enabled	Enabled	Enabled	Enabled
$\overline{RAS}/\overline{CE}$		High	High	High	High
$\overline{CAS}/\overline{CASLL}/\overline{OE}$		High	High	High	High
\overline{CASLH}		High	High	High	High
$\overline{CASHL}/\overline{CAS2L}$		High	High	High	High
$\overline{CASHH}/\overline{CAS2H}$		High	High	High	High
$\overline{DQMLL}/\overline{WE0}$	R	High	High	High	High
	W	High	High	High	High
$\overline{DQMLU}/\overline{WE1}$	R	High	High	High	High
	W	Low	Low	Low	Low
$\overline{DQMUL}/\overline{WE2}/\overline{ICIORD}$	R	High	High	High	High
	W	High	High	High	High
$\overline{DQMUU}/\overline{WE3}/\overline{ICIOWR}$	R	High	High	High	High
	W	High	High	High	High
$\overline{MD3}/\overline{CE2A}$		High	High	Low	Low
$\overline{MD4}/\overline{CE2B}$		High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}	High-Z or high ^{*2}
$\overline{MD5}/\overline{RAS2}$		High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}	High-Z or high ^{*3}
\overline{CKE}		Disabled	Disabled	Disabled	Disabled
\overline{WAIT}		Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}	Enabled ^{*4}
$\overline{IOIS16}$		Disabled	Disabled	Disabled	Disabled
A25 to A0		Address	Address	Address	Address
D7 to D0		Valid data	Invalid data	Valid data	Valid data
D15 to D8		High-Z	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0		High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24		High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

Table A.14 Pin States (PCMCIA/BIG-Endian) (cont)

Pin	PCMCIA Memory Interface (Area 6)					PCMCIA/IO Interface (Area 6)				
	8-Bit Bus Width	16-Bit Bus Width			8-Bit Bus Width	16-Bit Bus Width				
		Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)	Byte Access (Ad- dress 2n + 1)		Word/ Long- word Access	Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)	Byte Access (Ad- dress 2n + 1)	Word/ Long- word Access
CS6 to CS0	Enabled	Enabled	High	Enabled	Enabled	Enabled	High	Enabled		
RD	R	Low	Low	Low	Low	High	High	High	High	
	W	High	High	High	High	High	High	High	High	
RD/WR	R	High	High	High	High	High	High	High	High	
	W	Low	Low	Low	Low	Low	Low	Low	Low	
BS	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	
RAS/CE	High	High	High	High	High	High	High	High	High	
CAS/CASLL/OE	High	High	High	High	High	High	High	High	High	
CASLH	High	High	High	High	High	High	High	High	High	
CASHL/CAS2L	High	High	High	High	High	High	High	High	High	
CASHH/CAS2H	High	High	High	High	High	High	High	High	High	
DQMLL/WE0	R	High	High	High	High	High	High	High	High	
	W	High	High	High	High	High	High	High	High	
DQMLU/WE1	R	High	High	High	High	High	High	High	High	
	W	Low	Low	Low	Low	High	High	High	High	
DQMUL/WE2/ICIORD	R	High	High	High	High	Low	Low	Low	Low	
	W	High	High	High	High	High	High	High	High	
DQMUU/WE3/ICIOWR	R	High	High	High	High	High	High	High	High	
	W	High	High	High	High	Low	Low	Low	Low	
MD3/CE2A	High-Z or high*1	High-Z or high*1	High-Z or high*1	High-Z or high*1	High-Z or high*1	High-Z or high*1	High-Z or high*1	High-Z or high*1	High-Z or high*1	
MD4/CE2B	High	High	Low	Low	High	High	Low	Low		
MD5/RAS2	High-Z or high*3	High-Z or high*3	High-Z or high*3	High-Z or high*3	High-Z or high*3	High-Z or high*3	High-Z or high*3	High-Z or high*3	High-Z or high*3	
CKE	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	
WAIT	Enabled*4	Enabled*4	Enabled*4	Enabled*4	Enabled*4	Enabled*4	Enabled*4	Enabled*4	Enabled*4	
IOIS16	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Enabled	Enabled		
A25 to A0	Address	Address	Address	Address	Address	Address	Address	Address		

Table A.14 Pin States (PCMCIA/BIG-Endian) (cont)

Pin	PCMCIA Memory Interface (Area 6)				PCMCIA/IO Interface (Area 6)			
	8-Bit Bus Width	16-Bit Bus Width			8-Bit Bus Width	16-Bit Bus Width		
		Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)	Byte Access (Ad- dress 2n + 1)		Word/ Long- word Access	Byte/ Word/ Long- word Access	Byte Access (Ad- dress 2n)
	D7 to D0	Valid data	Invalid data	Valid data	Valid data	Valid data	Invalid data	Valid data
D15 to D8	High-Z	Valid data	Invalid data	Valid data	High-Z	Valid data	Invalid data	Valid data
D23 to D16/ PORT7 to PORT0	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}	High-Z ^{*5}
D31 to D24	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}	High-Z ^{*6}

- Notes:
1. When BCR1.A5PCM = 0, high-Z.
 2. When BCR1.A6PCM = 0, high-Z.
 3. When BCR1.DRAMTP (2-0) ≠ 101, high-Z.
 4. When WCR2 register wait setting is 0, disabled.
 5. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, dependent on PCTR register.
 6. When BCR2.PORTEN = 0, high-Z. When BCR2.PORTEN = 1, D31 and D30 only data output.

Appendix B Control Registers

B.1 Register Address Map

The address map of memory-mapped control registers is shown in Table B-1. The following module abbreviations are used.

- MMU: Memory management unit
- UBC: User break controller
- CPG: Clock pulse generator
- BSC: Bus state controller
- RTC: Realtime clock
- INTC: Interrupt controller
- TMU: Timer unit
- SCI: Serial communication interface
- CAC: Cache

The Bus column shows the internal bus to which the control register is connected.

- S: System bus, to which the CPU, cache, TLB, multiplier, and UBC are connected.
- C: Cache bus, to which the BSC and cache are connected.
- P: Peripheral bus, to which the BSC and peripheral modules (RTC, INTC, TMU, and SCI) are connected.

The Size column shows the register size in bits.

The Access Size column shows the size used when the control register is accessed (read or written). If a size other than that indicated is used in an access, the result will be incorrect.

Table B.1 Memory-Mapped Control Register Address Map

Register	Abbreviation	Module	Bus	Address	Size	Access Size
Page table entry high register	PTEH	MMU	S	H'FFFFFFFF0	32	32
Page table entry low register	PTL	MMU	S	H'FFFFFFFF4	32	32
Translation table page register	TTB	MMU	S	H'FFFFFFFF8	32	32
TLB exception address register	TEA	MMU	S	H'FFFFFFFC	32	32
MMU control register	MMUCR	MMU	S	H'FFFFFFE0	32	32
Break ASID register A	BASRA	UBC	S	H'FFFFFFE4	8	8
Break ASID register B	BASRB	UBC	S	H'FFFFFFE8	8	8
Cache control register	CCR	CAC	S	H'FFFFFFEC	32	32
TRAPA exception register	TRA	INTC	S	H'FFFFFFD0	32	32
Exception event register	EXPEVT	INTC	S	H'FFFFFFD4	32	32
Interrupt event register	INTEVT	INTC	S	H'FFFFFFD8	32	32
Break address register A	BARA	UBC	S	H'FFFFFFB0	32	32
Break address mask register A	BAMRA	UBC	S	H'FFFFFFB4	8	8
Break bus cycle register A	BBRA	UBC	S	H'FFFFFFB8	16	16
Break address register B	BARB	UBC	S	H'FFFFFFFA0	32	32
Break address mask register B	BAMRB	UBC	S	H'FFFFFFFA4	8	8
Break bus cycle register B	BBRB	UBC	S	H'FFFFFFFA8	16	16
Break data register B	BDRB	UBC	S	H'FFFFFFF90	32	32
Break data mask register B	BDMRB	UBC	S	H'FFFFFFF94	32	32
Break control register	BRCR	UBC	S	H'FFFFFFF98	16	16
Frequency control register	FRQCR	CPG	S	H'FFFFFFF80	16	16
Standby control register	STBCR	CPG	S	H'FFFFFFF82	8	8
Watchdog timer counter	WTCNT	CPG	S	H'FFFFFFF84	8	R = 8, W = 16
Watchdog timer control/status register	WTCSR	CPG	S	H'FFFFFFF86	8	R = 8, W = 16
Bus control register 1	BCR1	BSC	C	H'FFFFFFF60	16	16
Bus control register 2	BCR2	BSC	C	H'FFFFFFF62	16	16

Table B.1 Memory-Mapped Control Register Address Map (cont)

Register	Abbreviation	Module	Bus	Address	Size	Access Size
Wait state control register 1	WCR1	BSC	C	H'FFFFFF64	16	16
Wait state control register 2	WCR2	BSC	C	H'FFFFFF66	16	16
Individual memory control register	MCR	BSC	C	H'FFFFFF68	16	16
DRAM control register	DCR	BSC	C	H'FFFFFF6A	16	16
PCMCIA control register	PCR	BSC	C	H'FFFFFF6C	16	16
Refresh timer control/status register	RTCSR	BSC	C	H'FFFFFF6E	16	16
Refresh timer counter	RTCNT	BSC	C	H'FFFFFF70	16	16
Refresh timer constant counter	RTCOR	BSC	C	H'FFFFFF72	16	16
Refresh count register	RFCR	BSC	C	H'FFFFFF74	16	16
Port control register	PCTR	BSC	C	H'FFFFFF76	16	16
Port data register	PDTR	BSC	C	H'FFFFFF78	8	8
Serial port register	SCSPTR	SCI	P	H'FFFFFF7C	8	8
SDRAM mode register	SDMR	BSC	C	H'FFFD000	8	8
64 Hz counter	R64CNT	RTC	P	H'FFFEC0	8	8
Second counter	RSECCNT	RTC	P	H'FFFEC2	8	8
Minute counter	RMINCNT	RTC	P	H'FFFEC4	8	8
Hour counter	RHRCNT	RTC	P	H'FFFEC6	8	8
Day-of-week counter	RWKCNT	RTC	P	H'FFFEC8	8	8
Day counter	RDAYCNT	RTC	P	H'FFFECA	8	8
Month counter	RMONCNT	RTC	P	H'FFFECC	8	8
Year counter	RYRCNT	RTC	P	H'FFFECE	8	8
Second alarm register	RSECAR	RTC	P	H'FFFED0	8	8
Minute alarm register	RMINAR	RTC	P	H'FFFED2	8	8
Hour alarm register	RHRAR	RTC	P	H'FFFED4	8	8
Day-of-week alarm register	RWKAR	RTC	P	H'FFFED6	8	8
Day alarm register	RDAYAR	RTC	P	H'FFFED8	8	8
Month alarm register	RMONAR	RTC	P	H'FFFEDA	8	8
RTC control register 1	RCR1	RTC	P	H'FFFEDC	8	8
RTC control register 2	RCR2	RTC	P	H'FFFEEDE	8	8

Table B.1 Memory-Mapped Control Register Address Map (cont)

Register	Abbreviation	Module	Bus	Address	Size	Access Size
Interrupt control register	ICR	INTC	P	H'FFFFFFE0	16	16
Interrupt priority level setting register A	IPRA	INTC	P	H'FFFFFFE2	16	16
Interrupt priority level setting register B	IPRB	INTC	P	H'FFFFFFE4	16	16
Timer output control register	TOCR	TMU	P	H'FFFFFFE90	8	8
Timer start register	TSTR	TMU	P	H'FFFFFFE92	8	8
Timer constant register 0	TCOR0	TMU	P	H'FFFFFFE94	32	32
Timer counter 0	TCNT0	TMU	P	H'FFFFFFE98	32	32
Timer control register 0	TCR0	TMU	P	H'FFFFFFE9C	16	16
Timer constant register 1	TCOR1	TMU	P	H'FFFFFFEA0	32	32
Timer counter 1	TCNT1	TMU	P	H'FFFFFFEA4	32	32
Timer control register 1	TCR1	TMU	P	H'FFFFFFEA8	16	16
Timer constant register 2	TCOR2	TMU	P	H'FFFFFFEAC	32	32
Timer counter 2	TCNT2	TMU	P	H'FFFFFFEB0	32	32
Timer control register 2	TCR2	TMU	P	H'FFFFFFEB4	16	16
Input capture register 2	TCPR2	TMU	P	H'FFFFFFEB8	32	32
Serial mode register	SCSMR	SCI	P	H'FFFFFFE80	8	8
Bit rate register	SCBRR	SCI	P	H'FFFFFFE82	8	8
Serial control register	SCSCR	SCI	P	H'FFFFFFE84	8	8
Transmit data register	SCTDR	SCI	P	H'FFFFFFE86	8	8
Serial status register	SCSSR	SCI	P	H'FFFFFFE88	8	8
Receive data register	SCRDR	SCI	P	H'FFFFFFE8A	8	8
Smartcard mode register	SCSCMR	SCI	P	H'FFFFFFE8C	8	8

B.2 Register Bit List

A register bit list is shown in table B.2

Table B.2 Register Bit List

Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module
SDMR	—	—	—	—					BSC
SCSMR	C/ \bar{A}	CHR	PE	O/ \bar{E}	STOP	MP	CKS1	CKS0	SCI
SCBRR									SCI
SCSCR	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	SCI
SCTSR									SCI
SCTDR									SCI
SCSSR	TDRE	RDRF	ORER	FER	PER	TEND	MPB	MPBT	SCI
SCRSR									SCI
SCRDR									SCI
SCSCMR	—	—	—	—	SDIR	SINV	—	SMIF	SCI
TOCR	—	—	—	—	—	—	—	TCOE	TMU
TSTR	—	—	—	—	—	STR2	STR1	STR0	TMU
TCOR0									TMU
TCNT0									TMU
TCR0	—	—	—	—	—	—	—	UNF	TMU
	—	—	UNIE	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	
TCOR1									TMU
TCNT1									TMU

Table B.2 Register Bit List (cont)

Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module
TCR1	—	—	—	—	—	—	—	UNF	TMU
	—	—	UNIE	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	
TCOR2	—	—	—	—	—	—	—	—	TMU
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
TCNT2	—	—	—	—	—	—	—	—	TMU
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
TCR2	—	—	—	—	—	—	ICPF	UNF	TMU
	ICPE1	ICPE0	UNIE	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	
TCPR2	—	—	—	—	—	—	—	—	TMU
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
R64CNT	—	1Hz	2Hz	4Hz	8Hz	16Hz	32Hz	64Hz	RTC
RSECCNT	—	10 seconds	10 seconds	10 seconds	1 second	1 second	1 second	1 second	RTC
RMINCNT	—	10 minutes	10 minutes	10 minutes	1 minute	1 minute	1 minute	1 minute	RTC
RHRCNT	—	—	10 hours	10 hours	1 hours	1 hour	1 hour	1 hour	RTC
RWKCNT	—	—	—	—	—	Day of week	Day of week	Day of week	RTC
RDAYCNT	—	—	10 days	10 days	1 day	1 day	1 day	1 day	RTC
RMONCNT	—	—	—	10 months	1 month	1 month	1 month	1 month	RTC
RYRCNT	10 years	10 years	10 years	10 years	1 year	1 year	1 year	1 year	RTC
RSECAR	ENB	10 seconds	10 seconds	10 seconds	1 second	1 second	1 second	1 second	RTC
RMINAR	ENB	10 minutes	10 minutes	10 minutes	1 minute	1 minute	1 minute	1 minute	RTC
RHRAR	ENB	—	10 hours	10 hours	1 hour	1 hour	1 hour	1 hour	RTC
RWKAR	ENB	—	—	—	—	Day of week	Day of week	Day of week	RTC
RDAYAR	ENB	—	10 days	10 days	1 day	1 day	1 day	1 day	RTC
RMONAR	ENB	—	—	10 months	1 month	1 month	1 month	1 month	RTC

Table B.2 Register Bit List (cont)

Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module
RCR1	CF	—	—	CIE	AIE	—	—	AF	RTC
RCR2	PEF	PES2	PES1	PES0	RTCEN	ADJ	RESET	START	RTC
ICR	NMIL	—	—	—	—	—	—	NMIE	INTC
	—	—	—	—	—	—	—	—	
IPRA	TMU0	TMU0	TMU0	TMU0	TMU1	TMU1	TMU1	TMU1	INTC
	TMU2	TMU2	TMU2	TMU2	RTC	RTC	RTC	RTC	
IPRB	WDT	WDT	WDT	WDT	REF	REF	REF	REF	INTC
	SCI	SCI	SCI	SCI	—	—	—	—	
BCR1	—	—	HIZMEM*	HIZCNT	ENDIAN	A0BST1	A0BST0	A5BST1	BSC
	A5BST0	A6BST1	A6BST0	DRAMTP2	DRAMTP1	DRAMTP0	A5PCM	A6PCM	
BCR2	—	—	A6SZ1	A6SZ0	A5SZ1	A5SZ0	A4SZ1	A4SZ0	BSC
	A3SZ1	A3SZ0	A2SZ1	A2SZ0	A1SZ1	A1SZ0	—	PORTEN	
WCR1	—	—	A6IW1	A6IW0	A5IW1	A5IW0	A4IW1	A4IW0	BSC
	A3IW1	A3IW0	A2IW1	A2IW0	A1IW1	A1IW0	A0IW1	A0IW0	
WCR2	A6W2	A6W1	A6W0	A5W2	A5W1	A5W0	A4W2	A4W1	BSC
	A4W0	A3W1	A3W0	A1-2W1	A1-2W0	A0W2	A0W1	A0W0	
MCR	TPC1	TPC0	RCD1	RCD0	TRWL1	TRWL0	TRAS1	TRAS0	BSC
	—	BE	SZ	AMX1	AMX0	RFSH	RMODE	EDOMODE	
DCR	TPC1	TPC0	RCD1	RCD0	—	—	TRAS1	TRAS0	BSC
	—	BE	—	AMX1	AMX0	RFSH	RMODE	—	
PCR	—	—	—	—	—	—	—	—	BSC
	A5TED1	A5TED0	A6TED1	A6TED0	A5TEH1	A5TEH0	A6TEH1	A6TEH0	
RTCSR	—	—	—	—	—	—	—	—	BSC
	CMF	CMIE	CKS2	CKS1	CKS0	OVF	OVIE	LMTS	
RTCNT	—	—	—	—	—	—	—	—	BSC
RTCOR	—	—	—	—	—	—	—	—	BSC
RFCR	—	—	—	—	—	—	—	—	BSC
PCTR	PB7PUP	PB7IO	PB6PUP	PB6IO	PB5PUP	PB5IO	PB4PUP	PB4IO	I/O
	PB3PUP	PB3IO	PB2PUP	PB2IO	PB1PUP	PB1IO	PB0PUP	PB0IO	
PDTR	PB7DT	PB6DT	PB5DT	PB4DT	PB3DT	PB2DT	PB1DT	PB0DT	I/O
SCSPTR	—	—	—	—	SPB1IO	SPB1DT	SPB0IO	SPB0DT	I/O

Table B.2 Register Bit List (cont)

Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module
FRQCR	STC2	IFC2	PFC2	—	—	—	—	CKOEN	CPG
	PLLEN	PSTBY	STC1	STC0	IFC1	IFC0	PFC1	PFC0	
STBCR	STBY	—	—	—	—	MSTP2	MSTP1	MSTP0	Power-down states
WTCNT									CPG
WTCSR	TME	WT/IT	RSTS	WOVF	IOVF	CKS2	CKS1	CKS0	CPG
BDRB	BDB31	BDB30	BDB29	BDB28	BDB27	BDB26	BDB25	BDB24	UBC
	BDB23	BDB22	BDB21	BDB20	BDB19	BDB18	BDB17	BDB16	
	BDB15	BDB14	BDB13	BDB12	BDB11	BDB10	BDB9	BDB8	
	BDB7	BDB6	BDB5	BDB4	BDB3	BDB2	BDB1	BDB0	
BDMRB	BDM31	BDM30	BDM29	BDM28	BDM27	BDM26	BDM25	BDM24	UBC
	BDM23	BDM22	BDM21	BDM20	BDM19	BDM18	BDM17	BDM16	
	BDM15	BDM14	BDM13	BDM12	BDM11	BDM10	BDM9	BDM8	
	BDM7	BDM6	BDM5	BDM4	BDM3	BDM2	BDM1	BDM0	
BRCR	CMFA	CMFB	—	—	—	PCBA	—	—	UBC
	DBEB	PCBB	—	—	SEQ	—	—	—	
BARB	BAB31	BAB30	BAB29	BAB28	BAB27	BAB26	BAB25	BAB24	UBC
	BAB23	BAB22	BAB21	BAB20	BAB19	BAB18	BAB17	BAB16	
	BAB15	BAB14	BAB13	BAB12	BAB11	BAB10	BAB9	BAB8	
	BAB7	BAB6	BAB5	BAB4	BAB3	BAB2	BAB1	BAB0	
BAMRB	—	—	—	—	—	BASMB	BAMB1	BAMB0	UBC
BBRB	—	—	—	—	—	—	—	—	UBC
	—	—	IDB1	IDB0	RWB1	RWB0	SZB1	SZB0	
BARA	BAA31	BAA30	BAA29	BAA28	BAA27	BAA26	BAA25	BAA24	UBC
	BAA23	BAA22	BAA21	BAA20	BAA19	BAA18	BAA17	BAA16	
	BAA15	BAA14	BAA13	BAA12	BAA11	BAA10	BAA9	BAA8	
	BAA7	BAA6	BAA5	BAA4	BAA3	BAA2	BAA1	BAA0	
BAMRA	—	—	—	—	—	BASMA	BAMA1	BAMA0	UBC
BBRA	—	—	—	—	—	—	—	—	UBC
	—	—	IDA1	IDA0	RWA1	RWA0	SZA1	SZA0	

Table B.2 Register Bit List (cont)

Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module
TRA	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
EXPEVT	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
INTEVT	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
MMUCR	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	SV	
	—	—	RC	RC	—	TF	IX	AT	
BASRA	BASA7	BASA6	BASA5	BASA4	BASA3	BASA2	BASA1	BASA0	UBC
BASRB	BASB7	BASB6	BASB5	BASB4	BASB3	BASB2	BASB1	BASB0	UBC
CCR	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
	—	—	RA	0	CF	CB	WT	CE	
PTEH	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
PTEL	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	V	
	—	PR	PR	SZ	C	D	SH	—	
TTB	—	—	—	—	—	—	—	—	CCN
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	
	—	—	—	—	—	—	—	—	

Table B.2 Register Bit List (cont)

Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module
TEA									CCN

Legend

SCI: Serial communication interface

TMU: Timer unit

RTC: Real time clock

INTC: Interrupt controller

BSC: Bus state controller

CPG: Clock pulse generator

UBC: User break controller

CCN: Cache controller unit

B.3 Register States in Reset and Power-Down States

Table B.3 Register States in Reset and Power-Down States

Module	Register	Reset States		Power-Down States	
		Power-On	Manual	Standby	Sleep
CPU	R0–R15	Undefined	Undefined	Held	Held
	MACH, MACL	Undefined	Undefined	Held	Held
	PR	Undefined	Undefined	Held	Held
	PC	H'A0000000	H'A0000000	Held	Held
	SR	Initialized*1	Initialized*1	Held	Held
	SSR	Undefined	Undefined	Held	Held
	SPC	Undefined	Undefined	Held	Held
	GBR	Undefined	Undefined	Held	Held
	VBR	H'00000000	H'00000000	Held	Held
MMU	PTEH	Undefined	Undefined	Held	Held
	PTEL	Undefined	Undefined	Held	Held
	TTB	Undefined	Undefined	Held	Held
	TEA	Undefined	Undefined	Held	Held
	MMUCR	Initialized*2	Initialized*2	Held	Held
Cache	CCR	H'00000000	H'00000000	Held	Held
INTC	ICR	H'8000/H'0000*3	H'8000/H'0000*3	Held	Held
	IPRA	H'0000	H'0000	Held	Held
	IPRB	H'0000	H'0000	Held	Held
	TRA	Undefined	Undefined	Held	Held
	EXPEVT	H'00000000	H'00000020	Held	Held
	INTEVT	Undefined	Undefined	Held	Held
UBC	BARA	Undefined	Held	Held	Held
	BASRA	Undefined	Held	Held	Held
	BAMRA	Undefined	Held	Held	Held

Table B.3 Register States in Reset and Power-Down States (cont)

Module	Register	Reset States		Power-Down States	
		Power-On	Manual	Standby	Sleep
UBC	BBRA	H'0000	H'0000	Held	Held
	BARB	Undefined	Held	Held	Held
	BAMRB	Undefined	Held	Held	Held
	BASRB	Undefined	Held	Held	Held
	BBRB	H'0000	H'0000	Held	Held
	BDMRB	Undefined	Held	Held	Held
	BDRB	Undefined	Held	Held	Held
	BRCR	H'0000	H'0000	Held	Held
CPG	STBCR	H'00	Held	Held	Held
	FRQCR	H'0102 ^{*4}	Held	Held	Held
	WTCNT	H'00 ^{*4}	Runs	Runs	Runs
	WTCSR	H'00 ^{*4}	Runs	Runs	Runs
BSC	BCR1	H'0000	Held	Held	Held
	BCR2	H'3FFC	Held	Held	Held
	WCR1	H'3FFF	Held	Held	Held
	WCR2	H'FFFF	Held	Held	Held
	MCR	H'0000	Held	Held	Held
	DCR	H'0000	Held	Held	Held
	PCR	H'0000	Held	Held	Held
	RTCSR	H'0000	Runs	Held	Runs
	RTCNT	H'0000	Runs	Held	Runs
	RTCOR	H'0000	Held	Held	Held
	RFCR	H'0000	Runs	Held	Runs
	PCTR	H'0000	Held	Held	Held
PDTR	Undefined	Held	Held	Held	

Table B.3 Register States in Reset and Power-Down States (cont)

Module	Register	Reset States		Power-Down States	
		Power-On	Manual	Standby	Sleep
TMU	TOCR	H'00	H'00	Held	Held
	TSTR	H'00	H'00	Initialized/ Held ^{*5}	Held
	TCOR0	H'FFFFFFF	H'FFFFFFF	Held	Held
	TCNT0	H'FFFFFFF	H'FFFFFFF	Held/Runs ^{*5}	Runs
	TCR0	H'0000	H'0000	Held/Runs ^{*5}	Runs
	TCOR1	H'FFFFFFF	H'FFFFFFF	Held	Held
	TCNT1	H'FFFFFFF	H'FFFFFFF	Held/Runs ^{*5}	Runs
	TCR1	H'0000	H'0000	Held/Runs ^{*5}	Runs
	TCOR2	H'FFFFFFF	H'FFFFFFF	Held	Held
	TCNT2	H'FFFFFFF	H'FFFFFFF	Held/Runs ^{*5}	Runs
	TCR2	H'0000	H'0000	Held/Runs ^{*5}	Runs
	TCPR2	Undefined	Undefined	Held	Held
RTC	R64CNT	Undefined	Runs	Runs	Runs
	RSECCNT	Runs	Runs	Runs	Runs
	RMINCNT	Runs	Runs	Runs	Runs
	RHRCNT	Runs	Runs	Runs	Runs
	RWKCNT	Runs	Runs	Runs	Runs
	RDAYCNT	Runs	Runs	Runs	Runs
	RMONCNT	Runs	Runs	Runs	Runs
	RYRCNT	Runs	Runs	Runs	Runs
	RSECAR	Held ^{*6}	Held	Held	Held
	RMINAR	Held ^{*6}	Held	Held	Held
	RHRAR	Held ^{*6}	Held	Held	Held
	RWKAR	Held ^{*6}	Held	Held	Held
	RDAYAR	Held ^{*6}	Held	Held	Held
	RMONAR	Held ^{*6}	Held	Held	Held
	RCR1	H'00	Initialized ^{*7}	Held	Held
	RCR2	H'09	Initialized ^{*8}	Held	Held

Table B.3 Register States in Reset and Power-Down States (cont)

Module	Register	Reset States		Power-Down States	
		Power-On	Manual	Standby	Sleep
SCI	SCSMR	H'00	H'00	H'00	H'00 ^{*10}
	SCBRR	H'FF	H'FF	H'FF	H'FF ^{*10}
	SCSCR	H'00	H'00	H'00	H'00 ^{*10}
	SCTDR	H'FF	H'FF	H'FF	H'FF ^{*10}
	SCSSR	H'84	H'84	H'84	H'84 ^{*10}
	SCRDR	H'00	H'00	H'00	H'00 ^{*10}
	SCSPTR	Initialized ^{*9}	Held	Held	Held
	SCSCMR	Initialized ^{*11}	Initialized ^{*11}	Initialized ^{*11}	Initialized ^{*11}

Notes: 1. MD = 1, RB = 1, BL = 1, I3-I0 = B'1111

M, Q, S, T are undefined.

2. The SV bit is undefined, other bits = 0.

3. H'8000: NMI pin is high / H'0000: NMI pin is low.

4. Initialized in a power-on reset via the $\overline{\text{RESET}}$ pin.
Held in a power-on reset via the WDT.

5. Depends on the count clock mode.

6. Only the ENB bit is cleared.

7. CF bit is undefined, other bits = 0.

8. RTCEN and START are held, other bits = 0.

9. Bits 2 and 0 are undefined, other bits = 0

10. Held when SCI is operating, initialized when SCI is not used.

11. Bits 0, 2, and 3 are cleared, other bits are undefined.

Appendix C Load Time Variation Due to Load Capacitance

A graph (reference data) of the variation in delay time when a load capacitance greater than that stipulated is connected to the SH7708R's pins. The graph shown in figure C.1 should be taken into consideration if the stipulated capacitance is exceeded in connecting an external device.

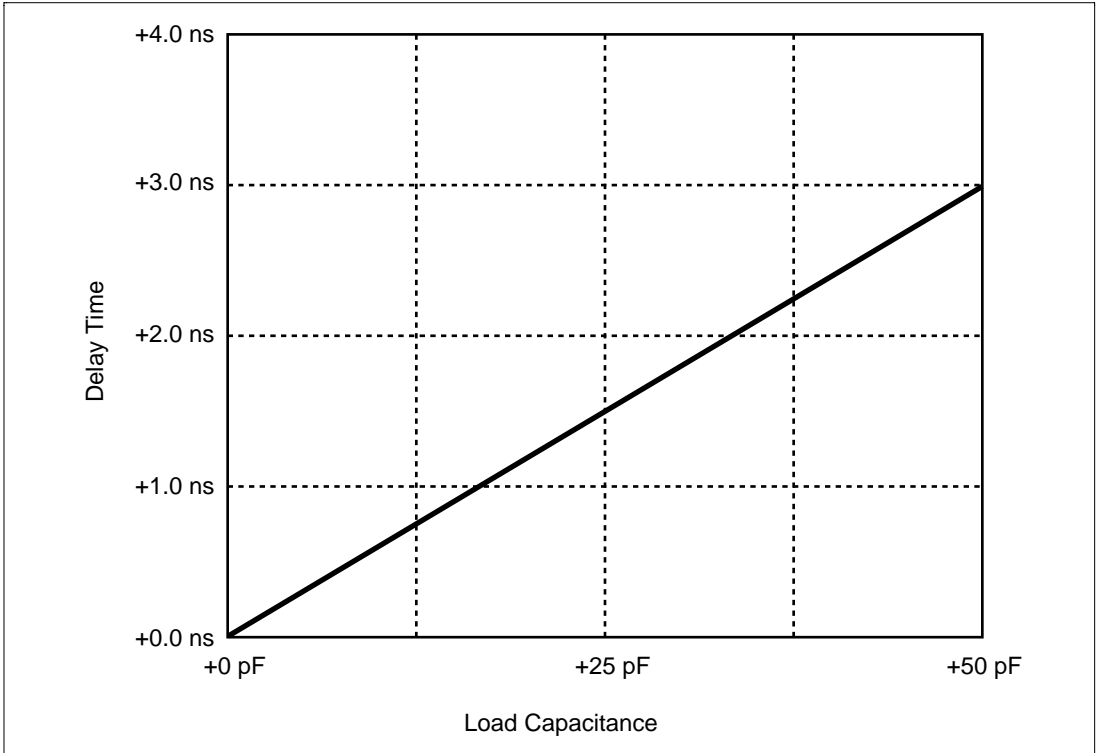


Figure C.1 Load Capacitance vs. Delay Time

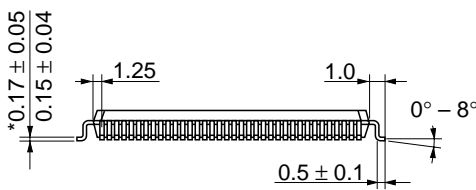
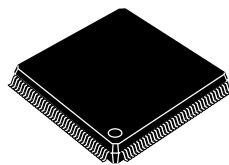
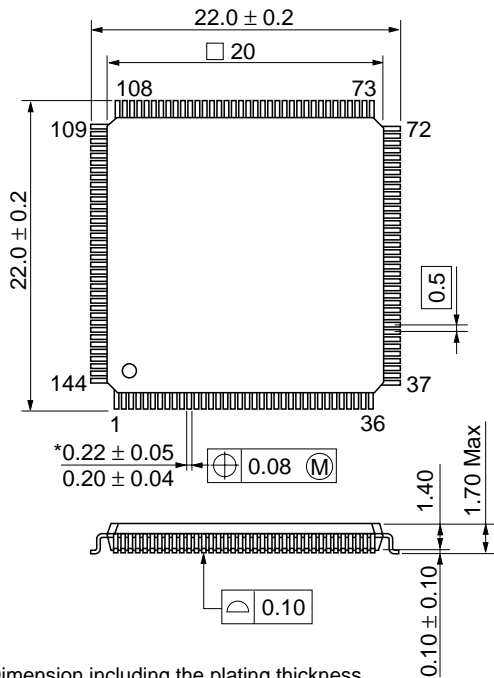
Appendix D List of Models

Table D.1 List of Models

Abbreviation	Voltage	Operating Frequency	Mask Version	Model Marking	Package
SH7718R	3.15 V to 3.6 V	100 MHz	—	HD6417718RF100	144-pin plastic
			A-mask	HD6417718RF100A	LQFP (FP-144F)

Appendix E Package Dimensions

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-144F
JEDEC	—
EIAJ	Conforms
Weight (reference value)	1.4 g

Figure E.1 Package Dimensions (FP-144F)

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